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H8/3067 Group

Hardware Manual
Renesas 16-Bit Single-Chip
Microcomputer
H8 Family/H8/300H Series

H8/3067 H8/3066 H8/3065 H8/3067RF

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Preface

The H8/3067 Group is a series of high-performance single-chip microcontrollers that integrate system supporting functions together with an H8/300H CPU core.

The H8/300H CPU has a 32-bit internal architecture with sixteen 16-bit general registers, and a concise, optimized instruction set designed for speed. It can address a 16-Mbyte linear address space.

The on-chip supporting functions include ROM, RAM, 16-bit timers, 8-bit timers, a programmable timing pattern controller (TPC), a watchdog timer (WDT), a serial communication interface (SCI), an A/D converter, a D/A converter, I/O ports, a DMA controller (DMAC), and other facilities. The three-channel SCI has been expanded to support the ISO/IEC7816-3 smart card interface. Functions have also been added to reduce power consumption in battery-powered applications: individual modules can be placed in standby, and the frequency of the system clock supplied to the chip can be divided down under software control.

The address space is divided into eight areas. The data bus width and access cycle length can be selected independently in each area, simplifying the connection of different types of memory. Seven MCU operating modes (modes 1 to 7) are provided, offering a choice of data bus width and address space size.

With these features, the H8/3067 Group offers easy implementation of compact, high-performance systems.

In addition to its mask ROM versions, the H8/3067 Group has an F-ZTAT^{TM*} version with onchip flash memory that can be programmed on-board. This version enables users to respond quickly and flexibly to changing application specifications.

This manual describes the H8/3067 Group hardware. For details of the instruction set, refer to the H8/300H Series Programming Manual.

Note: * F-ZTATTM (Flexible ZTAT) is a registered trademark of Renesas Technology Corp.

Main Revisions in This Edition

Item	Page	Revision (See Manual for Details)
All	_	Company name changed
		All references to Hitachi, Hitachi, Ltd., Hitachi Semiconductors, and other Hitachi brand names changed to Renesas Technology Corp.
		Designation for categories changed from "series" to "group"
		Designation changed
		H8/3067 Series → H8/3067 Group
		Changes due to change in package codes
		$FP-100A \rightarrow PRQP0100JE-B$
		$FP-100B \rightarrow PRQP0100KA-A$
		TFP-100B →PTQP0100KA-A
1.1 Overview	6	Table amended
Table 1.1 Features		Product lineup: HD64F3067F, HD64F3067TE, HD64F3067FP deleted
1.4.2 Product Type Names and Markings	_	Deleted
6.3.5 Address Output Method	150	Title amended
7.2.2 I/O Address	215	Description amended
Registers (IOAR)		An IOAR functions as a source or destination address register depending on how the DMAC is activated: as a source address register if activation is by a receive-data-full interrupt from serial communication interface (SCI) channel 0 or by an A/D converter conversion-end interrupt, and as a destination address register otherwise.
7.4.2 I/O Mode	231	Table amended
Table 7.6 Register		Function
Functions in I/O Mode		Activated by SCI 0 Receive-Data-Full Interrupt or by A/D Converter Register Conversion-End Interrupt Activation Initial Setting Operation

Item	Page	Revision (See Manual for Details)							
7.4.3 Idle Mode 234 Table amended									
Table 7.7 Register			Function						
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On-Board				mode 7		0*2	1	1	1 : V _{IH}
Programming Modes		User program mode		mode 5	_	1	0	1	
				mode 7		1	1	1	
B.2 Functions ADRCR	803	Note de	eleted						
Appendix F Product	926	Table a	mended						
Code Lineup		Product Code: HD64F3067F, HD64F3067TE and HD64F3067FP deleted							

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Section 1 Overview

1.1 Overview

The H8/3067 Group is a group of microcontrollers (MCUs) that integrate system supporting functions together with an H8/300H CPU core having an original Renesas architecture.

The H8/300H CPU has a 32-bit internal architecture with sixteen 16-bit general registers, and a concise, optimized instruction set designed for speed. It can address a 16-Mbyte linear address space. Its instruction set is upward-compatible at the object-code level with the H8/300 CPU, enabling easy porting of software from the H8/300 Series.

The on-chip system supporting functions include ROM, RAM, a 16-bit timer, an 8-bit timer, a programmable timing pattern controller (TPC), a watchdog timer (WDT), a serial communication interface (SCI), an A/D converter, a D/A converter, I/O ports, a direct memory access controller (DMAC), and other facilities.

The three members of the H8/3067 Group are the H8/3067, the H8/3066, and the H8/3065. The H8/3067 has 128 kbytes of ROM and 4 kbytes of RAM. The H8/3066 has 96 kbytes of ROM and 4 kbytes of RAM. The H8/3065 has 64 kbytes of ROM and 2 kbytes of RAM.

Seven MCU operating modes offer a choice of bus width and address space size. The modes (modes 1 to 7) include two single-chip modes and five expanded modes.

In addition to the mask ROM versions, the H8/3067 Group includes an F-ZTAT^{TM*} version with on-chip flash memory that can be programmed on-board. This version enables users to respond quickly and flexibly to changing application specifications, growing production volumes, and other conditions.

Table 1.1 summarizes the features of the H8/3067 Group.

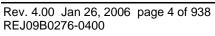
Note: * F-ZTATTM (Flexible ZTAT) is a trademark of Renesas Technology Corp.

Table 1.1 Features

Feature	Description								
CPU	Upward-compatible with the H8/300 CPU at the object-code level General-register machine								
	 Sixteen 16-bit general registers (also usable as sixteen 8-bit registers or eight 32-bit registers) 								
	High-speed operation								
	Maximum clock rate: 20 MHz								
	Add/subtract: 100 ns								
	Multiply/divide: 700 ns								
	16-Mbyte address space								
	Instruction features								
	 8/16/32-bit data transfer, arithmetic, and logic instructions 								
	 Signed and unsigned multiply instructions (8 bits x 8 bits, 16 bits x 16 bits) 								
	 Signed and unsigned divide instructions (16 bits ÷ 8 bits, 32 bits ÷ 16 bits) 								
	Bit accumulator function								
	Bit manipulation instructions with register-indirect specification of bit positions								
Memory	H8/3067								
	ROM: 128 kbytes								
	RAM: 4 kbytes								
	H8/3066								
	ROM: 96 kbytes								
	RAM: 4 kbytes								
	H8/3065								
	ROM: 64 kbytes								
	RAM: 2 kbytes								
Interrupt	• Seven external interrupt pins: NMI, $\overline{\overline{IRQ}}_{_0}$ to $\overline{\overline{IRQ}}_{_5}$								
controller	36 internal interrupts								
	Three selectable interrupt priority levels								

Feature	Description
Bus controller	Address space can be partitioned into eight areas, with independent bus
	specifications in each area
	Chip select output available for areas 0 to 7
	8-bit access or 16-bit access selectable for each area
	Two-state or three-state access selectable for each area
	Selection of two wait modes
	Number of program wait states selectable for each area
	Direct connection of burst ROM
	 Direct connection of up to 8-Mbyte DRAM (or DRAM interface can be used as interval timer)
	Bus arbitration function
DMA controller	Short address mode
(DMAC)	Maximum four channels available
	Selection of I/O mode, idle mode, or repeat mode
	 Can be activated by compare match/input capture A interrupts from 16-bit timer channels 0 to 2, conversion-end interrupts from the A/D converter, transmit-data-empty and receive-data-full interrupts from the SCI, or external requests
	Full address mode
	Maximum two channels available
	Selection of normal mode or block transfer mode
	 Can be activated by compare match/input capture A interrupts from 16-bit timer channels 0 to 2, conversion-end interrupts from the A/D converter, external requests, or auto-request
16-bit timer, 3 channels	Three 16-bit timer channels, capable of processing up to six pulse outputs or six pulse inputs
	16-bit timer counter (channels 0 to 2)
	• Two multiplexed output compare/input capture pins (channels 0 to 2)
	Operation can be synchronized (channels 0 to 2)
	PWM mode available (channels 0 to 2)
	Phase counting mode available (channel 2)
	DMAC can be activated by compare match/input capture A interrupts (channels 0 to 2)

Feature	Description
8-bit timer,	8-bit up-counter (external event count capability)
4 channels	Two time constant registers
	Two channels can be connected
Programmable	Maximum 16-bit pulse output, using 16-bit timer as time base
timing pattern controller (TPC)	• Up to four 4-bit pulse output groups (or one 16-bit group, or two 8-bit groups)
controller (TPC)	Non-overlap mode available
	Output data can be transferred by DMAC
Watchdog	Reset signal can be generated by overflow
timer (WDT), 1 channel	Reset signal can be output externally (not in the F-ZTAT version)
i Channei	Usable as an interval timer
Serial	Selection of asynchronous or synchronous mode
communication interface (SCI),	Full duplex: can transmit and receive simultaneously
3 channels	On-chip baud-rate generator
	Smart card interface functions added
A/D converter	Resolution: 10 bits
	Eight channels, with selection of single or scan mode
	Variable analog conversion voltage range
	Sample-and-hold function
	 A/D conversion can be started by an external trigger or 8-bit timer comparematch
	DMAC can be activated by an A/D conversion end interrupt
D/A converter	Resolution: 8 bits
	Two channels
	D/A outputs can be sustained in software standby mode
I/O ports	70 input/output pins
	9 input-only pins





Feature	Description								
Operating modes	Seven MCU operating modes								
	Mode	Address Space	A ddress Pins	Initial Bus Width	Max. Bus Width				
	Mode 1	1 Mbyte	A ₁₉ to A ₀	8 bits	16 bits				
	Mode 2	1 Mbyte	A ₁₉ to A ₀	16 bits	16 bits				
	Mode 3	16 Mbytes	A ₂₃ to A ₀	8 bits	16 bits				
	Mode 4	16 Mbytes	A ₂₃ to A ₀	16 bits	16 bits				
	Mode 5	16 Mbytes	A ₂₃ to A ₀	8 bits	16 bits				
	Mode 6	64 kbyte	_	_	_				
	Mode 7	1 Mbyte	_	_	_				
	On-chip ROM is disabled in modes 1 to 4								
Power-down	• Slee	p mode							
state	Software standby mode								
	Hardware standby mode								
	Module standby function								
	Programmable system clock frequency division								
Other features	• On-0	chip clock pulse g	enerator						

Feature	Descripti	Description							
Product	Product Type		Product Code	Package					
lineup	H8/3067	On-chip	5 VR	HD64F3067RF	100-pin QFP (PRQP0100KA-A)				
		flash memory		HD64F3067RTE	100-pin TQFP (PTQP0100KA-A)				
		Hemory		HD64F3067RFP	100-pin QFP (PRQP0100JE-B)				
			3 VR	HD64F3067RVF	100-pin QFP (PRQP0100KA-A)				
				HD64F3067RVTE	100-pin TQFP (PTQP0100KA-A)				
				HD64F3067RVFP	100-pin QFP (PRQP0100JE-B)				
		On-chip	5 V	HD6433067F	100-pin QFP (PRQP0100KA-A)				
		mask ROM		HD6433067TE	100-pin TQFP (PTQP0100KA-A)				
		KOW		HD6433067FP	100-pin QFP (PRQP0100JE-B)				
			3 V	HD6433067VF	100-pin QFP (PRQP0100KA-A)				
				HD6433067VTE	100-pin TQFP (PTQP0100KA-A)				
				HD6433067VFP	100-pin QFP (PRQP0100JE-B)				
	H8/3066	On-chip mask ROM	5 V	HD6433066F	100-pin QFP (PRQP0100KA-A)				
				HD6433066TE	100-pin TQFP (PTQP0100KA-A)				
				HD6433066FP	100-pin QFP (PRQP0100JE-B)				
				HD6433066VF	100-pin QFP (PRQP0100KA-A)				
				HD6433066VTE	100-pin TQFP (PTQP0100KA-A)				
				HD6433066VFP	100-pin QFP (PRQP0100JE-B)				
	H8/3065	mask	5 V	HD6433065F	100-pin QFP (PRQP0100KA-A)				
				HD6433065TE	100-pin TQFP (PTQP0100KA-A)				
		ROM		HD6433065FP	100-pin QFP (PRQP0100JE-B)				
			3 V	HD6433065VF	100-pin QFP (PRQP0100KA-A)				
				HD6433065VTE	100-pin TQFP (PTQP0100KA-A)				
				HD6433065VFP	100-pin QFP (PRQP0100JE-B)				

1.2 Block Diagram

Figure 1.1 shows an internal block diagram.

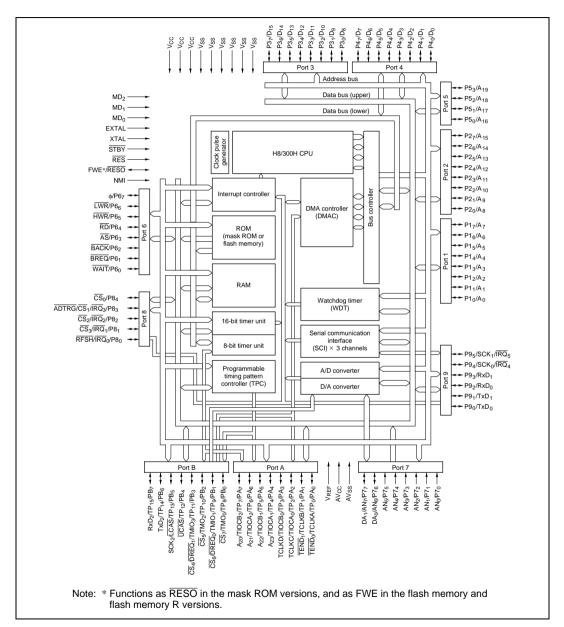


Figure 1.1 Block Diagram

1.3 Pin Description

1.3.1 Pin Arrangement

The pin arrangement of the H8/3067 Group PRQP0100KA-A and PTQP0100KA-A packages is shown in figure 1.2, and that of the PRQP0100JE-B package in figure 1.3.

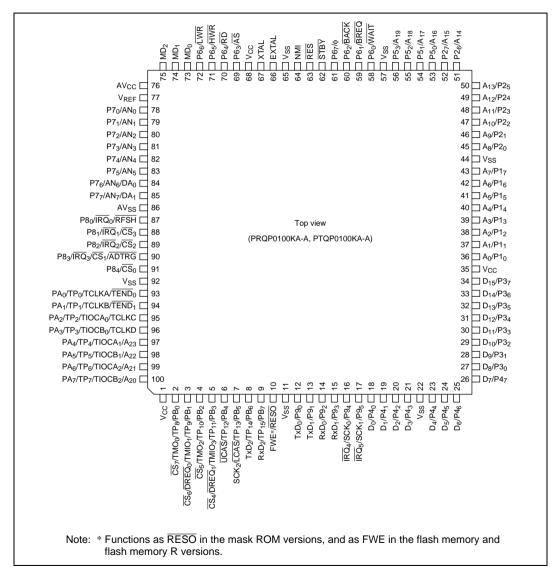


Figure 1.2 Pin Arrangement (PRQP0100KA-A or PTQP0100KA-A, Top View)

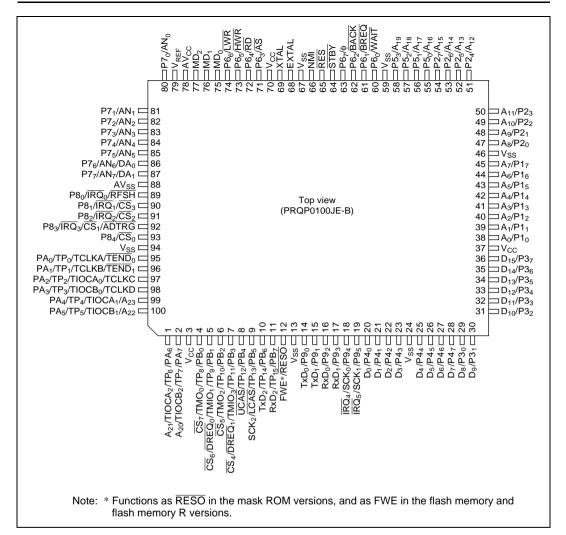


Figure 1.3 Pin Arrangement (PRQP0100JE-B, Top View)

1.3.2 Pin Functions

Table 1.2 summarizes the pin functions.

Table 1.2 Pin Functions

		Pin No.		_	
Туре	Symbol	PRQP 0100KA-A PTQP 0100KA-A	PRQP 0100JE-B	I/O	Name and Function
Power	V _{cc}	1, 35, 68	3, 37, 70	Input	Power: For connection to the power supply. Connect all V _{cc} pins to the system power supply.
	V _{SS}	11, 22, 44, 57, 65, 92	13, 24, 46, 59, 67, 94	Input	Ground: For connection to ground (0 V). Connect all V_{ss} pins to the 0-V system power supply.
Clock	XTAL	67	69	Input	For connection to a crystal resonator. For examples of crystal resonator and external clock input, see section 19, Clock Pulse Generator.
	EXTAL	66	68	Input	For connection to a crystal resonator or input of an external clock signal. For examples of crystal resonator and external clock input, see section 19, Clock Pulse Generator.
	ф	61	63	Output	System clock: Supplies the system clock to external devices.

		Pin No. PRQP 0100KA-A PTQP	PRQP	_				
Туре	Symbol	0100KA-A	0100JE-B	I/O	Name	and Fu	nction	
Operating mode control	MD ₂ to	75 to 73	77 to 75	Input	Mode 2 to mode 0: For setting the operating mode, as follows. Inputs at these pins must not be changed during operation.			
					$MD_{\scriptscriptstyle 2}$	$MD_{\scriptscriptstyle 1}$	MD_{o}	Operating Mode
					0	0	0	_
					0	0	1	Mode 1
					0	1	0	Mode 2
					0	1	1	Mode 3
					1	0	0	Mode 4
					1	0	1	Mode 5
					1	1	0	Mode 6
					1	1	1	Mode 7
System control	RES	63	65	Input		input: 'the chip		ven low, this pin
	RESO	10	12	Output	Reset output (Mask ROM version): Outputs the reset signal generated by the watchdog timer to external devices			
	FWE	10	12	Input	Write enable signal (Flash memory and flash memory R versions): Flash memory write control signal			
	STBY	62	64	Input	Standby: When driven low, this pin a transition to hardware standby m			•
	BREQ	59	61	Input			Used by uest the b	an external bus ous right
	BACK	60	62	Output		s has be		edge: Indicates that red to an external
Interrupts	NMI	64	66	Input			e interruj interrupt	ot: Requests a
	IRQ₅ to IRQ₀	17, 16, 90 to 87	19, 18, 92 to 89	Input			uest 5 to est pins	0: Maskable

Туре	Symbol	Pin No. PRQP 0100KA-A PTQP 0100KA-A	PRQP 0100JE-B	1/0	Name and Function
Address bus	A ₂₃ to A ₀	97 to 100, 56 to 45, 43 to 36	99, 100, 1, 2, 58 to 47, 45 to 38	Output	Address bus: Outputs address signals
Data bus	D ₁₅ to D ₀	34 to 23, 21 to 18	36 to 25, 23 to 20	Input/ output	Data bus: Bidirectional data bus
Bus control	CS _₀ to	2 to 5, 88 to 91	4 to 7, 90 to 93	Output	Chip select: Select signals for areas 7 to 0
	ĀS	69	71	Output	Address strobe: Goes low to indicate valid address output on the address bus
	RD	70	72	Output	Read: Goes low to indicate reading from the external address space
	HWR	71	73	Output	High write: Goes low to indicate writing to the external address space; indicates valid data on the upper data bus $(D_{15}$ to $D_8)$.
Bus control	LWR	72	74	Output	Low write: Goes low to indicate writing to the external address space; indicates valid data on the lower data bus (D_7 to D_0).
	WAIT	58	60	Input	Wait: Requests insertion of wait states in bus cycles during access to the external address space
DRAM interface	RFSH	87	89	Output	Refresh: Indicates a refresh cycle
	$\overline{\frac{CS}{CS_{5}}}$ to	89, 88, 5, 4	91, 90, 7, 6	Output	Row address strobe RAS: Row address strobe signal for DRAM
	RD	70	72	Output	Write enable WE : Write enable signal for DRAM
	HWR UCAS	71 6	73 8	Output	Upper column address strobe UCAS: Column address strobe signal for DRAM
	LWR LCAS	72 7	74 9	Output	Lower column address strobe COLUMN address strobe signal for DRAM
DMA controller (DMAC)	DREQ ₁ ,	5, 3	7, 5	Input	DMA request 1 and 0: DMAC activation requests
	TEND ₁ , TEND ₀	94, 93	96, 95	Output	Transfer end 1 and 0: These signals indicate that the DMAC has ended a data transfer

		Pin No.		-	
Туре	Symbol	0100KA-A PTQP 0100KA-A	PRQP 0100JE-B	I/O	Name and Function
16-bit timer	TCLKD to TCLKA	96 to 93	98 to95	Input	Clock input D to A: External clock inputs
	TIOCA ₂ to TIOCA ₀	99, 97, 95	1, 99, 97	Input/ output	Input capture/output compare A2 to A0: GRA2 to GRA0 output compare or input capture, or PWM output
	TIOCB ₂ to TIOCB ₀	100, 98, 96	2, 100, 98	Input/ output	Input capture/output compare B2 to B0: GRB2 to GRB0 output compare or input capture, or PWM output
8-bit timer	TMO ₀ ,	2, 4	4, 6	Output	Compare match output: Compare match output pins
	TMIO ₁ , TMIO ₃	3, 5	5, 7	Input/ output	Input capture input/compare match output: Input capture input or compare match output pins
	TCLKD to TCLKA	96 to 93	98 to 95	Input	Counter external clock input: These pins input an external clock to the counters.
Program- mable timing pattern controller (TPC)	TP ₁₅ to TP ₀	9 to 2, 100 to 93	11 to 4, 2, 1, 100 to 95	Output	TPC output 15 to 0: Pulse output
Serial communi-	TxD ₂ to TxD ₀	8, 13, 12	10, 15, 14	Output	Transmit data (channels 0, 1, 2): SCI data output
cation interface (SCI)	RxD ₂ to RxD ₀	9, 15, 14	11, 17, 16	Input	Receive data (channels 0, 1, 2): SCI data input
(301)	SCK ₂ to SCK ₀	7, 17, 16	9, 19, 18	Input/ output	Serial clock (channels 0, 1, 2): SCI clock input/output
A/D converter	AN ₇ to AN ₀	85 to 78	87 to 80	Input	Analog 7 to 0: Analog input pins
	ADTRG	90	92	Input	A/D conversion external trigger input: External trigger input for starting A/D conversion
D/A converter	DA ₁ , DA ₀	85, 84	87, 86	Output	Analog output: Analog output from the D/A converter

		Pin No.			
Туре	Symbol	PRQP 0100KA-A PTQP 0100KA-A	PRQP 0100JE-B	I/O	Name and Function
A/D and D/A converters	AV _{cc}	76	78	Input	Power supply pin for the A/D and D/A converters. Connect to the system power supply when not using the A/D and D/A converters.
	AV _{ss}	86	88	Input	Ground pin for the A/D and D/A converters. Connect to system ground (0 V).
	V _{REF}	77	79	Input	Reference voltage input pin for the A/D and D/A converters. Connect to the system power supply when not using the A/D and D/A converters.
I/O ports	P1, to P1 ₀	43 to 36	45 to 38	Input/ output	Port 1: Eight input/output pins. The direction of each pin can be selected in the port 1 data direction register (P1DDR).
_	P2, to P2 ₀	52 to 45	54 to 47	Input/ output	Port 2: Eight input/output pins. The direction of each pin can be selected in the port 2 data direction register (P2DDR).
	P3, to P3 ₀	34 to 27	36 to 29	Input/ output	Port 3: Eight input/output pins. The direction of each pin can be selected in the port 3 data direction register (P3DDR).
	P4 ₇ to P4 ₀	26 to 23, 21 to 18	28 to 25, 23 to 20	Input/ output	Port 4: Eight input/output pins. The direction of each pin can be selected in the port 4 data direction register (P4DDR).
	P5 ₃ to P5 ₀	56 to 53	58 to 55	Input/ output	Port 5: Four input/output pins. The direction of each pin can be selected in the port 5 data direction register (P5DDR).
	P6, to P6 ₀	61, 72 to 69, 60 to 58	63, 74 to 71, 62 to 60	Input/ output	Port 6: Eight input/output pins. The direction of each pin can be selected in the port 6 data direction register (P6DDR).
	P7, to P7 ₀	85 to 78	87 to 80	Input	Port 7: Eight input pins
	P8 ₄ to P8 ₀	91 to 87	93 to 89	Input/ output	Port 8: Five input/output pins. The direction of each pin can be selected in the port 8 data direction register (P8DDR).
	P9 ₅ to P9 ₀	17 to 12	19 to 14	Input/ output	Port 9: Six input/output pins. The direction of each pin can be selected in the port 9 data direction register (P9DDR).

		Pin No.			
Туре	Symbol	PRQP 0100KA-A PTQP 0100KA-A	PRQP 0100JE-B	I/O	Name and Function
I/O ports	PA ₇ to PA ₀	100 to 93	2, 1, 100 to 95	Input/ output	Port A: Eight input/output pins. The direction of each pin can be selected in the port A data direction register (PADDR).
	PB ₇ to PB ₀	9 to 2	11 to 4	Input/ output	Port B: Eight input/output pins. The direction of each pin can be selected in the port B data direction register (PBDDR).

1.3.3 Pin Assignments in Each Mode

Table 1.3 lists the pin assignments in each mode.

Table 1.3 Pin Assignments in Each Mode (PRQP0100KA-A or PTQP0100KA-A, PRQP0100JE-B)

Pin No.		Pin name						
PRQP 0100KA-A								
PTQP 0100KA-A	PRQP 0100JE-B	Mode 1	Mode 2	Mode 3	Mode 4	Mode 5	Mode 6	Mode 7
1	3	V _{CC}	V _{CC}	V _{CC}	V _{CC}	V _{CC}	V _{cc}	V _{cc}
2	4	PB ₀ /TP ₈ / TMO ₀ / CS ₇	PB ₀ /TP ₈ / TMO ₀ / CS ₇	PB ₀ /TP ₈ / TMO ₀ / CS ₇	PB ₀ /TP ₈ / TMO ₀ / CS ₇	$PB_0/TP_8/TMO_0/\overline{CS}_7$	PB ₀ /TP ₈ / TMO ₀	PB ₀ /TP ₈ / TMO ₀
3	5	PB ₁ /TP ₉ / TMIO ₁ / DREQ ₀ /CS ₆	PB ₁ /TP ₉ / TMIO ₁ / DREQ ₀ /CS ₆	PB ₁ /TP ₉ / TMIO ₁ / DREQ ₀ /CS ₆	PB ₁ /TP ₉ / TMIO ₁ / DREQ ₀ /CS ₆	PB ₁ /TP ₉ / TMIO ₁ / DREQ ₀ /CS ₆	PB ₁ /TP ₉ / TMIO ₁ / DREQ ₀	PB ₁ /TP ₉ / TMIO ₁ / DREQ ₀
4	6	$PB_2/TP_{10}/$ TMO_2/\overline{CS}_5	PB ₂ /TP ₁₀ / TMO ₂ / CS ₅	$PB_2/TP_{10}/$ TMO_2/\overline{CS}_5	PB ₂ /TP ₁₀ / TMO ₂ / CS ₅	$PB_2/TP_{10}/$ TMO_2/\overline{CS}_5	PB ₂ /TP ₁₀ / TMO ₂	PB ₂ /TP ₁₀ / TMO ₂
5	7	PB ₃ /TP ₁₁ / TMIO ₃ / DREQ ₁ /CS ₄	PB ₃ /TP ₁₁ / TMIO ₃ / DREQ ₁ /CS ₄	PB ₃ /TP ₁₁ / TMIO ₃ / DREQ ₁ /CS ₄	PB ₃ /TP ₁₁ / TMIO ₃ / DREQ ₁ /CS ₄	PB ₃ /TP ₁₁ / TMIO ₃ / DREQ ₁ /CS ₄	PB ₃ /TP ₁₁ / TMIO ₃ / DREQ ₁	PB ₃ /TP ₁₁ / TMIO ₃ / DREQ ₁
6	8	$\frac{PB_4/TP_{_{12}}}{UCAS}$	$\frac{PB_4/TP_{12}}{UCAS}$	$\frac{PB_4/TP_{\scriptscriptstyle{12}}}{UCAS}$	$\frac{PB_4/TP_{_{12}}}{UCAS}$	$\frac{PB_4/TP_{12}}{UCAS}$	PB ₄ /TP ₁₂	PB ₄ /TP ₁₂
7	9	$\frac{PB_{\scriptscriptstyle{5}}\!/TP_{\scriptscriptstyle{13}}\!/}{LCAS/SCK_{\scriptscriptstyle{2}}}$	PB ₅ /TP ₁₃ / \overline{LCAS}/SCK ₂	$\frac{PB_{\scriptscriptstyle{5}}\!/TP_{\scriptscriptstyle{13}}\!/}{LCAS/SCK_{\scriptscriptstyle{2}}}$	$\frac{PB_{\scriptscriptstyle{5}}\!/TP_{\scriptscriptstyle{13}}\!/}{\overline{LCAS}/SCK_{\scriptscriptstyle{2}}}$	PB ₅ /TP ₁₃ / \overline{LCAS}/SCK ₂	PB _s /TP ₁₃ / SCK ₂	PB ₅ /TP ₁₃ / SCK ₂
8	10	PB ₆ /TP ₁₄ / TxD ₂	PB ₆ /TP ₁₄ / TxD ₂	PB ₆ /TP ₁₄ / TxD ₂	PB ₆ /TP ₁₄ / TxD ₂	PB ₆ /TP ₁₄ / TxD ₂	PB ₆ /TP ₁₄ / TxD ₂	PB ₆ /TP ₁₄ / TxD ₂
9	11	PB ₇ /TP ₁₅ / RxD ₂	PB ₇ /TP ₁₅ / RxD ₂	PB ₇ /TP ₁₅ / RxD ₂	PB ₇ /TP ₁₅ / RxD ₂	PB ₇ /TP ₁₅ / RxD ₂	PB ₇ /TP ₁₅ / RxD ₂	PB ₇ /TP ₁₅ / RxD ₂
10	12	RESO/ FWE*3	RESO/ FWE*3	RESO/ FWE*3	RESO/ FWE*3	RESO/ FWE*3	RESO/ FWE*3	RESO/ FWE*3
11	13	V _{ss}	V _{ss}	V _{ss}	V _{ss}	V _{ss}	V _{ss}	V _{ss}
12	14	P9 ₀ /TxD ₀	P9 ₀ /TxD ₀	P9 ₀ /TxD ₀	P9 ₀ /TxD ₀	P9 ₀ /TxD ₀	P9 ₀ /TxD ₀	P9 ₀ /TxD ₀
13	15	P9 ₁ /TxD ₁	P9 ₁ /TxD ₁	P9 ₁ /TxD ₁	P9 ₁ /TxD ₁	P9 ₁ /TxD ₁	P9 ₁ /TxD ₁	P9 ₁ /TxD ₁
14	16	P9 ₂ /RxD ₀	P9 ₂ /RxD ₀	P9 ₂ /RxD ₀	P9 ₂ /RxD ₀	P9 ₂ /RxD ₀	P9 ₂ /RxD ₀	P9 ₂ /RxD ₀
15	17	P9 ₃ /RxD ₁	P9 ₃ /RxD ₁	P9 ₃ /RxD ₁	P9 ₃ /RxD ₁	P9 ₃ /RxD ₁	P9 ₃ /RxD ₁	P9 ₃ /RxD ₁
16	18	P9 ₄ /IRQ ₄ / SCK ₀	P9 ₄ /IRQ ₄ / SCK ₀	P9 ₄ /IRQ ₄ / SCK ₀	P9 ₄ /IRQ ₄ / SCK ₀	P9 ₄ /IRQ ₄ / SCK ₀	P9 ₄ /IRQ ₄ / SCK ₀	P9₄/ IRQ ₄/ SCK₀

Pin No.		Pin name						
PRQP 0100KA-A								
PTQP 0100KA-A	PRQP 0100JE-B	Mode 1	Mode 2	Mode 3	Mode 4	Mode 5	Mode 6	Mode 7
17	19	P9 _s /IRQ _s / SCK ₁	P9¸/ĪRQ¸/ SCK,	P9₅/ĪRQ₅/ SCK₁	P9₅/ĪRQ₅/ SCK₁	P9₅/ĪRQ₅/ SCK₁	P9¸/ĪRQ¸/ SCK₁	P9¸/ĪRQ¸/ SCK₁
18	20	P4 ₀ /D ₀ *1	P4 ₀ /D ₀ *2	P4 ₀ /D ₀ *1	P4 ₀ /D ₀ *2	P4 ₀ /D ₀ *1	P4 ₀	P4 ₀
19	21	P4 ₁ /D ₁ *1	P4 ₁ /D ₁ *2	P4 ₁ /D ₁ *1	P4 ₁ /D ₁ *2	P4 ₁ /D ₁ *1	P4 ₁	P4,
20	22	P4 ₂ /D ₂ *1	P4 ₂ /D ₂ *2	P4 ₂ /D ₂ *1	P4 ₂ /D ₂ *2	P4 ₂ /D ₂ *1	P4 ₂	P4 ₂
21	23	P4 ₃ /D ₃ *1	P4 ₃ /D ₃ *2	P4 ₃ /D ₃ *1	P4 ₃ /D ₃ *2	P4 ₃ /D ₃ *1	P4 ₃	P4 ₃
22	24	V _{ss}	V _{ss}	V _{ss}	V _{ss}	V _{ss}	V _{ss}	V _{ss}
23	25	P4 ₄ /D ₄ *1	P4 ₄ /D ₄ *2	P4 ₄ /D ₄ *1	P4 ₄ /D ₄ *2	P4 ₄ /D ₄ *1	P4 ₄	P4 ₄
24	26	P4 ₅ /D ₅ *1	P4 ₅ /D ₅ *2	P4 ₅ /D ₅ *1	P4 ₅ /D ₅ *2	P4 ₅ /D ₅ *1	P4 ₅	P4 ₅
25	27	P4 ₆ /D ₆ *1	P4 ₆ /D ₆ *2	P4 ₆ /D ₆ *1	P4 ₆ /D ₆ *2	P4 ₆ /D ₆ *1	P4 ₆	P4 ₆
26	28	P4 ₇ /D ₇ *1	P4 ₇ /D ₇ *2	P4 ₇ /D ₇ *1	P4 ₇ /D ₇ *2	P4 ₇ /D ₇ *1	P4,	P4,
27	29	D ₈	D _s	D ₈	D ₈	D ₈	P3 ₀	P3 ₀
28	30	D ₉	D ₉	D ₉	D ₉	D ₉	P3,	P3,
29	31	D ₁₀	D ₁₀	D ₁₀	D ₁₀	D ₁₀	P3 ₂	P3 ₂
30	32	D ₁₁	D ₁₁	D ₁₁	D ₁₁	D ₁₁	P3 ₃	P3 ₃
31	33	D ₁₂	D ₁₂	D ₁₂	D ₁₂	D ₁₂	P3 ₄	P3 ₄
32	34	D ₁₃	D ₁₃	D ₁₃	D ₁₃	D ₁₃	P3 ₅	P3₅
33	35	D ₁₄	D ₁₄	D ₁₄	D ₁₄	D ₁₄	P3 ₆	P3 ₆
34	36	D ₁₅	D ₁₅	D ₁₅	D ₁₅	D ₁₅	P3,	P3,
35	37	V _{cc}	V _{cc}	V _{cc}	V _{cc}	V _{cc}	V _{cc}	V _{cc}
36	38	A_{0}	A _o	A _o	A _o	P1 ₀ /A ₀	P1₀	P1 _o
37	39	A,	A ₁	A,	A,	P1,/A,	P1,	P1,
38	40	A ₂	A ₂	A ₂	A ₂	P1 ₂ /A ₂	P1 ₂	P1 ₂
39	41	$A_{_3}$	$A_{_3}$	$A_{_3}$	$A_{_3}$	P1 ₃ /A ₃	P1 ₃	P1 ₃
40	42	A_4	A_4	A_4	A_4	P1 ₄ /A ₄	P1 ₄	P1 ₄
41	43	A ₅	A _s	A ₅	A ₅	P1 _s /A _s	P1 ₅	P1 ₅
42	44	A ₆	A ₆	A ₆	A ₆	P1 _e /A _e	P1 ₆	P1 ₆
43	45	A,	A ₇	A,	A,	P1,/A,	P1,	P1,
44	46	V _{ss}	V _{ss}	V _{ss}	V _{ss}	V _{ss}	V _{ss}	V _{ss}
45	47	A ₈	A ₈	A ₈	A ₈	P2 ₀ /A ₈	P2 ₀	P2 ₀
46	48	A ₉	A ₉	A _q	A ₉	P2,/A,	P2,	P2,

Pin No.		Pin name						
PRQP 0100KA-A								
PTQP 0100KA-A	PRQP 0100JE-B	Mode 1	Mode 2	Mode 3	Mode 4	Mode 5	Mode 6	Mode 7
47	49	A ₁₀	A ₁₀	A ₁₀	A ₁₀	P2 ₂ /A ₁₀	P2 ₂	P2 ₂
48	50	A ₁₁	A ₁₁	A ₁₁	A ₁₁	P2 ₃ /A ₁₁	P2 ₃	P2 ₃
49	51	A ₁₂	A ₁₂	A ₁₂	A ₁₂	P2,/A ₁₂	P2 ₄	P2 ₄
50	52	A ₁₃	A ₁₃	A ₁₃	A ₁₃	P2 ₅ /A ₁₃	P2 ₅	P2 ₅
51	53	A ₁₄	A ₁₄	A ₁₄	A ₁₄	P2 ₆ /A ₁₄	P2 ₆	P2 ₆
52	54	A ₁₅	A ₁₅	A ₁₅	A ₁₅	P2/A ₁₅	P2,	P2,
53	55	A ₁₆	A ₁₆	A ₁₆	A ₁₆	P5 ₀ /A ₁₆	P5₀	P5₀
54	56	A ₁₇	A ₁₇	A ₁₇	A ₁₇	P5 ₁ /A ₁₇	P5 ₁	P5 ₁
55	57	A ₁₈	A ₁₈	A ₁₈	A ₁₈	P5 ₂ /A ₁₈	P5 ₂	P5 ₂
56	58	A ₁₉	A ₁₉	A ₁₉	A ₁₉	P5 ₃ /A ₁₉	P5 ₃	P5 ₃
57	59	V _{ss}	V _{ss}	V _{ss}				
58	60	P6 ₀ /WAIT	P6 ₀ /WAIT	P6 ₀ /WAIT	P6₀/WAIT	P6 ₀ /WAIT	P6₀	P6₀
59	61	P6 ₁ /BREQ	P6,/BREQ	P6 ₁ /BREQ	P6₁/BREQ	P6 ₁ /BREQ	P6,	P6,
60	62	P6 ₂ /BACK	P6 ₂	P6 ₂				
61	63	ф	ф	ф	ф	P6 ₇ /φ	P6,/ф	P6 ₋ /φ
62	64	STBY	STBY	STBY	STBY	STBY	STBY	STBY
63	65	RES	RES	RES	RES	RES	RES	RES
64	66	NMI	NMI	NMI	NMI	NMI	NMI	NMI
65	67	V _{ss}	V _{ss}	V _{ss}				
66	68	EXTAL	EXTAL	EXTAL	EXTAL	EXTAL	EXTAL	EXTAL
67	69	XTAL	XTAL	XTAL	XTAL	XTAL	XTAL	XTAL
68	70	V _{cc}	V _{cc}	V _{cc}				
69	71	ĀS	ĀS	ĀS	ĀS	ĀS	P6 ₃	P6 ₃
70	72	RD	RD	RD	RD	RD	P6 ₄	P6 ₄
71	73	HWR	HWR	HWR	HWR	HWR	P6 ₅	P6 ₅
72	74	LWR	LWR	LWR	LWR	LWR	P6 ₆	P6 ₆
73	75	MD₀	MD₀	MD₀	MD₀	MD₀	MD _o	MD _o
74	76	MD ₁	MD ₁	MD ₁				
75	77	MD ₂	MD ₂	MD ₂				
76	78	AV _{cc}	AV _{cc}	AV _{cc}				



Pin No.		Pin name		Pin name										
PRQP 0100KA-A														
PTQP 0100KA-A	PRQP 0100JE-B	Mode 1	Mode 2	Mode 3	Mode 4	Mode 5	Mode 6	Mode 7						
77	79	V_{REF}	V_{REF}	V_{REF}	V_{REF}	V_{REF}	V_{REF}	V_{REF}						
78	80	P7 ₀ /AN ₀	P7 ₀ /AN ₀	P7 ₀ /AN ₀	P7 ₀ /AN ₀	P7 ₀ /AN ₀	P7 ₀ /AN ₀	P7 ₀ /AN ₀						
79	81	P7 ₁ /AN ₁	P7,/AN,	P7,/AN,	P7,/AN,	P7,/AN,	P7 ₁ /AN ₁	P7,/AN,						
80	82	P7 ₂ /AN ₂	P7 ₂ /AN ₂	P7 ₂ /AN ₂	P7 ₂ /AN ₂	P7 ₂ /AN ₂	P7 ₂ /AN ₂	P7 ₂ /AN ₂						
81	83	P7 ₃ /AN ₃	P7 ₃ /AN ₃	P7 ₃ /AN ₃	P7 ₃ /AN ₃	P7 ₃ /AN ₃	P7 ₃ /AN ₃	P7 ₃ /AN ₃						
82	84	P7 ₄ /AN ₄	P7 ₄ /AN ₄	P7 ₄ /AN ₄	P7 ₄ /AN ₄	P7 ₄ /AN ₄	P7 ₄ /AN ₄	P7 ₄ /AN ₄						
83	85	P7 ₅ /AN ₅	P7 ₅ /AN ₅	P7 ₅ /AN ₅	P7 ₅ /AN ₅	P7 ₅ /AN ₅	P7 ₂ /AN ₅	P7 _s /AN _s						
84	86	P7/AN/DA	P7/AN/DA	P7/AN/DA	P7/AN/DA	P7/AN/DA	P7/AN/DA	P7 /AN /DA						
85	87	P7/AN/DA	P7/AN/DA	P7_/AN_/DA	P7/AN/DA	P7_/AN_/DA	P7/AN/DA	P7 ₋ /AN ₋ /DA						
86	88	AV _{ss}	AV _{ss}	AV _{ss}	AV _{ss}	AV _{ss}	AV _{ss}	AV _{ss}						
87	89	P8,/ĪRQ,/ RFSH	P8,/ĪRQ,/ RFSH	P8,/ĪRQ,/ RFSH	P8,/IRQ,/ RFSH	P8,/ĪRQ,/ RFSH	P8 ₀ /IRQ ₀	P8 ₀ /IRQ ₀						
88	90	P8 ₁ /IRQ ₁ /CS ₃	P8 ₁ /ĪRQ ₁ /CS ₃	P8 ₁ /IRQ ₁ /CS ₃	P8,/IRQ,/CS ₃	P8 ₁ /ĪRQ ₁ /CS ₃	P8,/IRQ	P8,/IRQ,						
89	91	P8 ₂ /IRQ ₂ /CS ₂	P8 ₂ /ĪRQ ₂ /CS ₂	P8 ₂ /ĪRQ ₂ /CS ₂	P8 ₂ /IRQ ₂ /CS ₂	P8 ₂ /ĪRQ ₂ /CS ₂	P8 ₂ /IRQ ₂	P8 ₂ /IRQ ₂						
90	92	P8 ₃ /IRQ ₃ / CS ₁ /ADTRG	P8,/IRQ,/ CS,/ADTRG	P8,/IRQ,/ CS,/ADTRG	P8 ₃ /IRQ ₃ / CS ₁ /ADTRG	P8 ₃ /IRQ ₃ / CS ₁ /ADTRG	P8 ₃ /IRQ ₃ / ADTRG	P8 ₃ /IRQ ₃ / ADTRG						
91	93	P8 ₄ /CS ₀	P8 ₄ /CS ₀	P8₄/ CS ₀	P8 ₄ /CS ₀	P8 ₄ /CS ₀	P8 ₄	P8 ₄						
92	94	V _{ss}	V _{ss}	V _{ss}	V _{ss}	V _{ss}	V _{ss}	V _{ss}						
93	95	PA,/TP,/ TCLKA/ TEND ₀	PA,/TP,/ TCLKA/ TEND ₀	PA,/TP,/ TCLKA/ TEND ₀	PA,/TP,/ TCLKA/ TEND ₀	PA,/TP,/ TCLKA/ TEND ₀	PA,/TP,/ TCLKA/ TEND,	PA,/TP,/ TCLKA/ TEND ₀						
94	96	PA,/TP,/ TCLKB/ TEND,	PA,/TP,/ TCLKB/ TEND,	PA,/TP, /TCLKB/ TEND,	PA,/TP,/ TCLKB/ TEND,	PA,/TP,/ TCLKB/ TEND,	PA,/TP,/ TCLKB/ TEND,	PA,/TP,/ TCLKB/ TEND,						
95	97	PA ₂ /TP ₂ / TIOCA ₀ / TCLKC	PA_/TP_/ TIOCA_/ TCLKC	PA ₂ /TP ₂ / TIOCA ₃ / TCLKC	PA ₂ /TP ₂ / TIOCA ₃ / TCLKC	PA ₂ /TP ₂ / TIOCA ₃ / TCLKC	PA ₂ /TP ₂ / TIOCA ₀ / TCLKC	PA ₂ /TP ₂ / TIOCA ₀ / TCLKC						
96	98	PA ₃ /TP ₃ / TIOCB ₀ / TCLKD	PA,/TP,/ TIOCB,/ TCLKD	PA,/TP,/ TIOCB,/ TCLKD	PA,/TP,/ TIOCB,/ TCLKD	PA,/TP,/ TIOCB,/ TCLKD	PA ₃ /TP ₃ / TIOCB ₀ / TCLKD	PA¸/TP¸/ TIOCB¸/ TCLKD						
97	99	PA ₄ /TP ₄ / TIOCA ₁	PA ₄ /TP ₄ / TIOCA ₁	PA ₄ /TP ₄ / TIOCA ₁ /A ₂₃	PA ₄ /TP ₄ / TIOCA ₁ /A ₂₃	PA ₄ /TP ₄ / TIOCA ₁ /A ₂₃	PA ₄ /TP ₄ / TIOCA ₁	PA ₄ /TP ₄ / TIOCA ₁						
98	100	PA _s /TP _s / TIOCB ₁	PA _s /TP _s / TIOCB ₁	PA ₅ /TP ₅ / TIOCB ₁ /A ₂₂	PA ₅ /TP ₅ / TIOCB ₁ /A ₂₂	PA ₅ /TP ₅ / TIOCB ₁ /A ₂₂	PA ₅ /TP ₅ / TIOCB ₁	PA _s /TP _s / TIOCB ₁						

Pin No.		Pin name						
PRQP 0100KA-A								
PTQP 0100KA-A	PRQP 0100JE-B	Mode 1	Mode 2	Mode 3	Mode 4	Mode 5	Mode 6	Mode 7
99	1	PA ₆ /TP ₆ / TIOCA ₂	PA ₆ /TP ₆ / TIOCA ₂	PA ₆ /TP ₆ / TIOCA ₂ /A ₂₁	PA ₆ /TP ₆ / TIOCA ₂ /A ₂₁	PA ₆ /TP ₆ / TIOCA ₂ /A ₂₁	PA ₆ /TP ₆ / TIOCA ₂	PA ₆ /TP ₆ / TIOCA ₂
100	2	PA/TP/ TIOCB	PA ₇ /TP ₇ / TIOCB	A ₂₀	A ₂₀	PA ₇ /TP ₇ / TIOCB ₂ /A ₂₂	PA ₇ /TP ₇ / TIOCB ₂	PA,/TP,/ TIOCB

Notes: 1. In modes 1, 3, 5 the P4₀ to P4₇ functions of pins P4₀/D₀ to P4₇/D₇ are selected after a reset, but they can be changed by software.

- 2. In modes 2 and 4 the D_0 to D_7 functions of pins $P4_0/D_0$ to $P4_7/D_7$ are selected after a reset, but they can be changed by software.
- 3. Functions as $\overline{\text{RESO}}$ in the mask ROM versions, and as FWE in the flash memory and flash memory R versions.

1.4 Notes on Flash Memory R Version Model

There are two models with on-chip flash memory in the H8/3067 Group: the flash memory version (HD64F3067) and the flash memory R version (HD64F3067R). Points to be noted when using the flash memory R version are given below.

1.4.1 Pin Arrangement

The flash memory R version has the same pin arrangement as the flash memory version and mask ROM versions.

1.4.2 Differences in Flash Memory R Version

Table 1.5 shows the differences between the flash memory version, flash memory R version, and mask ROM versions.

Table 1.5 Differences between Flash Memory Version, Flash Memory R Version, and Mask ROM Versions

	Flash Memory Version	Flash N	_	R	Mask ROM Versions				
Item	HD64F3067	HD64F3067R			HD6433	067 H	D643306	6 HD6	433065
ROM	128 kB flash memory				128 kB mask RC	•	6 kB ask ROM	64 k I mas	B k ROM
Address output functions	Compatible with previous H8/300H Series	H8/300I	H Series	s) or a	ddress up	odate r	ompatible node 2 for details	•	revious
ADRCR register (H'FEE01E)	— Corresponding	7	6 —	5 —	4 —	3 —	2	1 —	0 ADRCTL
(III ELOIL)	address consists of reserved bits	See the	section	on the	e bus con	troller	for the bit	t functi	on.

Section 2 CPU

2.1 Overview

The H8/300H CPU is a high-speed central processing unit with an internal 32-bit architecture that is upward-compatible with the H8/300 CPU. The H8/300H CPU has sixteen 16-bit general registers, can address a 16-Mbyte linear address space, and is ideal for realtime control.

2.1.1 **Features**

The H8/300H CPU has the following features.

- Upward compatibility with H8/300 CPU Can execute H8/300 Series object programs
- General-register architecture Sixteen 16-bit general registers (also usable as sixteen 8-bit registers or eight 32-bit registers)
- Sixty-two basic instructions
 - 8/16/32-bit arithmetic and logic instructions
 - Multiply and divide instructions
 - Powerful bit-manipulation instructions
- Eight addressing modes
 - Register direct [Rn]
 - Register indirect [@ERn]
 - Register indirect with displacement [@(d:16, ERn) or @(d:24, ERn)]
 - Register indirect with post-increment or pre-decrement [@ERn+ or @-ERn]
 - Absolute address [@aa:8, @aa:16, or @aa:24]
 - Immediate [#xx:8, #xx:16, or #xx:32]
 - Program-counter relative [@(d:8, PC) or @(d:16, PC)]
 - Memory indirect [@@aa:8]
- 16-Mbyte linear address space

- High-speed operation
- All frequently-used instructions execute in two to four states

Maximum clock frequency: 20 MHz
8/16/32-bit register-register add/subtract: 100 ns
8 × 8-bit register-register multiply: 700 ns
16 ÷ 8-bit register-register divide: 700 ns

- 16 × 16-bit register-register multiply: 1.1 μs 32 ÷ 16-bit register-register divide: 1.1 μs
- Two CPU operating modes
 - Normal mode
 - Advanced mode
- Low-power mode

Transition to power-down state by SLEEP instruction

2.1.2 Differences from H8/300 CPU

In comparison to the H8/300 CPU, the H8/300H has the following enhancements.

- More general registers
 - Eight 16-bit registers have been added.
- Expanded address space
 - Advanced mode supports a maximum 16-Mbyte address space.
 - Normal mode supports the same 64-kbyte address space as the H8/300 CPU.
- Enhanced addressing

The addressing modes have been enhanced to make effective use of the 16-Mbyte address space.

- Enhanced instructions
 - Data transfer, arithmetic, and logic instructions can operate on 32-bit data.
 - Signed multiply/divide instructions and other instructions have been added.



2.2 **CPU Operating Modes**

The H8/300H CPU has two operating modes: normal and advanced. Normal mode supports a maximum 64-kbyte address space. Advanced mode supports up to 16 Mbytes.

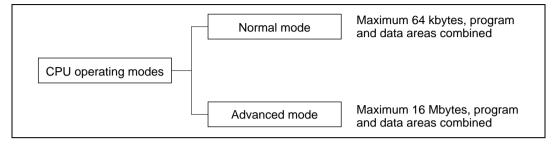


Figure 2.1 CPU Operating Modes

2.3 Address Space

Figure 2.2 shows a simple memory map for the H8/3067 Group. The H8/300H CPU can address a linear address space with a maximum size of 64 kbytes in normal mode, and 16 Mbytes in advanced mode. For further details see section 3.6, Memory Map in Each Operating Mode.

The 1-Mbyte operating modes use 20-bit addressing. The upper 4 bits of effective addresses are ignored.

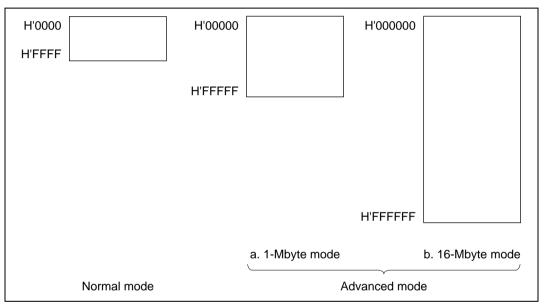


Figure 2.2 Memory Map

2.4 Register Configuration

2.4.1 Overview

The H8/300H CPU has the internal registers shown in figure 2.3. There are two types of registers: general registers and control registers.

15			0	7		0	7 0
ER0	Е	0			R0H		R0L
ER1	E	1			R1H		R1L
ER2	E	2			R2H		R2L
ER3	E	3			R3H		R3L
ER4	E	4			R4H		R4L
ER5	E	5			R5H		R5L
ER6	E	6			R6H		R6L
ER7	E	7	(S	P)	R7H		R7L
							7 6 5 4 3 2 1 0
Logond					(CCR	7 6 5 4 3 2 1 0 I UI H U N Z V C
	pointer				(CCR	
SP: Stack PC: Progr	pointer am counter				(CCR	
SP: Stack PC: Progr CCR: Condi	am counter ition code reg	ister			(CCR	
SP: Stack PC: Progr CCR: Condi I: Interre	am counter ition code regupt mask bit				(CCR	
SP: Stack PC: Progr CCR: Condi I: Interr UI: User	am counter ition code regupt mask bit bit or interrup				(CCR	
SP: Stack PC: Progr CCR: Condi I: Interri UI: User H: Half-c	am counter ition code regupt mask bit bit or interruptarry flag				(CCR	
SP: Stack PC: Progr CCR: Cond I: Interr UI: User H: Half-c U: User	am counter ition code regupt mask bit bit or interruptarry flag				(CCR	
PC: Progr CCR: Condi I: Interru UI: User H: Half-c U: User N: Nega Z: Zero f	am counter ition code regupt mask bit bit or interruptarry flag bit tive flag				(CCR	
SP: Stack PC: Progr CCR: Condi I: Interr UI: User H: Half-c U: User N: Nega Z: Zero f	am counter ition code regupt mask bit bit or interruptarry flag bit tive flag low flag low flag				(CCR	

Figure 2.3 CPU Registers

2.4.2 General Registers

The H8/300H CPU has eight 32-bit general registers. These general registers are all functionally alike and can be used without distinction between data registers and address registers. When a general register is used as a data register, it can be accessed as a 32-bit, 16-bit, or 8-bit register. When the general registers are used as 32-bit registers or as address registers, they are designated by the letters ER (ER0 to ER7).

The ER registers divide into 16-bit general registers designated by the letters E (E0 to E7) and R (R0 to R7). These registers are functionally equivalent, providing a maximum sixteen 16-bit registers. The E registers (E0 to E7) are also referred to as extended registers.

The R registers divide into 8-bit general registers designated by the letters RH (R0H to R7H) and RL (R0L to R7L). These registers are functionally equivalent, providing a maximum sixteen 8-bit registers.

Figure 2.4 illustrates the usage of the general registers. The usage of each register can be selected independently.

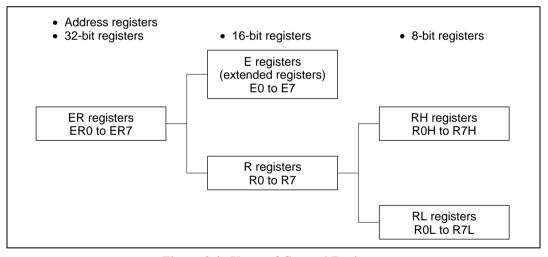


Figure 2.4 Usage of General Registers

General register ER7 has the function of stack pointer (SP) in addition to its general-register function, and is used implicitly in exception handling and subroutine calls. Figure 2.5 shows the stack.

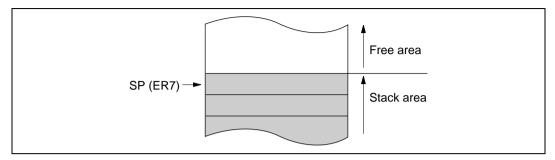


Figure 2.5 Stack

2.4.3 Control Registers

The control registers are the 24-bit program counter (PC) and the 8-bit condition code register (CCR).

Program Counter (PC): This 24-bit counter indicates the address of the next instruction the CPU will execute. The length of all CPU instructions is 2 bytes (one word), so the least significant PC bit is ignored. When an instruction is fetched, the least significant PC bit is regarded as 0.

Condition Code Register (CCR): This 8-bit register contains internal CPU status information, including the interrupt mask bit (I) and half-carry (H), negative (N), zero (Z), overflow (V), and carry (C) flags.

Bit 7—Interrupt Mask Bit (I): Masks interrupts other than NMI when set to 1. NMI is accepted regardless of the I bit setting. The I bit is set to 1 at the start of an exception-handling sequence.

Bit 6—User Bit or Interrupt Mask Bit (UI): Can be written and read by software using the LDC, STC, ANDC, ORC, and XORC instructions. This bit can also be used as an interrupt mask bit. For details see section 5, Interrupt Controller.

Bit 5—Half-Carry Flag (H): When the ADD.B, ADDX.B, SUB.B, SUBX.B, CMP.B, or NEG.B instruction is executed, this flag is set to 1 if there is a carry or borrow at bit 3, and cleared to 0 otherwise. When the ADD.W, SUB.W, CMP.W, or NEG.W instruction is executed, the H flag is set to 1 if there is a carry or borrow at bit 11, and cleared to 0 otherwise. When the ADD.L, SUB.L, CMP.L, or NEG.L instruction is executed, the H flag is set to 1 if there is a carry or borrow at bit 27, and cleared to 0 otherwise.

Bit 4—User Bit (U): Can be written and read by software using the LDC, STC, ANDC, ORC, and XORC instructions.

Bit 3—Negative Flag (N): Stores the value of the most significant bit of data, regarded as the sign bit.

Bit 2—Zero Flag (Z): Set to 1 to indicate zero data, and cleared to 0 to indicate non-zero data.

Bit 1—Overflow Flag (V): Set to 1 when an arithmetic overflow occurs, and cleared to 0 at other times.

Bit 0—Carry Flag (C): Set to 1 when a carry is generated by execution of an operation, and cleared to 0 otherwise. Used by:

- Add instructions, to indicate a carry
- Subtract instructions, to indicate a borrow
- Shift and rotate instructions

The carry flag is also used as a bit accumulator by bit manipulation instructions.

Some instructions leave flag bits unchanged. Operations can be performed on CCR by the LDC, STC, ANDC, ORC, and XORC instructions. The N, Z, V, and C flags are used by conditional branch (Bcc) instructions.

For the action of each instruction on the flag bits, see appendix A.1, Instruction List. For the I and UI bits, see section 5, Interrupt Controller.

2.4.4 Initial CPU Register Values

In reset exception handling, PC is initialized to a value loaded from the vector table, and the I bit in CCR is set to 1. The other CCR bits and the general registers are not initialized. In particular, the initial value of the stack pointer (ER7) is also undefined. The stack pointer (ER7) must therefore be initialized by an MOV.L instruction executed immediately after a reset.



2.5 Data Formats

The H8/300H CPU can process 1-bit, 4-bit (BCD), 8-bit (byte), 16-bit (word), and 32-bit (longword) data. Bit-manipulation instructions operate on 1-bit data by accessing bit n (n = 0, 1, 2, ..., 7) of byte operand data. The DAA and DAS decimal-adjust instructions treat byte data as two digits of 4-bit BCD data.

2.5.1 General Register Data Formats

Figures 2.6 and 2.7 show the data formats in general registers.

Data Type	General Register	Data Format
1-bit data	RnH	7 0 7 6 5 4 3 2 1 0 Don't care
1-bit data	RnL	7 0 Don't care 7 6 5 4 3 2 1 0
4-bit BCD data	RnH	7 4 3 0 Upper digit Lower digit Don't care
4-bit BCD data	RnL	7 4 3 0 Don't care Upper digit Lower digit
Byte data	RnH	7 0 Don't care MSB LSB
Byte data	RnL	7 0 Don't care MSB LSB
Legend RnH: General regis RnL: General regis		

Figure 2.6 General Register Data Formats

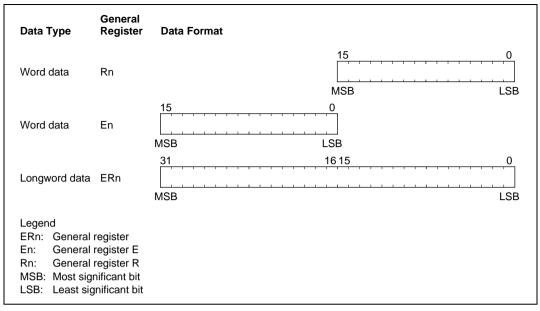


Figure 2.7 General Register Data Formats

2.5.2 Memory Data Formats

Figure 2.8 shows the data formats on memory. The H8/300H CPU can access word data and longword data on memory, but word or longword data must begin at an even address. If an attempt is made to access word or longword data at an odd address, no address error occurs but the least significant bit of the address is regarded as 0, so the access starts at the preceding address. This also applies to instruction fetches.



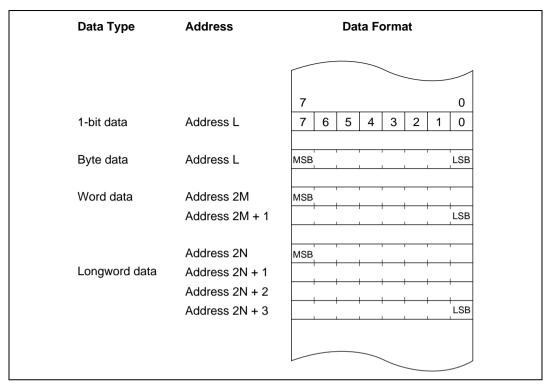


Figure 2.8 Memory Data Formats

When ER7 (SP) is used as an address register to access the stack, the operand size should be word size or longword size.

2.6 Instruction Set

2.6.1 Instruction Set Overview

The H8/300H CPU has 62 types of instructions, which are classified in table 2.1.

Table 2.1 Instruction Classification

Function	Instruction	Types
Data transfer	MOV, PUSH*1, POP*1, MOVTPE*2, MOVFPE*2	3
Arithmetic operations	ADD, SUB, ADDX, SUBX, INC, DEC, ADDS, SUBS, DAA, DAS, MULXU, MULXS, DIVXU, DIVXS, CMP, NEG, EXTS, EXTU	18
Logic operations	AND, OR, XOR, NOT	4
Shift operations	SHAL, SHAR, SHLL, SHLR, ROTL, ROTR, ROTXL, ROTXR	8
Bit manipulation	BSET, BCLR, BNOT, BTST, BAND, BIAND, BOR, BIOR, BXOR, BIXOR, BLD, BILD, BST, BIST	14
Branch	Bcc*3, JMP, BSR, JSR, RTS	5
System control	TRAPA, RTE, SLEEP, LDC, STC, ANDC, ORC, XORC, NOP	9
Block data transfer	EEPMOV	1

Total 62 types

Notes: 1. POP.W Rn is identical to MOV.W @SP+, Rn.

PUSH.W Rn is identical to MOV.W Rn, @-SP.

POP.L ERn is identical to MOV.L @SP+, Rn.

PUSH.L ERn is identical to MOV.L Rn, @-SP.

- 2. Not available in the H8/3067 Group.
- 3. Bcc is a generic branching instruction.



2.6.2 Instructions and Addressing Modes

Table 2.2 indicates the instructions available in the H8/300H CPU.

Table 2.2 Instructions and Addressing Modes

							Addre	ssing M	odes					
Function	Instruction	#xx	Rn	@ERn	@ (d:16, ERn)	@ (d:24, ERn)	@ERn+/ @-ERn	@ aa:8	@ aa:16	@ aa:24	@ (d:8, PC)	@ (d:16, PC)	@ @ aa:8	_
Data	MOV	BWL	BWL	BWL	BWL	BWL	BWL	В	BWL	BWL	_	_	_	_
transfer	POP, PUSH	_	_	_	_	_	_	_	_	_	_	_	_	WL
	MOVFPE,	_	_	_	_	_	_	_	_	_	_	_	_	_
	MOVTPE													
Arithmetic	ADD, CMP	BWL	BWL	_	_	_	_	_	_	_	_	_	_	_
operations	SUB	WL	BWL	_	_	_	_	_	_	_	_	_	_	_
	ADDX, SUBX	В	В	_	_	_	_	_	_	_	_	_	_	_
	ADDS, SUBS	_	L	_	_	_	_	_	_	_	_	_	_	_
	INC, DEC	_	BWL	_	_	_	_	_	_	_	_	_	_	_
	DAA, DAS	_	В	_	_	_	_	_	_	_	_	_	_	_
	MULXU,	_	BW	_	_	_	_	_	_	_	_	_	_	_
	MULXS,													
	DIVXU,													
	DIVXS													
	NEG	_	BWL	_	_	_	_	_	_	_	_	_	_	_
	EXTU, EXTS	_	WL	_	_	_	_	_	_	_	_	_	_	_
Logic	AND, OR, XOR	_	BWL	_	_	_	_	_	_	_	_	_	_	_
operations	NOT	_	BWL	_	_	_	_	_	_	_	_	_	_	_
Shift instruc	tions	_	BWL	_	_	_	_	_	_	_	_	_	_	_
Bit manipula	ation	_	В	В	_	_	_	В	_	_	_	_	_	_
Branch	Bcc, BSR	_	_	_	_	_	_	_	_	_	_	_	_	_
	JMP, JSR	_	_	0	_	_	_	_	_	_	0	0	_	_
	RTS	_	_	_	_	_	_	_	_	0	_	_	0	_
System	TRAPA	_	_	_	_	_	_	_	_	_	_	_	_	0
control	RTE	_	_	_	_	_	_	_	_	_	_	_	_	0
	SLEEP	_	_	_	_	_	_	_	_	_	_	_	_	0
	LDC	В	В	W	W	W	W	_	W	W	_	_	_	0
	STC	_	В	W	W	W	W	_	W	W	_	_	_	_
	ANDC, ORC, XORC	В	_	_	_	_	_	_	_	_	_	_	_	_
	NOP	_	_	_	_	_	_	_	_	_	_	_	_	0
Block data t	ransfer	_	_	_	_	_	_	_	_	_	_	_	_	BW

2.6.3 Tables of Instructions Classified by Function

Tables 2.3 to 2.10 summarize the instructions in each functional category. The operation notation used in these tables is defined next.

Operation Notation

Rd	General register (destination)*
Rs	General register (source)*
Rn	General register*
ERn	General register (32-bit register or address register)
(EAd)	Destination operand
(EAs)	Source operand
CCR	Condition code register
N	N (negative) flag of CCR
Z	Z (zero) flag of CCR
V	V (overflow) flag of CCR
С	C (carry) flag of CCR
PC	Program counter
SP	Stack pointer
#IMM	Immediate data
disp	Displacement
+	Addition
_	Subtraction
×	Multiplication
÷	Division
٨	AND logical
V	OR logical
\oplus	Exclusive OR logical
\rightarrow	Move
7	NOT (logical complement)
:3/:8/:16/:24	3-, 8-, 16-, or 24-bit length

Note: * General registers include 8-bit registers (R0H to R7H, R0L to R7L), 16-bit registers (R0 to R7, E0 to E7), and 32-bit data or address registers (ER0 to ER7).



Table 2.3 Data Transfer Instructions

Instruction	Size*	Function
MOV	B/W/L	$(EAs) \rightarrow Rd, Rs \rightarrow (EAd)$
		Moves data between two general registers or between a general register and memory, or moves immediate data to a general register.
MOVFPE	В	(EAs) o Rd
		Cannot be used in this LSI.
MOVTPE	В	$Rs \rightarrow (EAs)$
		Cannot be used in this LSI.
POP	W/L	$@SP+ \rightarrow Rn$
		Pops a general register from the stack. POP.W Rn is identical to MOV.W @SP+, Rn. Similarly, POP.L ERn is identical to MOV.L @SP+, ERn.
PUSH	W/L	$Rn \rightarrow @-SP$
		Pushes a general register onto the stack. PUSH.W Rn is identical to MOV.W Rn, @-SP. Similarly, PUSH.L ERn is identical to MOV.L ERn, @-SP.

B: ByteW: WordL: Longword

Arithmetic Operation Instructions Table 2.4

14010 201		
Instruction	Size*	Function
ADD,SUB	B/W/L	$Rd \pm Rs \to Rd, Rd \pm \#IMM \to Rd$
		Performs addition or subtraction on data in two general registers, or on immediate data and data in a general register. (Immediate byte data cannot be subtracted from data in a general register. Use the SUBX or ADD instruction.)
ADDX,	В	$Rd \pm Rs \pm C \to Rd, Rd \pm \#IMM \pm C \to Rd$
SUBX		Performs addition or subtraction with carry or borrow on data in two general registers, or on immediate data and data in a general register.
INC,	B/W/L	$Rd \pm 1 \rightarrow Rd, Rd \pm 2 \rightarrow Rd$
DEC		Increments or decrements a general register by 1 or 2. (Byte operands can be incremented or decremented by 1 only.)
ADDS,	L	$Rd \pm 1 \rightarrow Rd, Rd \pm 2 \rightarrow Rd, Rd \pm 4 \rightarrow Rd$
SUBS		Adds or subtracts the value 1, 2, or 4 to or from data in a 32-bit register.
DAA,	В	Rd decimal adjust → Rd
DAS		Decimal-adjusts an addition or subtraction result in a general register by referring to CCR to produce 4-bit BCD data.
MULXU	B/W	$Rd \times Rs \rightarrow Rd$
		Performs unsigned multiplication on data in two general registers: either 8 bits \times 8 bits \rightarrow 16 bits or 16 bits \times 16 bits \rightarrow 32 bits.
MULXS	B/W	$Rd \times Rs \rightarrow Rd$
		Performs signed multiplication on data in two general registers: either 8 bits \times 8 bits \rightarrow 16 bits or 16 bits \times 16 bits \rightarrow 32 bits.
DIVXU	B/W	$Rd \div Rs \rightarrow Rd$
		Performs unsigned division on data in two general registers: either 16 bits \div 8 bits \rightarrow 8-bit quotient and 8-bit remainder or 32 bits \div 16 bits \rightarrow 16-bit quotient and 16-bit remainder
DIVXS	B/W	$Rd \div Rs \rightarrow Rd$
		Performs signed division on data in two general registers: either 16 bits \div 8 bits \rightarrow 8-bit quotient and 8-bit remainder, or 32 bits \div 16 bits \rightarrow 16-bit quotient and 16-bit remainder
CMP	B/W/L	Rd – Rs, Rd – #IMM
		Compares data in a general register with data in another general register or with immediate data, and sets CCR according to the result.
NEG	B/W/L	$0 - Rd \rightarrow Rd$
		Takes the two's complement (arithmetic complement) of data in a general register.

Instruction	Size*	Function
EXTS W/L R		Rd (sign extension) $\rightarrow Rd$
		Extends byte data in the lower 8 bits of a 16-bit register to word data, or extends word data in the lower 16 bits of a 32-bit register to longword data, by extending the sign bit.
EXTU	W/L	Rd (zero extension) $\rightarrow Rd$
		Extends byte data in the lower 8 bits of a 16-bit register to word data, or extends word data in the lower 16 bits of a 32-bit register to longword data, by padding with zeros.

B: ByteW: WordL: Longword

Table 2.5 Logic Operation Instructions

Instruction	Size*	Function
AND	B/W/L	$Rd \wedge Rs \rightarrow Rd, Rd \wedge \#IMM \rightarrow Rd$
		Performs a logical AND operation on a general register and another general register or immediate data.
OR	B/W/L	$Rd \lor Rs \rightarrow Rd, Rd \lor \#IMM \rightarrow Rd$
		Performs a logical OR operation on a general register and another general register or immediate data.
XOR	B/W/L	$Rd \oplus Rs \rightarrow Rd, Rd \oplus \#IMM \rightarrow Rd$
		Performs a logical exclusive OR operation on a general register and another general register or immediate data.
NOT	B/W/L	$\neg Rd \rightarrow Rd$
		Takes the one's complement (logical complement) of general register contents.

Note: * Size refers to the operand size.

B: Byte W: Word

Longword

Table 2.6 Shift Instructions

Instruction	Size*	Function
SHAL,	B/W/L	$Rd (shift) \rightarrow Rd$
SHAR		Performs an arithmetic shift on general register contents.
SHLL,	B/W/L	$Rd (shift) \rightarrow Rd$
SHLR		Performs a logical shift on general register contents.
ROTL,	B/W/L	Rd (rotate) $\rightarrow Rd$
ROTR		Rotates general register contents.
ROTXL,	B/W/L	Rd (rotate) $\rightarrow Rd$
ROTXR		Rotates general register contents, including the carry bit.

B: Byte W: Word L: Longword



Table 2.7 Bit Manipulation Instructions

Instruction	Size*	Function
BSET	В	$1 \rightarrow (\text{sbit-No.} > \text{of } \text{EAd})$
		Sets a specified bit in a general register or memory operand to 1. The bit number is specified by 3-bit immediate data or the lower 3 bits of a general register.
BCLR	В	$0 \rightarrow (\text{sbit-No.} > \text{of } \text{sEAd})$
		Clears a specified bit in a general register or memory operand to 0. The bit number is specified by 3-bit immediate data or the lower 3 bits of a general register.
BNOT	В	\neg (<bit-no.> of <ead>) \rightarrow (<bit-no.> of <ead>)</ead></bit-no.></ead></bit-no.>
		Inverts a specified bit in a general register or memory operand. The bit number is specified by 3-bit immediate data or the lower 3 bits of a general register.
BTST	В	\neg (<bit-no.> of <ead>) \rightarrow Z</ead></bit-no.>
		Tests a specified bit in a general register or memory operand and sets or clears the Z flag accordingly. The bit number is specified by 3-bit immediate data or the lower 3 bits of a general register.
BAND	В	$C \land (\text{sbit-No.}) \rightarrow C$
		ANDs the carry flag with a specified bit in a general register or memory operand and stores the result in the carry flag.
BIAND	В	$C \wedge [\neg (\text{sbit-No.}) \text{ of } (\text{EAd})] \rightarrow C$
		ANDs the carry flag with the inverse of a specified bit in a general register or memory operand and stores the result in the carry flag.
		The bit number is specified by 3-bit immediate data.
BOR	В	$C \lor (sbit\text{-No.}>\ of\) \to C$
		ORs the carry flag with a specified bit in a general register or memory operand and stores the result in the carry flag.
BIOR	В	$C \vee [\neg \ (sbit\text{-No.}>\ of\)] \to C$
		ORs the carry flag with the inverse of a specified bit in a general register or memory operand and stores the result in the carry flag.
		The bit number is specified by 3-bit immediate data.
BXOR	В	$C \oplus (\text{sbit-No.> of } \in \text{EAd>}) \rightarrow C$
		Exclusive-ORs the carry flag with a specified bit in a general register or memory operand and stores the result in the carry flag.

Instruction	Size*	Function
BIXOR	В	$C \oplus [\neg (of)] \rightarrow C$
		Exclusive-ORs the carry flag with the inverse of a specified bit in a general register or memory operand and stores the result in the carry flag.
		The bit number is specified by 3-bit immediate data.
BLD	В	$($ bit-No.> of <ead>$) \rightarrow C$</ead>
		Transfers a specified bit in a general register or memory operand to the carry flag.
BILD	В	\neg (<bit-no.> of <ead>) \rightarrow C</ead></bit-no.>
		Transfers the inverse of a specified bit in a general register or memory operand to the carry flag.
		The bit number is specified by 3-bit immediate data.
BST	В	$C \rightarrow (\text{sbit-No.} \text{s of } \text{})$
		Transfers the carry flag value to a specified bit in a general register or memory operand.
BIST	В	$C \rightarrow \neg$ (<bit-no.> of <ead>)</ead></bit-no.>
		Transfers the inverse of the carry flag value to a specified bit in a general register or memory operand.
		The bit number is specified by 3-bit immediate data.

B: Byte



Table 2.8 Branching Instructions

BGT

BLE

Diun	ming motifications			
Size	Function			
_	Branches to a specified address if address specified condition is met. The branching conditions are listed below.			
	Mnemonic	Description	Condition	
	BRA (BT)	Always (true)	Always	
	BRN (BF)	Never (false)	Never	
	BHI	High	C ∨ Z = 0	
	BLS	Low or same	C ∨ Z = 1	
	Bcc (BHS)	Carry clear (high or same)	C = 0	
	BCS (BLO)	Carry set (low)	C = 1	
	BNE	Not equal	Z = 0	
	BEQ	Equal	Z = 1	
	BVC	Overflow clear	V = 0	
	BVS	Overflow set	V = 1	
	BPL	Plus	N = 0	
	BMI	Minus	N = 1	
	BGE	Greater or equal	$N \oplus V = 0$	
	BLT	Less than	N ⊕ V = 1	
		Branches to a specific branching conditions of the branchi	Branches to a specified address if address specified branching conditions are listed below. Mnemonic Description BRA (BT) Always (true) BRN (BF) Never (false) BHI High BLS Low or same Bcc (BHS) Carry clear (high or same) BCS (BLO) Carry set (low) BNE Not equal BEQ Equal BVC Overflow clear BVS Overflow set BPL Plus BMI Minus BGE Greater or equal	

JMP	_	Branches unconditionally to a specified address
BSR	_	Branches to a subroutine at a specified address
JSR	_	Branches to a subroutine at a specified address
RTS	_	Returns from a subroutine

Greater than

Less or equal

 $Z \vee (N \oplus V) = 0$

 $Z \vee (N \oplus V) = 1$

System Control Instructions Table 2.9

Instruction	Size*	Function
TRAPA	_	Starts trap-instruction exception handling
RTE	_	Returns from an exception-handling routine
SLEEP	_	Causes a transition to the power-down state
LDC	B/W	$(EAs) \rightarrow CCR$
		Moves the source operand contents to the condition code register. The condition code register size is one byte, but in transfer from memory, data is read by word access.
STC	B/W	CCR → (EAd)
		Transfers the CCR contents to a destination location. The condition code register size is one byte, but in transfer to memory, data is written by word access.
ANDC	В	$CCR \land \#IMM \rightarrow CCR$
		Logically ANDs the condition code register with immediate data.
ORC	В	$CCR \lor \#IMM \to CCR$
		Logically ORs the condition code register with immediate data.
XORC	В	$CCR \oplus \#IMM \to CCR$
		Logically exclusive-ORs the condition code register with immediate data.
NOP	_	$PC + 2 \rightarrow PC$
		Only increments the program counter.

B: Byte W: Word



Table 2.10 Block Transfer Instruction

Instruction	Size	Function
EEPMOV.B	_	if R4L \neq 0 then repeat @ER5+ \rightarrow @ER6+, R4L – 1 \rightarrow R4L until R4L = 0 else next;
EEPMOV.W	_	if R4 \neq 0 then repeat @ER5+ \rightarrow @ER6+, R4 – 1 \rightarrow R4 until R4 = 0 else next;
		Block transfer instruction. This instruction transfers the number of data bytes specified by R4L or R4, starting from the address indicated by ER5, to the location starting at the address indicated by ER6. At the end of the transfer, the next instruction is executed.

2.6.4 Basic Instruction Formats

The H8/300H instructions consist of 2-byte (1-word) units. An instruction consists of an operation field (OP field), a register field (r field), an effective address extension (EA field), and a condition field (cc).

Operation Field: Indicates the function of the instruction, the addressing mode, and the operation to be carried out on the operand. The operation field always includes the first 4 bits of the instruction. Some instructions have two operation fields.

Register Field: Specifies a general register. Address registers are specified by 3 bits, data registers by 3 bits or 4 bits. Some instructions have two register fields. Some have no register field.

Effective Address Extension: Eight, 16, or 32 bits specifying immediate data, an absolute address, or a displacement. A 24-bit address or displacement is treated as 32-bit data in which the first 8 bits are 0 (H'00).

Condition Field: Specifies the branching condition of Bcc instructions.

Figure 2.9 shows examples of instruction formats.

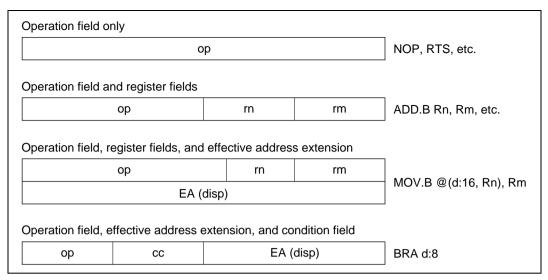


Figure 2.9 Instruction Formats

2.6.5 **Notes on Use of Bit Manipulation Instructions**

The BSET, BCLR, BNOT, BST, and BIST instructions read a byte of data, modify a bit in the byte, then write the byte back. Care is required when these instructions are used to access registers with write-only bits, or to access ports.

Step		Description
1	Read	Read one data byte at the specified address
2	Modify	Modify one bit in the data byte
3	Write	Write the modified data byte back to the specified address

Example 1: BCLR is executed to clear bit 0 in the port 4 data direction register (P4DDR) under the following conditions.

P4₇, P4₆: Input pins $P4_5 - P4_0$: Output pins

The intended purpose of this BCLR instruction is to switch P4₀ from output to input.

Before Execution of BCLR Instruction

	P4 ₇	P4 ₆	P4 ₅	P4 ₄	P4 ₃	P4 ₂	P4 ₁	P4 ₀
Input/output	Input	Input	Output	Output	Output	Output	Output	Output
DDR	0	0	1	1	1	1	1	1

Execution of BCLR Instruction

BCLR #0, @P4DDR ;Clear bit 0 in data direction register

After Execution of BCLR Instruction

	P4 ₇	P4 ₆	P4 ₅	P4 ₄	P4 ₃	P4 ₂	P4 ₁	P4 ₀
Input/output	Output	Input						
DDR	1	1	1	1	1	1	1	0

Explanation: To execute the BCLR instruction, the CPU begins by reading P4DDR. Since P4DDR is a write-only register, it is read as H'FF, even though its true value is H'3F.

Next the CPU clears bit 0 of the read data, changing the value to H'FE.

Finally, the CPU writes this value (H'FE) back to P4DDR to complete the BCLR instruction.

As a result, P4₀DDR is cleared to 0, making P4₀ an input pin. In addition, P4₇DDR and P4₆DDR are set to 1, making P4₇ and P4₆ output pins.

The BCLR instruction can be used to clear flags in the on-chip registers to 0. In an interrupt-handling routine, for example, if it is known that the flag is set to 1, it is not necessary to read the flag ahead of time.

2.7 Addressing Modes and Effective Address Calculation

2.7.1 Addressing Modes

The H8/300H CPU supports the eight addressing modes listed in table 2.11. Each instruction uses a subset of these addressing modes. Arithmetic and logic instructions can use the register direct and immediate modes. Data transfer instructions can use all addressing modes except program-counter relative and memory indirect. Bit manipulation instructions use register direct, register indirect, or absolute (@aa:8) addressing mode to specify an operand, and register direct (BSET, BCLR, BNOT, and BTST instructions) or immediate (3-bit) addressing mode to specify a bit number in the operand.

Table 2.11 Addressing Modes

No.	Addressing Mode	Symbol
1	Register direct	Rn
2	Register indirect	@ERn
3	Register indirect with displacement	@(d:16, ERn)/@(d:24, ERn)
4	Register indirect with post-increment Register indirect with pre-decrement	@ERn+ @-ERn
5	Absolute address	@aa:8/@aa:16/@aa:24
6	Immediate	#xx:8/#xx:16/#xx:32
7	Program-counter relative	@(d:8, PC)/@(d:16, PC)
8	Memory indirect	@@aa:8

- **1 Register Direct—Rn:** The register field of the instruction code specifies an 8-, 16-, or 32-bit register containing the operand. R0H to R7H and R0L to R7L can be specified as 8-bit registers. R0 to R7 and E0 to E7 can be specified as 16-bit registers. ER0 to ER7 can be specified as 32-bit registers.
- **2 Register Indirect**—@**ERn:** The register field of the instruction code specifies an address register (ERn), the lower 24 bits of which contain the address of the operand.
- 3 Register Indirect with Displacement—@(d:16, ERn) or @(d:24, ERn): A 16-bit or 24-bit displacement contained in the instruction code is added to the contents of an address register (ERn) specified by the register field of the instruction, and the lower 24 bits of the sum specify the address of a memory operand. A 16-bit displacement is sign-extended when added.



4 Register Indirect with Post-Increment or Pre-Decrement—@ERn+ or @-ERn:

- Register indirect with post-increment—@ERn+
 - The register field of the instruction code specifies an address register (ERn) the lower 24 bits of which contain the address of a memory operand. After the operand is accessed, 1, 2, or 4 is added to the address register contents (32 bits) and the sum is stored in the address register. The value added is 1 for byte access, 2 for word access, or 4 for longword access. For word or longword access, the register value should be even.
- Register indirect with pre-decrement—@-ERn The value 1, 2, or 4 is subtracted from an address register (ERn) specified by the register field in the instruction code, and the lower 24 bits of the result become the address of a memory operand. The result is also stored in the address register. The value subtracted is 1 for byte access, 2 for word access, or 4 for longword access. For word or longword access, the resulting register value should be even.
- **5** Absolute Address—@aa:8, @aa:16, or @aa:24: The instruction code contains the absolute address of a memory operand. The absolute address may be 8 bits long (@aa:8), 16 bits long (@aa:16), or 24 bits long (@aa:24). For an 8-bit absolute address, the upper 16 bits are all assumed to be 1 (H'FFFF). For a 16-bit absolute address the upper 8 bits are a sign extension. A 24-bit absolute address can access the entire address space. Table 2.12 indicates the accessible address ranges.

Table 2.12 Absolute Address Access Ranges

Absolute Address	1-Mbyte Modes	16-Mbyte Modes
8 bits (@aa:8)	H'FFF00 to H'FFFFF (1048320 to 1048575)	H'FFFF00 to H'FFFFFF (16776960 to 16777215)
16 bits (@aa:16)	H'00000 to H'07FFF, H'F8000 to H'FFFFF (0 to 32767, 1015808 to 1048575)	H'000000 to H'007FFF, H'FF8000 to H'FFFFFF (0 to 32767, 16744448 to 16777215)
24 bits (@aa:24)	H'00000 to H'FFFFF (0 to 1048575)	H'000000 to H'FFFFFF (0 to 16777215)

6 Immediate—#xx:8, #xx:16, or #xx:32: The instruction code contains 8-bit (#xx:8), 16-bit (#xx:16), or 32-bit (#xx:32) immediate data as an operand.

The instruction codes of the ADDS, SUBS, INC, and DEC instructions contain immediate data implicitly. The instruction codes of some bit manipulation instructions contain 3-bit immediate data specifying a bit number. The TRAPA instruction code contains 2-bit immediate data specifying a vector address.

- 7 **Program-Counter Relative**—@(**d:8, PC**) or @(**d:16, PC**): This mode is used in the Bcc and BSR instructions. An 8-bit or 16-bit displacement contained in the instruction code is sign-extended to 24 bits and added to the 24-bit PC contents to generate a 24-bit branch address. The PC value to which the displacement is added is the address of the first byte of the next instruction, so the possible branching range is –126 to +128 bytes (–63 to +64 words) or –32766 to +32768 bytes (–16383 to +16384 words) from the branch instruction. The resulting value should be an even number.
- **8 Memory Indirect**—@ @aa:8: This mode can be used by the JMP and JSR instructions. The instruction code contains an 8-bit absolute address specifying a memory operand. This memory operand contains a branch address. The memory operand is accessed by longword access. The first byte of the memory operand is ignored, generating a 24-bit branch address. See figure 2.10. The upper bits of the 8-bit absolute address are assumed to be 0 (H'0000), so the address range is 0 to 255 (H'000000 to H'0000FF). Note that the first part of this range is also the exception vector area. For further details see section 5, Interrupt Controller.

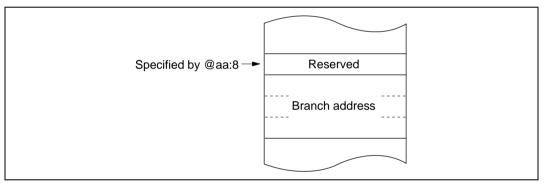


Figure 2.10 Memory-Indirect Branch Address Specification

When a word-size or longword-size memory operand is specified, or when a branch address is specified, if the specified memory address is odd, the least significant bit is regarded as 0. The accessed data or instruction code therefore begins at the preceding address. See section 2.5.2, Memory Data Formats.

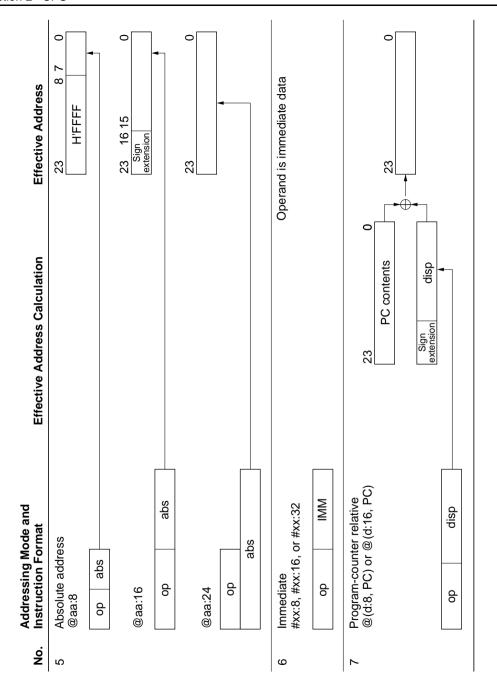
2.7.2 Effective Address Calculation

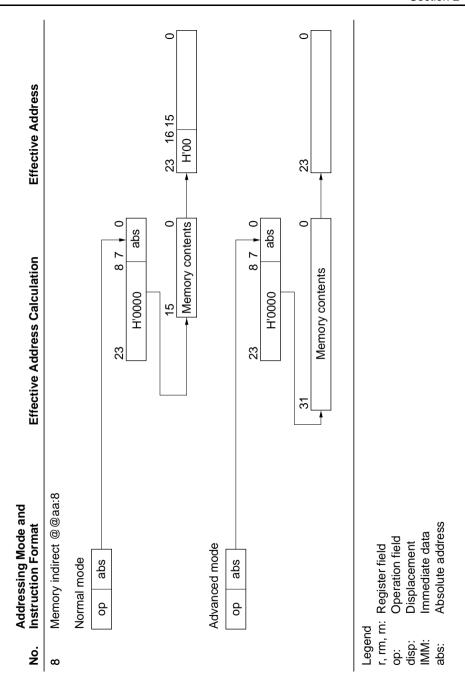
Table 2.13 explains how an effective address is calculated in each addressing mode. In the 1-Mbyte operating modes the upper 4 bits of the calculated address are ignored in order to generate a 20-bit effective address.



Effective Address Operand is general register contents 23 23 23 23 0 0 0 1, 2, or 4 1, 2, or 4 General register contents General register contents General register contents General register contents 2 for a word operand, 4 for a longword operand **Effective Address Calculation** disp 1 for a byte operand, Sign extension 3 3 3 3 Register indirect with post-increment Register indirect with post-increment Register indirect with pre-decrement @ĐERn Register indirect with displacement @(d:16, ERn)/@(d:24, ERn) Register indirect (@ERn) Addressing Mode and Register indirect (Rn) Instruction Format or pre-decrement rn rn @ERn+ do d ф do d ģ N က 4

Table 2.13 Effective Address Calculation





2.8 Processing States

2.8.1 Overview

The H8/300H CPU has five processing states: the program execution state, exception-handling state, power-down state, reset state, and bus-released state. The power-down state includes sleep mode, software standby mode, and hardware standby mode. Figure 2.11 classifies the processing states. Figure 2.13 indicates the state transitions.

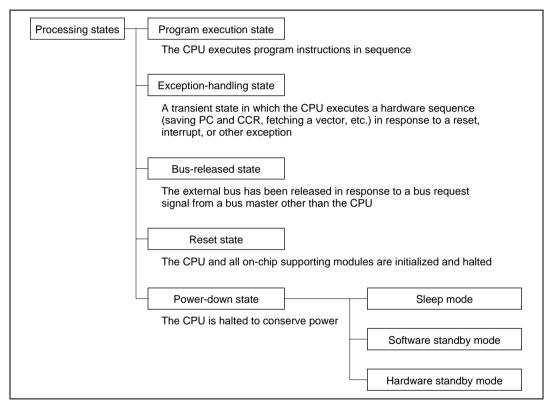


Figure 2.11 Processing States

2.8.2 Program Execution State

In this state the CPU executes program instructions in normal sequence.

2.8.3 Exception-Handling State

The exception-handling state is a transient state that occurs when the CPU alters the normal program flow due to a reset, interrupt, or trap instruction. The CPU fetches a starting address from the exception vector table and branches to that address. In interrupt and trap exception handling the CPU references the stack pointer (ER7) and saves the program counter and condition code register.

Types of Exception Handling and Their Priority: Exception handling is performed for resets, interrupts, and trap instructions. Table 2.14 indicates the types of exception handling and their priority. Trap instruction exceptions are accepted at all times in the program execution state.

Table 2.14 Exception Handling Types and Priority

Priority	Type of Exception	Detection Timing	Start of Exception Handling
High	Reset	Synchronized with clock	Exception handling starts immediately when RES changes from low to high
	Interrupt	End of instruction execution or end of exception handling*	When an interrupt is requested, exception handling starts at the end of the current instruction or current exception-handling sequence
Low	Trap instruction	When TRAPA instruction is executed	Exception handling starts when a trap (TRAPA) instruction is executed

Note: * Interrupts are not detected at the end of the ANDC, ORC, XORC, and LDC instructions, or immediately after reset exception handling.

Figure 2.12 classifies the exception sources. For further details about exception sources, vector numbers, and vector addresses, see section 4, Exception Handling, and section 5, Interrupt Controller.

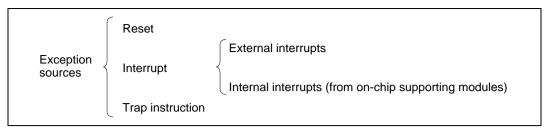


Figure 2.12 Classification of Exception Sources

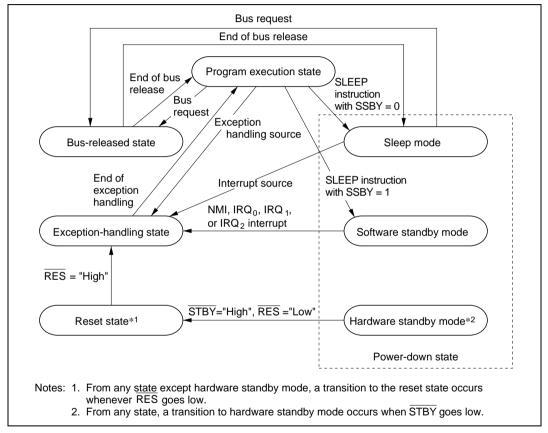


Figure 2.13 State Transitions

2.8.4 Exception-Handling Sequences

Reset Exception Handling: Reset exception handling has the highest priority. The reset state is entered when the \overline{RES} signal goes low. Reset exception handling starts after that, when \overline{RES} changes from low to high. When reset exception handling starts the CPU fetches a start address from the exception vector table and starts program execution from that address. All interrupts, including NMI, are disabled during the reset exception-handling sequence and immediately after it ends.

Interrupt Exception Handling and Trap Instruction Exception Handling: When these exception-handling sequences begin, the CPU references the stack pointer (ER7) and pushes the program counter and condition code register on the stack. Next, if the UE bit in the system control register (SYSCR) is set to 1, the CPU sets the I bit in the condition code register to 1. If the UE bit is cleared to 0, the CPU sets both the I bit and the UI bit in the condition code register to 1. Then the CPU fetches a start address from the exception vector table and execution branches to that address.

Figure 2.14 shows the stack after the exception-handling sequence.

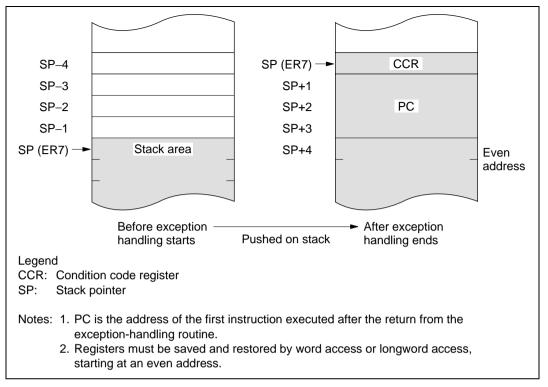


Figure 2.14 Stack Structure after Exception Handling

2.8.5 Bus-Released State

In this state the bus is released to a bus master other than the CPU, in response to a bus request. The bus masters other than the CPU are the DMA controller, the DRAM interface, and an external bus master. While the bus is released, the CPU halts except for internal operations. Interrupt requests are not accepted. For details see section 6.11, Bus Arbiter.

2.8.6 Reset State

When the \overline{RES} input goes low all current processing stops and the CPU enters the reset state. The I bit in the condition code register is set to 1 by a reset. All interrupts are masked in the reset state. Reset exception handling starts when the \overline{RES} signal changes from low to high.

The reset state can also be entered by a watchdog timer overflow. For details see section 12, Watchdog Timer.



2.8.7 Power-Down State

In the power-down state the CPU stops operating to conserve power. There are three modes: sleep mode, software standby mode, and hardware standby mode.

Sleep Mode: A transition to sleep mode is made if the SLEEP instruction is executed while the SSBY bit is cleared to 0 in the system control register (SYSCR). CPU operations stop immediately after execution of the SLEEP instruction, but the contents of CPU registers are retained.

Software Standby Mode: A transition to software standby mode is made if the SLEEP instruction is executed while the SSBY bit is set to 1 in SYSCR. The CPU and clock halt and all on-chip supporting modules stop operating. The on-chip supporting modules are reset, but as long as a specified voltage is supplied the contents of CPU registers and on-chip RAM are retained. The I/O ports also remain in their existing states.

Hardware Standby Mode: A transition to hardware standby mode is made when the STBY input goes low. As in software standby mode, the CPU and all clocks halt and the on-chip supporting modules are reset, but as long as a specified voltage is supplied, on-chip RAM contents are retained

For further information see section 20, Power-Down State.

2.9 Basic Operational Timing

2.9.1 Overview

The H8/300H CPU operates according to the system clock (ϕ). The interval from one rise of the system clock to the next rise is referred to as a "state." A memory cycle or bus cycle consists of two or three states. The CPU uses different methods to access on-chip memory, the on-chip supporting modules, and the external address space. Access to the external address space can be controlled by the bus controller.

2.9.2 On-Chip Memory Access Timing

On-chip memory is accessed in two states. The data bus is 16 bits wide, permitting both byte and word access. Figure 2.15 shows the on-chip memory access cycle. Figure 2.16 indicates the pin states.

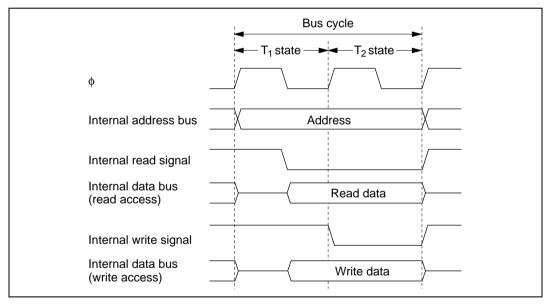


Figure 2.15 On-Chip Memory Access Cycle

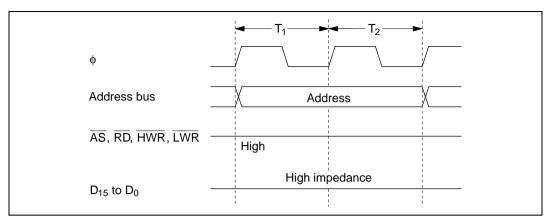


Figure 2.16 Pin States during On-Chip Memory Access

2.9.3 On-Chip Supporting Module Access Timing

The on-chip supporting modules are accessed in three states. The data bus is 8 or 16 bits wide, depending on the internal I/O register being accessed. Figure 2.17 shows the on-chip supporting module access timing. Figure 2.18 indicates the pin states.

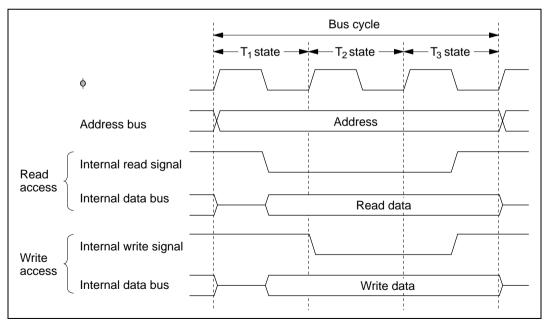


Figure 2.17 Access Cycle for On-Chip Supporting Modules

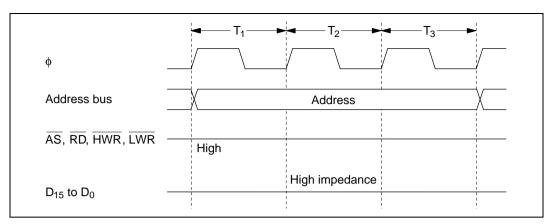


Figure 2.18 Pin States during Access to On-Chip Supporting Modules

2.9.4 Access to External Address Space

The external address space is divided into eight areas (areas 0 to 7). Bus-controller settings determine whether each area is accessed via an 8-bit or 16-bit bus, and whether it is accessed in two or three states. For details see section 6, Bus Controller.

Section 3 MCU Operating Modes

3.1 Overview

3.1.1 Operating Mode Selection

The H8/3067 Group has seven operating modes (modes 1 to 7) that are selected by the mode pins $(MD_2 \text{ to } MD_0)$ as indicated in table 3.1. The input at these pins determines the size of the address space and the initial bus mode.

Table 3.1 Operating Mode Selection

				Description			
Operating	Mode Pins		ins		Initial Bus	On-Chip	On-Chip
Mode	MD ₂	MD₁	MD₀	Address Space	Mode*1	ROM	RAM
_	0	0	0	_	_	_	_
Mode 1	0	0	1	Expanded mode	8 bits	Disabled	Enabled*2
Mode 2	0	1	0	Expanded mode	16 bits	Disabled	Enabled*2
Mode 3	0	1	1	Expanded mode	8 bits	Disabled	Enabled*2
Mode 4	1	0	0	Expanded mode	16 bits	Disabled	Enabled*2
Mode 5	1	0	1	Expanded mode	8 bits	Enabled	Enabled*2
Mode 6	1	1	0	Single-chip normal mode	_	Enabled	Enabled
Mode 7	1	1	1	Single-chip advanced mode	_	Enabled	Enabled

Notes: 1. In modes 1 to 5, an 8-bit or 16-bit data bus can be selected on a per-area basis by settings made in the area bus width control register (ABWCR). For details see section 6. Bus Controller.

2. If the RAME bit in SYSCR is cleared to 0, these addresses become external addresses.

For the address space size there are three choices: 64 kbytes, 1 Mbyte, or 16 Mbytes. The external data bus is either 8 or 16 bits wide depending on ABWCR settings. If 8-bit access is selected for all areas, 8-bit bus mode is used. For details see section 6, Bus Controller.

Modes 1 to 4 are externally expanded modes that enable access to external memory and peripheral devices and disable access to the on-chip ROM. Modes 1 and 2 support a maximum address space of 1 Mbyte. Modes 3 and 4 support a maximum address space of 16 Mbytes.

Section 3 MCU Operating Modes

Mode 5 is an externally expanded mode that enables access to external memory and peripheral devices and also enables access to the on-chip ROM. Mode 5 supports a maximum address space of 16 Mbytes.

Modes 6 and 7 are single-chip modes that operate using the on-chip ROM, RAM, and registers, and makes all I/O ports available. Mode 6 supports a maximum address space of 64 kbytes. Mode 7 supports a maximum address space of 1 Mbyte.

The H8/3067 Group can be used only in modes 1 to 7. The inputs at the mode pins must select one of these seven modes. The inputs at the mode pins must not be changed during operation.

3.1.2 Register Configuration

The H8/3067 Group has a mode control register (MDCR) that indicates the inputs at the mode pins (MD₂ to MD₀), and a system control register (SYSCR). Table 3.2 summarizes these registers.

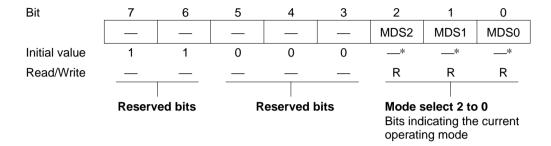
Table 3.2 Registers

Address*	Name	Abbreviation	R/W	Initial Value
H'EE011	Mode control register	MDCR	R	Undetermined
H'EE012	System control register	SYSCR	R/W	H'09

Note: *Lower 20 bits of the address in advanced mode.

3.2 Mode Control Register (MDCR)

MDCR is an 8-bit read-only register that indicates the current operating mode of the H8/3067 Group.



Note: * Determined by pins MD₂ to MD₀.

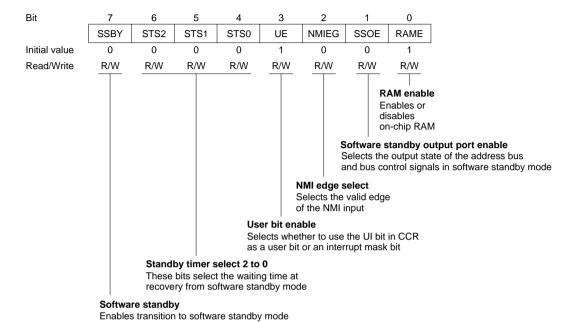
Bits 7 and 6—Reserved: These bits can not be modified and are always read as 1.

Bits 5 to 3—Reserved: These bits can not be modified and are always read as 0.

Bits 2 to 0—Mode Select 2 to 0 (MDS2 to MDS0): These bits indicate the logic levels at pins MD_2 to MD_0 (the current operating mode). MDS2 to MDS0 correspond to MD_2 to MD_0 . MDS2 to MDS0 are read-only bits. The mode pin $(MD_2$ to MD_0) levels are latched into these bits when MDCR is read.

3.3 System Control Register (SYSCR)

SYSCR is an 8-bit register that controls the operation of the H8/3067 Group.



Bit 7—Software Standby (SSBY): Enables transition to software standby mode. (For further information about software standby mode see section 20, Power-Down State.)

When software standby mode is exited by an external interrupt, this bit remains set to 1. To clear this bit, write 0.

Bit 7 SSBY	Description	
0	SLEEP instruction causes transition to sleep mode	(Initial value)
1	SLEEP instruction causes transition to software standby mode	

Bits 6 to 4—Standby Timer Select 2 to 0 (STS2 to STS0): These bits select the length of time the CPU and on-chip supporting modules wait for the internal clock oscillator to settle when software standby mode is exited by an external interrupt.

When using a crystal oscillator, set these bits so that the waiting time will be at least 7 ms at the system clock rate.

For further information about waiting time selection, see section 20.4.3, Selection of Waiting Time for Exit from Software Standby Mode.

Bit 6	Bit 5	Bit 4		
STS2	STS1	STS0	Description	
0	0	0	Waiting time = 8,192 states	(Initial value)
0	0	1	Waiting time = 16,384 states	
0	1	0	Waiting time = 32,768 states	
0	1	1	Waiting time = 65,536 states	
1	0	0	Waiting time = 131,072 states	
1	0	1	Waiting time = 262,144 states	
1	1	0	Waiting time = 1,024 states	
1	1	1	Illegal setting	

Bit 3—User Bit Enable (UE): Selects whether to use the UI bit in the condition code register as a user bit or an interrupt mask bit.

Bit 3 UE	Description	
0	UI bit in CCR is used as an interrupt mask bit	
1	UI bit in CCR is used as a user bit	(Initial value)

Bit 2—NMI Edge Select (NMIEG): Selects the valid edge of the NMI input.

Bit 2		
NMIEG	Description	
0	An interrupt is requested at the falling edge of NMI	(Initial value)
1	An interrupt is requested at the rising edge of NMI	

Bit 1—Software Standby Output Port Enable (SSOE): Specifies whether the address bus and bus control signals (\overline{CS}_0 to \overline{CS}_7 , \overline{AS} , \overline{RD} , \overline{HWR} , \overline{LWR} , \overline{UCAS} , \overline{LCAS} , and \overline{RFSH}) are kept as outputs or fixed high, or placed in the high-impedance state in software standby mode.

Bit 1 SSOE	Description
0	In software standby mode, the address bus and bus control signals are all high-impedance (Initial value)
1	In software standby mode, the address bus retains its output state and bus control signals are fixed high

Bit 0—RAM Enable (RAME): Enables or disables the on-chip RAM. The RAME bit is initialized by the rising edge of the RES signal. It is not initialized in software standby mode.

Bit 0 RAME	Description	
0	On-chip RAM is disabled	
1	On-chip RAM is enabled	(Initial value)

3.4 Operating Mode Descriptions

3.4.1 Mode 1

Ports 1, 2, and 5 function as address pins A_{19} to A_{0} , permitting access to a maximum 1-Mbyte address space. The initial bus mode after a reset is 8 bits, with 8-bit access to all areas. If at least one area is designated for 16-bit access in ABWCR, the bus mode switches to 16 bits.

3.4.2 Mode 2

Ports 1, 2, and 5 function as address pins A_{19} to A_{0} , permitting access to a maximum 1-Mbyte address space. The initial bus mode after a reset is 16 bits, with 16-bit access to all areas. If all areas are designated for 8-bit access in ABWCR, the bus mode switches to 8 bits.

3.4.3 Mode 3

Ports 1, 2, and 5 and part of port A function as address pins A_{23} to A_0 , permitting access to a maximum 16-Mbyte address space. The initial bus mode after a reset is 8 bits, with 8-bit access to all areas. If at least one area is designated for 16-bit access in ABWCR, the bus mode switches to



16 bits. A_{23} to A_{21} are valid when 0 is written in bits 7 to 5 of the bus release control register (BRCR). (In this mode A_{20} is always used for address output.)

3.4.4 Mode 4

Ports 1, 2, and 5 and part of port A function as address pins A_{23} to A_0 , permitting access to a maximum 16-Mbyte address space. The initial bus mode after a reset is 16 bits, with 16-bit access to all areas. If all areas are designated for 8-bit access in ABWCR, the bus mode switches to 8 bits. A_{23} to A_{21} are valid when 0 is written in bits 7 to 5 of BRCR. (In this mode A_{20} is always used for address output.)

3.4.5 Mode 5

Ports 1, 2, and 5 and part of port A can function as address pins A_{23} to A_0 , permitting access to a maximum 16-Mbyte address space, but following a reset they are input ports. To use ports 1, 2, and 5 as an address bus, the corresponding bits in their data direction registers (P1DDR, P2DDR, and P5DDR) must be set to 1. For A_{23} to A_{20} output, write 0 in bits 7 to 4 of BRCR. The initial bus mode after a reset is 8 bits, with 8-bit access to all areas. If at least one area is designated for 16-bit access in ABWCR, the bus mode switches to 16 bits.

3.4.6 Mode 6

This mode operates using the on-chip ROM, RAM, and registers. All I/O ports are available. Mode 6 supports a maximum address space of 64 kbytes.

3.4.7 Mode 7

This mode operates using the on-chip ROM, RAM, and registers. All I/O ports are available. Mode 7 supports a 1-Mbyte address space.

3.5 Pin Functions in Each Operating Mode

The pin functions of ports 1 to 5 and port A vary depending on the operating mode. Table 3.3 indicates their functions in each operating mode.

Table 3.3 Pin Functions in Each Mode

Port	Mode 1	Mode 2	Mode 3	Mode 4	Mode 5	Mode 6	Mode 7
Port 1	A ₇ to A ₀	A ₇ to A ₀	A ₇ to A ₀	A ₇ to A ₀	P1, to P1, *2	P1, to P1,	P1, to P1,
Port 2	A ₁₅ to A ₈	A ₁₅ to A ₈	A ₁₅ to A ₈	A ₁₅ to A ₈	P2, to P2,*2	P2, to P2	P2, to P2
Port 3	D ₁₅ to D ₈	D ₁₅ to D ₈	D ₁₅ to D ₈	D ₁₅ to D ₈	D ₁₅ to D ₈	P3, to P3,	P3, to P3,
Port 4	P4, to P4,*1	D, to D,*1	P4, to P4,*1	D ₇ to D ₀ *1	P4, to P4,*1	P4, to P4 ₀	P4, to P4 ₀
Port 5	A ₁₉ to A ₁₆	A ₁₉ to A ₁₆	A ₁₉ to A ₁₆	A ₁₉ to A ₁₆	P5 ₃ to P5 ₀ *2	P5 ₃ to P5 ₀	P5 ₃ to P5 ₀
Port A	PA, to PA,	PA, to PA,	PA ₆ to PA ₄ , A ₂₀ *3	PA ₆ to PA ₄ , A ₂₀ *3	PA, to PA,*4	PA, to PA,	PA, to PA,

Notes: 1. Initial state. The bus mode can be switched by settings in ABWCR. These pins function as P4, to P4, in 8-bit bus mode, and as D, to D, in 16-bit bus mode.

- 2. Initial state. These pins become address output pins when the corresponding bits in the data direction registers (P1DDR, P2DDR, P5DDR) are set to 1.
- 3. Initial state. A_{20} is always an address output pin. PA_{6} to PA_{4} are switched over to A_{23} to A_{24} output by writing 0 in bits 7 to 5 of BRCR.
- 4. Initial state. PA_7 to PA_4 are switched over to A_{23} to A_{20} output by writing 0 in bits 7 to 4 of BRCR.

3.6 Memory Map in Each Operating Mode

Figure 3.1 to 3.3 show a memory maps of the H8/3067, H8/3066, and H8/3065. The address space is divided into eight areas.

The initial bus mode differs between modes 1 and 2, and also between modes 3 and 4.

The address locations of the on-chip RAM and on-chip registers differ between the 64-kbyte mode (mode 6), the 1-Mbyte modes (modes 1, 2, and 7), and the 16-Mbyte modes (modes 3, 4, and 5). The address range specifiable by the CPU in the 8- and 16-bit absolute addressing modes (@aa:8 and @aa:16) also differs.

3.6.1 Note on Reserved Areas

The H8/3067 Group memory map includes reserved areas to which read/write access is prohibited. Note that normal operation is not guaranteed if the following reserved areas are accessed.

- (1) The reserved area in the internal I/O register space

 The H8/3067 Group internal I/O register space includes a reserved area to which access is prohibited. For details see Appendix B, Internal I/O Registers.
- (2) Other reserved areas
 In mode 5 in the H8/3066 and H8/3065, there is a reserved area in area 0 as shown in figures 3.2 and 3.3.

In modes 1 to 5 in the H8/3065, there is a reserved area in area 7 as shown in figure 3.3.

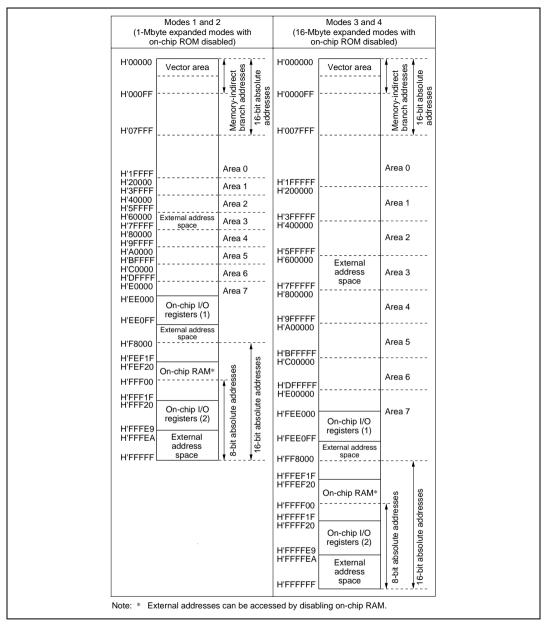
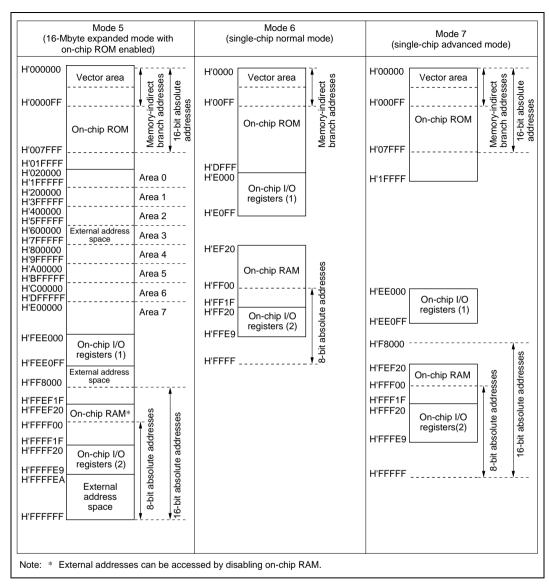


Figure 3.1 H8/3067 Memory Map in Each Operating Mode (1)



Figure~3.1~~H8/3067~Memory~Map~in~Each~Operating~Mode~(2)

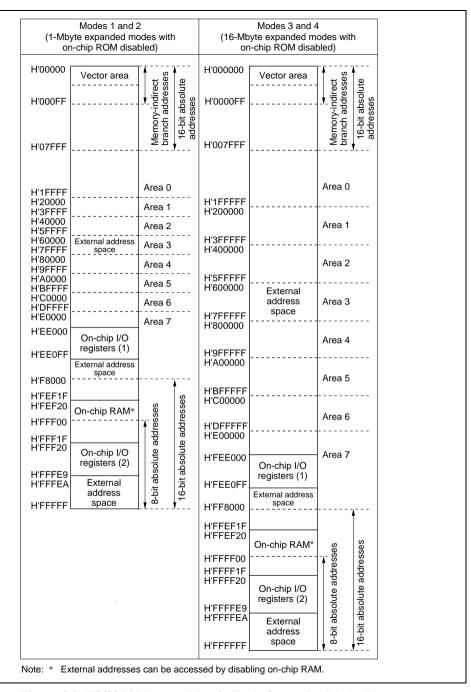


Figure 3.2 H8/3066 Memory Map in Each Operating Mode (1)

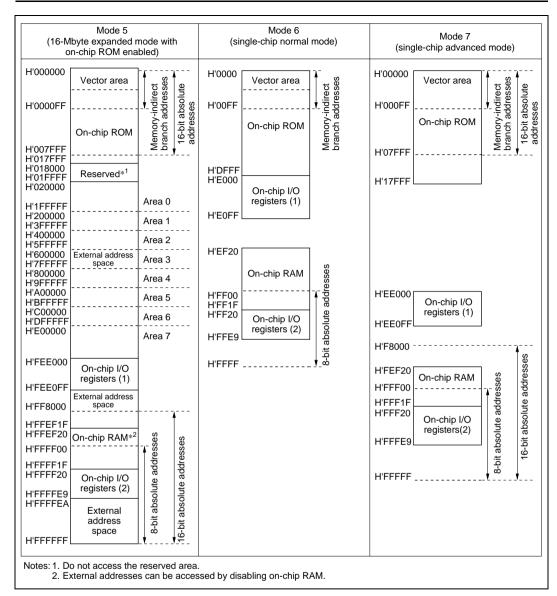


Figure 3.2 H8/3066 Memory Map in Each Operating Mode (2)

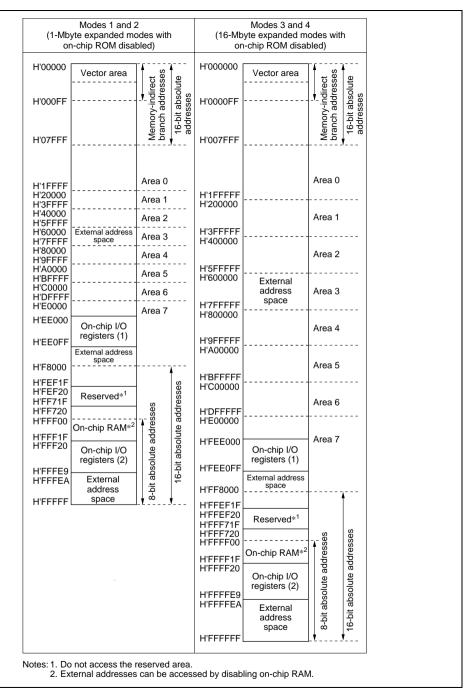


Figure 3.3 H8/3065 Memory Map in Each Operating Mode (1)

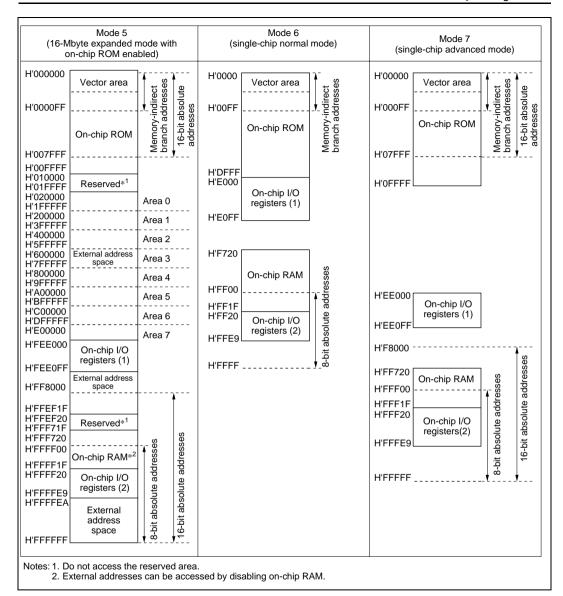


Figure 3.3 H8/3065 Memory Map in Each Operating Mode (2)

Section 4 Exception Handling

4.1 Overview

4.1.1 Exception Handling Types and Priority

As table 4.1 indicates, exception handling may be caused by a reset, trap instruction, or interrupt. Exception handling is prioritized as shown in table 4.1. If two or more exceptions occur simultaneously, they are accepted and processed in priority order. Trap instruction exceptions are accepted at all times in the program execution state.

Table 4.1 Exception Types and Priority

Priority	Exception Type	Start of Exception Handling
High	Reset	Starts immediately after a low-to-high transition at the RES pin
1	Interrupt	Interrupt requests are handled when execution of the current instruction or handling of the current exception is completed
Low	Trap instruction (TRAPA)	Started by execution of a trap instruction (TRAPA)

4.1.2 Exception Handling Operation

Exceptions originate from various sources. Trap instructions and interrupts are handled as follows.

- 1. The program counter (PC) and condition code register (CCR) are pushed onto the stack.
- 2. The CCR interrupt mask bit is set to 1.
- 3. A vector address corresponding to the exception source is generated, and program execution starts from that address.

For a reset exception, steps 2 and 3 above are carried out.

4.1.3 Exception Vector Table

The exception sources are classified as shown in figure 4.1. Different vectors are assigned to different exception sources. Table 4.2 lists the exception sources and their vector addresses.

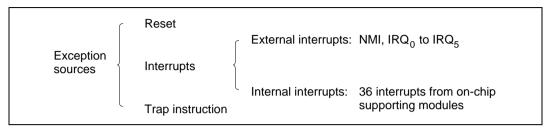


Figure 4.1 Exception Sources



Table 4.2 Exception Vector Table

Vector	Address*
--------	----------

Exception Source	Vector Number	Advanced Mode	Normal Mode
Reset	0	H'0000 to H'0003	H'0000 to H'0001
Reserved for system use	1	H'0004 to H'0007	H'0002 to H'0003
	2	H'0008 to H'000B	H'0004 to H'0005
	3	H'000C to H'000F	H'0006 to H'0007
	4	H'0010 to H'0013	H'0008 to H'0009
	5	H'0014 to H'0017	H'000A to H'000B
	6	H'0018 to H'001B	H'000C to H'000D
External interrupt (NMI)	7	H'001C to H'001F	H'000E to H'000F
Trap instruction (4 sources)	8	H'0020 to H'0023	H'0010 to H'0011
	9	H'0024 to H'0027	H'0012 to H'0013
	10	H'0028 to H'002B	H'0014 to H'0015
	11	H'002C to H'002F	H'0016 to H'0017
External interrupt IRQ _o	12	H'0030 to H'0033	H'0018 to H'0019
External interrupt IRQ,	13	H'0034 to H'0037	H'001A to H'001B
External interrupt IRQ ₂	14	H'0038 to H'003B	H'001C to H'001D
External interrupt IRQ ₃	15	H'003C to H'003F	H'001E to H'001F
External interrupt IRQ ₄	16	H'0040 to H'0043	H'0020 to H'0021
External interrupt IRQ ₅	17	H'0044 to H'0047	H'0022 to H'0023
Reserved for system use	18	H'0048 to H'004B	H'0024 to H'0025
	19	H'004C to H'004F	H'0026 to H'0027
Internal interrupts*2	20	H'0050 to H'0053	H'0028 to H'0029
	to 63	to H'00FC to H'00FF	to H'007E to H'007F

Notes: 1. Lower 16 bits of the address.

2. For the internal interrupt vectors, see section 5.3.3, Interrupt Vector Table.

4.2 Reset

4.2.1 Overview

A reset is the highest-priority exception. When the \overline{RES} pin goes low, all processing halts and the chip enters the reset state. A reset initializes the internal state of the CPU and the registers of the on-chip supporting modules. Reset exception handling begins when the \overline{RES} pin changes from low to high.

The chip can also be reset by overflow of the watchdog timer. For details see section 12, Watchdog Timer.

4.2.2 Reset Sequence

The chip enters the reset state when the \overline{RES} pin goes low.

To ensure that the chip is reset, hold the \overline{RES} pin low for at least 20 ms at power-up. To reset the chip during operation, hold the \overline{RES} pin low for at least 10 system clock (ϕ) cycles. When the flash memory and flash memory R versions are used, the \overline{RES} pin must be held low for at least 20 system clock cycles. See appendix D.2, Pin States at Reset, for the states of the pins in the reset state.

When the \overline{RES} pin goes high after being held low for the necessary time, the chip starts reset exception handling as follows.

- The internal state of the CPU and the registers of the on-chip supporting modules are initialized, and the I bit is set to 1 in CCR.
- The contents of the reset vector address (H'0000 to H'0003 in advanced mode, H'0000 to H'0001 in normal mode) are read, and program execution starts from the address indicated in the vector address.

Figure 4.2 shows the reset sequence in modes 1 and 3. Figure 4.3 shows the reset sequence in modes 2 and 4. Figure 4.4 shows the reset sequence in mode 6.



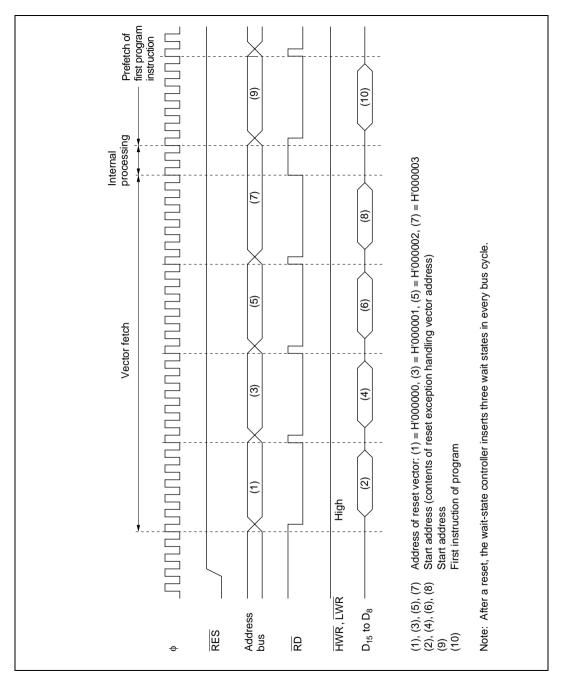


Figure 4.2 Reset Sequence (Modes 1 and 3)

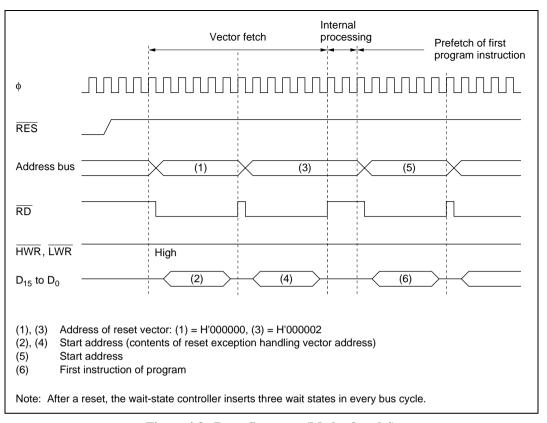


Figure 4.3 Reset Sequence (Modes 2 and 4)

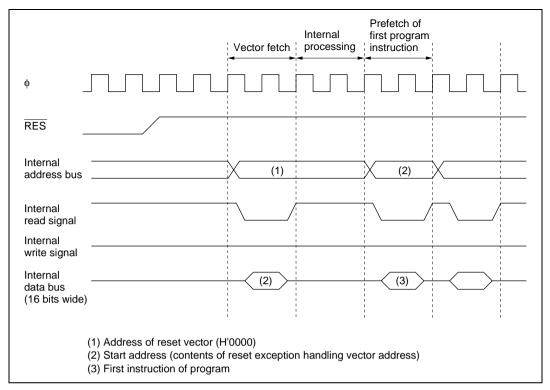


Figure 4.4 Reset Sequence (Mode 6)

4.2.3 Interrupts after Reset

If an interrupt is accepted after a reset but before the stack pointer (SP) is initialized, PC and CCR will not be saved correctly, leading to a program crash. To prevent this, all interrupt requests, including NMI, are disabled immediately after a reset. The first instruction of the program is always executed immediately after the reset state ends. This instruction should initialize the stack pointer (example: MOV.L #xx:32, SP).

4.3 Interrupts

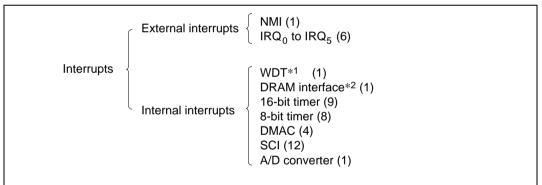
Interrupt exception handling can be requested by seven external sources (NMI, IRQ₀ to IRQ₅), and 36 internal sources in the on-chip supporting modules. Figure 4.5 classifies the interrupt sources and indicates the number of interrupts of each type.

The on-chip supporting modules that can request interrupts are the watchdog timer (WDT), DRAM interface, 16-bit timer, 8-bit timer, DMA controller (DMAC), serial communication interface (SCI), and A/D converter. Each interrupt source has a separate vector address.

NMI is the highest-priority interrupt and is always accepted*. Interrupts are controlled by the interrupt controller. The interrupt controller can assign interrupts other than NMI to two priority levels, and arbitrate between simultaneous interrupts. Interrupt priorities are assigned in interrupt priority registers A and B (IPRA and IPRB) in the interrupt controller.

Note: * In the flash memory and flash memory R versions, NMI input is sometimes disabled. For details see 18.6.4, NMI Input Disable Conditions.

For details on interrupts see section 5, Interrupt Controller.



Notes: Numbers in parentheses are the number of interrupt sources.

- 1. When the watchdog timer is used as an interval timer, it generates an interrupt request at every counter overflow.
- 2. When the DRAM interface is used as an interval timer, it generates an interrupt request at compare match.

Figure 4.5 Interrupt Sources and Number of Interrupts

4.4 Trap Instruction

Trap instruction exception handling starts when a TRAPA instruction is executed. If the UE bit is set to 1 in the system control register (SYSCR), the exception handling sequence sets the I bit to 1 in CCR. If the UE bit is 0, the I and UI bits are both set to 1. The TRAPA instruction fetches a start address from a vector table entry corresponding to a vector number from 0 to 3, which is specified in the instruction code.

4.5 Stack Status after Exception Handling

Figure 4.6 shows the stack after completion of trap instruction exception handling and interrupt exception handling.

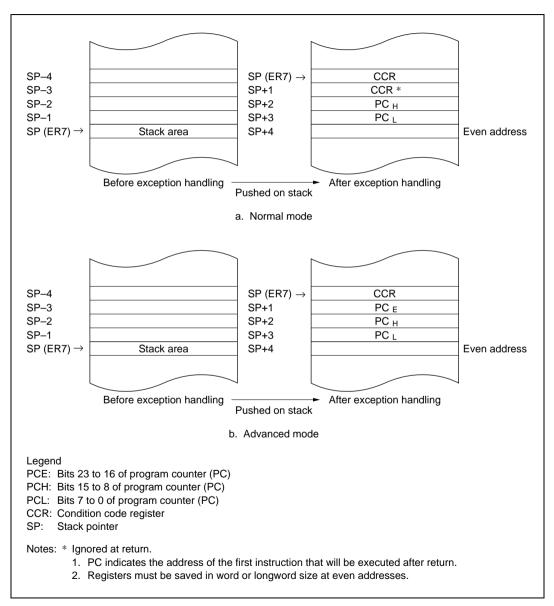


Figure 4.6 Stack after Completion of Exception Handling

4.6 Notes on Stack Usage

When accessing word data or longword data, the H8/3067 Group regards the lowest address bit as 0. The stack should always be accessed by word access or longword access, and the value of the stack pointer (SP, ER7) should always be kept even.

Use the following instructions to save registers:

PUSH.W Rn (or MOV.W Rn, @-SP)

PUSH.L ERn (or MOV.L ERn, @-SP)

Use the following instructions to restore registers:

POP.W Rn (or MOV.W @SP+, Rn)

POP.L ERn (or MOV.L @SP+, ERn)

Setting SP to an odd value may lead to a malfunction. Figure 4.7 shows an example of what happens when the SP value is odd.

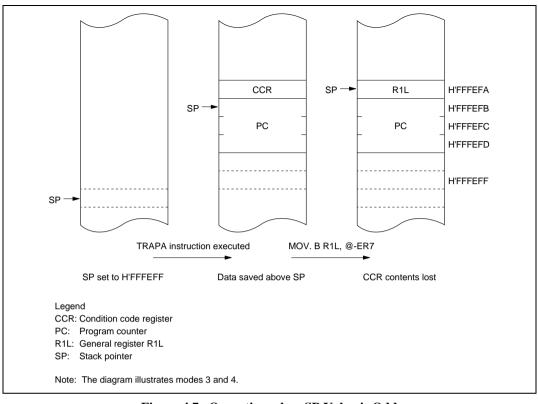


Figure 4.7 Operation when SP Value is Odd

Section 5 Interrupt Controller

5.1 Overview

5.1.1 Features

The interrupt controller has the following features:

- Interrupt priority registers (IPRs) for setting interrupt priorities

 Interrupts other than NMI can be assigned to two priority levels on a module-by-module basis in interrupt priority registers A and B (IPRA and IPRB).
- Three-level masking by the I and UI bits in the CPU condition code register (CCR)
- Seven external interrupt pins
 NMI has the highest priority and is always accepted*; either the rising or falling edge can be selected. For each of IRQ₀ to IRQ₅, sensing of the falling edge or level sensing can be selected independently.

Note: * In the flash memory and flash memory R versions, NMI input is sometimes disabled. For details see 18.6.4, NMI Input Disable Conditions.

5.1.2 Block Diagram

Figure 5.1 shows a block diagram of the interrupt controller.

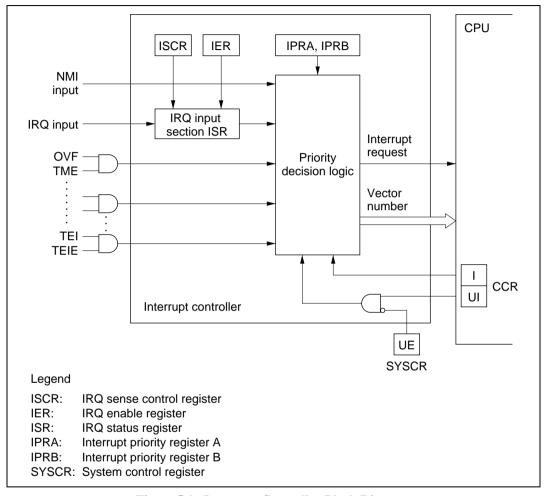


Figure 5.1 Interrupt Controller Block Diagram

5.1.3 Pin Configuration

Table 5.1 lists the interrupt pins.

Table 5.1 Interrupt Pins

Name	Abbreviation	I/O	Function
Nonmaskable interrupt	NMI	Input	Nonmaskable interrupt*, rising edge or falling edge selectable
External interrupt request 5 to 0	$\overline{IRQ}_{\scriptscriptstyle{5}}$ to $\overline{IRQ}_{\scriptscriptstyle{0}}$	Input	Maskable interrupts, falling edge or level sensing selectable

Note: * In the flash memory and flash memory R versions, NMI input is sometimes disabled. For details see 18.6.4, NMI Input Disable Conditions.

5.1.4 Register Configuration

Table 5.2 lists the registers of the interrupt controller.

Table 5.2 Interrupt Controller Registers

Address*1	Name	Abbreviation	R/W	Initial Value
H'EE012	System control register	SYSCR	R/W	H'09
H'EE014	IRQ sense control register	ISCR	R/W	H'00
H'EE015	IRQ enable register	IER	R/W	H'00
H'EE016	IRQ status register	ISR	R/(W)*2	H'00
H'EE018	Interrupt priority register A	IPRA	R/W	H'00
H'EE019	Interrupt priority register B	IPRB	R/W	H'00

Notes: 1. Lower 20 bits of the address in advanced mode.

2. Only 0 can be written, to clear flags.

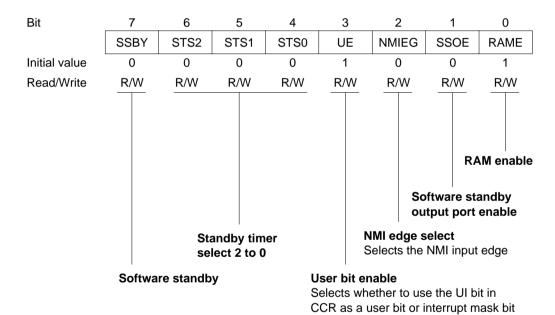
5.2 Register Descriptions

5.2.1 System Control Register (SYSCR)

SYSCR is an 8-bit readable/writable register that controls software standby mode, selects the action of the UI bit in CCR, selects the NMI edge, and enables or disables the on-chip RAM.

Only bits 3 and 2 are described here. For the other bits, see section 3.3, System Control Register (SYSCR).

SYSCR is initialized to H'09 by a reset and in hardware standby mode. It is not initialized in software standby mode.



REJ09B0276-0400



Bit 3—User Bit Enable (UE): Selects whether to use the UI bit in CCR as a user bit or an interrupt mask bit.

Bit 3 UE	Description	
0	UI bit in CCR is used as interrupt mask bit	
1	UI bit in CCR is used as user bit	(Initial value)

Bit 2—NMI Edge Select (NMIEG): Selects the NMI input edge.

Bit 2 NMIEG	Description	
0	Interrupt is requested at falling edge of NMI input	(Initial value)
1	Interrupt is requested at rising edge of NMI input	

5.2.2 Interrupt Priority Registers A and B (IPRA, IPRB)

IPRA and IPRB are 8-bit readable/writable registers that control interrupt priority.

Interrupt Priority Register A (IPRA): IPRA is an 8-bit readable/writable register in which interrupt priority levels can be set.

Bit	7	6	5	4	3	2	1	0
	IPRA7	IPRA6	IPRA5	IPRA4	IPRA3	IPRA2	IPRA1	IPRA0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
T COUGHT VITTE			Priority le	Priority le Selects th interrupt re	Priority le Selects th DRAM interinterrupt interrupt interrupt intervel A4 e priority lequests	Pr Se of in riority leve elects the 6-bit timer equests evel A3 e priority le erface, and requests evel of IRC	Fig. Sp. Oc. o	riority evel A0 elects the riority level f 16-bit timer hannel 2 elects the riority level equests el A1 priority level er channel 1 quests el of interrupt
		Priority le Selects th		evel of IRC	Q ₁ interrup	ot requests	5	

Priority level A7

Selects the priority level of IRQ₀ interrupt requests

IPRA is initialized to $H\sp{0}0$ by a reset and in hardware standby mode.



Bit 7—Priority Level A7 (IPRA7): Selects the priority level of IRQ₀ interrupt requests.

Bit 7 IPRA7	Description	
0	IRQ ₀ interrupt requests have priority level 0 (low priority)	(Initial value)
1	IRQ _o interrupt requests have priority level 1 (high priority)	

Bit 6—Priority Level A6 (IPRA6): Selects the priority level of IRQ₁ interrupt requests.

Bit 6		
IPRA6	Description	
0	IRQ, interrupt requests have priority level 0 (low priority)	(Initial value)
1	IRQ₁ interrupt requests have priority level 1 (high priority)	

Bit 5—Priority Level A5 (IPRA5): Selects the priority level of IRQ_2 and IRQ_3 interrupt requests.

Bit 5 IPRA5	Description	
0	IRQ ₂ and IRQ ₃ interrupt requests have priority level 0 (low priority)	(Initial value)
1	IRQ ₂ and IRQ ₃ interrupt requests have priority level 1 (high priority)	

Bit 4—Priority Level A4 (IPRA4): Selects the priority level of IRQ₄ and IRQ₅ interrupt requests.

Bit 4 IPRA4	Description	
0	IRQ ₄ and IRQ ₅ interrupt requests have priority level 0 (low priority)	(Initial value)
1	IRQ ₄ and IRQ ₅ interrupt requests have priority level 1 (high priority)	

Bit 3—Priority Level A3 (IPRA3): Selects the priority level of WDT, DRAM interface, and A/D converter interrupt requests.

Bit 3 IPRA3	Description	
0	WDT, DRAM interface, and A/D converter interrupt requests have priority level 0 (low priority) (Initial val	ue)
1	WDT, DRAM interface, and A/D converter interrupt requests have priority level 1 (high priority)	

Bit 2—Priority Level A2 (IPRA2): Selects the priority level of 16-bit timer channel 0 interrupt requests.

Bit 2 IPRA2	Description
0	16-bit timer channel 0 interrupt requests have priority level 0 (low priority) (Initial value)
1	16-bit timer channel 0 interrupt requests have priority level 1 (high priority)

Bit 1—Priority Level A1 (IPRA1): Selects the priority level of 16-bit timer channel 1 interrupt requests.

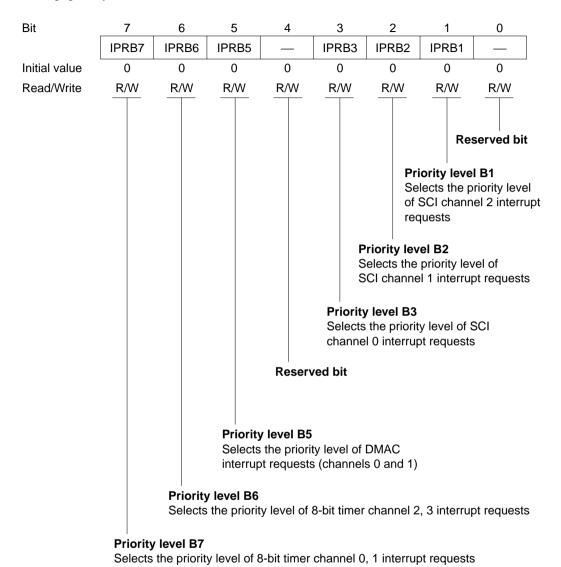
Bit 1 IPRA1	Description
0	16-bit timer channel 1 interrupt requests have priority level 0 (low priority) (Initial value)
1	16-bit timer channel 1 interrupt requests have priority level 1 (high priority)

Bit 0—Priority Level A0 (IPRA0): Selects the priority level of 16-bit timer channel 2 interrupt requests.

Bit 0 IPRA0	Description
0	16-bit timer channel 2 interrupt requests have priority level 0 (low priority) (Initial value)
1	16-bit timer channel 2 interrupt requests have priority level 1 (high priority)



Interrupt Priority Register B (IPRB): IPRB is an 8-bit readable/writable register in which interrupt priority levels can be set.



IPRB is initialized to H'00 by a reset and in hardware standby mode.

Bit 7—Priority Level B7 (IPRB7): Selects the priority level of 8-bit timer channel 0, 1 interrupt requests.

Bit 7	
IPRB7	Description
0	8-bit timer channel 0, 1 interrupt requests have priority level 0 (low priority)(Initial value)
1	8-bit timer channel 0, 1 interrupt requests have priority level 1 (high priority)

Bit 6—Priority Level B6 (IPRB6): Selects the priority level of 8-bit timer channel 2, 3 interrupt requests.

Bit 6 IPRB6	Description
0	8-bit timer channel 2, 3 interrupt requests have priority level 0 (low priority)(Initial value)
1	8-bit timer channel 2, 3 interrupt requests have priority level 1 (high priority)

Bit 5—Priority Level B5 (IPRB5): Selects the priority level of DMAC interrupt requests (channels 0 and 1).

Bit 5 IPRB5	Description	
0	DMAC interrupt requests (channels 0 and 1) have priority level 0 (low priority)	(Initial value)
1	DMAC interrupt requests (channels 0 and 1) have priority level 1 (h	igh priority)

Bit 4—Reserved: This bit can be written and read, but it does not affect interrupt priority.

Bit 3—Priority Level B3 (IPRB3): Selects the priority level of SCI channel 0 interrupt requests.

Bit 3 IPRB3	Description	
0	SCI0 interrupt requests have priority level 0 (low priority)	(Initial value)
1	SCI0 interrupt requests have priority level 1 (high priority)	



Bit 2—Priority Level B2 (IPRB2): Selects the priority level of SCI channel 1 interrupt requests.

Bit 2 IPRB2	Description	
0	SCI1 interrupt requests have priority level 0 (low priority)	(Initial value)
1	SCI1 interrupt requests have priority level 1 (high priority)	

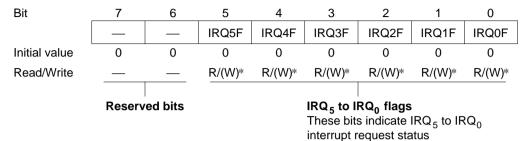
Bit 1—Priority Level B1 (IPRB1): Selects the priority level of SCI channel 2 interrupt requests.

Bit 1 IPRB1	Description	
0	SCI channel 2 interrupt requests have priority level 0 (low priority)	(Initial value)
1	SCI channel 2 interrupt requests have priority level 1 (high priority)	

Bit 0—Reserved: This bit can be written and read, but it does not affect interrupt priority.

5.2.3 IRQ Status Register (ISR)

ISR is an 8-bit readable/writable register that indicates the status of IRQ_0 to IRQ_5 interrupt requests.



Note: * Only 0 can be written, to clear flags.

ISR is initialized to H'00 by a reset and in hardware standby mode.

Bits 7 and 6—Reserved: These bits can not be modified and are always read as 0.

Bits 5 to 0—IRQ₅ to IRQ₀ Flags (IRQ5F to IRQ0F): These bits indicate the status of IRQ₅ to IRQ₀ interrupt requests.

Bits 5 to 0 IRQ5F to IRQ0F Description

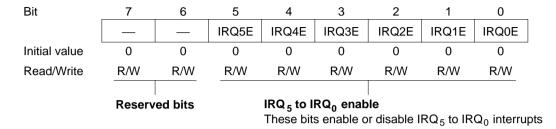
0	[Clearing conditions] 0 is written in IRQnF after reading the IRQnF flag when IRQnF = IRQnSC = 0, IRQn input is high, and interrupt exception handling IRQnSC = 1 and IRQn interrupt exception handling is carried out.	is carried out.
1	[Setting conditions] IRQnSC = 0 and IRQn input is low. IRQnSC = 1 and IRQn input changes from high to low.	

Note: n = 5 to 0

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5.2.4 IRO Enable Register (IER)

IER is an 8-bit readable/writable register that enables or disables IRQ_s to IRQ_n interrupt requests.



IER is initialized to H'00 by a reset and in hardware standby mode.

Bits 7 and 6—Reserved: These bits can be written and read, but they do not enable or disable interrupts.

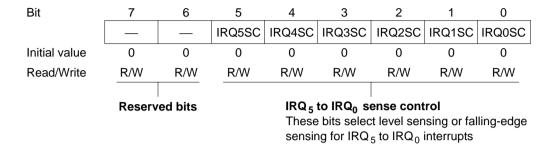
Bits 5 to 0—IRQ, to IRQ, Enable (IRQ5E to IRQ0E): These bits enable or disable IRQ₅ to IRQ₀ interrupts.

Bits 5 to 0 IRQ5E to IRQ0E Description

0	IRQ _s to IRQ _o interrupts are disabled	(Initial value)
1	IRQ₅ to IRQ₀ interrupts are enabled	_

5.2.5 IRQ Sense Control Register (ISCR)

ISCR is an 8-bit readable/writable register that selects level sensing or falling-edge sensing of the inputs at pins \overline{IRQ}_s to \overline{IRQ}_o .



ISCR is initialized to H'00 by a reset and in hardware standby mode.

Bits 7 and 6—Reserved: These bits can be written and read, but they do not select level or falling-edge sensing.

Bits 5 to 0—IRQ₅ to IRQ₀ Sense Control (IRQ5SC to IRQ0SC): These bits select whether interrupts IRQ₅ to IRQ₀ are requested by level sensing of pins $\overline{\text{IRQ}}_5$ to $\overline{\text{IRQ}}_0$, or by falling-edge sensing.

Bits 5 to 0 IRQ5SC to IRQ0SC Description

0	Interrupts are requested when $\overline{IRQ}_{\scriptscriptstyle{5}}$ to $\overline{IRQ}_{\scriptscriptstyle{0}}$ inputs are low	(Initial value)
1	Interrupts are requested by falling-edge input at $\overline{\text{IRQ}}_{\scriptscriptstyle{5}}$ to $\overline{\text{IRQ}}_{\scriptscriptstyle{0}}$	

5.3 Interrupt Sources

The interrupt sources include external interrupts (NMI, IRQ₀ to IRQ₅) and 36 internal interrupts.

5.3.1 External Interrupts

There are seven external interrupts: NMI, and IRQ₀ to IRQ₅. Of these, NMI, IRQ₀, IRQ₁, and IRQ₂ can be used to exit software standby mode.

NMI: NMI is the highest-priority interrupt and is always accepted, regardless of the states of the I and UI bits in CCR*. The NMIEG bit in SYSCR selects whether an interrupt is requested by the rising or falling edge of the input at the NMI pin. NMI interrupt exception handling has vector number 7.

Note: In the flash memory and flash memory R versions, NMI input is sometimes disabled. For details see 18.6.4, NMI Input Disable Conditions.

IRQ₀ to **IRQ**₅ **Interrupts:** These interrupts are requested by input signals at pins \overline{IRQ}_0 to \overline{IRQ}_5 . The IRQ₀ to IRQ₅ interrupts have the following features.

- ISCR settings can select whether an interrupt is requested by the low level of the input at pins \overline{IRQ}_0 to \overline{IRQ}_s , or by the falling edge.
- IER settings can enable or disable the IRQ₀ to IRQ₅ interrupts. Interrupt priority levels can be assigned by four bits in IPRA (IPRA7 to IPRA4).
- The status of IRQ₀ to IRQ₅ interrupt requests is indicated in ISR. The ISR flags can be cleared to 0 by software.

Figure 5.2 shows a block diagram of interrupts IRQ₀ to IRQ₅.

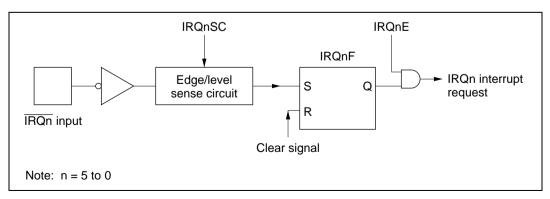


Figure 5.2 Block Diagram of Interrupts IRQ₀ to IRQ₅

Figure 5.3 shows the timing of the setting of the interrupt flags (IRQnF).

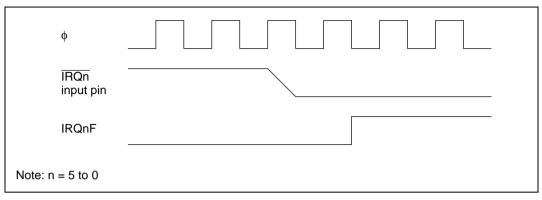


Figure 5.3 Timing of Setting of IRQnF

Interrupts IRQ $_0$ to IRQ $_5$ have vector numbers 12 to 17. These interrupts are detected regardless of whether the corresponding pin is set for input or output. When using a pin for external interrupt input, clear its DDR bit to 0 and do not use the pin for chip select output, refresh output, SCI input/output, or A/D external trigger input.

5.3.2 Internal Interrupts

Thirty-Six internal interrupts are requested from the on-chip supporting modules.

- Each on-chip supporting module has status flags for indicating interrupt status, and enable bits for enabling or disabling interrupts.
- Interrupt priority levels can be assigned in IPRA and IPRB.
- 16-bit timer, SCI, and A/D converter interrupt requests can activate the DMAC, in which case no interrupt request is sent to the interrupt controller, and the I and UI bits are disregarded.

5.3.3 Interrupt Vector Table

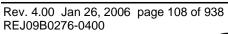
Table 5.3 lists the interrupt sources, their vector addresses, and their default priority order. In the default priority order, smaller vector numbers have higher priority. The priority of interrupts other than NMI can be changed in IPRA and IPRB. The priority order after a reset is the default order shown in table 5.3.



Table 5.3 Interrupt Sources, Vector Addresses, and Priority

		Vector	Vector Address*			
Interrupt Source	Origin	Number	Advanced Mode	Normal Mode	IPR	Priority
NMI	External	7	H'001C to H'001F	H'000E to H'000F	_	High
IRQ ₀	pins	12	H'0030 to H'0033	H'0018 to H'0019	IPRA7	
IRQ ₁	_	13	H'0034 to H0037	H'001A to H'001B	IPRA6	_
IRQ ₂	_	14 15	H'0038 to H'003B H'003C to H'003F	H'001C to H'001D H'001E to H'001F	IPRA5	_
IRQ ₃	_				10044	-
IRQ₄ IRQ₅		16 17	H'0040 to H'0043 H'0044 to H'0047	H'0020 to H'0021 H'0022 to H'0023	IPRA4	
Reserved		18	H'0048 to H'004B	H'0024 to H'0025	=	
Reserved	_	19	H'004C to H'004F	H'0024 to H'0027		
WOVI (interval timer)	Watchdog timer	20	H'0050 to H'0053	H'0028 to H'0029	IPRA3	_
CMI (compare match)	DRAM interface	21	H'0054 to H'0057	H'002A to H'002B	=	
Reserved	_	22	H'0058 to H'005B	H'002C to H'002D	-	
ADI (A/D end)	A/D	23	H'005C to H'005F	H'002E to H'002F	-	
IMIA0 (compare match/ input capture A0)	16-bit timer channel 0	24	H'0060 to H'0063	H'0030 to H'0031	IPRA2	_
IMIBO (compare match/ input capture B0)		25	H'0064 to H'0067	H'0032 to H'0033		
OVI0 (overflow 0)		26	H'0068 to H'006B	H'0034 to H'0035		
Reserved	_	27	H'006C to H'006F	H'0036 to H'0037	-	
IMIA1 (compare match/ inputcapture A1)	16-bit timer channel 1	28	H'0070 to H'0073	H'0038 to H'0039	IPRA1	
IMIB1 (compare match/ input capture B1)		29	H'0074 to H'0077	H'003A to H'003B		
OVI1 (overflow 1)		30	H'0078 to H'007B	H'003C to H'003D	_	
Reserved	_	31	H'007C to H'007F	H'003E to H'003F		Low

		Vector	Vector Address*			
Interrupt Source	Origin	Number	Advanced Mode	Normal Mode	IPR	Priority
IMIA2 (compare match/ input capture A2)	16-bit timer channel 2	32	H'0080 to H'0083	H'0040 to H'0041	IPRA0	High
IMIB2 (compare match/ input capture B2)		33	H'0084 to H'0087	H'0042 to H'0043		
OVI2 (overflow 2)		34	H'0088 to H'008B	H'0044 to H'0045	_	
Reserved	_	35	H'008C to H'008F	H'0046 to H'0047		
CMIA0 (compare match A0)	8-bit timer channel 0/1	36	H'0090 to H'0093	H'0048 to H'0049	IPRB7	
CMIB0 (compare match B0)		37	H'0094 to H'0097	H'004A to H'004B		
CMIA1/CMIB1 (compare match A1/B1)		38	H'0098 to H'009B	H'004C to H'004D		
TOVIO/TOVI1 (overflow 0/1)		39	H'009C to H'009F	H'004E to H'004F		_
CMIA2 (compare match A2)	8-bit timer channel 2/3	40	H'00A0 to H'00A3	H'0050 to H'0051	IPRB6	
CMIB2 (compare match B2)		41	H'00A4 to H'00A7	H'0052 to H'0053		
CMIA3/CMIB3 (compare match A3/B3)		42	H'00A8 to H'00AB	H'0054 to H'0055		
TOVI2/TOVI3 (overflow 2/3)		43	H'00AC to H'00AF	H'0056 to H'0057		_
DEND0A	DMAC	44		H'0058 to H'0059	IPRB5	
DEND0B		45 46		H'005A to H'005B		
DEND1A DEND1B		46 47		H'005C to H'005D H'005E to H'005F		
Reserved		48	H'00C0 to H'00C3	H'0060 to H'0061	_	-
		49	H'00C4 to H'00C7			
		50	H'00C8 to H'00CB	H'0064 to H'0065		
		51	H'00CC to H'00CF	H'0066 to H'0067		Low





		Vector	Vector Address*			
Interrupt Source	Origin	Number	Advanced Mode	Normal Mode	IPR	Priority
ERI0 (receive error 0)	SCI channel 0	52	H'00D0 to H'00D3	H'0068 to H'0069	IPRB3	High
RXI0 (receive data full 0)		53	H'00D4 to H'00D7	H'006A to H'006B		
TXI0 (transmit data empty 0)		54	H'00D8 to H'00DB	H'006C to H'006D		
TEI0 (transmit end 0)		55	H'00DC to H'00DF	H'006E to H'006F		_
ERI1 (receive error 1)	SCI channel 1	56	H'00E0 to H'00E3	H'0070 to H'0071	IPRB2	
RXI1 (receive data full 1)		57	H'00E4 to H'00E7	H'0072 to H'0073		
TXI1 (transmit data empty 1)		58	H'00E8 to H'00EB	H'0074 to H'0075		
TEI1 (transmit end 1)		59	H'00EC to H'00EF	H'0076 to H'0077		_
ERI2 (receive error 2)	SCI channel 2	60	H'00F0 to H'00F3	H'0078 to H'0079	IPRB1	
RXI2 (receive data full 2)		61	H'00F4 to H'00F7	H'007A to H'007B		
TXI2 (transmit data empty 2)		62	H'00F8 to H'00FB	H'007C to H'007D		
TEI2 (transmit end 2)		63	H'00FC to H'00FF	H'007E to H'007F		Low

Note: * Lower 16 bits of the address.

5.4 Interrupt Operation

5.4.1 Interrupt Handling Process

The H8/3067 Group handles interrupts differently depending on the setting of the UE bit. When UE = 1, interrupts are controlled by the I bit. When UE = 0, interrupts are controlled by the I and UI bits. Table 5.4 indicates how interrupts are handled for all setting combinations of the UE, I, and UI bits.

NMI interrupts are always accepted except in the reset and hardware standby states*. IRQ interrupts and interrupts from the on-chip supporting modules have their own enable bits. Interrupt requests are ignored when the enable bits are cleared to 0.

Note: In the flash memory and flash memory R versions, NMI input is sometimes disabled. For details see 18.6.4, NMI Input Disable Conditions.

Table 5.4 UE, I, and UI Bit Settings and Interrupt Handling

SYSCR	CCR					
UE	ī	UI	Description			
1	0	_	All interrupts are accepted. Interrupts with priority level 1 have higher priority.			
	1	_	No interrupts are accepted except NMI.			
0	0	_	All interrupts are accepted. Interrupts with priority level 1 have higher priority.			
	1	0	NMI and interrupts with priority level 1 are accepted.			
		1	No interrupts are accepted except NMI.			

UE = 1: Interrupts IRQ $_0$ to IRQ $_5$ and interrupts from the on-chip supporting modules can all be masked by the I bit in the CPU's CCR. Interrupts are masked when the I bit is set to 1, and unmasked when the I bit is cleared to 0. Interrupts with priority level 1 have higher priority. Figure 5.4 is a flowchart showing how interrupts are accepted when UE = 1.



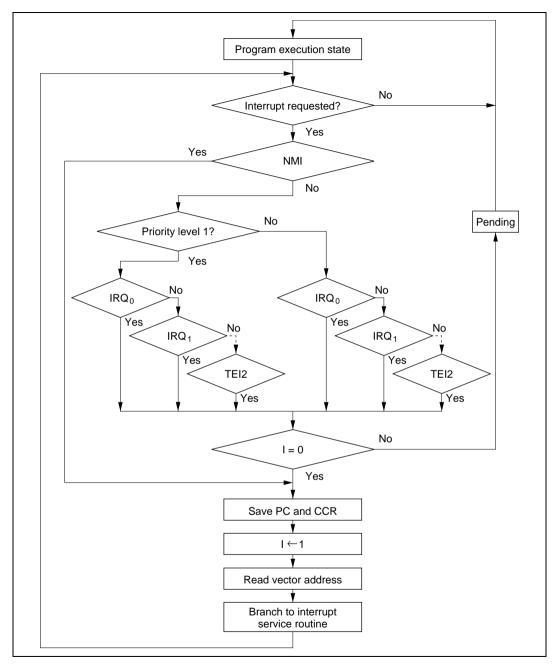


Figure 5.4 Process Up to Interrupt Acceptance when UE = 1

- If an interrupt condition occurs and the corresponding interrupt enable bit is set to 1, an interrupt request is sent to the interrupt controller.
- When the interrupt controller receives one or more interrupt requests, it selects the highest-priority request, following the IPR interrupt priority settings, and holds other requests pending. If two or more interrupts with the same IPR setting are requested simultaneously, the interrupt controller follows the priority order shown in table 5.3.
- The interrupt controller checks the I bit. If the I bit is cleared to 0, the selected interrupt request is accepted. If the I bit is set to 1, only NMI is accepted; other interrupt requests are held pending.
- When an interrupt request is accepted, interrupt exception handling starts after execution of the current instruction has been completed.
- In interrupt exception handling, PC and CCR are saved to the stack area. The PC value that is
 saved indicates the address of the first instruction that will be executed after the return from the
 interrupt service routine.
- Next the I bit is set to 1 in CCR, masking all interrupts except NMI.
- The vector address of the accepted interrupt is generated, and the interrupt service routine starts executing from the address indicated by the contents of the vector address.

UE = **0**: The I and UI bits in the CPU's CCR and the IPR bits enable three-level masking of IRQ_0 to IRQ_5 interrupts and interrupts from the on-chip supporting modules.

- Interrupt requests with priority level 0 are masked when the I bit is set to 1, and are unmasked when the I bit is cleared to 0.
- Interrupt requests with priority level 1 are masked when the I and UI bits are both set to 1, and are unmasked when either the I bit or the UI bit is cleared to 0.
 - For example, if the interrupt enable bits of all interrupt requests are set to 1, IPRA is set to H'20, and IPRB is set to H'00 (giving IRQ₂ and IRQ₃ interrupt requests priority over other interrupts), interrupts are masked as follows:
 - a. If I = 0, all interrupts are unmasked (priority order: $NMI > IRQ_2 > IRQ_3 > IRQ_0 \dots$).
 - b. If I = 1 and UI = 0, only NMI, IRQ_2 , and IRQ_3 are unmasked.
 - c. If I = 1 and UI = 1, all interrupts are masked except NMI.



Figure 5.5 shows the transitions among the above states.

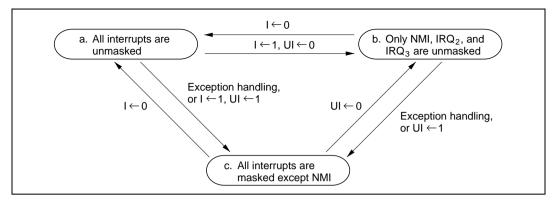


Figure 5.5 Interrupt Masking State Transitions (Example)

Figure 5.6 is a flowchart showing how interrupts are accepted when UE = 0.

- If an interrupt condition occurs and the corresponding interrupt enable bit is set to 1, an interrupt request is sent to the interrupt controller.
- When the interrupt controller receives one or more interrupt requests, it selects the highest-priority request, following the IPR interrupt priority settings, and holds other requests pending. If two or more interrupts with the same IPR setting are requested simultaneously, the interrupt controller follows the priority order shown in table 5.3.
- The interrupt controller checks the I bit. If the I bit is cleared to 0, the selected interrupt request is accepted regardless of its IPR setting, and regardless of the UI bit. If the I bit is set to 1 and the UI bit is cleared to 0, only NMI and interrupts with priority level 1 are accepted; interrupt requests with priority level 0 are held pending. If the I bit and UI bit are both set to 1, only NMI is accepted; all other interrupt requests are held pending.
- When an interrupt request is accepted, interrupt exception handling starts after execution of the current instruction has been completed.
- In interrupt exception handling, PC and CCR are saved to the stack area. The PC value that is
 saved indicates the address of the first instruction that will be executed after the return from the
 interrupt service routine.
- The I and UI bits are set to 1 in CCR, masking all interrupts except NMI.
- The vector address of the accepted interrupt is generated, and the interrupt service routine starts executing from the address indicated by the contents of the vector address.

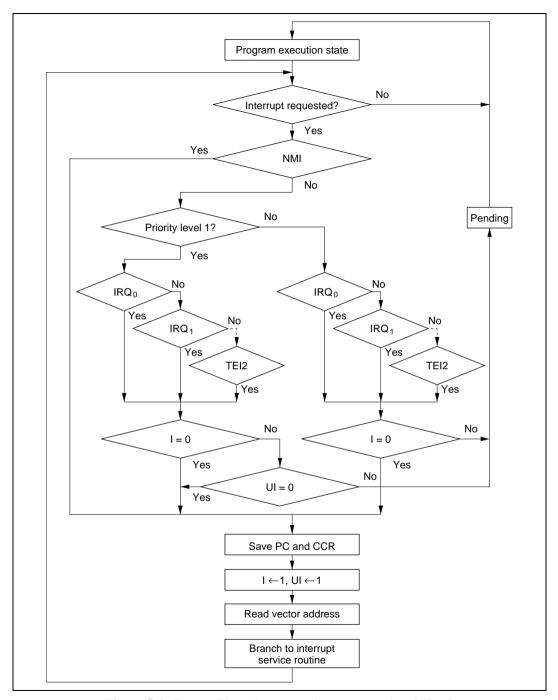


Figure 5.6 Process Up to Interrupt Acceptance when UE=0

5.4.2 Interrupt Sequence

Figure 5.7 shows the interrupt sequence in mode 2 when the program code and stack are in an external memory area accessed in two states via a 16-bit bus.

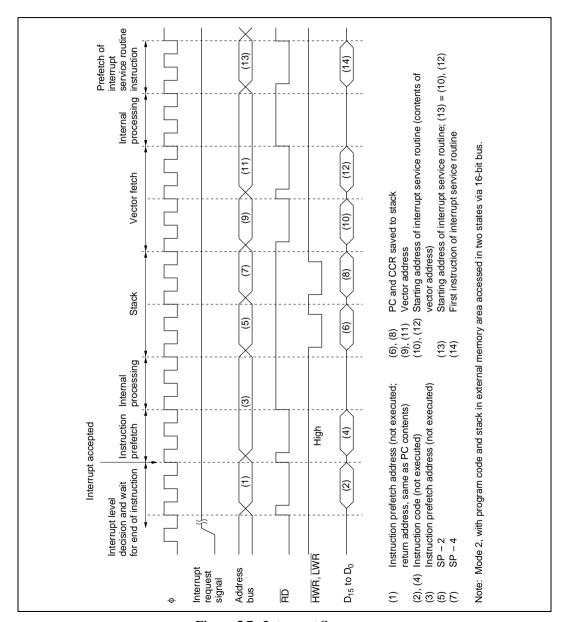


Figure 5.7 Interrupt Sequence

5.4.3 Interrupt Response Time

Table 5.5 indicates the interrupt response time from the occurrence of an interrupt request until the first instruction of the interrupt service routine is executed.

Table 5.5 Interrupt Response Time

			External Memory			
		On-Chip Memory	8-Bit Bus		16-Bit Bus	
No.	Item		2 States	3 States	2 States	3 States
1	Interrupt priority decision	2*1	2*1	2 ^{*1}	2*1	2*1
2	Maximum number of states until end of current instruction	1 to 23	1 to 27	1 to 31*4	1 to 23	1 to 25*4
3	Saving PC and CCR to stack	4	8	12*4	4	6*4
4	Vector fetch	4	8	12 ^{*4}	4	6*4
5	Instruction prefetch*2	4	8	12*4	4	6*4
6	Internal processing*3	4	4	4	4	4
Tota	I	19 to 41	31 to 57	43 to 73	19 to 41	25 to 49

Notes: 1. 1 state for internal interrupts.

- 2. Prefetch after the interrupt is accepted and prefetch of the first instruction in the interrupt service routine.
- 3. Internal processing after the interrupt is accepted and internal processing after vector fetch.
- 4. The number of states increases if wait states are inserted in external memory access.



5.5 Usage Notes

5.5.1 Contention between Interrupt and Interrupt-Disabling Instruction

When an instruction clears an interrupt enable bit to 0 to disable the interrupt, the interrupt is not disabled until after execution of the instruction is completed. If an interrupt occurs while a BCLR, MOV, or other instruction is being executed to clear its interrupt enable bit to 0, at the instant when execution of the instruction ends the interrupt is still enabled, so its interrupt exception handling is carried out. If a higher-priority interrupt is also requested, however, interrupt exception handling for the higher-priority interrupt is carried out, and the lower-priority interrupt is ignored. This also applies to the clearing of an interrupt flag to 0.

Figure 5.8 shows an example in which an IMIEA bit is cleared to 0 in the 16-bit timer's TISRA register.

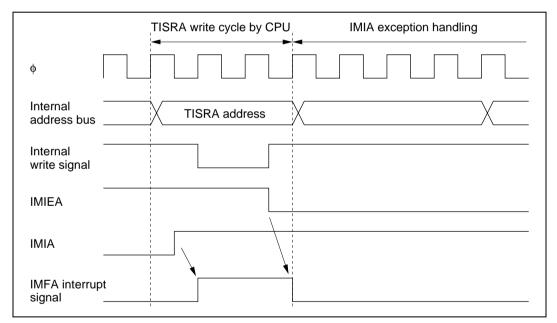


Figure 5.8 Contention between Interrupt and Interrupt-Disabling Instruction

This type of contention will not occur if the interrupt is masked when the interrupt enable bit or flag is cleared to 0.

5.5.2 Instructions that Inhibit Interrupts

The LDC, ANDC, ORC, and XORC instructions inhibit interrupts. When an interrupt occurs, after determining the interrupt priority, the interrupt controller requests a CPU interrupt. If the CPU is currently executing one of these interrupt-inhibiting instructions, however, when the instruction is completed the CPU always continues by executing the next instruction.

5.5.3 Interrupts during EEPMOV Instruction Execution

The EEPMOV.B and EEPMOV.W instructions differ in their reaction to interrupt requests.

When the EEPMOV.B instruction is executing a transfer, no interrupts are accepted until the transfer is completed, not even NMI.

When the EEPMOV.W instruction is executing a transfer, interrupt requests other than NMI are not accepted until the transfer is completed. If NMI is requested, NMI exception handling starts at a transfer cycle boundary. The PC value saved on the stack is the address of the next instruction. Programs should be coded as follows to allow for NMI interrupts during EEPMOV.W execution:

L1: EEPMOV.W

MOV.W R4,R4

BNE L1



Section 6 Bus Controller

6.1 Overview

The H8/3067 Group has an on-chip bus controller (BSC) that manages the external address space divided into eight areas. The bus specifications, such as bus width and number of access states, can be set independently for each area, enabling multiple memories to be connected easily.

The bus controller also has a bus arbitration function that controls the operation of the internal bus masters-the CPU, DMA controller (DMAC), and DRAM interface and can release the bus to an external device.

6.1.1 Features

The features of the bus controller are listed below.

- Manages external address space in area units
 - Manages the external space as eight areas (0 to 7) of 128 kbytes in 1M-byte modes, or 2
 Mbytes in 16-Mbyte modes
 - Bus specifications can be set independently for each area
 - DRAM/burst ROM interfaces can be set
- Basic bus interface
 - Chip select $(\overline{CS}_0 \text{ to } \overline{CS}_7)$ can be output for areas 0 to 7
 - 8-bit access or 16-bit access can be selected for each area
 - Two-state access or three-state access can be selected for each area
 - Program wait states can be inserted for each area
 - Pin wait insertion capability is provided
- DRAM interface
 - DRAM interface can be set for areas 2 to 5
 - Row address/column address multiplexed output (8/9/10 bits)
 - 2-CAS byte access mode
 - Burst operation (fast page mode)
 - T_p cycle insertion to secure RAS precharging time
 - Choice of CAS-before-RAS refreshing or self-refreshing
- Burst ROM interface
 - Burst ROM interface can be set for area 0
 - Selection of two- or three-state burst access

- Idle cycle insertion
 - An idle cycle can be inserted in case of an external read cycle between different areas
 - An idle cycle can be inserted when an external read cycle is immediately followed by an external write cycle
- Bus arbitration function
 - A built-in bus arbiter grants the bus right to the CPU, DMAC, DRAM interface, or an external bus master
- Other features
 - Refresh counter (refresh timer) can be used as interval timer
 - Choice of two address update modes (in flash memory R version and mask ROM versions)



6.1.2 Block Diagram

Figure 6.1 shows a block diagram of the bus controller.

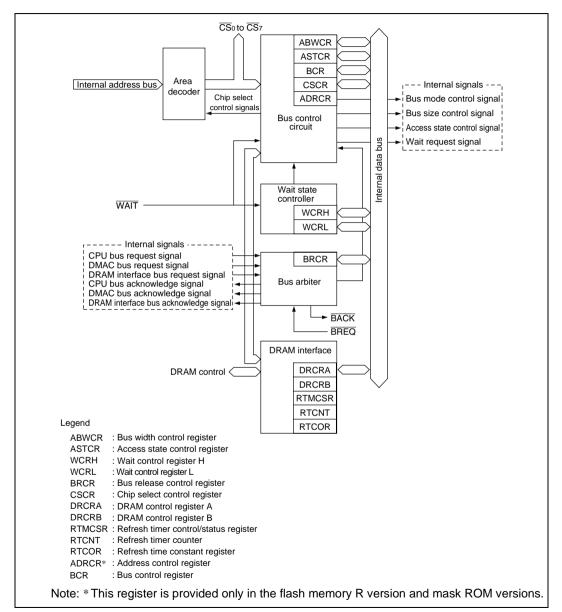


Figure 6.1 Block Diagram of Bus Controller

6.1.3 Pin Configuration

Table 6.1 summarizes the input/output pins of the bus controller.

Table 6.1 Bus Controller Pins

Name	Abbreviation	I/O	Function
Chip select 0 to 7	CS₀ to CS₁	Output	Strobe signals selecting areas 0 to 7
Address strobe	ĀS	Output	Strobe signal indicating valid address output on the address bus
Read	RD	Output	Strobe signal indicating reading from the external address space
High write	HWR	Output	Strobe signal indicating writing to the external address space, with valid data on the upper data bus (D_{15} to D_{8})
Low write	LWR	Output	Strobe signal indicating writing to the external address space, with valid data on the lower data bus $(D_7 \text{ to } D_0)$
Wait	WAIT	Input	Wait request signal for access to external three-state access areas
Bus request	BREQ	Input	Request signal for releasing the bus to an external device
Bus acknowledge	BACK	Output	Acknowledge signal indicating release of the bus to an external device



6.1.4 Register Configuration

Table 6.2 summarizes the bus controller's registers.

Table 6.2 Bus Controller Registers

Address*1	Name	Abbreviation	R/W	Initial Value
H'EE020	Bus width control register	ABWCR	R/W	H'FF*2
H'EE021	Access state control register	ASTCR	R/W	H'FF
H'EE022	Wait control register H	WCRH	R/W	H'FF
H'EE023	Wait control register L	WCRL	R/W	H'FF
H'EE013	Bus release control register	BRCR	R/W	H'FE*3
H'EE01F	Chip select control register	CSCR	R/W	H'0F
H'EE01E	Address control register*4	ADRCR	R/W	H'FF
H'EE024	Bus control register	BCR	R/W	H'C6
H'EE026	DRAM control register A	DRCRA	R/W	H'10
H'EE027	DRAM control register B	DRCRB	R/W	H'08
H'EE028	Refresh timer control/status register	RTMCSR	R(W)*5	H'07
H'EE029	Refresh timer counter	RTCNT	R/W	H'00
H'EE02A	Refresh time constant register	RTCOR	R/W	H'FF

Notes: 1. Lower 20 bits of the address in advanced mode.

- 2. In modes 2 and 4, the initial value is H'00.
- 3. In modes 3 and 4, the initial value is H'EE.
- 4. This register is provided only in the flash memory R version and mask ROM versions.
- 5. For Bit 7, only 0 can be written to clear the flag.

6.2 Register Descriptions

6.2.1 Bus Width Control Register (ABWCR)

ABWCR is an 8-bit readable/writable register that selects 8-bit or 16-bit access for each area.

Bit		7	6	5	4	3	2	1	0
		ABW7	ABW6	ABW5	ABW4	ABW3	ABW2	ABW1	ABW0
Modes 1, 3, 5, 6, and 7 Modes 2 and 4	∫ Initial value 1		1	1	1	1	1	1	1
	Read/Wri	te R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
	Initial valu	ue 0	0	0	0	0	0	0	0
	Read/Wri	te R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

When ABWCR contains H'FF (selecting 8-bit access for all areas), the chip operates in 8-bit bus mode: the upper data bus (D_{15} to D_8) is valid, and port 4 is an input/output port. When at least one bit is cleared to 0 in ABWCR, the chip operates in 16-bit bus mode with a 16-bit data bus (D_{15} to D_0). In modes 1, 3, 5, 6, and 7, ABWCR is initialized to H'FF by a reset and in hardware standby mode. In modes 2 and 4, ABWCR is initialized to H'00 by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bits 7 to 0—Area 7 to 0 Bus Width Control (ABW7 to ABW0): These bits select 8-bit access or 16-bit access for the corresponding areas.

Bits 7 to 0 ABW7 to ABW0	Description
0	Areas 7 to 0 are 16-bit access areas
1	Areas 7 to 0 are 8-bit access areas

ABWCR specifies the data bus width of external memory areas. The data bus width of on-chip memory and registers is fixed, and does not depend on ABWCR settings. These settings are therefore meaningless in the single-chip modes (modes 6 and 7).



6.2.2 Access State Control Register (ASTCR)

ASTCR is an 8-bit readable/writable register that selects whether each area is accessed in two states or three states.

Bit	7	6	5	4	3	2	1	0
	AST7	AST6	AST5	AST4	AST3	AST2	AST1	AST0
Initial value	1	1	1	1	1	1	1	1
Read/Write	R/W							

Bits selecting number of states for access to each area

ASTCR is initialized to H'FF by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bits 7 to 0—Area 7 to 0 Access State Control (AST7 to AST0): These bits select whether the corresponding area is accessed in two or three states.

Bits 7 to 0 AST7 to AST0	Description	
0	Areas 7 to 0 are accessed in two states	
1	Areas 7 to 0 are accessed in three states	(Initial value)

ASTCR specifies the number of states in which external areas are accessed. On-chip memory and registers are accessed in a fixed number of states that does not depend on ASTCR settings. These settings are therefore meaningless in the single-chip modes (modes 6 and 7).

When the corresponding area is designated as DRAM space by bits DRAS2 to DRAS0 in DRAM control register A (DRCRA), the number of access states does not depend on the AST bit setting. When an AST bit is cleared to 0, programmable wait insertion is not performed.

6.2.3 Wait Control Registers H and L (WCRH, WCRL)

WCRH and WCRL are 8-bit readable/writable registers that select the number of program wait states for each area.

On-chip memory and registers are accessed in a fixed number of states that does not depend on WCRH/WCRL settings.

WCRH and WCRL are initialized to H'FF by a reset and in hardware standby mode. They are not initialized in software standby mode.

WCRH

Bit	7	6	5	4	3	2	1	0
	W71	W70	W61	W60	W51	W50	W41	W40
Initial value	1	1	1	1	1	1	1	1
Read/Write	R/W							

Bits 7 and 6—Area 7 Wait Control 1 and 0 (W71, W70): These bits select the number of program wait states when area 7 in external space is accessed while the AST7 bit in ASTCR is set to 1.

Bit 7 W71	Bit 6 W70	Description
0	0	Program wait not inserted when external space area 7 is accessed
	1	1 program wait state inserted when external space area 7 is accessed
1	0	2 program wait states inserted when external space area 7 is accessed
	1	3 program wait states inserted when external space area 7 is accessed (Initial value)

Bits 5 and 4—Area 6 Wait Control 1 and 0 (W61, W60): These bits select the number of program wait states when area 6 in external space is accessed while the AST6 bit in ASTCR is set to 1.

Bit 5 W61	Bit 4 W60	Description
0	0	Program wait not inserted when external space area 6 is accessed
	1	1 program wait state inserted when external space area 6 is accessed
1	0	2 program wait states inserted when external space area 6 is accessed
	1	3 program wait states inserted when external space area 6 is accessed (Initial value)

Bits 3 and 2—Area 5 Wait Control 1 and 0 (W51, W50): These bits select the number of program wait states when area 5 in external space is accessed while the AST5 bit in ASTCR is set to 1.

Bit 3 W51	Bit 2 W50	Description
0	0	Program wait not inserted when external space area 5 is accessed
	1	1 program wait state inserted when external space area 5 is accessed
1	0	2 program wait states inserted when external space area 5 is accessed
	1	3 program wait states inserted when external space area 5 is accessed (Initial value)

Bits 1 and 0—Area 4 Wait Control 1 and 0 (W41, W40): These bits select the number of program wait states when area 4 in external space is accessed while the AST4 bit in ASTCR is set to 1.

Bit 1 W41	Bit 0 W40	Description
0	0	Program wait not inserted when external space area 4 is accessed
	1	1 program wait state inserted when external space area 4 is accessed
1	0	2 program wait states inserted when external space area 4 is accessed
	1	3 program wait states inserted when external space area 4 is accessed (Initial value)

WCRL

Bit	7	6	5	4	3	2	1	0
	W31	W30	W21	W20	W11	W10	W01	W00
Initial value	1	1	1	1	1	1	1	1
Read/Write	R/W							

Bits 7 and 6—Area 3 Wait Control 1 and 0 (W31, W30): These bits select the number of program wait states when area 3 in external space is accessed while the AST3 bit in ASTCR is set to 1.

Bit 7 W31	Bit 6 W30	Description
0	0	Program wait not inserted when external space area 3 is accessed
	1	1 program wait state inserted when external space area 3 is accessed
1	0	2 program wait states inserted when external space area 3 is accessed
	1	3 program wait states inserted when external space area 3 is accessed (Initial value)

Bits 5 and 4—Area 2 Wait Control 1 and 0 (W21, W20): These bits select the number of program wait states when area 2 in external space is accessed while the AST2 bit in ASTCR is set to 1.

Bit 5 W21	Bit 4 W20	Description
0	0	Program wait not inserted when external space area 2 is accessed
	1	1 program wait state inserted when external space area 2 is accessed
1	0	2 program wait states inserted when external space area 2 is accessed
	1	3 program wait states inserted when external space area 2 is accessed (Initial value)



Bits 3 and 2—Area 1 Wait Control 1 and 0 (W11, W10): These bits select the number of program wait states when area 1 in external space is accessed while the AST1 bit in ASTCR is set to 1.

Bit 3 W11	Bit 2 W10	Description
0	0	Program wait not inserted when external space area 1 is accessed
	1	1 program wait state inserted when external space area 1 is accessed
1	0	2 program wait states inserted when external space area 1 is accessed
	1	3 program wait states inserted when external space area 1 is accessed (Initial value)

Bits 1 and 0—Area 0 Wait Control 1 and 0 (W01, W00): These bits select the number of program wait states when area 0 in external space is accessed while the AST0 bit in ASTCR is set to 1.

Bit 1 W01	Bit 0 W00	Description
0	0	Program wait not inserted when external space area 0 is accessed
	1	1 program wait state inserted when external space area 0 is accessed
1	0	2 program wait states inserted when external space area 0 is accessed
	1	3 program wait states inserted when external space area 0 is accessed (Initial value)

Dit

6.2.4 Bus Release Control Register (BRCR)

BRCR is an 8-bit readable/writable register that enables address output on bus lines A_{23} to A_{20} and enables or disables release of the bus to an external device.

BIT		/	ь	5	4	3	2	1	U	
		A23E	A22E	A21E	A20E	_	_	_	BRLE	
Modes 1, 2, 6,	Initial valu	e 1	1	1	1	1	1	1	0	
and 7	Read/Writ	e —	_	_	_	_	_	_	R/W	
Modes	Initial valu	e 1	1	1	0	1	1	1	0	
3 and 4	Read/Writ	e R/W	R/W	R/W	_	_	_	_	R/W	
Mada 5	Initial valu	e 1	1	1	1	1	1	1	0	
Mode 5	Read/Writ	e R/W	R/W	R/W	R/W	_	_	_	R/W	
						F	Reserved b	oits		
Address 23 to 20 enable These bits enable PA_7 to PA_4 to be used for A_{23} to A_{20} address output					Enab	release ena les or disab bus to an e				

BRCR is initialized to H'FE in modes 1, 2, 5, 6, and 7, and to H'EE in modes 3 and 4, by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bit 7—Address 23 Enable (A23E): Enables PA_4 to be used as the A_{23} address output pin. Writing 0 in this bit enables A_{23} output from PA_4 . In modes other than 3, 4, and 5, this bit cannot be modified and PA_4 has its ordinary port functions.

Bit 7 A23E	Description	
0	PA ₄ is the A ₂₃ address output pin	
1	PA ₄ is an input/output pin	(Initial value)

Bit 6—Address 22 Enable (A22E): Enables PA_5 to be used as the A_{22} address output pin. Writing 0 in this bit enables A_{22} output from PA_5 . In modes other than 3, 4, and 5, this bit cannot be modified and PA_5 has its ordinary port functions.

Bit 6 A22E	Description	
0	PA ₅ is the A ₂₂ address output pin	
1	PA ₅ is an input/output pin	(Initial value)

Bit 5—Address 21 Enable (A21E): Enables PA_6 to be used as the A_{21} address output pin. Writing 0 in this bit enables A_{21} output from PA_6 . In modes other than 3, 4, and 5, this bit cannot be modified and PA_6 has its ordinary port functions.

Bit 5		
A21E	Description	
0	PA ₆ is the A ₂₁ address output pin	
1	PA _s is an input/output pin	(Initial value)

Bit 4—Address 20 Enable (A20E): Enables PA_7 to be used as the A_{20} address output pin. Writing 0 in this bit enables A_{20} output from PA_7 . This bit can only be modified in mode 5.

Bit 4 A20E	Description
0	PA ₇ is the A ₂₀ address output pin (Initial value when in mode 3 or 4)
1	PA ₇ is an input/output pin (Initial value when in mode 1, 2, 5, 6 or 7)

Bits 3 to 1—Reserved: These bits cannot be modified and are always read as 1.

Bit 0—Bus Release Enable (BRLE): Enables or disables release of the bus to an external device.

Bit 0 BRLE	Description	
0	The bus cannot be released to an external device BREQ and BACK can be used as input/output pins	(Initial value)
1	The bus can be released to an external device	

6.2.5 **Bus Control Register (BCR)**

Bit	7	6	5	4	3	2	1	0
	ICIS1	ICIS0	BROME	BRSTS1	BRSTS0	_	RDEA	WAITE
Initial value	1	1	0	0	0	1	1	0
Read/Write	R/W	R/W	R/W	R/W	R/W	_	R/W	R/W

BCR is an 8-bit readable/writable register that enables or disables idle cycle insertion, selects the area division unit, and enables or disables WAIT pin input.

BCR is initialized to H'C6 by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bit 7—Idle Cycle Insertion 1 (ICIS1): Selects whether one idle cycle state is to be inserted between bus cycles in case of consecutive external read cycles for different areas.

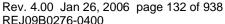
Bit 7 ICIS1	Description
0	No idle cycle inserted in case of consecutive external read cycles for different areas
1	Idle cycle inserted in case of consecutive external read cycles for different areas (Initial value)

Bit 6—Idle Cycle Insertion 0 (ICIS0): Selects whether one idle cycle state is to be inserted between bus cycles in case of consecutive external read and write cycles.

Bit 6 ICIS0	Description
0	No idle cycle inserted in case of consecutive external read and write cycles
1	Idle cycle inserted in case of consecutive external read and write cycles
	(Initial value)

Bit 5—Burst ROM Enable (BROME): Selects whether area 0 is a burst ROM interface area.

Bit 5 BROME	Description	
0	Area 0 is a basic bus interface area	(Initial value)
1	Area 0 is a burst ROM interface area	





Bit 4—Burst Cycle Select 1 (BRSTS1): Selects the number of burst cycle states for the burst ROM interface.

Bit 4 BRSTS1	Description	
0	Burst access cycle comprises 2 states	(Initial value)
1	Burst access cycle comprises 3 states	

Bit 3—Burst Cycle Select 0 (BRSTS0): Selects the number of words that can be accessed in a burst ROM interface burst access.

Bit 3	
BRSTS0	Description
0	Max. 4 words in burst access (burst access on match of address bits above A3)(
1	Max. 8 words in burst access (burst access on match of address bits above A4)

Bit 2—Reserved: Read-only bit, always read as 1.

Bit 1—Area Division Unit Select (RDEA): Selects the memory map area division units. This bit is valid in modes 3, 4, and 5, and is invalid in modes 1, 2, 6, and 7.

Bit 1 RDEA	Description		
0	Area divisions are as follows:	Area 0: 2 MB	Area 4: 1.93 MB
		Area 1: 2 MB	Area 5: 4 kB
		Area 2: 8 MB	Area 6: 23.75 kB
		Area 3: 2 MB	Area 7: 22 B
1	Areas 0 to 7 are the same size	e (2 MB)	(Initial value)

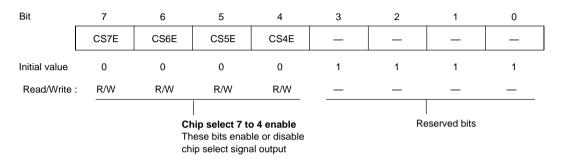
Bit 0—WAIT Pin Enable (WAITE): Enables or disables wait insertion by means of the $\overline{\text{WAIT}}$ pin.

Bit 0 WAITE	Description	
0	$\overline{\text{WAIT}}$ pin wait input is disabled, and the $\overline{\text{WAIT}}$ pin can be input/output port	used as an (Initial value)
1	WAIT pin wait input is enabled	

6.2.6 **Chip Select Control Register (CSCR)**

CSCR is an 8-bit readable/writable register that enables or disables output of chip select signals $(\overline{CS}_7 \text{ to } \overline{CS}_4).$

If output of a chip select signal is enabled by a setting in this register, the corresponding pin functions as a chip select signal $(\overline{CS}_7 \text{ to } \overline{CS}_4)$ output regardless of any other settings. CSCR cannot be modified in single-chip mode.



CSCR is initialized to H'0F by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bits 7 to 4—Chip Select 7 to 4 Enable (CS7E to CS4E): These bits enable or disable output of the corresponding chip select signal.

Bit n CSnE	Description	
0	Output of chip select signal CSn is disabled	(Initial value)
1	Output of chip select signal CSn is enabled	

Note: n = 7 to 4



Bits 3 to 0—Reserved: These bits cannot be modified and are always read as 1.

6.2.7 DRAM Control Register A (DRCRA)

Bit	7	6	5	4	3	2	1	0
	DRAS2	DRAS1	DRAS0	_	BE	RDM	SRFMD	RFSHE
Initial value	0	0	0	1	0	0	0	0
Read/Write	R/W	R/W	R/W	_	R/W	R/W	R/W	R/W

DRCRA is an 8-bit readable/writable register that selects the areas that have a DRAM interface function, and the access mode, and enables or disables self-refreshing and refresh pin output.

DRCRA is initialized to H'10 by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bits 7 to 5—DRAM Area Select (DRAS2 to DRAS0): These bits select which of areas 2 to 5 are to function as DRAM interface areas (DRAM space) in expanded mode, and at the same time select the \overline{RAS} output pin corresponding to each DRAM space.

Bit 7 Bit 6		Bit 5				
DRAS2	DRAS1	DRAS0	Area 5	Area 4	Area 3	Area 2
0	0	0	Normal	Normal	Normal	Normal
		1	Normal	Normal	Normal	DRAM space (CS ₂)
	1	0	Normal	Normal	DRAM space (CS ₃)	DRAM space (CS ₂)
		1	Normal	Normal	DRAM space (CS	52)*
1	0	0	Normal	DRAM space (CS₄)	DRAM space (CS ₃)	DRAM space (CS ₂)
		1	DRAM space (CS₅)	DRAM space (CS₄)	DRAM space (CS ₃)	DRAM space (CS ₂)
	1	0	DRAM space (CS	54)*	DRAM space (CS	52)*
		1	DRAM space (CS	52)*		

Note: * A single $\overline{\text{CSn}}$ pin serves as a common $\overline{\text{RAS}}$ output pin for a number of areas. Unused $\overline{\text{CSn}}$ pins can be used as input/output ports.

When any of bits DRAS2 to DRAS0 is set to 1 in expanded mode, it is not possible to write to DRCRB, RTMCSR, RTCNT, or RTCOR. However, 0 can be written to the CMF flag in RTMCSR to clear the flag.

When an arbitrary value has been set in DRAS2 to DRAS0, a write of a different value other than 000 must not be performed.

Bit 4—Reserved: This bit cannot be modified and is always read as 1.

Bit 3—Burst Access Enable (BE): Enables or disables burst access to DRAM space. DRAM space burst access is performed in fast page mode.

Bit 3 BE	Description	
0	Burst disabled (always full access)	(Initial value)
1	DRAM space access performed in fast page mode	

Bit 2—RAS Down Mode (RDM): Selects whether to wait for the next DRAM access with the \overline{RAS} signal held low (RAS down mode), or to drive the RAS signal high again (RAS up mode), when burst access is enabled for DRAM space (BE = 1), and access to DRAM is interrupted.

Caution is required when the \overline{HWR} and \overline{LWR} are used as the \overline{UCAS} and \overline{LCAS} output pins. For details, see RAS Down Mode and RAS Up Mode in section 6.5.10, Burst Operation.

Bit 2 RDM	Description	
0	DRAM interface: RAS up mode selected	(Initial value)
1	DRAM interface: RAS down mode selected	

Bit 1—Self-Refresh Mode (SRFMD): Specifies DRAM self-refreshing in software standby mode.

When any of areas 2 to 5 is designated as DRAM space, DRAM self-refreshing is possible when a transition is made to software standby mode after the SRFMD bit has been set to 1.

The normal access state is restored when software standby mode is exited, regardless of the SRFMD setting.

Bit 1 SRFMD	Description	
0	DRAM self-refreshing disabled in software standby mode	(Initial value)
1	DRAM self-refreshing enabled in software standby mode	



Bit 0—Refresh Pin Enable (RFSHE): Enables or disables RFSH pin refresh signal output. If areas 2 to 5 are not designated as DRAM space, this bit should not be set to 1.

Bit 0 RFSHE	Description	
0	RFSH pin refresh signal output disabled (RFSH pin can be used as input/output port)	(Initial value)
1	RFSH pin refresh signal output enabled	

6.2.8 DRAM Control Register B (DRCRB)

Bit	7	6	5	4	3	2	1	0
	MXC1	MXC0	CSEL	RCYCE	_	TPC	RCW	RLW
Initial value	0	0	0	0	1	0	0	0
Read/Write	R/W	R/W	R/W	R/W	_	R/W	R/W	R/W

DRCRB is an 8-bit readable/writable register that selects the number of address multiplex column address bits for the DRAM interface, the column address strobe output pin, enabling or disabling of refresh cycle insertion, the number of precharge cycles, enabling or disabling of wait state insertion between \overline{RAS} and \overline{CAS} , and enabling or disabling of wait state insertion in refresh cycles.

DRCRB is initialized to H'08 by a reset and in hardware standby mode. It is not initialized in software standby mode.

The settings in this register are invalid when bits DRAS2 to DRAS0 in DRCRA are all 0.

Bits 7 and 6—Multiplex Control 1 and 0 (MXC1, MXC0): These bits select the row address/column address multiplexing method used on the DRAM interface. In burst operation, the row address used for comparison is determined by the setting of these bits and the bus width of the relevant area set in ABWCR.

Bit 7 MXC1	Bit 6 MXC0	Description		
0	0	Column address: 8 bits		
		Compared address:		
		Modes 1, 2	8-bit access space	A_{19} to A_{8}
			16-bit access space	A_{19} to A_{9}
		Modes 3, 4, 5	8-bit access space	A_{23} to A_8
			16-bit access space	A_{23} to A_9
	1	Column address: 9 bits		
		Compared address:		
		Modes 1, 2	8-bit access space	A_{19} to A_{9}
			16-bit access space	A_{19} to A_{10}
		Modes 3, 4, 5	8-bit access space	A_{23} to A_9
			16-bit access space	A_{23} to A_{10}
1	0	Column address: 10 bits		
		Compared address:		
		Modes 1, 2	8-bit access space	A_{19} to A_{10}
			16-bit access space	A_{19} to A_{11}
		Modes 3, 4, 5	8-bit access space	A_{23} to A_{10}
			16-bit access space	A_{23} to A_{11}
	1	Illegal setting		

Bit 5— $\overline{\text{CAS}}$ Output Pin Select (CSEL): Selects the $\overline{\text{UCAS}}$ and $\overline{\text{LCAS}}$ output pins when areas 2 to 5 are designated as DRAM space.

Bit 5 CSEL	Description	
0	PB4 and PB5 selected as UCAS and LCAS output pins	(Initial value)
1	HWR and LWR selected as UCAS and LCAS output pins	

Bit 4—Refresh Cycle Enable (RCYCE): Enables or disables CAS-before-RAS refresh cycle insertion. When none of areas 2 to 5 has been designated as DRAM space, refresh cycles are not inserted regardless of the setting of this bit.

Bit 4 RCYCE	Description	
0	Refresh cycles disabled	(Initial value)
1	DRAM refresh cycles enabled	

Bit 3—Reserved: This bit cannot be modified and is always read as 1.

Bit 2—TP Cycle Control (TPC): Selects whether a 1-state or two-state precharge cycle (TP) is to be used for DRAM read/write cycles and CAS-before-RAS refresh cycles.

The setting of this bit does not affect the self-refresh function.

Bit 2 TPC	Description	
0	1-state precharge cycle inserted	(Initial value)
1	2-state precharge cycle inserted	

Bit 1— \overline{RAS} - \overline{CAS} Wait (RCW): Controls wait state (Trw) insertion between T_r and T_{cl} in DRAM read/write cycles. The setting of this bit does not affect refresh cycles.

Bit 1 RCW	Description	
0	Wait state (Trw) insertion disabled	(Initial value)
1	One wait state (Trw) inserted	

Bit 0—Refresh Cycle Wait Control (RLW): Controls wait state (T_{RW}) insertion for CAS-before-RAS refresh cycles. The setting of this bit does not affect DRAM read/write cycles.

Bit 0		
RLW	Description	
0	Wait state (T _{RW}) insertion disabled	(Initial value)
1	One wait state (T _{RW}) inserted	

6.2.9 Refresh Timer Control/Status Register (RTMCSR)

Bit	7	6	5	4	3	2	1	0
	CMF	CMIE	CKS2	CKS1	CKS0	_	_	_
Initial value	0	0	0	0	0	1	1	1
Read/Write	R(W)*	R/W	R/W	R/W	R/W	_	_	_

RTMCSR is an 8-bit readable/writable register that selects the refresh timer counter clock. When the refresh timer is used as an interval timer, RTMCSR also enables or disables interrupt requests. Bits 7 and 6 of RTMCSR are initialized to 0 by a reset and in the standby modes. Bits 5 to 3 are initialized to 0 by a reset and in hardware standby mode; they are not initialized in software standby mode.

Note: Only 0 can be written to clear the flag.

Bit 7—Compare Match Flag (CMF): Status flag that indicates a match between the values of RTCNT and RTCOR.

Bit 7 CMF	Description	
0	Clearing conditions When the chip is reset and in standby mode Read CMF when CMF = 1, then write 0 in CMF	(Initial value)
1	Setting condition When RTCNT = RTCOR	

Bit 6—Compare Match Interrupt Enable (CMIE): Enables or disables the CMI interrupt requested when the CMF flag is set to 1 in RTMCSR. The CMIE bit is always cleared to 0 when any of areas 2 to 5 is designated as DRAM space.

Bit 6 CMIE	Description	
0	The CMI interrupt requested by CMF is disabled	(Initial value)
1	The CMI interrupt requested by CMF is enabled	

Bits 5 to 3—Refresh Counter Clock Select (CKS2 to CKS0): These bits select the clock to be input to RTCNT from among 7 clocks obtained by dividing the system clock (ϕ). When the input clock is selected with bits CKS2 to CKS0, RTCNT begins counting up.

Bit 5	Bit 4	Bit 3	
CKS2	CKS1	CKS0	Description

0	0	0	Count operation halted	(Initial value)
		1	φ/2 used as counter clock	
	1	0	φ/8 used as counter clock	
		1	φ/32 used as counter clock	
1	0	0	φ/128 used as counter clock	
		1	φ/512 used as counter clock	
	1	0	φ/2048 used as counter clock	
		1	φ/4096 used as counter clock	

Bits 2 to 0—Reserved: These bits cannot be modified and are always read as 1.

6.2.10 Refresh Timer Counter (RTCNT)

Bit	7	6	5	4	3	2	1	0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W							

RTCNT is an 8-bit readable/writable up-counter.

RTCNT is incremented by an internal clock selected by bits CKS2 to CKS0 in RTMCSR. When RTCNT matches RTCOR (compare match), the CMF flag in RTMCSR is set to 1 and RTCNT is cleared to H'00. If the RCYCE bit in DRCRB is set to 1 at this time, a refresh cycle is started. Also, if the CMIE bit in RTMCSR is set to 1, a compare match interrupt (CMI) is generated.

RTCNT is initialized to H'00 by a reset and in standby mode.

6.2.11 Refresh Time Constant Register (RTCOR)

Bit	7	6	5	4	3	2	1	0
Initial value	1	1	1	1	1	1	1	1
Read/Write	R/W							

RTCOR is an 8-bit readable/writable register that determines the interval at which RTCNT is cleared.

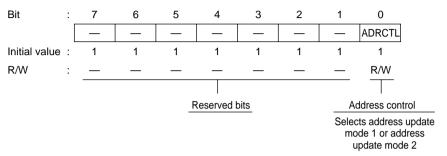
RTCOR and RTCNT are constantly compared. When their values match, the CMF flag is set to 1 in RTMCSR, and RTCNT is simultaneously cleared to H'00.

RTCOR is initialized to HFF by a reset and in hardware standby mode. It is not initialized in software standby mode.

Note: Only byte access can be used on this register.

6.2.12 Address Control Register (ADRCR) (Provided Only in Flash Memory R Version and Mask ROM Versions)

ADRCR is an 8-bit readable/writable register that selects either address update mode 1 or address update mode 2 as the address output method.



ADRCR is initialized to H'FF by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bits 7 to 1—Reserved: Read-only bits, always read as 1.

Bit 0—Address Control (ADRCTL): Selects the address output method.

Bit 0 ADRCTL	Description	
0	Address update mode 2 is selected	
1	Address update mode 1 is selected	(Initial value)

This register is provided only in the flash memory R version and mask ROM versions; it is not present in the flash memory version (HD64F3067). If this space is accessed in the flash memory version (HD64F3067), a write access will be invalid and a read access will return H'FF.

6.3 Operation

6.3.1 Area Division

The external address space is divided into areas 0 to 7. Each area has a size of 128 kbytes in the 1-Mbyte modes, or 2-Mbytes in the 16-Mbyte modes. Figure 6.2 shows a general view of the memory map.

H' 00000	A 0 (400 H 4)	H' 000000	4 0 (0 14)
H' 1FFFF	Area 0 (128 kbytes)	H' 1FFFFF	Area 0 (2 Mbytes)
H' 20000	A 4 (400 librator)	H' 200000	A 4 (O Mb-+)
H' 3FFFF	Area 1 (128 kbytes)	H' 3FFFFF	Area 1 (2 Mbytes)
H' 40000	A 0 (400 Heater)	H' 400000	A 0 (0 Mlost)
H' 5FFFF	Area 2 (128 kbytes)	H' 5FFFFF	Area 2 (2 Mbytes)
H' 60000		H' 600000	
H' 7FFFF	Area 3 (128 kbytes)	H' 7FFFFF	Area 3 (2 Mbytes)
H' 80000		H' 800000	
H' 9FFFF	Area 4 (128 kbytes)	H' 9FFFFF	Area 4 (2 Mbytes)
H' A0000		H' A00000	- (
H' BFFFF	Area 5 (128 kbytes)	H' BFFFFF	Area 5 (2 Mbytes)
H' C0000		H' C00000	
H' DFFFF	Area 6 (128 kbytes)	H' DFFFFF	Area 6 (2 Mbytes)
H' E0000	Area 7 (128 Mbytes)	H' E00000	Area 7 (2 Mbytes)
H' FFFFF		H' FFFFFF	
(a) 1-Mbyte mo	odes (modes 1, and 2)	(b) 16-Mbyte mo	odes (modes 3, 4, and 5)

Figure 6.2 Access Area Map for Each Operating Mode

Chip select signals (\overline{CS}_0 to \overline{CS}_7) can be output for areas 0 to 7. The bus specifications for each area are selected in ABWCR, ASTCR, WCRH, and WCRL.

In 16-Mbyte mode, the area division units can be selected with the RDEA bit in BCR.

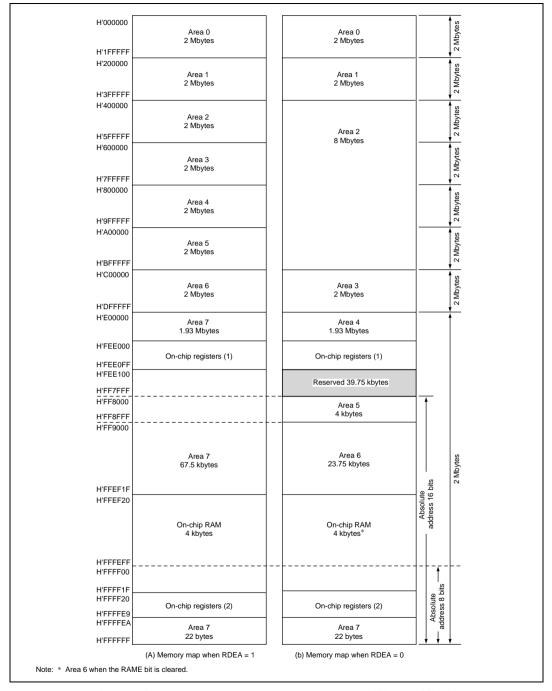


Figure 6.3 Memory Map in 16-Mbyte Mode (H8/3067, H8/3066)

6.3.2 Bus Specifications

The external space bus specifications consist of three elements: (1) bus width, (2) number of access states, and (3) number of program wait states.

The bus width and number of access states for on-chip memory and registers are fixed, and are not affected by the bus controller.

Bus Width: A bus width of 8 or 16 bits can be selected with ABWCR. An area for which an 8-bit bus is selected functions as an 8-bit access space, and an area for which a 16-bit bus is selected functions as a16-bit access space.

If all areas are designated for 8-bit access, 8-bit bus mode is set; if any area is designated for 16-bit access, 16-bit bus mode is set.

Number of Access States: Two or three access states can be selected with ASTCR. An area for which two-state access is selected functions as a two-state access space, and an area for which three-state access is selected functions as a three-state access space.

DRAM space is accessed in four states regardless of the ASTCR settings.

When two-state access space is designated, wait insertion is disabled.

Number of Program Wait States: When three-state access space is designated in ASTCR, the number of program wait states to be inserted automatically is selected with WCRH and WCRL. From 0 to 3 program wait states can be selected.

When ASTCR is cleared to 0 for DRAM space, a program wait (T_{c1} - T_{c2} wait) is not inserted. Also, no program wait is inserted in burst ROM space burst cycles.

Table 6.3 shows the bus specifications for each basic bus interface area.

Table 6.3 Bus Specifications for Each Area (Basic Bus Interface)

ABWCR ASTCR		WCRH/\	VCRL	Bus Specifications (Basic Bus Interface)				
ABWn	ASTn	Wn1	Wn0	Bus Width	Access States	Program Wait States		
0	0	_	_	16	2	0		
	1	0	0	_	3	0		
			1	_		1		
		1	0	_		2		
			1	_		3		
1	0	_	_	8	2	0		
	1	0	0	_	3	0		
			1	_		1		
		1	0	_		2		
			1	_		3		

Note: n = 7 to 0

6.3.3 Memory Interfaces

The H8/3067 Group memory interfaces comprise a basic bus interface that allows direct connection of ROM, SRAM, and so on; a DRAM interface that allows direct connection of DRAM; and a burst ROM interface that allows direct connection of burst ROM. The interface can be selected independently for each area.

An area for which the basic bus interface is designated functions as normal space, an area for which the DRAM interface is designated functions as DRAM space, and area 0 for which the burst ROM interface is designated functions as burst ROM space.

6.3.4 Chip Select Signals

For each of areas 0 to 7, the H8/3067 Group can output a chip select signal $(\overline{CS}_0 \text{ to } \overline{CS}_7)$ that goes low when the corresponding area is selected in expanded mode. Figure 6.4 shows the output timing of a \overline{CS}_n signal.

Output of \overline{CS}_0 to \overline{CS}_3: Output of \overline{CS}_0 to \overline{CS}_3 is enabled or disabled in the data direction register (DDR) of the corresponding port.

In the expanded modes with on-chip ROM disabled, a reset leaves pin \overline{CS}_0 in the output state and pins \overline{CS}_1 to \overline{CS}_3 in the input state. To output chip select signals \overline{CS}_1 to \overline{CS}_3 , the corresponding DDR bits must be set to 1. In the expanded modes with on-chip ROM enabled, a reset leaves pins \overline{CS}_0 to



 $\overline{\text{CS}}_3$ in the input state. To output chip select signals $\overline{\text{CS}}_0$ to $\overline{\text{CS}}_3$, the corresponding DDR bits must be set to 1. For details, see section 8, I/O Ports.

Output of \overline{CS}_4 to \overline{CS}_7 : Output of \overline{CS}_4 to \overline{CS}_7 is enabled or disabled in the chip select control register (CSCR). A reset leaves pins \overline{CS}_4 to \overline{CS}_7 in the input state. To output chip select signals \overline{CS}_4 to \overline{CS}_7 , the corresponding CSCR bits must be set to 1. For details, see section 8, I/O Ports.

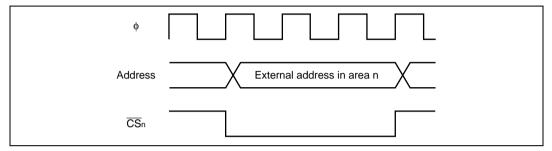


Figure 6.4 \overline{CS} n Signal Output Timing (n = 0 to 7)

When the on-chip ROM, on-chip RAM, and on-chip registers are accessed, \overline{CS}_0 to \overline{CS}_7 remain high. The \overline{CS}_n signals are decoded from the address signals. They can be used as chip select signals for SRAM and other devices.

6.3.5 Address Output Method

The H8/3067 Group provides a choice of two address update methods: either the same method as in the previous H8/300H Series (address update mode 1), or a method in which address update is restricted to external space accesses or self-refresh cycles (address update mode 2).

Figure 6.5 shows examples of address output in these two update modes.

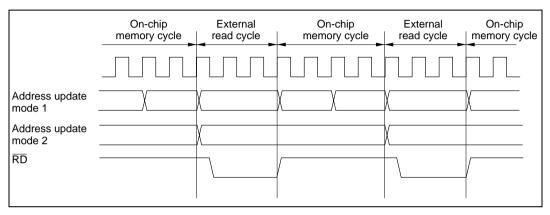


Figure 6.5 Sample Address Output in Each Address Update Mode (Basic Bus Interface, 3-State Space)

Address Update Mode 1: Address update mode 1 is compatible with the previous H8/300H Series. Addresses are always updated between bus cycles.

Address Update Mode 2: In address update mode 2, address updating is performed only in external space accesses or self-refresh cycles. In this mode, the address can be retained between an external space read cycle and an instruction fetch cycle (on-chip memory) by placing the program in on-chip memory. Address update mode 2 is therefore useful when connecting a device that requires address hold time with respect to the rise of the \overline{RD} strobe.

Switching between address update modes 1 and 2 is performed by means of the ADRCTL bit in ADRCR. The initial value of ADRCR is the address update mode 1 setting, providing compatibility with the previous H8/300H Series.

Cautions: The address output methods are designed so that the initial state with the bit selection method is compatible with the flash memory version (HD64F3067) (i.e. address update mode 1), and so there is basically no problem if this version is replaced with the flash memory R version or a mask ROM version. However, the following points should be noted.



- ADRCR is allocated to address H'FEE01E. In the flash memory version, the corresponding
 address is empty space, but it is necessary to confirm that no accesses are made to H'FEE01E
 in the program.
- When address update mode 2 is selected, the address in an internal space (on-chip memory or internal I/O) access cycle is not output externally.
- In order to secure address holding with respect to the rise of \overline{RD} , when address update mode 2 is used an external space read access must be completed within a single access cycle. For example, in a word access to 8-bit access space, the bus cycle is split into two as shown in figure 6.6., and so there is not a single access cycle. In this case, address holding is not guaranteed at the rise of \overline{RD} between the first (even address) and second (odd address) access cycles (area inside the ellipse in the figure).

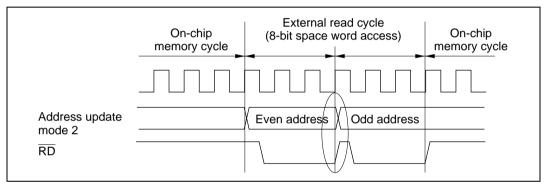


Figure 6.6 Example of Consecutive External Space Accesses in Address Update Mode 2

• When address update mode 2 is selected, in a DRAM space CAS-before-RAS (CBR) refresh cycle the previous address is retained (the area 2 start address is not output).

6.4 Basic Bus Interface

6.4.1 Overview

The basic bus interface enables direct connection of ROM, SRAM, and so on.

The bus specifications can be selected with ABWCR, ASTCR, WCRH, and WCRL (see table 6.3).

6.4.2 Data Size and Data Alignment

Data sizes for the CPU and other internal bus masters are byte, word, and longword. The bus controller has a data alignment function, and when accessing external space, controls whether the upper data bus (D_{15} to D_{8}) or lower data bus (D_{7} to D_{0}) is used according to the bus specifications for the area being accessed (8-bit access area or 16-bit access area) and the data size.

8-Bit Access Areas: Figure 6.7 illustrates data alignment control for 8-bit access space. With 8-bit access space, the upper data bus (D_{15} to D_{8}) is always used for accesses. The amount of data that can be accessed at one time is one byte: a word access is performed as two byte accesses, and a longword access, as four byte accesses.

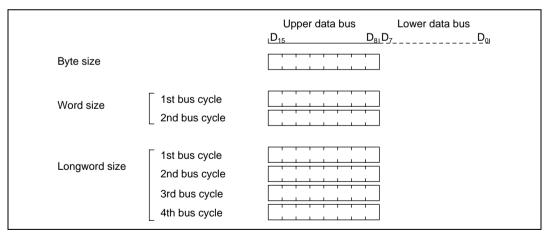


Figure 6.7 Access Sizes and Data Alignment Control (8-Bit Access Area)

16-Bit Access Areas: Figure 6.8 illustrates data alignment control for 16-bit access areas. With 16-bit access areas, the upper data bus (D_{15} to D_{8}) and lower data bus (D_{7} to D_{0}) are used for accesses. The amount of data that can be accessed at one time is one byte or one word, and a longword access is executed as two word accesses.

In byte access, whether the upper or lower data bus is used is determined by whether the address is even or odd. The upper data bus is used for an even address, and the lower data bus for an odd address.

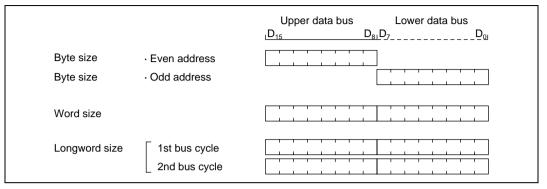


Figure 6.8 Access Sizes and Data Alignment Control (16-Bit Access Area)

6.4.3 Valid Strobes

Table 6.4 shows the data buses used, and the valid strobes, for the access spaces.

In a read, the \overline{RD} signal is valid for both the upper and the lower half of the data bus.

In a write, the \overline{HWR} signal is valid for the upper half of the data bus, and the \overline{LWR} signal for the lower half.

Table 6.4 Data Buses Used and Valid Strobes

Area	Access Size	Read/Write	Address	Valid Strobe	Upper Data Bus (D ₁₅ to D ₈)	Lower Data Bus (D ₇ to D ₀)
8-bit	Byte	Read	_	RD	Valid	Invalid
access area		Write	_	HWR	_	Undetermined data
16-bit access area	Byte	Read	Even	RD	Valid	Invalid
			Odd	_	Invalid	Valid
		Write	Even	HWR	Valid	Undetermined data
			Odd	LWR	Undetermined data	Valid
	Word	Read	_	RD	Valid	Valid
		Write	_	HWR, LWR	Valid	Valid

Notes: 1. Undetermined data means that unpredictable data is output.

2. Invalid means that the bus is in the input state and the input is ignored.

6.4.4 Memory Areas

The initial state of each area is basic bus interface, three-state access space. The initial bus width is selected according to the operating mode. The bus specifications described here cover basic items only, and the following sections should be referred to for further details: 6.4, Basic Bus Interface, 6.5, DRAM Interface, 6.8, Burst ROM Interface.

Area 0: Area 0 includes on-chip ROM, and in ROM-disabled expansion mode, all of area 0 is external space. In ROM-enabled expansion mode, the space excluding on-chip ROM is external space.

When area 0 external space is accessed, the $\overline{\text{CS}}_0$ signal can be output.

Either basic bus interface or burst ROM interface can be selected for area 0.

The size of area 0 is 128 kbytes in modes 1 and 2, and 2 Mbytes in modes 3, 4, and 5.

Areas 1 and 6: In external expansion mode, areas 1 and 6 are entirely external space.

When area 1 and 6 external space is accessed, the \overline{CS}_1 and \overline{CS}_6 pin signals respectively can be output.

Only the basic bus interface can be used for areas 1 and 6.

The size of areas 1 and 6 is 128 kbytes in modes 1 and 2, and 2 Mbytes in modes 3, 4, and 5.



Areas 2 to 5: In external expansion mode, areas 2 to 5 are entirely external space.

When area 2 to 5 external space is accessed, signals \overline{CS}_{5} to \overline{CS}_{5} can be output.

Basic bus interface or DRAM interface can be selected for areas 2 to 5. With the DRAM interface, signals \overline{CS} , to \overline{CS} , are used as \overline{RAS} signals.

The size of areas 2 to 5 is 128 kbytes in modes 1 and 2, and 2 Mbytes in modes 3, 4, and 5.

Area 7: Area 7 includes the on-chip RAM and registers. In external expansion mode, the space excluding the on-chip RAM and registers is external space. The on-chip RAM is enabled when the RAME bit in the system control register (SYSCR) is set to 1; when the RAME bit is cleared to 0, the on-chip RAM is disabled and the corresponding space becomes external space.

When area 7 external space is accessed, the \overline{CS}_7 signal can be output.

Only the basic bus interface can be used for the area 7 memory interface.

The size of area 7 is 128 kbytes in modes 1 and 2, and 2 Mbytes in modes 3, 4, and 5.

6.4.5 Basic Bus Control Signal Timing

8-Bit, Three-State-Access Areas

Figure 6.9 shows the timing of bus control signals for an 8-bit, three-state-access area. The upper data bus (D_{15} to D_{8}) is used in accesses to these areas. The \overline{LWR} pin is always high. Wait states can be inserted.

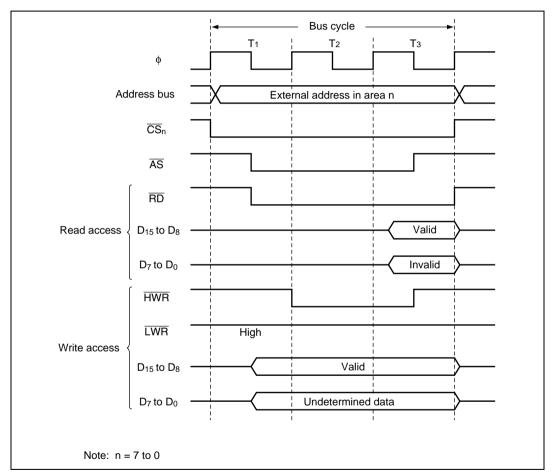


Figure 6.9 Bus Control Signal Timing for 8-Bit, Three-State-Access Area

8-Bit, Two-State-Access Areas

Figure 6.10 shows the timing of bus control signals for an 8-bit, two-state-access area. The upper data bus (D_{15} to D_{8}) is used in accesses to these areas. The \overline{LWR} pin is always high. Wait states cannot be inserted.

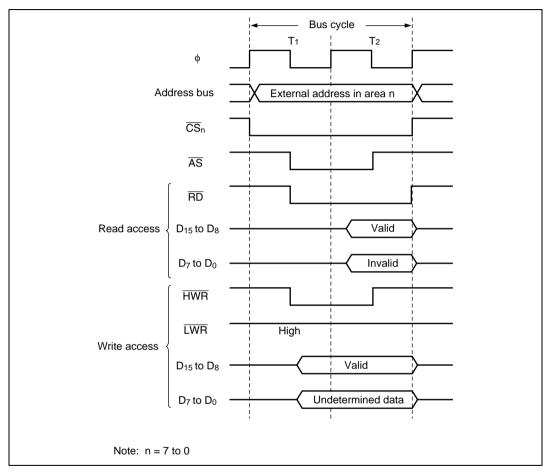


Figure 6.10 Bus Control Signal Timing for 8-Bit, Two-State-Access Area

16-Bit, Three-State-Access Areas

Figures 6.11 to 6.13 show the timing of bus control signals for a 16-bit, three-state-access area. In these areas, the upper data bus (D_{15} to D_{8}) is used in accesses to even addresses and the lower data bus (D_{2} to D_{3}) in accesses to odd addresses. Wait states can be inserted.

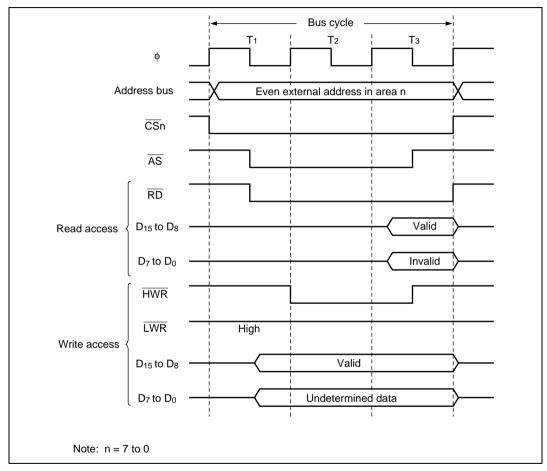


Figure 6.11 Bus Control Signal Timing for 16-Bit, Three-State-Access Area (1) (Byte Access to Even Address)

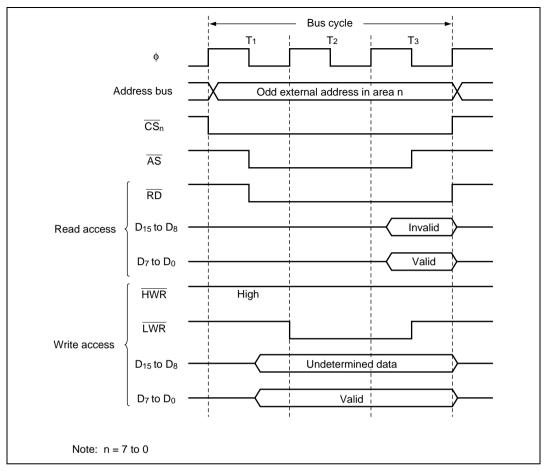


Figure 6.12 Bus Control Signal Timing for 16-Bit, Three-State-Access Area (2) (Byte Access to Odd Address)

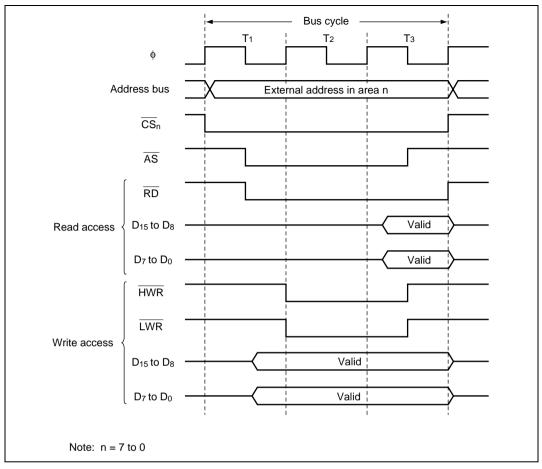


Figure 6.13 Bus Control Signal Timing for 16-Bit, Three-State-Access Area (3) (Word Access)

16-Bit, Two-State-Access Areas: Figures 6.14 to 6.16 show the timing of bus control signals for a 16-bit, two-state-access area. In these areas, the upper data bus (D_{15} to D_{8}) is used in accesses to even addresses and the lower data bus (D_{7} to D_{0}) in accesses to odd addresses. Wait states cannot be inserted.

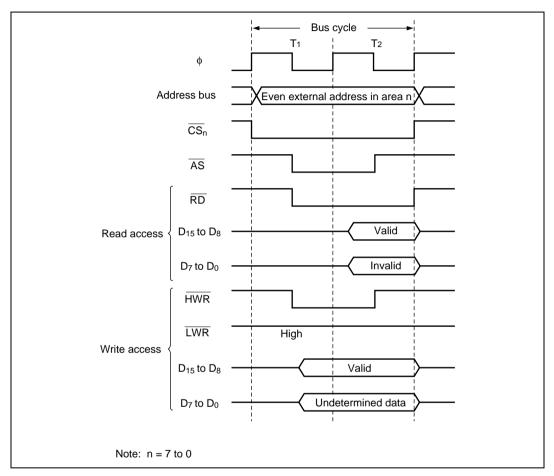


Figure 6.14 Bus Control Signal Timing for 16-Bit, Two-State-Access Area (1) (Byte Access to Even Address)

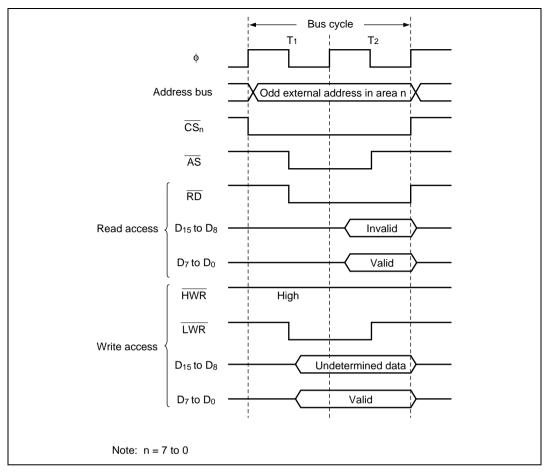


Figure 6.15 Bus Control Signal Timing for 16-Bit, Two-State-Access Area (2) (Byte Access to Odd Address)

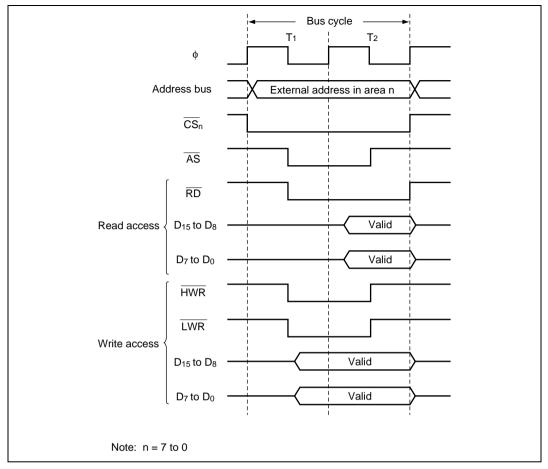


Figure 6.16 Bus Control Signal Timing for 16-Bit, Two-State-Access Area (3) (Word Access)

6.4.6 Wait Control

When accessing external space, the H8/3067 Group can extend the bus cycle by inserting one or more wait states (T_w). There are two ways of inserting wait states: (1) program wait insertion and (2) pin wait insertion using the \overline{WAIT} pin.

Program Wait Insertion: From 0 to 3 wait states can be inserted automatically between the T_2 state and T_3 state on an individual area basis in three-state access space, according to the settings of WCRH and WCRL.

Pin Wait Insertion: Setting the WAITE bit in BCR to 1 enables wait insertion by means of the WAIT pin. When external space is accessed in this state, a program wait is first inserted. If the $\overline{\text{WAIT}}$ pin is low at the falling edge of ϕ in the last T₂ or T_w state, another T_w state is inserted. If the \overline{WAIT} pin is held low, T_w states are inserted until it goes high.

This is useful when inserting four or more T_w states, or when changing the number of T_w states for different external devices.

The WAITE bit setting applies to all areas. Pin waits cannot be inserted in DRAM space.

Figure 6.17 shows an example of the timing for insertion of one program wait state in 3-state space.

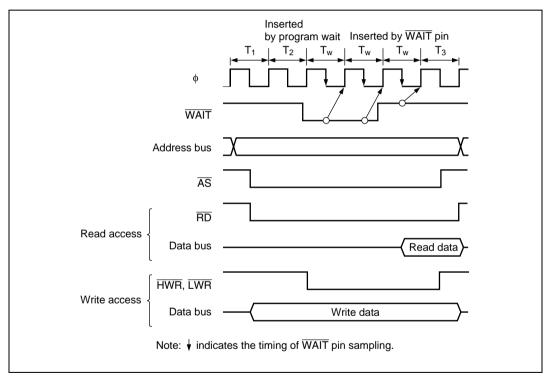


Figure 6.17 Example of Wait State Insertion Timing

6.5 DRAM Interface

6.5.1 Overview

The H8/3067 Group is provided with a DRAM interface with functions for DRAM control signal (RAS, UCAS, LCAS, WE) output, address multiplexing, and refreshing, that direct connection of DRAM. In the expanded modes, external address space areas 2 to 5 can be designated as DRAM space accessed via the DRAM interface. A data bus width of 8 or 16 bits can be selected for DRAM space by means of a setting in ABWCR. When a 16-bit data bus width is selected, CAS is used for byte access control. In the case of × 16-bit organization DRAM, therefore, the 2-CAS type can be connected. A fast page mode is supported in addition to the normal read and write access modes

6.5.2 DRAM Space and RAS Output Pin Settings

Designation of areas 2 to 5 as DRAM space, and selection of the \overline{RAS} output pin for each area designated as DRAM space, is performed by setting bits in DRCRA. Table 6.5 shows the correspondence between the settings of bits DRAS2 to DRAS0 and the selected DRAM space and \overline{RAS} output pin.

When an arbitrary value has been set in DRAS2 to DRAS0, a write of a different value other than 000 must not be performed.

Table 6.5 Settings of Bits DRAS2 to DRAS0 and Corresponding DRAM Space (RAS Output Pin)

DRAS2	DRAS1	DRAS0	Area 5	Area 4	Area 3	Area 2	
0 0		0	Normal space	Normal space	Normal space	Normal space	
		1 Normal space		Normal space	Normal space	DRAM space (\overline{CS}_2)	
1		0	Normal space	Normal space	DRAM space (CS ₃)	DRAM space (\overline{CS}_2)	
		1	Normal space Normal space		DRAM space (CS ₂)*		
1	0	0	Normal space $\frac{DRAM}{(\overline{CS}_4)}$		DRAM space (CS ₃)	$\frac{DRAM\;space}{(\overline{CS}_{\scriptscriptstyle{2}})}$	
		1	DRAM space (CS₅)	•		$\frac{DRAM\;space}{(\overline{CS}_{\scriptscriptstyle{2}})}$	
	1	0	DRAM space (CS	5,)*	DRAM space (CS ₂)*		
		1	DRAM space (CS	52)*			

Note: * A single $\overline{\text{CS}}_n$ pin serves as a common $\overline{\text{RAS}}$ output pin for a number of areas. Unused $\overline{\text{CS}}_n$ pins can be used as input/output ports.

6.5.3 Address Multiplexing

When DRAM space is accessed, the row address and column address are multiplexed. The address multiplexing method is selected with bits MXC1 and MXC0 in DRCRB according to the number of bits in the DRAM column address. Table 6.6 shows the correspondence between the settings of MXC1 and MXC0 and the address multiplexing method.

Table 6.6 Settings of Bits MXC1 and MXC0 and Address Multiplexing Method

	DRCRB		Column Address	Address Pins													
	MXC1	MXC0	Bits	A ₂₃ to A ₁₃	A ₁₂	A ₁₁	A ₁₀	A ₉	A ₈	A,	A ₆	A ₅	A ₄	A_3	A ₂	A ₁	A ₀
Row	0	0	8 bits	A ₂₃ to A ₁₃	A ₂₀ *	A ₁₉	A ₁₈	A ₁₇	A ₁₆	A ₁₅	A ₁₄	A ₁₃	A ₁₂	A ₁₁	A ₁₀	A ₉	A ₈
address		1	9 bits	A ₂₃ to A ₁₃	A ₁₂	A ₂₀ *	A ₁₉	A ₁₈	A ₁₇	A ₁₆	A ₁₅	A ₁₄	A ₁₃	A ₁₂	A ₁₁	A ₁₀	A ₉
	1	0	10 bits	A ₂₃ to A ₁₃	A ₁₂	A ₁₁	A ₂₀ *	A ₁₉	A ₁₈	A ₁₇	A ₁₆	A ₁₅	A ₁₄	A ₁₃	A ₁₂	A ₁₁	A ₁₀
		1	Illegal setting	_	_	_	_	_	_	_	_	_	_	_	_	_	_
Column address	_	_	_	A_{23} to A_{13}	A ₁₂	A ₁₁	A ₁₀	A ₉	A ₈	A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀

Note: * Row address bit A₂₀ is not multiplexed in 1-Mbyte mode.

6.5.4 Data Bus

If the bit in ABWCR corresponding to an area designated as DRAM space is set to 1, that area is designated as 8-bit DRAM space; if the bit is cleared to 0, the area is designated as 16-bit DRAM space. In 16-bit DRAM space, × 16-bit organization DRAM can be connected directly.

In 8-bit DRAM space the upper half of the data bus, D_{15} to D_8 , is enabled, while in 16-bit DRAM space both the upper and lower halves of the data bus, D_{15} to D_0 , are enabled.

Access sizes and data alignment are the same as for the basic bus interface: see section 6.4.2, Data Size and Data Alignment.

6.5.5 Pins Used for DRAM Interface

Table 6.7 shows the pins used for DRAM interfacing and their functions.

Table 6.7 **DRAM Interface Pins**

	With DRAM			
Pin	Designated	Name	I/O	Function
PB4	<u>UCAS</u>	Upper column address strobe	Output	Upper column address strobe for DRAM space access (when CSEL = 0 in DRCRB)
PB5	LCAS	Lower column address strobe	Output	Lower column address strobe for DRAM space access (when CSEL = 0 in DRCRB)
HWR	<u>UCAS</u>	Upper column address strobe	Output	Upper column address strobe for DRAM space access (when CSEL = 1 in DRCRB)
LWR	<u>LCAS</u>	Lower column address strobe	Output	Lower column address strobe for DRAM space access (when CSEL = 1 in DRCRB)
$\overline{CS}_{\scriptscriptstyle 2}$	$\overline{RAS}_{\scriptscriptstyle 2}$	Row address strobe 2	Output	Row address strobe for DRAM space access
$\overline{\text{CS}}_{\scriptscriptstyle 3}$	RAS ₃	Row address strobe 3	Output	Row address strobe for DRAM space access
$\overline{\text{CS}}_{\scriptscriptstyle{4}}$	RAS₄	Row address strobe 4	Output	Row address strobe for DRAM space access
$\overline{\text{CS}}_{\scriptscriptstyle{5}}$	$\overline{RAS}_{\scriptscriptstyle{5}}$	Row address strobe 5	Output	Row address strobe for DRAM space access
RD	WE	Write enable	Output	Write enable for DRAM space write access*
P80	RFSH	Refresh	Output	Goes low in refresh cycle
A_{12} to A_0	A_{12} to A_0	Address	Output	Row address/column address multiplexed output
D ₁₅ to D ₀	D ₁₅ to D ₀	Data	I/O	Data input/output pins

Note: * Fixed high in a read access.

6.5.6 **Basic Timing**

Figure 6.18 shows the basic access timing for DRAM space. The basic DRAM access timing is four states: one precharge cycle (T_p) state, one row address output cycle (T_p) state, and two column address output cycle (T_{c1}, T_{c2}) states. Unlike the basic bus interface, the corresponding bits in ASTCR control only enabling or disabling of wait insertion between T_{c1} and T_{c2}, and do not affect the number of access states. When the corresponding bit in ASTCR is cleared to 0, wait states cannot be inserted between T_{c1} and T_{c2} in the DRAM access cycle.



If a DRAM read/write cycle is followed by an access cycle for an external area other than DRAM space when \overline{HWR} and \overline{LWR} are selected as the \overline{UCAS} and \overline{LCAS} output pins, an idle cycle (Ti) is inserted unconditionally immediately after the DRAM access cycle. See section 6.9, Idle Cycle, for details.

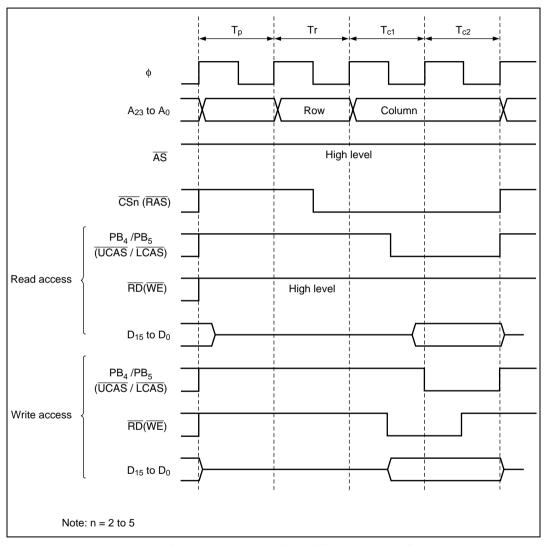


Figure 6.18 Basic Access Timing (CSEL = 0 in DRCRB)

6.5.7 Precharge State Control

In the H8/3067 Group, provision is made for the DRAM RAS precharge time by always inserting one RAS precharge state (T_p) when DRAM space is accessed. This can be changed to two T_p states by setting the TPC bit to 1 in DRCRB. The optimum number of T_p cycles should be set according to the DRAM connected and the operating frequency of the H8/3067 Group chip. Figure 6.19 shows the timing when two T_p states are inserted.

When the TCP bit is set to 1, two $T_{_{\scriptscriptstyle p}}$ states are also used for CAS-before-RAS refresh cycles.

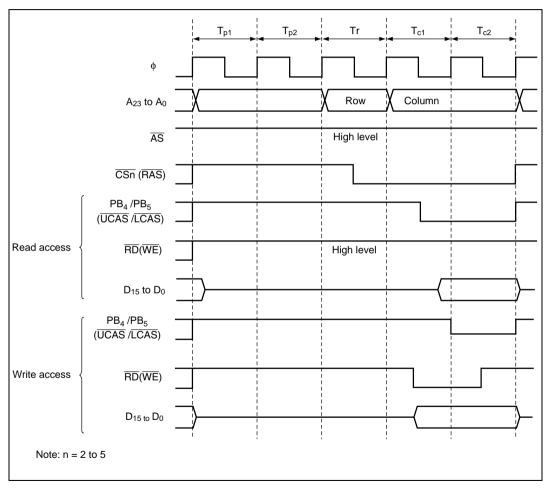


Figure 6.19 Timing with Two Precharge States (CSEL = 0 in DRCRB)

6.5.8 Wait Control

In a DRAM access cycle, wait states can be inserted (1) between the T_r state and T_{cl} state, and (2) between the T_{c1} state and T_{c2} state.

Insertion of T_{rw} Wait State between T_r and T_{cl}: One T_{rw} state can be inserted between T_r and T_{cl} by setting the RCW bit to 1 in DRCRB.

Insertion of T_w Wait State(s) between T_{cl} and T_{cl}: When the bit in ASTCR corresponding to an area designated as DRAM space is set to 1, from 0 to 3 wait states can be inserted between the T_{cl} state and T_o state by means of settings in WCRH and WCRL.

Figure 6.20 shows an example of the timing for wait state insertion.

The settings of the RCW bit in DRCRB and of ASTCR, WCRH, and WCRL do not affect refresh cycles. Wait states cannot be inserted in a DRAM space access cycle by means of the $\overline{\text{WAIT}}$ pin.

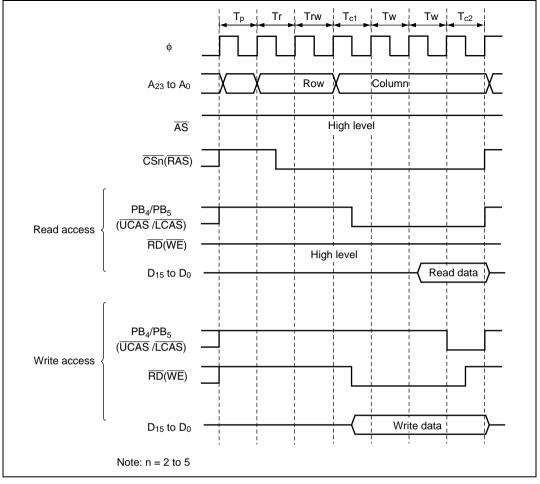


Figure 6.20 Example of Wait State Insertion Timing (CSEL = 0)

6.5.9 Byte Access Control and CAS Output Pin

When an access is made to DRAM space designated as a 16-bit-access area in ABWCR, column address strobes (\overline{UCAS} and \overline{LCAS}) corresponding to the upper and lower halves of the external data bus are output. In the case of \times 16-bit organization DRAM, the 2-CAS type can be connected.

Either PB4 and PB5, or \overline{HWR} and \overline{LWR} , can be used as the \overline{UCAS} and \overline{LCAS} output pins, the selection being made with the CSEL bit in DRCRB. Table 6.8 shows the CSEL bit settings and corresponding output pin selections.

When an access is made to DRAM space designated as an 8-bit-access area in ABWCR, only $\overline{\text{UCAS}}$ is output. When the entire DRAM space is designated as 8-bit-access space and CSEL = 0, PB5 can be used as an input/output port.

Note that \overline{RAS} down mode cannot be used when a device other than DRAM is connected to external space and \overline{HWR} and \overline{LWR} are used as write strobes. In this case, also, an idle cycle (Ti) is always inserted when an external access to other than DRAM space occurs after a DRAM space access. For details, see section 6.9, Idle Cycle.

Table 6.8 CSEL Settings and UCAS and LCAS Output Pins

CSEL	UCAS	LCAS
0	PB4	PB5
1	HWR	LWR

Figure 6.21 shows the control timing.

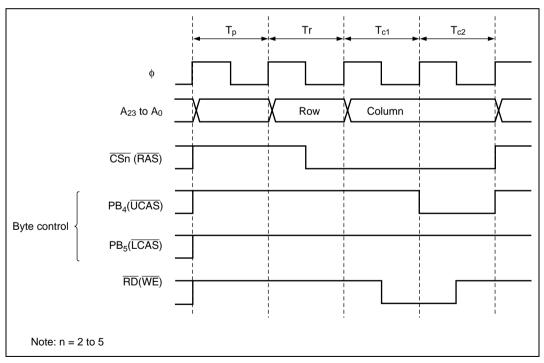


Figure 6.21 Control Timing (Upper-Byte Write Access When CSEL = 0)

6.5.10 Burst Operation

With DRAM, in addition to full access (normal access) in which data is accessed by outputting a row address for each access, a fast page mode is also provided which can be used when making a number of consecutive accesses to the same row address. This mode enables fast (burst) access of data by simply changing the column address after the row address has been output. Burst access can be selected by setting the BE bit to 1 in DRCRA.

Burst Access (Fast Page Mode) Operation Timing: Figure 6.22 shows the operation timing for burst access. When there are consecutive access cycles for DRAM space, the column address and $\overline{\text{CAS}}$ signal output cycles (two states) continue as long as the row address is the same for consecutive access cycles. In burst access, too, the bus cycle can be extended by inserting wait states between T_{c1} and T_{c2} . The wait state insertion method and timing are the same as for full access: see section 6.5.8, Wait Control, for details.

The row address used for the comparison is determined by the bus width of the relevant area set in bits MXC1 and MXC0 in BRCRB, and in ABWCR. Table 6.9 shows the compared row addresses corresponding to the various settings of bits MXC1 and MXC0, and ABWCR.



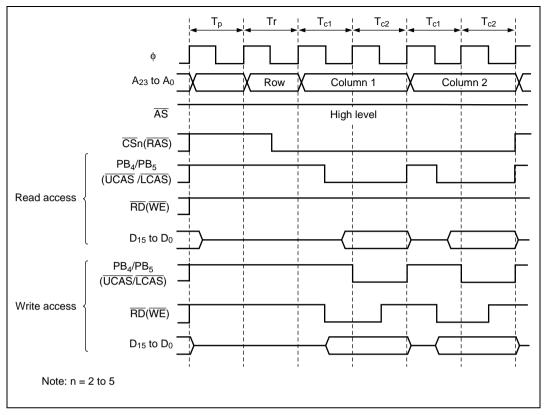


Figure 6.22 Operation Timing in Fast Page Mode

Table 6.9 Correspondence between Settings of MXC1 and MXC0 Bits and ABWCR, and Row Address Compared in Burst Access

	DF	CRB	ABWCR					
Operating Mode	MXC1	MXC0	ABWn	Bus Width	Compared Row Address			
Modes 1 and 2	0	0	0	16 bits	A19 to A9			
(1-Mbyte)			1	8 bits	A19 to A8			
		1	0	16 bits	A19 to A10			
			1	8 bits	A19 to A9			
	1	0	0	16 bits	A19 to A11			
			1	8 bits	A19 to A10			
		1	_	_	Illegal setting			
Modes 3, 4, and 5	0	0	0	16 bits	A23 to A9			
(16-Mbyte)			1	8 bits	A23 to A8			
		1	0	16 bits	A23 to A10			
			1	8 bits	A23 to A9			
	1	0	0	16 bits	A23 to A11			
			1	8 bits	A23 to A10			
		1	_	_	Illegal setting			

Note: n = 2 to 5

RAS Down Mode and RAS Up Mode: With DRAM provided with fast page mode, as long as accesses are to the same row address, burst operation can be continued without interruption even if accesses are not consecutive by holding the RAS signal low.

RAS Down Mode

To select RAS down mode, set the BE and RDM bits to 1 in DRCRA. If access to DRAM space is interrupted and another space is accessed, the \overline{RAS} signal is held low during the access to the other space, and burst access is performed if the row address of the next DRAM space access is the same as the row address of the previous DRAM space access. Figure 6.23 shows an example of the timing in RAS down mode.

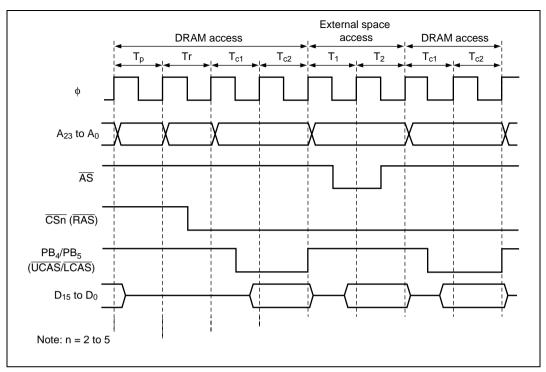


Figure 6.23 Example of Operation Timing in RAS Down Mode (CSEL = 0)

When RAS down mode is selected, the conditions for an asserted \overline{RAS} n signal to return to the high level are as shown below. The timing in these cases is shown in figure 6.24.

- When DRAM space with a different row address is accessed
- Immediately before a CAS-before-RAS refresh cycle
- When the BE bit or RDM bit is cleared to 0 in DRCRA
- Immediately before release of the external bus

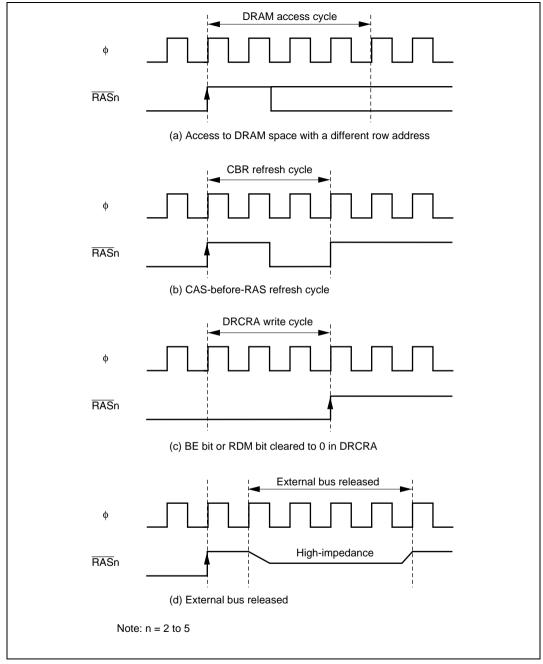


Figure 6.24 RAS n Negation Timing when RAS Down Mode is Selected

When RAS down mode is selected, the CAS-before-RAS refresh function provided with this DRAM interface must always be used as the DRAM refreshing method. When a refresh operation is performed, the \overline{RAS} signal goes high immediately beforehand. The refresh interval setting must be made so that the maximum DRAM \overline{RAS} pulse width specification is observed.

When the self-refresh function is used, the RDM bit must be cleared to 0, and RAS up mode selected, before executing a SLEEP instruction in order to enter software standby mode. Select RAS down mode again after exiting software standby mode.

Note that RAS down mode cannot be used when \overline{HWR} and \overline{LWR} are selected for \overline{UCAS} and \overline{LCAS} , a device other than DRAM is connected to external space, and \overline{HWR} and \overline{LWR} are used as write strobes.

• RAS Up Mode

To select RAS up mode, clear the RDM bit to 0 in DRCRA. Each time access to DRAM space is interrupted and another space is accessed, the \overline{RAS} signal returns to the high level. Burst operation is only performed if DRAM space is continuous. Figure 6.25 shows an example of the timing in RAS up mode.

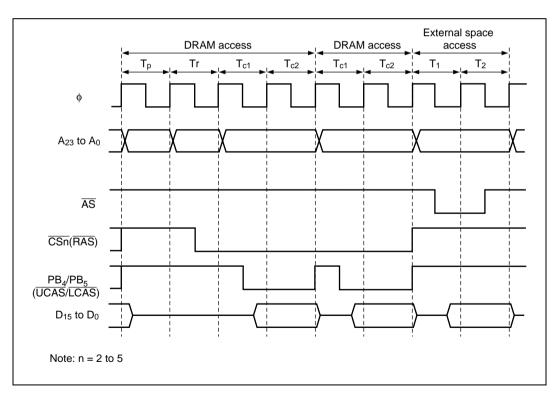


Figure 6.25 Example of Operation Timing in RAS Up Mode

6.5.11 Refresh Control

The H8/3067 Group is provided with a CAS-before-RAS (CBR) function and self-refresh function as DRAM refresh control functions.

CAS-Before-RAS (**CBR**) **Refreshing:** To select CBR refreshing, set the RCYCE bit to 1 in DRCRB.

With CBR refreshing, RTCNT counts up using the input clock selected by bits CKS2 to CKS0 in RTMCSR, and a refresh request is generated when the count matches the value set in RTCOR (compare match). At the same time, RTCNT is reset and starts counting up again from H'00. Refreshing is thus repeated at fixed intervals determined by RTCOR and bits CKS2 to CKS0. A refresh cycle is executed after this refresh request has been accepted and the DRAM interface has acquired the bus. Set a value in bits CKS2 to CKS0 in RTCOR that will meet the refresh interval specification for the DRAM used. When RAS down mode is used, set the refresh interval so that the maximum \overline{RAS} pulse width specification is met.

RTCNT starts counting up when bits CKS2 to CKS0 are set. RTCNT and RTCOR settings should therefore be completed before setting bits CKS2 to CKS0.

Also note that a repeat refresh request generated during a bus request, or a refresh request during refresh cycle execution, will be ignored.

RTCNT operation is shown in figure 6.26, compare match timing in figure 6.27, and CBR refresh timing in figures 6.28 and 6.29.

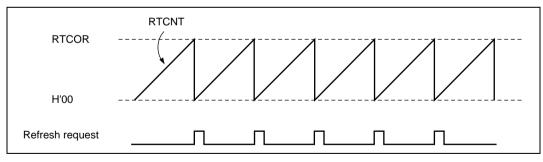


Figure 6.26 RTCNT Operation

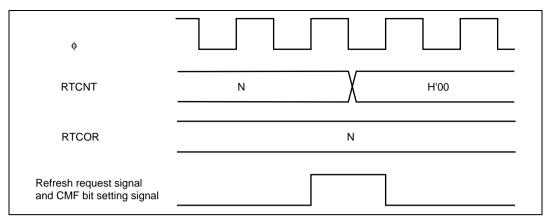


Figure 6.27 Compare Match Timing

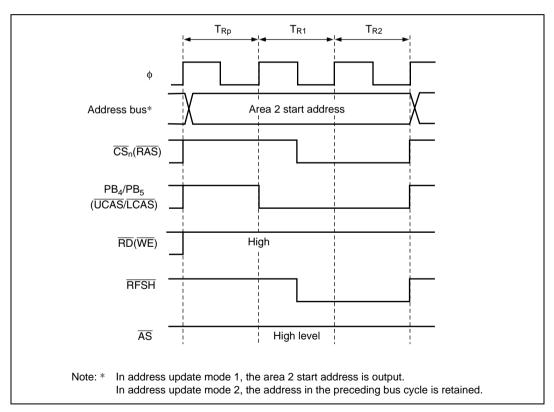


Figure 6.28 CBR Refresh Timing (CSEL = 0, TPC = 0, RLW = 0)

The basic CBS refresh cycle timing comprises three states: one RAS precharge cycle (T_{RP}) state, and two RAS output cycle (T_{R1} , T_{R2}) states. Either one or two states can be selected for the RAS precharge cycle. When the TPC bit is set to 1 in DRCRB, \overline{RAS} signal output is delayed by one cycle. This does not affect the timing of \overline{UCAS} and \overline{LCAS} output.

Use the RLW bit in DRCRB to adjust the \overline{RAS} signal width. A single refresh wait state (T_{RW}) can be inserted between the T_{R1} state and T_{R2} state by setting the RLW bit to 1.

The RLW bit setting is valid only for CBR refresh cycles, and does not affect DRAM read/write cycles. The number of states in the CBR refresh cycle is not affected by the settings in ASTCR, WCRH, or WCRL, or by the state of the WAIT pin.

Figure 6.29 shows the timing when the TPC bit and RLW bit are both set to 1.

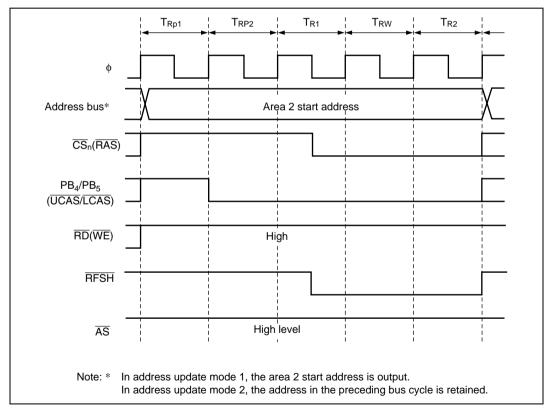


Figure 6.29 CBR Refresh Timing (CSEL = 0, TPC = 1, RLW = 1)

DRAM must be refreshed immediately after powering on in order to stabilize its internal state. When using the H8/3067 Group CAS-before-RAS refresh function, therefore, a DRAM stabilization period should be provided by means of interrupts by another timer module, or by counting the number of times bit 7 (CMF) of RTMCSR is set, for instance, immediately after bits DRAS2 to DRAS0 have been set in DRCRA.

Self-Refreshing: A self-refresh mode (battery backup mode) is provided for DRAM as a kind of standby mode. In this mode, refresh timing and refresh addresses are generated within the DRAM. The H8/3067 Group has a function that places the DRAM in self-refresh mode when the chip enters software standby mode.

To use the self-refresh function, set the SRFMD bit to 1 in DRCRA. When a SLEEP instruction is subsequently executed in order to enter software standby mode, the $\overline{\text{CAS}}$ and $\overline{\text{RAS}}$ signals are output and the DRAM enters self-refresh mode, as shown in figure 6.30.

When the chip exits software standby mode, \overline{CAS} and \overline{RAS} outputs go high.

The following conditions must be observed when the self-refresh function is used:

- When burst access is selected, RAS up mode must be selected before executing a SLEEP
 instruction in order to enter software standby mode. Therefore, if RAS down mode has been
 selected, the RDM bit in DRCRA must be cleared to 0 and RAS up mode selected before
 executing the SLEEP instruction. Select RAS down mode again after exiting software standby
 mode.
- The instruction immediately following a SLEEP instruction must not be located in an area designated as DRAM space.

The self-refresh function will not work properly unless the above conditions are observed.

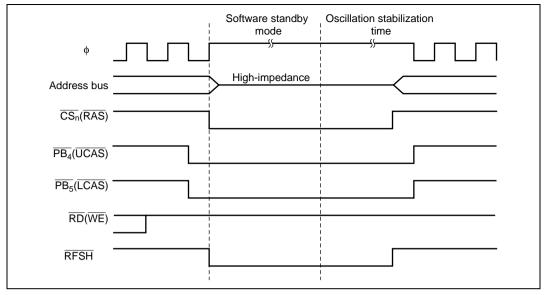


Figure 6.30 Self-Refresh Timing (CSEL = 0)

Refresh Signal ($\overline{\text{RFSH}}$): A refresh signal ($\overline{\text{RFSH}}$) that transmits a refresh cycle off-chip can be output by setting the RFSHE bit to 1 in DRCRA. $\overline{\text{RFSH}}$ output timing is shown in figures 6.28, 6.29, and 6.30.

6.5.12 Examples of Use

Examples of DRAM connection and program setup procedures are shown below. When the DRAM interface is used, check the DRAM device characteristics and choose the most appropriate method of use for that device.

Connection Examples

• Figure 6.31 shows typical interconnections when using two 2-CAS type 16-Mbit DRAMs using a × 16-bit organization, and the corresponding address map. The DRAMs used in this example are of the 10-bit row address × 10-bit column address type. Up to four DRAMs can be connected by designating areas 2 to 5 as DRAM space.



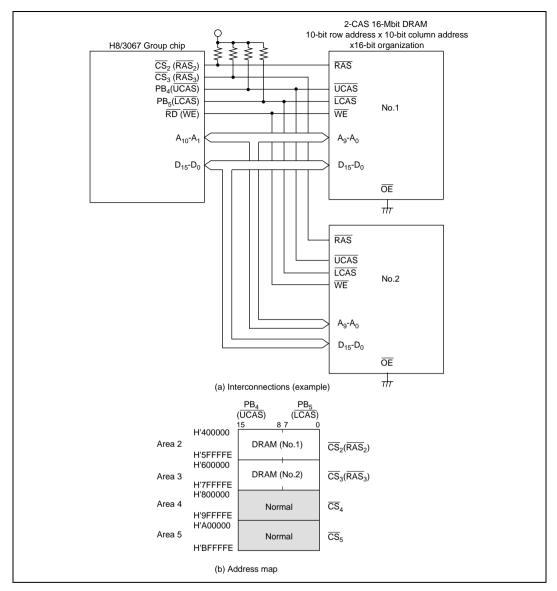


Figure 6.31 Interconnections and Address Map for 2-CAS 16-Mbit DRAMs with \times 16-Bit Organization

Figure 6.32 shows typical interconnections when using two 16-Mbit DRAMs using a \times 8-bit organization, and the corresponding address map. The DRAMs used in this example are of the 11-bit row address \times 10-bit column address type. The \overline{CS}_2 pin is used as the common \overline{RAS} output pin for areas 2 and 3. When the \overline{DRAM} address space spans a number of contiguous areas, as in this example, the appropriate setting of bits DRAS2 to DRAS0 enables a single \overline{CS} pin to be used as the common \overline{RAS} output pin for a number of areas, and makes it possible to directly connect large-capacity DRAM with address space that spans a maximum of four areas. Any unused \overline{CS} pins (in this example, the \overline{CS}_3 pin) can be used as input/output ports.

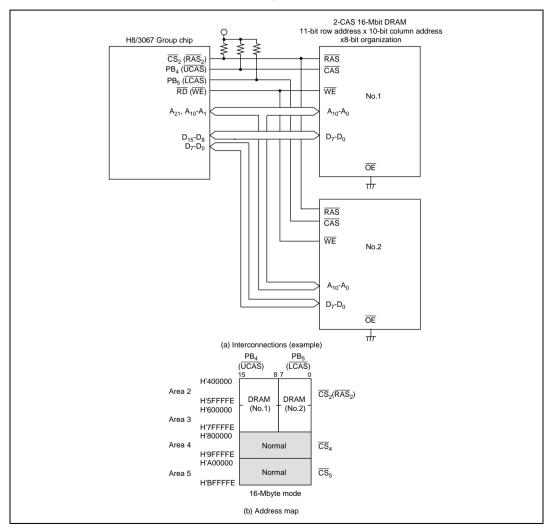


Figure 6.32 Interconnections and Address Map for 16-Mbit DRAMs with \times 8-Bit Organization

• Figure 6.33 shows typical interconnections when using two 4-Mbit DRAMs, and the corresponding address map. The DRAMs used in this example are of the 9-bit row address × 10-bit column address type. In this example, upper address decoding allows multiple DRAMs to be connected to a single area. The RFSH pin is used in this case, since both DRAMs must be refreshed simultaneously. However, note that RAS down mode cannot be used in this interconnection example.

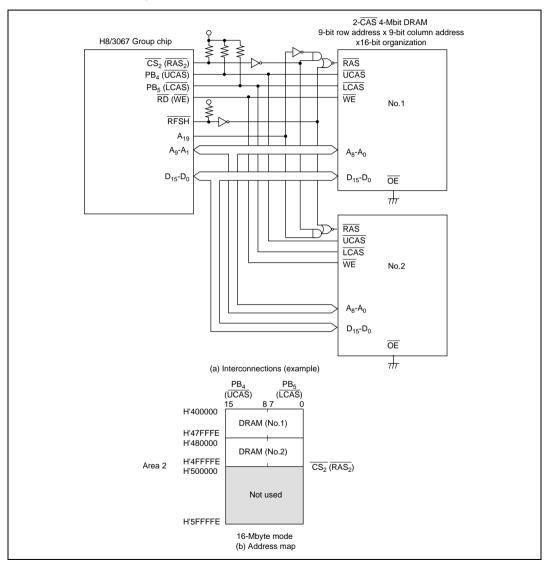


Figure 6.33 Interconnections and Address Map for 2-CAS 4-Mbit DRAMs with \times 16-Bit Organization

Example of Program Setup Procedure: Figure 6.34 shows an example of the program setup procedure.

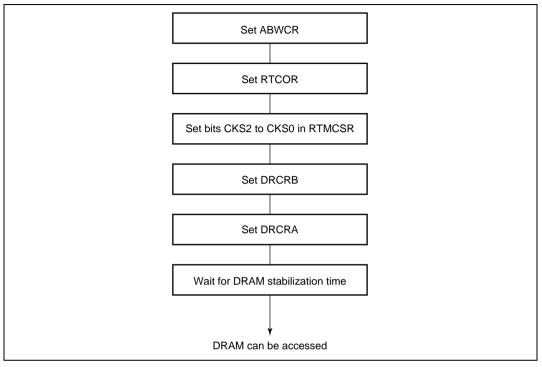


Figure 6.34 Example of Setup Procedure when Using DRAM Interface

6.5.13 Usage Notes

Note the following points when using the DRAM refresh function.

- Refresh cycles will not be executed when the external bus released state, software standby
 mode, or a bus cycle is extended by means of wait state insertion. Refreshing must therefore be
 performed by other means in these cases.
- If a refresh request is generated internally while the external bus is released, the first request is retained and a single refresh cycle will be executed after the bus-released state is cleared. Figure 6.35 shows the bus cycle in this case.
- When a bus cycle is extended by means of wait state insertion, the first request is retained in the same way as when the external bus has been released.



- In the event of contention with a bus request from an external bus master when a transition is made to software standby mode, the BACK and strobe states may be indeterminate after the transition to software standby mode (see figure 6.36).
 - When software standby mode is used, the BRLE bit should be cleared to 0 in BRCR before executing the SLEEP instruction.
 - Similar contention in a transition to self-refresh mode may prevent dependable strobe waveform output. This can also be avoided by clearing the BRLW bit to 0 in BRCR.
- Immediately after self-refreshing is cleared, external bus release is possible during a given period until the start of a CPU cycle. Attention must be paid to the \overline{RAS} state to ensure that the specification for the \overline{RAS} precharge time immediately after self-refreshing is met.

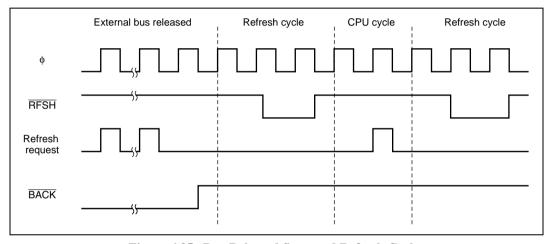


Figure 6.35 Bus-Released State and Refresh Cycles

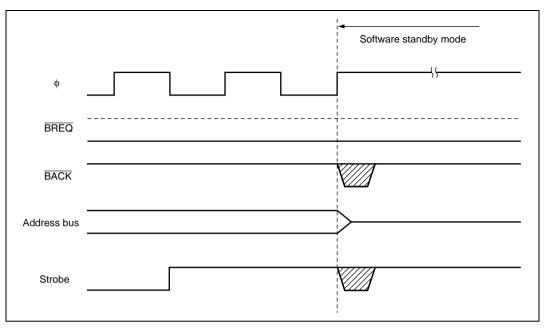


Figure 6.36 Bus-Released State and Software Standby Mode

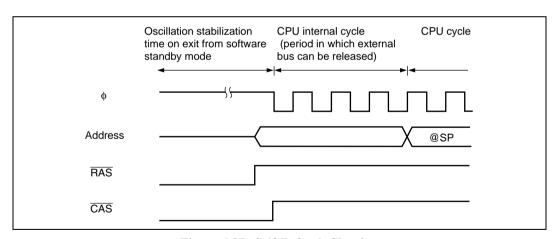


Figure 6.37 Self-Refresh Clearing

6.6 Interval Timer

6.6.1 Operation

When DRAM is not connected to the H8/3067 Group chip, the refresh timer can be used as an interval timer by clearing bits DRAS2 to DRAS0 in DRCRA to 0. After setting RTCOR, selection a clock source with bits CKS2 to CKS0 in RTMCSR, and set the CMIE bit to 1.

Timing of Setting of Compare Match Flag and Clearing by Compare Match: The CMF flag in RTMCSR is set to 1 by a compare match output when the RTCOR and RTCNT values match. The compare match signal is generated in the last state in which the values match (when RTCNT is updated from the matching value to a new value). Accordingly, when RTCNT and RTCOR match, the compare match signal is not generated until the next counter clock pulse. Figure 6.38 shows the timing.

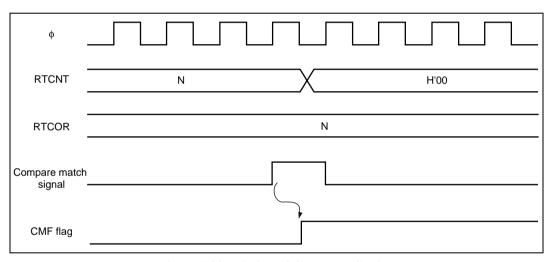


Figure 6.38 Timing of CMF Flag Setting

Operation in Power-Down State: The interval timer operates in sleep mode. It does not operate in hardware standby mode. In software standby mode, RTCNT and RTMCSR bits 7 and 6 are initialized, but RTMCSR bits 5 to 3 and RTCOR retain their settings prior to the transition to software standby mode.

Contention between RTCNT Write and Counter Clear: If a counter clear signal occurs in the T₃ state of an RTCNT write cycle, clearing of the counter takes priority and the write is not performed. See Figure 6.39.

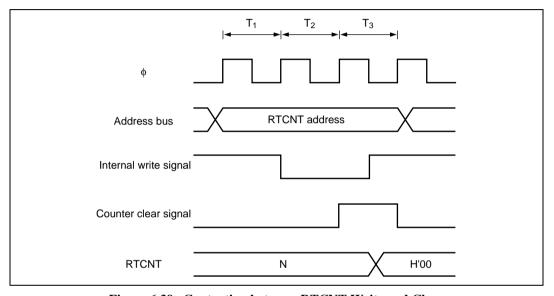


Figure 6.39 Contention between RTCNT Write and Clear

Contention between RTCNT Write and Increment: If an increment pulse occurs in the T₃ state of an RTCNT write cycle, writing takes priority and RTCNT is not incremented. See Figure 6.40.

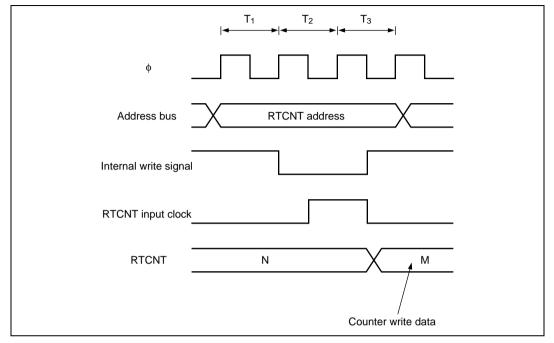


Figure 6.40 Contention between RTCNT Write and Increment

Contention between RTCOR Write and Compare Match: If a compare match occurs in the T₃ state of an RTCOR write cycle, writing takes priority and the compare match signal is inhibited. See Figure 6.41.

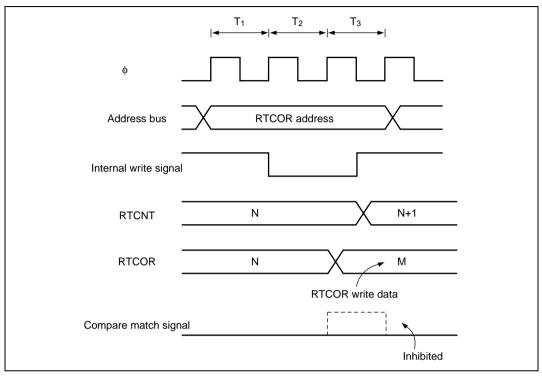
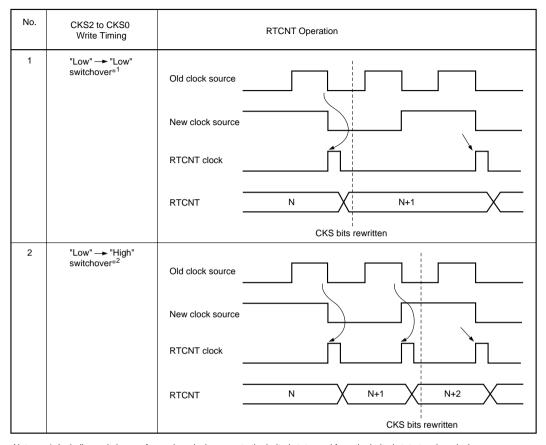


Figure 6.41 Contention between RTCOR Write and Compare Match

RTCNT Operation at Internal Clock Source Switchover: Switching internal clock sources may cause RTCNT to increment, depending on the switchover timing. Table 6.10 shows the relation between the time of the switchover (by writing to bits CKS2 to CKS0) and the operation of RTCNT.

The RTCNT input clock is generated from the internal clock source by detecting the falling edge of the internal clock. If a switchover is made from a high clock source to a low clock source, as in case No. 3 in table 6.10, the switchover will be regarded as a falling edge, an RTCNT clock pulse will be generated, and RTCNT will be incremented.

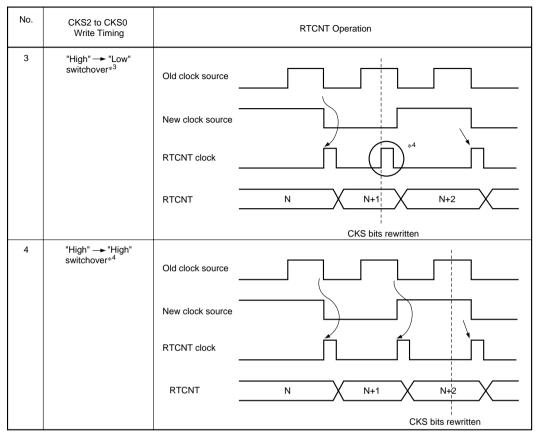
Table 6.10 Internal Clock Switchover and RTCNT Operation (1)



Notes: 1. Including switchovers from a low clock source to the halted state, and from the halted state to a low clock source.

^{2.} Including switchover from the halted state to a high clock source.

Table 6.10 Internal Clock Switchover and RTCNT Operation (2)



Notes: 3. Including switchover from a high clock source to the halted state.

4. The switchover is regarded as a falling edge, causing RTCNT to increment.

6.7 Interrupt Sources

Compare match interrupts (CMI) can be generated when the refresh timer is used as an interval timer. Compare match interrupt requests are masked/unmasked with the CMIE bit in RTMCSR.

6.8 Burst ROM Interface

6.8.1 Overview

With the H8/3067 Group, external space area 0 can be designated as burst ROM space, and burst ROM space interfacing can be performed. The burst ROM space interface enables 16-bit organization ROM with burst access capability to be accessed at high speed. Area 0 is designated as burst ROM space by means of the BROME bit in BCR.

Continuous burst access of a maximum or four or eight words can be performed on external space area 0. Two or three states can be selected for burst access.

6.8.2 Basic Timing

The number of states in the initial cycle (full access) and a burst cycle of the burst ROM interface is determined by the setting of the AST0 bit in ASTCR. When the AST0 bit is set to 1, wait states can also be inserted in the initial cycle. Wait states cannot be inserted in a burst cycle.

Burst access of up to four words is performed when the BRSTS0 bit is cleared to 0 in BCR, and burst access of up to eight words when the BRSTS0 bit is set to 1. The number of burst access states is two when the BRSTS1 bit is cleared to 0, and three when the BRSTS1 bit is set to 1.

The basic access timing for burst ROM space is shown in figure 6.42.

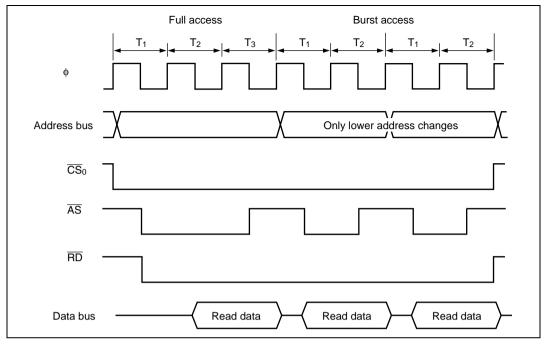


Figure 6.42 Example of Burst ROM Access Timing

6.8.3 Wait Control

As with the basic bus interface, either program wait insertion or pin wait insertion using the \overline{WAIT} pin can be used in the initial cycle (full access) of the burst ROM interface.

Wait states cannot be inserted in a burst cycle.

6.9 Idle Cycle

6.9.1 Operation

When the H8/3067 Group chip accesses external space, it can insert a 1-state idle cycle (T₁) between bus cycles in the following cases: (1) when read accesses between different areas occur consecutively, (2) when a write cycle occurs immediately after a read cycle, and (3) immediately after a DRAM space access. By inserting an idle cycle it is possible, for example, to avoid data collisions between ROM, which has a long output floating time, and high-speed memory, I/O interfaces, and so on.

The ICIS1 and ICIS0 bits in BCR both have an initial value of 1, so that an idle cycle is inserted in the initial state. If there are no data collisions, the ICIS bits can be cleared.

Consecutive Reads between Different Areas: If consecutive reads between different areas occur while the ICIS1 bit is set to 1 in BCR, an idle cycle is inserted at the start of the second read cycle.

Figure 6.43 shows an example of the operation in this case. In this example, bus cycle A is a read cycle from ROM with a long output floating time, and bus cycle B is a read cycle from SRAM, each being located in a different area. In (a), an idle cycle is not inserted, and a collision occurs in cycle B between the read data from ROM and that from SRAM. In (b), an idle cycle is inserted, and a data collision is prevented.

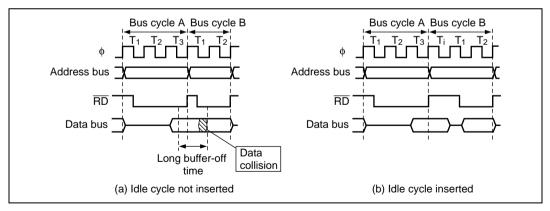


Figure 6.43 Example of Idle Cycle Operation (1) (ICIS1 = 1)

Write after Read: If an external write occurs after an external read while the ICISO bit is set to 1 in BCR, an idle cycle is inserted at the start of the write cycle.

Figure 6.44 shows an example of the operation in this case. In this example, bus cycle A is a read cycle from ROM with a long output floating time, and bus cycle B is a CPU write cycle.

In (a), an idle cycle is not inserted, and a collision occurs in cycle B between the read data from ROM and the CPU write data. In (b), an idle cycle is inserted, and a data collision is prevented.

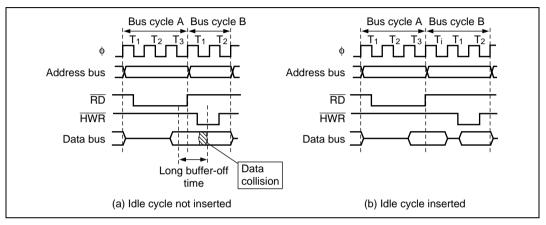


Figure 6.44 Example of Idle Cycle Operation (2) (ICIS0 = 1)

External Address Space Access Immediately after DRAM Space Access: If a DRAM space access is followed by a non-DRAM external access when \overline{HWR} and \overline{LWR} have been selected as the \overline{UCAS} and \overline{LCAS} output pins by means of the CSEL bit in DRCRB, a Ti cycle is inserted regardless of the settings of bits ICIS0 and ICIS1 in BCR. Figure 6.45 shows an example of the operation.

This is done to prevent simultaneous changing of the \overline{HWR} and \overline{LWR} signals used as \overline{UCAS} and \overline{LCAS} in DRAM space and \overline{CS} n for the space in the next cycle, and so avoid an erroneous write to the external device in the next cycle.

A T_i cycle is not inserted when PB4 and PB5 have been selected as the \overline{UCAS} and \overline{LCAS} output pins.

In the case of consecutive DRAM space access precharge cycles (T_p), the ICIS0 and ICIS1 bit settings are invalid. In the case of consecutive reads between different areas, for example, if the second access is a DRAM access, only a T_p cycle is inserted, and a T_i cycle is not. The timing in this case is shown in figure 6.46.



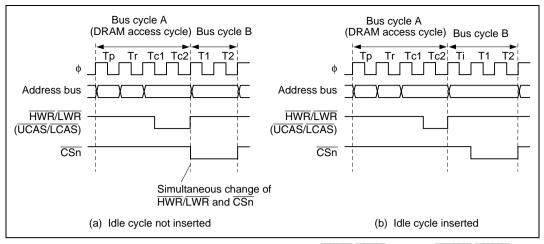


Figure 6.45 Example of Idle Cycle Operation (3) (HWR/LWR Used as UCAS/LCAS)

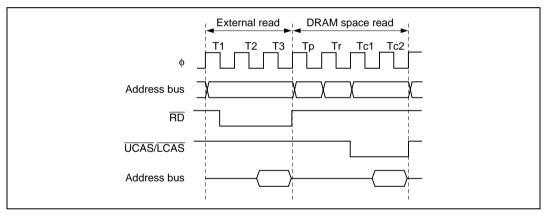


Figure 6.46 Example of Idle Cycle Operation (4) (Consecutive Precharge Cycles)

Usage Notes: When non-insertion of idle cycles is set, the rise (negation) of RD and the fall (assertion) of $\overline{\text{CSn}}$ may occur simultaneously. An example of the operation is shown in figure 6.47.

If consecutive reads between different external areas occur while the ICIS1 bit is cleared to 0 in BCR, or if a write cycle to a different external area occurs after an external read while the ICIS0 bit is cleared to 0, the \overline{RD} negation in the first read cycle and the \overline{CSn} assertion in the following bus cycle will occur simultaneously. Therefore, depending on the output delay time of each signal, it is possible that the low-level output of \overline{RD} in the preceding read cycle and the low-level output of \overline{CSn} in the following bus cycle will overlap.

A setting whereby idle cycle insertion is not performed can be made only when \overline{RD} and \overline{CSn} do not change simultaneously, or when it does not matter if they do.

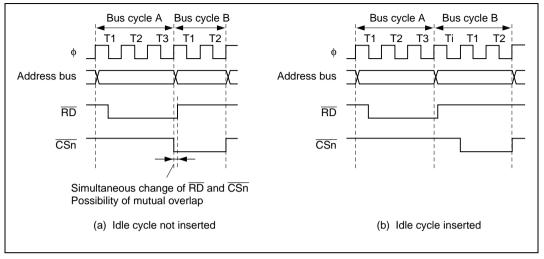


Figure 6.47 Example of Idle Cycle Operation (5)

6.9.2 Pin States in Idle Cycle

Table 6.11 shows the pin states in an idle cycle.

Table 6.11 Pin States in Idle Cycle

Pins	Pin State
$\overline{A_{23}}$ to A_{0}	Next cycle address value
$\frac{A_{23} \text{ to } A_0}{D_{15} \text{ to } D_0}$	High impedance
CS n	High*
UCAS, LCAS	High
ĀS	High
RD	High
HWR	High
<u>LWR</u>	High

Note: * Remains low in DRAM space RAS down mode.

6.10 Bus Arbiter

The bus controller has a built-in bus arbiter that arbitrates between different bus masters. There are four bus masters: the CPU, DMA controller (DMAC), DRAM interface, and an external bus master. When a bus master has the bus right it can carry out read, write, or refresh access. Each bus master uses a bus request signal to request the bus right. At fixed times the bus arbiter determines priority and uses a bus acknowledge signal to grant the bus to a bus master, which can the operate using the bus.

The bus arbiter checks whether the bus request signal from a bus master is active or inactive, and returns an acknowledge signal to the bus master. When two or more bus masters request the bus, the highest-priority bus master receives an acknowledge signal. The bus master that receives an acknowledge signal can continue to use the bus until the acknowledge signal is deactivated.

The bus master priority order is:

The bus arbiter samples the bus request signals and determines priority at all times, but it does not always grant the bus immediately, even when it receives a bus request from a bus master with higher priority than the current bus master. Each bus master has certain times at which it can release the bus to a higher-priority bus master.

6.10.1 Operation

CPU: The CPU is the lowest-priority bus master. If the DMAC, DRAM interface, or an external bus master requests the bus while the CPU has the bus right, the bus arbiter transfers the bus right to the bus master that requested it. The bus right is transferred at the following times:

- The bus right is transferred at the boundary of a bus cycle. If word data is accessed by two
 consecutive byte accesses, however, the bus right is not transferred between the two byte
 accesses.
- If another bus master requests the bus while the CPU is performing internal operations, such as
 executing a multiply or divide instruction, the bus right is transferred immediately. The CPU
 continues its internal operations.
- If another bus master requests the bus while the CPU is in sleep mode, the bus right is transferred immediately.

DMAC: When the DMAC receives an activation request, it requests the bus right from the bus arbiter. If the DMAC is bus master and the DRAM interface or an external bus master requests the bus, the bus arbiter transfers the bus right from the DMAC to the bus master that requested the bus. The bus right is transferred at the following times.

The bus right is transferred when the DMAC finishes transferring one byte or one word. A DMAC transfer cycle consists of a read cycle and a write cycle. The bus right is not transferred between the read cycle and the write cycle.

There is a priority order among the DMAC channels. For details see section 7.4.9, Multiple-Channel Operation.

DRAM Interface: The DRAM interface requests the bus right from the bus arbiter when a refresh cycle request is issued, and releases the bus at the end of the refresh cycle. For details see section 6.5, DRAM Interface.

External Bus Master: When the BRLE bit is set to 1 in BRCR, the bus can be released to an external bus master. The external bus master has highest priority, and requests the bus right from the bus arbiter y driving the \overline{BREQ} signal low. Once the external bus master acquires the bus, it keeps the bus until the \overline{BREQ} signal goes high. While the bus is released to an external bus master, the H8/3067 Group chip holds the address bus, data bus, bus control signals (\overline{AS} , \overline{RD} , \overline{HWR} , and \overline{LWR}), and chip select signals (\overline{CS} n: n = 7 to 0) in the high-impedance state, and holds the \overline{BACK} pin in the low output state.

The bus arbiter samples the \overline{BREQ} pin at the rise of the system clock (ϕ). If \overline{BREQ} is low, the bus is released to the external bus master at the appropriate opportunity. The \overline{BREQ} signal should be held low until the \overline{BACK} signal goes low.

When the \overline{BREQ} pin is high in two consecutive samples, the \overline{BACK} pin is driven high to end the bus-release cycle.

Figure 6.48 shows the timing when the bus right is requested by an external bus master during a read cycle in a two-state access area. There is a minimum interval of three states from when the \overline{BREQ} signal goes low until the bus is released.



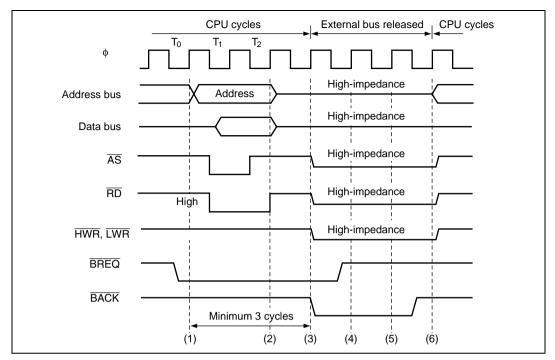


Figure 6.48 Example of External Bus Master Operation

In the event of contention with a bus request from an external bus master when a transition is made to software standby mode, the \overline{BACK} and strobe states may be indeterminate after the transition to software standby mode (see figure 6.36).

When software standby mode is used, the BRLE bit should be cleared to 0 in BRCR before executing the SLEEP instruction.

6.11 Register and Pin Input Timing

6.11.1 Register Write Timing

ABWCR, ASTCR, WCRH, and WCRL Write Timing: Data written to ABWCR, ASTCR, WCRH, and WCRL takes effect starting from the next bus cycle. Figure 6.49 shows the timing when an instruction fetched from area 0 changes area 0 from three-state access to two-state access.

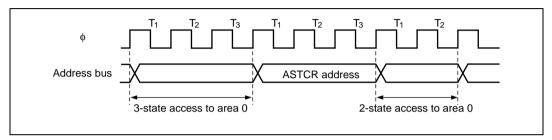


Figure 6.49 ASTCR Write Timing

DDR and **CSCR** Write Timing: Data written to DDR or CSCR for the port corresponding to the \overline{CS} n pin to switch between \overline{CS} n output and generic input takes effect starting from the T_3 state of the DDR write cycle. Figure 6.50 shows the timing when the \overline{CS}_1 pin is changed from generic input to \overline{CS}_1 output.

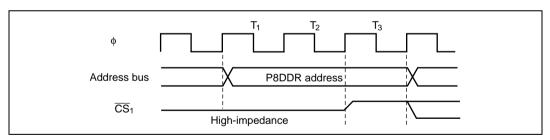


Figure 6.50 DDR Write Timing

BRCR Write Timing: Data written to BRCR to switch between A_{23} , A_{22} , A_{21} , or A_{20} output and generic input or output takes effect starting from the T₃ state of the BRCR write cycle. Figure 6.51 shows the timing when a pin is changed from generic input to A_{23} , A_{22} , A_{21} , or A_{20} output.

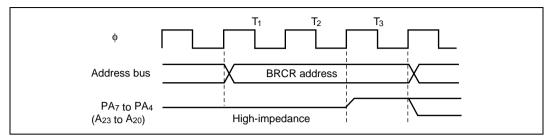


Figure 6.51 BRCR Write Timing

BREO Pin Input Timing 6.11.2

After driving the BREQ pin low, hold it low until BACK goes low. If BREQ returns to the high level before BACK goes lows, the bus arbiter may operate incorrectly.

To terminate the external-bus-released state, hold the BREQ signal high for at least three states. If BREQ is high for too short an interval, the bus arbiter may operate incorrectly.

Section 7 DMA Controller

7.1 Overview

The H8/3067 Group has an on-chip DMA controller (DMAC) that can transfer data on up to four channels.

When the DMA controller is not used, it can be independently halted to conserve power. For details see section 20.6, Module Standby Function.

7.1.1 Features

DMAC features are listed below.

- Selection of short address mode or full address mode
 - Short address mode
 - 8-bit source address and 24-bit destination address, or vice versa
 - Maximum four channels available
 - Selection of I/O mode, idle mode, or repeat mode

Full address mode

- 24-bit source and destination addresses
- Maximum two channels available
- Selection of normal mode or block transfer mode
- Directly addressable 16-Mbyte address space
- Selection of byte or word transfer
- Activation by internal interrupts, external requests, or auto-request (depending on transfer mode)
 - 16-bit timer compare match/input capture interrupts (×3)
 - Serial communication interface (SCI channel 0) transmit-data-empty/receive-data-full interrupts
 - External requests
 - Auto-request
 - A/D converter conversion-end interrupt

7.1.2 Block Diagram

Figure 7.1 shows a DMAC block diagram.

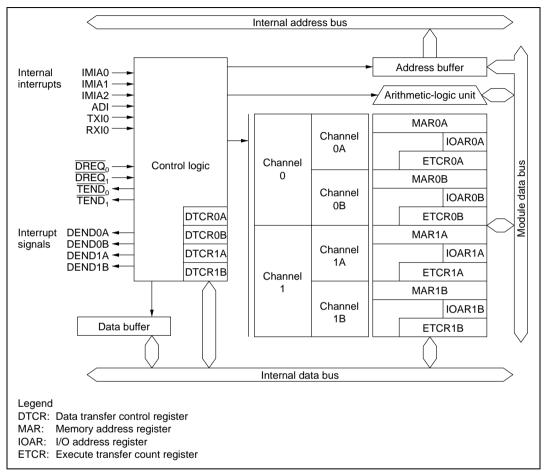


Figure 7.1 Block Diagram of DMAC

7.1.3 Functional Overview

Table 7.1 gives an overview of the DMAC functions.

Table 7.1 DMAC Functional Overview

			Address	Reg. Length		
Transfer	Mode	Activation	Source	Destination		
Short address mode	 I/O mode Transfers one byte or one word per request Increments or decrements the memory address by 1 or 2 Executes 1 to 65,536 transfers 	 Transfers one byte or one word per request Increments or decrements the memory address by 1 or 2 Transmit-data-empty interrupt from SCI channel 				
	 Transfers one byte or one word per request Holds the memory address fixed 	Conversion-end interrupt from A/D converter Receive-data-full interrupt from SCI channel 0	8	24		
	 Executes 1 to 65,536 transfers Repeat mode Transfers one byte or one word per request Increments or decrements the memory address by 1 or 2 Executes a specified number (1 to 255) of transfers, then returns to the initial state and continues 	External request	24	8		
Full address mode	Normal mode Auto-request Retains the transfer request internally Executes a specified number(1 to 65,536) of transfers continuously Selection of burst mode or cyclesteal mode External request Transfers one byte or one word per request Executes 1 to 65,536 transfers	Auto-request External request	24	24		
	Block transfer Transfers one block of a specified size per request Executes 1 to 65,536 transfers Allows either the source or destination to be a fixed block area Block size can be 1 to 255 bytes or words	 Compare match/ input capture A interrupts from 16-bit timer channels 0 to 2 External request Conversion-end interrupt from A/D converter 	24	24		

7.1.4 Input/Output Pins

Table 7.2 lists the DMAC pins.

Table 7.2 DMAC Pins

Channel	Name	Abbrevia- tion	Input/ Output	Function
0	DMA request 0	DREQ _₀	Input	External request for DMAC channel 0
	Transfer end 0	TEND ₀	Output	Transfer end on DMAC channel 0
1	DMA request 1	DREQ,	Input	External request for DMAC channel 1
	Transfer end 1	TEND,	Output	Transfer end on DMAC channel 1

Note: External requests cannot be made to channel A in short address mode.

7.1.5 Register Configuration

Table 7.3 lists the DMAC registers.

Table 7.3 DMAC Registers

Channel	Address*	Name	Abbreviation	R/W	Initial Value
0	H'FFF20	Memory address register 0AR	MAR0AR	R/W	Undetermined
	H'FFF21	Memory address register 0AE	MAR0AE	R/W	Undetermined
	H'FFF22	Memory address register 0AH	MAR0AH	R/W	Undetermined
	H'FFF23	Memory address register 0AL	MAR0AL	R/W	Undetermined
	H'FFF26	I/O address register 0A	IOAR0A	R/W	Undetermined
	H'FFF24	Execute transfer count register 0AH	ETCR0AH	R/W	Undetermined
	H'FFF25	Execute transfer count register 0AL	ETCR0AL	R/W	Undetermined
	H'FFF27	Data transfer control register 0A	DTCR0A	R/W	H'00
	H'FFF28	Memory address register 0BR	MAR0BR	R/W	Undetermined
	H'FFF29	Memory address register 0BE	MAR0BE	R/W	Undetermined
	H'FFF2A	Memory address register 0BH	MAR0BH	R/W	Undetermined
	H'FFF2B	Memory address register 0BL	MAR0BL	R/W	Undetermined
	H'FFF2E	I/O address register 0B	IOAR0B	R/W	Undetermined
	H'FFF2C	Execute transfer count register 0BH	ETCR0BH	R/W	Undetermined
	H'FFF2D	Execute transfer count register 0BL	ETCR0BL	R/W	Undetermined
	H'FFF2F	Data transfer control register 0B	DTCR0B	R/W	H'00
1	H'FFF30	Memory address register 1AR	MAR1AR	R/W	Undetermined
	H'FFF31	Memory address register 1AE	MAR1AE	R/W	Undetermined
	H'FFF32	Memory address register 1AH	MAR1AH	R/W	Undetermined
	H'FFF33	Memory address register 1AL	MAR1AL	R/W	Undetermined
	H'FFF36	I/O address register 1A	IOAR1A	R/W	Undetermined
	H'FFF34	Execute transfer count register 1AH	ETCR1AH	R/W	Undetermined
	H'FFF35	Execute transfer count register 1AL	ETCR1AL	R/W	Undetermined
	H'FFF37	Data transfer control register 1A	DTCR1A	R/W	H'00
	H'FFF38	Memory address register 1BR	MAR1BR	R/W	Undetermined
	H'FFF39	Memory address register 1BE	MAR1BE	R/W	Undetermined
	H'FFF3A	Memory address register 1BH	MAR1BH	R/W	Undetermined
	H'FFF3B	Memory address register 1BL	MAR1BL	R/W	Undetermined
	H'FFF3E	I/O address register 1B	IOAR1B	R/W	Undetermined
	H'FFF3C	Execute transfer count register 1BH	ETCR1BH	R/W	Undetermined
	H'FFF3D	Execute transfer count register 1BL	ETCR1BL	R/W	Undetermined
	H'FFF3F	Data transfer control register 1B	DTCR1B	R/W	H'00

Note: *The lower 20 bits of the address are indicated.

7.2 Register Descriptions (1) (Short Address Mode)

In short address mode, transfers can be carried out independently on channels A and B. Short address mode is selected by bits DTS2A and DTS1A in data transfer control register A (DTCRA) as indicated in table 7.4.

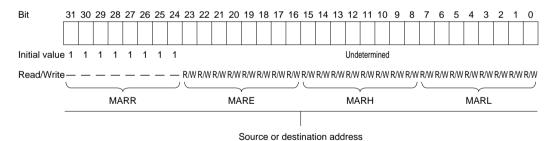
Table 7.4 Selection of Short and Full Address Modes

Channel	Bit 2 DTS2A	Bit 1 DTS1A	Description
0	1	1	DMAC channel 0 operates as one channel in full address mode
	Other than	above	DMAC channels 0A and 0B operate as two independent channels in short address mode
1	1	1	DMAC channel 1 operates as one channel in full address mode
	Other than	above	DMAC channels 1A and 1B operate as two independent channels in short address mode

7.2.1 Memory Address Registers (MAR)

A memory address register (MAR) is a 32-bit readable/writable register that specifies a source or destination address. The transfer direction is determined automatically from the activation source.

An MAR consists of four 8-bit registers designated MARR, MARE, MARH, and MARL. All bits of MARR are reserved; they cannot be modified and are always read as 1.



An MAR functions as a source or destination address register depending on how the DMAC is activated: as a destination address register if activation is by a receive-data-full interrupt from serial communication interface (SCI) channel 0 or by an A/D converter conversion-end interrupt, and as a source address register otherwise.

The MAR value is incremented or decremented each time one byte or word is transferred, automatically updating the source or destination memory address. For details, see section 7.3.4, Data Transfer Control Registers (DTCR).

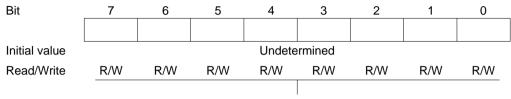
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RENESAS

The MARs are not initialized by a reset or in standby mode.

7.2.2 I/O Address Registers (IOAR)

An I/O address register (IOAR) is an 8-bit readable/writable register that specifies a source or destination address. The IOAR value is the lower 8 bits of the address. The upper 16 address bits are all 1 (H'FFFF).



Source or destination address

An IOAR functions as a source or destination address register depending on how the DMAC is activated: as a source address register if activation is by a receive-data-full interrupt from serial communication interface (SCI) channel 0 or by an A/D converter conversion-end interrupt, and as a destination address register otherwise.

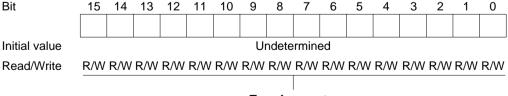
The IOAR value is held fixed. It is not incremented or decremented when a transfer is executed.

The IOARs are not initialized by a reset or in standby mode.

7.2.3 Execute Transfer Count Registers (ETCR)

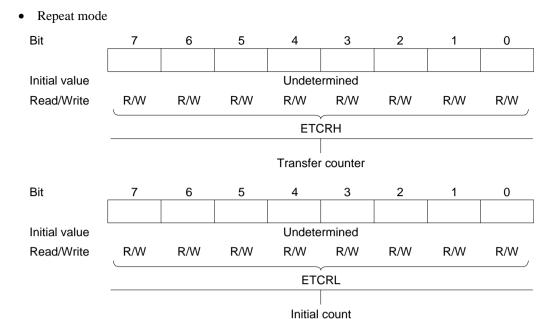
An execute transfer count register (ETCR) is a 16-bit readable/writable register that specifies the number of transfers to be executed. These registers function in one way in I/O mode and idle mode, and another way in repeat mode.

I/O mode and idle mode



Transfer counter

In I/O mode and idle mode, ETCR functions as a 16-bit counter. The count is decremented by 1 each time one transfer is executed. The transfer ends when the count reaches H'0000.

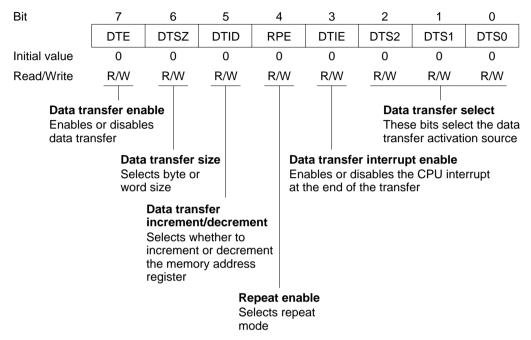


In repeat mode, ETCRH functions as an 8-bit transfer counter and ETCRL holds the initial transfer count. ETCRH is decremented by 1 each time one transfer is executed. When ETCRH reaches H'00, the value in ETCRL is reloaded into ETCRH and the same operation is repeated.

The ETCRs are not initialized by a reset or in standby mode.

7.2.4 Data Transfer Control Registers (DTCR)

A data transfer control register (DTCR) is an 8-bit readable/writable register that controls the operation of one DMAC channel.



The DTCRs are initialized to H'00 by a reset and in standby mode.

Bit 7—Data Transfer Enable (DTE): Enables or disables data transfer on a channel. When the DTE bit is set to 1, the channel waits for a transfer to be requested, and executes the transfer when activated as specified by bits DTS2 to DTS0. When DTE is 0, the channel is disabled and does not accept transfer requests. DTE is set to 1 by reading the register when DTE is 0, then writing 1.

Bit 7 DTE	Description	
0	Data transfer is disabled. In I/O mode or idle mode, DTE is cleared to 0 when the specified number of transfers have been completed	(Initial value)
1	Data transfer is enabled	

If DTIE is set to 1, a CPU interrupt is requested when DTIE is cleared to 0.

Bit 6—Data Transfer Size (DTSZ): Selects the data size of each transfer.

Bit 6 DTSZ	Description	
0	Byte-size transfer	(Initial value)
1	Word-size transfer	

Bit 5—Data Transfer Increment/Decrement (DTID): Selects whether to increment or decrement the memory address register (MAR) after a data transfer in I/O mode or repeat mode.

Bit 5 DTID	Description	
0	MAR is incremented after each data transfer	(Initial value)
	• If DTSZ = 0, MAR is incremented by 1 after each transfer	
	 If DTSZ = 1, MAR is incremented by 2 after each transfer 	
1	MAR is decremented after each data transfer	
	 If DTSZ = 0, MAR is decremented by 1 after each transfer 	
	• If DTSZ = 1, MAR is decremented by 2 after each transfer	

MAR is not incremented or decremented in idle mode.

Bit 4—Repeat Enable (RPE): Selects whether to transfer data in I/O mode, idle mode, or repeat mode.

Bit 4 RPE	Bit 3 DTIE	Description	
0	0	I/O mode	(Initial value)
	1		
1	0	Repeat mode	
	1	Idle mode	

Operations in these modes are described in sections 7.4.2, I/O Mode, 7.4.3, Idle Mode, and 7.4.4, Repeat Mode.

Bit 3—Data Transfer Interrupt Enable (DTIE): Enables or disables the CPU interrupt (DEND) requested when the DTE bit is cleared to 0.

Bit 3		
DTIE	Description	
0	The DEND interrupt requested by DTE is disabled	(Initial value)
1	The DEND interrupt requested by DTE is enabled	

Bits 2 to 0—Data Transfer Select (DTS2, DTS1, DTS0): These bits select the data transfer activation source. Some of the selectable sources differ between channels A and B.

Bit 2 DTS2	Bit 1 DTS1	Bit 0 DTS0	Description	
0	0	0	Compare match/input capture A interrupt from 16-bit timer	
			channel 0 (Initial value)	
		1	Compare match/input capture A interrupt from 16-bit timer channel 1	
	1	0	Compare match/input capture A interrupt from 16-bit timer channel 2	
		1	Conversion-end interrupt from A/D converter	
1	0 0	0	Transmit-data-empty interrupt from SCI channel 0	
		1	Receive-data-full interrupt from SCI channel 0	
	1	0	Falling edge of DREQ input (channel B)	
			Transfer in full address mode (channel A)	
		1	Low level of DREQ input (channel B)	
			Transfer in full address mode (channel A)	

Note: See section 7.3.4, Data Transfer Control Registers (DTCR).

The same internal interrupt can be selected as an activation source for two or more channels at once. In that case the channels are activated in a priority order, highest-priority channel first. For the priority order, see section 7.4.9, Multiple-Channel Operation.

When a channel is enabled (DTE = 1), its selected DMAC activation source cannot generate a CPU interrupt.

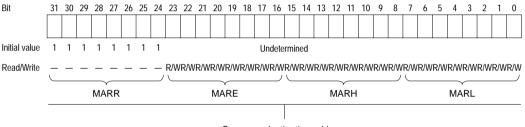
7.3 Register Descriptions (2) (Full Address Mode)

In full address mode the A and B channels operate together. Full address mode is selected as indicated in table 7.4.

7.3.1 Memory Address Registers (MAR)

A memory address register (MAR) is a 32-bit readable/writable register. MARA functions as the source address register of the transfer, and MARB as the destination address register.

An MAR consists of four 8-bit registers designated MARR, MARE, MARH, and MARL. All bits of MARR are reserved; they cannot be modified and are always read as 1. (Write is invalid.)



Source or destination address

The MAR value is incremented or decremented each time one byte or word is transferred, automatically updating the source or destination memory address. For details, see section 7.3.4, Data Transfer Control Registers (DTCR).

The MARs are not initialized by a reset or in standby mode.

7.3.2 I/O Address Registers (IOAR)

The I/O address registers (IOARs) are not used in full address mode.

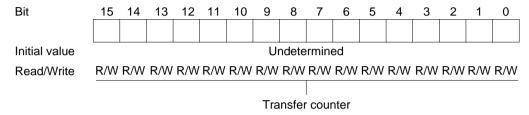


7.3.3 **Execute Transfer Count Registers (ETCR)**

An execute transfer count register (ETCR) is a 16-bit readable/writable register that specifies the number of transfers to be executed. The functions of these registers differ between normal mode and block transfer mode.

Normal mode

ETCRA

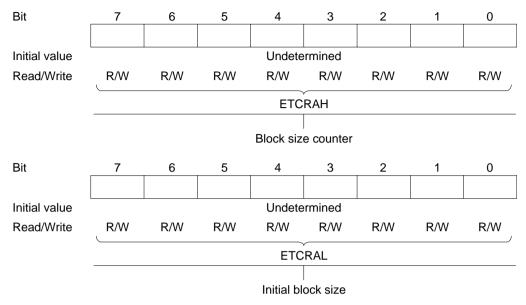


ETCRB: Is not used in normal mode.

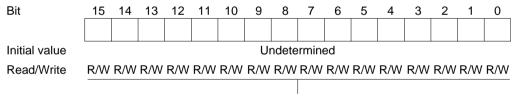
In normal mode ETCRA functions as a 16-bit transfer counter. The count is decremented by 1 each time one transfer is executed. The transfer ends when the count reaches H'0000. ETCRB is not used.

Block transfer mode

ETCRA



ETCRB



Block transfer counter

In block transfer mode, ETCRAH functions as an 8-bit block size counter. ETCRAL holds the initial block size. ETCRAH is decremented by 1 each time one byte or word is transferred. When the count reaches H'00, ETCRAH is reloaded from ETCRAL. Blocks consisting of an arbitrary number of bytes or words can be transferred repeatedly by setting the same initial block size value in ETCRAH and ETCRAL.

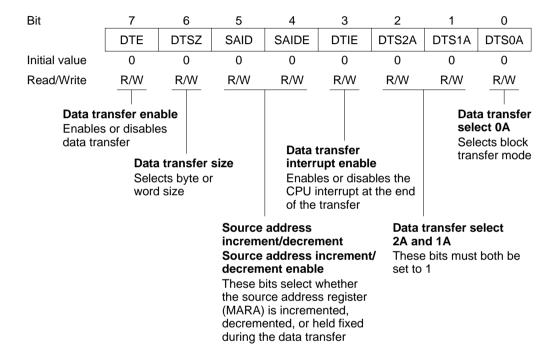
In block transfer mode ETCRB functions as a 16-bit block transfer counter. ETCRB is decremented by 1 each time one block is transferred. The transfer ends when the count reaches H'0000.

The ETCRs are not initialized by a reset or in standby mode.

7.3.4 Data Transfer Control Registers (DTCR)

The data transfer control registers (DTCRs) are 8-bit readable/writable registers that control the operation of the DMAC channels. A channel operates in full address mode when bits DTS2A and DTS1A are both set to 1 in DTCRA. DTCRA and DTCRB have different functions in full address mode.

DTCRA



DTCRA is initialized to H'00 by a reset and in standby mode.

Bit 7—Data Transfer Enable (DTE): Together with the DTME bit in DTCRB, this bit enables or disables data transfer on the channel. When the DTME and DTE bits are both set to 1, the channel is enabled. If auto-request is specified, data transfer begins immediately. Otherwise, the channel waits for transfers to be requested. When the specified number of transfers have been completed, the DTE bit is automatically cleared to 0. When DTE is 0, the channel is disabled and does not accept transfer requests. DTE is set to 1 by reading the register when DTE is 0, then writing 1.

Bit 7 DTE	Description	
0	Data transfer is disabled (DTE is cleared to 0 when the specified number of transfers have been completed)	(Initial value)
1	Data transfer is enabled	

If DTIE is set to 1, a CPU interrupt is requested when DTE is cleared to 0.

Bit 6—Data Transfer Size (DTSZ): Selects the data size of each transfer.

Bit 6 DTSZ	Description	
0	Byte-size transfer	(Initial value)
1	Word-size transfer	

Bit 5—Source Address Increment/Decrement (SAID) and,

Bit 4—Source Address Increment/Decrement Enable (SAIDE): These bits select whether the source address register (MARA) is incremented, decremented, or held fixed during the data transfer.

Bit 4 SAIDE	Description	
0	MARA is held fixed	(Initial value)
1	MARA is incremented after each data transfer	
	• If DTSZ = 0, MARA is incremented by 1 after each transfer	
	• If DTSZ = 1, MARA is incremented by 2 after each transfer	
0	MARA is held fixed	
1	MARA is decremented after each data transfer	
	• If DTSZ = 0, MARA is decremented by 1 after each transfer	
	• If DTSZ = 1, MARA is decremented by 2 after each transfer	
	0 1	Description MARA is held fixed MARA is incremented after each data transfer If DTSZ = 0, MARA is incremented by 1 after each transfer If DTSZ = 1, MARA is incremented by 2 after each transfer MARA is held fixed MARA is decremented after each data transfer If DTSZ = 0, MARA is decremented by 1 after each transfer If DTSZ = 0, MARA is decremented by 1 after each transfer



Bit 3—Data Transfer Interrupt Enable (DTIE): Enables or disables the CPU interrupt (DEND) requested when the DTE bit is cleared to 0.

Bit 3 DTIE	Description	
0	The DEND interrupt requested by DTE is disabled	(Initial value)
1	The DEND interrupt requested by DTE is enabled	

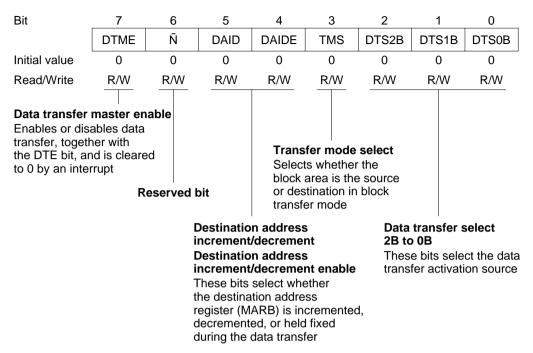
Bits 2 and 1—Data Transfer Select 2A and 1A (DTS2A, DTS1A): A channel operates in full address mode when DTS2A and DTS1A are both set to 1.

Bit 0—Data Transfer Select 0A (DTS0A): Selects normal mode or block transfer mode.

Bit 0 DTS0A Description		
0	Normal mode	(Initial value)
1	Block transfer mode	

Operations in these modes are described in sections 7.4.5, Normal Mode, and 7.4.6, Block Transfer Mode.

DTCRB



DTCRB is initialized to H'00 by a reset and in standby mode.

Bit 7—Data Transfer Master Enable (DTME): Together with the DTE bit in DTCRA, this bit enables or disables data transfer. When the DTME and DTE bits are both set to 1, the channel is enabled. When an NMI interrupt occurs DTME is cleared to 0, suspending the transfer so that the CPU can use the bus. The suspended transfer resumes when DTME is set to 1 again. For further information on operation in block transfer mode, see section 7.6.6, NMI Interrupts and Block Transfer Mode.

DTME is set to 1 by reading the register while DTME = 0, then writing 1.

Bit 7 DTME	Description	
0	Data transfer is disabled (DTME is cleared to 0 when an NMI interrupt occurs)	(Initial value)
1	Data transfer is enabled	

Bit 6—Reserved: Although reserved, this bit can be written and read.



Bit 5—Destination Address Increment/Decrement (DAID) and,

Bit 4—Destination Address Increment/Decrement Enable (DAIDE): These bits select whether the destination address register (MARB) is incremented, decremented, or held fixed during the data transfer.

Bit 5 DAID	Bit 4 DAIDE	Description	
0	0	MARB is held fixed	(Initial value)
	1	MARB is incremented after each data transfer	
		If DTSZ = 0, MARB is incremented by 1 after each data transfer.	nsfer
		If DTSZ = 1, MARB is incremented by 2 after each data transfer.	nsfer
1	0	MARB is held fixed	
	1	MARB is decremented after each data transfer	
		If DTSZ = 0, MARB is decremented by 1 after each data tra	ansfer
		If DTSZ = 1, MARB is decremented by 2 after each data tra	ansfer

Bit 3—Transfer Mode Select (TMS): Selects whether the source or destination is the block area in block transfer mode.

Bit 3 TMS	Description	
0	Destination is the block area in block transfer mode	(Initial value)
1	Source is the block area in block transfer mode	

Bits 2 to 0—Data Transfer Select 2B to 0B (DTS2B, DTS1B, DTS0B): These bits select the data transfer activation source. The selectable activation sources differ between normal mode and block transfer mode.

Normal mode

Bit 2 DTS2B	Bit 1 DTS1B	Bit 0 DTS0B	Description	
0	0	0	Auto-request (burst mode)	(Initial value)
		1	Cannot be used	
	1	0	Auto-request (cycle-steal mode)	
		1	Cannot be used	
1	0	0	Cannot be used	
		1	Cannot be used	
	1	0	Falling edge of DREQ	
		1	Low level input at DREQ	

Block transfer mode

Bit 2 Bit 1 Bit 0 DTS2B DTS1B DTS0B Description

0 0		0	Compare match/input capture A interrupt from 16-bit timer channel 0 (Initial value)
		1	Compare match/input capture A interrupt from 16-bit timer channel 1
	1	0	Compare match/input capture A interrupt from 16-bit timer channel 2
		1	Conversion-end interrupt from A/D converter
1	0	0	Cannot be used
		1	Cannot be used
	1	0	Falling edge of DREQ
		1	Cannot be used

The same internal interrupt can be selected to activate two or more channels. The channels are activated in a priority order, highest priority first. For the priority order, see section 7.4.9, Multiple-Channel Operation.



7.4 Operation

7.4.1 Overview

Table 7.5 summarizes the DMAC modes.

Table 7.5 DMAC Modes

Transfer Mode		Activation	Notes
Short address mode	I/O mode Idle mode Repeat mode	Compare match/input capture A interrupt from 16-bit timer channels 0 to 2	Up to four channels can operate independently
		Transmit-data-empty and receive-data-full interrupts from SCI channel 0	Only the B channels support external requests
		Conversion-end interrupt from A/D converter	-
		External request	_
Full address mode	Normal mode	Auto-request	 A and B channels are paired; up to two channels are available
		External request	_
	Block transfer mode	Compare match/input capture A interrupt from 16-bit timer channels 0 to 2	Burst mode transfer or cycle-steal mode transfer can be selected for auto- requests
		Conversion-end interrupt from A/D converter	-
		External request	_

A summary of operations in these modes follows.

I/O Mode: One byte or word is transferred per request. A designated number of these transfers are executed. A CPU interrupt can be requested at completion of the designated number of transfers. One 24-bit address and one 8-bit address are specified. The transfer direction is determined automatically from the activation source.

Idle Mode: One byte or word is transferred per request. A designated number of these transfers are executed. A CPU interrupt can be requested at completion of the designated number of

transfers. One 24-bit address and one 8-bit address are specified. The addresses are held fixed. The transfer direction is determined automatically from the activation source.

Repeat Mode: One byte or word is transferred per request. A designated number of these transfers are executed. When the designated number of transfers are completed, the initial address and counter value are restored and operation continues. No CPU interrupt is requested. One 24-bit address and one 8-bit address are specified. The transfer direction is determined automatically from the activation source.

Normal Mode

Auto-request

The DMAC is activated by register setup alone, and continues executing transfers until the designated number of transfers have been completed. A CPU interrupt can be requested at completion of the transfers. Both addresses are 24-bit addresses.

- Cycle-steal mode
 - The bus is released to another bus master after each byte or word is transferred.
- Burst mode Unless requested by a higher-priority bus master, the bus is not released until the designated number of transfers have been completed.
- External request

One byte or word is transferred per request. A designated number of these transfers are executed. A CPU interrupt can be requested at completion of the designated number of transfers. Both addresses are 24-bit addresses.

Block Transfer Mode: One block of a specified size is transferred per request. A designated number of block transfers are executed. At the end of each block transfer, one address is restored to its initial value. When the designated number of blocks have been transferred, a CPU interrupt can be requested. Both addresses are 24-bit addresses.



7.4.2 I/O Mode

I/O mode can be selected independently for each channel.

One byte or word is transferred at each transfer request in I/O mode. A designated number of these transfers are executed. One address is specified in the memory address register (MAR), the other in the I/O address register (IOAR). The direction of transfer is determined automatically from the activation source. The transfer is from the address specified in IOAR to the address specified in MAR if activated by an SCI channel 0 receive-data-full interrupt, and from the address specified in MAR to the address specified in IOAR otherwise.

Table 7.6 indicates the register functions in I/O mode.

Table 7.6 Register Functions in I/O Mode

	Function			
Register	Activated by SCI 0 Receive- Data-Full Interrupt or by A/D Converter Conversion- End Interrupt	Other Activation	Initial Setting	Operation
23 0 MAR	Destination address register	Source address register	Destination or source start address	Incremented or decremented once per transfer
23 7 0 All 1s IOAR	Source address register	Destination address register	Source or destination address	Held fixed
15 0 ETCR	Transfer counter	•	Number of transfers	Decremented once per transfer until H'0000 is reached and transfer ends

Legend

MAR: Memory address register IOAR: I/O address register

ETCR: Execute transfer count register

MAR and IOAR specify the source and destination addresses. MAR specifies a 24-bit source or destination address, which is incremented or decremented as each byte or word is transferred. IOAR specifies the lower 8 bits of a fixed address. The upper 16 bits are all 1s. IOAR is not incremented or decremented.

Figure 7.2 illustrates how I/O mode operates.

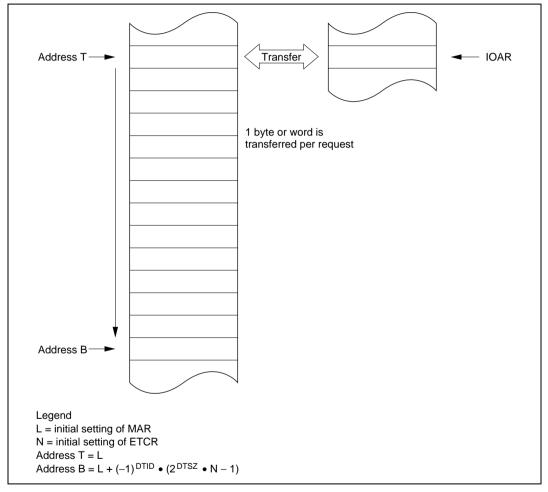


Figure 7.2 Operation in I/O Mode

The transfer count is specified as a 16-bit value in ETCR. The ETCR value is decremented by 1 at each transfer. When the ETCR value reaches H'0000, the DTE bit is cleared and the transfer ends. If the DTIE bit is set to 1, a CPU interrupt is requested at this time. The maximum transfer count is 65,536, obtained by setting ETCR to H'0000.

Transfers can be requested (activated) by compare match/input capture A interrupts from 16-bit timer channels 0 to 2, transmit-data-empty and receive-data-full interrupts from SCI channel 0, conversion-end interrupts from the A/D converter, and external request signals.

For the detailed settings see section 7.2.4, Data Transfer Control Registers (DTCR).

Figure 7.3 shows a sample setup procedure for I/O mode.

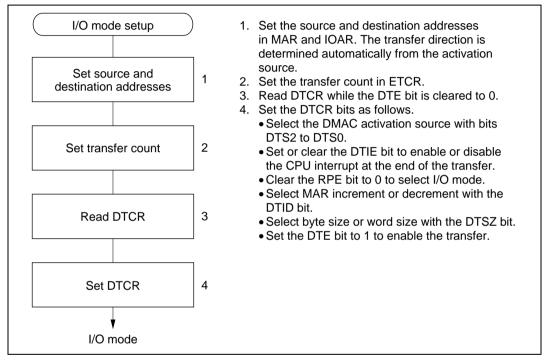


Figure 7.3 I/O Mode Setup Procedure (Example)

7.4.3 Idle Mode

Idle mode can be selected independently for each channel.

One byte or word is transferred at each transfer request in idle mode. A designated number of these transfers are executed. One address is specified in the memory address register (MAR), the other in the I/O address register (IOAR). The direction of transfer is determined automatically from the activation source. The transfer is from the address specified in IOAR to the address specified in MAR if activated by an SCI channel 0 receive-data-full interrupt, and from the address specified in MAR to the address specified in IOAR otherwise.

Table 7.7 indicates the register functions in idle mode.

Table 7.7 Register Functions in Idle Mode

	Function			
Register	Activated by SCI 0 Receive- Data-Full Interrupt or by A/D Converter Conversion- End Interrupt	Other Activation	Initial Setting	Operation
23 0 MAR	Destination address register	Source address register	Destination or source address	Held fixed
23 7 0 All 1s IOAR	Source address register	Destination address register	Source or destination address	Held fixed
15 0 ETCR	Transfer counter	•	Number of transfers	Decremented once per transfer until H'0000 is reached and transfer ends

Legend

MAR: Memory address register IOAR: I/O address register

ETCR: Execute transfer count register

MAR and IOAR specify the source and destination addresses. MAR specifies a 24-bit source or destination address. IOAR specifies the lower 8 bits of a fixed address. The upper 16 bits are all 1s. MAR and IOAR are not incremented or decremented.

Figure 7.4 illustrates how idle mode operates.

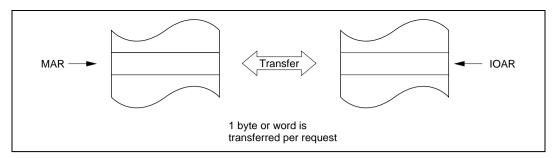


Figure 7.4 Operation in Idle Mode

The transfer count is specified as a 16-bit value in ETCR. The ETCR value is decremented by 1 at each transfer. When the ETCR value reaches H'0000, the DTE bit is cleared, the transfer ends, and a CPU interrupt is requested. The maximum transfer count is 65,536, obtained by setting ETCR to H'0000.

Transfers can be requested (activated) by compare match/input capture A interrupts from 16-bit timer channels 0 to 2, transmit-data-empty and receive-data-full interrupts from SCI channel 0, conversion-end interrupts from the A/D converter, and external request signals.

For the detailed settings see section 7.3.4, Data Transfer Control Registers (DTCR).

Figure 7.5 shows a sample setup procedure for idle mode.

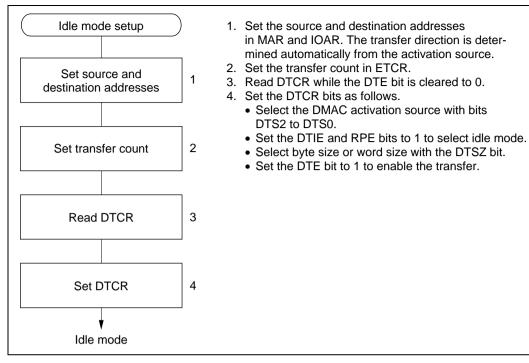


Figure 7.5 Idle Mode Setup Procedure (Example)

7.4.4 Repeat Mode

Repeat mode is useful for cyclically transferring a bit pattern from a table to the programmable timing pattern controller (TPC) in synchronization, for example, with 16-bit timer compare match. Repeat mode can be selected for each channel independently.

One byte or word is transferred per request in repeat mode, as in I/O mode. A designated number of these transfers are executed. One address is specified in the memory address register (MAR), the other in the I/O address register (IOAR). At the end of the designated number of transfers, MAR and ETCRH are restored to their original values and operation continues. The direction of transfer is determined automatically from the activation source. The transfer is from the address specified in IOAR to the address specified in MAR if activated by an SCI channel 0 receive-data-full interrupt, and from the address specified in MAR to the address specified in IOAR otherwise.

Table 7.8 indicates the register functions in repeat mode.

Table 7.8 Register Functions in Repeat Mode

	Function			
Register	Activated by SCI 0 Receive- Data-Full Interrupt or by A/D Converter Conversion- End Interrupt	Other Activation	Initial Setting	Operation
23 0 MAR	Destination address register	Source address register	Destination or source start address	Incremented or decremented at each transfer until ETCRH reaches H'0000, then restored to initial value
23 7 0 All 1s IOAR	Source address register	Destination address register	Source or destination address	Held fixed
7 0 ETCRH 7 0	Transfer counter		Number of transfers	Decremented once per transfer until H'0000 is reached, then reloaded from ETCRL
ETCRL	Initial transfer co	unt	Number of transfers	Held fixed

Legend

MAR: Memory address register IOAR: I/O address register

ETCR: Execute transfer count register

In repeat mode ETCRH is used as the transfer counter while ETCRL holds the initial transfer count. ETCRH is decremented by 1 at each transfer until it reaches H'00, then is reloaded from ETCRL. MAR is also restored to its initial value, which is calculated from the DTSZ and DTID bits in DTCR. Specifically, MAR is restored as follows:

$$MAR \leftarrow MAR - (-1)^{DTID} \bullet 2^{DTSZ} \bullet ETCRL$$

ETCRH and ETCRL should be initially set to the same value.

In repeat mode transfers continue until the CPU clears the DTE bit to 0. After DTE is cleared to 0, if the CPU sets DTE to 1 again, transfers resume from the state at which DTE was cleared. No CPU interrupt is requested.

As in I/O mode, MAR and IOAR specify the source and destination addresses. MAR specifies a 24-bit source or destination address. IOAR specifies the lower 8 bits of a fixed address. The upper 16 bits are all 1s. IOAR is not incremented or decremented.

Figure 7.6 illustrates how repeat mode operates.

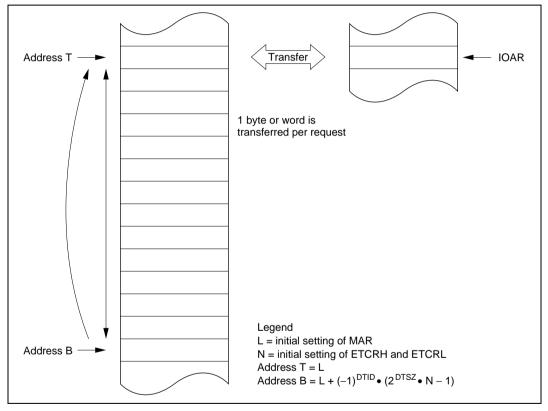


Figure 7.6 Operation in Repeat Mode

The transfer count is specified as an 8-bit value in ETCRH and ETCRL. The maximum transfer count is 255, obtained by setting both ETCRH and ETCRL to H'FF.

Transfers can be requested (activated) by compare match/input capture A interrupts from 16-bit timer channels 0 to 2, transmit-data-empty and receive-data-full interrupts from SCI channel 0, conversion-end interrupts from the A/D converter, and external request signals.

For the detailed settings see section 7.2.4, Data Transfer Control Registers (DTCR).

Figure 7.7 shows a sample setup procedure for repeat mode.

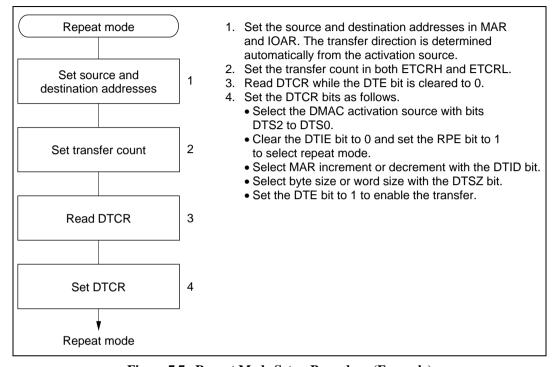


Figure 7.7 Repeat Mode Setup Procedure (Example)

7.4.5 Normal Mode

In normal mode the A and B channels are combined. One byte or word is transferred per request. A designated number of these transfers are executed. Addresses are specified in MARA and MARB. Table 7.9 indicates the register functions in I/O mode.

Table 7.9 Register Functions in Normal Mode

Register	Function	Initial Setting	Operation
23 MAR	0 Source address register	Source start address	Incremented or decremented once per transfer, or held fixed
23 MAR	0 Destination address register	Destination start address	Incremented or decremented once per transfer, or held fixed
15 I	0 Transfer counter	Number of transfers	Decremented once per transfer

Legend

MARA: Memory address register A
MARB: Memory address register B
ETCRA: Execute transfer count register A

The source and destination addresses are both 24-bit addresses. MARA specifies the source address. MARB specifies the destination address. MARA and MARB can be independently incremented, decremented, or held fixed as data is transferred.

The transfer count is specified as a 16-bit value in ETCRA. The ETCRA value is decremented by 1 at each transfer. When the ETCRA value reaches H'0000, the DTE bit is cleared and the transfer ends. If the DTIE bit is set to 1, a CPU interrupt is requested at this time. The maximum transfer count is 65,536, obtained by setting ETCRA to H'0000.

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Figure 7.8 illustrates how normal mode operates.

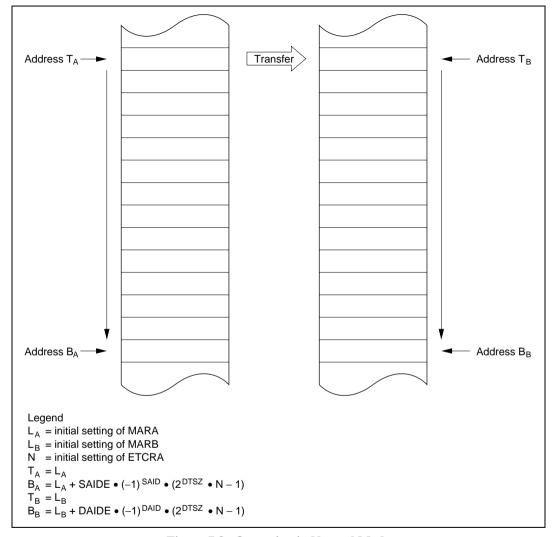


Figure 7.8 Operation in Normal Mode

Transfers can be requested (activated) by an external request or auto-request. An auto-requested transfer is activated by the register settings alone. The designated number of transfers are executed automatically. Either cycle-steal or burst mode can be selected. In cycle-steal mode the DMAC releases the bus temporarily after each transfer. In burst mode the DMAC keeps the bus until the transfers are completed, unless there is a bus request from a higher-priority bus master.

For the detailed settings see section 7.3.4, Data Transfer Control Registers (DTCR).

Figure 7.9 shows a sample setup procedure for normal mode.

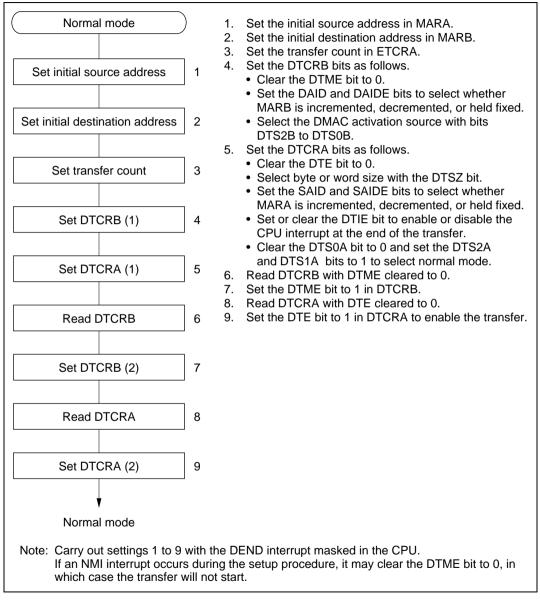


Figure 7.9 Normal Mode Setup Procedure (Example)

7.4.6 Block Transfer Mode

In block transfer mode the A and B channels are combined. One block of a specified size is transferred per request. A designated number of block transfers are executed. Addresses are specified in MARA and MARB. The block area address can be either held fixed or cycled.

Table 7.10 indicates the register functions in block transfer mode.

 Table 7.10
 Register Functions in Block Transfer Mode

Register		Function	Initial Setting	Operation
23 MAR	0 (A	Source address register	Source start address	Incremented or decremented once per transfer, or held fixed
23 MAR	0 B	Destination address register	Destination start address	Incremented or decremented once per transfer, or held fixed
	7 0 ETCRAH	Block size counter	Block size	Decremented once per transfer until H'00 is reached, then reloaded from ETCRL
	7 0 ETCRAL	Initial block size	Block size	Held fixed
15 E	0 ETÇRB	Block transfer counter	Number of block transfers	Decremented once per block transfer until H'0000 is reached and the transfer ends

Legend

MARA: Memory address register A
MARB: Memory address register B
ETCRA: Execute transfer count register A
ETCRB: Execute transfer count register B

The source and destination addresses are both 24-bit addresses. MARA specifies the source address. MARB specifies the destination address. MARA and MARB can be independently incremented, decremented, or held fixed as data is transferred. One of these registers operates as a block area register: even if it is incremented or decremented, it is restored to its initial value at the end of each block transfer. The TMS bit in DTCRB selects whether the block area is the source or destination.

If M (1 to 255) is the size of the block transferred at each request and N (1 to 65,536) is the number of blocks to be transferred, then ETCRAH and ETCRAL should initially be set to M and ETCRB should initially be set to N.

Figure 7.10 illustrates how block transfer mode operates. In this figure, bit TMS is cleared to 0, meaning the block area is the destination.

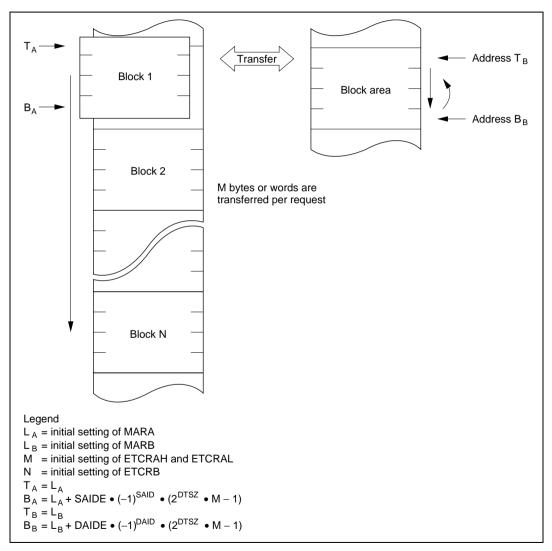


Figure 7.10 Operation in Block Transfer Mode

When activated by a transfer request, the DMAC executes a burst transfer. During the transfer MARA and MARB are updated according to the DTCR settings, and ETCRAH is decremented. When ETCRAH reaches H'00, it is reloaded from ETCRAL to restore the initial value. The memory address register of the block area is also restored to its initial value, and ETCRB is decremented. If ETCRB is not H'0000, the DMAC then waits for the next transfer request. ETCRAH and ETCRAL should be initially set to the same value.

The above operation is repeated until ETCRB reaches H'0000, at which point the DTE bit is cleared to 0 and the transfer ends. If the DTIE bit is set to 1, a CPU interrupt is requested at this time.

Figure 7.11 shows examples of a block transfer with byte data size when the block area is the destination. In (a) the block area address is cycled. In (b) the block area address is held fixed.

Transfers can be requested (activated) by compare match/input capture A interrupts from ITU channels 0 to 2, by an A/D converter conversion-end interrupt, and by external request signals.

For the detailed settings see section 7.3.4, Data Transfer Control Registers (DTCR).

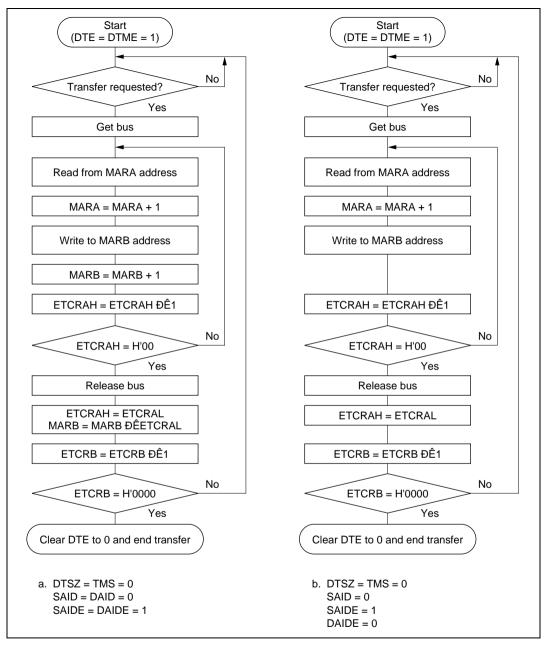


Figure 7.11 Block Transfer Mode Flowcharts (Examples)

Figure 7.12 shows a sample setup procedure for block transfer mode.

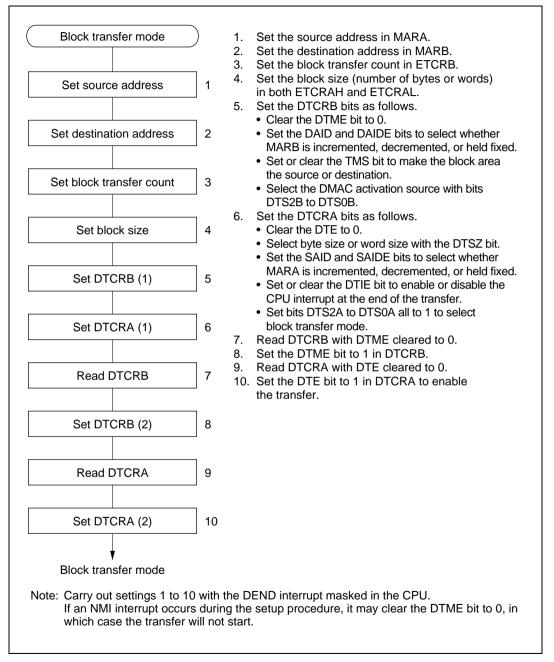


Figure 7.12 Block Transfer Mode Setup Procedure (Example)

7.4.7 DMAC Activation

The DMAC can be activated by an internal interrupt, external request, or auto-request. The available activation sources differ depending on the transfer mode and channel as indicated in table 7.11

Table 7.11 DMAC Activation Sources

		Short A	ddress Mode		
		Channels	Channels	Full A	Address Mode
Activation Source		0A and 1A	0B and 1B	Normal	Block
Internal	IMIA0	0	0	×	0
interrupts	IMIA1	0	0	×	0
	IMIA2	0	0	×	0
	ADI	0	0	×	0
	TXI0	0	0	×	×
	RXI0	0	0	×	×
External requests	Falling edge of DREQ	×	0	0	0
	Low input at DREQ	×	0	0	×
Auto-request		×	×	0	×

Activation by Internal Interrupts: When an interrupt request is selected as a DMAC activation source and the DTE bit is set to 1, that interrupt request is not sent to the CPU. It is not possible for an interrupt request to activate the DMAC and simultaneously generate a CPU interrupt.

When the DMAC is activated by an interrupt request, the interrupt request flag is cleared automatically. If the same interrupt is selected to activate two or more channels, the interrupt request flag is cleared when the highest-priority channel is activated, but the transfer request is held pending on the other channels in the DMAC, which are activated in their priority order.

Activation by External Request: If an external request $(\overline{DREQ} \text{ pin})$ is selected as an activation source, the \overline{DREQ} pin becomes an input pin and the corresponding \overline{TEND} pin becomes an output pin, regardless of the port data direction register (DDR) settings. The \overline{DREQ} input can be level-sensitive or edge-sensitive.

In short address mode and normal mode, an external request operates as follows. If edge sensing is selected, one byte or word is transferred each time a high-to-low transition of the $\overline{\text{DREQ}}$ input is detected. If the next edge is input before the transfer is completed, the next transfer may not be



executed. If level sensing is selected, the transfer continues while \overline{DREQ} is low, until the transfer is completed. The bus is released temporarily after each byte or word has been transferred, however. If the \overline{DREQ} input goes high during a transfer, the transfer is suspended after the current byte or word has been transferred. When \overline{DREQ} goes low, the request is held internally until one byte or word has been transferred. The \overline{TEND} signal goes low during the last write cycle.

In block transfer mode, an external request operates as follows. Only edge-sensitive transfer requests are possible in block transfer mode. Each time a high-to-low transition of the \overline{DREQ} input is detected, a block of the specified size is transferred. The \overline{TEND} signal goes low during the last write cycle in each block.

Activation by Auto-Request: The transfer starts as soon as enabled by register setup, and continues until completed. Cycle-steal mode or burst mode can be selected.

In cycle-steal mode the DMAC releases the bus temporarily after transferring each byte or word. Normally, DMAC cycles alternate with CPU cycles.

In burst mode the DMAC keeps the bus until the transfer is completed, unless there is a higher-priority bus request. If there is a higher-priority bus request, the bus is released after the current byte or word has been transferred.

7.4.8 DMAC Bus Cycle

Figure 7.13 shows an example of the timing of the basic DMAC bus cycle. This example shows a word-size transfer from a 16-bit two-state access area to an 8-bit three-state access area. When the DMAC gets the bus from the CPU, after one dead cycle (T_d), it reads from the source address and writes to the destination address. During these read and write operations the bus is not released even if there is another bus request. DMAC cycles comply with bus controller settings in the same way as CPU cycles.

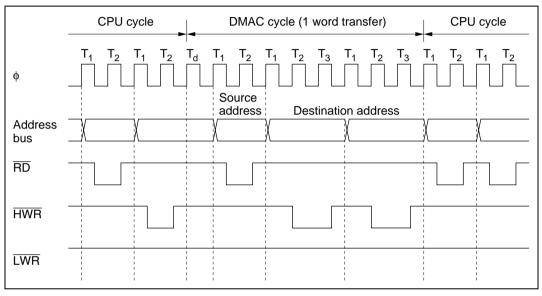


Figure 7.13 DMA Transfer Bus Timing (Example)

Figure 7.14 shows the timing when the DMAC is activated by low input at a \overline{DREQ} pin. This example shows a word-size transfer from a 16-bit two-state access area to another 16-bit two-state access area. The DMAC continues the transfer while the \overline{DREQ} pin is held low.

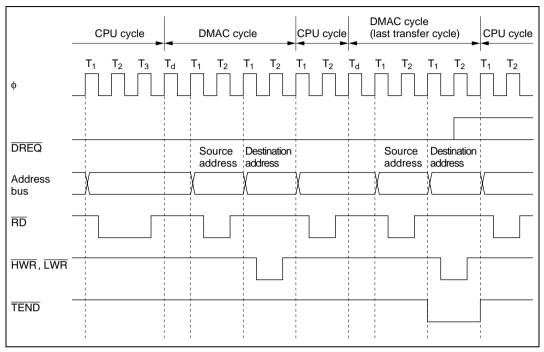


Figure 7.14 Bus Timing of DMA Transfer Requested by Low DREQ Input

Figure 7.15 shows an auto-requested burst-mode transfer. This example shows a transfer of three words from a 16-bit two-state access area to another 16-bit two-state access area.

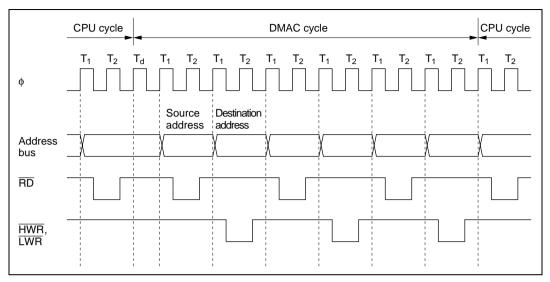


Figure 7.15 Burst DMA Bus Timing

When the DMAC is activated from a \overline{DREQ} pin there is a minimum interval of four states from when the transfer is requested until the DMAC starts operating. The \overline{DREQ} pin is not sampled during the time between the transfer request and the start of the transfer. In short address mode and normal mode, the pin is next sampled at the end of the read cycle. In block transfer mode, the pin is next sampled at the end of one block transfer.

Figure 7.16 shows the timing when the DMAC is activated by the falling edge of DREO in normal mode.

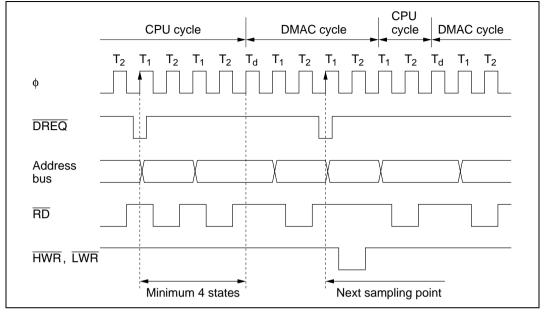


Figure 7.16 Timing of DMAC Activation by Falling Edge of DREQ in Normal Mode

Figure 7.17 shows the timing when the DMAC is activated by level-sensitive low $\overline{\text{DREQ}}$ input in normal mode.

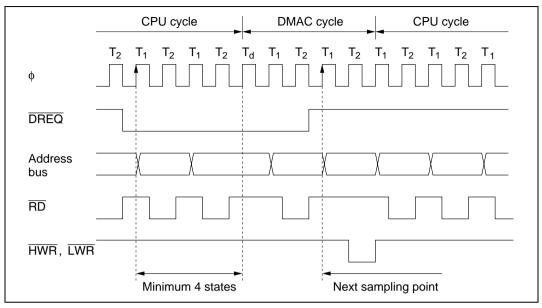


Figure 7.17 Timing of DMAC Activation by Low DREQ Level in Normal Mode

Figure 7.18 shows the timing when the DMAC is activated by the falling edge of \overline{DREQ} in block transfer mode.

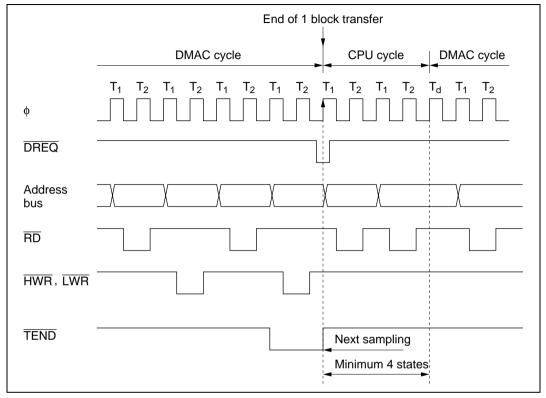


Figure 7.18 Timing of DMAC Activation by Falling Edge of DREQ in Block Transfer Mode

7.4.9 Multiple-Channel Operation

The DMAC channel priority order is: channel 0 > channel 1 and channel A > channel B.

Table 7.12 shows the complete priority order.

Table 7.12 Channel Priority Order

Short Address Mode	Full Address Mode	Priority
Channel 0A	Channel 0	High
Channel 0B		^
Channel 1A	Channel 1	
Channel 1B		Low

If transfers are requested on two or more channels simultaneously, or if a transfer on one channel is requested during a transfer on another channel, the DMAC operates as follows.

- When a transfer is requested, the DMAC requests the bus right. When it gets the bus right, it starts a transfer on the highest-priority channel at that time.
- Once a transfer starts on one channel, requests to other channels are held pending until that channel releases the bus.
- After each transfer in short address mode, and each externally-requested or cycle-steal transfer
 in normal mode, the DMAC releases the bus and returns to step 1. After releasing the bus, if
 there is a transfer request for another channel, the DMAC requests the bus again.
- After completion of a burst-mode transfer, or after transfer of one block in block transfer
 mode, the DMAC releases the bus and returns to step 1. If there is a transfer request for a
 higher-priority channel or a bus request from a higher-priority bus master, however, the
 DMAC releases the bus after completing the transfer of the current byte or word. After
 releasing the bus, if there is a transfer request for another channel, the DMAC requests the bus
 again.

Figure 7.19 shows the timing when channel 0A is set up for I/O mode and channel 1 for burst mode, and a transfer request for channel 0A is received while channel 1 is active.



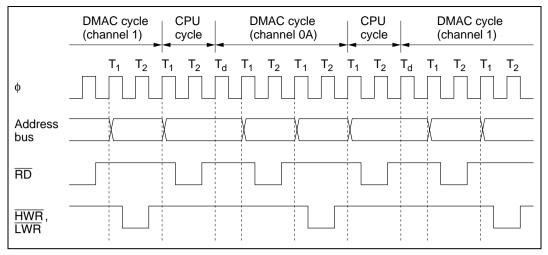


Figure 7.19 Timing of Multiple-Channel Operations

7.4.10 External Bus Requests, DRAM Interface, and DMAC

During a DMAC transfer, if the bus right is requested by an external bus request signal (BREQ) or by the DRAM interface (refresh cycle), the DMAC releases the bus after completing the transfer of the current byte or word. If there is a transfer request at this point, the DMAC requests the bus right again. Figure 7.20 shows an example of the timing of insertion of a refresh cycle during a burst transfer on channel 0.

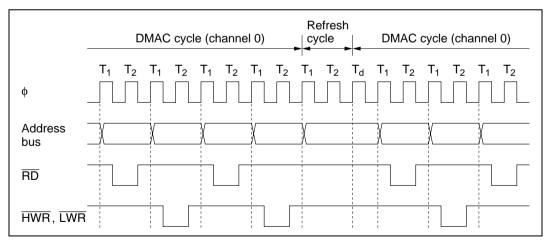


Figure 7.20 Bus Timing of DRAM Interface, and DMAC

7.4.11 NMI Interrupts and DMAC

NMI interrupts do not affect DMAC operations in short address mode.

If an NMI interrupt occurs during a transfer in full address mode, the DMAC suspends operations. In full address mode, a channel is enabled when its DTE and DTME bits are both set to 1. NMI input clears the DTME bit to 0. After transferring the current byte or word, the DMAC releases the bus to the CPU. In normal mode, the suspended transfer resumes when the CPU sets the DTME bit to 1 again. Check that the DTE bit is set to 1 and the DTME bit is cleared to 0 before setting the DTME bit to 1.

Figure 7.21 shows the procedure for resuming a DMAC transfer in normal mode on channel 0 after the transfer was halted by NMI input.

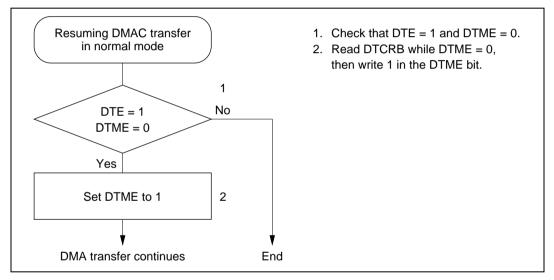


Figure 7.21 Procedure for Resuming a DMAC Transfer Halted by NMI (Example)

For information about NMI interrupts in block transfer mode, see section 7.6.6, NMI Interrupts and Block Transfer Mode.

7.4.12 Aborting a DMAC Transfer

When the DTE bit in an active channel is cleared to 0, the DMAC halts after transferring the current byte or word. The DMAC starts again when the DTE bit is set to 1. In full address mode, the DTME bit can be used for the same purpose. Figure 7.22 shows the procedure for aborting a DMAC transfer by software.

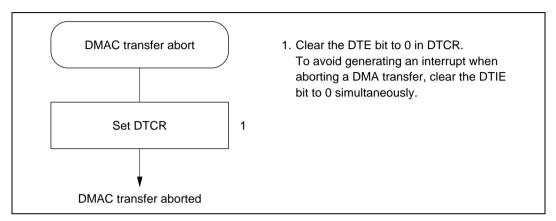


Figure 7.22 Procedure for Aborting a DMAC Transfer

7.4.13 Exiting Full Address Mode

Figure 7.23 shows the procedure for exiting full address mode and initializing the pair of channels. To set the channels up in another mode after exiting full address mode, follow the setup procedure for the relevant mode.

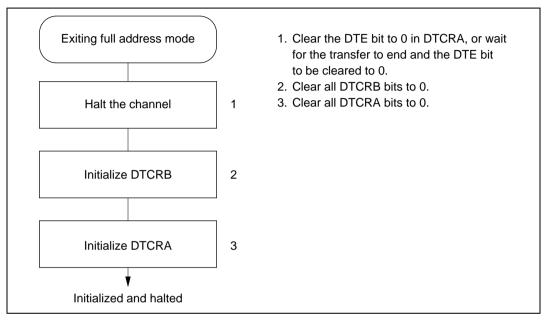


Figure 7.23 Procedure for Exiting Full Address Mode (Example)

7.4.14 DMAC States in Reset State, Standby Modes, and Sleep Mode

When the chip is reset or enters software standby mode, the DMAC is initialized and halts. DMAC operations continue in sleep mode. Figure 7.24 shows the timing of a cycle-steal transfer in sleep mode.

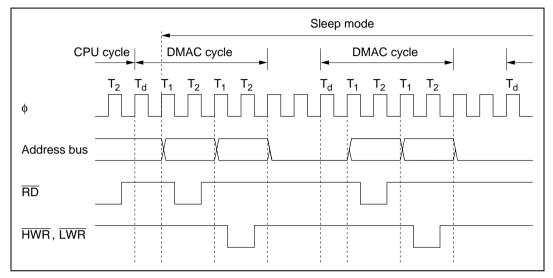


Figure 7.24 Timing of Cycle-Steal Transfer in Sleep Mode

7.5 Interrupts

The DMAC generates only DMA-end interrupts. Table 7.13 lists the interrupts and their priority.

Table 7.13 DMAC Interrupts

	Desc		
Interrupt	Short Address Mode	Full Address Mode	Interrupt Priority
DEND0A	End of transfer on channel 0A	End of transfer on channel 0	High
DEND0B	End of transfer on channel 0B	_	_ 🖊
DEND1A	End of transfer on channel 1A	End of transfer on channel 1	_
DEND1B	End of transfer on channel 1B	_	Low

Each interrupt is enabled or disabled by the DTIE bit in the corresponding data transfer control register (DTCR). Separate interrupt signals are sent to the interrupt controller.

The interrupt priority order among channels is channel 0 > channel 1 and channel A > channel B.

Figure 7.25 shows the DMA-end interrupt logic. An interrupt is requested whenever DTE = 0 and DTIE = 1.

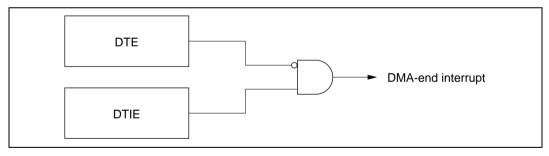


Figure 7.25 DMA-End Interrupt Logic

The DMA-end interrupt for the B channels (DENDB) is unavailable in full address mode. The DTME bit does not affect interrupt operations.

7.6 Usage Notes

7.6.1 Note on Word Data Transfer

Word data cannot be accessed starting at an odd address. When word-size transfer is selected, set even values in the memory and I/O address registers (MAR and IOAR).

7.6.2 DMAC Self-Access

The DMAC itself cannot be accessed during a DMAC cycle. DMAC registers cannot be specified as source or destination addresses.

7.6.3 Longword Access to Memory Address Registers

A memory address register can be accessed as longword data at the MARR address.

Example

```
MOV.L #LBL, ER0
MOV.L ER0, @MARR
```

Four byte accesses are performed. Note that the CPU may release the bus between the second byte (MARE) and third byte (MARH).

Memory address registers should be written and read only when the DMAC is halted.

7.6.4 Note on Full Address Mode Setup

Full address mode is controlled by two registers: DTCRA and DTCRB. Care must be taken to prevent the B channel from operating in short address mode during the register setup. The enable bits (DTE and DTME) should not be set to 1 until the end of the setup procedure.

7.6.5 Note on Activating DMAC by Internal Interrupts

When using an internal interrupt to activate the DMAC, make sure that the interrupt selected as the activating source does not occur during the interval after it has been selected but before the DMAC has been enabled. The on-chip supporting module that will generate the interrupt should not be activated until the DMAC has been enabled. If the DMAC must be enabled while the on-chip supporting module is active, follow the procedure in figure 7.26.

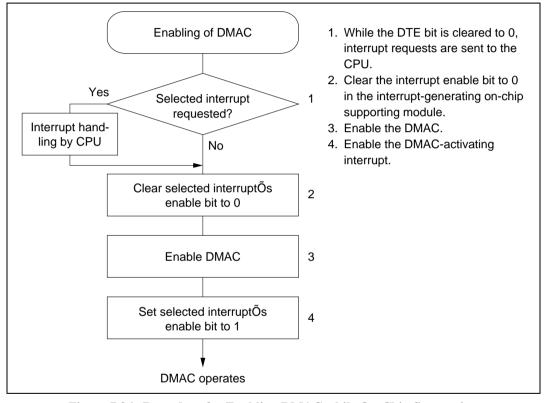


Figure 7.26 Procedure for Enabling DMAC while On-Chip Supporting Module is Operating (Example)

If the DTE bit is set to 1 but the DTME bit is cleared to 0, the DMAC is halted and the selected activating source cannot generate a CPU interrupt. If the DMAC is halted by an NMI interrupt, for example, the selected activating source cannot generate CPU interrupts. To terminate DMAC operations in this state, clear the DTE bit to 0 to allow CPU interrupts to be requested. To continue DMAC operations, carry out steps 2 and 4 in figure 7.26 before and after setting the DTME bit to 1.

When 16-bit timer interrupt activates the DMAC, make sure the next interrupt does not occur before the DMA transfer ends. If one 16-bit timer interrupt activates two or more channels, make sure the next interrupt does not occur before the DMA transfers end on all the activated channels. If the next interrupt occurs before a transfer ends, the channel or channels for which that interrupt was selected may fail to accept further activation requests.

7.6.6 NMI Interrupts and Block Transfer Mode

If an NMI interrupt occurs in block transfer mode, the DMAC operates as follows.

- When the NMI interrupt occurs, the DMAC finishes transferring the current byte or word, then clears the DTME bit to 0 and halts. The halt may occur in the middle of a block.
 It is possible to find whether a transfer was halted in the middle of a block by checking the block size counter. If the block size counter does not have its initial value, the transfer was halted in the middle of a block
- If the transfer is halted in the middle of a block, the activating interrupt flag is cleared to 0. The activation request is not held pending.
- While the DTE bit is set to 1 and the DTME bit is cleared to 0, the DMAC is halted and does not accept activating interrupt requests. If an activating interrupt occurs in this state, the DMAC does not operate and does not hold the transfer request pending internally. Neither is a CPU interrupt requested.
 - For this reason, before setting the DTME bit to 1, first clear the enable bit of the activating interrupt to 0. Then, after setting the DTME bit to 1, set the interrupt enable bit to 1 again. See section 7.6.5, Note on Activating DMAC by Internal Interrupts.
- When the DTME bit is set to 1, the DMAC waits for the next transfer request. If it was halted
 in the middle of a block transfer, the rest of the block is transferred when the next transfer
 request occurs. Otherwise, the next block is transferred when the next transfer request occurs.

7.6.7 Memory and I/O Address Register Values

Table 7.14 indicates the address ranges that can be specified in the memory and I/O address registers (MAR and IOAR).

Table 7.14 Address Ranges Specifiable in MAR and IOAR

	1-Mbyte Mode	16-Mbyte Mode	
MAR	H'00000 to H'FFFFF (0 to 1048575)	H'000000 to H'FFFFF (0 to 16777215)	
IOAR	H'FFF00 to H'FFFFF (1048320 to 1048575)	H'FFFF00 to H'FFFFFF (16776960 to 16777215)	

MAR bits 23 to 20 are ignored in 1-Mbyte mode.

7.6.8 Bus Cycle when Transfer is Aborted

When a transfer is aborted by clearing the DTE bit or suspended by an NMI that clears the DTME bit, if this halts a channel for which the DMAC has a transfer request pending internally, a dead cycle may occur. This dead cycle does not update the halted channel's address register or counter value. Figure 7.27 shows an example in which an auto-requested transfer in cycle-steal mode on channel 0 is aborted by clearing the DTE bit in channel 0.

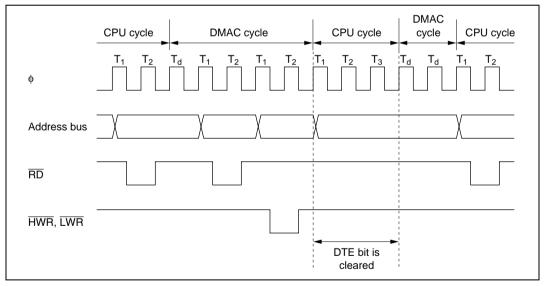


Figure 7.27 Bus Timing at Abort of DMA Transfer in Cycle-Steal Mode

7.6.9 Transfer Requests by A/D Converter

When the A/D converter is set to scan mode and conversion is performed on more than one channel, the A/D converter generates a transfer request when all conversions are completed. The converted data is stored in the appropriate ADDR registers. Block transfer mode and full address mode should therefore be used to transfer all the conversion results at one time.

Section 8 I/O Ports

8.1 Overview

The H8/3067 Group has 11 input/output ports (ports 1, 2, 3, 4, 5, 6, 7, 8, 9, A, and B). Table 8.1 summarizes the port functions. The pins in each port are multiplexed as shown in table 8.1.

Each port has a data direction register (DDR) for selecting input or output, and a data register (DR) for storing output data. In addition to these registers, ports 2, 4, and 5 have an input pull-up control register (PCR) for switching input pull-up transistors on and off.

Ports 1 to 6 and port 8 can drive one TTL load and a 90-pF capacitive load. Ports 9, A, and B can drive one TTL load and a 30-pF capacitive load. Ports 1 to 6 and 8 to B can drive a darlington pair. Ports 1, 2, and 5 can drive LEDs (with 10-mA current sink). Pins $P8_2$ to $P8_0$, PA_7 to PA_0 have Schmitt-trigger input circuits.

For block diagrams of the ports see appendix C, I/O Port Block Diagrams.

Table 8.1 Port Functions (1)

			Expanded	Modes				Single-Chi	p Modes
Port	Description	Pins	Mode 1	Mode 2	Mode 3	Mode 4	Mode 5	Mode 6	Mode 7
Port 1	8-bit I/O port Can drive LEDs	P1, to P1,/ A, to A _o	Address ou	utput pins (A, i	to A ₀)		Address output (A, to A _s) and generic input DDR = 0: generic input DDR = 1: address output	Generic inp	out/output
Port 2	8-bit I/O port Built-in input pull-up transistors Can drive LEDs	$P2_7$ to $P2_7$ A_{15} to A_8	Address ou	utput pins (A ₁₅	to A _a)		Address output (A ₁₅ to A ₅) and generic input DDR = 0: generic input DDR = 1: address output	Generic inp	out/output
Port 3	8-bit I/O port	P3, to P3,/ D ₁₅ to D ₈	Data input/	output (D ₁₅ to	D _s)			Generic inp	out/output
Port 4	 8-bit I/O port Built-in input pull-up transistors 	P4 ₇ to P4 ₀ / D ₇ to D ₀	8-bit bus m	output (D ₇ to node: generic mode: data in		generic inpi	ut/output	Generic inp	out/output
Port 5	 4-bit I/O port Built-in input pull-up transistors Can drive LEDs 	P5 ₃ to P5 ₀ / A ₁₉ to A ₁₆	Address ou	utput (A ₁₉ to A	16)		Address output $(A_{19}$ to $A_{10})$ and 4-bit generic input DDR = 0: generic input DDR = 1: address output	Generic inp	out/output
Port 6	8-bit I/O port	P6 ₇ /φ	Clock outp	ut (φ) and ger	neric input				
		P6₅/LWR P6₅/HWR P6₄/RD P6₃/AS	Bus contro	l signal outpu	t (LWR, HWR	, RD, AS)		Generic inp	out/output
		P6./BACK P6./BREQ P6./WAIT		l signal input/ ic input/outpu	output (BACK it	, BREQ, W	AIT) and	_	
Port 7	8-bit I/O port	P7 _r /AN _r /DA ₁ P7 _e /AN _e /DA ₀			to A/D conver generic input	ter, analog	output (DA ₁ , DA ₀)		
		P7 _s to P7 _o / AN _s to AN _o	Analog inp	ut (AN ₅ to AN	。) to A/D conv	erter, and o	generic input		
Port 8	 5-bit I/O port P8₂ to P8₀ have Schmitt inputs 	P8 ₄ /CS ₀	-	generic input eset value): (OS₀ output		DDR = 0 (reset value): generic input DDR = 1: \overline{CS}_0 output	Generic inp	out/output
		P8 ₃ /ĪRQ ₃ / CS ₁ /ADTRG	and generi	c input after reset): ge		r input (AD	TRG) to A/D converter,	input (ADT	and generic
		P8 ₂ /IRQ ₂ /CS ₂ P8 ₁ /IRQ ₁ /CS ₃	DDR = 0 (r	\overline{RQ}_1 input, \overline{CS}_2 reset value): \overline{CS}_2 and \overline{CS}_3 c		out, and ge	neric input*	IRQ ₂ and If generic inp	RQ, input and ut/output
		P8,/IRQ _o /RFSH	ĪRQ₀ input,	RFSH output	t, and generic	input/outp	ut	ĪRQ₀ input a	and generic t



			Expanded	Modes				Single-Ch	ip Modes
Port	Description	Pins	Mode 1	Mode 2	Mode 3	Mode 4	Mode 5	Mode 6	Mode 7
Port 9	6-bit I/O port	P9 _s /IRQ _s /SCK _t P9 ₄ /IRQ ₄ /SCK _o P9 ₃ /RxD _t P9 ₂ /RxD _o P9 ₁ /TxD _t P9 ₀ /TxD _o			SCK ₀ , RxD ₁ , ₄ input, and 6-		ΓxD₀) for serial communicat put/output	ion interfaces	s 1 and 0
Port A	8-bit I/O port	PA,/TP,/) from pro-	Address o	utput	Address output (A ₂₀),		ut (TP ₇), 16-bit
	Schmitt inputs	TIOCB ₂ /A ₂₀		ntroller (TPC) tput (TIOCB ₂ mer and			TPC output (TP ₇), input or output (TIOCB ₂) for 16-bit timer, and generic input/output	timer input (TIOCB ₂), input/outpu	and generic
		PA ₈ /TP ₈ / TIOCA ₂ /A ₂₁ PA ₃ /TP ₅ / TIOCB ₁ /A ₂₂ PA ₄ /TP ₄ / TIOCA ₁ /A ₂₃	16-bit time output (TIC	it (TP ₆ to TP ₄) r input and DCA ₂ , TIOCB and generic ut	16-bit time output (TIOCA ₁), a	ut (TP ₆ to TP ₄) er input and OCA ₂ , TIOCB address output l, and generic ut	ir at	16-bit time output (TIC	ut (TP ₆ to TP ₄), er input and OCA ₂ , TIOCB ₁ , nd generic ut
		PA/TP/ TIOCB/ TCLKD PA/TP/ TIOCA/ TCLKC PA/TP/ TCLKB /TEND, PA/TP/ TCLKA	TCLKA), 8	-bit timer inpu		CLKC, TCLKE	put (TIOCB ₉ , TIOCA ₉ , TCL <mark>K</mark> 3, TCLKA), output (<u>TEND,</u> ,		
Port B	8-bit I/O port	PB,/TP,s/ RXD2 PBe/TP,s/ TXD2 PBs/TP,s/ SCK_/LCAS PB_/TP,s/ UCAS		. 15	₂), SCI2 input UCAS), and		SCK ₂ , RxD ₂ , TxD ₂), DRAM /output	SCI2 input	ut (TP ₁₅ to TP ₁₂), t and output D ₂ , TxD ₂), and out/output
		PB _y TP ₁ ,/ TMIO ₃ / DREQ ₁ /CS ₄ PB ₂ /TP ₁₀ / TMO ₂ /CS ₅ PB ₂ /TP ₃ / TMIO ₂ / DREQ ₂ /CS ₆ PB ₃ /TP ₃ / TMO ₃ /CS ₇		IAC input (DF			out (TMIO ₃ , TMO ₂ , TMIO ₁ , output, and generic	8-bit timer output (TM TMIO ₁ , TM input (DRE	It (TP ₁ , to TP ₈), input and MIO ₃ , TMO ₂ , TMO ₂ , O _{O,0} , DMAC EQ,, DREQ ₀), ic input/output

Note: * P8, can be used as an output port by making a setting in DRCRA.

8.2 Port 1

8.2.1 Overview

Port 1 is an 8-bit input/output port also used for address output, with the pin configuration shown in figure 8.1. The pin functions differ between the expanded modes with on-chip ROM disabled, expanded modes with on-chip ROM enabled, and single-chip mode. In modes 1 to 4 (expanded modes with on-chip ROM disabled), they are address bus output pins (A₂ to A₃).

In modes 5 (expanded modes with on-chip ROM enabled), settings in the port 1 data direction register (P1DDR) can designate pins for address bus output (A_2 to A_0) or generic input. In mode 6 and 7 (single-chip mode), port 1 is a generic input/output port.

When DRAM is connected to area 2, 3, 4, 5, A₇ to A₀ output row and column addresses in read and write cycles. For details see section 6.5, DRAM Interface.

Pins in port 1 can drive one TTL load and a 90-pF capacitive load. They can also drive an LED or a darlington transistor pair.

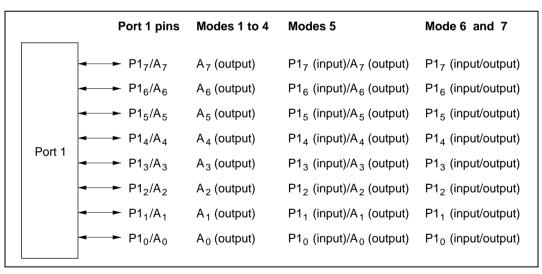


Figure 8.1 Port 1 Pin Configuration

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8.2.2 Register Descriptions

Table 8.2 summarizes the registers of port 1.

Table 8.2 Port 1 Registers

				Initial Value			
Address*	Name	Abbreviation	R/W	Modes 1 to 4	Modes 5 to 7		
H'EE000	Port 1 data direction register	P1DDR	W	H'FF	H'00		
H'FFFD0	Port 1 data register	P1DR	R/W	H'00	H'00		

Note: *Lower 20 bits of the address in advanced mode.

Port 1 Data Direction Register (P1DDR): P1DDR is an 8-bit write-only register that can select input or output for each pin in port 1.

0
P1 ₀ DDR
1
_
0
W
- R

Port 1 data direction 7 to 0
These bits select input or output for port 1 pins

Modes 1 to 4 (Expanded Modes with On-Chip ROM Disabled): P1DDR values are fixed at 1. Port 1 functions as an address bus.

Modes 5 (Expanded Modes with On-Chip ROM Enabled): After a reset, port 1 functions as an input port. A pin in port 1 becomes an address output pin if the corresponding P1DDR bit is set to 1, and a generic input pin if this bit is cleared to 0.

Mode 6 and 7 (Single-Chip Mode): Port 1 functions as an input/output port. A pin in port 1 becomes an output port if the corresponding P1DDR bit is set to 1, and an input port if this bit is cleared to 0.

In modes 1 to 4, P1DDR bits are always read as 1, and cannot be modified.

In modes 5 to 7, P1DDR is a write-only register. Its value cannot be read. All bits return 1 when read.

P1DDR is initialized to H'FF in modes 1 to 4, and to H'00 in modes 5 to 7, by a reset and in hardware standby mode. In software standby mode it retains its previous setting. Therefore, if a transition is made to software standby mode while port 1 is functioning as an input/output port and a P1DDR bit is set to 1, the corresponding pin maintains its output state.

Port 1 Data Register (P1DR): P1DR is an 8-bit readable/writable register that stores port 1 output data. When port 1 functions as an output port, the value of this register is output. When this register is read, the pin logic level is read for bits for which the P1DDR setting is 0, and the P1DR value is read for bits for which the P1DDR setting is 1.

Bit	7	6	5	4	3	2	1	0
	P1 ₇	P1 ₆	P1 ₅	P1 ₄	P1 ₃	P1 ₂	P1 ₁	P1 ₀
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W							

Port 1 data 7 to 0
These bits store data for port 1 pins

P1DR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

8.3 Port 2

8.3.1 Overview

Port 2 is an 8-bit input/output port with the pin configuration shown in figure 8.2. The pin functions differ according to the operating mode.

In modes 1 to 4 (expanded modes with on-chip ROM disabled), port 2 consists of address bus output pins (A_{15} to A_8). In modes 5 (expanded modes with on-chip ROM enabled), settings in the port 2 data direction register (P2DDR) can designate pins for address bus output (A_{15} to A_8) or generic input. In mode 6 and 7 (single-chip mode), port 2 is a generic input/output port.

When DRAM is connected to areas 2 to 5, A_{12} to A_{8} output row and column addresses in read and write cycles. For details see section 6.5, DRAM Interface.

Port 2 has software-programmable built-in pull-up transistors.

Pins in port 2 can drive one TTL load and a 90-pF capacitive load. They can also drive an LED or a darlington transistor pair.

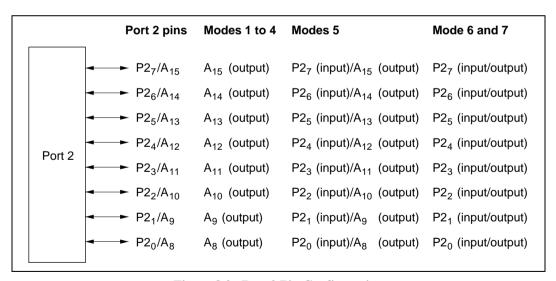


Figure 8.2 Port 2 Pin Configuration

8.3.2 Register Descriptions

Table 8.3 summarizes the registers of port 2.

Table 8.3 Port 2 Registers

				Initial	Value
Address*	Name	Abbreviation	R/W	Modes 1 to 4	Modes 5 to 7
H'EE001	Port 2 data direction register	P2DDR	W	H'FF	H'00
H'FFFD1	Port 2 data register	P2DR	R/W	H'00	H'00
H'EE03C	Port 2 input pull-up MOS control register	P2PCR	R/W	H'00	H'00

Note: *Lower 20 bits of the address in advanced mode.

Port 2 Data Direction Register (P2DDR): P2DDR is an 8-bit write-only register that can select input or output for each pin in port 2.

Bit	7	6	5	4	3	2	1	0
	P2 ₇ DDR	P2 ₆ DDR	P2 ₅ DDR	P2 ₄ DDR	P2 ₃ DDR	P2 ₂ DDR	P2 ₁ DDR	P2 ₀ DDR
Modes Initial valu		1	1	1	1	1	1	1
1 to 4 Read/Writ	te —	_	_	_	_	_	_	_
Modes Initial valu	ie 0	0	0	0	0	0	0	0
5 to 7 Read/Writ	te W	W	W	W	W	W	W	W

Port 2 data direction 7 to 0

These bits select input or output for port 2 pins

Modes 1 to 4 (Expanded Modes with On-Chip ROM Disabled): P2DDR values are fixed at 1. Port 2 functions as an address bus.

Modes 5 (Expanded Modes with On-Chip ROM Enabled): Following a reset, port 2 is an input port. A pin in port 2 becomes an address output pin if the corresponding P2DDR bit is set to 1, and a generic input port if this bit is cleared to 0.

Mode 6 and 7 (Single-Chip Mode): Port 2 functions as an input/output port. A pin in port 2 becomes an output port if the corresponding P2DDR bit is set to 1, and an input port if this bit is cleared to 0.

In modes 1 to 4, P2DDR bits are always read as 1, and cannot be modified.

In modes 5 to 7, P2DDR is a write-only register. Its value cannot be read. All bits return 1 when read.

P2DDR is initialized to H'FF in modes 1 to 4, and to H'00 in modes 5 to 7, by a reset and in hardware standby mode. In software standby mode it retains its previous setting. Therefore, if a transition is made to software standby mode while port 2 is functioning as an input/output port and a P2DDR bit is set to 1, the corresponding pin maintains its output state.

Port 2 Data Register (P2DR): P2DR is an 8-bit readable/writable register that stores output data for Port 2. When port 2 functions as an output port, the value of this register is output. When a bit in P2DDR is set to 1, if port 2 is read the value of the corresponding P2DR bit is returned. When a bit in P2DDR is cleared to 0, if port 2 is read the corresponding pin logic level is read.

Bit	7	6	5	4	3	2	1	0
	P2 ₇	P2 ₆	P2 ₅	P2 ₄	P2 ₃	P2 ₂	P2 ₁	P2 ₀
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W							

Port 2 data 7 to 0
These bits store data for port 2 pins

P2DR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

Port 2 Input Pull-Up MOS Control Register (P2PCR): P2PCR is an 8-bit readable/writable register that controls the MOS input pull-up transistors in port 2.

Bit	7	6	5	4	3	2	1	0
	P2 ₇ PCR	P2 ₆ PCR	P2 ₅ PCR	P2 ₄ PCR	P2 ₃ PCR	P2 ₂ PCR	P2 ₁ PCR	P2 ₀ PCR
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W							

Port 2 input pull-up MOS control 7 to 0

These bits control input pull-up transistors built into port 2

In modes 5 to 7, when a P2DDR bit is cleared to 0 (selecting generic input), if the corresponding bit in P2PCR is set to 1, the input pull-up transistor is turned on.

P2PCR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

Table 8.4 Input Pull-Up Transistor States (Port 2)

Mode	Reset	Hardware Standby Mode	Software Standby Mode	Other Modes	
1 2 3 4	Off	Off	Off	Off	
5 6 7	Off	Off	On/off	On/off	

Legend

Off: The input pull-up transistor is always off.

On/off: The input pull-up transistor is on if P2PCR = 1 and P2DDR = 0. Otherwise, it is off.



8.4 Port 3

8.4.1 Overview

Port 3 is an 8-bit input/output port with the pin configuration shown in figure 8.3. Port 3 is a data bus in modes 1 to 5 (expanded modes) and a generic input/output port in mode 6, 7 (single-chip mode).

Pins in port 3 can drive one TTL load and a 90-pF capacitive load. They can also drive a darlington transistor pair.

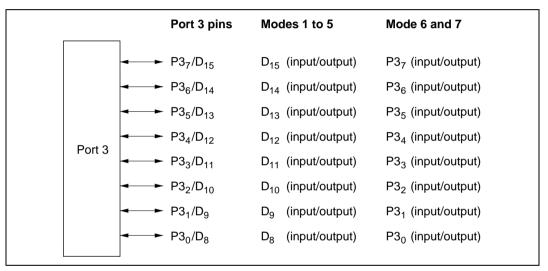


Figure 8.3 Port 3 Pin Configuration

8.4.2 Register Descriptions

Table 8.5 summarizes the registers of port 3.

Table 8.5 Port 3 Registers

Address*	Name	Abbreviation	R/W	Initial Value
H'EE002	Port 3 data direction register	P3DDR	W	H'00
H'FFFD2	Port 3 data register	P3DR	R/W	H'00

Note: *Lower 20 bits of the address in advanced mode.

Port 3 Data Direction Register (P3DDR): P3DDR is an 8-bit write-only register that can select input or output for each pin in port 3.

Bit	7	6	5	4	3	2	1	0
	P3 ₇ DDR	P3 ₆ DDR	P3 ₅ DDR	P3 ₄ DDR	P3 ₃ DDR	P3 ₂ DDR	P3 ₁ DDR	P3 ₀ DDR
Initial value	0	0	0	0	0	0	0	0
Read/Write	W	W	W	W	W	W	W	W

Port 3 data direction 7 to 0 These bits select input or output for port 3 pins

Modes 1 to 5 (Expanded Modes): Port 3 functions as a data bus, regardless of the P3DDR settings.

Mode 6 and 7 (Single-Chip Mode): Port 3 functions as an input/output port. A pin in port 3 becomes an output port if the corresponding P3DDR bit is set to 1, and an input port if this bit is cleared to 0

P3DDR is a write-only register. Its value cannot be read. All bits return 1 when read.

P3DDR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting. Therefore, if a transition is made to software standby mode while port 3 is functioning as an input/output port and a P3DDR bit is set to 1, the corresponding pin maintains its output state.

Port 3 Data Register (P3DR): P3DR is an 8-bit readable/writable register that stores output data for port 3. When port 3 functions as an output port, the value of this register is output. When a bit in P3DDR is set to 1, if port 3 is read the value of the corresponding P3DR bit is returned. When a bit in P3DDR is cleared to 0, if port 3 is read the corresponding pin logic level is read.

Bit	7	6	5	4	3	2	1	0
	P3 ₇	P3 ₆	P3 ₅	P3 ₄	P3 ₃	P3 ₂	P3 ₁	P3 ₀
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W							

Port 3 data 7 to 0 These bits store data for port 3 pins

P3DR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.



8.5 Port 4

8.5.1 Overview

Port 4 is an 8-bit input/output port with the pin configuration shown in figure 8.4. The pin functions differ depending on the operating mode.

In modes 1 to 5 (expanded modes), when the bus width control register (ABWCR) designates areas 0 to 7 all as 8-bit-access areas, the chip operates in 8-bit bus mode and port 4 is a generic input/output port. When at least one of areas 0 to 7 is designated as a 16-bit-access area, the chip operates in 16-bit bus mode and port 4 becomes part of the data bus. In mode 6, 7 (single-chip mode), port 4 is a generic input/output port.

Port 4 has software-programmable built-in pull-up transistors.

Pins in port 4 can drive one TTL load and a 90-pF capacitive load. They can also drive a darlington transistor pair.

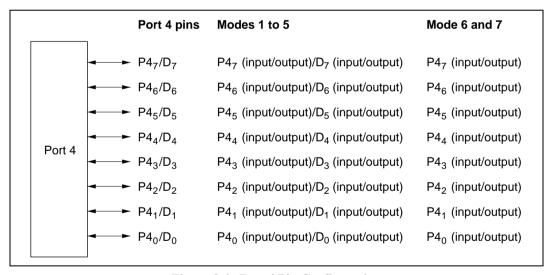


Figure 8.4 Port 4 Pin Configuration

8.5.2 Register Descriptions

Table 8.6 summarizes the registers of port 4.

Table 8.6 Port 4 Registers

Address*	Name	Abbreviation	R/W	Initial Value
H'EE003	Port 4 data direction register	P4DDR	W	H'00
H'FFFD3	Port 4 data register	P4DR	R/W	H'00
H'EE03E	Port 4 input pull-up control register	P4PCR	R/W	H'00

Note: * Lower 20 bits of the address in advanced mode.

Port 4 Data Direction Register (P4DDR): P4DDR is an 8-bit write-only register that can select input or output for each pin in port 4.

Bit	7	6	5	4	3	2	1	0
	P4 ₇ DDR	P4 ₆ DDR	P4 ₅ DDR	P4 ₄ DDR	P4 ₃ DDR	P4 ₂ DDR	P4 ₁ DDR	P4 ₀ DDR
Initial value	0	0	0	0	0	0	0	0
Read/Write	W	W	W	W	W	W	W	W

Port 4 data direction 7 to 0
These bits select input or output for port 4 pins

Modes 1 to 5 (Expanded Modes): When all areas are designated as 8-bit-access areas by the bus controller's bus width control register (ABWCR), selecting 8-bit bus mode, port 4 functions as an input/output port. In this case, a pin in port 4 becomes an output port if the corresponding P4DDR bit is set to 1, and an input port if this bit is cleared to 0.

When at least one area is designated as a 16-bit-access area, selecting 16-bit bus mode, port 4 functions as part of the data bus, regardless of the P4DDR settings.

Mode 6 and 7 (Single-Chip Mode): Port 4 functions as an input/output port. A pin in port 4 becomes an output port if the corresponding P4DDR bit is set to 1, and an input port if this bit is cleared to 0.

P4DDR is a write-only register. Its value cannot be read. All bits return 1 when read.

P4DDR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

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ABWCR and P4DDR are not initialized in software standby mode. Therefore, if a transition is made to software standby mode while port 4 is functioning as an input/output port and a P4DDR bit is set to 1, the corresponding pin maintains its output state.

Port 4 Data Register (P4DR): P4DR is an 8-bit readable/writable register that stores output data for port 4. When port 4 functions as an output port, the value of this register is output. When a bit in P4DDR is set to 1, if port 4 is read the value of the corresponding P4DR bit is returned. When a bit in P4DDR is cleared to 0, if port 4 is read the corresponding pin logic level is read.

Bit	7	6	5	4	3	2	1	0
	P4 ₇	P4 ₆	P4 ₅	P4 ₄	P4 ₃	P4 ₂	P4 ₁	P4 ₀
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W							

Port 4 data 7 to 0
These bits store data for port 4 pins

P4DR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

Port 4 Input Pull-Up MOS Control Register (P4PCR): P4PCR is an 8-bit readable/writable register that controls the MOS input pull-up transistors in port 4.

Bit	7	6	5	4	3	2	1	0
	P4 ₇ PCR	P4 ₆ PCR	P4 ₅ PCR	P4 ₄ PCR	P4 ₃ PCR	P4 ₂ PCR	P4 ₁ PCR	P4 ₀ PCR
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W							

Port 4 input pull-up control 7 to 0

These bits control input pull-up transistors built into port 4

In mode 6 and 7 (single-chip mode), and in 8-bit bus mode in modes 1 to 5 (expanded modes), when a P4DDR bit is cleared to 0 (selecting generic input), if the corresponding P4PCR bit is set to 1, the input pull-up transistor is turned on.

P4PCR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

Table 8.7 summarizes the states of the input pull-ups in each operating mode.

Table 8.7 Input Pull-Up Transistor States (Port 4)

Mode		Reset	Hardware Standby Mode	Software Standby Mode	Other Modes
1 to 5	8-bit bus mode	Off	Off	On/off	On/off
	16-bit bus mode	=		Off	Off
6 and 7		=		On/off	On/off

Legend

Off: The input pull-up transistor is always off.

On/off: The input pull-up transistor is on if P4PCR = 1 and P4DDR = 0. Otherwise, it is off.



8.6 Port 5

8.6.1 Overview

Port 5 is a 4-bit input/output port with the pin configuration shown in figure 8.5. The pin functions differ depending on the operating mode.

In modes 1 to 4 (expanded modes with on-chip ROM disabled), port 5 consists of address output pins (A_{19} to A_{16}). In modes 5 (expanded modes with on-chip ROM enabled), settings in the port 5 data direction register (P5DDR) designate pins for address bus output (A_{19} to A_{16}) or generic input. In mode 6, 7 (single-chip mode), port 5 is a generic input/output port.

Port 5 has software-programmable built-in pull-up transistors.

Pins in port 5 can drive one TTL load and a 90-pF capacitive load. They can also drive an LED or a darlington transistor pair.

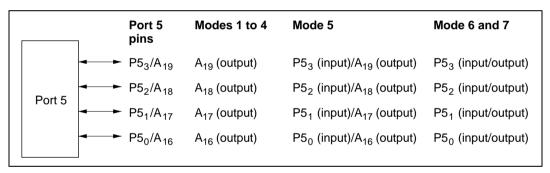


Figure 8.5 Port 5 Pin Configuration

8.6.2 Register Descriptions

Table 8.8 summarizes the registers of port 5.

Table 8.8 Port 5 Registers

				Initial Value	
Address*	Name	Abbreviation	R/W	Modes 1 to 4	Modes 5 to 7
H'EE004	Port 5 data direction register	P5DDR	W	H'FF	H'F0
H'FFFD4	Port 5 data register	P5DR	R/W	H'F0	H'F0
H'EE03F	Port 5 input pull-up control register	P5PCR	R/W	H'F0	H'F0

Note: * Lower 20 bits of the address in advanced mode.

Port 5 Data Direction Register (P5DDR): P5DDR is an 8-bit write-only register that can select input or output for each pin in port 5.

Bits 7 to 4 are reserved. They are fixed at 1, and cannot be modified.

Bit	7	6	5	4	3	2	1	0
	_	_	_	_	P5 ₃ DDR	P5 ₂ DDR	P5₁DDR	P5 ₀ DDR
Modes∫Initial valu	e 1	1	1	1	1	1	1	1
1 to 4 Read/Writ	e —	_	_	_	_	_	_	
Modes∫Initial valu	e 1	1	1	1	0	0	0	0
5 to 7 Read/Writ	e				W	W	W	W
Reserved bits						rt 5 data c ese bits se		

Modes 1 to 4 (Expanded Modes with On-Chip ROM Disabled): P5DDR values are fixed at 1. Port 5 functions as an address bus.

output for port 5 pins

Modes 5 (Expanded Modes with On-Chip ROM Enabled): Following a reset, port 5 is an input port. A pin in port 5 becomes an address output pin if the corresponding P5DDR bit is set to 1, and an input port if this bit is cleared to 0.

Mode 6 and 7 (Single-Chip Mode): Port 5 functions as an input/output port. A pin in port 5 becomes an output port if the corresponding P5DDR bit is set to 1, and an input port if this bit is cleared to 0.

In modes 1 to 4, P5DDR bits are always read as 1, and cannot be modified.

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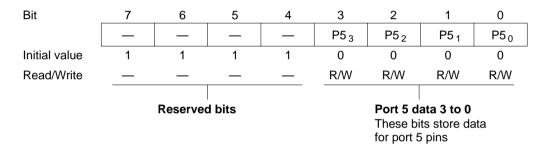


In modes 5 to 7, P5DDR is a write-only register. Its value cannot be read. All bits return 1 when read.

P5DDR is initialized to H'FF in modes 1 to 4, and to H'F0 in modes 5 to 7, by a reset and in hardware standby mode. In software standby mode it retains its previous setting. Therefore, if a transition is made to software standby mode while port 5 is functioning as an input/output port and a P5DDR bit is set to 1, the corresponding pin maintains its output state.

Port 5 Data Register (P5DR): P5DR is an 8-bit readable/writable register that stores output data for port 5. When port 5 functions as an output port, the value of this register is output. When a bit in P5DDR is set to 1, if port 5 is read the value of the corresponding P5DR bit is returned. When a bit in P5DDR is cleared to 0, if port 5 is read the corresponding pin logic level is read.

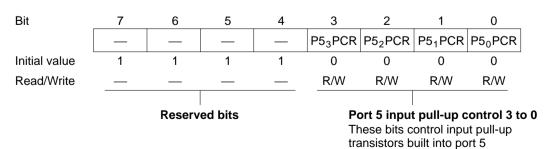
Bits 7 to 4 are reserved. They are fixed at 1, and cannot be modified.



P5DR is initialized to H'F0 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

Port 5 Input Pull-Up MOS Control Register (P5PCR): P5PCR is an 8-bit readable/writable register that controls the MOS input pull-up transistors in port 5.

Bits 7 to 4 are reserved. They are fixed at 1, and cannot be modified.



In modes 5 to 7, when a P5DDR bit is cleared to 0 (selecting generic input), if the corresponding bit in P5PCR is set to 1, the input pull-up transistor is turned on.

P5PCR is initialized to H'F0 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

Table 8.9 summarizes the states of the input pull-ups in each mode.

Input Pull-Up Transistor States (Port 5) Table 8.9

Mode	Reset	Hardware Standby Mode	Software Standby Mode	Other Modes
1 2 3 4	Off	Off	Off	Off
5 6 7	Off	Off	On/off	On/off

Legend

Off: The input pull-up transistor is always off.

On/off: The input pull-up transistor is on if P5PCR = 1 and P5DDR = 0. Otherwise, it is off.



8.7 Port 6

8.7.1 Overview

Port 6 is an 8-bit input/output port that is also used for input and output of bus control signals (\overline{LWR} , \overline{HWR} , \overline{RD} , \overline{AS} , \overline{BACK} , \overline{BREQ} , \overline{WAIT}) and for clock (ϕ) output.

In modes 1 to 5 (expanded modes), the pin functions are $P6_7$ (generic input)/ ϕ , \overline{LWR} , \overline{HWR} , \overline{RD} , \overline{AS} , $P6_2/\overline{BACK}$, $P6_1/\overline{BREQ}$, and $P6_0/\overline{WAIT}$). See table 8.11 for the selection of the pin functions. In modes 6 and 7 (single-chip modes), $P6_7$ functions as a generic input port or \emptyset output, and $P6_6$ to $P6_0$ function as generic input/output ports.

When DRAM is connected to areas 2 to 5, \overline{LWR} , \overline{HWR} , and \overline{RD} also function as \overline{LCAS} , \overline{UCAS} , and \overline{WE} , respectively. For details see section 6.5, DRAM Interface.

Pins in port 6 can drive one TTL load and a 90-pF capacitive load. They can also drive a darlington transistor pair.

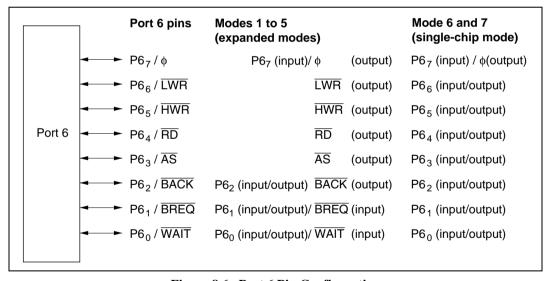


Figure 8.6 Port 6 Pin Configuration

8.7.2 **Register Descriptions**

Table 8.10 summarizes the registers of port 6.

Table 8.10 Port 6 Registers

Address*	Name	Abbreviation	R/W	Initial Value
H'EE005	Port 6 data direction register	P6DDR	W	H'80
H'FFFD5	Port 6 data register	P6DR	R/W	H'80

Note: *Lower 20 bits of the address in advanced mode.

Port 6 Data Direction Register (P6DDR): P6DDR is an 8-bit write-only register that can select input or output for each pin in port 6.

Bit 7 is reserved. It is fixed at 1, and cannot be modified.

Bit		7	6	5	4	3	2	1	0
		_	P6 ₆ DDR	P6 ₅ DDR	P6 ₄ DDR	P6 ₃ DDR	P6 ₂ DDR	P6₁DDR	P6 ₀ DDR
Initial value		1	0	0	0	0	0	0	0
Read/Write	_		W	W	W	W	W	W	W
	Res	erved b	oit		ion 6 to 0		rt 6 pins		

Modes 1 to 5 (Expanded Modes): P6, functions as the clock output pin (ϕ) or an input port. P6, is the clock output pin (Ø) if the PSTOP bit in MSTRCH is cleared to 0 (initial value), and an input port if this bit is set to 1.

 $P6_6$ to $P6_3$ function as bus control output pins (\overline{LWR} , \overline{HWR} , \overline{RD} , and \overline{AS}), regardless of the settings of bits P6₂DDR to P6₃DDR.

P6₂ to P6₀ function as bus control input/output pins (BACK, BREQ, and WAIT) or input/output ports. For the method of selecting the pin functions, see table 8.11.

When P6, to P6₀ function as input/output ports, the pin becomes an output port if the corresponding P6DDR bit is set to 1, and an input port if this bit is cleared to 0.

Mode 6 and 7 (Single-Chip Mode): P6, functions as the clock output pin (ϕ) or an input port. P6, to P6₀ function as generic input/output ports. P6₇ is the clock output pin (φ) if the PSTOP bit in MSTCRH is cleared to 0 (initial value), and an input port if this bit is set to 1. A pin in port 6



becomes an output port if the corresponding bit of P6₆DDR to P6₀DDR is set to 1, and an input port if this pin is cleared to 0.

P6DDR is a write-only register. Its value cannot be read. All bits return 1 when read.

P6DDR is initialized to H'80 by a reset and in hardware standby mode. In software standby mode it retains its previous setting. Therefore, if a transition is made to software standby mode while port 6 is functioning as an input/output port and a P6DDR bit is set to 1, the corresponding pin maintains its output state.

Port 6 Data Register (P6DR): P6DR is an 8-bit readable/writable register that stores output data for port 6. When port 6 functions as an output port, the value of this register is output. For bit 7, a value of 1 is returned if the bit is read while the PSTOP bit in MSTCRH is cleared to 0, and the P67 pin logic level is returned if the bit is read while the PSTOP bit is set to 1. Bit 7 cannot be modified. For bits 6 to 0, the pin logic level is returned if the bit is read while the corresponding bit in P6DDR is cleared to 0, and the P6DR value is returned if the bit is read while the corresponding bit in P6DDR is set to 1.

Bit	7	6	5	4	3	2	1	0
	P6 ₇	P6 ₆	P6 ₅	P6 ₄	P6 ₃	P6 ₂	P6 ₁	P6 ₀
Initial value	1	0	0	0	0	0	0	0
Read/Write	R	R/W						
	Port 6 data 7 to 0							

These bits store data for port 6 pins

P6DR is initialized to H'80 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

Table 8.11 Port 6 Pin Functions in Modes 1 to 5

Pin	Pin Functions and S	Pin Functions and Selection Method								
P6,/ф	Bit PSTOP in MSTCRH selects the pin function.									
	PSTOP		0	1						
	Pin function	ф О	utput	P6, input						
LWR	Functions as LWR reg	ardless of the setti	ng of bit P6 ₆ DDR							
	P6₅DDR		0	1						
	Pin function		LWR c	putput*						
	· · · · · · · · · · · · · · · · · · ·	DRAS2 to DRAS0 ons as LCAS.	in DRCRA is 1 and	d bit CSEL in DRCRB is 1, LWR						
HWR	Functions as HWR re	gardless of the setti	ing of bit P6₅DDR							
	P6₅DDR		0	1						
	Pin function		HWR o	output*						
		Note: * If any of bits DRAS2 to DRAS0 in DRCRA is 1 and bit CSEL in DRCRB is 1, HWR output functions as UCAS.								
RD	Functions as RD rega	rdless of the setting	g of bit P6 ₄ DDR							
	P6₄DDR		0	1						
	Pin function		RD output*							
	Note: * If any of bits	Note: * If any of bits DRAS2 to DRAS0 in DRCRA is 1, $\overline{\text{RD}}$ output functions as $\overline{\text{WE}}$.								
ĀS	Functions as $\overline{\text{AS}}$ regardless of the setting of bit P6 ₃ DDR									
	P6 ₃ DDR		0	1						
	Pin function		ĀS o	utput						
P6 ₂ /BACK	Bit BRLE in BRCR an	d bit P6 ₂ DDR selec	t the pin function a	s follows						
	BRLE		0	1						
	P6 ₂ DDR	0	1	_						
	Pin function	P6 ₂ input	P6 ₂ output	BACK output						
P6,/BREQ	Bit BRLE in BRCR and bit P6,DDR select the pin function as follows									
	BRLE		0	1						
	P6₁DDR	0	1	_						
	Pin function	P6, input P6, output		BREQ input						
P6 ₀ /WAIT	Bit WAITE in BCR and	Bit WAITE in BCR and bit P6 ₀ DDR select the pin function as follows.								
	WAITE		0	1						
	P6 ₀ DDR	0	1	0*						
	Pin function	P6₀ input	P6 _o output	WAIT input						
	Note: * Do not set bit P6 ₀ DDR to 1.									

8.8 Port 7

8.8.1 Overview

Port 7 is an 8-bit input port that is also used for analog input to the A/D converter and analog output from the D/A converter. The pin functions are the same in all operating modes. Figure 8.7 shows the pin configuration of port 7.

See section 15, A/D Converter, for details of the A/D converter analog input pins, and section 16, D/A Converter, for details of the D/A converter analog output pins.

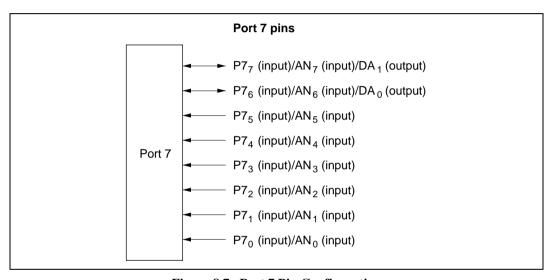


Figure 8.7 Port 7 Pin Configuration

8.8.2 **Register Description**

Table 8.12 summarizes the port 7 register. Port 7 is an input port, and port 7 has no data direction register.

Table 8.12 Port 7 Data Register

Address*	Name	Abbreviation	R/W	Initial Value
H'FFFD6	Port 7 data register	P7DR	R	Undetermined

Note: *Lower 20 bits of the address in advanced mode.

Port 7 Data Register (P7DR)

Bit	7	6	5	4	3	2	1	0
	P7 ₇	P7 ₆	P7 ₅	P7 ₄	P7 ₃	P7 ₂	P7 ₁	P7 ₀
Initial value	*	*	*	*	*	*	*	*
Read/Write	R	R	R	R	R	R	R	R

Note: * Determined by pins P7₇ to P7₀.

When port 7 is read, the pin logic levels are always read. P7DR cannot be modified.



8.9 Port 8

8.9.1 Overview

Port 8 is a 5-bit input/output port that is also used for \overline{CS}_3 to \overline{CS}_0 output, \overline{RFSH} output, \overline{IRQ}_3 to \overline{IRQ}_0 input, and A/D converter \overline{ADTRG} input. Figure 8.8 shows the pin configuration of port 8.

In modes 1 to 5 (expanded modes), port 8 can provide \overline{CS}_3 to \overline{CS}_0 output, \overline{RFSH} output, \overline{IRQ}_3 to \overline{IRQ}_0 input, and \overline{ADTRG} input. See table 8.14 for the selection of pin functions in expanded modes.

In modes 6 and 7 (single-chip modes), port 8 can provide \overline{IRQ}_3 to \overline{IRQ}_0 input and \overline{ADTRG} input. See table 8.15 for the selection of pin functions in single-chip mode.

See section 15, A/D Converter, for a description of the A/D converter's ADTRG input pin.

The \overline{IRQ}_3 to \overline{IRQ}_0 functions are selected by IER settings, regardless of whether the pin is used for input or output. Caution is therefore required. For details see section 5.3.1, External Interrupts.

When DRAM is connected to areas 2 to 5, the \overline{CS}_3 and \overline{CS}_2 output pins function as \overline{RAS} output pins for each area. For details see section 6.5, DRAM Interface.

Pins in port 8 can drive one TTL load and a 90-pF capacitive load. They can also drive a darlington transistor pair.

Pins P8, to P8, have Schmitt-trigger inputs.

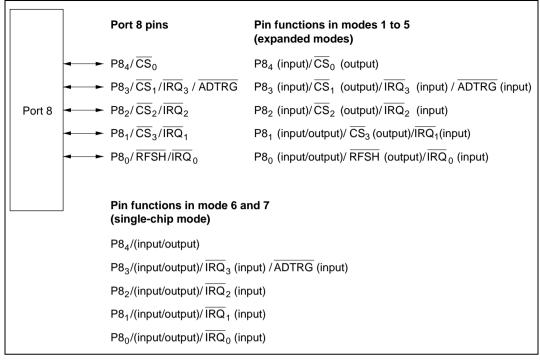


Figure 8.8 Port 8 Pin Configuration

8.9.2 Register Descriptions

Table 8.13 summarizes the registers of port 8.

Table 8.13 Port 8 Registers

				Initial Value	
Address*	Name	Abbreviation	R/W	Mode 1 to 4	Mode 5 to 7
H'EE007	Port 8 data direction register	P8DDR	W	H'F0	H'E0
H'FFFD7	Port 8 data register	P8DR	R/W	H'E0	H'E0

Note: *Lower 20 bits of the address in advanced mode.

Port 8 Data Direction Register (P8DDR): P8DDR is an 8-bit write-only register that can select input or output for each pin in port 8.

Bits 7 to 5 are reserved. They are fixed at 1, and cannot be modified.

Bit	_	7	6	5	. 4	3	2	1	0
		_	_	_	P8 ₄ DDR	P8 ₃ DDR	P8 ₂ DDR	P8₁DDR	P8 ₀ DDR
Modes	Initial value	1	1	1	1	0	0	0	0
1 to 4	Read/Write	_	_	_	W	W	W	W	W
Modes	Initial value	1	1	1	0	0	0	0	0
5 to 7	Read/Write	_	_	_	W	W	W	W	W
		F	Reserved	bits		These bit	ata directi ts select in r port 8 pir	put or	

Modes 1 to 5 (Expanded Modes): When bits in P8DDR bit are set to 1, P8₁ to P8₁ become $\overline{\text{CS}}_0$ to $\overline{\text{CS}}_3$ output pins. When bits in P8DDR are cleared to 0, the corresponding pins become input ports. However, P8₁ can also be used as an output port, depending on the setting of bits DRAS2 to DRAS0 in DRAM control register A (DRCRA). For details see section 6.5.2, DRAM Space and $\overline{\text{RAS}}$ Output Pin Settings.

In modes 1 to 4 (expanded modes with on-chip ROM disabled), following a reset P8₄ functions as the \overline{CS}_0 output, while \overline{CS}_1 to \overline{CS}_3 are input ports. In mode 5 (expanded mode with on-chip ROM enabled), following a reset \overline{CS}_0 to \overline{CS}_3 are all input ports.

When the refresh enable bit (RFSHE) in DRCRA is set to 1, $P8_0$ is used for \overline{RFSH} output. When RFSHE is cleared to 0, $P8_0$ becomes an input/output port according to the P8DDR setting. For details see table 8.14.

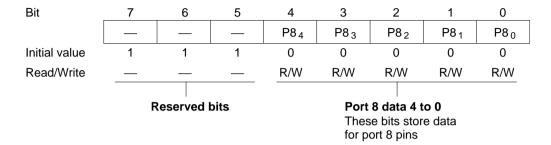
Mode 6 and 7 (Single-Chip Mode): Port 8 is a generic input/output port. A pin in port 8 becomes an output port if the corresponding P8DDR bit is set to 1, and an input port if this bit is cleared to 0.

P8DDR is a write-only register. Its value cannot be read. All bits return 1 when read.

P8DDR is initialized to H'F0 in modes 1 to 4, and to H'E0 in modes 5 to 7, by a reset and in hardware standby mode. In software standby mode P8DDR retains its previous setting. Therefore, if a transition is made to software standby mode while port 8 is functioning as an input/output port and a P8DDR bit is set to 1, the corresponding pin maintains its output state.

Port 8 Data Register (P8DR): P8DR is an 8-bit readable/writable register that stores output data for port 8. When port 8 functions as an output port, the value of this register is output. When a bit in P8DDR is set to 1, if port 8 is read the value of the corresponding P8DR bit is returned. When a bit in P8DDR is cleared to 0, if port 8 is read the corresponding pin logic level is read.

Bits 7 to 5 are reserved. They are fixed at 1, and cannot be modified.



P8DR is initialized to H'E0 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

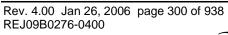


Table 8.14 Port 8 Pin Functions in Modes 1 to 5

Pin	Pin Functions and	Selection Me	thod						
P8 ₄ / CS ₀	Bit P8 ₄ DDR selects the pin function as follows								
	P8 ₄ DDR 0				1				
	Pin function		P8₄ inp	ut			$\overline{\text{CS}}_{_{\scriptscriptstyle{0}}}$ c	output	
P8 ₃ /CS ₁ /IRQ ₃ /ADTRG	Bit P8 ₃ DDR selects the pin function as follows								
	P8 ₃ DDR	0						1	
	Pin function		P8₃ inp	ut			CS₁ c	output	
					ĪRQ ₃	input			
					ADTR	G input			
P8 ₂ /CS ₂ /IRQ ₂	The DRAM interface pin function as follow		its DRAS2	to D	DRAS0 in D	RCRA, and	bit P8	DDR, sel	lect the
	DRAM interface	,	4) :- t-l-l- l	l l		1/0	\ ! 4-I		
	settings	(1) in tab		belo	<u>w</u> 1	(2) in tai	ole below	
	P8 ₂ DDR Pin function	0	n 4	<u> </u>	, output				
	Pin function	P8 ₂ in	pui	US		input	US ₂ 0	utput*	
	Note: * \overline{CS}_s is output	as RAS.			111043	прис			
	DRAM interface	2				(0)			
	setting DRAS2	(1) 0			(2)				
	DRAS1	0	0 1		1	0		1	
	DRAS0	0	1	0	1	0	1	0	1
P8 ₁ /CS ₃ /IRQ ₁	The DRAM interface pin function as follow DRAM interface settings	's.	its DRAS2			ORCRA, and		in table b	
	P8,DDR	0	1			1	ζ-,	_	
	Pin function	P8 ₁ input				P8 ₁ output $\overline{\text{CS}}_3$ out		S₃ output	pin*
		pin	pin	·		·			
	Note: * \overline{CS}_3 is output as \overline{RAS}_3 .								
	DRAM interface	put as nAO ₃ .							
	setting	(1)		(3)	(2)	(3)	(2))
	DRAS2		0				1		
	DRAS1	0			1	0		1	
	DRAS0	0	1	0	1	0	1	0	1
P8 ₀ /RFSH/IRQ ₀	Bit RFSHE in DRCR	A and bit P8 ₀	DDR selec	t the	pin function	on as follows	S.		
	RFSHE		0				1	*	
	P8 ₀ DDR	0		1		_			
	Pin function	P8₀ in	put	P8 _o output		RFSH output			
					ĪRQ₀	input			
	Note: * If areas 2 to	5 are not de	esignated a	as Di	RAM snace	this hit sho	ould n	nt he set t	o 1

Table 8.15 Port 8 Pin Functions in Mode 6 and 7

Pin	Pin Functions and Sel	ection Method						
P8 ₄	Bit P8 ₄ DDR selects the pin function as follows							
	P8 ₄ DDR	0	1					
	Pin function	P8, input	P8 ₄ output					
P8,/IRQ,/ADTRG	Bit P8 ₃ DDR selects the	pin function as follows						
	P8 ₃ DDR	0	1					
	Pin function	P8 ₃ input	P8 ₃ output					
		IRQ ₃ input						
		G input						
P8 _z /IRQ ₂	Bit P8 ₂ DDR selects the pin function as follows							
	P8 ₂ DDR	0	1					
	Pin function	P8 ₂ input P8 ₂ output						
	ĪRQ ₂ input							
P8,/IRQ,	Bit P8,DDR selects the pin function as follows							
	P8,DDR	0	1					
	Pin function	P8₁ input	P8, output					
		ĪRQ,	input					
P8 ₀ /IRQ ₀	Bit P8,DDR select the pin function as follows							
	P8 ₀ DDR	0	1					
	Pin function	P8 _o input	P8 _o output					
		ĪRQ₀ input						





8.10 Port 9

8.10.1 Overview

Port 9 is a 6-bit input/output port that is also used for input and output $(TxD_0, TxD_1, RxD_0, RxD_1, SCK_0, SCK_1)$ by serial communication interface channels 0 and 1 (SCI0 and SCI1), and for \overline{IRQ}_5 and \overline{IRQ}_4 input. See table 8.17 for the selection of pin functions.

The \overline{IRQ}_5 and \overline{IRQ}_4 functions are selected by IER settings, regardless of whether the pin is used for input or output. Caution is therefore required. For details see section 5.3.1, External Interrupts.

Port 9 has the same set of pin functions in all operating modes. Figure 8.9 shows the pin configuration of port 9.

Pins in port 9 can drive one TTL load and a 30-pF capacitive load. They can also drive a darlington transistor pair.

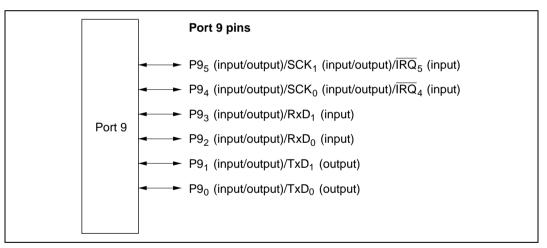


Figure 8.9 Port 9 Pin Configuration

8.10.2 Register Descriptions

Table 8.16 summarizes the registers of port 9.

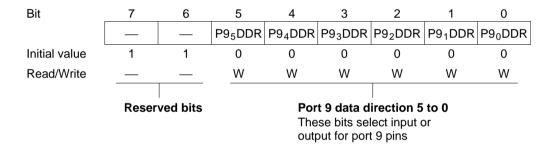
Table 8.16 Port 9 Registers

Address*	Name	Abbreviation	R/W	Initial Value
H'EE008	Port 9 data direction register	P9DDR	W	H'C0
H'FFFD8	Port 9 data register	P9DR	R/W	H'C0

Note: *Lower 20 bits of the address in advanced mode.

Port 9 Data Direction Register (P9DDR): P9DDR is an 8-bit write-only register that can select input or output for each pin in port 9.

Bits 7 and 6 are reserved. They are fixed at 1, and cannot be modified.



When port 9 functions as an input/output port, a pin in port 9 becomes an output port if the corresponding P9DDR bit is set to 1, and an input port if this bit is cleared to 0. For the method of selecting the pin functions, see table 8.17.

P9DDR is a write-only register. Its value cannot be read. All bits return 1 when read.

P9DDR is initialized to H'C0 by a reset and in hardware standby mode. In software standby mode it retains its previous setting. Therefore, if a transition is made to software standby mode while port 9 is functioning as an input/output port and a P9DDR bit is set to 1, the corresponding pin maintains its output state.

Port 9 Data Register (P9DR): P9DR is an 8-bit readable/writable register that stores output data for port 9. When port 9 functions as an output port, the value of this register is output. When a bit in P9DDR is set to 1, if port 9 is read the value of the corresponding P9DR bit is returned. When a bit in P9DDR is cleared to 0, if port 9 is read the corresponding pin logic level is read.

Bits 7 and 6 are reserved. They are fixed at 1, and cannot be modified.

Bit	7	6	5	4	3	2	1	0
	_	_	P9 ₅	P9 ₄	P9 ₃	P9 ₂	P9 ₁	P9 ₀
Initial value	1	1	0	0	0	0	0	0
Read/Write	_	_	R/W	R/W	R/W	R/W	R/W	R/W
	Reserv	ed bits			Port 9 da	ata 5 to 0		
					These bit for port 9	s store da pins	ta	

P9DR is initialized to H'C0 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

Table 8.17 Port 9 Pin Functions

Pin	Pin Functions and	Selection N	Method						
P9 ₅ /SCK ₁ /IRQ ₅	Bit C/ \overline{A} in SMR of SCI1, bits CKE0 and CKE1 in SCR, and bit P9 $_{\rm s}$ DDR select the pin function as follows								
	CKE1		0			1			
	C/Ā		0		1	_			
	CKE0		0	1	_	_			
	P9₅DDR	0	1	_	_	_			
	Pin function	P9₅ input	P9₅ output	SCK, output	SCK, output	SCK, input			
			•	ĪRQ _s	input				
P9 ₄ /SCK ₀ /IRQ ₄	Bit C/A in SMR of SCI0, bits CKE0 and CKE1 in SCR, and bit P9 ₄ DDR select the pin function as follows								
	CKE1			0		1			
	C/Ā		0		1	_			
	CKE0	(0 1		_	_			
	P9₄DDR	0	1	_	_	_			
	Pin function	P9 ₄ input	P9 ₄ output	SCK₀ output	SCK₀ output	SCK₀ input			
				ĪRQ ₄	input				
P9 ₃ /RxD ₁	Bit RE in SCR of S	CI1, bit SMIF	in SCMR	, and bit P9 ₃ DDR	select the pin fund	ction as follows			
	SMIF			0		1			
	RE		()	1	_			
	P9 ₃ DDR	(0		_	_			
	Pin function	P9 ₃	input	P9 ₃ output	RxD₁ input	RxD₁ input			
P9 ₂ /RxD ₀	Bit RE in SCR of S	CI0, bit SMIF	in SCMR	, and bit P9 ₂ DDR	select the pin fund	ction as follows			
	SMIF			0		1			
	RE		()	1				
	P9 ₂ DDR		0	1	_				
	Pin function	P9 ₂	input	P9 ₂ output	RxD₀ input	RxD₀ input			

Bit TE in SCR of SCI1, SMIF TE P9, DDR	(0	· · · · · · · · · · · · · · · · · · ·	tion as follows.		
ГЕ			T .	1		
)				
P9, DDR	_		1	_		
	0	1	_	_		
Pin function	P9₁ input	P9₁ output	TxD₁ output	TxD₁ output*		
Note: * Functions as the TxD, output pin, but there are two states: one in which the pindriven, and another in which the pin is at high-impedance. Bit TE in SCR of SCI0, bit SMIF in SCMR, and bit P9,DDR select the pin function as follows:						
SMIF	0			1		
ГЕ	()	1	_		
P9 ₀ DDR	0	1	_	_		
Pin function P9, input P9, output TxD, outp				TxD ₀ output*		
	driven, and a Bit TE in SCR of SCI0, SMIF TE P9,DDR Pin function Note: * Functions as	driven, and another in which the Bit TE in SCR of SCI0, bit SMIF in SCMR SMIF TE OP, DDR OPin function P9, input Note: * Functions as the TxD, output pin	driven, and another in which the pin is at high-implication of the pin is at high-implication of the pin is at high-implication. Bit TE in SCR of SCI0, bit SMIF in SCMR, and bit P9,0DDR OFFICE OFFIC	driven, and another in which the pin is at high-impedance. Bit TE in SCR of SCI0, bit SMIF in SCMR, and bit P9 DDR select the pin function O 1 P9 DDR 0 1 P1 Hongton P9 input P9 output TxD output		

8.11 Port A

8.11.1 Overview

Port A is an 8-bit input/output port that is also used for output (TP_7 to TP_0) from the programmable timing pattern controller (TPC), input and output, (TIOCB₂, TIOCA₂, TIOCB₁, TIOCA₁, TIOCB₀, TIOCA₀, TCLKD, TCLKC, TCLKB, TCLKA) by the 16-bit timer, input (TCLKD, TCLKC, TCLKB, TCLKA) to the 8-bit timer, output ($\overline{TEND_1}$, $\overline{TEND_0}$) from the DMA controller (DMAC), and address output (A_{23} to A_{20}). A reset or hardware standby transition leaves port A as an input port, except that in modes 3 and 4, one pin is always used for A_{20} output. See table 8.19 to 8.21 for the selection of pin functions.

Usage of pins for TPC, 16-bit timer, 8-bit timer, and DMAC input and output is described in the sections on those modules. For output of address bits A_{23} to A_{20} in modes 3, 4, and 5, see section 6.2.4, Bus Release Control Register (BRCR). Pins not assigned to any of these functions are available for generic input/output. Figure 8.10 shows the pin configuration of port A.

Pins in port A can drive one TTL load and a 30-pF capacitive load. They can also drive a darlington transistor pair. Port A has Schmitt-trigger inputs.



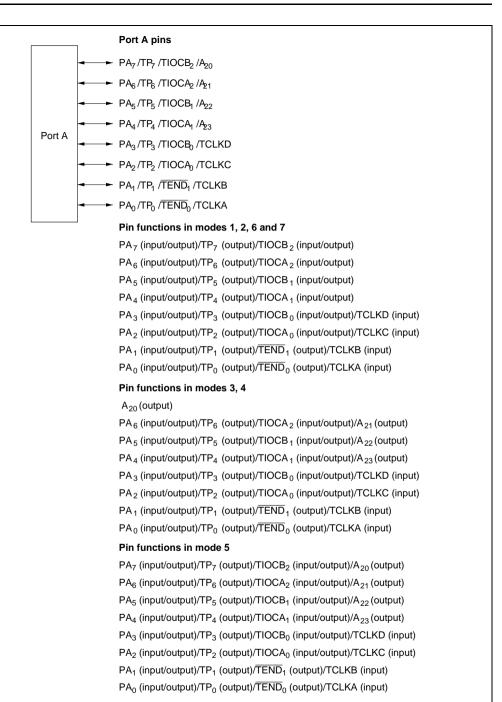


Figure 8.10 Port A Pin Configuration

8.11.2 Register Descriptions

Table 8.18 summarizes the registers of port A.

Table 8.18 Port A Registers

				Initial Value	
Address*	Name		R/W	Modes 1, 2, 5, 6 and 7	Modes 3, 4
H'EE009	Port A data direction register	PADDR	W	H'00	H'80
H'FFFD9	Port A data register	PADR	R/W	H'00	H'00

Note: * Lower 20 bits of the address in advanced mode.

Port A Data Direction Register (PADDR): PADDR is an 8-bit write-only register that can select input or output for each pin in port A. When pins are used for TPC output, the corresponding PADDR bits must also be set.

Bit		7	6	5	4	3	2	1	0
		PA ₇ DDR	PA ₆ DDR	PA ₅ DDR	PA ₄ DDR	PA ₃ DDR	PA ₂ DDR	PA ₁ DDR	PA ₀ DDR
Modes	Initial valu	ie 1	0	0	0	0	0	0	0
3, 4	Read/Wri	te —	W	W	W	W	W	W	W
Modes 1, 2, 5,	Initial valu	ue 0	0	0	0	0	0	0	0
6 and 7	Read/Wri	te W	W	W	W	W	W	W	W

Port A data direction 7 to 0
These bits select input or output for port A pins

The pin functions that can be selected for pins PA_7 to PA_4 differ between modes 1, 2, 6, and 7, and modes 3 to 5. For the method of selecting the pin functions, see tables 8.19 and 8.20.

The pin functions that can be selected for pins PA₃ to PA₀ are the same in modes 1 to 7. For the method of selecting the pin functions, see table 8.21.

When port A functions as an input/output port, a pin in port A becomes an output port if the corresponding PADDR bit is set to 1, and an input port if this bit is cleared to 0. In modes 3 and 4, PA_7DDR is fixed at 1 and PA_7 functions as the A_{20} address output pin.

PADDR is a write-only register. Its value cannot be read. All bits return 1 when read.

PADDR is initialized to H'00 by a reset and in hardware standby mode in modes 1, 2, 5, 6, and 7. It is initialized to H'80 by a reset and in hardware standby mode in modes 3 and 4. In software standby mode it retains its previous setting. Therefore, if a transition is made to software standby mode while port A is functioning as an input/output port and a PADDR bit is set to 1, the corresponding pin maintains its output state.

Port A Data Register (PADR): PADR is an 8-bit readable/writable register that stores output data for port A. When port A functions as an output port, the value of this register is output. When a bit in PADDR is set to 1, if port A is read the value of the corresponding PADR bit is returned. When a bit in PADDR is cleared to 0, if port A is read the corresponding pin logic level is read.

Bit	7	6	5	4	3	2	1	0
	PA ₇	PA ₆	PA ₅	PA ₄	PA_3	PA_2	PA ₁	PA ₀
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Port A data 7 to 0
These bits store data for port A pins

PADR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

Table 8.19 Port A Pin Functions (Modes 1, 2, 6, 7)

Pin Pin Functions and Selection Method

PA7/TP7/ TIOCB₃ Bit PWM2 in TMDR, bits IOB2 to IOB0 in TIOR2, bit NDER7 in NDERA, and bit PA7DDR select the pin function as follows.

16-bit timer channel 2 settings	(1) in table below	(2	2) in table belo	w
PA,DDR	_	0	1	1
NDER7	_	_	0	1
Pin function	TIOCB ₂ output	PA, input	PA, output	TP, output
			TIOCB ₂ input*	

Note: * TIOCB, input when IOB2 = 1 and PWM2 = 0.

16-bit timer channel 2 settings	(2)	(*	1)	(2)
IOB2	0			1
IOB1	0	0	1	_
IOB0	0	1	_	_

PA,/TP,/ TIOCA, Bit PWM2 in TMDR, bits IOA2 to IOA0 in TIOR2, bit NDER6 in NDERA, and bit $PA_{\rm e}DDR$ select the pin function as follows.

16-bit timer channel 2 settings	(1) in table below	(2	2) in table belo	w
PA ₆ DDR	_	0	1	1
NDER6	_	_	0	1
Pin function	TIOCA ₂ output	PA ₆ input	PA ₆ output	TP ₆ output
			TIOCA ₂ input*	

Note: * TIOCA, input when IOA2 = 1.

16-bit timer channel 2 settings	(2)	(*	1)	(2)	(1)
PWM2				1	
IOA2		0		1	_
IOA1	0	0	1	_	_
IOA0	0	1	_	_	_

PA₅/TP₅/TIOCB₁

Bit PWM1 in TMDR, bits IOB2 to IOB0 in TIOR1, bit NDER5 in NDERA, and bit PA_sDDR select the pin function as follows.

16-bit timer channel 1 settings	(1) in table below	(:	2) in table belo	w
PA₅DDR	_	0	1	1
NDER5	_	_	0	1
Pin function	TIOCB, output	PA₅ input	PA₅ output	TP₅ output
			TIOCB, input*	

Note: * $TIOCB_1$ input when IOB2 = 1 and PWM1 = 0.

16-bit timer channel 1 settings	(2)	(1)	(2)
IOB2	0			1
IOB1	0 0 1			_
IOB0	0	1	_	_

PA₄/TP₄/TIOCA₁

Bit PWM1 in TMDR, bits IOA2 to IOA0 in TIOR1, bit NDER4 in NDERA, and bit PA₄DDR select the pin function as follows.

16-bit timer channel 1 settings	(1) in table below	(2) in table below		
PA ₄ DDR	_	0	1	1
NDER4	_	_	0	1
Pin function	TIOCA, output	PA₄ input	PA ₄ output	TP₄ output
		TIOCA, input*		

Note: * $TIOCA_1$ input when IOA2 = 1.

16-bit timer channel 1 settings	(2) (1)		(2)	(1)	
PWM1		0			1
IOA2	0			1	_
IOA1	0	0 1		_	_
IOA0	0	1	_	_	_

Table 8.20 Port A Pin Functions (Modes 3, 4, 5)

Pin Pin Functions and Selection Method

PA₇/TP₇/

Modes 3 and 4: Always used as A₂₀ output.

TIOCB / A

Pin function A₂₀ output

Mode 5:

Bit PWM2 in TMDR, bits IOB2 to IOB0 in TIOR2, bit NDER7 in NDERA, bit A20E in BRCR, and bit $PA_{\gamma}DDR$ select the pin function as follows.

A20E		0			
16-bit timer channel 2 settings	(1) in table below	(2) in table below			_
PA,DDR	_	0 1		1	_
NDER7	_	_	0	1	1
Pin function	TIOCB ₂ output	PA ₇ input PA ₇ output TP ₇ output		A ₂₀ output	
		TIOCB ₂ input*			

Note: * TIOCB, input when IOB2 = 1 and PWM2 = 0.

16-bit timer channel 2 settings	(2)	(2) (1)		(2)
IOB2		0		
IOB1	0	0	1	_
IOB0	0	1	_	_

PA₆/TP₆/ TIOCA₂/A₂₁ Bit PWM2 in TMDR, bits IOA2 to IOA0 in TIOR2, bit NDER6 in NDERA, bit A21E in BRCR, and bit PA_sDDR select the pin function as follows.

A21E		0			
16-bit timer channel 2 settings	(1) in table below	(2) in table below			_
PA ₆ DDR	_	0	1	1	_
NDER6	_	_	0	1	-
Pin function	TIOCA ₂ output	PA ₆ input	PA ₆ output	TP ₆ output	A ₂₁ output

Note: * TIOCA, input when IOA2 = 1.

16-bit timer channel 2 settings	(2) (1)		(2)	(1)	
PWM2	0				1
IOA2	0			1	
IOA1	0	0	1	_	_
IOA0	0	1		_	



PA_s/TP_s/ TIOCB₁/A₂₂

Bit PWM1 in TMDR, bits IOB2 to IOB0 in TIOR1, bit NDER5 in NDERA, bit A22E in BRCR, and bit PA_sDDR select the pin function as follows.

A22E		0			
16-bit timer channel 1 settings	(1) in table below	(2) in table below			_
PA₅DDR	_	0	1	1	_
NDER5	_	_	0	1	_
Pin function	TIOCB ₁ output	PA₅ input	PA₅ output	TP₅ output	A ₂₂ output
			TIOCB, input*		

Note: * TIOCB, input when IOB2 = 1 and PWM1 = 0.

16-bit timer channel 1 settings	(2)	(1)		(2)
IOB2	0			1
IOB1	0	0 1		_
IOB0	0	1	_	_

PA₄/TP₄/ TIOCA₁/A₂₃

Bit PWM1 in TMDR, bits IOA2 to IOA0 in TIOR1, bit NDER4 in NDERA, bit A23E in BRCR, and bit PA_4DDR select the pin function as follows.

A23E			0		
16-bit timer channel 1 settings	(1) in table below	(2) in table below			_
PA ₄ DDR	_	0	1	1	_
NDER4	_	_	0	1	_
Pin function	TIOCA, output	PA ₄ input	PA ₄ output	TP ₄ output	A ₂₃ output

Note: * TIOCA, input when IOA2 = 1.

16-bit timer channel 1 settings	(2) (1)		(2)	(1)	
PWM1		0			1
IOA2	0		1	_	
IOA1	0	0	1	_	_
IOA0	0	1	_	_	_

Table 8.21 Port A Pin Functions (Modes 1 to 7)

Pin Pin Functions and Selection Method

PA₃/TP₃/ TIOCB₀/ TCLKD Bit PWM0 in TMDR, bits IOB2 to IOB0 in TIOR0, bits TPSC2 to TPSC0 in TCR2 to TCR0 of the 16-bit timer, bits CKS2 to CKS0 in TCR3 of the 8-bit timer, bit NDER3 in NDERA, and bit PA_3DDR select the pin function as follows.

16-bit timer channel 0 settings	(1) in table below	(2) in table below				
PA ₃ DDR	_	0 1 1				
NDER3	_	_	0	1		
Pin function	TIOCB _o output	PA ₃ input	PA ₃ output	TP ₃ output		
		TIOCB ₀ input*1				
	TCLKD input*2					

Notes:

- 1. TIOCB₀ input when IOB2 = 1 and PWM0 = 0.
- TCLKD input when TPSC2 = TPSC1 = TPSC0 = 1 in any of TCR2 to TCR0, or bits CKS2 to CKS0 in TCR3 are as shown in (3) in the table below.

16-bit timer channel 0 settings	(2)	(1)	(2)
IOB2	(1		
IOB1	0	0	1	_
IOB0	0	1	_	_

8-bit timer channel 0 settings	(4	4)		(3)	
CKS2	0	1			
CKS1	_	()	1	
CKS0	_	0	1	_	

PA_/TP_/ TIOCA_/ TCLKC Bit PWM0 in TMDR, bits IOA2 to IOA0 in TIOR0, bits TPSC2 to TPSC0 in TCR2 to TCR0 of the 16-bit timer, bits CKS2 to CKS0 in TCR1 of the 8-bit timer, bit NDER2 in NDERA, and bit PA_2DDR select the pin function as follows.

16-bit timer channel 0 settings	(1) in table below	(2) in table below					
PA ₂ DDR	_	0	1	1			
NDER2	_	_	0	1			
Pin function	TIOCA _o output	PA ₂ input	PA ₂ output	TP ₂ output			
			TIOCA₀ input*	1			
	TCLKC input*2						

Notes:

- 1. TIOCA input when IOA2 = 1.
- TCLKC input when TPSC2 = TPSC1 = 1 and TPSC0 = 0 in any of TCR2 to TCR0, or bits CKS2 to CKS0 in TCR1 are as shown in (3) in the table below.

16-bit timer channel 0 settings	(2)	(1)	(2)	(1)
PWM0	0				1
IOA2	0			1	_
IOA1	0	0	1	_	_
IOA0	0	1	_	_	_

8-bit timer channel 1 settings	(4	1)		(3)	
CKS2	0	1			
CKS1	_	(0	1	
CKS0		0	1	_	

PA,/TP,/ TCLKB/ TEND, Bit MDF in TMDR, bits TPSC2 to TPSC0 in TCR2 to TCR0 of the 16-bit timer, bits CKS2 to CKS0 in TCR2 of the 8-bit timer, bit NDER1 in NDERA, and bit PA,DDR select the pin function as follows.

PA,DDR	0	1	1			
NDER1	_	0	1			
Pin function	PA₁ input	PA, output	TP₁ output			
	TCLKB input*1					
	TEND, output*2					

Notes: 1. TCLKB input when MDF = 1 in TMDR, or TPSC2 = 1, TPSC1 = 0, and TPSC0 = 1 in any of TCR2 to TCR0, or bits CKS2 to CKS0 in TCR2 are as shown in (1) in the table below.

When an external request is specified as a DMAC activation source, TEND, output regardless
of bits PA,DDR and NDER1.

8-bit timer channel 1 settings	(2	2)		(1)	
CKS2	0	1			
CKS1	_	()	1	
CKS0	_	0	1	_	

PA,/TP,/ TCLKA/ TEND Bit MDF in TMDR, bits TPSC2 to TPSC0 in TCR2 to TCR0 of the 16-bit timer, bits CKS2 to CKS0 in TCR0 of the 8-bit timer, bit NDER0 in NDERA, and bit $PA_{o}DDR$ select the pin function as follows.

PA₀DDR	0	1				
NDER0	_	0 1				
Pin function	PA₀ input	ut PA _o output TP _o				
		TCLKA input*1				
	TEND ₀ output*2					

Notes: 1. TCLKA input when MDF = 1 in TMDR, or TPSC2 = 1, TPSC1 = 0 and TPSC0 = 0 in any of TCR2 to TCR0, or bits CKS2 to CKS0 in TCR0 are as shown in (1) in the table below.

 When an external request is specified as a DMAC activation source, TEND₀ output regardless of bits PA₀DDR and NDER0.

8-bit timer channel 0 settings	(2	2)		(1)	
CKS2	0	1			
CKS1	_	()	1	
CKS0	_	0	1	_	

8.12 Port B

8.12.1 Overview

Port B is an 8-bit input/output port that is also used for output (TP_{15} to TP_{8}) from the programmable timing pattern controller (TPC), input/output ($TMIO_{3}$, TMO_{2} , $TMIO_{1}$, TMO_{0}) by the 8-bit timer, \overline{CS}_{7} to \overline{CS}_{4} output, input (\overline{DREQ}_{1} , \overline{DREQ}_{0}) to the DMA controller (DMAC), input and output (TxD_{2} , RxD_{2} , SCK_{2}) by serial communication interface channel 2 (SCI2), and output (\overline{UCAS} , \overline{LCAS}) by the DRAM interface. See table 8.23 to 8.24 for the selection of pin functions. A reset or hardware standby transition leaves port B as an input port.

For output of \overline{CS}_7 to \overline{CS}_4 in modes 1 to 5, see section 6.3.4, Chip Select Signals. When DRAM is connected to areas 2, 3, 4, and 5, the \overline{CS}_4 and \overline{CS}_5 output pins become \overline{RAS} output pins for these areas. For details see 6.5, DRAM Interface. Pins not assigned to any of these functions are available for generic input/output. Figure 8.11 shows the pin configuration of port B.

When DRAM is connected to areas 2, 3, 4, and 5, the \overline{CS}_4 and \overline{CS}_5 output pins become \overline{RAS} output pins for these areas. For details see 6.5, DRAM Interface.

Pins in port B can drive one TTL load and a 30-pF capacitive load. They can also drive darlington transistor pair.

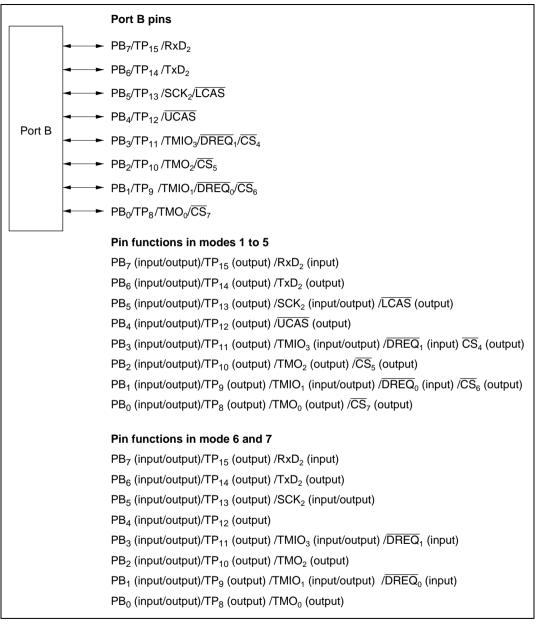


Figure 8.11 Port B Pin Configuration

8.12.2 Register Descriptions

Table 8.22 summarizes the registers of port B.

Table 8.22 Port B Registers

Address*	Name	Abbreviation	R/W	Initial Value
H'EE00A	Port B data direction register	PBDDR	W	H'00
H'FFFDA	Port B data register	PBDR	R/W	H'00

Note: *Lower 20 bits of the address in advanced mode.

Port B Data Direction Register (PBDDR): PBDDR is an 8-bit write-only register that can select input or output for each pin in port B. When pins are used for TPC output, the corresponding PBDDR bits must also be set.

Bit	7	6	5	4	3	2	1	0
	PB ₇ DDR	PB ₆ DDR	PB ₅ DDR	PB ₄ DDR	PB ₃ DDR	PB ₂ DDR	PB₁DDR	PB ₀ DDR
Initial value	0	0	0	0	0	0	0	0
Read/Write	W	W	W	W	W	W	W	W

Port B data direction 7 to 0
These bits select input or output for port B pins

The pin functions that can be selected for port B differ between modes 1 to 5, and modes 6 and 7. For the method of selecting the pin functions, see tables 8.23 and 8.24.

When port B functions as an input/output port, a pin in port B becomes an output port if the corresponding PBDDR bit is set to 1, and an input port if this bit is cleared to 0.

PBDDR is a write-only register. Its value cannot be read. All bits return 1 when read.

PBDDR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting. Therefore, if a transition is made to software standby mode while port B is functioning as an input/output port and a PBDDR bit is set to 1, the corresponding pin maintains its output state.

Port B Data Register (PBDR): PBDR is an 8-bit readable/writable register that stores output data for pins port B. When port B functions as an output port, the value of this register is output. When a bit in PBDDR is set to 1, if port B is read the value of the corresponding PBDR bit is returned. When a bit in PBDDR is cleared to 0, if port B is read the corresponding pin logic level is read.

Bit	7	6	5	4	3	2	1	0
	PB ₇	PB ₆	PB_5	PB_4	PB_3	PB ₂	PB ₁	PB ₀
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Port B data 7 to 0
These bits store data for port B pins

PBDR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

Table 8.23 Port B Pin Functions (Modes 1 to 5)

Pin Pin Functions and Selection Method

PB₇/TP₁₅/ RxD₂ Bit RE in SCR of SCI2, bit SMIF in SCMR, bit NDER15 in NDERB, and bit PB,DDR select the pin function as follows.

SMIF		0					
RE		0	1	_			
PB,DDR	0	1	1	_	_		
NDER15	_	0	1	_	_		
Pin function	PB ₇ input	PB ₇ output	TP ₁₅ output	RxD ₂ input	RxD ₂ input		

PB₆/TP₁₄/TxD₀

Bit TE in SCR of SCI2, bit SMIF in SCMR, bit NDER14 in NDERB, and bit PB_eDDR select the pin function as follows.

SMIF		0				
TE		1	_			
PB ₆ DDR	0	1	-	_		
NDER14	_	0	_	_		
Pin function	PB ₆ input	PB ₆ output	TP ₁₄ output	TxD ₂ output	TxD ₂ output*	

Note: * Functions as the TxD₂ output pin, but there are two states: one in which the pin is driven, and another in which the pin is at high-impedance.

PB_s/TP₁₃/ SCK_s/LCAS

Bit C/ \overline{A} in SMR of SCI2, bits CKE0 and CKE1 in SCR, bit NDER13 in NDERB, and bit PB $_{\rm s}$ DDR select the pin function as follows.

CKE1		0					
C/Ā		()		1	_	
CKE0	0			1	_	_	
PB₅DDR	0	1	1	_	_	_	
NDER13	_	0	1	_	_	_	
Pin function	PB₅ input	PB _s input PB _s output TP ₁₃ output SCK ₂ output SCK ₂					
		<u>ICAS</u> output∗					

Note: * \overline{LCAS} output depending on bits DRAS2 to DRAS0 in DRCRA and bit CSEL in DRCRB, and regardless of bits C/\overline{A}, CKE0 and CKE1, NDER13, and PB_DDR. For details, see section 6, Bus Controller.

PB₄/TP₁₂/ UCAS Bit NDER12 in NDERB and bit PB₄DDR select the pin function as follows.

PB ₄ DDR	0	1	1
NDER12	_	0	1
Pin function	PB₄ input	PB ₄ output	TP ₁₂ output
		UCAS output*	

Note: * UCAS output depending on bits DRAS2 to DRAS0 in DRCRA and bit CSEL in DRCRB, and regardless of bits NDER12 and PB₄DDR. For details, see section 6, Bus Controller.

 $\frac{\mathsf{PB_3/TP_{11}/}}{\mathsf{TMIO_3/}} \\ \overline{\mathsf{DREQ_1/CS_4}}$

The DRAM interface settings by bits DRAS2 to DRAS0 in DRCRA, bits OIS3/2 and OS1/0 in TCSR3, bits CCLR1 and CCLR0 in TCR3, bit CS4E in CSCR, bit NDER11 in NDERB, and bit PB₃DDR select the pin function as follows.

DRAM interface settings		(1) in table below						
OIS3/2 and OS1/0		Al	10		Not all 0	_		
CS4E		0		1	_	_		
PB ₃ DDR	0	0 1 1 —				_		
NDER11	_	0	1	_	_	_		
Pin function	PB ₃ input							
		TMIO ₃ input*1						
		DREQ, input*2						

Notes:

- 1. TMIO₃ input when CCLR1 = CCLR0 = 1.
- When an external request is specified as a DMAC activation source, DREQ, input regardless of bits OIS3 and OIS2, OS1 and OS0, CCLR1 and CCLR0, CS4E, NDER11, and PB,DDR.
- 3. \overline{CS}_{λ} is output as \overline{RAS}_{λ} .

DRAM interface settings		(1)			(2)			(1)
DRAS2		0			1			
DRAS1	(0 1			()		1
DRAS0	0	1	0	1	0	1	0	1

PB₂/TP₁₀/ TMO₂/CS_E The DRAM interface settings by bits DRAS2 to DRAS0 in DRCRA, bits OIS3/2 and OS1/0 in TCSR2, bit CS5E in CSCR, bit NDER10 in NDERB, and bit PB_DDR select the pin function as follows.

DRAM interface settings		(1) in table below						
OIS3/2 and OS1/0		Al	10		Not all 0	_		
CS5E		0		1	_	_		
PB ₂ DDR	0	1	1	_	_	_		
NDER10	_	_ 0 1				_		
Pin function	PB ₂ input							

Note: * \overline{CS}_{5} is output as \overline{RAS}_{5} .

DRAM interface settings		(1)			(2)	(*	1)	
DRAS2		0					1	
DRAS1	(0 1			()		1
DRAS0	0	0 1 0 1				1	0	1



PB₁/TP₉/ TMIO₁/ DREQ₀/CS₆ Bits OIS3/2 and OS1/0 in TCSR1, bits CCLR1 and CCLR0 in TCR1, bit CS6E in CSCR, bit NDER9 in NDERB, and bit PB,DDR select the pin function as follows.

OIS3/2 and OS1/0		All 0						
CS6E		0	1	_				
PB₁DDR	0	1	1	_	_			
NDER9	_	0	1	_	_			
Pin function	PB, input	PB ₁ output	CS _₅ output	TMIO ₁ output				
		TMIO, input*1						
			DREQ₀ input*2					

Notes: 1. TMIO, input when CCLR1 = CCLR0 = 1.

 When an external request is specified as a DMAC activation source, DREQ₀ input regardless of bits OIS3/2 and OS1/0, bits CCLR1/0, bit CS6E, bit NDER9, and bit PB,DDR.

PB₀/TP₈/ TMO₀/CS₇

Bits OIS3/2 and OS1/0 in TCSR0, bit CS7E in CSCR, bit NDER8 in NDERB, and bit PB_0DDR select the pin function as follows.

OIS3/2 and OS1/0		All 0					
CS7E		0	1	_			
PB₀DDR	0	1	_	_			
NDER8	_	0	_	_			
Pin function	PB₀ input	PB₀ output	TP _s output	CS ₇ output	TMO₀ output		

Table 8.24 Port B Pin Functions (Modes 6 to 7)

Pin Pin Functions and Selection Method

PB₇/TP₁₅/ RxD₃ Bit RE in SCR of SCI2, bit SMIF in SCMR, bit NDER15 in NDERB, and bit PB,DDR select the pin function as follows.

SMIF		0					
RE		0	1	_			
PB,DDR	0	1	_	_			
NDER15	_	0	-	_			
Pin function	PB ₇ input	PB ₇ output	TP ₁₅ output	RxD ₂ input	RxD ₂ input		

PB₆/TP₁₄/TxD₃

Bit TE in SCR of SCI2, bit SMIF in SCMR, bit NDER14 in NDERB, and bit PB DDR select the pin function as follows.

SMIF		0				
TE		0	1	_		
PB ₆ DDR	0	0 1 1			_	
NDER14	_	_ 0 1			_	
Pin function	PB ₆ input	PB ₆ output	TP ₁₄ output	TxD ₂ output	TxD ₂ output*	

Note: * Functions as the TxD2 output pin, but there are two states: one in which the pin is driven, and another in which the pin is at high-impedance.

PB₅/TP₁₃/ SCK₂ Bit C/ \overline{A} in SMR of SCI2, bits CKE0 and CKE1 in SCR, bit NDER13 in NDERB, and bit PB $_{\rm s}$ DDR select the pin function as follows.

CKE1		0				1
C/Ā		0 1				_
CKE0		0			_	_
PB₅DDR	0	1	1	_	_	_
NDER13	_	0	1	_	_	_
Pin function	PB₅ input	PB₅ output	TP ₁₃ output	SCK ₂ output	SCK ₂ output	SCK ₂ input

PB₄/TP₁₂

Bit NDER12 in NDERB and bit PB,DDR select the pin function as follows.

PB ₄ DDR	0	1	1
NDER12	_	0	1
Pin function	PB, input	PB, output	TP,, output

PB₃/TP₁₁/ TMIO₃/ DREQ,

Bits OIS3/2 and OS1/0 in TCSR3, bits CCLR1 and CCLR0 in TCR3, bit NDER11 in NDERB, and bit PB₃DDR select the pin function as follows.

OIS3/2 and OS1/0	All 0 Not all 0			
PB ₃ DDR	0 1 1		_	
NDER11	_	0	1	_
Pin function	PB₃ input	PB₃ output	TP ₁₁ output	TMIO₃ output
	TMIO ₃ input*1			
	DREQ, input*2			

Notes:

- 1. TMIO₃ input when CCLR1 = CCLR0 = 1.
 - When an external request is specified as a DMAC activation source, DREQ, input regardless of bits OIS3/2 and OS1/0, bit NDER11, and bit PB,DDR.

PB₂/TP₁₀/ TMO₂

Bits OIS3/2 and OS1/0 in TCSR2, bit NDER10 in NDERB, and bit PB₂DDR select the pin function as follows.

OIS3/2 and OS1/0	All 0			Not all 0
PB ₂ DDR	0	1	1	_
NDER10	_	0	1	_
Pin function	PB ₂ input	PB ₂ output	TP ₁₀ output	TMO ₂ output

PB₁/TP₃/ TMIO₁/ DREQ.

Bits OIS3/2 and OS1/0 in TCSR1, bits CCLR1 and CCLR0 in TCR1, bit NDER9 in NDERB, and bit PB,DDR select the pin function as follows.

coloci, and pair random do remone.					
OIS3/2 and OS1/0	All 0			Not all 0	
PB,DDR	0 1 1		_		
NDER9	_	0	1	_	
Pin function	PB ₁ input	PB ₁ output	TP ₉ output	TMIO₁ output	
	TMIO ₁ input*1				
	DREQ ₀ input*2				

Notes:

- 1. TMIO, input when CCLR1 = CCLR0 = 1.
- When an external request is specified as a DMAC activation source, DREQ₀ input regardless of bits OIS3/2 and OS1/0, bit NDER9, and bit PB,DDR.

PB₀/TP₈/

Bits OIS3/2 and OS1/0 in TCSR0, bit NDER8 in NDERB, and bit PB, DDR select the pin function as follows.

OIS3/2 and OS1/0	All 0			Not all 0
PB ₀ DDR	0 1 1		_	
NDER8	_	0	1	_
Pin function	PB₀ input	PB₀ output	TP _s output	TMO _o output

Section 9 16-Bit Timer

9.1 Overview

The H8/3067 Group has built-in 16-bit timer module with three 16-bit counter channels.

9.1.1 Features

16-bit timer features are listed below.

- Capability to process up to 6 pulse outputs or 6 pulse inputs
- Six general registers (GRs, two per channel) with independently-assignable output compare or input capture functions
- Selection of eight counter clock sources for each channel:

Internal clocks: ϕ , $\phi/2$, $\phi/4$, $\phi/8$

External clocks: TCLKA, TCLKB, TCLKC, TCLKD

- Five operating modes selectable in all channels:
 - Waveform output by compare match

Selection of 0 output, 1 output, or toggle output (only 0 or 1 output in channel 2)

— Input capture function

Rising edge, falling edge, or both edges (selectable)

— Counter clearing function

Counters can be cleared by compare match or input capture

— Synchronization

Two or more timer counters (TCNTs) can be preset simultaneously, or cleared simultaneously by compare match or input capture. Counter synchronization enables synchronous register input and output.

- PWM mode

PWM output can be provided with an arbitrary duty cycle. With synchronization, up to three-phase PWM output is possible

• Phase counting mode selectable in channel 2

Two-phase encoder output can be counted automatically.

• High-speed access via internal 16-bit bus

The TCNTs and GRs can be accessed at high speed via a 16-bit bus.

• Any initial timer output value can be set

- Nine interrupt sources
 Each channel has two compare match/input capture interrupts and an overflow interrupt. All interrupts can be requested independently.
- Output triggering of programmable timing pattern controller (TPC)

 Compare match/input capture signals from channels 0 to 2 can be used as TPC output triggers.

Table 9.1 summarizes the 16-bit timer functions.

Table 9.1 16-bit timer Functions

Item		Channel 0	Channel 1	Channel 2		
Clock sources		Internal clocks: ϕ , ϕ /2, ϕ /4, ϕ /8				
		External clocks: TCLKA, TCLKB, TCLKC, TCLKD, selectable independently				
General registers compare/input ca registers)		GRA0, GRB0	GRA1, GRB1	GRA2, GRB2		
Input/output pins		TIOCA ₀ , TIOCB ₀	TIOCA ₁ , TIOCB ₁	TIOCA ₂ , TIOCB ₂		
Counter clearing	function			GRA2/GRB2 compare match or input capture		
Initial output value function	e setting	0	0	0		
Compare match	0	0	0	0		
output	1	0	0	0		
	Toggle	0	0	_		
Input capture fund	ction	0	0	0		
Synchronization		0	0	0		
PWM mode		0	0	0		
Phase counting n	node	_	_	0		
Interrupt sources		Three sources	Three sources	Three sources		
		 Compare match/input capture A0 	 Compare match/input capture A1 	 Compare match/input capture A2 		
		 Compare match/input capture B0 	 Compare match/input capture B1 	• Compare match/input capture B2		
		 Overflow 	 Overflow 	Overflow		

Legend

o: Available

—: Not available

9.1.2 **Block Diagrams**

16-bit timer Block Diagram (Overall): Figure 9.1 is a block diagram of the 16-bit timer.

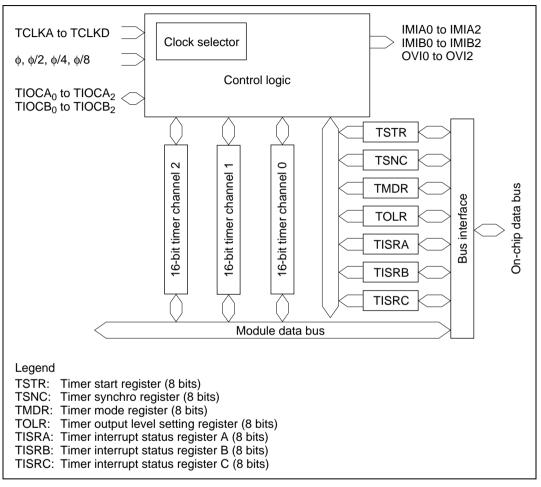
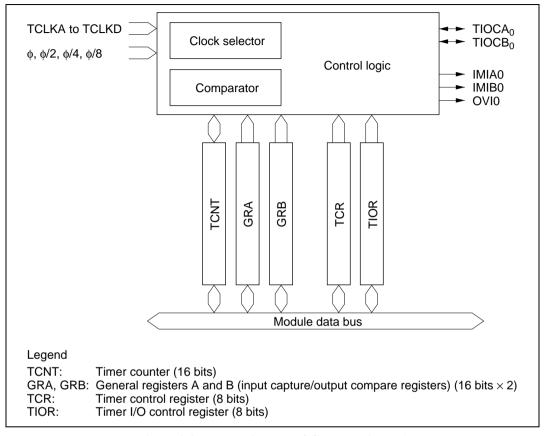


Figure 9.1 16-bit timer Block Diagram (Overall)

Block Diagram of Channels 0 and 1: 16-bit timer channels 0 and 1 are functionally identical. Both have the structure shown in figure 9.2.



 $Figure \ 9.2 \quad Block \ Diagram \ of \ Channels \ 0 \ and \ 1$

Block Diagram of Channel 2: Figure 9.3 is a block diagram of channel 2

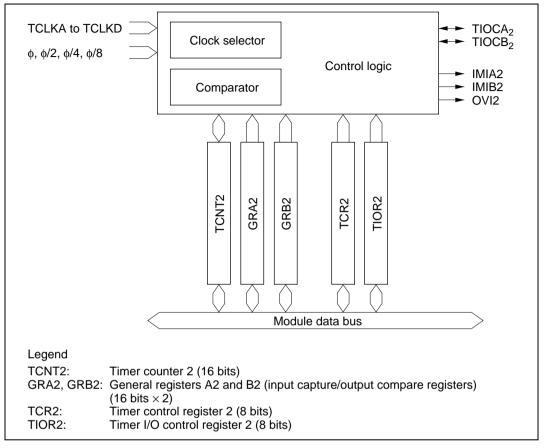


Figure 9.3 Block Diagram of Channel 2

9.1.3 Input/Output Pins

Table 9.2 summarizes the 16-bit timer pins.

Table 9.2 16-bit timer Pins

Channel	Name	Abbre- viation	Input/ Output	Function
Common	Clock input A	TCLKA	Input	External clock A input pin (phase-A input pin in phase counting mode)
	Clock input B	TCLKB	Input	External clock B input pin (phase-B input pin in phase counting mode)
	Clock input C	TCLKC	Input	External clock C input pin
	Clock input D	TCLKD	Input	External clock D input pin
0	Input capture/output compare A0	TIOCA ₀	Input/ output	GRA0 output compare or input capture pin PWM output pin in PWM mode
	Input capture/output compare B0	TIOCB ₀	Input/ output	GRB0 output compare or input capture pin
1	Input capture/output compare A1	TIOCA ₁	Input/ output	GRA1 output compare or input capture pin PWM output pin in PWM mode
	Input capture/output compare B1	TIOCB ₁	Input/ output	GRB1 output compare or input capture pin
2	Input capture/output compare A2	TIOCA ₂	Input/ output	GRA2 output compare or input capture pin PWM output pin in PWM mode
	Input capture/output compare B2	TIOCB ₂	Input/ output	GRB2 output compare or input capture pin

9.1.4 Register Configuration

Table 9.3 summarizes the 16-bit timer registers.

 Table 9.3
 16-bit timer Registers

Channel	Address*1	Name	Abbre- viation	R/W	Initial Value
Common	H'FFF60	Timer start register	TSTR	R/W	H'F8
	H'FFF61	Timer synchro register	TSNC	R/W	H'F8
	H'FFF62	Timer mode register	TMDR	R/W	H'98
	H'FFF63	Timer output level setting register	TOLR	W	H'C0
	H'FFF64	Timer interrupt status register A	TISRA	R/(W) *2	H'80
	H'FFF65	Timer interrupt status register B	TISRB	R/(W) *2	H'88
	H'FFF66	Timer interrupt status register C	TISRC	R/(W) *2	H'88
0	H'FFF68	Timer control register 0	TCR0	R/W	H'80
	H'FFF69	Timer I/O control register 0	TIOR0	R/W	H'88
	H'FFF6A	Timer counter 0H	TCNT0H	R/W	H'00
	H'FFF6B	Timer counter 0L	TCNT0L	R/W	H'00
	H'FFF6C	General register A0H	GRA0H	R/W	H'FF
	H'FFF6D	General register A0L	GRA0L	R/W	H'FF
	H'FFF6E	General register B0H	GRB0H	R/W	H'FF
	H'FFF6F	General register B0L	GRB0L	R/W	H'FF
1	H'FFF70	Timer control register 1	TCR1	R/W	H'80
	H'FFF71	Timer I/O control register 1	TIOR1	R/W	H'88
	H'FFF72	Timer counter 1H	TCNT1H	R/W	H'00
	H'FFF73	Timer counter 1L	TCNT1L	R/W	H'00
	H'FFF74	General register A1H	GRA1H	R/W	H'FF
	H'FFF75	General register A1L	GRA1L	R/W	H'FF
	H'FFF76	General register B1H	GRB1H	R/W	H'FF
	H'FFF77	General register B1L	GRB1L	R/W	H'FF



Channel	Address*1	Name	Abbre- viation	R/W	Initial Value
2	H'FFF78	Timer control register 2	TCR2	R/W	H'80
	H'FFF79	Timer I/O control register 2	TIOR2	R/W	H'88
	H'FFF7A	Timer counter 2H	TCNT2H	R/W	H'00
	H'FFF7B	Timer counter 2L	TCNT2L	R/W	H'00
	H'FFF7C	General register A2H	GRA2H	R/W	H'FF
	H'FFF7D	General register A2L	GRA2L	R/W	H'FF
	H'FFF7E	General register B2H	GRB2H	R/W	H'FF
	H'FFF7F	General register B2L	GRB2L	R/W	H'FF

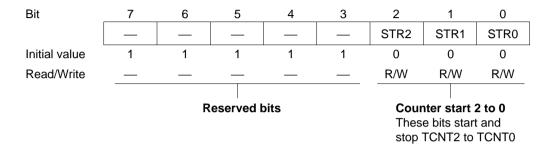
Notes: 1. The lower 20 bits of the address in advanced mode are indicated.

2. Only 0 can be written in bits 3 to 0, to clear the flags.

9.2 Register Descriptions

9.2.1 Timer Start Register (TSTR)

TSTR is an 8-bit readable/writable register that starts and stops the timer counter (TCNT) in channels 0 to 2.



TSTR is initialized to H'F8 by a reset and in standby mode.

Bits 7 to 3—Reserved: These bits cannot be modified and are always read as 1.

Bit 2—Counter Start 2 (STR2): Starts and stops timer counter 2 (TCNT2).

Bit 2		
STR2	Description	
0	TCNT2 is halted	(Initial value)
1	TCNT2 is counting	

Bit 1—Counter Start 1 (STR1): Starts and stops timer counter 1 (TCNT1).

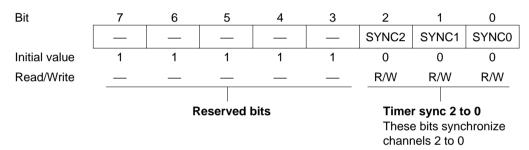
Bit 1 STR1	Description	
0	TCNT1 is halted	(Initial value)
1	TCNT1 is counting	

Bit 0—Counter Start 0 (STR0): Starts and stops timer counter 0 (TCNT0).

Bit 0 STR0	Description	
0	TCNT0 is halted	(Initial value)
1	TCNT0 is counting	

9.2.2 Timer Synchro Register (TSNC)

TSNC is an 8-bit readable/writable register that selects whether channels 0 to 2 operate independently or synchronously. Channels are synchronized by setting the corresponding bits to 1.



TSNC is initialized to H'F8 by a reset and in standby mode.

Bits 7 to 3—Reserved: These bits cannot be modified and are always read as 1.

Bit 2—Timer Sync 2 (SYNC2): Selects whether channel 2 operates independently or synchronously.

Bit 2 SYNC2			
0	Channel 2's timer counter (TCNT2) operates independently TCNT2 is preset and cleared independently of other channels	(Initial value)	
1	Channel 2 operates synchronously TCNT2 can be synchronously preset and cleared		

Bit 1—Timer Sync 1 (SYNC1): Selects whether channel 1 operates independently or synchronously.

Bit 1 SYNC1	Description	
0	Channel 1's timer counter (TCNT1) operates independently TCNT1 is preset and cleared independently of other channels	(Initial value)
1	Channel 1 operates synchronously TCNT1 can be synchronously preset and cleared	

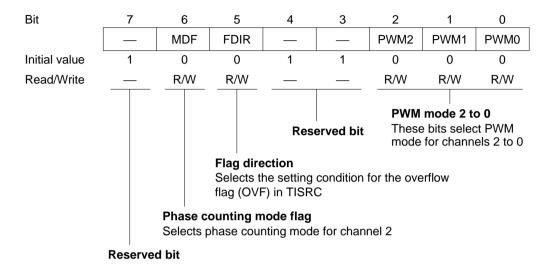
Bit 0—Timer Sync 0 (SYNC0): Selects whether channel 0 operates independently or synchronously.

Bit 0 SYNC0	Description	
0	Channel 0's timer counter (TCNT0) operates independently TCNT0 is preset and cleared independently of other channels	(Initial value)
1	Channel 0 operates synchronously TCNT0 can be synchronously preset and cleared	



9.2.3 Timer Mode Register (TMDR)

TMDR is an 8-bit readable/writable register that selects PWM mode for channels 0 to 2. It also selects phase counting mode and the overflow flag (OVF) setting conditions for channel 2.



TMDR is initialized to H'98 by a reset and in standby mode.

Bit 7—Reserved: This bit cannot be modified and is always read as 1.

Bit 6—Phase Counting Mode Flag (MDF): Selects whether channel 2 operates normally or in phase counting mode.

Bit 6		
MDF	Description	
0	Channel 2 operates normally	(Initial value)
1	Channel 2 operates in phase counting mode	

When MDF is set to 1 to select phase counting mode, TCNT2 operates as an up/down-counter and pins TCLKA and TCLKB become counter clock input pins. TCNT2 counts both rising and falling edges of TCLKA and TCLKB, and counts up or down as follows.

Counting Direction	Down-Co	ounting	Up-Counting					
TCLKA pin	Ā	High	Ť	Low	Low	Ī	High	<u> </u>
TCLKB pin	Low	Ī	High	Ţ	<u> </u>	High	Ţ	Low

In phase counting mode channel 2 operates as above regardless of the external clock edges selected by bits CKEG1 and CKEG0 and the clock source selected by bits TPSC2 to TPSC0. Phase counting mode takes precedence over these settings.

The counter clearing condition selected by the CCLR1 and CCLR0 bits in TCR2 and the compare match/input capture settings and interrupt functions of TIOR2, TISRA, TISRB, TISRC remain effective in phase counting mode.

Bit 5—Flag Direction (FDIR): Designates the setting condition for the OVF flag in TISRC. The FDIR designation is valid in all modes in channel 2.

Bit 5 FDIR	Description	
0	OVF is set to 1 in TISRC when TCNT2 overflows or underflows	(Initial value)
1	OVF is set to 1 in TISRC when TCNT2 overflows	

Bits 4 and 3—Reserved: These bits cannot be modified and are always read as 1.

Bit 2—PWM Mode 2 (PWM2): Selects whether channel 2 operates normally or in PWM mode.

Bit 2 PWM2	Description	
0	Channel 2 operates normally	(Initial value)
1	Channel 2 operates in PWM mode	

When bit PWM2 is set to 1 to select PWM mode, pin TIOCA₂ becomes a PWM output pin. The output goes to 1 at compare match with GRA2, and to 0 at compare match with GRB2.



Bit 1—PWM Mode 1 (PWM1): Selects whether channel 1 operates normally or in PWM mode.

Bit 1 PWM1	Description	
0	Channel 1 operates normally	(Initial value)
1	Channel 1 operates in PWM mode	

When bit PWM1 is set to 1 to select PWM mode, pin TIOCA₁ becomes a PWM output pin. The output goes to 1 at compare match with GRA1, and to 0 at compare match with GRB1.

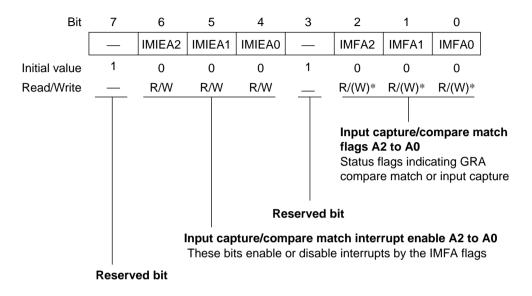
Bit 0—PWM Mode 0 (PWM0): Selects whether channel 0 operates normally or in PWM mode.

Bit 0		
PWM0	Description	
0	Channel 0 operates normally	(Initial value)
1	Channel 0 operates in PWM mode	

When bit PWM0 is set to 1 to select PWM mode, pin TIOCA₀ becomes a PWM output pin. The output goes to 1 at compare match with GRA0, and to 0 at compare match with GRB0.

9.2.4 Timer Interrupt Status Register A (TISRA)

TISRA is an 8-bit readable/writable register that indicates GRA compare match or input capture and enables or disables general register compare match and input capture interrupt requests.



Note: * Only 0 can be written, to clear the flag.

TISRA is initialized to H'88 by a reset and in standby mode.

Bit 7—Reserved: This bit cannot be modified and is always read as 1.

Bit 6—Input Capture/Compare Match Interrupt Enable A2 (IMIEA2): Enables or disables the interrupt requested by the IMFA2 flag when IMFA2 is set to 1.

Bit 6
IMIEA2 Description

0 IMIA2 interrupt requested by IMFA2 flag is disabled (Initial value)

1 IMIA2 interrupt requested by IMFA2 flag is enabled



Bit 5—Input Capture/Compare Match Interrupt Enable A1 (IMIEA1): Enables or disables the interrupt requested by the IMFA1 flag when IMFA1 is set to 1.

Bit 5 IMIEA1	Description	
0	IMIA1 interrupt requested by IMFA1 flag is disabled	(Initial value)
1	IMIA1 interrupt requested by IMFA1 flag is enabled	

Bit 4—Input Capture/Compare Match Interrupt Enable A0 (IMIEA0): Enables or disables the interrupt requested by the IMFA0 flag when IMFA0 is set to 1.

Bit 4 IMIEA0	Description	
0	IMIA0 interrupt requested by IMFA0 flag is disabled	(Initial value)
1	IMIA0 interrupt requested by IMFA0 flag is enabled	

Bit 3—Reserved: This bit cannot be modified and is always read as 1.

Bit 2—Input Capture/Compare Match Flag A2 (IMFA2): This status flag indicates GRA2 compare match or input capture events.

Bit 2 IMFA2	Description
0	[Clearing conditions] (Initial value) Read IMFA2 when IMFA2 =1, then write 0 in IMFA2. DMAC activated by IMIA2 interrupt.
1	[Setting conditions] TCNT2 = GRA2 when GRA2 functions as an output compare register. TCNT2 value is transferred to GRA2 by an input capture signal when GRA2 functions as an input capture register.

Bit 1—Input Capture/Compare Match Flag A1 (IMFA1): This status flag indicates GRA1 compare match or input capture events.

Bit 1 IMFA1	Description
0	[Clearing conditions] (Initial value) Read IMFA1 when IMFA1 =1, then write 0 in IMFA1. DMAC activated by IMIA1 interrupt.
1	[Setting conditions] TCNT1 = GRA1 when GRA1 functions as an output compare register. TCNT1 value is transferred to GRA1 by an input capture signal when GRA1 functions as an input capture register.

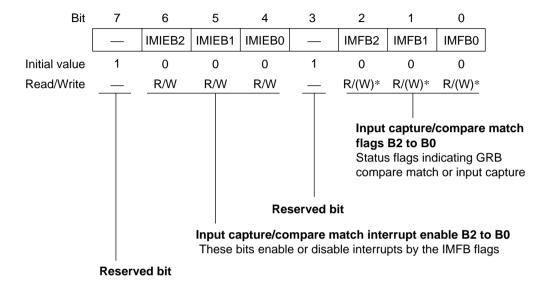
Bit 0—Input Capture/Compare Match Flag A0 (IMFA0): This status flag indicates GRA0 compare match or input capture events.

Bit 0 IMFA0	Description
0	[Clearing conditions] (Initial value) Read IMFA0 when IMFA0 =1, then write 0 in IMFA0. DMAC activated by IMIA0 interrupt.
1	[Setting conditions] TCNT0 = GRA0 when GRA0 functions as an output compare register. TCNT0 value is transferred to GRA0 by an input capture signal when GRA0 functions as an input capture register.



9.2.5 Timer Interrupt Status Register B (TISRB)

TISRB is an 8-bit readable/writable register that indicates GRB compare match or input capture and enables or disables general register compare match and input capture interrupt requests.



Note: * Only 0 can be written, to clear the flag.

TISRB is initialized to H'88 by a reset and in standby mode.

Bit 7—Reserved: This bit cannot be modified and is always read as 1.

Bit 6—Input Capture/Compare Match Interrupt Enable B2 (IMIEB2): Enables or disables the interrupt requested by the IMFB2 flag when IMFB2 is set to 1.

Bit 6		
IMIEB2	Description	
0	IMIB2 interrupt requested by IMFB2 flag is disabled	(Initial value)
1	IMIB2 interrupt requested by IMFB2 flag is enabled	

Bit 5—Input Capture/Compare Match Interrupt Enable B1 (IMIEB1): Enables or disables the interrupt requested by the IMFB1 flag when IMFB1 is set to 1.

Bit 5 IMIEB1	Description	
0	IMIB1 interrupt requested by IMFB1 flag is disabled	(Initial value)
1	IMIB1 interrupt requested by IMFB1 flag is enabled	

Bit 4—Input Capture/Compare Match Interrupt Enable B0 (IMIEB0): Enables or disables the interrupt requested by the IMFB0 flag when IMFB0 is set to 1.

Bit 4 IMIEB0	Description	
0	IMIB0 interrupt requested by IMFB0 flag is disabled	(Initial value)
1	IMIB0 interrupt requested by IMFB0 flag is enabled	

Bit 3—Reserved: This bit cannot be modified and is always read as 1.

Bit 2—Input Capture/Compare Match Flag B2 (IMFB2): This status flag indicates GRB2 compare match or input capture events.

Bit 2 IMFB2	Description
0	[Clearing condition] (Initial value Read IMFB2 when IMFB2 =1, then write 0 in IMFB2.
1	[Setting conditions] TCNT2 = GRB2 when GRB2 functions as an output compare register. TCNT2 value is transferred to GRB2 by an input capture signal when GRB2 functions as an input capture register.



Bit 1—Input Capture/Compare Match Flag B1 (IMFB1): This status flag indicates GRB1 compare match or input capture events.

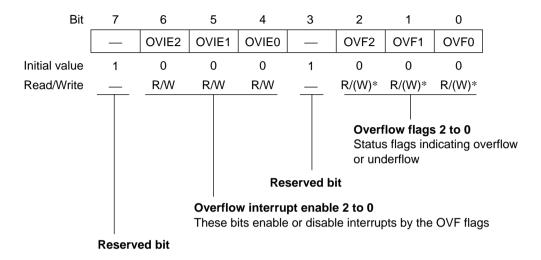
Bit 1 IMFB1	Description
0	[Clearing condition] (Initial value) Read IMFB1 when IMFB1 =1, then write 0 in IMFB1.
1	[Setting conditions] TCNT1 = GRB1 when GRB1 functions as an output compare register. TCNT1 value is transferred to GRB1 by an input capture signal when GRB1 functions as an input capture register.

Bit 0—Input Capture/Compare Match Flag B0 (IMFB0): This status flag indicates GRB0 compare match or input capture events.

Bit 0 IMFB0	Description
0	[Clearing condition] (Initial value)
	Read IMFB0 when IMFB0 =1, then write 0 in IMFB0.
1	[Setting conditions] TCNT0 = GRB0 when GRB0 functions as an output compare register. TCNT0 value is transferred to GRB0 by an input capture signal when GRB0 functions as an input capture register.

9.2.6 Timer Interrupt Status Register C (TISRC)

TISRC is an 8-bit readable/writable register that indicates TCNT overflow or underflow and enables or disables overflow interrupt requests.



Note: * Only 0 can be written, to clear the flag.

TISRC is initialized to H'88 by a reset and in standby mode.

Bit 7—Reserved: This bit cannot be modified and is always read as 1.

Bit 6—Overflow Interrupt Enable 2 (OVIE2): Enables or disables the interrupt requested by the OVF2 flag when OVF2 is set to 1.

Bit 6 OVIE2	Description	
0	OVI2 interrupt requested by OVF2 flag is disabled	(Initial value)
1	OVI2 interrupt requested by OVF2 flag is enabled	



Bit 5—Overflow Interrupt Enable 1 (OVIE1): Enables or disables the interrupt requested by the OVF1 flag when OVF1 is set to 1.

Bit 5 OVIE1	Description	
0	OVI1 interrupt requested by OVF1 flag is disabled	(Initial value)
1	OVI1 interrupt requested by OVF1 flag is enabled	

Bit 4—Overflow Interrupt Enable 0 (OVIE0): Enables or disables the interrupt requested by the OVF0 flag when OVF0 is set to 1.

Bit 4		
OVIE0	Description	
0	OVI0 interrupt requested by OVF0 flag is disabled	(Initial value)
1	OVI0 interrupt requested by OVF0 flag is enabled	

Bit 3—Reserved: This bit cannot be modified and is always read as 1.

Bit 2—Overflow Flag 2 (OVF2): This status flag indicates TCNT2 overflow or underflow.

Bit 2 OVF2	Description	
0	[Clearing condition] Read OVF2 when OVF2 =1, then write 0 in OVF2.	(Initial value)
1	[Setting condition] TCNT2 overflowed from H'FFFF to H'0000, or underflowed from H'0000 to	o H'FFFF.

Note: TCNT underflow occurs when TCNT operates as an up/down-counter. Underflow occurs only when channel 2 operates in phase counting mode (MDF = 1 in TMDR).

Bit 1—Overflow Flag 1 (OVF1): This status flag indicates TCNT1 overflow.

Bit 1 OVF1	Description	
0	[Clearing condition] Read OVF1 when OVF1 =1, then write 0 in OVF1.	(Initial value)
1	[Setting condition] TCNT1 overflowed from H'FFFF to H'0000.	

Bit 0—Overflow Flag 0 (OVF0): This status flag indicates TCNT0 overflow.

Bit 0 OVF0	Description	
0	[Clearing condition] Read OVF0 when OVF0 =1, then write 0 in OVF0.	(Initial value)
1	[Setting condition] TCNT0 overflowed from H'FFFF to H'0000.	

9.2.7 Timer Counters (TCNT)

TCNT is a 16-bit counter. The 16-bit timer has three TCNTs, one for each channel.

Channel	Abbreviation	Function
0	TCNT0	Up-counter
1	TCNT1	
2	TCNT2	Phase counting mode: up/down-counter Other modes: up-counter
		·

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Read/Write	R/W															

Each TCNT is a 16-bit readable/writable register that counts pulse inputs from a clock source. The clock source is selected by bits TPSC2 to TPSC0 in TCR.

TCNT0 and TCNT1 are up-counters. TCNT2 is an up/down-counter in phase counting mode and an up-counter in other modes.

TCNT can be cleared to H'0000 by compare match with GRA or GRB or by input capture to GRA or GRB (counter clearing function).

When TCNT overflows (changes from H'FFFF to H'0000), the OVF flag is set to 1 in TISRC of the corresponding channel.

When TCNT underflows (changes from H'0000 to H'FFFF), the OVF flag is set to 1 in TISRC of the corresponding channel.



The TCNTs are linked to the CPU by an internal 16-bit bus and can be written or read by either word access or byte access.

Each TCNT is initialized to H'0000 by a reset and in standby mode.

9.2.8 General Registers (GRA, GRB)

The general registers are 16-bit registers. The 16-bit timer has 6 general registers, two in each channel.

Channel	Abbreviation	Function
0	GRA0, GRB0	Output compare/input capture register
1	GRA1, GRB1	
2	GRA2, GRB2	

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
Read/Write	R/W															

A general register is a 16-bit readable/writable register that can function as either an output compare register or an input capture register. The function is selected by settings in TIOR.

When a general register is used as an output compare register, its value is constantly compared with the TCNT value. When the two values match (compare match), the IMFA or IMFB flag is set to 1 in TISRA/TISRB. Compare match output can be selected in TIOR.

When a general register is used as an input capture register, rising edges, falling edges, or both edges of an external input capture signal are detected and the current TCNT value is stored in the general register. The corresponding IMFA or IMFB flag in TISRA/TISRB is set to 1 at the same time. The valid edge or edges of the input capture signal are selected in TIOR.

TIOR settings are ignored in PWM mode.

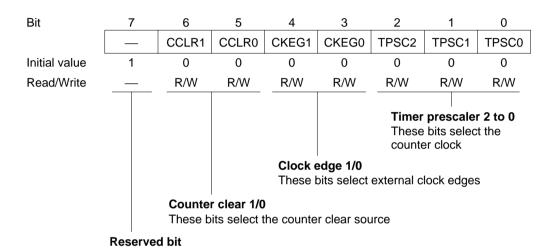
General registers are linked to the CPU by an internal 16-bit bus and can be written or read by either word access or byte access.

General registers are initialized to the output compare function (with no output signal) by a reset and in standby mode. The initial value is H'FFFF.

9.2.9 Timer Control Registers (TCR)

TCR is an 8-bit register. The 16-bit timer has three TCRs, one in each channel.

Channel	Abbreviation	Function
0	TCR0	CR controls the timer counter. The TCRs in all channels are
1	TCR1	functionally identical. When phase counting mode is ——selected in channel 2, the settings of bits CKEG1 and
2	TCR2	CKEG0 and TPSC2 to TPSC0 in TCR2 are ignored.



Each TCR is an 8-bit readable/writable register that selects the timer counter clock source, selects the edge or edges of external clock sources, and selects how the counter is cleared.

TCR is initialized to H'80 by a reset and in standby mode.

Bit 7—Reserved: This bit cannot be modified and is always read as 1.

Bits 6 and 5—Counter Clear 1/0 (CCLR1, CCLR0): These bits select how TCNT is cleared.

Bit 6 CCLR1	Bit 5 CCLR0	Description	
0	0	TCNT is not cleared	(Initial value)
	1	TCNT is cleared by GRA compare match or input capture*1	
1	0	TCNT is cleared by GRB compare match or input capture*1	
	1	Synchronous clear: TCNT is cleared in synchronization with oth synchronized timers*2	ner

Notes: 1. TCNT is cleared by compare match when the general register functions as an output compare register, and by input capture when the general register functions as an input capture register.

2. Selected in TSNC.

Bits 4 and 3—Clock Edge 1/0 (CKEG1, CKEG0): These bits select external clock input edges when an external clock source is used.

Bit 4 CKEG1	Bit 3 CKEG0	Description	
0	0	Count rising edges	(Initial value)
	1	Count falling edges	
1	_	Count both edges	

When channel 2 is set to phase counting mode, bits CKEG1 and CKEG0 in TCR2 are ignored. Phase counting takes precedence.

Bits 2 to 0—Timer Prescaler 2 to 0 (TPSC2 to TPSC0): These bits select the counter clock source.

Bit 2 TPSC2	Bit 1 TPSC1	Bit 0 TPSC0	Function	
0	0	0	Internal clock: ϕ	(Initial value)
		1	Internal clock: $\phi/2$	
	1	0	Internal clock: $\phi/4$	
		1	Internal clock: $\phi/8$	-
1	0	0	External clock A: TCLKA input	
		1	External clock B: TCLKB input	
	1	0	External clock C: TCLKC input	-
		1	External clock D: TCLKD input	

When bit TPSC2 is cleared to 0 an internal clock source is selected, and the timer counts only falling edges. When bit TPSC2 is set to 1 an external clock source is selected, and the timer counts the edge or edges selected by bits CKEG1 and CKEG0.

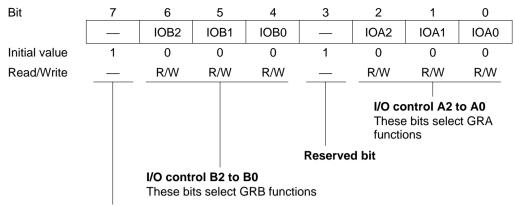
When channel 2 is set to phase counting mode (MDF = 1 in TMDR), the settings of bits TPSC2 to TPSC0 in TCR2 are ignored. Phase counting takes precedence.

9.2.10 Timer I/O Control Register (TIOR)

TIOR is an 8-bit register. The 16-bit timer has three TIORs, one in each channel.

Channel	Abbreviation	Function
0	TIOR0	TIOR controls the general registers. Some functions differ in PWM
1	TIOR1	mode.
2	TIOR2	_





Reserved bit

Each TIOR is an 8-bit readable/writable register that selects the output compare or input capture function for GRA and GRB, and specifies the functions of the TIORA and TIORC pins. If the output compare function is selected, TIOR also selects the type of output. If input capture is selected, TIOR also selects the edge or edges of the input capture signal.

TIOR is initialized to H'88 by a reset and in standby mode.

Bit 7—Reserved: This bit cannot be modified and is always read as 1.

Bits 6 to 4—I/O Control B2 to B0 (IOB2 to IOB0): These bits select the GRB function.

Bit 6 IOB2	Bit 5 IOB1	Bit 4 IOB0	Function	
0	0	0	GRB is an output	No output at compare match (Initial value)
		1	compare register	0 output at GRB compare match*1
	1	0	<u> </u>	1 output at GRB compare match*1
		1	_	Output toggles at GRB compare match (1 output in channel 2)*1 *2
1	0	0	GRB is an input	GRB captures rising edge of input
1 0 1	compare register	GRB captures falling edge of input		
	1	0		GRB captures both edges of input
		1		

Notes: 1. After a reset, the output conforms to the TOLR setting until the first compare match.

Channel 2 output cannot be toggled by compare match. This setting selects 1 output instead. **Bit 3—Reserved:** This bit cannot be modified and is always read as 1.

Bits 2 to 0—I/O Control A2 to A0 (IOA2 to IOA0): These bits select the GRA function.

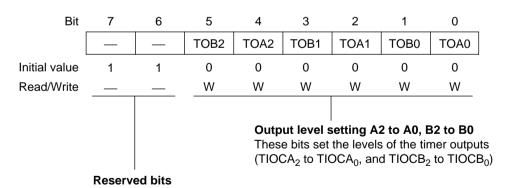
Bit 2 IOA2	Bit 1 IOA1	Bit 0 IOA0	Function	
0	0	0	GRA is an output compare register	No output at compare match (Initial value)
		1		0 output at GRA compare match*1
	1	0		1 output at GRA compare match*1
		1		Output toggles at GRA compare match (1 output in channel 2)*1*2
1	0 GRA is an input compare registe	GRA is an input	GRA captures rising edge of input	
		1	compare register	GRA captures falling edge of input
	1	0	<u> </u>	GRA captures both edges of input
		1	<u>—</u>	

Notes: 1. After a reset, the output conforms to the TOLR setting until the first compare match.

2. Channel 2 output cannot be toggled by compare match. This setting selects 1 output instead.

9.2.11 Timer Output Level Setting Register C (TOLR)

TOLR is an 8-bit write-only register that selects the timer output level for channels 0 to 2.



A TOLR setting can only be made when the corresponding bit in TSTR is 0.

TOLR is a write-only register; if read, a value of 1 will be returned.

TOLR is initialized to H'C0 by a reset and in standby mode.



Bits 7 and 6—Reserved: These bits cannot be modified.

Bit 5—Output Level Setting B2 (TOB2): Sets the value of timer output TIOCB,

Bit 5 TOB2	Description	
0	TIOCB ₂ is 0	(Initial value)
1	TIOCB ₂ is 1	

Bit 4—Output Level Setting A2 (TOA2): Sets the value of timer output TIOCA,.

Bit 4 TOA2	Description	
0	TIOCA ₂ is 0	(Initial value)
1	TIOCA ₂ is 1	

Bit 3—Output Level Setting B1 (TOB1): Sets the value of timer output TIOCB₁.

Bit 3		
TOB1	Description	
0	TIOCB₁ is 0	(Initial value)
1	TIOCB₁ is 1	

Bit 2—Output Level Setting A1 (TOA1): Sets the value of timer output TIOCA,

Bit 2 TOA1	Description	
0	TIOCA, is 0	(Initial value)
1	TIOCA, is 1	

Bit 1—Output Level Setting B0 (TOB0): Sets the value of timer output TIOCB₀.

Bit 0 TOB0	Description	
0	TIOCB₀ is 0	(Initial value)
1	TIOCB ₀ is 1	

Bit 0—Output Level Setting A0 (TOA0): Sets the value of timer output TIOCA₀.

Bit 0 TOA0	Description	
0	TIOCA ₀ is 0	(Initial value)
1	TIOCA ₀ is 1	

9.3 CPU Interface

9.3.1 16-Bit Accessible Registers

The timer counters (TCNTs), general registers A and B (GRAs and GRBs) are 16-bit registers, and are linked to the CPU by an internal 16-bit data bus. These registers can be written or read a word at a time, or a byte at a time.

Figures 9.4 and 9.5 show examples of word read/write access to a timer counter (TCNT). Figures 9.6, 9.7, 9.8, and 9.9 show examples of byte read/write access to TCNTH and TCNTL.

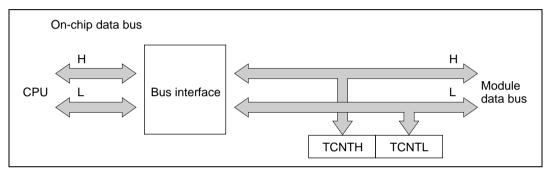


Figure 9.4 Access to Timer Counter (CPU Writes to TCNT, Word)

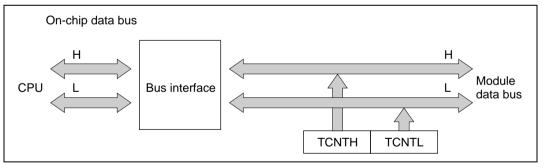


Figure 9.5 Access to Timer Counter (CPU Reads TCNT, Word)

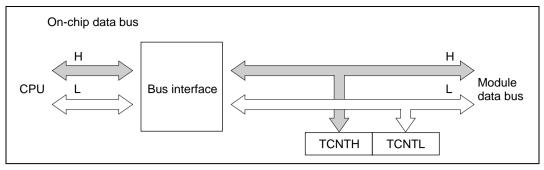


Figure 9.6 Access to Timer Counter (CPU Writes to TCNT, Upper Byte)

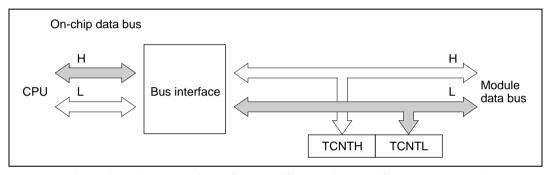


Figure 9.7 Access to Timer Counter (CPU Writes to TCNT, Lower Byte)

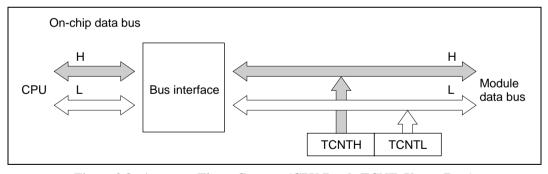


Figure 9.8 Access to Timer Counter (CPU Reads TCNT, Upper Byte)

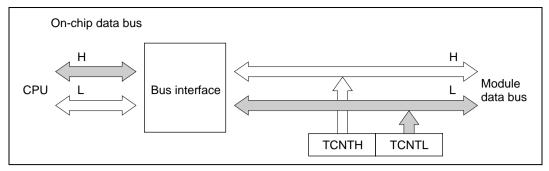


Figure 9.9 Access to Timer Counter (CPU Reads TCNT, Lower Byte)

9.3.2 8-Bit Accessible Registers

The registers other than the timer counters, general registers, and buffer registers are 8-bit registers. These registers are linked to the CPU by an internal 8-bit data bus.

Figures 9.10 and 9.11 show examples of byte read and write access to a TCR.

If a word-size data transfer instruction is executed, two byte transfers are performed.

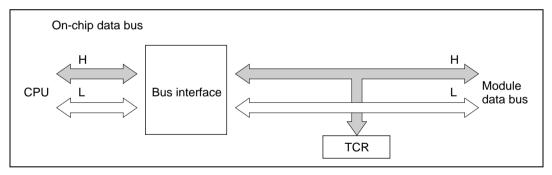


Figure 9.10 TCR Access (CPU Writes to TCR)

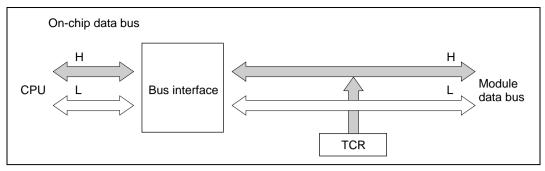


Figure 9.11 TCR Access (CPU Reads TCR)

9.4 Operation

9.4.1 Overview

A summary of operations in the various modes is given below.

Normal Operation: Each channel has a timer counter and general registers. The timer counter counts up, and can operate as a free-running counter, periodic counter, or external event counter. General registers A and B can be used for input capture or output compare.

Synchronous Operation: The timer counters in designated channels are preset synchronously. Data written to the timer counter in any one of these channels is simultaneously written to the timer counters in the other channels as well. The timer counters can also be cleared synchronously if so designated by the CCLR1 and CCLR0 bits in the TCRs.

PWM Mode: A PWM waveform is output from the TIOCA pin. The output goes to 1 at compare match A and to 0 at compare match B. The duty cycle can be varied from 0% to 100% depending on the settings of GRA and GRB. When a channel is set to PWM mode, its GRA and GRB automatically become output compare registers.

Phase Counting Mode: The phase relationship between two clock signals input at TCLKA and TCLKB is detected and TCNT2 counts up or down accordingly. When phase counting mode is selected TCLKA and TCLKB become clock input pins and TCNT2 operates as an up/down-counter.



9.4.2 Basic Functions

Counter Operation: When one of bits STR0 to STR2 is set to 1 in the timer start register (TSTR), the timer counter (TCNT) in the corresponding channel starts counting. The counting can be free-running or periodic.

• Sample setup procedure for counter
Figure 9.12 shows a sample procedure for setting up a counter.

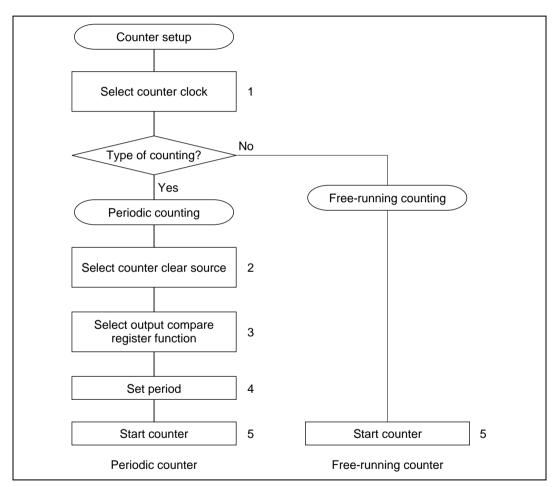


Figure 9.12 Counter Setup Procedure (Example)

Set bits TPSC2 to TPSC0 in TCR to select the counter clock source. If an external clock source
is selected, set bits CKEG1 and CKEG0 in TCR to select the desired edge(s) of the external
clock signal.

- 2. For periodic counting, set CCLR1 and CCLR0 in TCR to have TCNT cleared at GRA compare match or GRB compare match.
- 3. Set TIOR to select the output compare function of GRA or GRB, whichever was selected in step 2.
- 4. Write the count period in GRA or GRB, whichever was selected in step 2.
- 5. Set the STR bit to 1 in TSTR to start the timer counter.
- Free-running and periodic counter operation
 A reset leaves the counters (TCNTs) in 16-bit timer channels 0 to 2 all set as free-running

to 1. When the count overflows from H'FFFF to H'0000, the OVF flag is set to 1 in TISRC. After the overflow, the counter continues counting up from H'0000. Figure 9.13 illustrates free-running counting.

counters. A free-running counter starts counting up when the corresponding bit in TSTR is set

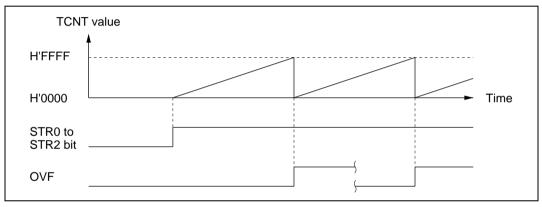


Figure 9.13 Free-Running Counter Operation

When a channel is set to have its counter cleared by compare match, in that channel TCNT operates as a periodic counter. Select the output compare function of GRA or GRB, set bit CCLR1 or CCLR0 in TCR to have the counter cleared by compare match, and set the count period in GRA or GRB. After these settings, the counter starts counting up as a periodic counter when the corresponding bit is set to 1 in TSTR. When the count matches GRA or GRB, the IMFA or IMFB flag is set to 1 in TISRA/TISRB and the counter is cleared to H'0000. If the corresponding IMIEA or IMIEB bit is set to 1 in TISRA/TISRB, a CPU interrupt is requested at this time. After the compare match, TCNT continues counting up from H'0000. Figure 9.14 illustrates periodic counting.

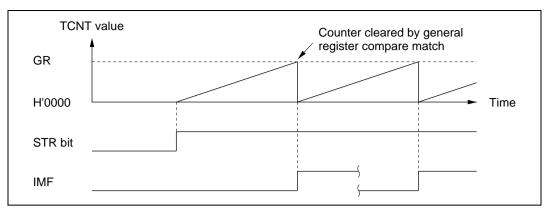


Figure 9.14 Periodic Counter Operation

- TCNT count timing
 - Internal clock source

Bits TPSC2 to TPSC0 in TCR select the system clock (ϕ) or one of three internal clock sources obtained by prescaling the system clock (ϕ /2, ϕ /4, ϕ /8).

Figure 9.15 shows the timing.

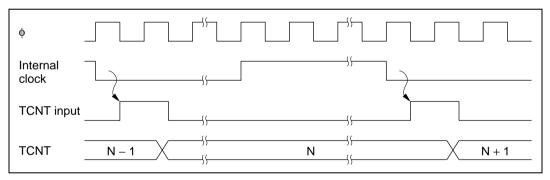


Figure 9.15 Count Timing for Internal Clock Sources

External clock source

Bits TPSC2 to TPSC0 in TCR select an external clock input pin (TCLKA to TCLKD), and its valid edge or edges are selected by bits CKEG1 and CKEG0. The rising edge, falling edge, or both edges can be selected.

The pulse width of the external clock signal must be at least 1.5 system clocks when a single edge is selected, and at least 2.5 system clocks when both edges are selected. Shorter pulses will not be counted correctly.

Figure 9.16 shows the timing when both edges are detected.

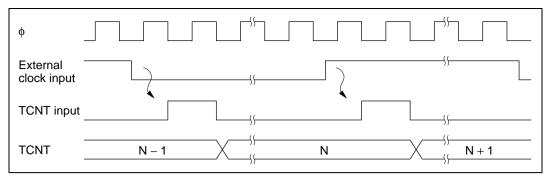


Figure 9.16 Count Timing for External Clock Sources (when Both Edges are Detected)

Waveform Output by Compare Match: In 16-bit timer channels 0, 1 compare match A or B can cause the output at the TIOCA or TIOCB pin to go to 0, go to 1, or toggle. In channel 2 the output can only go to 0 or go to 1.

Sample setup procedure for waveform output by compare match
 Figure 9.17 shows the timing for detection of both rising and falling edges.

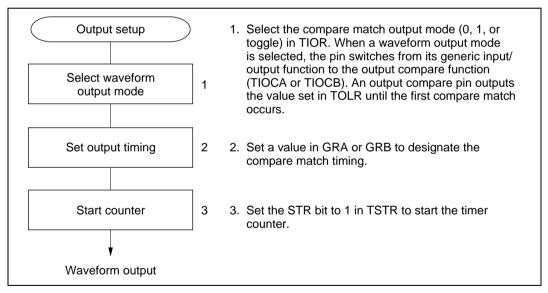


Figure 9.17 Setup Procedure for Waveform Output by Compare Match (Example)

Examples of waveform output
 Figure 9.18 shows examples of 0 and 1 output. TCNT operates as a free-running counter, 0 output is selected for compare match A, and 1 output is selected for compare match B. When the pin is already at the selected output level, the pin level does not change.

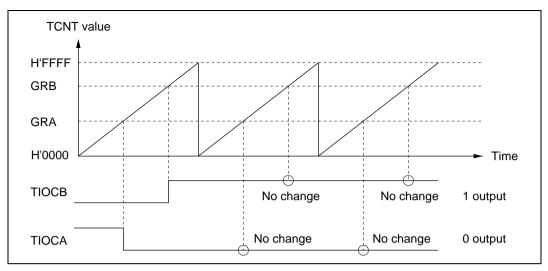


Figure 9.18 0 and 1 Output (TOA = 1, TOB = 0)

Figure 9.19 shows examples of toggle output. TCNT operates as a periodic counter, cleared by compare match B. Toggle output is selected for both compare match A and B.

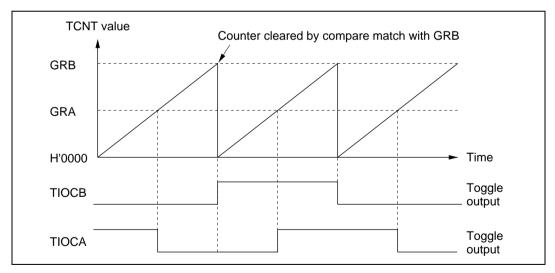


Figure 9.19 Toggle Output (TOA = 1, TOB = 0)

• Output compare output timing

The compare match signal is generated in the last state in which TCNT and the general register match (when TCNT changes from the matching value to the next value). When the compare match signal is generated, the output value selected in TIOR is output at the output compare pin (TIOCA or TIOCB). When TCNT matches a general register, the compare match signal is not generated until the next counter clock pulse.

Figure 9.20 shows the output compare timing.

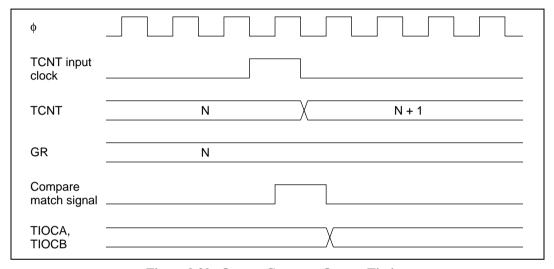


Figure 9.20 Output Compare Output Timing

Input Capture Function: The TCNT value can be captured into a general register when a transition occurs at an input capture/output compare pin (TIOCA or TIOCB). Capture can take place on the rising edge, falling edge, or both edges. The input capture function can be used to measure pulse width or period.

Sample setup procedure for input capture
 Figure 9.21 shows a sample procedure for setting up input capture.

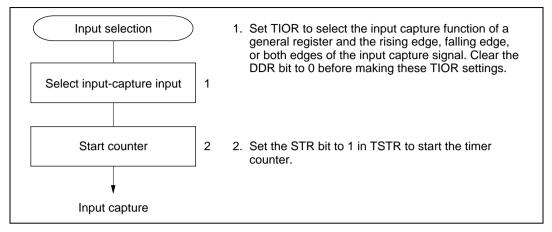


Figure 9.21 Setup Procedure for Input Capture (Example)

Examples of input capture
 Figure 9.22 illustrates input capture when the falling edge of TIOCB and both edges of TIOCA

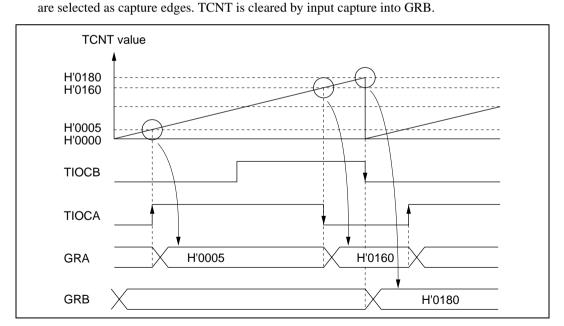


Figure 9.22 Input Capture (Example)

Input capture signal timing
Input capture on the rising edge, falling edge, or both edges can be selected by settings in
TIOR. Figure 9.23 shows the timing when the rising edge is selected. The pulse width of the
input capture signal must be at least 1.5 system clocks for single-edge capture, and 2.5 system
clocks for capture of both edges.

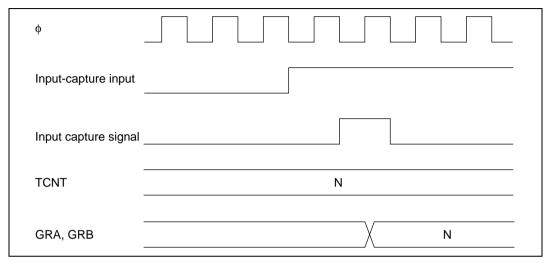
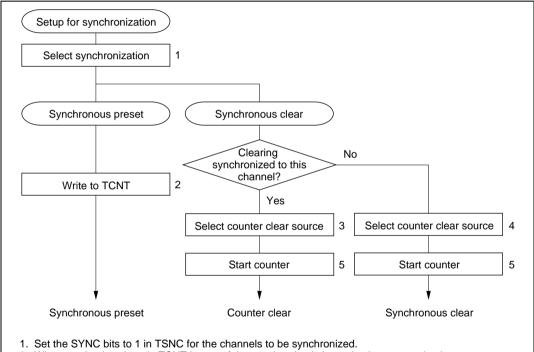


Figure 9.23 Input Capture Signal Timing

9.4.3 Synchronization

The synchronization function enables two or more timer counters to be synchronized by writing the same data to them simultaneously (synchronous preset). With appropriate TCR settings, two or more timer counters can also be cleared simultaneously (synchronous clear). Synchronization enables additional general registers to be associated with a single time base. Synchronization can be selected for all channels (0 to 2).

Sample Setup Procedure for Synchronization: Figure 9.24 shows a sample procedure for setting up synchronization.



- 2. When a value is written in TCNT in one of the synchronized channels, the same value is simultaneously written in TCNT in the other channels (synchronized preset).
- 3. Set the CCLR1 or CCLR0 bit in TCR to have the counter cleared by compare match or input capture.
- 4. Set the CCLR1 and CCLR0 bits in TCR to have the counter cleared synchronously.
- 5. Set the STR bits in TSTR to 1 to start the synchronized counters.

Figure 9.24 Setup Procedure for Synchronization (Example)

Example of Synchronization: Figure 9.25 shows an example of synchronization. Channels 0, 1, and 2 are synchronized, and are set to operate in PWM mode. Channel 0 is set for counter clearing by compare match with GRB0. Channels 1 and 2 are set for synchronous counter clearing. The timer counters in channels 0, 1, and 2 are synchronously preset, and are synchronously cleared by compare match with GRB0. A three-phase PWM waveform is output from pins TIOCA₀, TIOCA₁, and TIOCA₂. For further information on PWM mode, see section 9.4.4, PWM Mode.

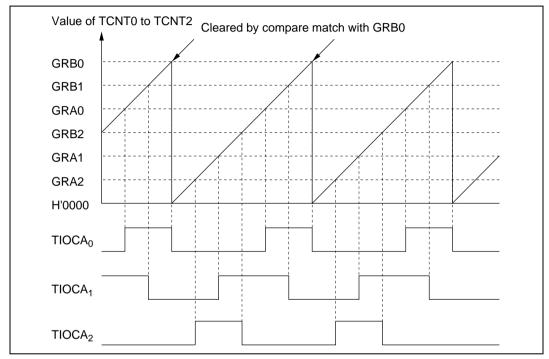


Figure 9.25 Synchronization (Example)

9.4.4 PWM Mode

In PWM mode GRA and GRB are paired and a PWM waveform is output from the TIOCA pin. GRA specifies the time at which the PWM output changes to 1. GRB specifies the time at which the PWM output changes to 0. If either GRA or GRB is selected as the counter clear source, a PWM waveform with a duty cycle from 0% to 100% is output at the TIOCA pin. PWM mode can be selected in all channels (0 to 2).

Table 9.4 summarizes the PWM output pins and corresponding registers. If the same value is set in GRA and GRB, the output does not change when compare match occurs.

Table 9.4 PWM Output Pins and Registers

Channel	Output Pin	1 Output	0 Output	
0	TIOCA₀	GRA0	GRB0	
1	TIOCA ₁	GRA1	GRB1	
2	TIOCA ₂	GRA2	GRB2	

Sample Setup Procedure for PWM Mode: Figure 9.26 shows a sample procedure for setting up PWM mode.

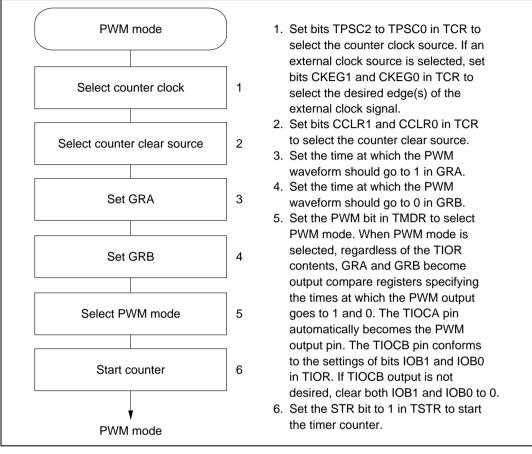


Figure 9.26 Setup Procedure for PWM Mode (Example)

Examples of PWM Mode: Figure 9.27 shows examples of operation in PWM mode. In PWM mode TIOCA becomes an output pin. The output goes to 1 at compare match with GRA, and to 0 at compare match with GRB.

In the examples shown, TCNT is cleared by compare match with GRA or GRB. Synchronized operation and free-running counting are also possible.

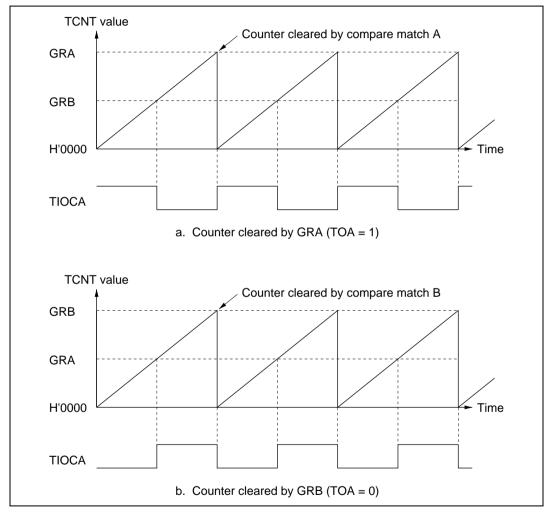


Figure 9.27 PWM Mode (Example 1)

Figure 9.28 shows examples of the output of PWM waveforms with duty cycles of 0% and 100%. If the counter is cleared by compare match with GRB, and GRA is set to a higher value than GRB, the duty cycle is 0%. If the counter is cleared by compare match with GRA, and GRB is set to a higher value than GRA, the duty cycle is 100%.

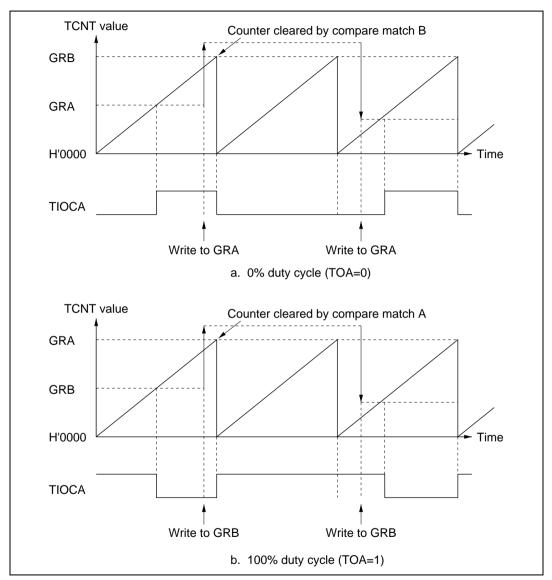


Figure 9.28 PWM Mode (Example 2)

9.4.5 Phase Counting Mode

In phase counting mode the phase difference between two external clock inputs (at the TCLKA and TCLKB pins) is detected, and TCNT2 counts up or down accordingly.

In phase counting mode, the TCLKA and TCLKB pins automatically function as external clock input pins and TCNT2 becomes an up/down-counter, regardless of the settings of bits TPSC2 to TPSC0, CKEG1, and CKEG0 in TCR2. Settings of bits CCLR1, CCLR0 in TCR2, and settings in TIOR2, TISRA, TISRB, TISRC, STR2 in TSTR, GRA2, and GRB2 are valid. The input capture and output compare functions can be used, and interrupts can be generated.

Phase counting is available only in channel 2.

Sample Setup Procedure for Phase Counting Mode: Figure 9.29 shows a sample procedure for setting up phase counting mode.

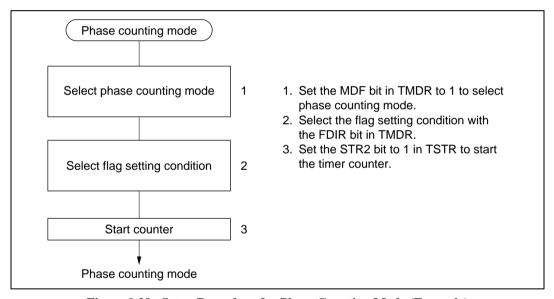


Figure 9.29 Setup Procedure for Phase Counting Mode (Example)

Example of Phase Counting Mode: Figure 9.30 shows an example of operations in phase counting mode. Table 9.5 lists the up-counting and down-counting conditions for TCNT2.

In phase counting mode both the rising and falling edges of TCLKA and TCLKB are counted. The phase difference between TCLKA and TCLKB must be at least 1.5 states, the phase overlap must also be at least 1.5 states, and the pulse width must be at least 2.5 states.

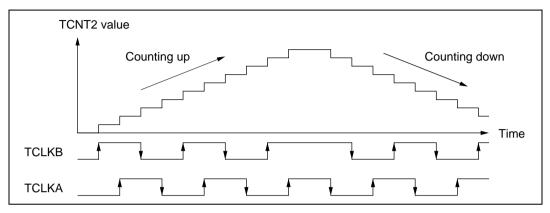


Figure 9.30 Operation in Phase Counting Mode (Example)

Table 9.5 Up/Down Counting Conditions

Counting Direction	Up-Co	unting	Down-Counting						
TCLKB pin	<u></u>	High	Ť	Low	High	Ť	Low	<u></u>	
TCLKA pin	Low	<u>_</u>	High	Ť	Ť	Low	<u>_</u>	High	

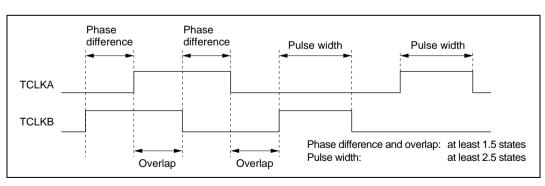


Figure 9.31 Phase Difference, Overlap, and Pulse Width in Phase Counting Mode

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9.4.6 **Setting Initial Value of 16-Bit Timer Output**

Any desired value can be specified for the initial 16-bit timer output value when a timer count operation is started by making a setting in TOLR.

Figure 9.32 shows the timing for setting the initial output value with TOLR.

Only write to TOLR when the corresponding bit in TSTR is cleared to 0.

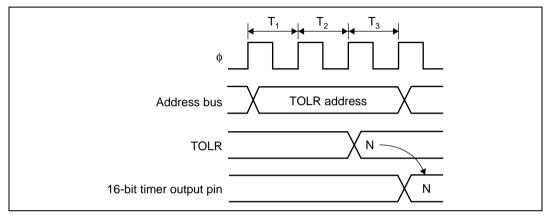


Figure 9.32 Example of Timing for Setting Initial Value of 16-Bit Timer Output by Writing to TOLR

9.5 Interrupts

The 16-bit timer has two types of interrupts: input capture/compare match interrupts, and overflow interrupts.

9.5.1 Setting of Status Flags

Timing of Setting of IMFA and IMFB at Compare Match: IMFA and IMFB are set to 1 by a compare match signal generated when TCNT matches a general register (GR). The compare match signal is generated in the last state in which the values match (when TCNT is updated from the matching count to the next count). Therefore, when TCNT matches a general register, the compare match signal is not generated until the next TCNT clock input. Figure 9.33 shows the timing of the setting of IMFA and IMFB.

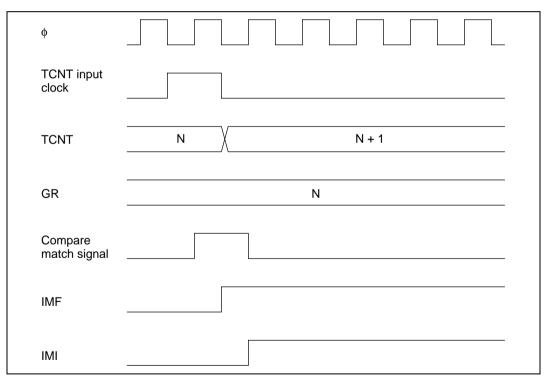


Figure 9.33 Timing of Setting of IMFA and IMFB by Compare Match

Timing of Setting of IMFA and IMFB by Input Capture: IMFA and IMFB are set to 1 by an input capture signal. The TCNT contents are simultaneously transferred to the corresponding general register. Figure 9.34 shows the timing.

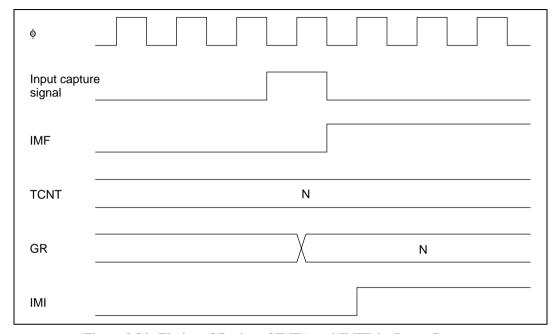


Figure 9.34 Timing of Setting of IMFA and IMFB by Input Capture

Timing of Setting of Overflow Flag (OVF): OVF is set to 1 when TCNT overflows from H'FFFF to H'0000 or underflows from H'0000 to H'FFFF. Figure 9.35 shows the timing.

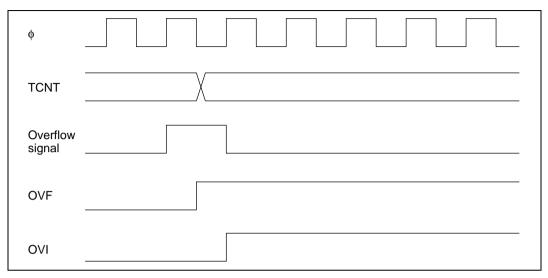


Figure 9.35 Timing of Setting of OVF

9.5.2 **Timing of Clearing of Status Flags**

If the CPU reads a status flag while it is set to 1, then writes 0 in the status flag, the status flag is cleared. Figure 9.36 shows the timing.

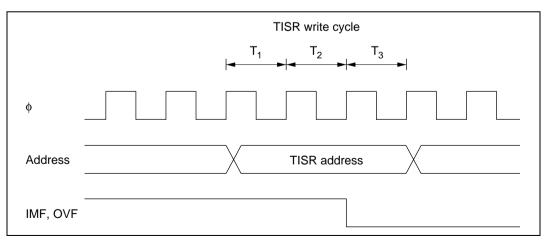


Figure 9.36 Timing of Clearing of Status Flags



9.5.3 Interrupt Sources and DMA Controller Activation

Each 16-bit timer channel can generate a compare match/input capture A interrupt, a compare match/input capture B interrupt, and an overflow interrupt. In total there are nine interrupt sources of three kinds, all independently vectored. An interrupt is requested when the interrupt request flag are set to 1.

The priority order of the channels can be modified in interrupt priority register A (IPRA). For details see section 5, Interrupt Controller.

Compare match/input capture A interrupts in channels 0 to 2 can activate the DMA controller (DMAC). When the DMAC is activated a CPU interrupt is not requested.

Table 9.6 lists the interrupt sources.

Table 9.6 16-bit timer Interrupt Sources

Channel	Interrupt Source	Description	DMAC Activatable	Priority*
0	IMIA0	Compare match/input capture A0	Yes	High
	IMIB0	Compare match/input capture B0	No	A
	OVI0	Overflow 0	No	lack
1	IMIA1	Compare match/input capture A1	Yes	
	IMIB1	Compare match/input capture B1	No	
	OVI1	Overflow 1	No	
2	IMIA2	Compare match/input capture A2	Yes	
	IMIB2	Compare match/input capture B2	No	
	OVI2	Overflow 2	No	Low

Note: * The priority immediately after a reset is indicated. Inter-channel priorities can be changed by settings in IPRA.

9.6 Usage Notes

This section describes contention and other matters requiring special attention during 16-bit timer operations.

Contention between TCNT Write and Clear: If a counter clear signal occurs in the T₃ state of a TCNT write cycle, clearing of the counter takes priority and the write is not performed. See figure 9.37.

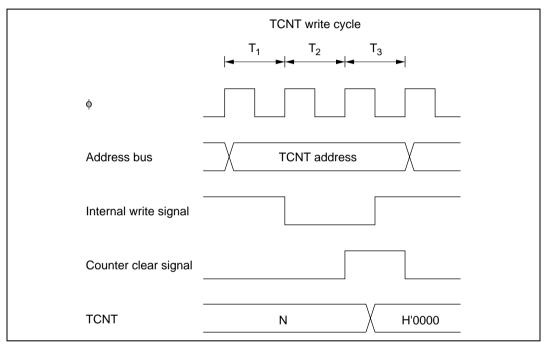


Figure 9.37 Contention between TCNT Write and Clear



Contention between TCNT Word Write and Increment: If an increment pulse occurs in the T₃ state of a TCNT word write cycle, writing takes priority and TCNT is not incremented. Figure 9.38 shows the timing in this case.

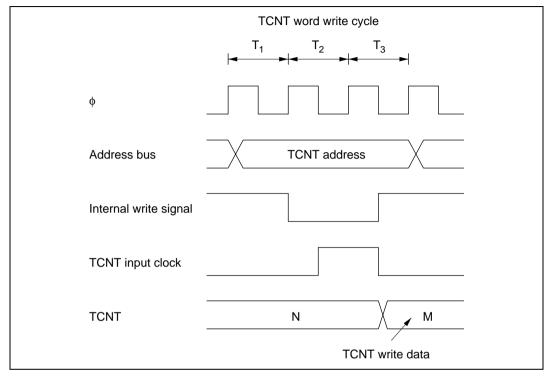


Figure 9.38 Contention between TCNT Word Write and Increment

Contention between TCNT Byte Write and Increment: If an increment pulse occurs in the T_2 or T_3 state of a TCNT byte write cycle, writing takes priority and TCNT is not incremented. The TCNT byte that was not written retains its previous value. See figure 9.39, which shows an increment pulse occurring in the T_2 state of a byte write to TCNTH.

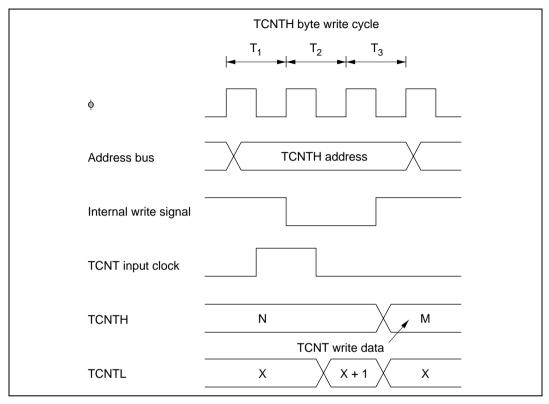


Figure 9.39 Contention between TCNT Byte Write and Increment

Contention between General Register Write and Compare Match: If a compare match occurs in the T_3 state of a general register write cycle, writing takes priority and the compare match signal is inhibited. See figure 9.40.

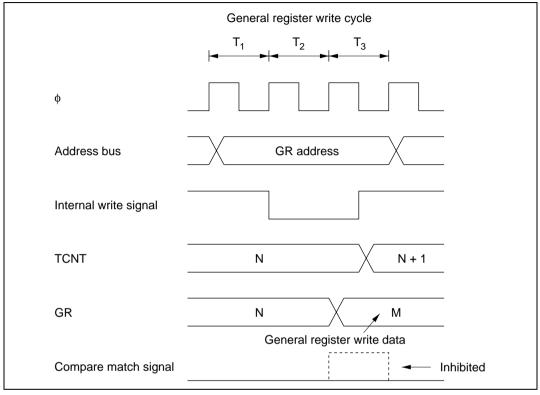


Figure 9.40 Contention between General Register Write and Compare Match

Contention between TCNT Write and Overflow or Underflow: If an overflow occurs in the T_3 state of a TCNT write cycle, writing takes priority and the counter is not incremented. OVF is set to 1. The same holds for underflow. See figure 9.41.

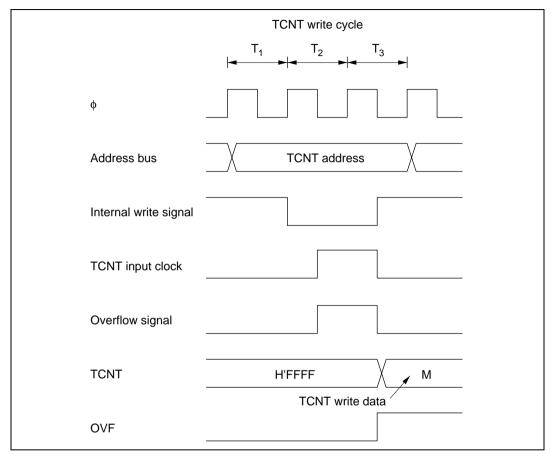


Figure 9.41 Contention between TCNT Write and Overflow

Contention between General Register Read and Input Capture: If an input capture signal occurs during the T_3 state of a general register read cycle, the value before input capture is read. See figure 9.42.

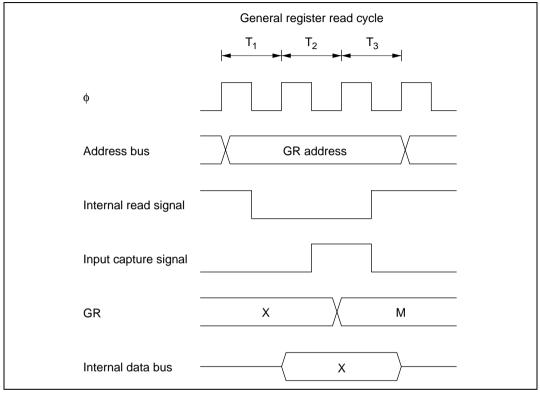


Figure 9.42 Contention between General Register Read and Input Capture

Contention between Counter Clearing by Input Capture and Counter Increment: If an input capture signal and counter increment signal occur simultaneously, the counter is cleared according to the input capture signal. The counter is not incremented by the increment signal. The counter is not incremented by the increment signal. The value before the counter is cleared is transferred to the general register. See figure 9.43.

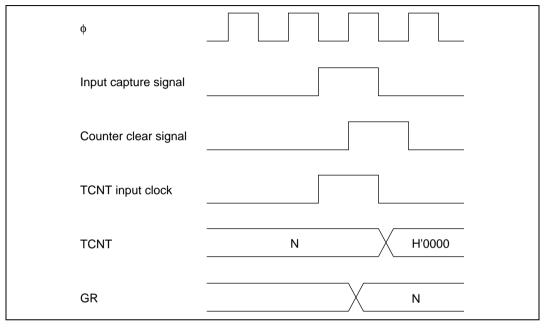


Figure 9.43 Contention between Counter Clearing by Input Capture and Counter Increment

Contention between General Register Write and Input Capture: If an input capture signal occurs in the T_3 state of a general register write cycle, input capture takes priority and the write to the general register is not performed. See figure 9.44.

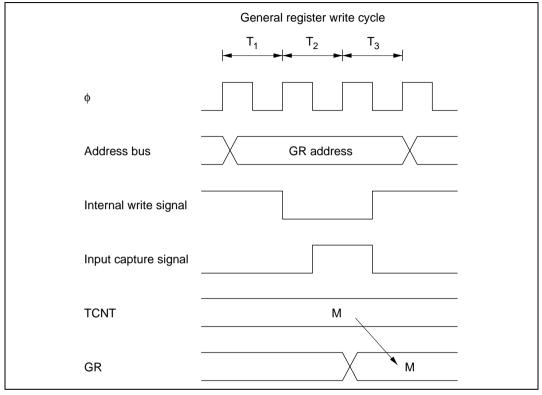


Figure 9.44 Contention between General Register Write and Input Capture

Note on Waveform Period Setting: When a counter is cleared by compare match, the counter is cleared in the last state at which the TCNT value matches the general register value, at the time when this value would normally be updated to the next count. The actual counter frequency is therefore given by the following formula:

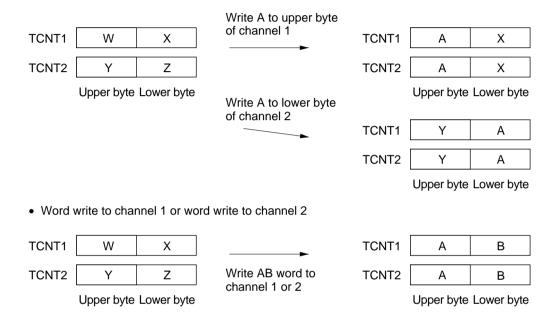
$$f = \frac{\phi}{(N+1)}$$

(f: counter frequency. ϕ : system clock frequency. N: value set in general register.)

Note on Writes in Synchronized Operation: When channels are synchronized, if a TCNT value is modified by byte write access, all 16 bits of all synchronized counters assume the same value as the counter that was addressed.

(Example) When channels 1 and 2 are synchronized

• Byte write to channel 1 or byte write to channel 2





16-bit timer Operating Modes:

Table 9.7 (a)16-bit timer Operating Modes (Channel 0)

					Regis	ter Settings			
		TSNC		TMD	R	TIC	DR0	TCR	0
Operating Mode		Synchro- nization	MDF	FDIR	PWM	IOA	ЮВ	Clear Select	Clock Select
Synchro	nous preset	SYNC0 = 1	_	_	0	0	0	0	0
PWM mo	ode	0		_	PWM0 = 1	_	0*	0	0
Output c	ompare A	0	_	_	PWM0 = 0	IOA2 = 0 Other bits unrestricted	0	0	0
Output c	ompare B	0	_	_	0	0	IOB2 = 0 Other bits unrestricted	0	0
Input cap	oture A	0	_	_	PWM0 = 0	IOA2 = 1 Other bits unrestricted	0	0	0
Input cap	oture B	0	_	_	PWM0 = 0	0	IOB2 = 1 Other bits unrestricted	0	0
Counter	By compare match/input capture A	0	_	_	0	0	0	CCLR1 = 0 CCLR0 = 1	0
	By compare match/input capture B	0	_	_	0	0	0	CCLR1 = 1 CCLR0 = 0	0
	Syn- chronous clear	SYNC0 = 1	_	_	0	0	0	CCLR1 = 1 CCLR0 = 1	0

Legend: O Setting available (valid). — Setting does not affect this mode.

Note: * The input capture function cannot be used in PWM mode. If compare match A and compare match B occur simultaneously, the compare match signal is inhibited.

Table 9.7 (b) 16-bit timer Operating Modes (Channel 1)

		Register Settings									
		TSNC		TMD	R	TIC	DR1	TCR	1		
Operatir	ng Mode	Synchro- nization	MDF	FDIR	PWM	IOA	IOB	Clear Select	Clock Select		
Synchronous preset		SYNC1 = 1	_	_	0	0	0	0	0		
PWM mo	ode	0	_	_	PWM1 = 1	_	0*	0	0		
Output c	ompare A	0	_	_	PWM1 = 0	IOA2 = 0 Other bits unrestricted	0	0	0		
Output c	ompare B	0	_	_	0	0	IOB2 = 0 Other bits unrestricted	0	0		
Input cap	oture A	0	_	_	PWM1 = 0	IOA2 = 1 Other bits unrestricted	0	0	0		
Input cap	oture B	0	_	_	PWM1 = 0	0	IOB2 = 1 Other bits unrestricted	0	0		
Counter	By compare match/input capture A	0	_	_	0	0	0	CCLR1 = 0 CCLR0 = 1	0		
	By compare match/input capture B	0	_	_	0	0	0	CCLR1 = 1 CCLR0 = 0	0		
	Syn- chronous clear	SYNC1 = 1	_	_	0	0	0	CCLR1 = 1 CCLR0 = 1	0		

Legend: O Setting available (valid). — Setting does not affect this mode.

Notes: * The input capture function cannot be used in PWM mode. If compare match A and compare match B occur simultaneously, the compare match signal is inhibited.

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Table 9.7 (c) 16-bit timer Operating Modes (Channel 2)

					Regis	ter Settings			
		TSNC		TMD	R	TIC	DR2	TCR:	2
Operatir	ng Mode	Synchro- nization	MDF	FDIR	PWM	IOA	IOB	Clear Select	Clock Select
Synchro	nous preset	SYNC2 = 1	0	_	0	0	0	0	0
PWM mo	ode	0	0	_	PWM2 = 1	_	0*	0	0
Output c	ompare A	0	0	_	PWM2 = 0	IOA2 = 0 Other bits unrestricted	0	0	0
Output c	ompare B	0	0	_	0	0	IOB2 = 0 Other bits unrestricted	0	0
Input cap	oture A	0	0	_	PWM2 = 0	IOA2 = 1 Other bits unrestricted	0	0	0
Input cap	oture B	0	0	_	PWM2 = 0	0	IOB2 = 1 Other bits unrestricted	0	0
Counter	By compare match/input capture A	0	0	_	0	0	0	CCLR1 = 0 CCLR0 = 1	0
	By compare match/input capture B	0	0	_	0	0	0	CCLR1 = 1 CCLR0 = 0	0
	Syn- chronous clear	SYNC2 = 1	0	_	0	0	0	CCLR1 = 1 CCLR0 = 1	0
Phase co	ounting	0	MDF = 1	0	0	0	0	0	_

Legend: O Setting available (valid). — Setting does not affect this mode.

Note: * The input capture function cannot be used in PWM mode. If compare match A and compare match B occur simultaneously, the compare match signal is inhibited.

Section 10 8-Bit Timers

10.1 Overview

The H8/3067 Group has a built-in 8-bit timer module with four channels (TMR0, TMR1, TMR2, and TMR3), based on 8-bit counters. Each channel has an 8-bit timer counter (TCNT) and two 8-bit time constant registers (TCORA and TCORB) that are constantly compared with the TCNT value to detect compare match events. The timers can be used as multifunctional timers in a variety of applications, including the generation of a rectangular-wave output with an arbitrary duty cycle.

10.1.1 Features

The features of the 8-bit timer module are listed below.

- Selection of four clock sources
 - The counters can be driven by one of three internal clock signals ($\phi/8$, $\phi/64$, or $\phi/8192$) or an external clock input (enabling use as an external event counter).
- Selection of three ways to clear the counters
 - The counters can be cleared on compare match A or B, or input capture B.
- Timer output controlled by two compare match signals
 - The timer output signal in each channel is controlled by two independent compare match signals, enabling the timer to generate output waveforms with an arbitrary duty cycle or PWM output.
- A/D converter can be activated by a compare match
- Two channels can be cascaded.
 - Channels 0 and 1 can be operated as the upper and lower halves of a 16-bit timer (16-bit count mode).
 - Channels 2 and 3 can be operated as the upper and lower halves of a 16-bit timer (16-bit count mode).
 - Channel 1 can count channel 0 compare match events (compare match count mode).
 - Channel 3 can count channel 2 compare match events (compare match count mode).
- Input capture function can be set
 - 8-bit or 16-bit input capture operation is available.
- Twelve interrupt sources
 - There are twelve interrupt sources: four compare match sources, four compare match/input capture sources, four overflow sources.

Two of the compare match sources and two of the combined compare match/input capture sources each have an independent interrupt vector. The remaining compare match interrupts, combined compare match/input capture interrupts, and overflow interrupts have one interrupt vector for two sources.



10.1.2 Block Diagram

The 8-bit timers are divided into two groups of two channels each: group 0 comprising channels 0 and 1, and group 1 comprising channels 2 and 3. Figure 10.1 shows a block diagram of 8-bit timer group 0.

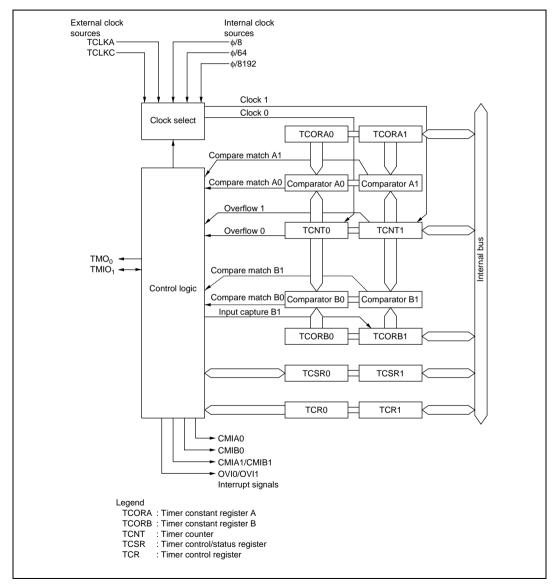


Figure 10.1 Block Diagram of 8-Bit Timer Unit (Two Channels: Group 0)

10.1.3 Pin Configuration

Table 10.1 summarizes the input/output pins of the 8-bit timer module.

Table 10.1 8-Bit Timer Pins

Group	Channel	Name	Abbreviation	I/O	Input/output
0	0	Timer output	TMO _o	Output	Compare match output
		Timer clock input	TCLKC	Input	Counter external clock input
	1	Timer input/output	TMIO ₁	I/O	Compare match output/input capture input
		Timer clock input	TCLKA	Input	Counter external clock input
1	2	Timer output	TMO ₂	Output	Compare match output
		Timer clock input	TCLKD	Input	Counter external clock input
	3	Timer input/output	TMIO ₃	I/O	Compare match output/input capture input
		Timer clock input	TCLKB	Input	Counter external clock input

10.1.4 Register Configuration

Table 10.2 summarizes the registers of the 8-bit timer module.

Table 10.2 8-Bit Timer Registers

l'FFF82 l'FFF84	Timer control register 0 Timer control/status register 0 Timer constant register A0	TCR0 TCSR0	R/W R/(W)*2	H'00
l'FFF84		TCSR0	R/(W)*2	
	Timer constant register A0		, (,	H'00
UEEEOO		TCORA0	R/W	H'FF
177786	Timer constant register B0	TCORB0	R/W	H'FF
l'FFF88	Timer counter 0	TCNT0	R/W	H'00
l'FFF81	Timer control register 1	TCR1	R/W	H'00
l'FFF83	Timer control/status register 1	TCSR1	R/(W)*2	H'00
l'FFF85	Timer constant register A1	TCORA1	R/W	H'FF
l'FFF87	Timer constant register B1	TCORB1	R/W	H'FF
l'FFF89	Timer counter 1	TCNT1	R/W	H'00
l'FFF90	Timer control register 2	TCR2	R/W	H'00
l'FFF92	Timer control/status register 2	TCSR2	R/(W)*2	H'00
l'FFF94	Timer constant register A2	TCORA2	R/W	H'FF
l'FFF96	Timer constant register B2	TCORB2	R/W	H'FF
l'FFF98	Timer counter 2	TCNT2	R/W	H'00
l'FFF91	Timer control register 3	TCR3	R/W	H'00
l'FFF93	Timer control/status register 3	TCSR3	R/(W)*2	H'00
l'FFF95	Timer constant register A3	TCORA3	R/W	H'FF
l'FFF97	Timer constant register B3	TCORB3	R/W	H'FF
l'FFF99	Timer counter 3	TCNT3	R/W	H'00
	FFF88 FFF81 FFF83 FFF85 FFF87 FFF89 FFF90 FFF92 FFF96 FFF96 FFF98 FFF91 FFF93 FFF95	Timer counter 0 Timer control register 1 Timer control/status register 1 Timer constant register A1 Timer constant register B1 Timer constant register B1 Timer counter 1 Timer control register 2 Timer control/status register 2 Timer control/status register A2 Timer constant register A2 Timer constant register B2 Timer constant register B2 Timer control register B2 Timer control register B2 Timer control register A3 Timer control/status register A3 Timer constant register A3 Timer constant register B3	TCNT0 TFFF88 Timer counter 0 TCNT0 TFFF81 Timer control register 1 TCR1 TFFF83 Timer control/status register 1 TCSR1 TFFF85 Timer constant register A1 TCORA1 TFFF87 Timer constant register B1 TCORB1 TFFF89 Timer counter 1 TCNT1 TFFF90 Timer control register 2 TCR2 TFFF92 Timer control/status register 2 TCR2 TFFF94 Timer constant register A2 TCORA2 TFFF96 Timer constant register B2 TCORB2 TFFF97 Timer control/status register 3 TCR3 TFFF91 Timer control/status register 3 TCR3 TFFF95 Timer constant register A3 TCORA3 TFFF97 Timer constant register B3 TCORB3	Timer counter 0 TCNT0 R/W TFFF81 Timer control register 1 TCR1 R/W TFFF83 Timer control/status register 1 TCSR1 R/(W)*2 TFFF85 Timer constant register A1 TCORA1 R/W TFFF87 Timer constant register B1 TCORB1 R/W TFFF89 Timer counter 1 TCNT1 R/W TFFF90 Timer control register 2 TCR2 R/W TFFF91 Timer constant register A2 TCORA2 R/W TFFF96 Timer constant register B2 TCORB2 R/W TFFF98 Timer counter 2 TCNT2 R/W TFFF99 Timer control register 3 TCR3 R/W TFFF91 Timer control register 3 TCR3 R/W TFFF93 Timer constant register A3 TCORA3 R/W TFFF95 Timer constant register B3 TCORB3 R/W TFFF97 Timer constant register B3 TCORB3 R/W TFFF99 Timer counter 3 TCNT3 R/W TFFF99 Timer constant register B3 TCORB3 R/W TFFF99 Timer constant register B3 TCORB3 R/W TFFF99 Timer counter 3 TCNT3 R/W

Notes: 1. Indicates the lower 20 bits of the address in advanced mode.

2. Only 0 can be written to bits 7 to 5, to clear these flags.

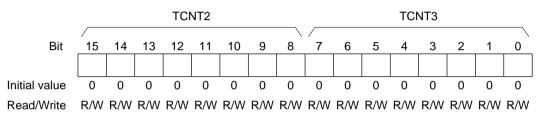
Each pair of registers for channel 0 and channel 1 comprises a 16-bit register with the channel 0 register as the upper 8 bits and the channel 1 register as the lower 8 bits, so they can be accessed together by word access.

Similarly, each pair of registers for channel 2 and channel 3 comprises a 16-bit register with the channel 2 register as the upper 8 bits and the channel 3 register as the lower 8 bits, so they can be accessed together by word access.

10.2 Register Descriptions

10.2.1 Timer Counters (TCNT)

		TCNT0							TCNT1							
Bit	_15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W



The timer counters (TCNT) are 8-bit readable/writable up-counters that increment on pulses generated from an internal or external clock source. The clock source is selected by clock select bits 2 to 0 (CKS2 to CKS0) in the timer control register (TCR). The CPU can always read or write to the timer counters.

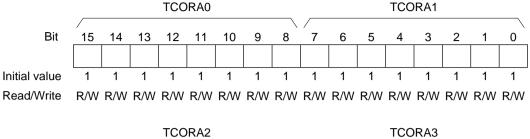
The TCNT0 and TCNT1 pair, and the TCNT2 and TCNT3 pair, can each be accessed as a 16-bit register by word access.

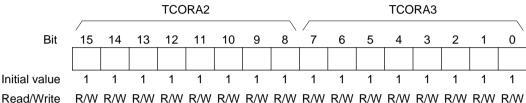
TCNT can be cleared by an input capture signal or compare match signal. Counter clear bits 1 and 0 (CCLR1 and CCLR0) in TCR select the method of clearing.

When TCNT overflows from H'FF to H'00, the overflow flag (OVF) in the timer control/status register (TCSR) is set to 1.

Each TCNT is initialized to H'00 by a reset and in standby mode.

10.2.2 Time Constant Registers A (TCORA)





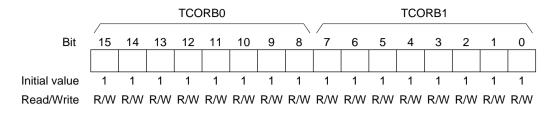
TCORA0 to TCORA3 are 8-bit readable/writable registers. The TCORA0 and TCORA1 pair, and the TCORA2 and TCORA3 pair, can each be accessed as a 16-bit register by word access.

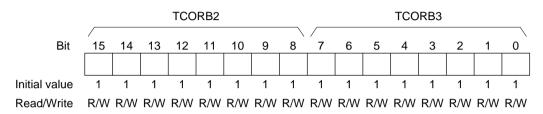
The TCORA value is constantly compared with the TCNT value. When a match is detected, the corresponding compare match flag A (CMFA) is set to 1 in TCSR.

The timer output can be freely controlled by these compare match signals and the settings of output select bits 1 and 0 (OS1, OS0) in TCSR.

Each TCORA register is initialized to H'FF by a reset and in standby mode.

10.2.3 Time Constant Registers B (TCORB)





TCORB0 to TCORB3 are 8-bit readable/writable registers. The TCORB0 and TCORB1 pair, and the TCORB2 and TCORB3 pair, can each be accessed as a 16-bit register by word access.

The TCORB value is constantly compared with the TCNT value. When a match is detected, the corresponding compare match flag B (CMFB) is set to 1 in TCSR.

The timer output can be freely controlled by these compare match signals and the settings of output/input capture edge select bits 3 and 2 (OIS3, OIS2) in TCSR.

When TCORB is used for input capture, it stores the TCNT value on detection of an external input capture signal. At this time, the CMFB flag is set to 1 in the corresponding TCSR register. The detected edge of the input capture signal is set in TCSR.

Each TCORB register is initialized to H'FF by a reset and in standby mode.



10.2.4 Timer Control Register (TCR)

Bit	7	6	5	4	3	2	1	0
	CMIEB	CMIEA	OVIE	CCLR1	CCLR0	CKS2	CKS1	CKS0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

TCR is an 8-bit readable/writable register that selects the input clock source and the time at which TCNT is cleared, and enables interrupts.

TCR is initialized to H'00 by a reset and in standby mode.

For the timing, see section 10.4, Operation.

Bit 7—Compare Match Interrupt Enable B (CMIEB): Enables or disables the CMIB interrupt request when the CMFB flag is set to 1 in TCSR.

Bit 7 CMIEB	Description	
0	CMIB interrupt requested by CMFB is disabled	(Initial value)
1	CMIB interrupt requested by CMFB is enabled	

Bit 6—Compare Match Interrupt Enable A (CMIEA): Enables or disables the CMIA interrupt request when the CMFA flag is set to 1 in TCSR.

Bit 6 CMIEA	Description	
0	CMIA interrupt requested by CMFA is disabled	(Initial value)
1	CMIA interrupt requested by CMFA is enabled	

Bit 5—Timer Overflow Interrupt Enable (OVIE): Enables or disables the OVI interrupt request when the OVF flag is set to 1 in TCSR.

Bit 5 OVIE	Description				
0	OVI interrupt requested by OVF is disabled	(Initial value)			
1	OVI interrupt requested by OVF is enabled				

Bits 4 and 3—Counter Clear 1 and 0 (CCLR1 and CCLR0): These bits select how TCNT is cleared: by compare match A or B, or input capture B..

Bit 4 CCLR1	Bit 3 CCLR0	Description	
0	0	Clearing is disabled	(Initial value)
	1	Cleared by compare match A	
1	0	Cleared by compare match B/ input capture B	
	1	Cleared by input capture B	

Bits 2 to 0—Clock Select 2 to 0 (CSK2 to CSK0): These bits select whether the clock input to TCNT is an internal or external clock.

Three internal clocks can be selected, all divided from the system clock (ϕ): $\phi/8$, $\phi/64$, and $\phi/8192$. The rising edge of the selected internal clock triggers the count.

When use of an external clock is selected, three types of count can be selected: at the rising edge, the falling edge, and both rising and falling edges.

Some functions differ between channels 0 and 2 and channels 1 and 3.

Bit 2 CKS2	Bit 1 CKS1	Bit 0 CKS0	Description		
0	0	0	0	Clock input disabled	(Initial value)
		1	Internal clock, counted on rising edge of $\phi/8$		
	1	0	Internal clock, counted on rising edge of \$\phi/64\$		
		1	Internal clock, counted on rising edge of \$\phi/8192\$		
1	0	0	Channel 0: Count on TCNT1 overflow signal*1		
			Channel 1: Count on TCNT0 compare match A*1		
			Channel 2: Count on TCNT3 overflow signal*2		
			Channel 3: Count on TCNT2 compare match A*2		
		1	External clock, counted on falling edge		
	1	0	External clock, counted on rising edge		
		1	External clock, counted on both rising and falling ed	dges	

Notes: 1. If the clock input of channel 0 is the TCNT1 overflow signal and that of channel 1 is the TCNT0 compare match signal, no incrementing clock is generated. Do not use this setting.

If the clock input of channel 2 is the TCNT3 overflow signal and that of channel 3 is the TCNT2 compare match signal, no incrementing clock is generated. Do not use this setting.

10.2.5 Timer Control/Status Registers (TCSR)

TCSR0								
Bit	7	6	5	4	3	2	1	0
	CMFB	CMFA	OVF	ADTE	OIS3	OIS2	OS1	OS0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/(W)*	R/(W)*	R/(W)*	R/W	R/W	R/W	R/W	R/W
TCSR2								
Bit	7	6	5	4	3	2	1	0
	CMFB	CMFA	OVF	_	OIS3	OIS2	OS1	OS0
Initial value	0	0	0	1	0	0	0	0
Read/Write	R/(W)*	R/(W)*	R/(W)*	_	R/W	R/W	R/W	R/W
TCSR1, TCSR3								
Bit	7	6	5	4	3	2	1	0
	CMFB	CMFA	OVF	ICE	OIS3	OIS2	OS1	OS0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/(W)*	R/(W)*	R/(W)*	R/W	R/W	R/W	R/W	R/W

Note: * Only 0 can be written to bits 7 to 5, to clear these flags.

The timer control/status registers (TCSR0 to TCSR3) are 8-bit registers that indicate compare match/input capture and overflow statuses, and control compare match output/input capture edge selection.

Each TCSR is initialized to H'00 by a reset and in standby mode.

Bit 7—Compare Match/Input Capture Flag B (CMFB): Status flag that indicates the occurrence of a TCORB compare match or input capture.

Bit 7 CMFB	Description
0	Clearing condition (Initial value) Read CMFB when CMFB = 1, then write 0 in CMFB
1	Setting conditions TCNT = TCORB The TCNT value is transferred to TCORB by an input capture signal when TCORB functions as an input capture register

Bit 6—Compare Match Flag A (CMFA): Status flag that indicates the occurrence of a TCORA compare match.

Bit 6 CMFA	Description	
0	Clearing condition Read CMFA when CMFA = 1, then write 0 in CMFA	(Initial value)
1	Setting condition TCNT = TCORA	

Bit 5—Timer Overflow Flag (OVF): Status flag that indicates that the TCNT has overflowed (from H'FF to H'00).

Bit 5 OVF Description		
0	Clearing condition Read OVF when OVF = 1, then write 0 in OVF	(Initial value)
1	Setting condition TCNT overflows from H'FF to H'00	

Bit 4—A/D Trigger Enable (ADTE) (TCSR0): In combination with TRGE in the A/D control register (ADCR), enables or disables A/D converter start requests by compare match A or an external trigger. TCSR2 is a reserved bit, but can be read and written.

TRGE*	Bit 4 ADTE	Description
0	0	A/D converter start requests by compare match A or an external trigger are disabled (Initial value
	1	A/D converter start requests by compare match A or an external trigger are disabled
1	0	A/D converter start requests by an external trigger are enabled, and A/D converter start requests by compare match A are disabled
	1	A/D converter start requests by compare match A are enabled, and A/D converter start requests by an external trigger are disabled

Note: *TRGE is bit 7 of the A/D control register (ADCR).

Bit 4—Input Capture Enable (ICE) (TCSR1, TCSR3): Selects the function of TCORB.

Bit 4 ICE	Description	
0	TCORB is a compare match register	(Initial value)
1	TCORB is an input capture register	

Bits 3 and 2—Output/Input Capture Edge Select B3 and B2 (OIS3, OIS2): In combination with the ICE bit in TCSR1 (TCSR3), these bits select the compare match B output level or the input capture input detected edge.

The function of TCORB1 (TCORB3) depends on the setting of bit 4 of TCSR1 (TCSR3). TCORB0 and TCORB2 function as compare match registers regardless of the setting of bit 4 of TCSR1 (TCSR3).

ICE Bit in TCSR1	Bit 3	Bit 2	
(TCSR3)	OIS3	OIS2	Description
0	0	0	No change when compare match B occurs (Initial value)
		1	0 is output when compare match B occurs
	1	0	1 is output when compare match B occurs
		1	Output is inverted when compare match B occurs (toggle output)
1	0	0	TCORB input capture on rising edge
		1	TCORB input capture on falling edge
	1	0	TCORB input capture on both rising and falling edges
		1	-

- When the compare match register function is used, the timer output priority order is: toggle output > 1 output > 0 output.
- If compare match A and B occur simultaneously, the output changes in accordance with the higher-priority compare match.
- When bits OIS3, OIS2, OS1, and OS0 are all cleared to 0, timer output is disabled.

Bits 1 and 0—Output Select A1 and A0 (OS1, OS0): These bits select the compare match A output level.

Bit 1 OS1	Bit 0 OS0	Description	
0	0	No change when compare match A occurs	(Initial value)
	1	0 is output when compare match A occurs	
1	0	1 is output when compare match A occurs	
	1	Output is inverted when compare match A occurs (toggle output)	

• When the compare match register function is used, the timer output priority order is: toggle output > 1 output > 0 output.

- If compare match A and B occur simultaneously, the output changes in accordance with the higher-priority compare match.
- When bits OIS3, OIS2, OS1, and OS0 are all cleared to 0, timer output is disabled.



10.3 CPU Interface

10.3.1 8-Bit Registers

TCNT, TCORA, TCORB, TCR, and TCSR are 8-bit registers. These registers are connected to the CPU by an internal 16-bit data bus and can be read and written a word at a time or a byte at a time.

Figures 10.2 and 10.3 show the operation in word read and write accesses to TCNT.

Figures 10.4 to 10.7 show the operation in byte read and write accesses to TCNT0 and TCNT1.

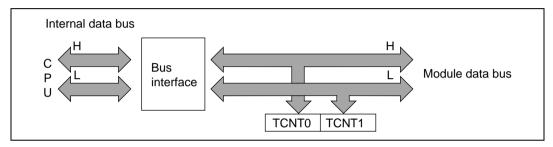


Figure 10.2 TCNT Access Operation (CPU Writes to TCNT, Word)

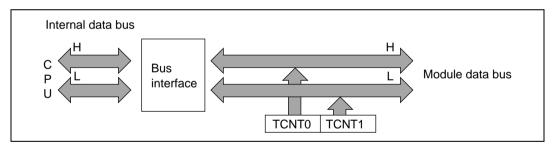


Figure 10.3 TCNT Access Operation (CPU Reads TCNT, Word)

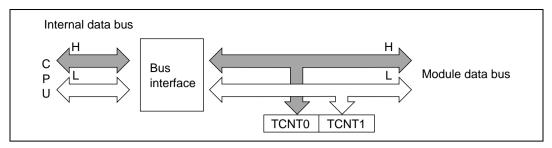


Figure 10.4 TCNT Access Operation (CPU Writes to TCNT, Upper Byte)

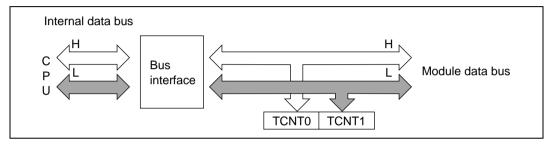


Figure 10.5 TCNT Access Operation (CPU Writes to TCNT, Lower Byte)

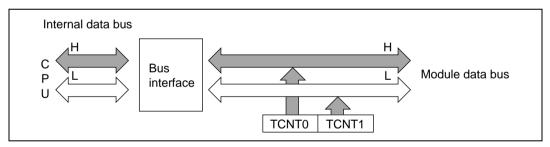


Figure 10.6 TCNT Access Operation (CPU Reads TCNT, Upper Byte)

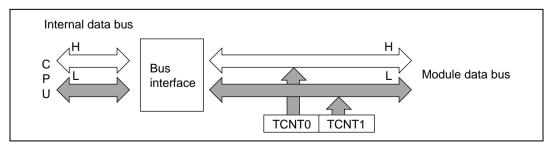


Figure 10.7 TCNT Access Operation (CPU Reads TCNT, Lower Byte)

10.4 Operation

10.4.1 TCNT Count Timing

TCNT is incremented by input clock pulses (either internal or external).

Internal Clock: Three different internal clock signals ($\phi/8$, $\phi/64$, or $\phi/8192$) divided from the system clock (ϕ) can be selected, by setting bits CKS2 to CKS0 in TCR. Figure 10.8 shows the count timing.

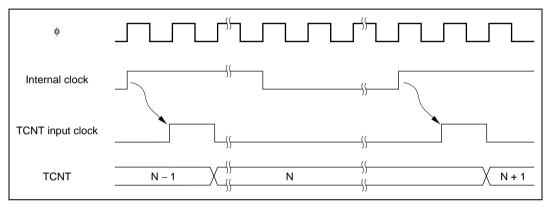


Figure 10.8 Count Timing for Internal Clock Input

Note: Even when the same internal clock is selected for both the 16- and 8-bit timers, they do not operate in the same manner because the count-up edge differs.

External Clock: Three incrementation methods can be selected by setting bits CKS2 to CKS0 in TCR: on the rising edge, the falling edge, and both rising and falling edges.

The pulse width of the external clock signal must be at least 1.5 serial clocks when a single edge is selected, and at least 2.5 system clocks when both edges are selected. Shorter pulses will not be counted correctly.

Figure 10.9 shows the timing for incrementation on both edges of the external clock signal.

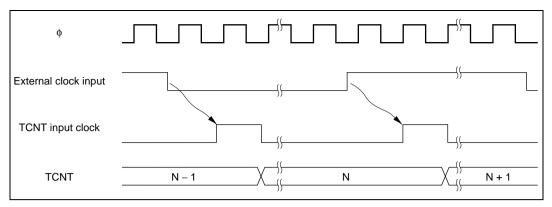


Figure 10.9 Count Timing for External Clock Input (when Detecting the Both Edges)

10.4.2 Compare Match Timing

Timer Output Timing: When compare match A or B occurs, the timer output is as specified by the OIS3, OIS2, OS1, and OS0 bits in TCSR (unchanged, 0 output, 1 output, or toggle output).

Figure 10.10 shows the timing when the output is set to toggle on compare match A.

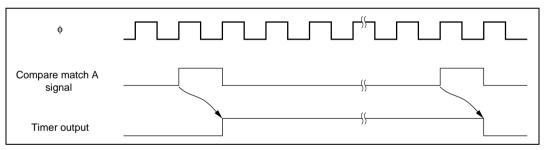


Figure 10.10 Timing of Timer Output

Clear by Compare Match: Depending on the setting of the CCLR1 and CCLR0 bits in TCR, TCNT can be cleared when compare match A or B occurs, Figure 10.11 shows the timing of this operation.

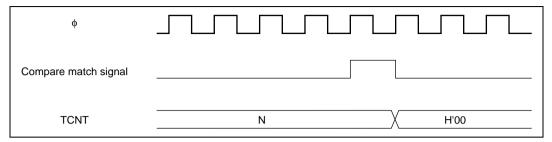


Figure 10.11 Timing of Clear by Compare Match

Clear by Input Capture: Depending on the setting of the CCLR1 and CCLR0 bits in TCR, TCNT can be cleared when input capture B occurs. Figure 10.12 shows the timing of this operation.

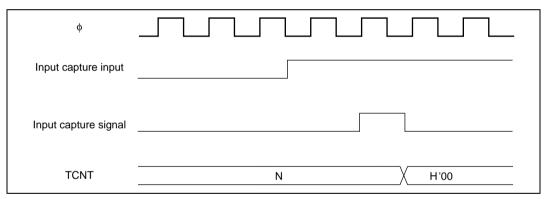


Figure 10.12 Timing of Clear by Input Capture

10.4.3 Input Capture Signal Timing

Input capture on the rising edge, falling edge, or both edges can be selected by settings in TCSR.

Figure 10.13 shows the timing when the rising edge is selected.

The pulse width of the input capture input signal must be at least 1.5 system clocks when a single edge is selected, and at least 2.5 system clocks when both edges are selected.

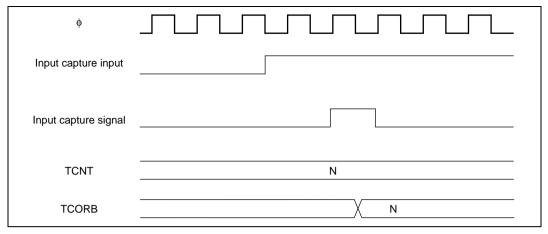


Figure 10.13 Timing of Input Capture Input Signal

10.4.4 Timing of Status Flag Setting

Timing of CMFA/CMFB Flag Setting when Compare Match Occurs: CMFA and CMFB in TCSR are set to 1 by the compare match signal output when the TCOR and TCNT values match. The compare match signal is generated in the last state of the match (when the matched TCNT count value is updated). Therefore, after the TCNT and TCOR values match, the compare match signal is not generated until an incrementing clock pulse is generated. Figure 10.14 shows the timing in this case.

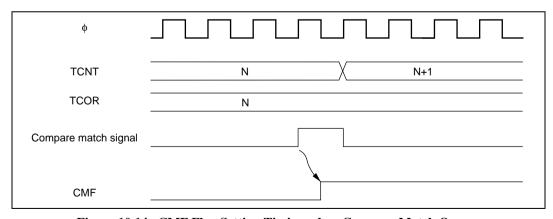
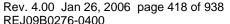


Figure 10.14 CMF Flag Setting Timing when Compare Match Occurs

Timing of CMFB Flag Setting when Input Capture Occurs: On generation of an input capture signal, the CMFB flag is set to 1 and at the same time the TCNT value is transferred to TCORB. Figure 10.15 shows the timing in this case.





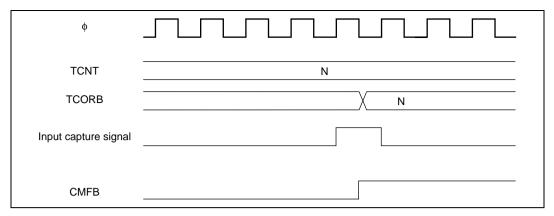


Figure 10.15 CMFB Flag Setting Timing when Input Capture Occurs

Timing of Overflow Flag (OVF) Setting: The OVF flag in TCSR is set to 1 by the overflow signal generated when TCNT overflows (from H'FF to H'00). Figure 10.16 shows the timing in this case.

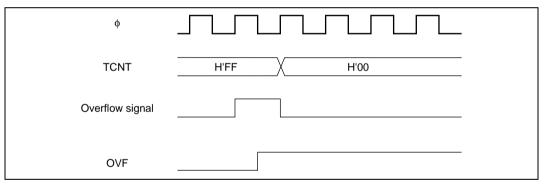


Figure 10.16 Timing of OVF Setting

10.4.5 Operation with Cascaded Connection

If bits CKS2 to CKS0 are set to B'100 in either TCR0 or TCR1, the 8-bit timers of channels 0 and 1 are cascaded. With this configuration, the two timers can be used as a single 16-bit timer (16-bit count mode), or channel 0 8-bit timer compare matches can be counted in channel 1 (compare match count mode). In this case, the timer operates as below. Similarly, if bits CKS2 to CKS0 are set to B'100 in either TCR2 or TCR3, the 8-bit timers of channels 0 and 1 are cascaded. With this configuration, the two timers can be used as a single 16-bit timer (16-bit count mode), or channel 2 8-bit timer compare matches can be counted in channel 3 (compare match count mode). Timer operation in these cases is described below.

16-Bit Count Mode

Channels 0 and 1:

When bits CKS2 to CKS0 are set to B'100 in TCR0, the timer functions as a single 16-bit timer with channel 0 occupying the upper 8 bits and channel 1 occupying the lower 8 bits.

- Setting when Compare Match Occurs
 - The CMF flag is set to 1 in TCR0 when a 16-bit compare match occurs.
 - The CMF flag is set to 1 in TCR1 when a lower 8-bit compare match occurs.
 - TMO₀ pin output control by bits OIS3, OIS2, OS1, and OS0 in TCSR0 is in accordance with the 16-bit compare match conditions.
 - TMIO₁ pin output control by bits OIS3, OIS2, OS1, and OS0 in TCSR1 is in accordance with the lower 8-bit compare match conditions.
- Setting when Input Capture Occurs
 - The CMFB flag is set to 1 in TCR0 and TCR1 when the ICE bit is 1 in TCSR1 and input capture occurs.
 - TMIO₁ pin input capture input signal edge detection is selected by bits OIS3 and OIS2 in TCSR0.
- Counter Clear Specification
 - If counter clear on compare match or input capture has been selected by the CCLR1 and CCLR0 bits in TCR0, the 16-bit counter (both TCNT0 and TCNT1) is cleared.
 - The settings of the CCLR1 and CCLR0 bits in TCR1 are ignored. The lower 8 bits cannot be cleared independently.
- OVF Flag Operation
 - The OVF flag is set to 1 in TCSR0 when the 16-bit counter (TCNT0 and TCNT1) overflows (from H'FFFF to H'0000).
 - The OVF flag is set to 1 in TCSR1 when the 8-bit counter (TCNT1) overflows (from H'FF to H'00).
- Channels 2 and 3:

When bits CKS2 to CKS0 are set to B'100 in TCR2, the timer functions as a single 16-bit timer with channel 2 occupying the upper 8 bits and channel 3 occupying the lower 8 bits.

- Setting when Compare Match Occurs
 - The CMF flag is set to 1 in TCR2 when a 16-bit compare match occurs.
 - The CMF flag is set to 1 in TCR3 when a lower 8-bit compare match occurs.
 - TMO₂ pin output control by bits OIS3, OIS2, OS1, and OS0 in TCSR2 is in accordance with the 16-bit compare match conditions.
 - TMIO₃ pin output control by bits OIS3, OIS2, OS1, and OS0 in TCSR3 is in accordance with the lower 8-bit compare match conditions.



- Setting when Input Capture Occurs
 - The CMFB flag is set to 1 in TCR2 and TCR3 when the ICE bit is 1 in TCSR3 and input capture occurs.
 - TMIO₃ pin input capture input signal edge detection is selected by bits OIS3 and OIS2 in TCSR2.
- Counter Clear Specification
 - If counter clear on compare match has been selected by the CCLR1 and CCLR0 bits in TCR2, the 16-bit counter (both TCNT2 and TCNT3) is cleared.
 - The settings of the CCLR1 and CCLR0 bits in TCR3 are ignored. The lower 8 bits cannot be cleared independently.
- OVF Flag Operation
 - The OVF flag is set to 1 in TCSR2 when the 16-bit counter (TCNT2 and TCNT3) overflows (from H'FFFF to H'0000).
 - The OVF flag is set to 1 in TCSR3 when the 16-bit counter (TCNT3) overflows (from H'FF to H'00).

Compare Match Count Mode

Channels 0 and 1:

When bits CKS2 to CKS0 are set to B'100 in TCR1, TCNT1 counts channel 0 compare match A events.

Channels 0 and 1 are controlled independently. CMF flag setting, interrupt generation, TMO pin output, counter clearing, and so on, is in accordance with the settings for each channel.

Channels 2 and 3:

When bits CKS2 to CKS0 are set to B'100 in TCR3, TCNT3 counts channel 2 compare match A events.

Channels 2 and 3 are controlled independently. CMF flag setting, interrupt generation, TMO pin output, counter clearing, and so on, is in accordance with the settings for each channel.

Caution

Do not set 16-bit count mode and compare match count mode simultaneously within the same group, as the TCNT input clock will not be generated and the counters will not operate.

10.4.6 Input Capture Setting

The TCNT value can be transferred to TCORB on detection of an input edge on the input capture/output compare pin (TMIO₁ or TMIO₃). Rising edge, falling edge, or both edge detection can be selected. In 16-bit count mode, 16-bit input capture can be used.

Setting Input Capture Operation in 8-Bit Timer Mode (Normal Operation)

• Channel 1:

- Set TCORB1 as an 8-bit input capture register with the ICE bit in TCSR1.
- Select rising edge, falling edge, or both edges as the input edge(s) for the input capture signal (TMIO₁) with bits OIS3 and OIS2 in TCSR1.
- Select the input clock with bits CKS2 to CKS0 in TCR1, and start the TCNT count.

• Channel 3:

- Set TCORB3 as an 8-bit input capture register with the ICE bit in TCSR3.
- Select rising edge, falling edge, or both edges as the input edge(s) for the input capture signal (TMIO₃) with bits OIS3 and OIS2 in TCSR3.
- Select the input clock with bits CKS2 to CKS0 in TCR3, and start the TCNT count.

Setting Input Capture Operation in 16-Bit Count Mode

• Channels 0 and 1:

- In 16-bit count mode, TCORB0 and TCORB1 function as a 16-bit input capture register when the ICE bit is set to 1 in TCSR1.
- Select rising edge, falling edge, or both edges as the input edge(s) for the input capture signal (TMIO₁) with bits OIS3 and OIS2 in TCSR0. (In 16-bit count mode, the settings of bits OIS3 and OIS2 in TCSR1 are ignored.)
- Select the input clock with bits CKS2 to CKS0 in TCR1, and start the TCNT count.

Channels 2 and 3:

- In 16-bit count mode, TCORB2 and TCORB3 function as a 16-bit input capture register when the ICE bit is set to 1 in TCSR3.
- Select rising edge, falling edge, or both edges as the input edge(s) for the input capture signal (TMIO₃) with bits OIS3 and OIS2 in TCSR2. (In 16-bit count mode, the settings of bits OIS3 and OIS2 in TCSR3 are ignored.)
- Select the input clock with bits CKS2 to CKS0 in TCR3, and start the TCNT count.



10.5 Interrupts

10.5.1 Interrupt Sources

The 8-bit timer unit can generate three types of interrupt: compare match A and B (CMIA and CMIB) and overflow (OVI). Table 10.3 shows the interrupt sources and their priority order. Each interrupt source is enabled or disabled by the corresponding interrupt enable bit in TCR. A separate interrupt request signal is sent to the interrupt controller by each interrupt source.

Table 10.3 Types of 8-Bit Timer Interrupt Sources and Priority Order

Interrupt Source	Description	Priority
CMIA	Interrupt by CMFA	High
CMIB	Interrupt by CMFB	^
TOVI	Interrupt by OVF	Low

For compare match interrupts CMIA1/CMIB1 and CMIA3/CMIB3 and the overflow interrupts (TOVI0/TOVI1 and TOVI2/TOVI3), one vector is shared by two interrupts.

Table 10.4 lists the interrupt sources.

Table 10.4 8-Bit Timer Interrupt Sources

Channel	Interrupt Source	Description
0	CMIA0	TCORA0 compare match
	CMIB0	TCORB0 compare match/input capture
1	CMIA1/CMIB1	TCORA1 compare match, or TCORB1 compare match/input capture
0, 1	TOVI0/TOVI1	Counter 0 or counter 1 overflow
2	CMIA2	TCORA2 compare match
	CMIB2	TCORB2 compare match/input capture
3	CMIA3/CMIB3	TCORA3 compare match, or TCORB3 compare match/input capture
2,3	TOVI2/TOVI3	Counter 2 or counter 3 overflow

10.5.2 A/D Converter Activation

The A/D converter can only be activated by channel 0 compare match A.

If the ADTE bit setting is 1 when the CMFA flag in TCSR0 is set to 1 by generation of channel 0 compare match A, an A/D conversion start request will be issued to the A/D converter. If the TRGE bit in ADCR is 1 at this time, the A/D converter will be started. If the ADTE bit in TCSR0 is 1, the A/D converter external trigger input (ADTRG) is disabled.

10.6 8-Bit Timer Application Example

Figure 10.17 shows how the 8-bit timer module can be used to output pulses with any desired duty cycle. The settings for this example are as follows:

- Clear the CCLR1 bit to 0 and set the CCLR0 bit to 1 in TCR so that TCNT is cleared by a TCORA compare match.
- Set bits OIS3, OIS2, OS1, and OS0 to B'0110 in TCSR so that 1 is output on a TCORA compare match and 0 is output on a TCORB compare match.

The above settings enable a waveform with the cycle determined by TCORA and the pulse width detected by TCORB to be output without software intervention.

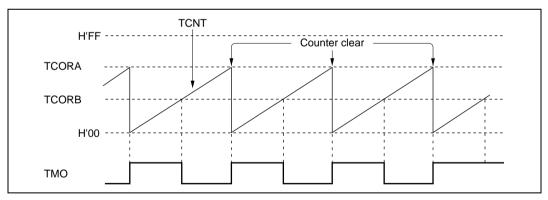


Figure 10.17 Example of Pulse Output

10.7 Usage Notes

Note that the following kinds of contention can occur in 8-bit timer operation.

10.7.1 Contention between TCNT Write and Clear

If a timer counter clear signal occurs in the T₃ state of a TCNT write cycle, clearing of the counter takes priority and the write is not performed. Figure 10.18 shows the timing in this case.

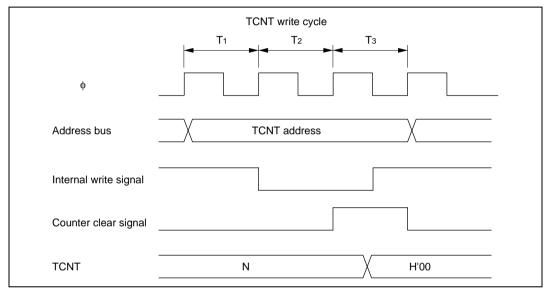


Figure 10.18 Contention between TCNT Write and Clear

10.7.2 Contention between TCNT Write and Increment

If an increment pulse occurs in the T_3 state of a TCNT write cycle, writing takes priority and TCNT is not incremented. Figure 10.19 shows the timing in this case.

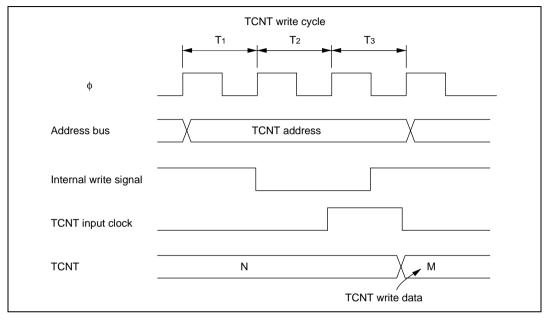


Figure 10.19 Contention between TCNT Write and Increment

10.7.3 Contention between TCOR Write and Compare Match

If a compare match occurs in the T_3 state of a TCOR write cycle, writing takes priority and the compare match signal is inhibited. Figure 10.20 shows the timing in this case.

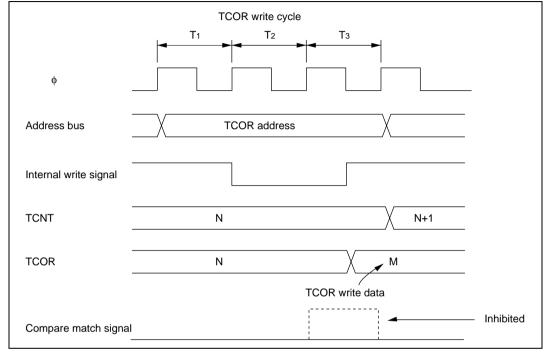


Figure 10.20 Contention between TCOR Write and Compare Match

10.7.4 Contention between TCOR Read and Input Capture

If an input capture signal occurs in the T₃ state of a TCOR read cycle, the value before input capture is read. Figure 10.21 shows the timing in this case.

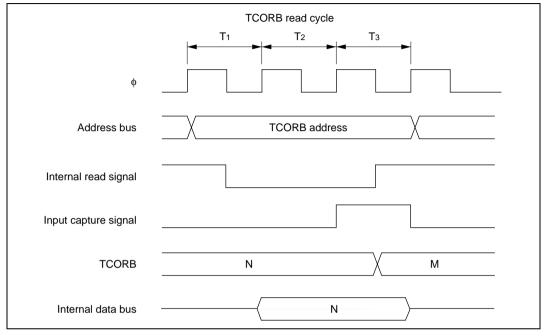


Figure 10.21 Contention between TCOR Read and Input Capture



10.7.5 Contention between Counter Clearing by Input Capture and Counter Increment

If an input capture signal and counter increment signal occur simultaneously, counter clearing by the input capture signal takes priority and the counter is not incremented. The value before the counter is cleared is transferred to TCORB. Figure 10.22 shows the timing in this case.

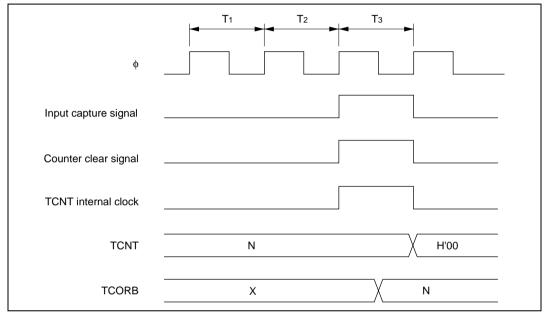


Figure 10.22 Contention between Counter Clearing by Input Capture and Counter Increment

10.7.6 Contention between TCOR Write and Input Capture

If an input capture signal occurs in the T_3 state of a TCOR write cycle, input capture takes priority and the write to TCOR is not performed. Figure 10.23 shows the timing in this case.

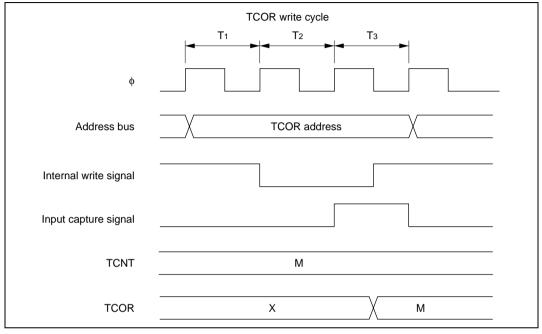


Figure 10.23 Contention between TCOR Write and Input Capture

10.7.7 Contention between TCNT Byte Write and Increment in 16-Bit Count Mode (Cascaded Connection)

If an increment pulse occurs in the T_2 or T_3 state of a TCNT byte write cycle in 16-bit count mode, writing takes priority and TCNT is not incremented. The TCNT byte that was not written retains its previous value. Figure 10.24 shows the timing when an increment pulse occurs in the T_2 state of a byte write to TCNTH.

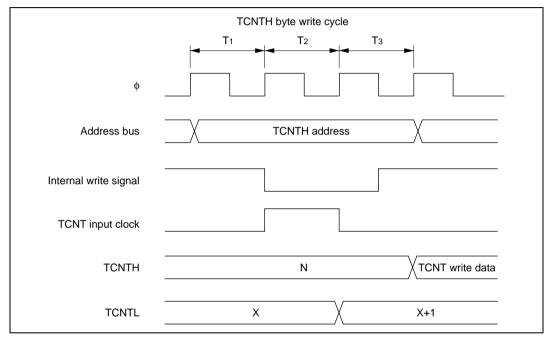


Figure 10.24 Contention between TCNT Byte Write and Increment in 16-Bit Count Mode

10.7.8 Contention between Compare Matches A and B

If compare matches A and B occur at the same time, the 8-bit timer operates according to the relative priority of the output states set for compare match A and compare match B, as shown in Table 10.5

Table 10.5 Timer Output Priority Order

Output Setting	Priority
Toggle output	High
1 output	↑
0 output	
No change	Low

10.7.9 TCNT Operation at Internal Clock Source Switchover

Switching internal clock sources may cause TCNT to increment, depending on the switchover timing. Table 10.6 shows the relation between the time of the switchover (by writing to bits CKS1 and CKS0) and the operation of TCNT.

The TCNT input clock is generated from the internal clock source by detecting the rising edge of the internal clock. If a switchover is made from a Low clock source to a High clock source, as in case No. 3 in Table 10.6, the switchover will be regarded as a falling edge, a TCNT clock pulse will be generated, and TCNT will be incremented.

TCNT may also be incremented when switching between internal and external clocks.

Table 10.6 Internal Clock Switchover and TCNT Operation

No.	CKS1 and CKS0 Write Timing	TCNT Operation
1	High → high switchover*1	Old clock source
		New clock source
		TCNT clock
		TCNT N N+1
		CKS bits rewritten
2	High → low switchover*2	Old clock source
		New clock source
		TCNT clock
		TCNT N N+1 N+2
		CKS bits rewritten
3	Low → high switchover*3	Old clock source
		New clock source
		TCNT clock
		TCNT N N+1 N+2
		CKS bits rewritten

	TCNT Operation
$Low \to low \; switchover$	Old clock source
	New clock source
	TCNT clock
	TCNT N N+1 N+2 CKS bits rewritten
	Low → low switchover

- Notes: 1. Including switchovers from a high clock source to the halted state, and from the halted state to a high clock source.
 - 2. Including switchover from the halted state to a low clock source.
 - 3. Including switchover from a low clock source to the halted state.
 - 4. The switchover is regarded as a rising edge, causing TCNT to increment.

Programmable Timing Pattern Controller (TPC) Section 11

11.1 Overview

The H8/3067 Group has a built-in programmable timing pattern controller (TPC) that provides pulse outputs by using the 16-bit timer as a time base. The TPC pulse outputs are divided into 4bit groups (group 3 to group 0) that can operate simultaneously and independently.

11.1.1 **Features**

TPC features are listed below.

- 16-bit output data Maximum 16-bit data can be output. TPC output can be enabled on a bit-by-bit basis.
- Four output groups Output trigger signals can be selected in 4-bit groups to provide up to four different 4-bit outputs.
- Selectable output trigger signals Output trigger signals can be selected for each group from the compare match signals of three 16-bit timer channels.
- Non-overlap mode A non-overlap margin can be provided between pulse outputs. Can operate together with the DMA controller (DMAC)
- The compare-match signals selected as trigger signals can activate the DMAC for sequential output of data without CPU intervention.

11.1.2 Block Diagram

Figure 11.1 shows a block diagram of the TPC.

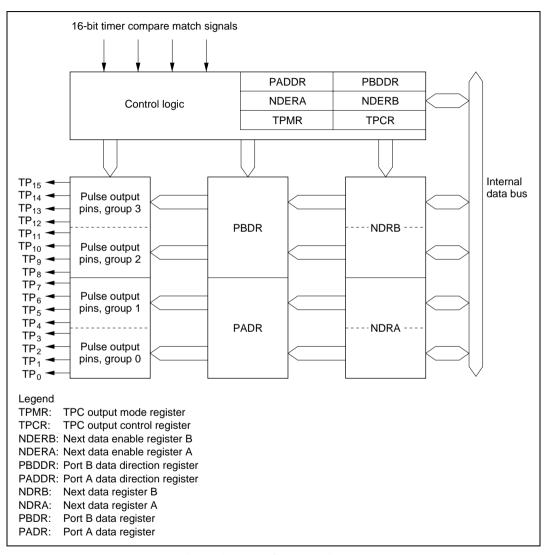


Figure 11.1 TPC Block Diagram

11.1.3 TPC Pins

Table 11.1 summarizes the TPC output pins.

Table 11.1 TPC Pins

Name	Symbol	I/O	Function
TPC output 0	TP _o	Output	Group 0 pulse output
TPC output 1	TP ₁	Output	
TPC output 2	TP ₂	Output	
TPC output 3	TP ₃	Output	
TPC output 4	TP ₄	Output	Group 1 pulse output
TPC output 5	TP ₅	Output	
TPC output 6	TP ₆	Output	
TPC output 7	TP ₇	Output	
TPC output 8	TP ₈	Output	Group 2 pulse output
TPC output 9	TP ₉	Output	
TPC output 10	TP ₁₀	Output	
TPC output 11	TP ₁₁	Output	
TPC output 12	TP ₁₂	Output	Group 3 pulse output
TPC output 13	TP ₁₃	Output	
TPC output 14	TP ₁₄	Output	
TPC output 15	TP ₁₅	Output	
·		·	· · · · · · · · · · · · · · · · · · ·

11.1.4 Registers

Table 11.2 summarizes the TPC registers.

Table 11.2 TPC Registers

Address*1	Name	Abbreviation	R/W	Function
H'EE009	Port A data direction register	PADDR	W	H'00
H'FFFD9	Port A data register	PADR	R/(W)*2	H'00
H'EE00A	Port B data direction register	PBDDR	W	H'00
H'FFFDA	Port B data register	PBDR	R/(W)*2	H'00
H'FFFA0	TPC output mode register	TPMR	R/W	H'F0
H'FFFA1	TPC output control register	TPCR	R/W	H'FF
H'FFFA2	Next data enable register B	NDERB	R/W	H'00
H'FFFA3	Next data enable register A	NDERA	R/W	H'00
H'FFFA5/ H'FFFA7*3	Next data register A	NDRA	R/W	H'00
H'FFFA4/ H'FFFA6*3	Next data register B	NDRB	R/W	H'00

Notes: 1. Lower 20 bits of the address in advanced mode.

- 2. Bits used for TPC output cannot be written.
- 3. The NDRA address is H'FFFA5 when the same output trigger is selected for TPC output groups 0 and 1 by settings in TPCR. When the output triggers are different, the NDRA address is H'FFFA7 for group 0 and H'FFFA5 for group 1. Similarly, the address of NDRB is H'FFFA4 when the same output trigger is selected for TPC output groups 2 and 3 by settings in TPCR. When the output triggers are different, the NDRB address is H'FFFA6 for group 2 and H'FFFA4 for group 3.

11.2 Register Descriptions

11.2.1 Port A Data Direction Register (PADDR)

PADDR is an 8-bit write-only register that selects input or output for each pin in port A.

Bit	7	6	5	4	3	2	1	0
	PA ₇ DDR	PA ₆ DDR	PA ₅ DDR	PA ₄ DDR	PA ₃ DDR	PA ₂ DDR	PA ₁ DDR	PA ₀ DDR
Initial value	0	0	0	0	0	0	0	0
Read/Write	W	W	W	W	W	W	W	W

Port A data direction 7 to 0

These bits select input or output for port A pins

Port A is multiplexed with pins TP_7 to TP_0 . Bits corresponding to pins used for TPC output must be set to 1. For further information about PADDR, see section 8.11, Port A.

11.2.2 Port A Data Register (PADR)

PADR is an 8-bit readable/writable register that stores TPC output data for groups 0 and 1, when these TPC output groups are used.

Bit	7	6	5	4	3	2	1	0
	PA ₇	PA ₆	PA ₅	PA ₄	PA ₃	PA ₂	PA ₁	PA ₀
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/(W)*							

Port A data 7 to 0

These bits store output data for TPC output groups 0 and 1

Note: * Bits selected for TPC output by NDERA settings become read-only bits.

For further information about PADR, see section 8.11, Port A.

11.2.3 Port B Data Direction Register (PBDDR)

PBDDR is an 8-bit write-only register that selects input or output for each pin in port B.

Bit	7	6	5	4	3	2	1	0
	PB ₇ DDR	PB ₆ DDR	PB ₅ DDR	PB ₄ DDR	PB ₃ DDR	PB ₂ DDR	PB₁DDR	PB ₀ DDR
Initial value	0	0	0	0	0	0	0	0
Read/Write	W	W	W	W	W	W	W	W
					I			

Port B direction 7 to 0
These bits select input or output for port B pins

Port B is multiplexed with pins TP₁₅ to TP₈. Bits corresponding to pins used for TPC output must be set to 1. For further information about PBDDR, see section 8.12, Port B.

11.2.4 Port B Data Register (PBDR)

PBDR is an 8-bit readable/writable register that stores TPC output data for groups 2 and 3, when these TPC output groups are used.

Bit	7	6	5	4	3	2	1	0
	PB ₇	PB_6	PB ₅	PB_4	PB_3	PB ₂	PB ₁	PB ₀
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/(W)*	R/(W)*	R/(W)*	R/(W)*	R/(W)*	R/(W)*	R/(W)*	R/(W)*

Port B data 7 to 0
These bits store output data for TPC output groups 2 and 3

Note: * Bits selected for TPC output by NDERB settings become read-only bits.

For further information about PBDR, see section 8.12, Port B.

11.2.5 Next Data Register A (NDRA)

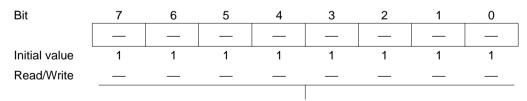
NDRA is an 8-bit readable/writable register that stores the next output data for TPC output groups 1 and 0 (pins TP_7 to TP_0). During TPC output, when an 16-bit timer compare match event specified in TPCR occurs, NDRA contents are transferred to the corresponding bits in PADR. The address of NDRA differs depending on whether TPC output groups 0 and 1 have the same output trigger or different output triggers.

NDRA is initialized to H'00 by a reset and in hardware standby mode. It is not initialized in software standby mode.

Same Trigger for TPC Output Groups 0 and 1: If TPC output groups 0 and 1 are triggered by the same compare match event, the NDRA address is H'FFFA5. The upper 4 bits belong to group 1 and the lower 4 bits to group 0. Address H'FFFA7 consists entirely of reserved bits that cannot be modified and always read 1.

Address H'FFFA5

Bit	7	6	5	4	3	2	1	0
	NDR7	NDR6	NDR5	NDR4	NDR3	NDR2	NDR1	NDR0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
	Th		to 4 ore the ne output gro		Th	xt data 3 ese bits st ta for TPC	ore the ne	

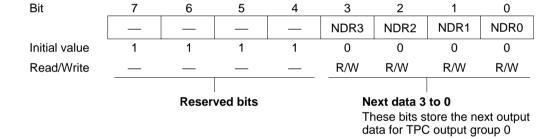


Reserved bits

Different Triggers for TPC Output Groups 0 and 1: If TPC output groups 0 and 1 are triggered by different compare match events, the address of the upper 4 bits of NDRA (group 1) is H'FFFA5 and the address of the lower 4 bits (group 0) is H'FFFA7. Bits 3 to 0 of address H'FFFA5 and bits 7 to 4 of address H'FFFA7 are reserved bits that cannot be modified and always read 1.

Address H'FFFA5

Bit	7	6	5	4	3	2	1	0
	NDR7	NDR6	NDR5	NDR4	_	_	_	_
Initial value	0	0	0	0	1	1	1	1
Read/Write	R/W	R/W	R/W	R/W				
	Th	xt data 7 tese bits state for TPC	ore the ne			Reser	ved bits	



11.2.6 Next Data Register B (NDRB)

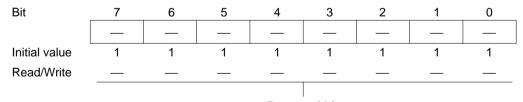
NDRB is an 8-bit readable/writable register that stores the next output data for TPC output groups 3 and 2 (pins TP₁₅ to TP₈). During TPC output, when an 16-bit timer compare match event specified in TPCR occurs, NDRB contents are transferred to the corresponding bits in PBDR. The address of NDRB differs depending on whether TPC output groups 2 and 3 have the same output trigger or different output triggers.

NDRB is initialized to H'00 by a reset and in hardware standby mode. It is not initialized in software standby mode.

Same Trigger for TPC Output Groups 2 and 3: If TPC output groups 2 and 3 are triggered by the same compare match event, the NDRB address is H'FFFA4. The upper 4 bits belong to group 3 and the lower 4 bits to group 2. Address H'FFFA6 consists entirely of reserved bits that cannot be modified and always read 1.

Address H'FFFA4

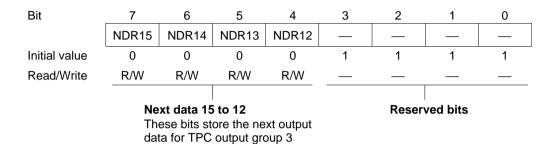
Bit	7	6	5	4	3	2	1	0
	NDR15	NDR14	NDR13	NDR12	NDR11	NDR10	NDR9	NDR8
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
	Th	xt data 15 ese bits st ta for TPC	ore the ne		Th	xt data 11 ese bits state to the state to th	ore the ne	

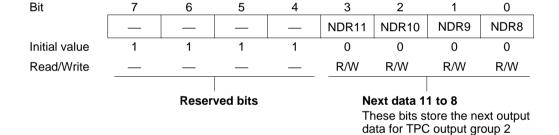


Reserved bits

Different Triggers for TPC Output Groups 2 and 3: If TPC output groups 2 and 3 are triggered by different compare match events, the address of the upper 4 bits of NDRB (group 3) is H'FFFA4 and the address of the lower 4 bits (group 2) is H'FFFA6. Bits 3 to 0 of address H'FFFA4 and bits 7 to 4 of address H'FFFA6 are reserved bits that cannot be modified and always read 1.

Address H'FFFA4





11.2.7 Next Data Enable Register A (NDERA)

NDERA is an 8-bit readable/writable register that enables or disables TPC output groups 1 and 0 (TP₂ to TP₀) on a bit-by-bit basis.

Bit	7	6	5	4	3	2	1	0
	NDER7	NDER6	NDER5	NDER4	NDER3	NDER2	NDER1	NDER0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W							
					l			

Next data enable 7 to 0
These bits enable or disable TPC output groups 1 and 0

If a bit is enabled for TPC output by NDERA, then when the 16-bit timer compare match event selected in the TPC output control register (TPCR) occurs, the NDRA value is automatically transferred to the corresponding PADR bit, updating the output value. If TPC output is disabled, the bit value is not transferred from NDRA to PADR and the output value does not change.

NDERA is initialized to H'00 by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bits 7 to 0—Next Data Enable 7 to 0 (NDER7 to NDER0): These bits enable or disable TPC output groups 1 and 0 (TP₂ to TP₆) on a bit-by-bit basis.

Bits 7 to 0 NDER7 to NDER0	Description	
0	TPC outputs TP ₇ to TP ₀ are disabled (NDR7 to NDR0 are not transferred to PA ₇ to PA ₀)	(Initial value)
1	TPC outputs TP ₇ to TP ₀ are enabled (NDR7 to NDR0 are transferred to PA ₇ to PA ₀)	

11.2.8 Next Data Enable Register B (NDERB)

NDERB is an 8-bit readable/writable register that enables or disables TPC output groups 3 and 2 (TP_{1s} to TP_{s}) on a bit-by-bit basis.

Bit	7	6	5	4	3	2	1	0
	NDER15	NDER14	NDER13	NDER12	NDER11	NDER10	NDER9	NDER8
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Next data enable 15 to 8 These bits enable or disable TPC output groups 3 and 2

If a bit is enabled for TPC output by NDERB, then when the 16-bit timer compare match event selected in the TPC output control register (TPCR) occurs, the NDRB value is automatically transferred to the corresponding PBDR bit, updating the output value. If TPC output is disabled, the bit value is not transferred from NDRB to PBDR and the output value does not change.

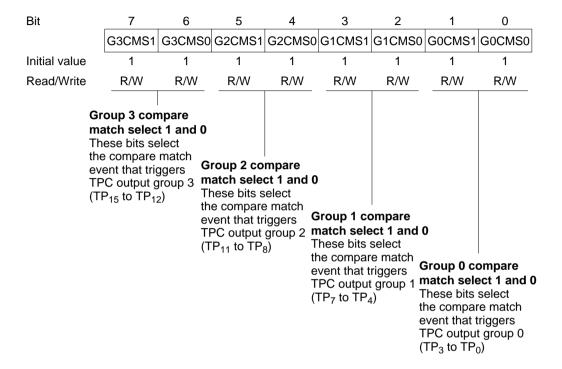
NDERB is initialized to H'00 by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bits 7 to 0—Next Data Enable 15 to 8 (NDER15 to NDER8): These bits enable or disable TPC output groups 3 and 2 (TP₁₅ to TP₈) on a bit-by-bit basis.

Bits 7 to 0 NDER15 to NDER8	Description	
0	TPC outputs TP_{15} to TP_{8} are disabled (NDR15 to NDR8 are not transferred to PB_{7} to PB_{0})	(Initial value)
1	TPC outputs TP ₁₅ to TP ₈ are enabled (NDR15 to NDR8 are transferred to PB ₇ to PB ₀)	

11.2.9 TPC Output Control Register (TPCR)

TPCR is an 8-bit readable/writable register that selects output trigger signals for TPC outputs on a group-by-group basis.



TPCR is initialized to H'FF by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bits 7 and 6—Group 3 Compare Match Select 1 and 0 (G3CMS1, G3CMS0): These bits select the compare match event that triggers TPC output group 3 (TP_{15} to TP_{12}).

Bit 7 G3CMS1	Bit 6 G3CMS0	Description
0	0	TPC output group 3 (TP $_{15}$ to TP $_{12}$) is triggered by compare match in 16-bit timer channel 0
	1	TPC output group 3 (TP $_{15}$ to TP $_{12}$) is triggered by compare match in 16-bit timer channel 1
1	0	TPC output group 3 (TP $_{15}$ to TP $_{12}$) is triggered by compare match in 16-bit timer channel 2
	1	TPC output group 3 (TP ₁₅ to TP ₁₂) is triggered by compare match in 16-bit timer channel 2 (Initial value)

Bits 5 and 4—Group 2 Compare Match Select 1 and 0 (G2CMS1, G2CMS0): These bits select the compare match event that triggers TPC output group 2 (TP_{11} to TP_{8}).

Bit 5 G2CMS1	Bit 4 G2CMS0	Description	
0 TPC output group 2 (TP ₁₁ to TP ₈) is triggered by compare mate timer channel 0			
	1	TPC output group 2 (TP $_{11}$ to TP $_{8}$) is triggered by compare match in 16-bit timer channel 1	
1 0 TPC output group 2 (TP ₁₁ to TP ₈) is triggered by compare match timer channel 2			
	1	TPC output group 2 (TP ₁₁ to TP ₈) is triggered by compare match in 16-bit timer channel 2	

Bits 3 and 2—Group 1 Compare Match Select 1 and 0 (G1CMS1, G1CMS0): These bits select the compare match event that triggers TPC output group 1 (TP₂ to TP₄).

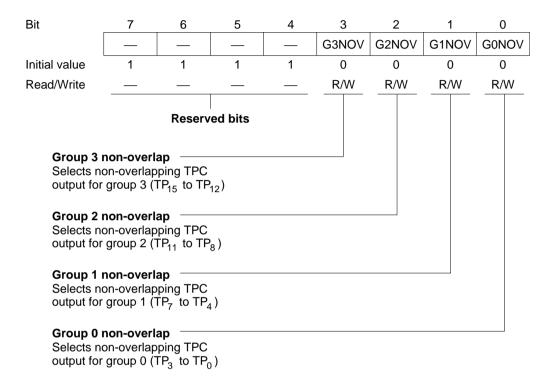
Bit 3	Bit 2				
G1CMS1	G1CMS0	Description			
0	0	TPC output group 1 (TP $_{\!\scriptscriptstyle 7}$ to TP $_{\!\scriptscriptstyle 4}$) is triggered by compare match in timer channel 0			
	1	TPC output group 1 (TP ₇ to TP ₄) is triggered by compare ma timer channel 1	tch in 16-bit		
1	0 TPC output group 1 (TP ₇ to TP ₄) is triggered by compare match in 1 timer channel 2				
	1	TPC output group 1 (TP ₇ to TP ₄) is triggered by compare match in 16-bit timer channel 2	(Initial value)		

Bits 1 and 0—Group 0 Compare Match Select 1 and 0 (G0CMS1, G0CMS0): These bits select the compare match event that triggers TPC output group 0 (TP₃ to TP₀).

Bit 1 G0CMS1	Bit 0 G0CMS0	Description
0	0	TPC output group 0 (TP $_{\!\scriptscriptstyle 3}$ to TP $_{\!\scriptscriptstyle 0}$) is triggered by compare match in 16-bit timer channel 0
	1	TPC output group 0 (TP $_{\rm 3}$ to TP $_{\rm 0}$) is triggered by compare match in 16-bit timer channel 1
1	0	TPC output group 0 (TP $_{\!_{3}}$ to TP $_{\!_{0}})$ is triggered by compare match in 16-bit timer channel 2
	1	TPC output group 0 (TP ₃ to TP ₀) is triggered by compare match in 16-bit timer channel 2

11.2.10 TPC Output Mode Register (TPMR)

TPMR is an 8-bit readable/writable register that selects normal or non-overlapping TPC output for each group.



The output trigger period of a non-overlapping TPC output waveform is set in general register B (GRB) in the 16-bit timer channel selected for output triggering. The non-overlap margin is set in general register A (GRA). The output values change at compare match A and B. For details see section 11.3.4, Non-Overlapping TPC Output.

TPMR is initialized to H'F0 by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bits 7 to 4—Reserved: These bits cannot be modified and are always read as 1.

Bit 3—Group 3 Non-Overlap (G3NOV): Selects normal or non-overlapping TPC output for group 3 (TP_{15} to TP_{12}).

Bit 3 G3NOV	Description	
0	Normal TPC output in group 3 (output values change at compare match A in the selected 16-bit timer channel)	(Initial value)
1	Non-overlapping TPC output in group 3 (independent 1 and 0 output at compare match A and B in the selected 16-bit timer channel)	

Bit 2—Group 2 Non-Overlap (G2NOV): Selects normal or non-overlapping TPC output for group 2 (TP₁₁ to TP₈).

Bit 2 G2NOV	Description	
0	Normal TPC output in group 2 (output values change at compare match A in the selected 16-bit timer channel)	(Initial value)
1	Non-overlapping TPC output in group 2 (independent 1 and 0 output at compare match A and B in the selected 16-bit timer channel)	

Bit 1—Group 1 Non-Overlap (G1NOV): Selects normal or non-overlapping TPC output for group 1 (TP_7 to TP_4).

Bit 1 G1NOV	Description	
0	Normal TPC output in group 1 (output values change at compare match A in the selected 16-bit timer channel)	(Initial value)
1	Non-overlapping TPC output in group 1 (independent 1 and 0 output at compare match A and B in the selected 16-bit timer channel)	

Bit 0—Group 0 Non-Overlap (G0NOV): Selects normal or non-overlapping TPC output for group 0 (TP_3 to TP_0).

Bit 0 G0NOV	Description	
0	Normal TPC output in group 0 (output values change at compare match A in the selected 16-bit timer channel)	(Initial value)
1	Non-overlapping TPC output in group 0 (independent 1 and 0 output at compare match A and B in the selected 16-bit timer channel)	

11.3 **Operation**

11.3.1 Overview

When corresponding bits in PADDR or PBDDR and NDERA or NDERB are set to 1, TPC output is enabled. The TPC output initially consists of the corresponding PADR or PBDR contents. When a compare-match event selected in TPCR occurs, the corresponding NDRA or NDRB bit contents are transferred to PADR or PBDR to update the output values.

Figure 11.2 illustrates the TPC output operation. Table 11.3 summarizes the TPC operating conditions.

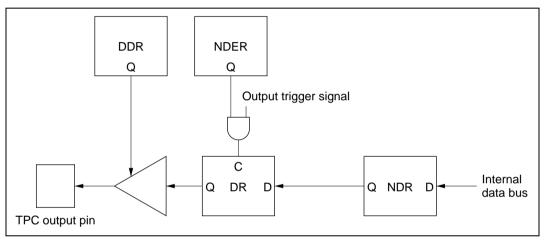


Figure 11.2 TPC Output Operation

Table 11.3 TPC Operating Conditions

NDER	DDR	Pin Function
0	0	Generic input port
	1	Generic output port
1	0	Generic input port (but the DR bit is a read-only bit, and when compare match occurs, the NDR bit value is transferred to the DR bit)
	1	TPC pulse output

Sequential output of up to 16-bit patterns is possible by writing new output data to NDRA and NDRB before the next compare match. For information on non-overlapping operation, see section 11.3.4, Non-Overlapping TPC Output.

11.3.2 Output Timing

If TPC output is enabled, NDRA/NDRB contents are transferred to PADR/PBDR and output when the selected compare match event occurs. Figure 11.3 shows the timing of these operations for the case of normal output in groups 2 and 3, triggered by compare match A.

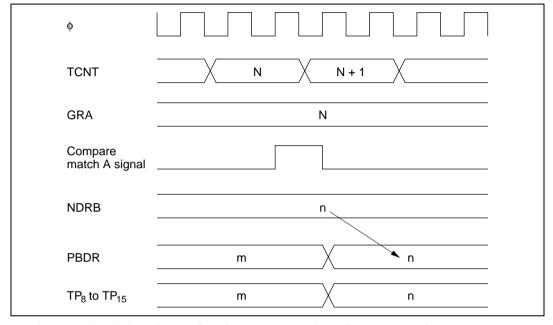


Figure 11.3 Timing of Transfer of Next Data Register Contents and Output (Example)

11.3.3 Normal TPC Output

Sample Setup Procedure for Normal TPC Output: Figure 11.4 shows a sample procedure for setting up normal TPC output.

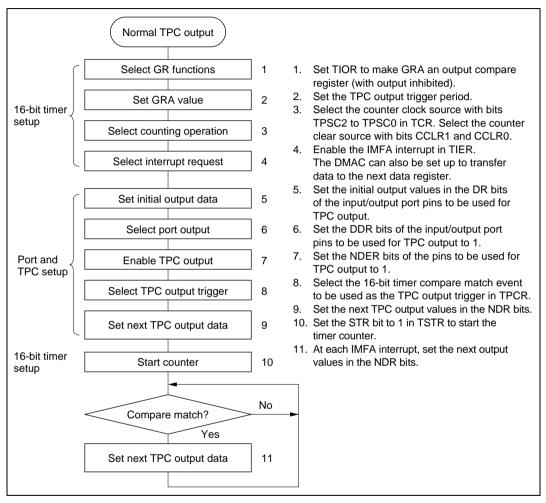
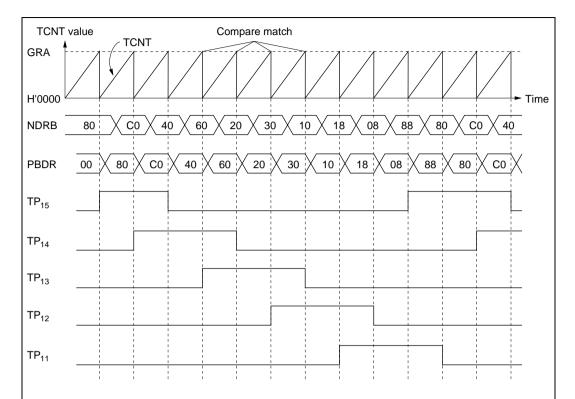


Figure 11.4 Setup Procedure for Normal TPC Output (Example)

Example of Normal TPC Output (Example of Five-Phase Pulse Output): Figure 11.5 shows an example in which the TPC is used for cyclic five-phase pulse output.



- The 16-bit timer channel to be used as the output trigger channel is set up so that GRA is an output compare register and the counter will be cleared by compare match A. The trigger period is set in GRA. The IMIEA bit is set to 1 in TIER to enable the compare match A interrupt.
- H'F8 is written in PBDDR and NDERB, and bits G3CMS1, G3CMS0, G2CMS1, and G2CMS0 are set in TPCR to select compare match in the 16-bit timer channel set up in step 1 as the output trigger.
 Output data H'80 is written in NDRB.
- The timer counter in this 16-bit timer channel is started. When compare match A occurs, the NDRB contents are transferred to PBDR and output. The compare match/input capture A (IMFA) interrupt service routine writes the next output data (H'C0) in NDRB.
- Five-phase overlapping pulse output (one or two phases active at a time) can be obtained by writing
 H'40, H'60, H'20, H'30, H'10, H'18, H'08, H'88... at successive IMFA interrupts. If the DMAC is set for
 activation by this interrupt, pulse output can be obtained without loading the CPU.

Figure 11.5 Normal TPC Output Example (Five-Phase Pulse Output)

11.3.4 Non-Overlapping TPC Output

Sample Setup Procedure for Non-Overlapping TPC Output: Figure 11.6 shows a sample procedure for setting up non-overlapping TPC output.

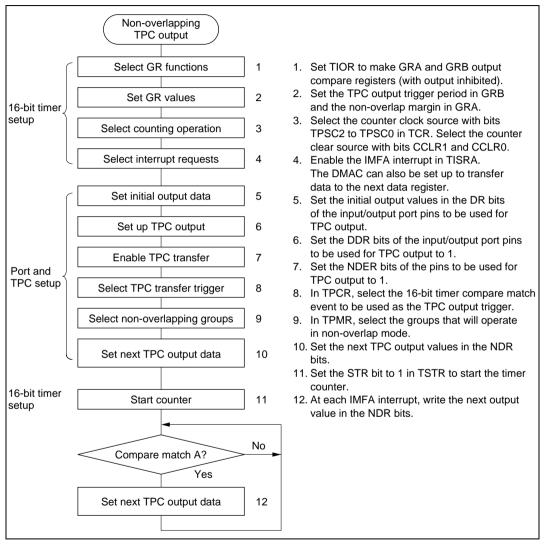
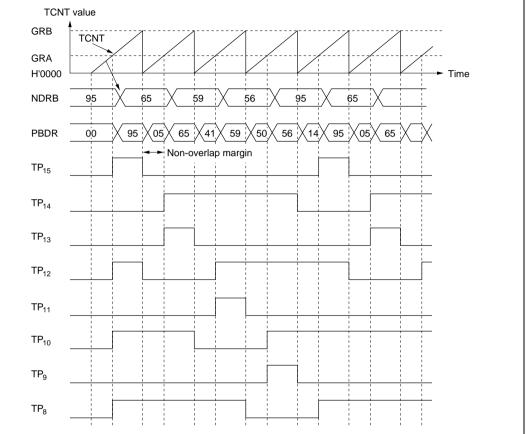


Figure 11.6 Setup Procedure for Non-Overlapping TPC Output (Example)

Example of Non-Overlapping TPC Output (Example of Four-Phase Complementary Non-Overlapping Output): Figure 11.7 shows an example of the use of TPC output for four-phase complementary non-overlapping pulse output.



- The 16-bit timer channel to be used as the output trigger channel is set up so that GRA and GRB are
 output compare registers and the counter will be cleared by compare match B. The TPC output trigger
 period is set in GRB. The non-overlap margin is set in GRA. The IMIEA bit is set to 1 in TISRA to enable
 IMFA interrupts.
- H'FF is written in PBDDR and NDERB, and bits G3CMS1, G3CMS0, G2CMS1, and G2CMS0 are set in TPCR to select compare match in the 16-bit timer channel set up in step 1 as the output trigger. Bits G3NOV and G2NOV are set to 1 in TPMR to select non-overlapping output. Output data H'95 is written in NDRB.
- The timer counter in this 16-bit timer channel is started. When compare match B occurs, outputs change from 1 to 0. When compare match A occurs, outputs change from 0 to 1 (the change from 0 to 1 is delayed by the value of GRA). The IMFA interrupt service routine writes the next output data (H'65) in NDRB.
- Four-phase complementary non-overlapping pulse output can be obtained by writing H'59, H'56, H'95...
 at successive IMFA interrupts. If the DMAC is set for activation by this interrupt, pulse output can be
 obtained without loading the CPU.

Figure 11.7 Non-Overlapping TPC Output Example (Four-Phase Complementary Non-Overlapping Pulse Output)

11.3.5 TPC Output Triggering by Input Capture

TPC output can be triggered by 16-bit timer input capture as well as by compare match. If GRA functions as an input capture register in the 16-bit timer channel selected in TPCR, TPC output will be triggered by the input capture signal. Figure 11.8 shows the timing.

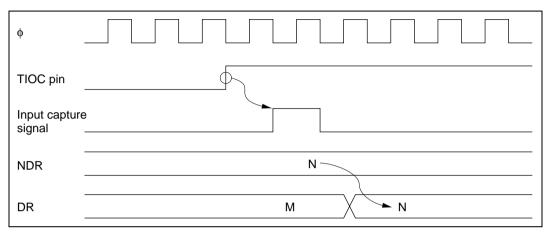


Figure 11.8 TPC Output Triggering by Input Capture (Example)

11.4 Usage Notes

11.4.1 Operation of TPC Output Pins

TP₀ to TP₁₅ are multiplexed with 16-bit timer, DMAC, address bus, and other pin functions. When 16-bit timer, DMAC, or address output is enabled, the corresponding pins cannot be used for TPC output. The data transfer from NDR bits to DR bits takes place, however, regardless of the usage of the pin.

Pin functions should be changed only under conditions in which the output trigger event will not occur.

11.4.2 Note on Non-Overlapping Output

During non-overlapping operation, the transfer of NDR bit values to DR bits takes place as follows.

- 1. NDR bits are always transferred to DR bits at compare match A.
- 2. At compare match B, NDR bits are transferred only if their value is 0. Bits are not transferred if their value is 1.

Figure 11.9 illustrates the non-overlapping TPC output operation.

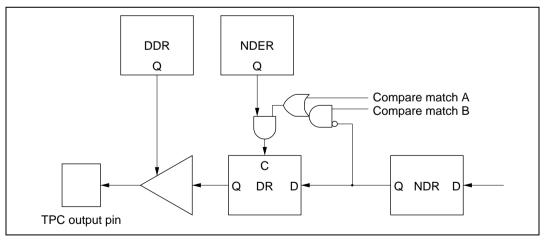


Figure 11.9 Non-Overlapping TPC Output

Therefore, 0 data can be transferred ahead of 1 data by making compare match B occur before compare match A. NDR contents should not be altered during the interval from compare match B to compare match A (the non-overlap margin).

This can be accomplished by having the IMFA interrupt service routine write the next data in NDR, or by having the IMFA interrupt activate the DMAC. The next data must be written before the next compare match B occurs.

Figure 11.10 shows the timing relationships.

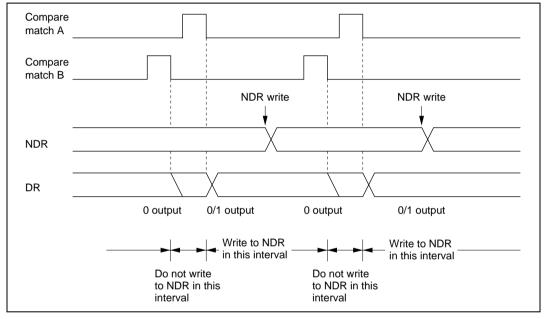


Figure 11.10 Non-Overlapping Operation and NDR Write Timing

Section 12 Watchdog Timer

12.1 Overview

The H8/3067 has an on-chip watchdog timer (WDT). The WDT has two selectable functions: it can operate as a watchdog timer to supervise system operation, or it can operate as an interval timer. As a watchdog timer, it generates a reset signal for the H8/3067 chip if a system crash allows the timer counter (TCNT) to overflow before being rewritten. In interval timer operation, an interval timer interrupt is requested at each TCNT overflow.

12.1.1 Features

WDT features are listed below

- Selection of eight counter clock sources
 φ/2, φ/32, φ/64, φ/128, φ/256, φ/512, φ/2048, or φ/4096
- Interval timer option
- Timer counter overflow generates a reset signal or interrupt.
 The reset signal is generated in watchdog timer operation. An interval timer interrupt is generated in interval timer operation.
- Watchdog timer reset signal resets the entire H8/3067 internally, and can also be output externally.
 - The reset signal generated by timer counter overflow during watchdog timer operation resets the entire H8/3067 internally. An external reset signal can be output from the \overline{RESO} pin to reset other system devices simultaneously. This function is not provided in the flash memory and flash memory R versions.

12.1.2 Block Diagram

Figure 12.1 shows a block diagram of the WDT.

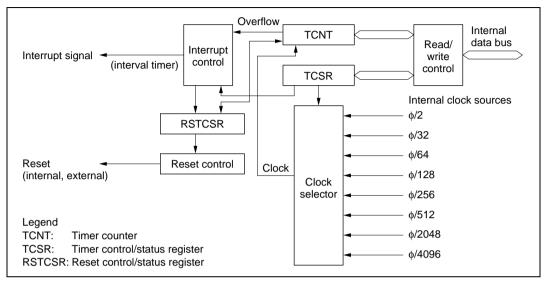


Figure 12.1 WDT Block Diagram

12.1.3 Pin Configuration

Table 12.1 describes the WDT output pin*1.

Table 12.1 WDT Pin

Name	Abbreviation	I/O	Function
Reset output	RESO	Output*2	External output of the watchdog timer reset signal

Notes: 1. Not present in the flash memory and flash memory R versions.

2. Open-drain output.

12.1.4 Register Configuration

Table 12.2 summarizes the WDT registers.

Table 12.2 WDT Registers

Address*1

Write*2	Read	Name	Abbreviation	R/W	Initial Value
H'FFF8C	H'FFF8C	Timer control/status register	TCSR	R/(W)*3	H'18
	H'FFF8D	Timer counter	TCNT	R/W	H'00
H'FFF8E	H'FFF8F	Reset control/status register	RSTCSR	R/(W)*3	H'3F

Notes: 1. Lower 20 bits of the address in advanced mode.

- 2. Write word data starting at this address.
- 3. Only 0 can be written in bit 7, to clear the flag.

12.2 Register Descriptions

12.2.1 Timer Counter (TCNT)

TCNT is an 8-bit readable and writable up-counter.

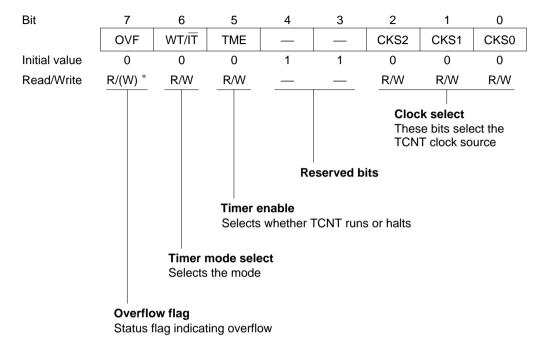
Bit	7	6	5	4	3	2	1	0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W							

Note: TCNT is write-protected by a password. For details see section 12.2.4, Notes on Register Access.

When the TME bit is set to 1 in TCSR, TCNT starts counting pulses generated from an internal clock source selected by bits CKS2 to CKS0 in TCSR. When the count overflows (changes from H'FF to H'00), the OVF bit is set to 1 in TCSR. TCNT is initialized to H'00 by a reset and when the TME bit is cleared to 0.

12.2.2 Timer Control/Status Register (TCSR)

TCSR is an 8-bit readable and writable register. Its functions include selecting the timer mode and clock source.



Notes: TCSR is write-protected by a password. For details see section 12.2.4, Notes on Register Access.

* Only 0 can be written, to clear the flag.

Bits 7 to 5 are initialized to 0 by a reset and in standby mode. Bits 2 to 0 are initialized to 0 by a reset. In software standby mode bits 2 to 0 are not initialized, but retain their previous values.

Bit 7—Overflow Flag (OVF): This status flag indicates that the timer counter has overflowed from H'FF to H'00.

Bit 7 OVF	Description	
0	[Clearing condition] Cleared by reading OVF when OVF = 1, then writing 0 in OVF	(Initial value)
1	[Setting condition] Set when TCNT changes from H'FF to H'00	

Bit 6—Timer Mode Select (WT/IT): Selects whether to use the WDT as a watchdog timer or interval timer. If used as an interval timer, the WDT generates an interval timer interrupt request when TCNT overflows. If used as a watchdog timer, the WDT generates a reset signal when TCNT overflows.

Bit 6 WT/ IT	Description	
0	Interval timer: requests interval timer interrupts	(Initial value)
1	Watchdog timer: generates a reset signal	

Bit 5—Timer Enable (TME): Selects whether TCNT runs or is halted. When $WT/\overline{IT} = 1$, clear the software standby bit (SSBY) to 0 in SYSCR before setting TME. When setting SSBY to 1, TME should be cleared to 0.

Bit 5 TME	Description	
0	TCNT is initialized to H'00 and halted	(Initial value)
1	TCNT is counting	

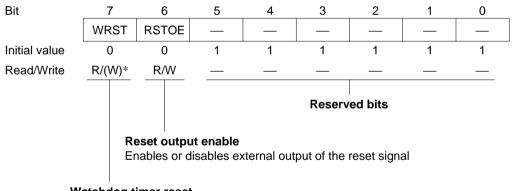
Bits 4 and 3—Reserved: These bits cannot be modified and are always read as 1.

Bits 2 to 0—Clock Select 2 to 0 (CKS2/1/0): These bits select one of eight internal clock sources, obtained by prescaling the system clock (ϕ) , for input to TCNT.

Bit 2 CKS2	Bit 1 CKS1	Bit 0 CKS0	Description	
0	0	0	φ/2	(Initial value)
		1	φ/32	
	1	0	φ /64	
		1	φ /128	
1	0	0	ф /256	
		1	φ /512	
	1	0	φ /2048	
		1	φ /4096	

12.2.3 Reset Control/Status Register (RSTCSR)

RSTCSR is an 8-bit readable and writable register that indicates when a reset signal has been generated by watchdog timer overflow, and controls external output of the reset signal.



Watchdog timer reset

Indicates that a reset signal has been generated

Notes: RSTCSR is write-protected by a password. For details see section 12.2.4, Notes on Register Access.

* Only 0 can be written in bit 7, to clear the flag.

Bits 7 and 6 are initialized by input of a reset signal at the \overline{RES} pin. They are not initialized by reset signals generated by watchdog timer overflow.

Bit 7—Watchdog Timer Reset (WRST): During watchdog timer operation, this bit indicates that TCNT has overflowed and generated a reset signal. This reset signal resets the entire H8/3067 chip internally. If bit RSTOE is set to 1, this reset signal is also output (low) at the $\overline{\text{RESO}}$ pin to initialize external system devices. Note that there is no $\overline{\text{RESO}}$ pin in the flash memory and flash memory R versions.

Bit 7 WRST	Description	
0	[Clearing condition] Reset signal at RES pin. Read WRST when WRST =1, then write 0 in WRST. (Initial value)	ue)
1	[Setting condition] Set when TCNT overflow generates a reset signal during watchdog timer operation	

Bit 6—Reset Output Enable (RSTOE): Enables or disables external output at the RESO pin of the reset signal generated if TCNT overflows during watchdog timer operation. Note that there is no RESO pin in the flash memory and flash memory R versions.

Bit 6 RSTOE Description

0	Reset signal is not output externally (Initial value)	(Initial value)
1	Reset signal is output externally	

Bits 5 to 0—Reserved: These bits cannot be modified and are always read as 1.

12.2.4 Notes on Register Access

The watchdog timer's TCNT, TCSR, and RSTCSR registers differ from other registers in being more difficult to write. The procedures for writing and reading these registers are given below.

Writing to TCNT and TCSR: These registers must be written by a word transfer instruction. They cannot be written by byte instructions. Figure 12.2 shows the format of data written to TCNT and TCSR. TCNT and TCSR both have the same write address. The write data must be contained in the lower byte of the written word. The upper byte must contain H'5A (password for TCNT) or H'A5 (password for TCSR). This transfers the write data from the lower byte to TCNT or TCSR.

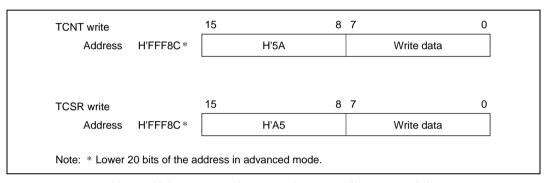


Figure 12.2 Format of Data Written to TCNT and TCSR

Writing to RSTCSR: RSTCSR must be written by a word transfer instruction. It cannot be written by byte transfer instructions. Figure 12.3 shows the format of data written to RSTCSR. To write 0 in the WRST bit, the write data must have H'A5 in the upper byte and H'00 in the lower byte. The data (H'00) in the lower byte is written to RSTCSR, clearing the WRST bit to 0. To write to the RSTOE bit, the upper byte must contain H'5A and the lower byte must contain the write data. Writing this word transfers a write data value into the RSTOE bit.

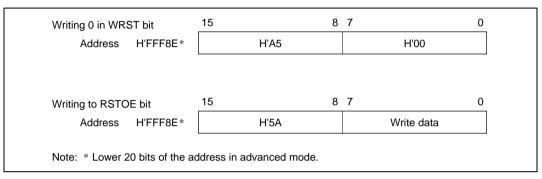


Figure 12.3 Format of Data Written to RSTCSR

Reading TCNT, TCSR, and RSTCSR: These registers are read like other registers. Reading TCNT, TCSR, and RSTCSR: These registers are read like other registers. Byte transfer instructions can be used. The read addresses are H'FFF8C for TCSR, H'FFF8D for TCNT, and H'FFF8F for RSTCSR, as listed in table 12-3.

Table 12.3 Read Addresses of TCNT, TCSR, and RSTCSR

Address*	Register
H'FFF8C	TCSR
H'FFF8D	TCNT
H'FFF8F	RSTCSR

Note: *Lower 20 bits of the address in advanced mode.

12.3 Operation

Operations when the WDT is used as a watchdog timer and as an interval timer are described below.

12.3.1 Watchdog Timer Operation

Figure 12.4 illustrates watchdog timer operation. To use the WDT as a watchdog timer, set the WT/IT and TME bits to 1 in TCSR. Software must prevent TCNT overflow by rewriting the TCNT value (normally by writing H'00) before overflow occurs. If TCNT fails to be rewritten and overflows due to a system crash etc., the H8/3067 is internally reset for a duration of 518 states.

The watchdog reset signal can be externally output from the \overline{RESO} pin to reset external system devices. The reset signal is output externally for 132 states. External output can be enabled or disabled by the RSTOE bit in RSTCSR. The \overline{RESO} pin function is not available in the flash memory and flash memory R versions.

A watchdog reset has the same vector as a reset generated by input at the \overline{RES} pin. Software can distinguish a \overline{RES} reset from a watchdog reset by checking the WRST bit in RSTCSR.

If a RES reset and a watchdog reset occur simultaneously, the RES reset takes priority.

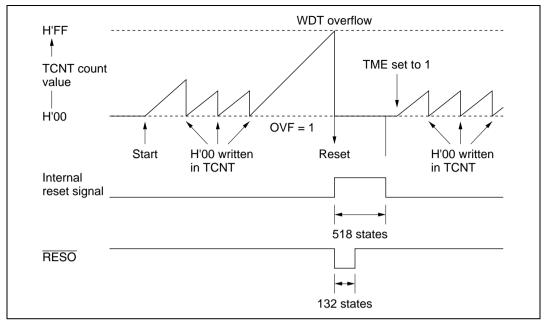


Figure 12.4 Operation in Watchdog Timer Mode

12.3.2 Interval Timer Operation

Figure 12.5 illustrates interval timer operation. To use the WDT as an interval timer, clear bit WT/\overline{IT} to 0 and set bit TME to 1 in TCSR. An interval timer interrupt request is generated at each TCNT overflow. This function can be used to generate interval timer interrupts at regular intervals.

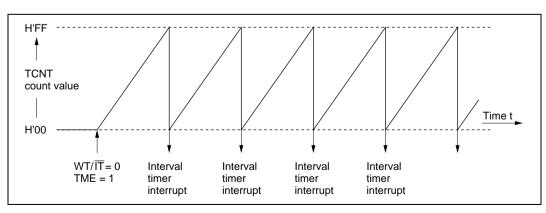


Figure 12.5 Interval Timer Operation

12.3.3 Timing of Setting of Overflow Flag (OVF)

Figure 12.6 shows the timing of setting of the OVF flag. The OVF flag is set to 1 when TCNT overflows. At the same time, a reset signal is generated in watchdog timer operation, or an interval timer interrupt is generated in interval timer operation.

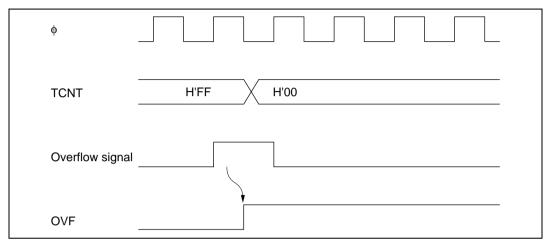


Figure 12.6 Timing of Setting of OVF

12.3.4 Timing of Setting of Watchdog Timer Reset Bit (WRST)

The WRST bit in RSTCSR is valid when bits WT/IT and TME are both set to 1 in TCSR.

Figure 12.7 shows the timing of setting of WRST and the internal reset timing. The WRST bit is set to 1 when TCNT overflows and OVF is set to 1. At the same time an internal reset signal is generated for the entire H8/3067 chip. This internal reset signal clears OVF to 0, but the WRST bit remains set to 1. The reset routine must therefore clear the WRST bit.

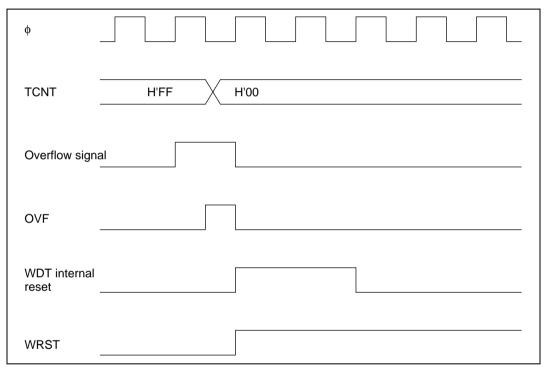


Figure 12.7 Timing of Setting of WRST Bit and Internal Reset

12.4 Interrupts

During interval timer operation, an overflow generates an interval timer interrupt (WOVI). The interval timer interrupt is requested whenever the OVF bit is set to 1 in TCSR.

12.5 Usage Notes

Contention between TCNT Write and Increment: If a timer counter clock pulse is generated during the T_3 state of a write cycle to TCNT, the write takes priority and the timer count is not incremented. See figure 12.8.

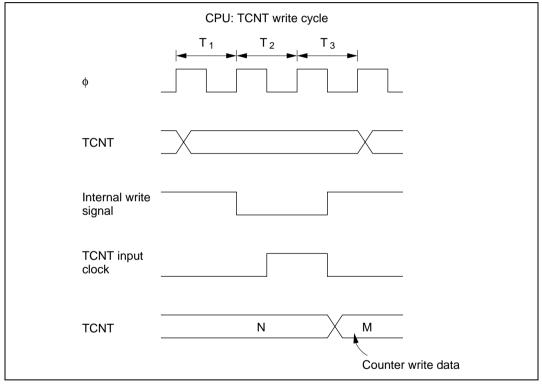


Figure 12.8 Contention between TCNT Write and Count up

Changing CKS2 to CKS0 Bit: Halt TCNT by clearing the TME bit to 0 in TCSR before changing the values of bits CKS2 to CKS0.



Section 13 Serial Communication Interface

13.1 Overview

The H8/3067 Group has a serial communication interface (SCI) with three independent channels. All three channels have identical functions. The SCI can communicate in both asynchronous and synchronous mode. It also has a multiprocessor communication function for serial communication among two or more processors.

When the SCI is not used, it can be halted to conserve power. Each SCI channel can be halted independently. For details, see section 20.6, Module Standby Function.

The SCI also has a smart card interface function conforming to the ISO/IEC 7816-3 (Identification Card) standard. This function supports serial communication with a smart card. Switching between the normal serial communication interface and the smart card interface is carried out by means of a register setting.

13.1.1 Features

SCI features are listed below.

• Selection of synchronous or asynchronous mode for serial communication

Asynchronous mode

Serial data communication is synchronized one channel at a time. The SCI can communicate with a universal asynchronous receiver/transmitter (UART), asynchronous communication interface adapter (ACIA), or other chip that employs standard asynchronous communication. It can also communicate with two or more other processors using the multiprocessor communication function. There are twelve selectable serial data transfer formats.

Data length: 7 or 8 bits
Stop bit length: 1 or 2 bits
Parity: even/odd/none

— Multiprocessor bit: 1 or 0

— Receive error detection: parity, overrun, and framing errors

— Break detection: by reading the RxD level directly when a framing error occurs

Synchronous mode

Serial data communication is synchronized with a clock signal. The SCI can communicate with other chips having a synchronous communication function.

There is a single serial data communication format.

Section 13 Serial Communication Interface

- Data length: 8 bits
- Receive error detection: overrun errors
- Full-duplex communication

The transmitting and receiving sections are independent, so the SCI can transmit and receive simultaneously. The transmitting and receiving sections are both double-buffered, so serial data can be transmitted and received continuously.

- The following settings can be made for the serial data to be transferred:
 - LSB-first or MSB-first transfer
 - Inversion of data logic level
- Built-in baud rate generator with selectable bit rates
- Selectable transmit/receive clock sources: internal clock from baud rate generator, or external clock from the SCK pin
- Four types of interrupts

Transmit-data-empty, transmit-end, receive-data-full, and receive-error interrupts are requested independently. The transmit-data-empty and receive-data-full interrupts from SCI0 can activate the DMA controller (DMAC) to transfer data.

Features of the smart card interface are listed below.

- Asynchronous communication
 - Data length: 8 bits
 - Parity bits generated and checked
 - Error signal output in receive mode (parity error)
 - Error signal detect and automatic data retransmit in transmit mode
 - Supports both direct convention and inverse convention
- Built-in baud rate generator with selectable bit rates
- Three types of interrupts

Transmit-data-empty, receive-data-full, and transmit/receive-error interrupts are requested independently. The transmit-data-empty and receive-data-full interrupts can activate the DMA controller (DMAC) to transfer data.



13.1.2 Block Diagram

Figure 13.1 shows a block diagram of the SCI.

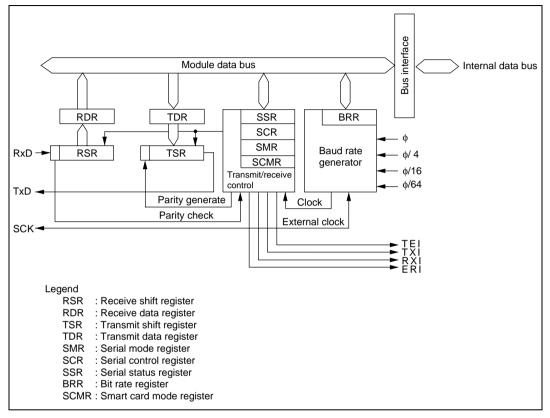


Figure 13.1 SCI Block Diagram

13.1.3 Input/Output Pins

The SCI has serial pins for each channel as listed in table 13.1.

Table 13.1 SCI Pins

Channel	Name	Abbreviation	I/O	Function
0	Serial clock pin	SCK₀	Input/output	SCI ₀ clock input/output
	Receive data pin	RxD _o	Input	SCI ₀ receive data input
	Transmit data pin	TxD ₀	Output	SCI ₀ transmit data output
1	Serial clock pin	SCK,	Input/output	SCI₁ clock input/output
	Receive data pin	RxD ₁	Input	SCI, receive data input
	Transmit data pin	TxD ₁	Output	SCI, transmit data output
2	Serial clock pin	SCK ₂	Input/output	SCI ₂ clock input/output
	Receive data pin	RxD ₂	Input	SCI ₂ receive data input
	Transmit data pin	TxD ₂	Output	SCI ₂ transmit data output

13.1.4 Register Configuration

The SCI has internal registers as listed in table 13.2. These registers select asynchronous or synchronous mode, specify the data format and bit rate, control the transmitter and receiver sections, and specify switching between the serial communication interface and smart card interface.

Table 13.2 SCI Registers

Channel	Address*1	Name	Abbreviation	R/W	Initial Value
0	H'FFFB0	Serial mode register	SMR	R/W	H'00
	H'FFFB1	Bit rate register	BRR	R/W	H'FF
	H'FFFB2	Serial control register	SCR	R/W	H'00
	H'FFFB3	Transmit data register	TDR	R/W	H'FF
	H'FFFB4	Serial status register	SSR	R/(W)*2	H'84
	H'FFFB5	Receive data register	RDR	R	H'00
	H'FFFB6	Smart card mode register	SCMR	R/W	H'F2
1	H'FFFB8	Serial mode register	SMR	R/W	H'00
	H'FFFB9	Bit rate register	BRR	R/W	H'FF
	H'FFFBA	Serial control register	SCR	R/W	H'00
	H'FFFBB	Transmit data register	TDR	R/W	H'FF
	H'FFFBC	Serial status register	SSR	R/(W)*2	H'84
	H'FFFBD	Receive data register	RDR	R	H'00
	H'FFFBE	Smart card mode register	SCMR	R/W	H'F2
2	H'FFFC0	Serial mode register	SMR	R/W	H'00
	H'FFFC1	Bit rate register	BRR	R/W	H'FF
	H'FFFC2	Serial control register	SCR	R/W	H'00
	H'FFFC3	Transmit data register	TDR	R/W	H'FF
	H'FFFC4	Serial status register	SSR	R/(W)*2	H'84
	H'FFFC5	Receive data register	RDR	R	H'00
	H'FFFC6	Smart card mode register	SCMR	R/W	H'F2

Notes: 1. Indicates the lower 20 bits of the address in advanced mode.

2. Only 0 can be written, to clear flags.

13.2 Register Descriptions

13.2.1 Receive Shift Register (RSR)

RSR is the register that receives serial data.

Bit	7	6	5	4	3	2	1	0
Read/Write								

The SCI loads serial data input at the RxD pin into RSR in the order received, LSB (bit 0) first, thereby converting the data to parallel data. When one byte of data has been received, it is automatically transferred to RDR. The CPU cannot read or write RSR directly.

13.2.2 Receive Data Register (RDR)

RDR is the register that stores received serial data.

Bit	7	6	5	4	3	2	1	0	
Initial value	0	0	0	0	0	0	0	0	
Read/Write	R	R	R	R	R	R	R	R	

When the SCI has received one byte of serial data, it transfers the received data from RSR into RDR for storage, completing the receive operation. RSR is then ready to receive the next data. This double-buffering allows data to be received continuously.

RDR is a read-only register. Its contents cannot be modified by the CPU. RDR is initialized to H'00 by a reset and in standby mode.

13.2.3 Transmit Shift Register (TSR)

TSR is the register that transmits serial data.

Bit	7	6	5	4	3	2	1	0
Read/Write								

The SCI loads transmit data from TDR to TSR, then transmits the data serially from the TxD pin, LSB (bit 0) first. After transmitting one data byte, the SCI automatically loads the next transmit data from TDR into TSR and starts transmitting it. If the TDRE flag is set to 1 in SSR, however, the SCI does not load the TDR contents into TSR. The CPU cannot read or write RSR directly.

13.2.4 Transmit Data Register (TDR)

TDR is an 8-bit register that stores data for serial transmission.

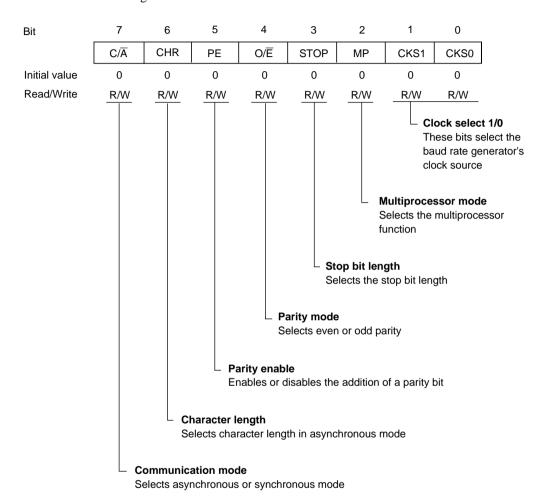
Bit	7	6	5	4	3	2	1	0
Initial value	1	1	1	1	1	1	1	1
Read/Write	R/W							

When the SCI detects that TSR is empty, it moves transmit data written in TDR from TDR into TSR and starts serial transmission. Continuous serial transmission is possible by writing the next transmit data in TDR during serial transmission from TSR.

The CPU can always read and write TDR. TDR is initialized to H'FF by a reset and in standby mode.

13.2.5 Serial Mode Register (SMR)

SMR is an 8-bit register that specifies the SCI's serial communication format and selects the clock source for the baud rate generator.



The CPU can always read and write SMR. SMR is initialized to H'00 by a reset and in standby mode.

Bit 7—Communication Mode (C/A)/GSM Mode (GM): The function of this bit differs for the normal serial communication interface and for the smart card interface. Its function is switched with the SMIF bit in SCMR.

For serial communication interface (SMIF bit in SCMR cleared to 0): Selects whether the SCI operates in asynchronous or synchronous mode.

Bit 7 C/Ā	Description	
0	Asynchronous mode	(Initial value)
1	Synchronous mode	

For smart card interface (SMIF bit in SCMR set to 1): Selects GSM mode for the smart card interface

Description	
The TEND flag is set 12.5 etu after the start bit	(Initial value)
The TEND flag is set 11.0 etu after the start bit	
	The TEND flag is set 12.5 etu after the start bit

Note: etu: Elementary time unit (time required to transmit one bit)

Bit 6—Character Length (CHR): Selects 7-bit or 8-bits data length in asynchronous mode. In synchronous mode, the data length is 8 bits regardless of the CHR setting,

Bit 6 CHR	Description	
0	8-bit data	(Initial value)
1	7-bit data*	

Note: * When 7-bit data is selected, the MSB (bit 7) of TDR is not transmitted.

Bit 5—Parity Enable (PE): In asynchronous mode, this bit enables or disables the addition of a parity bit to transmit data, and the checking of the parity bit in receive data. In synchronous mode, the parity bit is neither added nor checked, regardless of the PE bit setting.

Bit 5		
PE	Description	
0	Parity bit not added or checked	(Initial value)
1	Parity bit added and checked*	

Note: *When PE bit is set to 1, an even or odd parity bit is added to transmit data according to the even or odd parity mode selection by the O/E bit, and the parity bit in receive data is checked to see that it matches the even or odd mode selected by the O/E bit.

Bit 4—Parity Mode (O/\overline{E}): Selects even or odd parity. The O/ \overline{E} bit setting is only valid when the PE bit is set to 1, enabling parity bit addition and checking, in asynchronous mode. The O/ \overline{E} bit setting is ignored in synchronous mode, or when parity addition and checking is disabled in asynchronous mode.

Bit 4 O/E	Description	
0	Even parity*1	(Initial value)
1	Odd parity*2	

- Notes: 1. When even parity is selected, the parity bit added to transmit data makes an even number of 1s in the transmitted character and parity bit combined. Receive data must have an even number of 1s in the received character and parity bit combined.
 - When odd parity is selected, the parity bit added to transmit data makes an odd number of 1s in the transmitted character and parity bit combined. Receive data must have an odd number of 1s in the received character and parity bit combined.

Bit 3—Stop Bit Length (STOP): Selects one or two stop bits in asynchronous mode. This setting is used only in asynchronous mode. In synchronous mod no stop bit is added, so the STOP bit setting is ignored.

Bit 3 STOP	Description	
0	1 stop bit*1	(Initial value)
1	2 stop bits*2	

Notes: 1. One stop bit (with value 1) is added to the end of each transmitted character.

2. Two stop bits (with value 1) are added to the end of each transmitted character.



In receiving, only the first stop bit is checked, regardless of the STOP bit setting. If the second stop bit is 1, it is treated as a stop bit. If the second stop bit is 0, it is treated as the start bit of the next incoming character.

Bit 2—Multiprocessor Mode (MP): Selects a multiprocessor format. When a multiprocessor format is selected, parity settings made by the PE and O/\overline{E} bits are ignored. The MP bit setting is valid only in asynchronous mode. It is ignored in synchronous mode.

For further information on the multiprocessor communication function, see section 13.3.3, Multiprocessor Communication.

Bit 2 MP	Description	
0	Multiprocessor function disabled	(Initial value)
1	Multiprocessor format selected	

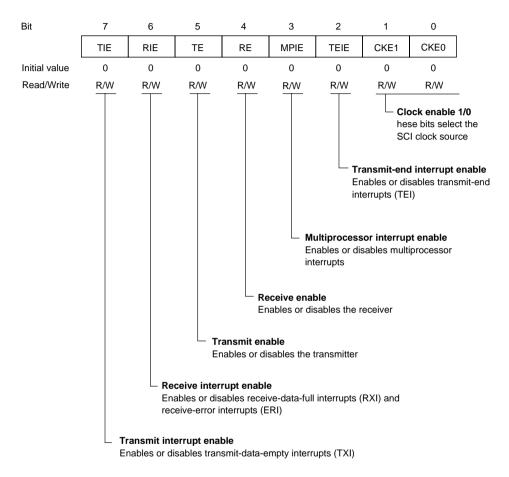
Bits 1 and 0—Clock Select 1 and 0 (CKS1/0): These bits select the clock source for the on-chip baud rate generator. Four clock sources are available: ϕ , $\phi/4$, $\phi/16$, and $\phi/64$.

For the relationship between the clock source, bit rate register setting, and baud rate, see section 13.2.8, Bit Rate Register (BRR).

Bit 1 CKS1	Bit 0 CKS0	Description	
0	0	ф	(Initial value)
0	1	φ/4	
1	0	φ/16	
1	1	φ/64	

13.2.6 Serial Control Register (SCR)

SCR register enables or disables the SCI transmitter and receiver, enables or disables serial clock output in asynchronous mode, enables or disables interrupts, and selects the transmit/receive clock source.



The CPU can always read and write SCR. SCR is initialized to H'00 by a reset and in standby mode.

Bit 7—Transmit Interrupt Enable (**TIE**): Enables or disables the transmit-data-empty interrupt (TXI) requested when the TDRE flag in SSR is set to 1 due to transfer of serial transmit data from TDR to TSR.

Bit 7		
TIE	Description	
0	Transmit-data-empty interrupt request (TXI) is disabled*	(Initial value)
1	Transmit-data-empty interrupt request (TXI) is enabled	

Note: *TXI interrupt requests can be cleared by reading the value 1 from the TDRE flag, then clearing it to 0; or by clearing the TIE bit to 0.

Bit 6—Receive Interrupt Enable (RIE): Enables or disables the receive-data-full interrupt (RXI) requested when the RDRF flag in SSR is set to 1 due to transfer of serial receive data from RSR to RDR; also enables or disables the receive-error interrupt (ERI).

Bit 6 RIE	Description
0	Receive-data-full (RXI) and receive-error (ERI) interrupt requests are disabled* (Initial value)
1	Receive-data-full (RXI) and receive-error (ERI) interrupt requests are enabled

Note: *RXI and ERI interrupt requests can be cleared by reading the value 1 from the RDRF, FER, PER, or ORER flag, then clearing the flag to 0; or by clearing the RIE bit to 0.

Bit 5—Transmit Enable (TE): Enables or disables the start of SCI serial transmitting operations.

Bit 5		
TE	Description	
0	Transmitting disabled*1	(Initial value)
1	Transmitting enabled*2	

Notes: 1. The TDRE flag is fixed at 1 in SSR.

2. In the enabled state, serial transmission starts when the TDRE flag in SSR is cleared to 0 after writing of transmit data into TDR. Select the transmit format in SMR before setting the TE bit to 1.

Bit 4—Receive Enable (RE): Enables or disables the start of SCI serial receiving operations.

Bit 4 RE	Description	
0	Receiving disabled*1	(Initial value)
1	Receiving enabled*2	

- Notes: 1. Clearing the RE bit to 0 does not affect the RDRF, FER, PER, and ORER flags. These flags retain their previous values.
 - 2. In the enabled state, serial receiving starts when a start bit is detected in asynchronous mode, or serial clock input is detected in synchronous mode. Select the receive format in SMR before setting the RE bit to 1.

Bit 3—Multiprocessor Interrupt Enable (MPIE): Enables or disables multiprocessor interrupts. The MPIE bit setting is valid only in asynchronous mode, and only if the MP bit is set to 1 in SMR. The MPIE bit setting is ignored in synchronous mode or when the MP bit is cleared to 0.

Bit 3 MPIE	Description
0	Multiprocessor interrupts are disabled (normal receive operation) (Initial value) Clearing conditions (1) The MPIE bit is cleared to 0 (2) MPB = 1 in received data
1	Multiprocessor interrupts are enabled* Receive-data-full interrupts (RXI), receive-error interrupts (ERI), and setting of the RDRF, FER, and ORER status flags in SSR are disabled until data with the multiprocessor bit set to 1 is received.

Note: *The SCI does not transfer receive data from RSR to RDR, does not detect receive errors, and does not set the RDRF, FER, and ORER flags in SSR. When it receives data in which MPB = 1, the SCI sets the MPB bit to 1 in SSR, automatically clears the MPIE bit to 0, enables RXI and ERI interrupts (if the TIE and RIE bits in SCR are set to 1), and allows the FER and ORER flags to be set.

Bit 2—Transmit-End interrupt Enable (TEIE): Enables or disables the transmit-end interrupt (TEI) requested if TDR does not contain valid transmit data when the MSB is transmitted.

Bit 2 TEIE	Description	
0	Transmit-end interrupt requests (TEI) are disabled*	(Initial value)
1	Transmit-end interrupt requests (TEI) are enabled*	

Note: *TEI interrupt requests can be cleared by reading the value 1 from the TDRE flag in SSR, then clearing the TDRE flag to 0, thereby also clearing the TEND flag to 0; or by clearing the TEIE bit to 0.

Bits 1 and 0—Clock Enable 1 and 0 (CKE1/0): The function of these bits differs for the normal serial communication interface and for the smart card interface. Their function is switched with the SMIF bit in SCMR.

For serial communication interface (SMIF bit in SCMR cleared to 0): These bits select the SCI clock source and enable or disable clock output from the SCK pin. Depending on the settings of CKE1 and CKE0, the SCK pin can be used for generic input/output, serial clock output, or serial clock input.

The CKE0 setting is valid only in asynchronous mode, and only when the SCI is internally clocked (CKE1 = 0). The CKE0 setting is ignored in synchronous mode, or when an external clock source is selected (CKE1 = 1). Select the SCI operating mode in SMR before setting the CKE1 and CKE0 bits . For further details on selection of the SCI clock source, see table 13.9 in section 13.3, Operation.

Bit 1 Bit 0 CKE1 CKE0 Description

0	0	Asynchronous mode	Internal clock, SCK pin available for generic input/output*1
		Synchronous mode	Internal clock, SCK pin used for serial clock output*1
0	1	Asynchronous mode	Internal clock, SCK pin used for clock output*2
		Synchronous mode	Internal clock, SCK pin used for serial clock output
1	0	Asynchronous mode	External clock, SCK pin used for clock input*3
		Synchronous mode	External clock, SCK pin used for serial clock input
1	1	Asynchronous mode	External clock, SCK pin used for clock input*3
		Synchronous mode	External clock, SCK pin used for serial clock input

Notes: 1. Initial value

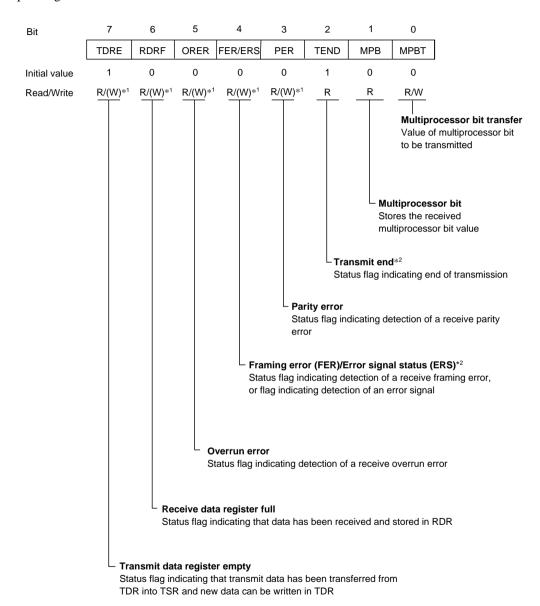
- 2. The output clock frequency is the same as the bit rate.
- 3. The input clock frequency is 16 times the bit rate.

For smart card interface (SMIF bit in SCMR set to 1): These bits, together with the GM bit in SMR, determine whether the SCK pin is used for generic input/output or as the serial clock output pin.

SMR	Bit 1	Bit 0		
GM	CKE1	CKE0	Description	
0	0	0	SCK pin available for generic input/output (Initia	al value)
0	0	1	SCK pin used for clock output	
1	0	0	SCK pin output fixed low	
1	0	1	SCK pin used for clock output	
1	1	0	SCK pin output fixed high	
1	1	1	SCK pin used for clock output	

13.2.7 Serial Status Register (SSR)

SSR is an 8-bit register containing multiprocessor bit values, and status flags that indicate the operating status of the SCI.



- Notes: 1. Only 0 can be written, to clear the flag.
 - 2. Function differs between the normal serial communication interface and the smart card interface.

The CPU can always read and write SSR, but cannot write 1 in the TDRE, RDRF, ORER, PER, and FER flags. These flags can be cleared to 0 only if they have first been read while set to 1. The TEND and MPB flags are read-only bits that cannot be written.

SSR is initialized to H'84 by a reset and in standby mode.

Bit 7—Transmit Data Register Empty (TDRE): Indicates that the SCI has loaded transmit data from TDR into TSR and the next serial data can be written in TDR.

Bit 7 TDRE	Description	
0	TDR contains valid transmit data Clearing conditions Read TDRE when TDRE = 1, then write 0 in TDRE The DMAC writes data in TDR	
1	TDR does not contain valid transmit data Setting conditions The chip is reset or enters standby mode The TE bit in SCR is cleared to 0 TDR contents are loaded into TSR, so new data can be written in	(Initial value)

Bit 6—Receive Data Register Full (RDRF): Indicates that RDR contains new receive data.

Bit 6	
RDRF	Description
0	RDR does not contain new receive data (Initial value) Clearing conditions The chip is reset or enters standby mode Read RDRF when RDRF = 1, then write 0 in RDRF The DMAC reads data from RDR
1	RDR contains new receive data Setting condition Serial data is received normally and transferred from RSR to RDR

Note: The RDR contents and the RDRF flag are not affected by detection of receive errors or by clearing of the RE bit to 0 in SCR. They retain their previous values. If the RDRF flag is still set to 1 when reception of the next data ends, an overrun error will occur and the receive data will be lost.



Bit 5—Overrun Error (ORER): Indicates that data reception ended abnormally due to an overrun error.

Bit 5 ORER	Description	
0	Receiving is in progress or has ended normally*1 Clearing conditions The chip is reset or enters standby mode Read ORER when ORER = 1, then write 0 in ORER	(Initial value)
1	A receive overrun error occurred*2 Setting condition Reception of the next serial data ends when RDRF = 1	

Notes: 1. Clearing the RE bit to 0 in SCR does not affect the ORER flag, which retains its previous value.

RDR continues to hold the receive data prior to the overrun error, so subsequent receive data is lost. Serial receiving cannot continue while the ORER flag is set to 1. In synchronous mode, serial transmitting is also disabled.

Bit 4—Framing Error (FER)/Error Signal Status (ERS): The function of this bit differs for the normal serial communication interface and for the smart card interface. Its function is switched with the SMIF bit in SCMR.

For serial communication interface (SMIF bit in SCMR cleared to 0): Indicates that data reception ended abnormally due to a framing error in asynchronous mode.

Bit 4 FER	Description	
0	Receiving is in progress or has ended normally*1 Clearing conditions The chip is reset or enters standby mode Read FER when FER = 1, then write 0 in FER	(Initial value)
1	A receive framing error occurred*2 Setting condition The stop bit at the end of the receive data is checked and	I found to be 0

Notes: 1. Clearing the RE bit to 0 in SCR does not affect the FER flag, which retains its previous value.

2. When the stop bit length is 2 bits, only the first bit is checked. The second stop bit is not checked. When a framing error occurs the SCI transfers the receive data into RDR but does not set the RDRF flag. Serial receiving cannot continue while the FER flag is set to 1. In synchronous mode, serial transmitting is also disabled.

For smart card interface (SMIF bit in SCMR set to 1): Indicates the status of the error signal sent back from the receiving side during transmission. Framing errors are not detected in smart card interface mode.

Bit 4		
ERS	Description	
0	Normal reception, no error signal* Clearing conditions The chip is reset or enters standby mode Read ERS when ERS = 1, then write 0 in ERS	(Initial value)
1	An error signal has been sent from the receiving side indicatin parity error Setting condition The error signal is low when sampled	g detection of a

Note: * Clearing the TE bit to 0 in SCR does not affect the ERS flag, which retains its previous value.

Bit 3—Parity Error (PER): Indicates that data reception ended abnormally due to a parity error in asynchronous mode.

Bit 3 PER	Description	
0	Receiving is in progress or has ended normally*1 Clearing conditions The chip is reset or enters standby mode Read PER when PER = 1, then write 0 in PER	(Initial value)
1	A receive parity error occurred*2 Setting condition The number of 1s in receive data, including the parity bit, does reven or odd parity setting of O/E in SMR	not match the

Notes: 1. Clearing the RE bit to 0 in SCR does not affect the PER flag, which retains its previous value.

When a parity error occurs the SCI transfers the receive data into RDR but does not set the RDRF flag. Serial receiving cannot continue while the PER flag is set to 1. In synchronous mode, serial transmitting is also disabled. **Bit 2—Transmit End (TEND):** The function of this bit differs for the normal serial communication interface and for the smart card interface. Its function is switched with the SMIF bit in SCMR.

For serial communication interface (SMIF bit in SCMR cleared to 0): Indicates that when the last bit of a serial character was transmitted TDR did not contain valid transmit data, so transmission has ended. The TEND flag is a read-only bit and cannot be written.

Bit 2 TEND	Description	
0	Transmission is in progress Clearing conditions Read TDRE when TDRE = 1, then write 0 in TDRE The DMAC writes data in TDR	
1	End of transmission (Initial Setting conditions The chip is reset or enters standby mode The TE bit in SCR is cleared to 0 TDRE is 1 when the last bit of a 1-byte serial transmit character is transmit	,

For smart card interface (SMIF bit in SCMR set to 1): Indicates that when the last bit of a serial character was transmitted TDR did not contain valid transmit data, so transmission has ended. The TEND flag is a read-only bit and cannot be written.

Bit 2 TEND	Description
0	Transmission is in progress Clearing conditions Read TDRE when TDRE = 1, then write 0 in TDRE The DMAC writes data in TDR
1	End of transmission (Initial value) Setting conditions The chip is reset or enters standby mode The TE bit is cleared to 0 in SCR and the FER/ERS bit is also cleared to 0 TDRE is 1 and FER/ERS is 0 (normal transmission) 2.5 etu (when GM = 0) or 1.0 etu (when GM = 1) after a 1-byte serial character is transmitted

Note: etu: Elementary time unit (time required to transmit one bit)

Bit 1—Multiprocessor bit (MPB): Stores the value of the multiprocessor bit in the receive data when a multiprocessor format is used in asynchronous mode. MPB is a read-only bit, and cannot be written.

Bit 1		
MPB	Description	
0	Multiprocessor bit value in receive data is 0*	(Initial value)
1	Multiprocessor bit value in receive data is 1	

Note: * If the RE bit in SCR is cleared to 0 when a multiprocessor format is selected, MPB retains its previous value.

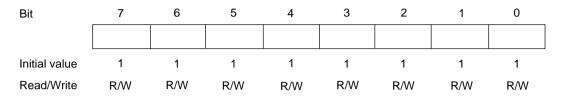
Bit 0—Multiprocessor Bit Transfer (MPBT): Stores the value of the multiprocessor bit added to transmit data when a multiprocessor format in selected for transmitting in asynchronous mode.

The MPBT bit setting is ignored in synchronous mode, when a multiprocessor format is not selected, or when the SCI cannot transmit.

Bit 1 MPBT	Description	
0	Multiprocessor bit value in transmit data is 0	(Initial value)
1	Multiprocessor bit value in transmit data is 1	

13.2.8 Bit Rate Register (BRR)

BRR is an 8-bit register that., together with the CKS1 and CKS0 bits in SMR that select the baud rate generator clock source, determines the serial communication bit rate.



The CPU can always read and write BRR. BRR is initialized to H'FF by a reset and in standby mode. Each SCI channel has independent baud rate generator control, so different values can be set in the three channels.

Table 13.3 shows examples of BRR settings in asynchronous mode. Table 13.4 shows examples of BRR settings in synchronous mode.

Table 13.3 Examples of Bit Rates and BRR Settings in Asynchronous Mode

φ (MHz) 2 2.097152 2.4576 3 Bit Rate Ν Error (%) n Ν Error (%) n Ν Error (%) n Ν Error (%) (bit/s) n 110 1 141 0.03 1 148 -0.04 1 174 - 0.261 212 0.03 103 0.16 127 0.00 150 1 1 108 0.21 1 1 155 0.16 77 300 0 207 0.16 0 217 0.21 0 255 0.00 1 0.16 600 0 103 0.16 0 108 0.21 0 127 0.00 0 155 0.16 1200 0 51 0.16 0 54 -0.700 63 0.00 0 77 0.16 0 2400 0 25 0.16 0 26 1.14 0 31 0.00 38 0.16 4800 0 12 0.16 0 13 -2.480 15 0.00 0 19 -2.349600 0 6 -6.990 6 -2.480 7 0.00 0 9 -2.3419200 0 2 8.51 0 2 13.78 0 3 0.00 0 4 -2.3431250 0 1 0.00 0 1 4.86 0 1 22.88 0 2 0.00 38400 0 1 -18.620 1 -14.670 1 0.00

		φ (MHz)													
Bit Rate		3.0	6864		4			4.9	9152	5					
(bit/s)	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)			
110	2	64	0.07	2	70	0.03	2	86	0.31	2	88	-0.25			
150	1	191	0.00	1	207	0.16	1	255	0.00	2	64	0.16			
300	1	95	0.00	1	103	0.16	1	127	0.00	1	129	0.16			
600	0	191	0.00	0	207	0.16	0	255	0.00	1	64	0.16			
1200	0	95	0.00	0	103	0.16	0	127	0.00	0	129	0.16			
2400	0	47	0.00	0	51	0.16	0	63	0.00	0	64	0.16			
4800	0	23	0.00	0	25	0.16	0	31	0.00	0	32	-1.36			
9600	0	11	0.00	0	12	0.16	0	15	0.00	0	15	1.73			
19200	0	5	0.00	0	6	-6.99	0	7	0.00	0	7	1.73			
31250	_	_	_	0	3	0.00	0	4	-1.70	0	4	0.00			
38400	0	2	0.00	0	2	8.51	0	3	0.00	0	3	1.73			

φ (MHz)

		6		6.	144		7.3	3728	8				
n	N	Error (%)	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)		
2	106	-0.44	2	108	0.08	2	130	-0.07	2	141	0.03		
2	77	0.16	2	79	0.00	2	95	0.00	2	103	0.16		
1	155	0.16	1	159	0.00	1	191	0.00	1	207	0.16		
1	77	0.16	1	79	0.00	1	95	0.00	1	103	0.16		
0	155	0.16	0	159	0.00	0	191	0.00	0	207	0.16		
0	77	0.16	0	79	0.00	0	95	0.00	0	103	0.16		
0	38	0.16	0	39	0.00	0	47	0.00	0	51	0.16		
0	19	-2.34	0	19	0.00	0	23	0.00	0	25	0.16		
0	9	-2.34	0	9	0.00	0	11	0.00	0	12	0.16		
0	5	0.00	0	5	2.40	0	6	5.33	0	7	0.00		
0	4	-2.34	0	4	0.00	0	5	0.00	0	6	-6.99		
	2 2 1 1 0 0 0 0 0	n N 2 106 2 77 1 155 1 77 0 155 0 77 0 38 0 19 0 9 0 5	2 106 -0.44 2 77 0.16 1 155 0.16 1 77 0.16 0 155 0.16 0 77 0.16 0 38 0.16 0 19 -2.34 0 9 -2.34 0 5 0.00	n N Error (%) n 2 106 -0.44 2 2 77 0.16 2 1 155 0.16 1 1 77 0.16 0 0 77 0.16 0 0 38 0.16 0 0 19 -2.34 0 0 5 0.00 0	n N Error (%) n N 2 106 -0.44 2 108 2 77 0.16 2 79 1 155 0.16 1 159 1 77 0.16 0 159 0 77 0.16 0 79 0 38 0.16 0 39 0 19 -2.34 0 19 0 5 0.00 0 5	n N Error (%) n N Error (%) 2 106 -0.44 2 108 0.08 2 77 0.16 2 79 0.00 1 155 0.16 1 159 0.00 0 155 0.16 0 159 0.00 0 77 0.16 0 79 0.00 0 38 0.16 0 39 0.00 0 19 -2.34 0 19 0.00 0 9 -2.34 0 9 0.00 0 5 0.00 0 5 2.40	n N Error (%) n N Error (%) n 2 106 -0.44 2 108 0.08 2 2 77 0.16 2 79 0.00 2 1 155 0.16 1 159 0.00 1 1 77 0.16 1 79 0.00 0 0 77 0.16 0 79 0.00 0 0 38 0.16 0 39 0.00 0 0 19 -2.34 0 19 0.00 0 0 9 -2.34 0 9 0.00 0 0 5 0.00 0 5 2.40 0	n N Error (%) n N Error (%) n N 2 106 -0.44 2 108 0.08 2 130 2 77 0.16 2 79 0.00 2 95 1 155 0.16 1 159 0.00 1 191 1 77 0.16 1 79 0.00 0 191 0 77 0.16 0 79 0.00 0 95 0 38 0.16 0 39 0.00 0 47 0 19 -2.34 0 19 0.00 0 23 0 9 -2.34 0 9 0.00 0 11 0 5 0.00 0 5 2.40 0 6	n N Error (%) n N Error (%) n N Error (%) 2 106 -0.44 2 108 0.08 2 130 -0.07 2 77 0.16 2 79 0.00 2 95 0.00 1 155 0.16 1 159 0.00 1 191 0.00 0 155 0.16 0 159 0.00 0 191 0.00 0 77 0.16 0 79 0.00 0 95 0.00 0 38 0.16 0 39 0.00 0 47 0.00 0 19 -2.34 0 19 0.00 0 23 0.00 0 5 0.00 0 5 2.40 0 6 5.33	n N Error (%) n N Error (%) n N Error (%) n 2 106 -0.44 2 108 0.08 2 130 -0.07 2 2 77 0.16 2 79 0.00 2 95 0.00 2 1 155 0.16 1 159 0.00 1 191 0.00 1 0 155 0.16 0 159 0.00 0 191 0.00 0 0 77 0.16 0 79 0.00 0 95 0.00 0 0 38 0.16 0 39 0.00 0 47 0.00 0 0 19 -2.34 0 19 0.00 0 23 0.00 0 0 9 -2.34 0 9 0.00 0 11 0.00 0 0	n N Error (%) n N Error (%) n N Error (%) n N 2 106 -0.44 2 108 0.08 2 130 -0.07 2 141 2 77 0.16 2 79 0.00 2 95 0.00 2 103 1 155 0.16 1 159 0.00 1 191 0.00 1 207 1 77 0.16 1 79 0.00 1 195 0.00 1 103 0 155 0.16 0 159 0.00 0 191 0.00 0 207 0 77 0.16 0 79 0.00 0 95 0.00 0 103 0 38 0.16 0 39 0.00 0 47 0.00 0 25 0 9 -2.34 0		

φ	(N	ЛΙ	4,	٠1
w		,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	14	

Bit Rate		9.8	3304	10				•	12	12.288			
(bit/s)	n N		Error (%)	n	n N Erro		n N		Error (%)	n	N	Error (%)	
110	2	174	-0.26	2	177	-0.25	2	212	0.03	2	217	0.08	
150	2	127	0.00	2	129	0.16	2	155	0.16	2	159	0.00	
300	1	255	0.00	2	64	0.16	2	77	0.16	2	79	0.00	
600	1	127	0.00	1	129	0.16	1	155	0.16	1	159	0.00	
1200	0	255	0.00	1	64	0.16	1	77	0.16	1	79	0.00	
2400	0	127	0.00	0	129	0.16	0	155	0.16	0	159	0.00	
4800	0	63	0.00	0	64	0.16	0	77	0.16	0	79	0.00	
9600	0	31	0.00	0	32	-1.36	0	38	0.16	0	39	0.00	
19200	0	15	0.00	0	15	1.73	0	19	-2.34	0	19	0.00	
31250	0	9	-1.70	0	9	0.00	0	11	0.00	0	11	2.40	
38400	0	7	0.00	0	7	1.73	0	9	-2.34	0	9	0.00	

φ (MHz)

Bit	13				14			14.7456			1	6		1	8	20		
Rate (bit/s)	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)
110	2	230	-0.08	2	248	-0.17	3	64	0.70	3	70	0.03	3	79	-0.12	3	88	-0.25
150	2	168	0.16	2	181	0.16	2	191	0.00	2	207	0.16	2	233	0.16	3	64	0.16
300	2	84	-0.43	2	90	0.16	2	95	0.00	2	103	0.16	2	116	0.16	2	129	0.16
600	1	168	0.16	1	181	0.16	1	191	0.00	1	207	0.16	1	233	0.16	2	64	0.16
1200	1	84	-0.43	1	90	0.16	1	95	0.00	1	103	0.16	1	116	0.16	1	129	0.16
2400	0	168	0.16	0	181	0.16	0	191	0.00	0	207	0.16	0	233	0.16	1	64	0.16
4800	0	84	-0.43	0	90	0.16	0	95	0.00	0	103	0.16	0	116	0.16	0	129	0.16
9600	0	41	0.76	0	45	-0.93	0	47	0.00	0	51	0.16	0	58	-0.69	0	64	0.16
19200	0	20	0.76	0	22	-0.93	0	23	0.00	0	25	0.16	0	28	1.02	0	32	-1.36
31250	0	12	0.00	0	13	0.00	0	14	-1.70	0	15	0.00	0	17	0.00	0	19	0.00
38400	0	10	-3.82	0	10	3.57	0	11	0.00	0	12	0.16	0	14	-2.34	0	15	1.73

Table 13.4 Examples of Bit Rates and BRR Settings in Synchronous Mode

D.,		ψ (ινιτιε)														
Bit Rate	2		4		8		10		13		16		18		20	
(bit/s)	n	N	n	N	n	N	n	N	n	N	n	N	n	N	n	N
110	3	70	_	_	_	_	_	_	_	_	_	_	_	_	_	_
250	2	124	2	249	3	124	_	_	3	202	3	249		_	_	_
500	1	249	2	124	2	249	_	_	3	101	3	124	3	140	3	155
1k	1	124	1	249	2	124	_	_	2	202	2	249	3	69	3	77
2.5k	0	199	1	99	1	199	1	249	2	80	2	99	2	112	2	124
5k	0	99	0	199	1	99	1	124	1	162	1	199	1	224	1	249
10k	0	49	0	99	0	199	0	249	1	80	1	99	1	112	1	124
25k	0	19	0	39	0	79	0	99	0	129	0	159	0	179	0	199
50k	0	9	0	19	0	39	0	49	0	64	0	79	0	89	0	99
100k	0	4	0	9	0	19	0	24	_	_	0	39	0	44	0	49
250k	0	1	0	3	0	7	0	9	0	12	0	15	0	17	0	19
500k	0	0*	0	1	0	3	0	4	_	_	0	7	0	8	0	9
1M			0	0*	0	1	_	_	_	_	0	3	0	4	0	4
2M					0	0*	_	_	_	_	0	1	_	_	_	_
2.5M					_	_	0	0*	_	_	_	_	_	_	_	_
4M											0	0*	_	_	_	_

φ (MHz)

Note: Settings with an error of 1% or less are recommended.

Legend

Blank: No setting available

—: Setting possible, but error occurs

*: Continuous transmission/reception not possible

SMR Settings

The BRR setting is calculated as follows:

Asynchronous mode:

$$N = \frac{\phi}{64 \times 2^{2n-1} \times B} \times 10^6 - 1$$

Synchronous mode:

$$N = \frac{\phi}{8 \times 2^{2n-1} \times B} \times 10^6 - 1$$

B: Bit rate (bit/s)

N: BRR setting for band rate generator $(0 \le N \le 255)$

φ: System clock frequency (MHz)

n: Baud rate generator clock source (n = 0, 1, 2, 3) (For the clock sources and values of n, see the following table.)

		Omit Octangs					
n	Clock Source	CKS1	CKS0				
0	ф	0	0				
1	φ/4	0	1				
2	φ/16	1	0				
3	φ/64	1	1				

The bit rate error in asynchronous mode is calculated as follows:

Error (%) =
$$\left\{ \frac{\phi \times 10^6}{(N+1) \times B \times 64 \times 2^{2n-1}} - 1 \right\} \times 100$$

Table 13.5 shows the maximum bit rates in asynchronous mode for various system clock frequencies. Table 13.6 and 13.7 shows the maximum bit rates with external clock input.

 Table 13.5
 Maximum Bit Rates for Various Frequencies (Asynchronous Mode)

		Settings		
φ (MHz)	Maximum Bit Rate (bit/s)	n	N	
2	62500	0	0	
2.097152	65536	0	0	
2.4576	76800	0	0	
3	93750	0	0	
3.6864	115200	0	0	
4	125000	0	0	
4.9152	153600	0	0	
5	156250	0	0	
6	187500	0	0	
6.144	192000	0	0	
7.3728	230400	0	0	
8	250000	0	0	
9.8304	307200	0	0	
10	312500	0	0	
12	375000	0	0	
12.288	384000	0	0	
14	437500	0	0	
14.7456	460800	0	0	
16	500000	0	0	
17.2032	537600	0	0	
18	562500	0	0	
20	625000	0	0	-

Table 13.6 Maximum Bit Rates with External Clock Input (Asynchronous Mode)

φ (MHz)	External Input Clock (MHz)	Maximum Bit Rate (bit/s)
2	0.5000	31250
2.097152	0.5243	32768
2.4576	0.6144	38400
3	0.7500	46875
3.6864	0.9216	57600
4	1.0000	62500
4.9152	1.2288	76800
5	1.2500	78125
6	1.5000	93750
6.144	1.5360	96000
7.3728	1.8432	115200
8	2.0000	125000
9.8304	2.4576	153600
10	2.5000	156250
12	3.0000	187500
12.288	3.0720	192000
14	3.5000	218750
14.7456	3.6864	230400
16	4.0000	250000
17.2032	4.3008	268800
18	4.5000	281250
20	5.0000	312500

 Table 13.7
 Maximum Bit Rates with External Clock Input (Synchronous Mode)

φ (MHz)	External Input Clock (MHz)	Maximum Bit Rate (bit/s)
2	0.3333	333333.3
4	0.6667	666666.7
6	1.0000	1000000.0
8	1.3333	1333333.3
10	1.6667	1666666.7
12	2.0000	2000000.0
14	2.3333	2333333.3
16	2.6667	2666666.7
18	3.0000	3000000.0
20	3.3333	333333333

13.3 Operation

13.3.1 Overview

The SCI can carry out serial communication in two modes: asynchronous mode in which synchronization is achieved character by character, and synchronous mode in which synchronization is achieved with clock pulses. A smart card interface is also supported as a serial communication function for an IC card interface.

Selection of asynchronous or synchronous mode and the transmission format for the normal serial communication interface is made in SMR, as shown in table 13.8. The SCI clock source is selected by the C/\overline{A} bit in SMR and the CKE1 and CKE0 bits in SCR, as shown in table 13.9.

For details of the procedures for switching between LSB-first and MSB-first mode and inverting the data logic level, see section 14.2.1, Smart Card Mode Register (SCMR).

For selection of the smart card interface format, see section 14.3.3, Data Format.

Asynchronous Mode

- Data length is selectable: 7 or 8 bits
- Parity and multiprocessor bits are selectable, and so is the stop bit length (1 or 2 bits). These selections determine the communication format and character length.
- In receiving, it is possible to detect framing errors, parity errors, overrun errors, and the break state.
- An internal or external clock can be selected as the SCI clock source.
 - When an internal clock is selected, the SCI operates using the on-chip baud rate generator, and can output a serial clock signal with a frequency matching the bit rate.
 - When an external clock is selected, the external clock input must have a frequency 16 times the bit rate. (The on-chip baud rate generator is not used.)

Synchronous Mode

- The communication format has a fixed 8-bit data length.
- In receiving, it is possible to detect overrun errors.
- An internal or external clock can be selected as the SCI clock source.
 - When an internal clock is selected, the SCI operates using the on-chip baud rate generator, and can output a serial clock signal to external devices.
 - When an external clock is selected, the SCI operates on the input serial clock. The on-chip baud rate generator is not used.

Smart Card Interface

- One frame consists of 8-bit data and a parity bit.
- In transmitting, a guard time of at least two elementary time units (2 etu) is provided between the end of the parity bit and the start of he next frame. (An elementary time unit is the time required to transmit one bit.)
- In receiving, if a parity error is detected, a low error signal level is output for 1 etu, beginning 10.5 etu after the start bit..
- In transmitting, if an error signal is received, the same data is automatically transmitted again after at least 2 etu.
- Only asynchronous communication is supported. There is no synchronous communication function.

For details of smart card interface operation, see section 14, Smart Card Interface.

Table 13.8 SMR Settings and Serial Communication Formats

	SM	R Setti	ngs			SCI Communication Format			
Bit 7 C/Ā	Bit 6 CHR	Bit 2 MP	Bit 5 PE	Bit 3 STOP	Mode	Data Length	Multi- processor Bit	Parity Bit	Stop Bit Length
0	0	0	0	0	AsynChronous	8-bit data	Absent	Absent	1 bit
				1	mode				2 bits
			1	0	•			Present	1 bit
				1	•				2 bits
	1	=	0	0	-	7-bit data	_	Absent	1 bit
				1	•				2 bits
			1	0	-			Present	1 bit
				1	-				2 bits
	0	1		0	Asynchronous	8-bit data	Present	Absent	1 bit
			_	1	mode (multi- processor				2 bits
	1	=	_	0	format)	7-bit data	_		1 bit
			_	1	•				2 bits
1	_	_	_	_	Synchronous mode	8-bit data	Absent	_	None

Table 13.9 SMR and SCR Settings and SCI Clock Source Selection

SMR	SCR S	Setting		SCI Transmit/Receive clock			
Bit 7 C/Ā	Bit 1 CKE1	Bit 0 CKE0	Mode	Clock Source	SCK Pin Function		
0 0	0	0	Asynchronous	Internal	SCI does not use the SCK pin		
		1	mode		Outputs clock with frequency matching the bit rate		
	1	0		External	Inputs clock with frequency 16 times the bit		
		1			rate		
1	0	0	Synchronous	Internal	Outputs the serial clock		
		1	mode				
	1	0		External	Inputs the serial clock		
		1					

13.3.2 Operation in Asynchronous Mode

In asynchronous mode, each transmitted or received character begins with a start bit and ends with one or two stop bits. Serial communication is synchronized one character at a time.

The transmitting and receiving sections of the SCI are independent, so full-duplex communication is possible. The transmitter and the receiver are both double-buffered, so data can be written and read while transmitting and receiving are in progress, enabling continuous transmitting and receiving.

Figure 13.2 shows the general format of asynchronous serial communication. In asynchronous serial communication the communication line is normally held in the mark (high) state. The SCI monitors the line and starts serial communication when the line goes to the space (low) state, indicating a start bit. One serial character consists of a start bit (low), data (LSB first), parity bit (high or low), and one or two stop bits (high), in that order.

When receiving in asynchronous mode, the SCI synchronizes at the falling edge of the start bit. The SCI samples each data bit on the eighth pulse of a clock with a frequency 16 times the bit rate. Receive data is latched at the center of each bit.

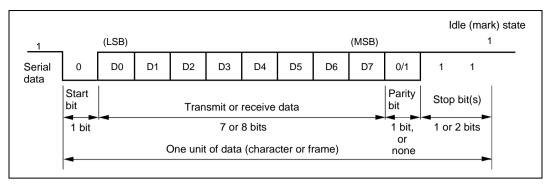


Figure 13.2 Data Format in Asynchronous Communication (Example: 8-Bit Data with Parity and 2 Stop Bits)

Communication Formats: Table 13.10 shows the 12 communication formats that can be selected in asynchronous mode. The format is selected by settings in SMR.



Table 13.10 Serial Communication Formats (Asynchronous Mode)

	SMR S	ettings		Serial Communication Format and Frame Length				
CHR	PE	MP	STOP	1 2 3 4 5 6 7 8 9 10 11 12				
0	0	0	0	S 8-bit data STOP				
0	0	0	1	S 8-bit data STOP STOP				
0	1	0	0	S 8-bit data P STOP				
0	1	0	1	S 8-bit data P STOP STOP				
1	0	0	0	S 7-bit data STOP				
1	0	0	1	S 7-bit data STOP STOP				
1	1	0	0	S 7-bit data P STOP				
1	1	0	1	S 7-bit data P STOP STOP				
0	_	1	0	S 8-bit data MPB STOP				
0	_	1	1	S 8-bit data MPB STOP STOP				
1	_	1	0	S 7-bit data MPB STOP				
1	_	1	1	S 7-bit data MPB STOP STOP				

Legend

S: Start bit STOP: Stop bit P: Parity bit

MPB: Multiprocessor bit

Clock: An internal clock generated by the on-chip baud rate generator or an external clock input from the SCK pin can be selected as the SCI transmit/receive clock. The clock source is selected by the C/\overline{A} bit in SMR and bits CKE1 and CKE0 in SCR. For details of SCI clock source selection, see table 13.9.

When an external clock is input at the SCK pin, it must have a frequency 16 times the desired bit rate.

When the SCI is operated on an internal clock, it can output a clock signal at the SCK pin. The frequency of this output clock is equal to the bit rate. The phase is aligned as shown in figure 13.3 so that the rising edge of the clock occurs at the center of each transmit data bit.

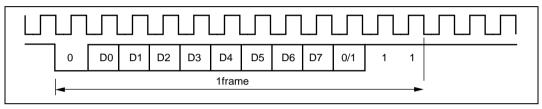


Figure 13.3 Phase Relationship between Output Clock and Serial Data (Asynchronous Mode)

Transmitting and Receiving Data:

• SCI Initialization (Asynchronous Mode): Before transmitting or receiving data, clear the TE and RE bits to 0 in SCR, then initialize the SCI as follows.

When changing the communication mode or format, always clear the TE and RE bits to 0 before following the procedure given below. Clearing TE to 0 sets the TDRE flag to 1 and initializes TSR. Clearing RE to 0, however, does not initialize the RDRF, PER, FER, and ORER flags, or RDR, which retain their previous contents.

When an external clock is used the clock should not be stopped during initialization or subsequent operation, since operation will be unreliable in this case.

Figure 13.4 shows a sample flowchart for initializing the SCI.

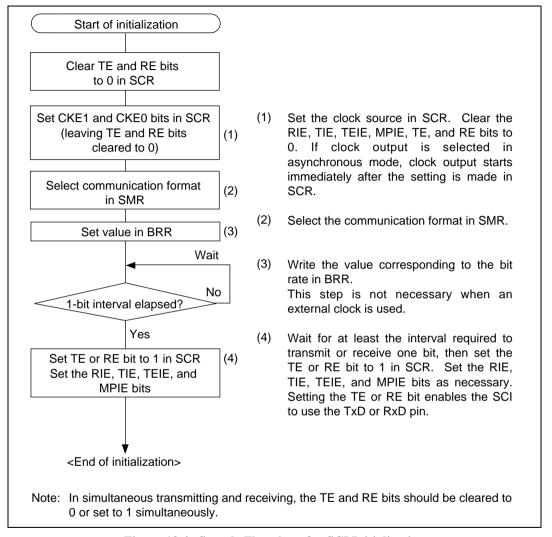


Figure 13.4 Sample Flowchart for SCI Initialization

 Transmitting Serial Data (Asynchronous Mode): Figure 13.5 shows a sample flowchart for transmitting serial data and indicates the procedure to follow.

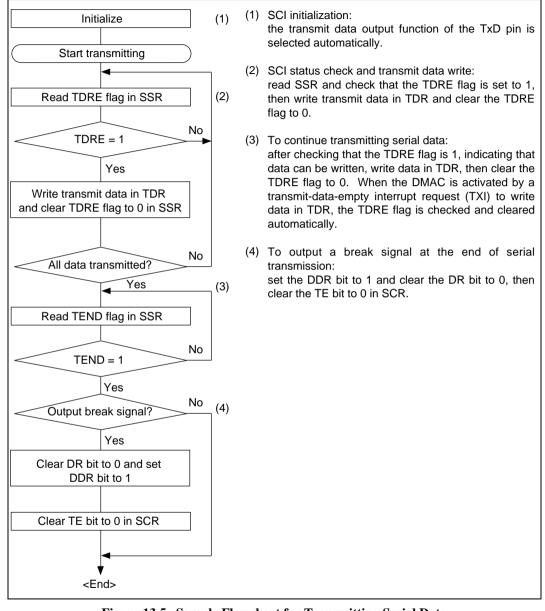


Figure 13.5 Sample Flowchart for Transmitting Serial Data

In transmitting serial data, the SCI operates as follows:

- The SCI monitors the TDRE flag in SSR. When the TDRE flag is cleared to 0, the SCI recognizes that TDR contains new data, and loads this data from TDR into TSR.
- After loading the data from TDR to TSR, the SCI sets the TDRE flag to 1 and starts transmitting. If the TIE bit is set to 1 in SCR, the SCI requests a transmit-data-empty interrupt (TXI) at this time.

Serial transmit data is transmitted in the following order from the TxD pin:

- Start bit: One 0 bit is output.
- Transmit data: 7 or 8 bits are output, LSB first.
- Parity bit or multiprocessor bit: One parity bit (even or odd parity), or one multiprocessor bit is output. Formats in which neither a parity bit nor a multiprocessor bit is output can also be selected.
- Stop bit(s): One or two 1 bits (stop bits) are output.
- Mark state: Output of 1 bits continues until the start bit of the next transmit data.
- The SCI checks the TDRE flag when it outputs the stop bit. If the TDRE flag is 0, the SCI loads new data from TDR into TSR, outputs the stop bit, then begins serial transmission of the next frame. If the TDRE flag is 1, the SCI sets the TEND flag to 1 in SSR, outputs the stop bit, then continues output of 1 bits in the mark state. If the TEIE bit is set to 1 in SCR, a transmitend interrupt (TEI) is requested at this time

Figure 13.6 shows an example of SCI transmit operation in asynchronous mode.

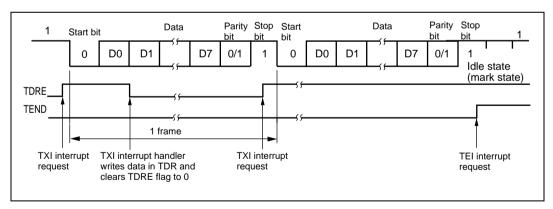


Figure 13.6 Example of SCI Transmit Operation in Asynchronous Mode (8-Bit Data with Parity and One Stop Bit)

 Receiving Serial Data (Asynchronous Mode): Figure 13.7 shows a sample flowchart for receiving serial data and indicates the procedure to follow.

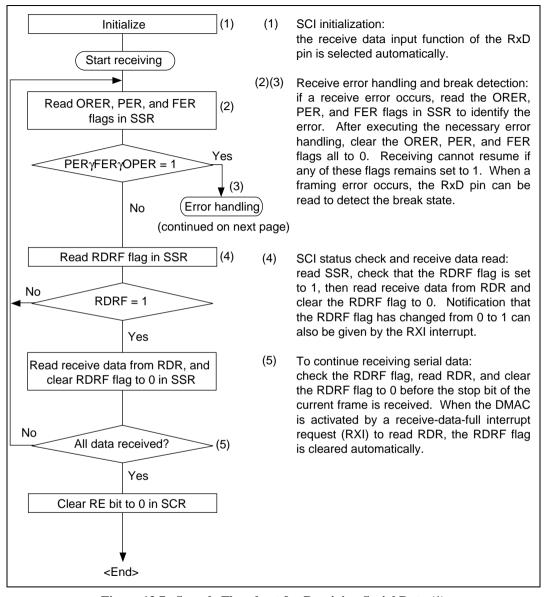


Figure 13.7 Sample Flowchart for Receiving Serial Data (1)

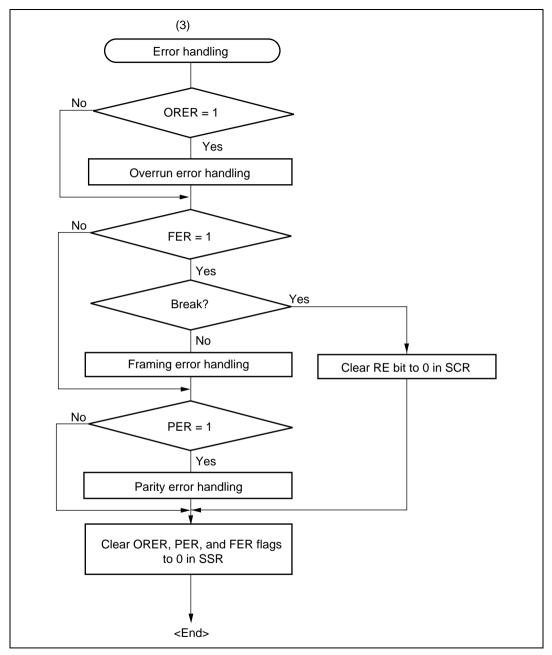


Figure 13.7 Sample Flowchart for Receiving Serial Data (2)

In receiving, the SCI operates as follows:

- The SCI monitors the communication line. When it detects a start bit (0 bit), the SCI synchronizes internally and starts receiving.
- Receive data is stored in RSR in order from LSB to MSB.
- The parity bit and stop bit are received.

After receiving these bits, the SCI carries out the following checks:

- Parity check: The number of 1s in the receive data must match the even or odd parity setting of in the O/\overline{E} bit in SMR.
- Stop bit check: The stop bit value must be 1. If there are two stop bits, only the first is checked.
- Status check: The RDRF flag must be 0, indicating that the receive data can be transferred from RSR into RDR.

If these all checks pass, the RDRF flag is set to 1 and the received data is stored in RDR. If one of the checks fails (receive error*), the SCI operates as shown in table 13.11.

Note: * When a receive error occurs, further receiving is disabled. In receiving, the RDRF flag is not set to 1. Be sure to clear the error flags to 0.

• When the RDRF flag is set to 1, if the RIE bit is set to 1 in SCR, a receive-data-full interrupt (RXI) is requested. If the ORER, PER, or FER flag is set to 1 and the RIE bit in SCR is also set to 1, a receive-error interrupt (ERI) is requested.

Table 13.11 Receive Error Conditions

Receive Error	Abbreviation	Condition	Data Transfer
Overrun error	ORER	Receiving of next data ends while RDRF flag is still set to 1 in SSR	
Framing error	FER	Stop bit is 0	Receive data is transferred from RSR to RDR
Parity error	PER	Parity of received data differs from even/odd parity setting in SMR	

Figure 13.8 shows an example of SCI receive operation in asynchronous mode.

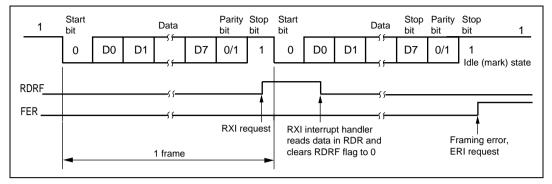


Figure 13.8 Example of SCI Receive Operation (8-Bit Data with Parity and One Stop Bit)

13.3.3 Multiprocessor Communication

The multiprocessor communication function enables several processors to share a single serial communication line. The processors communicate in asynchronous mode using a format with an additional multiprocessor bit (multiprocessor format).

In multiprocessor communication, each receiving processor is addressed by an ID. A serial communication cycle consists of an ID-sending cycle that identifies the receiving processor, and a data-sending cycle. The multiprocessor bit distinguishes ID-sending cycles from data-sending cycles.

The transmitting processor stars by sending the ID of the receiving processor with which it wants to communicate as data with the multiprocessor bit set to 1. Next the transmitting processor sends transmit data with the multiprocessor bit cleared to 0.

Receiving processors skip incoming data until they receive data with the multiprocessor bit set to 1. When they receive data with the multiprocessor bit set to 1, receiving processors compare the data with their IDs. Processors with IDs not matching the received data skip further incoming data until they again receive data with the multiprocessor bit set to 1. Multiple processors can send and receive data in this way.

Figure 13.9 shows an example of communication among different processors using a multiprocessor format.

Communication Formats: Four formats are available. Parity bit settings are ignored when a multiprocessor format is selected. For details see table 13.10.

Clock: See the description of asynchronous mode.

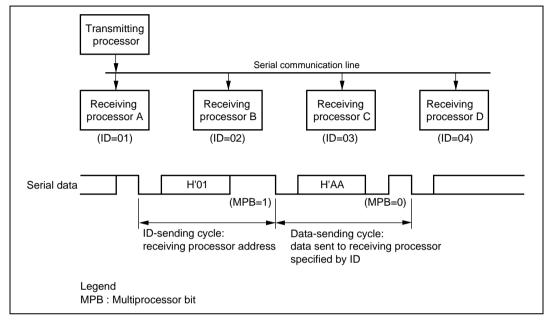
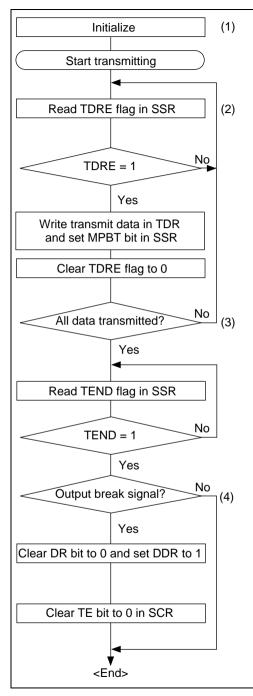


Figure 13.9 Example of Communication among Processors using Multiprocessor Format (Sending Data H'AA to Receiving Processor A)

Transmitting and Receiving Data:

 Transmitting Multiprocessor Serial Data: Figure 13.10 shows a sample flowchart for transmitting multiprocessor serial data and indicates the procedure to follow.



- SCI initialization: the transmit data output function of the TxD pin is selected automatically.
- (2) SCI status check and transmit data write: read SSR, check that the TDRE flag is 1, then write transmit data in TDR. Also set the MPBT flag to 0 or 1 in SSR. Finally, clear the TDRE flag to 0.
- (3) To continue transmitting serial data: after checking that the TDRE flag is 1, indicating that data can be written, write data in TDR, then clear the TDRE flag to 0. When the DMAC is activated by a transmit-dataempty interrupt request (TXI) to write data in TDR, the TDRE flag is checked and cleared automatically.
- (4) To output a break signal at the end of serial transmission: set the DDR bit to 1 and clear the DR bit to 0, then clear the TE bit to 0 in SCR.

Figure 13.10 Sample Flowchart for Transmitting Multiprocessor Serial Data

In transmitting serial data, the SCI operates as follows:

- The SCI monitors the TDRE flag in SSR. When the TDRE flag is cleared to 0, the SCI recognizes that TDR contains new data, and loads this data from TDR into TSR.
- After loading the data from TDR to TSR, the SCI sets the TDRE flag to 1 and starts transmitting. If the TIE bit is set to 1 in SCR, the SCI requests a transmit-data-empty interrupt (TXI) at this time.

Serial transmit data is transmitted in the following order from the TxD pin:

- Start bit: One 0 bit is output.
- Transmit data: 7 or 8 bits are output, LSB first.
- Multiprocessor bit: One multiprocessor bit (MPBT value) is output.
- Stop bit(s): One or two 1 bits (stop bits) are output.
- Mark state: Output of 1 bits continues until the start bit of the next transmit data.
- The SCI checks the TDRE flag when it outputs the stop bit. If the TDRE flag is 0, the SCI loads new data from TDR into TSR, outputs the stop bit, then begins serial transmission of the next frame. If the TDRE flag is 1, the SCI sets the TEND flag to 1 in SSR, outputs the stop bit, then continues output of 1 bits in the mark state. If the TEIE bit is set to 1 in SCR, a transmitend interrupt (TEI) is requested at this time

Figure 13.11 shows an example of SCI transmit operation using a multiprocessor format.

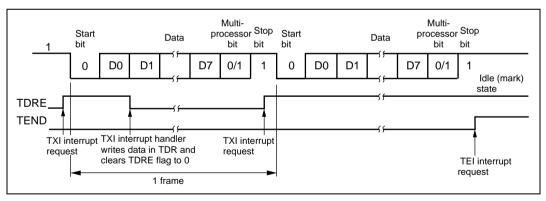


Figure 13.11 Example of SCI Transmit Operation (8-Bit Data with Multiprocessor Bit and One Stop Bit)

 Receiving Multiprocessor Serial Data: Figure 13.12 shows a sample flowchart for receiving multiprocessor serial data and indicates the procedure to follow.

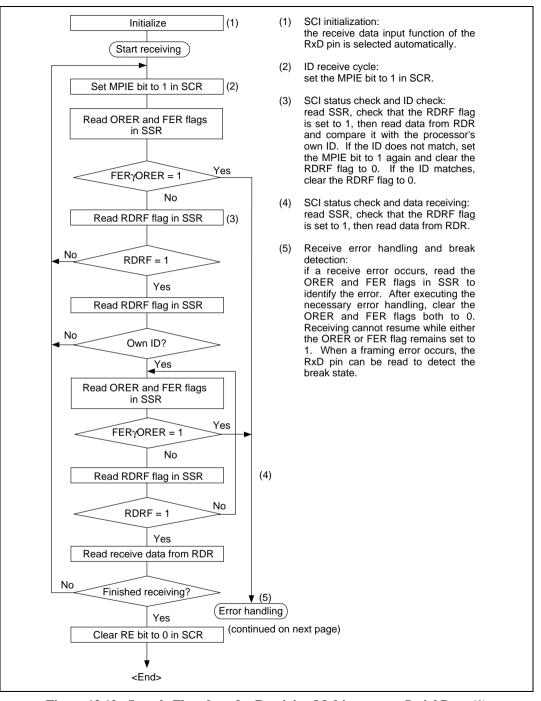


Figure 13.12 Sample Flowchart for Receiving Multiprocessor Serial Data (1)

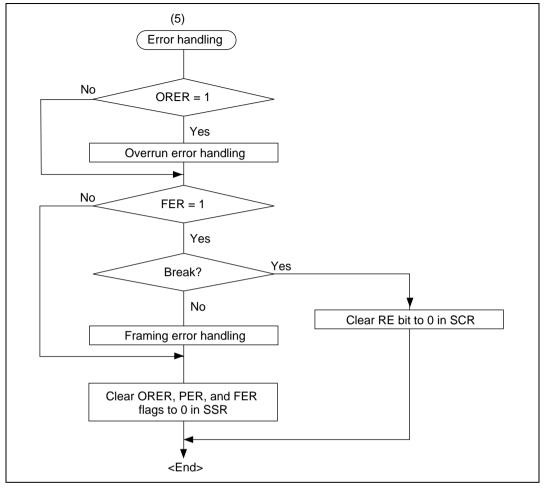


Figure 13.12 Sample Flowchart for Receiving Multiprocessor Serial Data (2)

Figure 13.13 shows an example of SCI receive operation using a multiprocessor format.

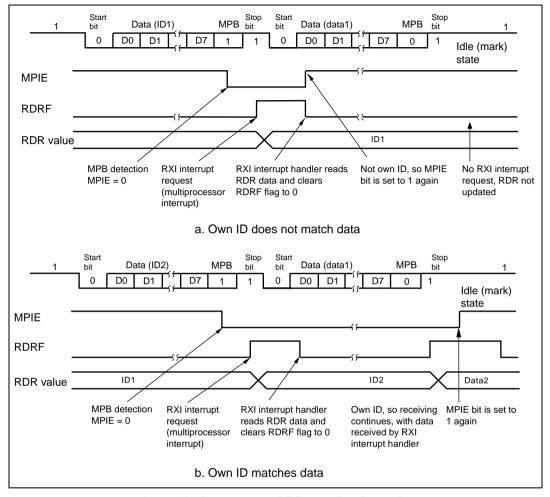


Figure 13.13 Example of SCI Receive Operation (8-Bit Data with Multiprocessor Bit and One Stop Bit)

13.3.4 Synchronous Operation

In synchronous mode, the SCI transmits and receives data in synchronization with clock pulses. This mode is suitable for high-speed serial communication.

The SCI transmitter and receiver share the same clock but are otherwise independent, so full-duplex communication is possible. The transmitter and the receiver are also double-buffered, so continuous transmitting or receiving is possible by reading or writing data while transmitting or receiving is in progress.

Figure 13.14 shows the general format in synchronous serial communication.

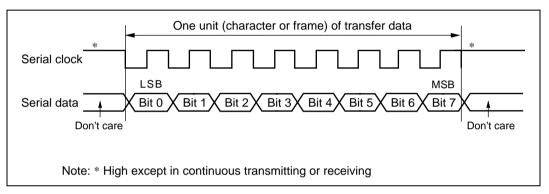


Figure 13.14 Data Format in Synchronous Communication

In synchronous serial communication, each data bit is placed on the communication line from one falling edge of the serial clock to the next. Data is guaranteed valid at the rise of the serial clock. In each character, the serial data bits are transferred in order from LSB (first) to MSB (last). After output of the MSB, the communication line remains in the state of the MSB. In synchronous mode the SCI receives data by synchronizing with the rise of the serial clock.

Communication Format: The data length is fixed at 8 bits. No parity bit or multiprocessor bit can be added.

Clock: An internal clock generated by the on-chip baud rate generator or an external clock input from the SCK pin can be selected by means of the C/\overline{A} bit in SMR and the CKE1 and CKE0 bits in SCR. See table 13.6 for details of SCI clock source selection.

When the SCI operates on an internal clock, it outputs the clock source at the SCK pin. Eight clock pulses are output per transmitted or received character. When the SCI is not transmitting or receiving, the clock signal remains in the high state. If receiving in single-character units is required, an external clock should be selected.

Transmitting and Receiving Data:

• SCI Initialization (Synchronous Mode): Before transmitting or receiving data, clear the TE and RE bits to 0 in SCR, then initialize the SCI as follows.

When changing the communication mode or format, always clear the TE and RE bits to 0 before following the procedure given below. Clearing TE to 0 sets the TDRE flag to 1 and initializes TSR. Note that clearing RE to 0, however, does not initialize the RDRF, PER, and ORE flags, or RDR, which retain their previous contents.

Figure 13.15 shows a sample flowchart for initializing the SCI.

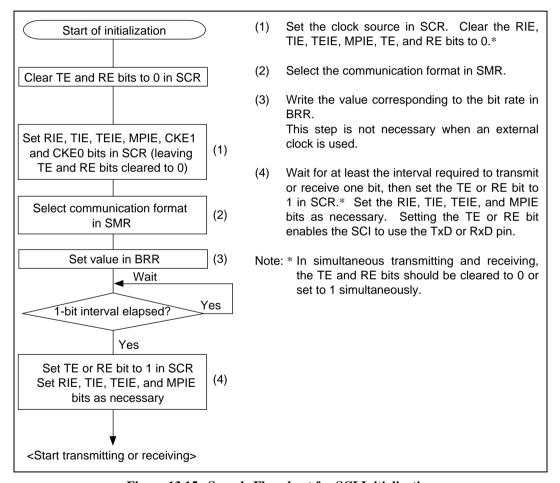
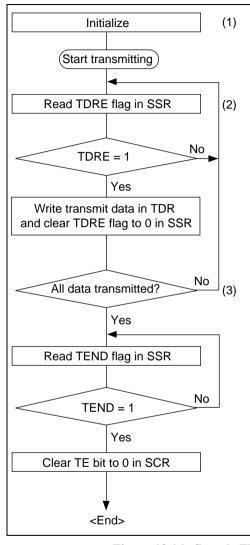


Figure 13.15 Sample Flowchart for SCI Initialization

• Transmitting Serial Data (Synchronous Mode): Figure 13.16 shows a sample flowchart for transmitting serial data and indicates the procedure to follow.



- (1) SCI initialization: the transmit data output function of the TxD pin is selected automatically.
- (2) SCI status check and transmit data write: read SSR, check that the TDRE flag is 1, then write transmit data in TDR and clear the TDRE flag to 0.
- (3) To continue transmitting serial data: after checking that the TDRE flag is 1, indicating that data can be written, write data in TDR, then clear the TDRE flag to 0. When the DMAC is activated by a transmit-data-empty interrupt request (TXI) to write data in TDR, the TDRE flag is checked and cleared automatically.

Figure 13.16 Sample Flowchart for Serial Transmitting

In transmitting serial data, the SCI operates as follows.

- The SCI monitors the TDRE flag in SSR. When the TDRE flag is cleared to 0, the SCI recognizes that TDR contains new data, and loads this data from TDR into TSR.
- After loading the data from TDR to TSR, the SCI sets the TDRE flag to 1 and starts transmitting. If the TIE bit is set to 1 in SCR, the SCI requests a transmit-data-empty interrupt (TXI) at this time.
 - If clock output is selected, the SCI outputs eight serial clock pulses. If an external clock source is selected, the SCI outputs data in synchronization with the input clock. Data is output from the TxD pin n order from LSB (bit 0) to MSB (bit 7).
- The SCI checks the TDRE flag when it outputs the MSB (bit 7). If the TDRE flag is 0, the SCI loads data from TDR into TSR and begins serial transmission of the next frame. If the TDRE flag is 1, the SCI sets the TEND flag to 1 in SSR, and after transmitting the MSB (bit 7), holds the TxD pin in the MSB state. If the TEIE bit is set to 1 in SCR, a transmit-end interrupt (TEI) is requested at this time
- After the end of serial transmission, the SCK pin is held in a constant state.

Figure 13.17 shows an example of SCI transmit operation.

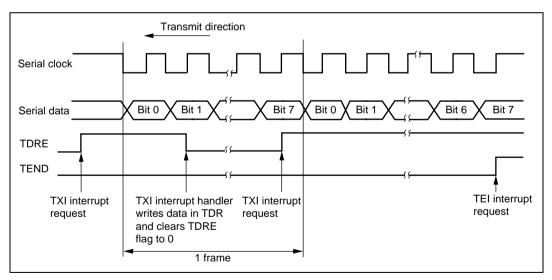


Figure 13.17 Example of SCI Transmit Operation

Receiving Serial Data (Synchronous Mode): Figure 13.18 shows a sample flowchart for
receiving serial data and indicates the procedure to follow. When switching from asynchronous
to synchronous mode. make sure that the ORER, PER, and FER flags are cleared to 0. If the
FER or PER flag is set to 1 the RDRF flag will not be set and both transmitting and receiving
will be disabled.

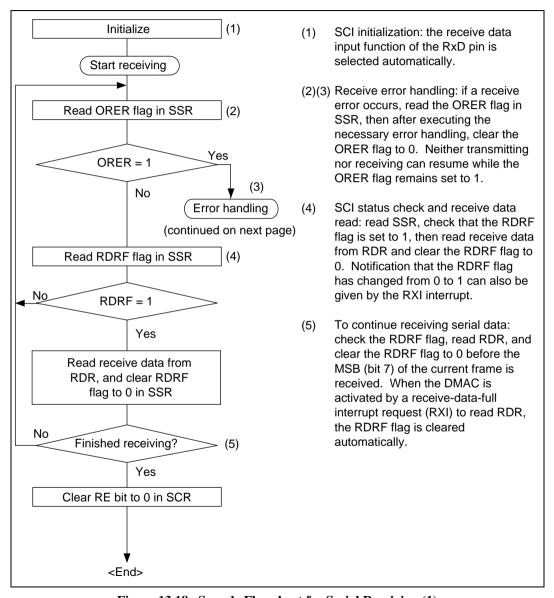


Figure 13.18 Sample Flowchart for Serial Receiving (1)

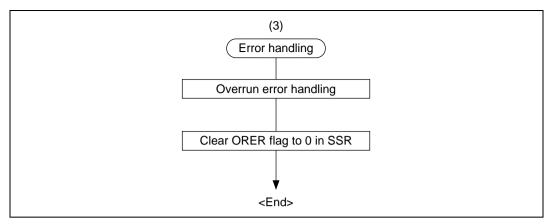


Figure 13.18 Sample Flowchart for Serial Receiving (2)

In receiving, the SCI operates as follows:

- The SCI synchronizes with serial clock input or output and synchronizes internally.
- Receive data is stored in RSR in order from LSB to MSB.

After receiving the data, the SCI checks that the RDRF flag is 0, so that receive data can be transferred from RSR to RDR. If this check passes, the RDRF flag is set to 1 and the received data is stored in RDR. If the checks fails (receive error), the SCI operates as shown in table 13.11.

When a receive error has been identified in the error check, subsequent transmit and receive operations are disabled.

When the RDRF flag is set to 1, if the RIE bit is set to 1 in SCR, a receive-data-full interrupt
(RXI) is requested. If the ORER flag is set to 1 and the RIE bit in SCR is also set to 1, a
receive-error interrupt (ERI) is requested.

Figure 13.19 shows an example of SCI receive operation.

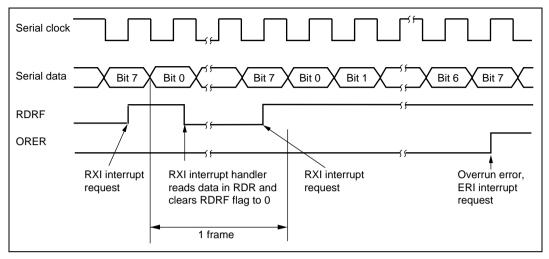


Figure 13.19 Example of SCI Receive Operation

• Transmitting and Receiving Data Simultaneously (Synchronous Mode): Figure 13.20 shows a sample flowchart for transmitting and receiving serial data simultaneously and indicates the procedure to follow.

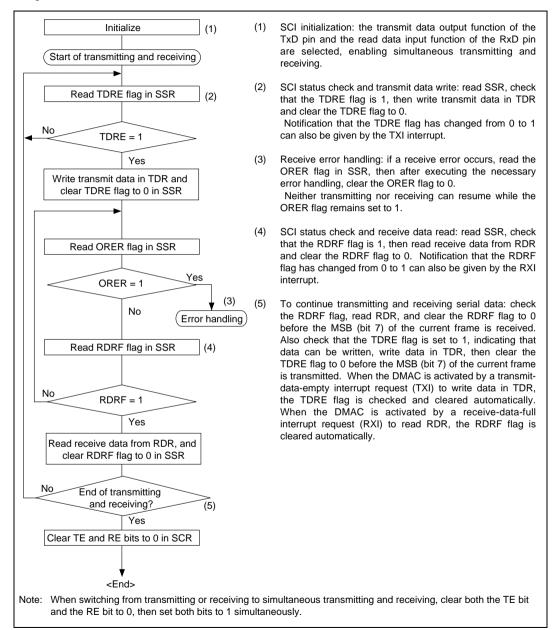


Figure 13.20 Sample Flowchart for Simultaneous Serial Transmitting and Receiving

13.4 SCI Interrupts

The SCI has four interrupt request sources: the transmit-end interrupt (TEI), receive-error interrupt (ERI), receive-data-full interrupt (RXI), and transmit-data-empty interrupt (TXI). Table 13.12 lists the interrupt sources and indicates their priority. These interrupts can be enabled or disabled by the TIE, RIE, and TEIE bits in SCR. Each interrupt request is sent separately to the interrupt controller

A TXI interrupt is requested when the TDRE flag is set to 1 in SSR. A TEI interrupt is requested when the TEND flag is set to 1 in SSR. A TXI interrupt request can activate the DMAC to transfer data. Data transfer by the DMAC automatically clears the TDRE flag to 0. A TEI interrupt request cannot activate the DMAC.

An RXI interrupt is requested when the RDRF flag is set to 1 in SSR. An ERI interrupt is requested when the ORER, PER, or FER flag is set to 1 in SSR. An RXI interrupt can activate the DMAC to transfer data. Data transfer by the DMAC automatically clears the RDRF flag to 0. An ERI interrupt request cannot activate the DMAC.

The DMAC can be activated by interrupts from SCI channel 0.

Table 13.12 SCI Interrupt Sources

Interrupt Source	Description	Priority
ERI	Receive error (ORER, FER, or PER)	High
RXI	Receive data register full (RDRF)	
TXI	Transmit data register empty (TDRE)	
TEI	Transmit end (TEND)	Low

13.5 Usage Notes

SCD Status Flags

13.5.1 Notes on Use of SCI

Note the following points when using the SCI.

TDR Write and TDRE Flag: The TDRE flag in SSR is a status flag indicating the loading of transmit data from TDR to TSR. The SCI sets the TDRE flag to 1 when it transfers data from TDR to TSR.

Data can be written into TDR regardless of the state of the TDRE flag. If new data is written in TDR when the TDRE flag is 0, the old data stored in TDR will be lost because this data has not yet been transferred to TSR. Before writing transmit data in TDR, be sure to check that the TDRE flag is set to 1.

Simultaneous Multiple Receive Errors: Table 13.13 shows the state of the SSR status flags when multiple receive errors occur simultaneously. When an overrun error occurs the RSR contents are not transferred to RDR, so receive data is lost.

Table 13.13 SSR Status Flags and Transfer of Receive Data

SOK SIG	atus riags	•		Receive Data Trans	sier
RDRF	ORER	FER	PER	RSR → RDR	Receive Errors
1	1	0	0	×	Overrun error
0	0	1	0	0	Framing error
0	0	0	1	0	Parity error
1	1	1	0	×	Overrun error + framing error
1	1	0	1	×	Overrun error + parity error
0	0	1	1	0	Framing error + parity error
1	1	1	1	×	Overrun error + framing error + parity error

Pacaiva Data Transfor

Notes: O: Receive data is transferred from RSR to RDR.

×: Receive data is not transferred from RSR to RDR.

Break Detection and Processing: Break signals can be detected by reading the RxD pin directly when a framing error (FER) is detected. In the break state the input from the RxD pin consists of all 0s, so the FER flag is set and the parity error flag (PER) may also be set. In the break state the SCI receiver continues to operate, so if the FER flag is cleared to 0 it will be set to 1 again.

Sending a Break Signal: The input/output condition and level of the TxD pin are determined by DR and DDR bits. This feature can be used to send a break signal.

After the serial transmitter is initialized, the DR value substitutes for the mark state until the TE bit is set to 1 (the TxD pin function is not selected until the TE bit is set to 1). The DDR and DR bits should therefore be set to 1 beforehand.

To send a break signal during serial transmission, clear the DR bit to 0, then clear the TE bit to 0. When the TE bit is cleared to 0 the transmitter is initialized, regardless of its current state, so the TxD pin becomes an input/output outputting the value 0.

Receive Error Flags and Transmitter Operation (Synchronous Mode Only): When a receive error flag (ORER, PER, or FER) is set to 1 the SCI will not start transmitting, even if the TDRE flag is cleared to 0. Be sure to clear the receive error flags to 0 when starting to transmit. Note that clearing the RE bit to 0 does not clear the receive error flags to 0.

Receive Data Sampling Timing in Asynchronous Mode and Receive Margin: In asynchronous mode the SCI operates on a base clock with 16 times the bit rate frequency. In receiving, the SCI synchronizes internally with the fall of the start bit, which it samples on the base clock. Receive data is latched at the rising edge of the eighth base clock pulse. See figure 13.21.

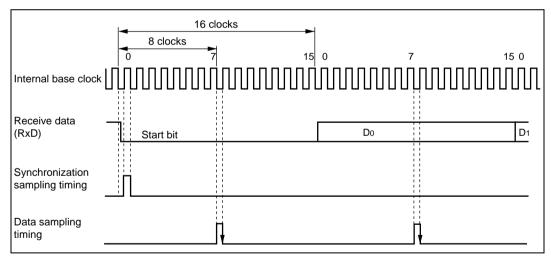


Figure 13.21 Receive Data Sampling Timing in Asynchronous Mode

The receive margin in asynchronous mode can therefore be expressed as shown in equation (1).

$$M = \left| (0.5 - \frac{1}{2N}) - (L - 0.5) F - \frac{|D - 0.5|}{N} (1 + F) \right| \times 100\%$$
.....(1)

M: Receive margin (%)

N: Ratio of clock frequency to bit rate (N = 16)

D: Clock duty cycle (L = 0 to 1.0)

L: Frame length (L = 9 to 12)

F: Absolute deviation of clock frequency

From equation (1), if F = 0 and D = 0.5, the receive margin is 46.875%, as given by equation (2).

This is a theoretical value. A reasonable margin to allow in system designs is 20% to 30%.

Restrictions on Use of DMAC:

- When an external clock source is used for the serial clock, after the DMAC updates TDR, allow an inversion of at least five system clock (φ) cycles before input of the serial clock to start transmitting. If the serial clock is input within four states of the TDR update, a malfunction may occur. (See figure 13.22)
- To have the DMAC read RDR, be sure to select the corresponding SCI receive-data-full interrupt (RXI) as the activation source with bits DTS2 to DTS0 in DTCR.

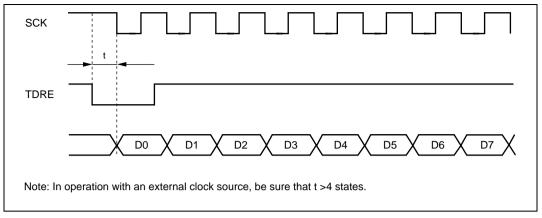
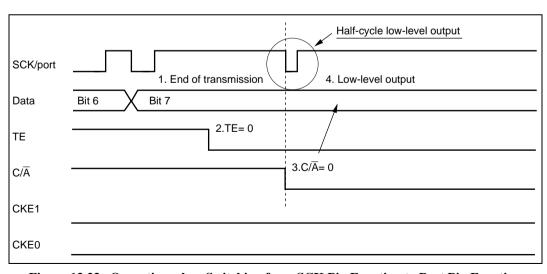


Figure 13.22 Example of Synchronous Transmission Using DMAC

Switching from SCK Pin Function to Port Pin Function:

- Problem in Operation: When switching the SCK pin function to the output port function (high-level output) by making the following settings while DDR = 1, DR = 1, C/A = 1, CKE1 = 0, CKE0 = 0, and TE = 1 (synchronous mode), low-level output occurs for one half-cycle.
- 1. End of serial data transmission
- 2. TE bit = 0
- 3. C/\overline{A} bit = 0 ... switchover to port output
- 4. Occurrence of low-level output (see figure 13.23)



Figure~13.23~~Operation~when~Switching~from~SCK~Pin~Function~to~Port~Pin~Function

• Sample Procedure for Avoiding Low-Level Output: As this sample procedure temporarily places the SCK pin in the input state, the SCK/port pin should be pulled up beforehand with an external circuit.

With DDR = 1, DR = 1, C/\overline{A} = 1, CKE1 = 0, CKE0 = 0, and TE = 1, make the following settings in the order shown.

- 1. End of serial data transmission
- 2. TE bit = 0
- 3. CKE1 bit = 1
- 4. C/\overline{A} bit = 0 ... switchover to port output
- 5. CKE1 bit = 0

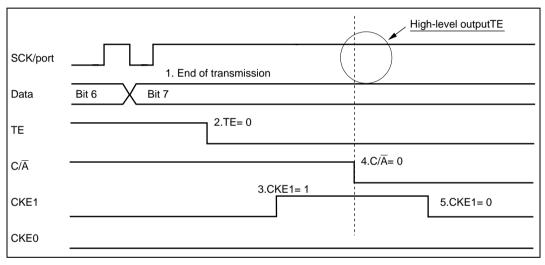


Figure 13.24 Operation when Switching from SCK Pin Function to Port Pin Function (Example of Preventing Low-Level Output)

Section 14 Smart Card Interface

14.1 Overview

An IC card (smart card) interface conforming to the ISO/IEC 7816-3 (Identification Card) standard is supported as an extension of the serial communication interface (SCI) functions.

Switchover between the normal serial communication interface and the smart card interface is controlled by a register setting.

14.1.1 Features

Features of the smart card interface supported by the H8/3067 Group are listed below.

- Asynchronous communication
 - Data length: 8 bits
 - Parity bit generation and checking
 - Transmission of error signal (parity error) in receive mode
 - Error signal detection and automatic data retransmission in transmit mode
 - Direct convention and inverse convention both supported
- Built-in baud rate generator allows any bit rate to be selected
- Three interrupt sources
 - There are three interrupt sources—transmit-data-empty, receive-data-full, and transmit/receive error—that can issue requests independently.
 - The transmit-data-empty interrupt and receive-data-full interrupt can activate the DMA controller (DMAC) to execute data transfer.

14.1.2 Block Diagram

Figure 14.1 shows a block diagram of the smart card interface.

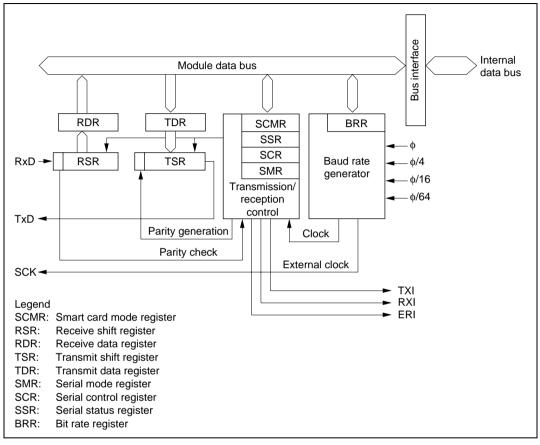


Figure 14.1 Block Diagram of Smart Card Interface

14.1.3 Pin Configuration

Table 14.1 shows the smart card interface pins.

Table 14.1 Smart Card Interface Pins

Pin Name	Abbreviation	I/O	Function
Serial clock pin	SCK	I/O	Clock input/output
Receive data pin	RxD	Input	Receive data input
Transmit data pin	TxD	Output	Transmit data output

14.1.4 Register Configuration

The smart card interface has the internal registers listed in table 14.2. The BRR, TDR, and RDR registers have their normal serial communication interface functions, as described in section 13, Serial Communication Interface.

Table 14.2 Smart Card Interface Registers

Channel	Address*1	Name	Abbreviation	R/W	Initial Value
0	H'FFFB0	Serial mode register	SMR	R/W	H'00
	H'FFFB1	Bit rate register	BRR	R/W	H'FF
	H'FFFB2	Serial control register	SCR	R/W	H'00
	H'FFFB3	Transmit data register	TDR	R/W	H'FF
	H'FFFB4	Serial status register	SSR	R/(W)*2	H'84
	H'FFFB5	Receive data register	RDR	R	H'00
	H'FFFB6	Smart card mode register	SCMR	R/W	H'F2
1	H'FFFB8	Serial mode register	SMR	R/W	H'00
	H'FFFB9	Bit rate register	BRR	R/W	H'FF
	H'FFFBA	Serial control register	SCR	R/W	H'00
	H'FFFBB	Transmit data register	TDR	R/W	H'FF
	H'FFFBC	Serial status register	SSR	R/(W)*2	H'84
	H'FFFBD	Receive data register	RDR	R	H'00
	H'FFFBE	Smart card mode register	SCMR	R/W	H'F2
2	H'FFFC0	Serial mode register	SMR	R/W	H'00
	H'FFFC1	Bit rate register	BRR	R/W	H'FF
	H'FFFC2	Serial control register	SCR	R/W	H'00
	H'FFFC3	Transmit data register	TDR	R/W	H'FF
	H'FFFC4	Serial status register	SSR	R/(W)*2	H'84
	H'FFFC5	Receive data register	RDR	R	H'00
	H'FFFC6	Smart card mode register	SCMR	R/W	H'F2

Notes: 1. Lower 20 bits of the address in advanced mode.

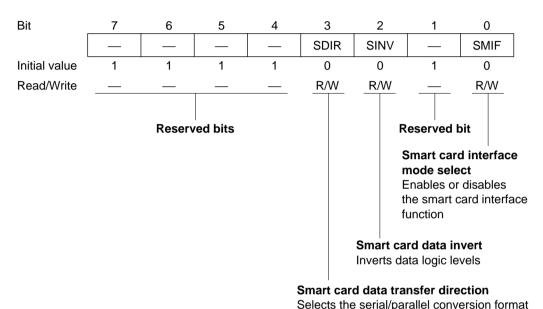
2. Only 0 can be written in bits 7 to 3, to clear the flags.

14.2 Register Descriptions

This section describes the new or modified registers and bit functions in the smart card interface.

14.2.1 Smart Card Mode Register (SCMR)

SCMR is an 8-bit readable/writable register that selects smart card interface functions.



SCMR is initialized to H'F2 by a reset and in standby mode.

Bits 7 to 4—Reserved: Read-only bits, always read as 1.

Bit 3—Smart Card Data Transfer Direction (SDIR): Selects the serial/parallel conversion format.*

Bit 3 SDIR	Description	
0	TDR contents are transmitted LSB-first	(Initial value)
	Receive data is stored LSB-first in RDR	
1	TDR contents are transmitted MSB-first	
	Receive data is stored MSB-first in RDR	

Bit 2—Smart Card Data Invert (SINV): Specifies inversion of the data logic level. This function is used in combination with the SDIR bit to communicate with inverse-convention cards.* The SINV bit does not affect the logic level of the parity bit. For parity settings, see section 14.3.4, Register Settings.

Bit 2 SINV	Description	
0	Unmodified TDR contents are transmitted	(Initial value)
	Receive data is stored unmodified in RDR	
1	Inverted TDR contents are transmitted	
	Receive data is inverted before storage in RDR	

Bit 1—Reserved: Read-only bit, always read as 1.

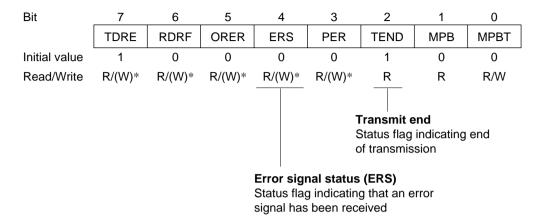
Bit 0—Smart Card Interface Mode Select (SMIF): Enables the smart card interface function.

Bit 0 SMIF	Description	
0	Smart card interface function is disabled	(Initial value)
1	Smart card interface function is enabled	

- Notes: 1. The function for switching between LSB-first and MSB-first mode can also be used with the normal serial communication interface. Note that when the communication format data length is set to 7 bits and MSB-first mode is selected for the serial data to be transferred, bit 0 of TDR is not transmitted, and only bits 7 to 1 of the received data are valid.
 - 2. The data logic level inversion function can also be used with the normal serial communication interface. Note that, when inverting the serial data to be transferred, parity transmission and parity checking is based on the number of high-level periods at the serial data I/O pin, and not on the register value.

14.2.2 Serial Status Register (SSR)

The function of SSR bit 4 is modified in smart card interface mode. This change also causes a modification to the setting conditions for bit 2 (TEND).



Note: * Only 0 can be written, to clear the flag.

Bits 7 to 5: These bits operate as in normal serial communication. For details see section 13.2.7, Serial Status Register (SSR).

Bit 4—Error Signal Status (ERS): In smart card interface mode, this flag indicates the status of the error signal sent from the receiving device to the transmitting device. The smart card interface does not detection framing errors.

Bit 4		
ERS	Description	
0	Indicates normal transmission, with no error signal returned (Ini	tial value)
	[Clearing conditions]	
	The chip is reset, or enters standby mode or module stop mode	
	Software reads ERS while it is set to 1, then writes 0.	
1	Indicates that the receiving device sent an error signal reporting a parity error	r
	[Setting condition]	
	A low error signal was sampled.	
Note:	Clearing the TE bit to 0 in SCR does not affect the ERS flag, which retains its pre	vious

Note: Clearing the TE bit to 0 in SCR does not affect the ERS flag, which retains its previous value.

Bits 3 to 0: These bits operate as in normal serial communication. For details see section 13.2.7, Serial Status Register (SSR). The setting conditions for transmit end (TEND), however, are modified as follows.

Bit 2		
TEND	Description	
0	Transmission is in progress	
	[Clearing conditions]	
	Software reads TDRE while it is set to 1, then writes 0 in the TDRE flag.	
	The DMAC or DTC writes data in TDR.	
1	End of transmission	
	[Setting conditions]	(Initial value)
	The chip is reset or enters standby mode.	
	The TE bit and FER/ERS bit are both cleared to 0 in SCR.	
	TDRE is 1 and FER/ERS is 0 at a time 2.5 etu after the last bit of a 1-byt character is transmitted (normal transmission).	e serial

Note: An etu (elementary time unit) is the time needed to transmit one bit.

14.2.3 Serial Mode Register (SMR)

The function of SMR bit 7 is modified in smart card interface mode. This change also causes a modification to the function of bits 1 and 0 in the serial control register (SCR).

Bit	7	6	5	4	3	2	1	0
	GM	CHR	PE	O/E	STOP	MP	CKS1	CKS0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Bit 7—GSM Mode (GM): With the normal smart card interface, this bit is cleared to 0. Setting this bit to 1 selects GSM mode, an additional mode for controlling the timing for setting the TEND flag that indicates completion of transmission, and the type of clock output used. The details of the additional clock output control mode are specified by the CKE1 and CKE0 bits in the serial control register (SCR).

Bit 7		
GM	Description	
0	Normal smart card interface mode operation	
	The TEND flag is set 12.5 etu after the beginning of the start bit.	
	Clock output on/off control only.	(Initial value)
1	GSM mode smart card interface mode operation	
	The TEND flag is set 11.0 etu after the beginning of the start bit.	
	Clock output on/off and fixed-high/fixed-low control.	

Bits 6 to 0: These bits operate as in normal serial communication. For details see section 13.2.5, Serial Mode Register (SMR).

14.2.4 Serial Control Register (SCR)

The function of SCR bits 1 and 0 is modified in smart card interface mode

Bit	7	6	5	4	3	2	1	0
	TIE	RIE	TE	RE	MPIE	TEIE	CKE1	CKE0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Bits 7 to 2: These bits operate as in normal serial communication. For details see section 13.2.6, Serial Control Register (SCR).

Bits 1 and 0—Clock Enable 1 and 0 (CKE1, CKE0): These bits select the SCI clock source and enable or disable clock output from the SCK pin. In smart card interface mode, it is possible to specify a fixed high level or fixed low level for the clock output, in addition to the usual switching between enabling and disabling of the clock output.

Bit 7 GM	Bit 1 CKE1	Bit 0 CKE0	Description	
0	0	0	Internal clock/SCK pin is I/O port	(Initial value)
		1	Internal clock/SCK pin is clock output	
1	_	0	Internal clock/SCK pin is fixed at low output	
		1	Internal clock/SCK pin is clock output	
	1	0	Internal clock/SCK pin is fixed at high output	
		1	Internal clock/SCK pin is clock output	

14.3 Operation

14.3.1 Overview

The main features of the smart card interface are as follows.

- One frame consists of 8-bit data plus a parity bit.
- In transmission, a guard time of at least 2 etu (elementary time units: the time for transfer of one bit) is provided between the end of the parity bit and the start of the next frame.
- If a parity error is detected during reception, a low error signal level is output for a1 etu period 10.5 etu after the start bit.
- If an error signal is detected during transmission, the same data is transmitted automatically after the elapse of 2 etu or longer.
- Only asynchronous communication is supported; there is no synchronous communication function.

14.3.2 Pin Connections

Figure 14.2 shows a pin connection diagram for the smart card interface.

In communication with a smart card, since both transmission and reception are carried out on a single data transmission line, the TxD pin and RxD pin should both be connected to this line. The data transmission line should be pulled up to $V_{\rm CC}$ with a resistor.

When the smart card uses the clock generated on the smart card interface, the SCK pin output is input to the CLK pin of the smart card. If the smart card uses an internal clock, this connection is unnecessary.

The reset signal should be output from one of the H8/3067 Group's generic ports.

In addition to these pin connections, power and ground connections will normally also be necessary.

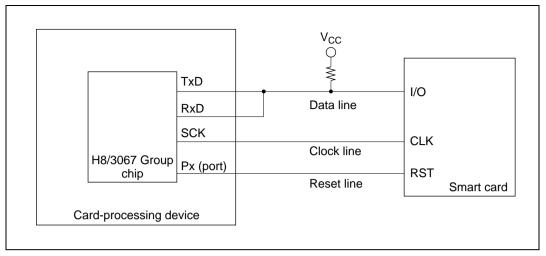


Figure 14.2 Smart Card Interface Connection Diagram

Note: A loop-back test can be performed by setting both RE and TE to 1 without connecting a smart card.

14.3.3 Data Format

Figure 14.3 shows the smart card interface data format. In reception in this mode, a parity check is carried out on each frame, and if an error is detected an error signal is sent back to the transmitting device to request retransmission of the data. In transmission, the error signal is sampled and the same data is retransmitted if the error signal is low.

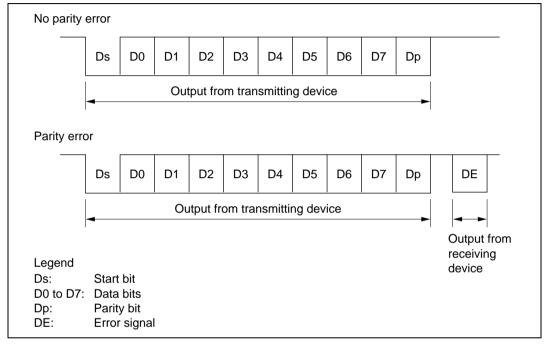


Figure 14.3 Smart Card Interface Data Format

The operating sequence is as follows.

- 1. When the data line is not in use it is in the high-impedance state, and is fixed high with a pull-up resistor.
- 2. The transmitting device starts transfer of one frame of data. The data frame starts with a start bit (Ds, low-level), followed by 8 data bits (D0 to D7) and a parity bit (Dp).
- 3. With the smart card interface, the data line then returns to the high-impedance state. The data line is pulled high with a pull-up resistor.
- 4. The receiving device carries out a parity check. If there is no parity error and the data is received normally, the receiving device waits for reception of the next data. If a parity error occurs, however, the receiving device outputs an error signal (DE, low-level) to request retransmission of the data. After outputting the error signal for the prescribed length of time,

- the receiving device places the signal line in the high-impedance state again. The signal line is pulled high again by a pull-up resistor.
- 5. If the transmitting device does not receive an error signal, it proceeds to transmit the next data frame. If it receives an error signal, however, it returns to step 2 and transmits the same data again.

14.3.4 Register Settings

Table 14.3 shows a bit map of the registers used in the smart card interface. Bits indicated as 0 or 1 must be set to the value shown. The setting of other bits is described in this section.

Table 14.3 Smart Card Interface Register Settings

						Bit			
Register	Address*1	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
SMR	H'FFFB0	GM	0	1	O/E	1	0	CKS1	CKS0
BRR	H'FFFB1	BRR7	BRR6	BRR5	BRR4	BRR3	BRR2	BRR1	BRR0
SCR	H'FFFB2	TIE	RIE	TE	RE	0	0	CKE1*2	CKE0
TDR	H'FFFB3	TDR7	TDR6	TDR5	TDR4	TDR3	TDR2	TDR1	TDR0
SSR	H'FFFB4	TDRE	RDRF	ORER	ERS	PER	TEND	0	0
RDR	H'FFFB5	RDR7	RDR6	RDR5	RDR4	RDR3	RDR2	RDR1	RDR0
SCMR	H'FFFB6	_	_	_	_	SDIR	SINV	_	SMIF

Notes: — Unused bit.

- 1. Lower 20 bits of the address in advanced mode.
- 2. When GM is cleared to 0 in SMR, the CKE1 bit must also be cleared to 0.

Serial Mode Register (SMR) Settings: Clear the GM bit to 0 when using the normal smart card interface mode, or set to 1 when using GSM mode. Clear the O/\overline{E} bit to 0 if the smart card is of the direct convention type, or set to 1 if of the inverse convention type.

Bits CKS1 and CKS0 select the clock source of the built-in baud rate generator. See section 14.3.5, Clock.

Bit Rate Register (BRR) Settings: BRR is used to set the bit rate. See section 14.3.5, Clock, for the method of calculating the value to be set.

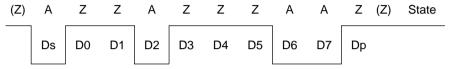
Serial Control Register (SCR) Settings: The TIE, RIE, TE, and RE bits have their normal serial communication functions. See section 13, Serial Communication Interface, for details. The CKE1 and CKE0 bits specify clock output. To disable clock output, clear these bits to 00; to enable clock

output, set these bits to 01. Clock output is not performed when the GM bit is set to 1 in SMR. Clock output can also be fixed low or high.

Smart Card Mode Register (SCMR) Settings: Clear both the SDIR bit and SINV bit cleared to 0 if the smart card is of the direct convention type, and set both to 1 if of the inverse convention type. To use the smart card interface, set the SMIF bit to 1.

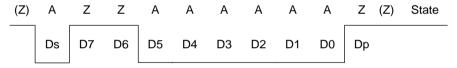
The register settings and examples of starting character waveforms are shown below for two smart cards, one following the direct convention and one the inverse convention.

1. Direct Convention (SDIR = SINV = $O/\overline{E} = 0$)



With the direct convention type, the logic 0 level corresponds to state Z and the logic 1 level to state A, and transfer is performed in LSB-first order. In the example above, the first character data is H'3B. The parity bit is 1, following the even parity rule designated for smart cards.

2. Indirect Convention (SDIR = SINV = $O/\overline{E} = 1$)



With the indirect convention type, the logic 1 level corresponds to state Z and the logic 0 level to state A, and transfer is performed in MSB-first order. In the example above, the first character data is H'3F. The parity bit is 0, corresponding to state Z, following the even parity rule designated for smart cards.

In the H8/3067 Group, inversion specified by the SINV bit applies only to the data bits, D7 to D0. For parity bit inversion, the O/E bit in SMR must be set to odd parity mode. This applies to both transmission and reception.

14.3.5 Clock

Only an internal clock generated by the on-chip baud rate generator can be used as the transmit/receive clock for the smart card interface. The bit rate is set with the bit rate register (BRR) and the CKS1 and CKS0 bits in the serial mode register (SMR). The equation for calculating the bit rate is shown below. Table 14.5 shows some sample bit rates.

If clock output is selected with CKE0 set to 1, a clock with a frequency of 372 times the bit rate is output from the SCK pin.

$$B = \frac{\phi}{1488 \times 2^{2n-1} \times (N+1)} \times 10^{6}$$

where, N: BRR setting $(0 \le N \le 255)$

B: Bit rate (bit/s)

Operating frequency (MHz)

n: See table 14.4

Table 14.4 n-Values of CKS1 and CKS0 Settings

n	CKS1	CKS0
0	0	0
1	_	1
2	1	0
3	-	1

Note: If the gear function is used to divide the clock frequency, use the divided frequency to calculate the bit rate. The equation above applies directly to 1/1 frequency division.

Table 14.5 Bit Rates (bits/s) for Various BRR Settings (When n = 0)

	φ (MHz)						
N	7.1424	10.00	10.7136	13.00	14.2848	16.00	18.00
0	9600.0	13440.9	14400.0	17473.1	19200.0	21505.4	24193.5
1	4800.0	6720.4	7200.0	8736.6	9600.0	10752.7	12096.8
2	3200.0	4480.3	4800.0	5824.4	6400.0	7168.5	8064.5

Note: Bit rates are rounded off to one decimal place.

The following equation calculates the bit rate register (BRR) setting from the operating frequency and bit rate. N is an integer from 0 to 255, specifying the value with the smaller error.

$$N = \frac{\phi}{1488 \times 2^{2n-1} \times B} \times 10^6 - 1$$

Table 14.6 BRR Settings for Typical Bit Rates (bits/s) (When n = 0)

							φ	(MHz)						
	7.1424 10.00 10.7136 13.00 1				14.2848		16.00		18.00					
bit/s	N	Error	N	Error	N	Error	N	Error	N	Error	N	Error	N	Error
9600	0	0.00	1	30	1	25	1	8.99	1	0.00	1	12.01	2	15.99

Table 14.7 Maximum Bit Rates for Various Frequencies (Smart Card Interface Mode)

φ (MHz)	Maximum Bit Rate (bits/s)	N	n	
7.1424	9600	0	0	
10.00	13441	0	0	
10.7136	14400	0	0	
13.00	17473	0	0	
14.2848	19200	0	0	
16.00	21505	0	0	
18.00	24194	0	0	

The bit rate error is given by the following equation:

Error (%) =
$$\left(\frac{\phi}{1488 \times 2^{2n-1} \times B \times (N+1)} \times 10^6 - 1\right) \times 100$$

14.3.6 Transmitting and Receiving Data

Initialization: Before transmitting or receiving data, the smart card interface must be initialized as described below. Initialization is also necessary when switching from transmit mode to receive mode, or vice versa.

- 1. Clear the TE and RE bits to 0 in the serial control register (SCR).
- 2. Clear error flags FER/ERS, PER, and ORER to 0 in the serial status register (SSR).
- 3. Set the parity bit (O/\overline{E}) and baud rate generator select bits (CKS1 and CKS0) in the serial mode register (SMR). Clear the C/\overline{A} , CHR, and MP bits to 0, and set the STOP and PE bits to 1.
- 4. Set the SMIF, SDIR, and SINV bits in the smart card mode register (SCMR).

When the SMIF bit is set to 1, the TxD pin and RxD pin are both switched from port to SCI pin functions and go to the high-impedance state.

- 5. Set a value corresponding to the desired bit rate in the bit rate register (BRR).
- 6. Set the CKE0 bit in SCR. Clear the TIE, RIE, TE, RE, MPIE, TEIE, and CKE1 bits to 0. If the CKE0 bit is set to 1, the clock is output from the SCK pin.
- 7. Wait at least one bit interval, then set the TIE, RIE, TE, and RE bits in SCR. Do not set the TE bit and RE bit at the same time, except for self-diagnosis.

Transmitting Serial Data: As data transmission in smart card mode involves error signal sampling and retransmission processing, the processing procedure is different from that for the normal SCI. Figure 14.5 shows a sample transmission processing flowchart.

- 1. Perform smart card interface mode initialization as described in Initialization above.
- 2. Check that the FER/ERS error flag is cleared to 0 in SSR.
- 3. Repeat steps 2 and 3 until it can be confirmed that the TEND flag is set to 1 in SSR.
- 4. Write the transmit data in TDR, clear the TDRE flag to 0, and perform the transmit operation. The TEND flag is cleared to 0.
- 5. To continue transmitting data, go back to step 2.
- 6. To end transmission, clear the TE bit to 0.

The above processing may include interrupt handling DMA transfer.

If transmission ends and the TEND flag is set to 1 while the TIE bit is set to 1 and interrupt requests are enabled, a transmit-data-empty interrupt (TXI) will be requested. If an error occurs in transmission and the ERS flag is set to 1 while the RIE bit is set to 1 and interrupt requests are enabled, a transmit/receive-error interrupt (ERI) will be requested.

The timing of TEND flag setting depends on the GM bit in SMR (see figure 14.4).



If the TXI interrupt activates the DMAC, the number of bytes designated in the DMAC can be transmitted automatically, including automatic retransmission.

For details, see Interrupt Operations and Data Transfer by DMAC in this section.

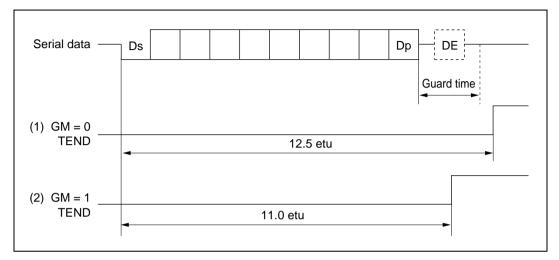


Figure 14.4 Timing of TEND Flag Setting

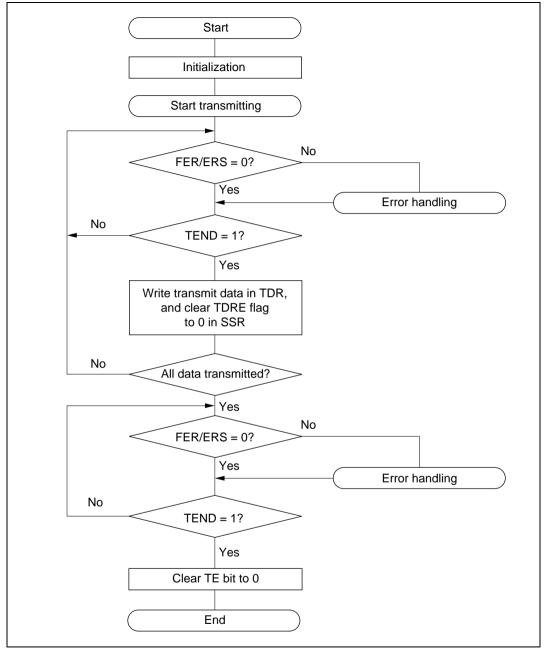


Figure 14.5 Sample Transmission Processing Flowchart

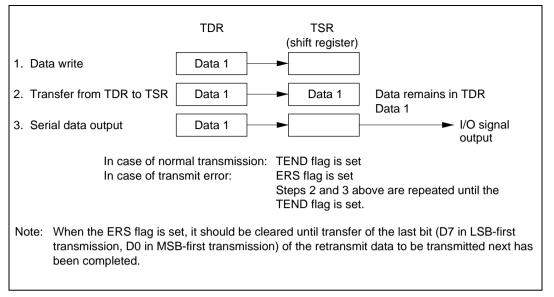


Figure 14.6 Relation Between Transmit Operation and Internal Registers

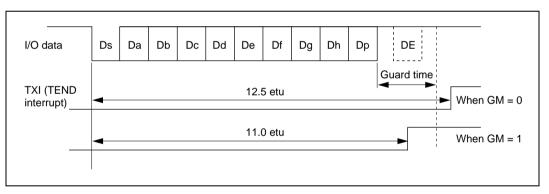


Figure 14.7 Timing of TEND Flag Setting

Receiving Serial Data: Data reception in smart card mode uses the same processing procedure as for the normal SCI. Figure 14.8 shows a sample reception processing flowchart.

- 1. Perform smart card interface mode initialization as described in Initialization above.
- 2. Check that the ORER flag and PER flag are cleared to 0 in SSR. If either is set, perform the appropriate receive error handling, then clear both the ORER and the PER flag to 0.
- 3. Repeat steps 2 and 3 until it can be confirmed that the RDRF flag is set to 1.
- 4. Read the receive data from RDR.
- 5. To continue receiving data, clear the RDRF flag to 0 and go back to step 2.

6. To end reception, clear the RE bit to 0.

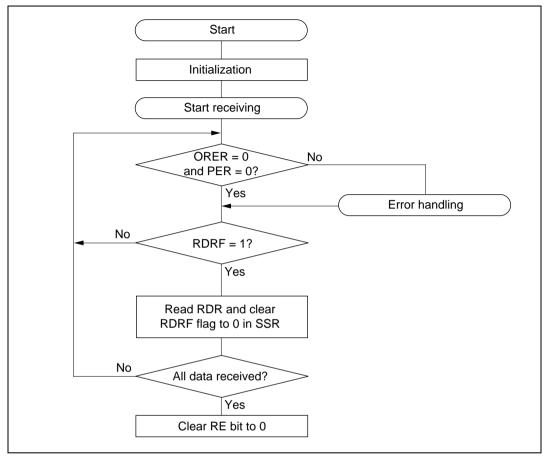


Figure 14.8 Sample Reception Processing Flowchart

The above procedure may include interrupt handling and DMA transfer.

If reception ends and the RDRF flag is set to 1 while the RIE bit is set to 1 and interrupt requests are enabled, a receive-data-full interrupt (RXI) will be requested. If an error occurs in reception and either the ORER flag or the PER flag is set to 1, a transmit/receive-error interrupt (ERI) will be requested.

If the RXI interrupt activates the DMAC, the number of bytes designated in the DMAC will be transferred, skipping receive data in which an error occurred.

For details, see Interrupt Operations and Data Transfer by DMAC in this section.



If a parity error occurs during reception and the PER flag is set to 1, the received data is transferred to RDR, so the erroneous data can be read.

Switching Modes: When switching from receive mode to transmit mode, first confirm that the receive operation has been completed, then start from initialization, clearing RE to 0 and setting TE to 1. The RDRF, PER, or ORER flag can be used to check that the receive operation has been completed.

When switching from transmit mode to receive mode, first confirm that the transmit operation has been completed, then start from initialization, clearing TE to 0 and setting RE to 1. The TEND flag can be used to check that the transmit operation has been completed.

Fixing Clock Output: When the GM bit is set to 1 in SMR, clock output can be fixed by means of the CKE1 and CKE0 bits in SCR. The minimum clock pulse width can be set to the specified width in this case.

Figure 14.9 shows the timing for fixing clock output. In this example, GM = 1, CKE1 = 0, and the CKE0 bit is controlled.

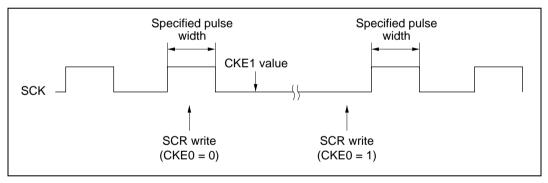


Figure 14.9 Timing for Fixing Cock Output

Interrupt Operations: The smart card interface has three interrupt sources: transmit-data-empty (TXI), transmit/receive-error (ERI), and receive-data-full (RXI). The transmit-end interrupt request (TEI) is not available in smart card mode.

A TXI interrupt is requested when the TEND flag is set to 1 in SSR. An RXI interrupt is requested when the RDRF flag is set to 1 in SSR. An ERI interrupt is requested when the ORER, PER, or ERS flag is set to 1 in SSR. These relationships are shown in table 14.8.

Table 14.8 Smart Card Interface Mode Operating States and Interrupt Sources

Operating State		Flag	Enable Bit	Interrupt Source	DMAC Activation
Transmit Mode	Normal operation	TEND	TIE	TXI	Available
	Error	ERS	RIE	ERI	Not available
Receive Mode	Normal operation	RDRF	RIE	RXI	Available
	Error	PER, ORER	RIE	ERI	Not available

Data Transfer by DMAC: The DMAC can be used to transmit and receive data in smart card mode, as in normal SCI operations. In transmit mode, when the TEND flag is set to 1 in SSR, the TDRE flag is set simultaneously, generating a TXI interrupt. If the TXI request is designated beforehand as a DMAC activation source, the DMAC will be activated by the TXI request and will transfer the next transmit data. This data transfer by the DMAC automatically clears the TDRE and TEND flags to 0. In the event of an error, the SCI automatically retransmits the same data, keeping the TEND flag cleared to 0 so that the DMAC is not activated. The SCI and DMAC will therefore automatically transmit the designated number of bytes, including retransmission when an error occurs. When an error occurs, the ERS flag is not cleared automatically, so the RIE bit should be set to 1 to enable the error to generate an ERI request, and the ERI interrupt handler should clear ERS.

When using the DMAC to transmit or receive, first set up and enable the DMAC, then make SCI settings. DMAC settings are described in section 7, DMA controller.

In receive operations, an RXI interrupt is requested when the RDRF flag is set to 1 in SSR. If the RXI request is designated beforehand as a DMAC activation source, the DMAC will be activated by the RXI request and will transfer the received data. This data transfer by the DMAC automatically clears the RDRF flag to 0. When an error occurs, the RDRF flag is not set and an error flag is set instead. The DMAC is not activated. The ERI interrupt request is directed to the CPU. The ERI interrupt handler should clear the error flags.

Examples of Operation in GSM Mode: When switching between smart card interface mode and software standby mode, use the following procedures to maintain the clock duty cycle.

- Switching from smart card interface mode to software standby mode
- 1. Set the P9₄ data register (DR) and data direction register (DDR) to the values for the fixed output state in software standby mode.
- 2. Write 0 in the TE and RE bits in the serial control register (SCR) to stop transmit/receive operations. At the same time, set the CKE1 bit to the value for the fixed output state in software standby mode.



- 3. Write 0 in the CKE0 bit in SCR to stop the clock.
- 4. Wait for one serial clock cycle. During this period, the duty cycle is preserved and clock output is fixed at the specified level.
- 5. Write H'00 in the serial mode register (SMR) and smart card mode register (SCMR).
- 6. Make the transition to the software standby state.
- Returning from software standby mode to smart card interface mode
- 1. Clear the software standby state.
- 2. Set the CKE1 bit in SCR to the value for the fixed output state at the start of software standby (the current P9, pin state).
- 3. Set smart card interface mode and output the clock. Clock signal generation is started with the normal duty cycle.

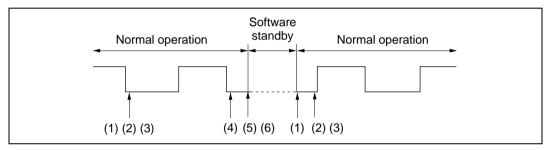


Figure 14.10 Procedure for Stopping and Restarting the Clock

Use the following procedure to secure the clock duty cycle after powering on.

- 1. The initial state is port input and high impedance. Use pull-up or pull-down resistors to fix the potential.
- 2. Fix at the output specified by the CKE1 bit in SCR.
- 3. Set SMR and SCMR, and switch to smart card interface mode operation.
- 4. Set the CKE0 bit to 1 in SCR to start clock output.

14.4 Usage Notes

The following points should be noted when using the SCI as a smart card interface.

Receive Data Sampling Timing and Receive Margin in Smart Card Interface Mode: In smart card interface mode, the SCI operates on a base clock with a frequency of 372 times the transfer rate. In reception, the SCI synchronizes internally with the fall of the start bit, which it samples on the base clock. Receive data is latched at the rising edge of the 186th base clock pulse. The timing is shown in figure 14.11.

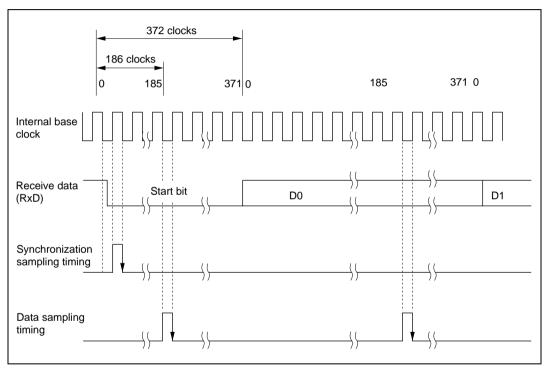


Figure 14.11 Receive Data Sampling Timing in Smart Card Interface Mode

The receive margin can therefore be expressed as follows.

Receive margin in smart card interface mode:

$$M = \left| (0.5 - \frac{1}{2N}) - (L - 0.5) F - \frac{|D - 0.5|}{N} (1 + F) \right| \times 100\%$$

M: Receive margin (%)

N: Ratio of clock frequency to bit rate (N = 372)

D: Clock duty cycle (L = 0 to 1.0)

L: Frame length (L =10)

F: Absolute deviation of clock frequency

From the above equation, if F = 0 and D = 0.5, the receive margin is as follows.

When D = 0.5 and F = 0:

$$M = (0.5 - 1/2 \times 372) \times 100\%$$
$$= 49.866\%$$

Retransmission: Retransmission is performed by the SCI in receive mode and transmit mode as described below.

- Retransmission when SCI is in Receive Mode
 Figure 14.12 illustrates retransmission when the SCI is in receive mode.
- 1. If an error is found when the received parity bit is checked, the PER bit is automatically set to 1. If the RIE bit in SCR is set to the enable state, an ERI interrupt is requested. The PER bit should be cleared to 0 in SSR before the next parity bit sampling timing.
- 2. The RDRF bit in SSR is not set for the frame in which the error has occurred.
- 3. If no error is found when the received parity bit is checked, the PER bit is not set to 1 in SSR.
- 4. If no error is found when the received parity bit is checked, the receive operation is assumed to have been completed normally, and the RDRF bit is automatically set to 1 in SSR. If the RIE bit in SCR is set to the enable state, an RXI interrupt is requested. If RXI is enabled as a DMA transfer activation source, the RDR contents can be read automatically. When the DMAC reads the RDR data, the RDRF flag is automatically cleared to 0.
- 5. When a normal frame is received, the data pin is held in the high-impedance state at the error signal transmission timing.

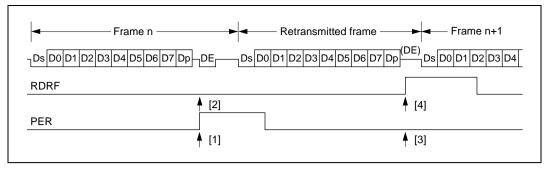


Figure 14.12 Retransmission in SCI Receive Mode

- Retransmission when SCI is in Transmit Mode
 Figure 14.13 illustrates retransmission when the SCI is in transmit mode.
- 6. If an error signal is sent back from the receiving device after transmission of one frame is completed, the FER/ERS bit is set to 1 in SSR. If the RIE bit in SCR is set to the enable state, an ERI interrupt is requested. The ERS bit should be cleared to 0 in SSR before the next parity bit sampling timing.
- 7. The TEND bit in SSR is not set for the frame for which the error signal was received.
- 8. If an error signal is not sent back from the receiving device, the ERS flag is not set in SSR.
- 9. If an error signal is not sent back from the receiving device, transmission of one frame, including retransmission, is assumed to have been completed, and the TEND bit is set to 1 in SSR. If the TIE bit in SCR is set to the enable state, a TXI interrupt is requested. If TXI is enabled as a DMA transfer activation source, the next data can be written in TDR automatically. When the DMAC writes data in TDR, the TDRE bit is automatically cleared to 0.

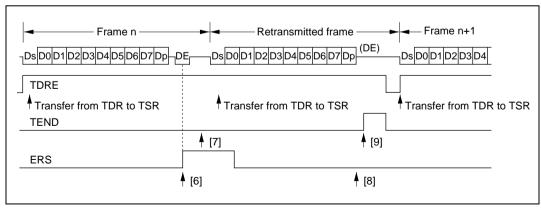


Figure 14.13 Retransmission in SCI Transmit Mode

Section 15 A/D Converter

15.1 Overview

The H8/3067 Group includes a 10-bit successive-approximations A/D converter with a selection of up to eight analog input channels.

When the A/D converter is not used, it can be halted independently to conserve power. For details see section 20.6, Module Standby Function.

15.1.1 Features

A/D converter features are listed below.

- 10-bit resolution
- Eight input channels
- Selectable analog conversion voltage range

The analog voltage conversion range can be programmed by input of an analog reference voltage at the V_{RFF} pin.

• High-speed conversion

Conversion time: maximum 3.5 µs per channel (with 20 MHz system clock)

• Two conversion modes

Single mode: A/D conversion of one channel

Scan mode: continuous conversion on one to four channels

• Four 16-bit data registers

A/D conversion results are transferred for storage into data registers corresponding to the channels.

- Sample-and-hold function
- Three conversion start sources

The A/D converter can be activated by software, an external trigger, or an 8-bit timer compare match.

• A/D interrupt requested at end of conversion

At the end of A/D conversion, an A/D end interrupt (ADI) can be requested.

• DMA controller (DMAC) activation

The DMAC can be activated at the end of A/D conversion.

15.1.2 Block Diagram

Figure 15.1 shows a block diagram of the A/D converter.

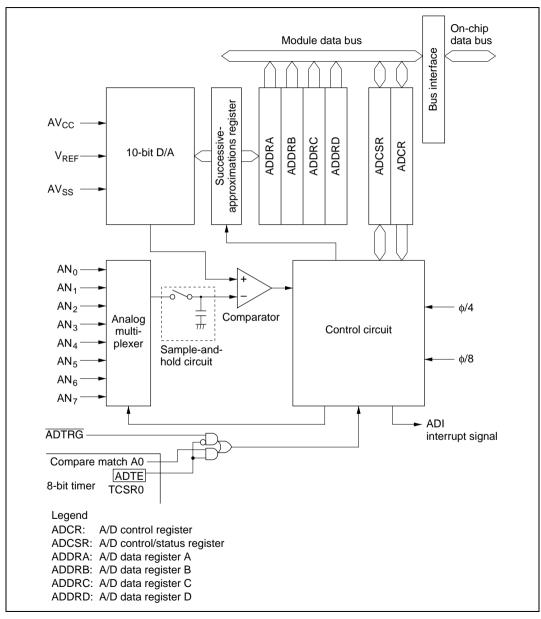


Figure 15.1 A/D Converter Block Diagram

15.1.3 Input Pins

Table 15.1 summarizes the A/D converter's input pins. The eight analog input pins are divided into two groups: group 0 (AN $_0$ to AN $_3$), and group 1 (AN $_4$ to AN $_7$). AV $_{CC}$ and AV $_{SS}$ are the power supply for the analog circuits in the A/D converter. V_{REF} is the A/D conversion reference voltage.

Table 15.1 A/D Converter Pins

Pin Name	Abbrevi- ation	I/O	Function
Analog power supply pin	AV _{cc}	Input	Analog power supply
Analog ground pin	AV _{ss}	Input	Analog ground and reference voltage
Reference voltage pin	V_{REF}	Input	Analog reference voltage
Analog input pin 0	AN _o	Input	Group 0 analog inputs
Analog input pin 1	AN ₁	Input	_
Analog input pin 2	AN ₂	Input	_
Analog input pin 3	AN ₃	Input	_
Analog input pin 4	AN ₄	Input	Group 1 analog inputs
Analog input pin 5	AN ₅	Input	_
Analog input pin 6	AN ₆	Input	-
Analog input pin 7	AN ₇	Input	-
A/D external trigger input pin	ADTRG	Input	External trigger input for starting A/D conversion

15.1.4 Register Configuration

Table 15.2 summarizes the A/D converter's registers.

Table 15.2 A/D Converter Registers

Address*1	Name	Abbreviation	R/W	Initial Value
H'FFFE0	A/D data register A H	ADDRAH	R	H'00
H'FFFE1	A/D data register A L	ADDRAL	R	H'00
H'FFFE2	A/D data register B H	ADDRBH	R	H'00
H'FFFE3	A/D data register B L	ADDRBL	R	H'00
H'FFFE4	A/D data register C H	ADDRCH	R	H'00
H'FFFE5	A/D data register C L	ADDRCL	R	H'00
H'FFFE6	A/D data register D H	ADDRDH	R	H'00
H'FFFE7	A/D data register D L	ADDRDL	R	H'00
H'FFFE8	A/D control/status register	ADCSR	R/(W)*2	H'00
H'FFFE9	A/D control register	ADCR	R/W	H'7E

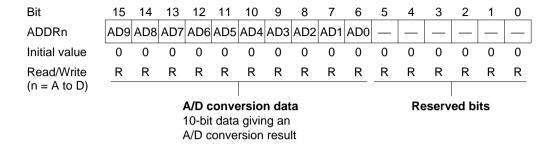
Notes: 1. Lower 20 bits of the address in advanced mode.



^{2.} Only 0 can be written in bit 7, to clear the flag.

15.2 Register Descriptions

15.2.1 A/D Data Registers A to D (ADDRA to ADDRD)



The four A/D data registers (ADDRA to ADDRD) are 16-bit read-only registers that store the results of A/D conversion.

An A/D conversion produces 10-bit data, which is transferred for storage into the A/D data register corresponding to the selected channel. The upper 8 bits of the result are stored in the upper byte of the A/D data register. The lower 2 bits are stored in the lower byte. Bits 5 to 0 of an A/D data register are reserved bits that are always read as 0. Table 15.3 indicates the pairings of analog input channels and A/D data registers.

The CPU can always read and write the A/D data registers. The upper byte can be read directly, but the lower byte is read through a temporary register (TEMP). For details see section 15.3, CPU Interface.

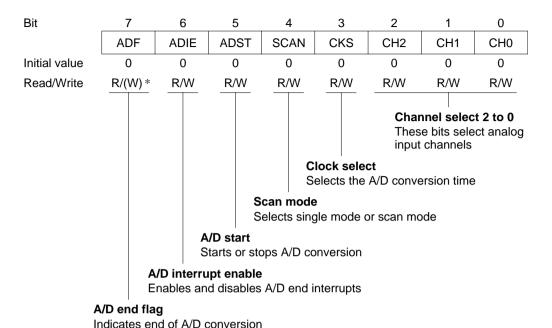
The A/D data registers are initialized to H'0000 by a reset and in standby mode.

Table 15.3 Analog Input Channels and A/D Data Registers

Analog Input Channel

Group 0	Group 1	A/D Data Register
AN ₀	AN ₄	ADDRA
AN ₁	AN ₅	ADDRB
AN ₂	AN ₆	ADDRC
AN ₃	AN ₇	ADDRD

15.2.2 A/D Control/Status Register (ADCSR)



Note: * Only 0 can be written, to clear the flag.

ADCSR is an 8-bit readable/writable register that selects the mode and controls the A/D converter. ADCSR is initialized to H'00 by a reset and in standby mode.



Bit 7—A/D End Flag (ADF): Indicates the end of A/D conversion.

Bit 7 ADF	Description	
0	[Clearing condition] Read ADF when ADF =1, then write 0 in ADF. DMAC activated by ADI interrupt.	(Initial value)
1	[Setting conditions] Single mode: A/D conversion ends Scan mode: A/D conversion ends in all selected channels	

Bit 6—A/D Interrupt Enable (ADIE): Enables or disables the interrupt (ADI) requested at the end of A/D conversion.

Bit 6		
ADIE	Description	
0	A/D end interrupt request (ADI) is disabled	(Initial value)
1	A/D end interrupt request (ADI) is enabled	

Bit 5—A/D Start (ADST): Starts or stops A/D conversion. The ADST bit remains set to 1 during A/D conversion. It can also be set to 1 by external trigger input at the ADTRG pin, or by an 8-bit timer compare match.

Bit 5 ADST	Description	
0	A/D conversion is stopped	(Initial value)
1	Single mode: A/D conversion starts; ADST is automatically cle conversion ends. Scan mode: A/D conversion starts and continues, cycling amo channels, until ADST is cleared to 0 by software, by a reset, o standby mode.	ong the selected

Bit 4—Scan Mode (SCAN): Selects single mode or scan mode. For further information on operation in these modes, see section 15.4, Operation. Clear the ADST bit to 0 before switching the conversion mode.

Bit 4		
SCAN	Description	
0	Single mode	(Initial value)
1	Scan mode	

Bit 3—Clock Select (CKS): Selects the A/D conversion time. Clear the ADST bit to 0 before switching the conversion time.

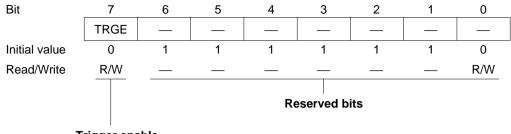
Bit 3		
CKS	Description	
0	Conversion time = 134 states (maximum)	(Initial value)
1	Conversion time = 70 states (maximum)	

Bits 2 to 0—Channel Select 2 to 0 (CH2 to CH0): These bits and the SCAN bit select the analog input channels. Clear the ADST bit to 0 before changing the channel selection.

Group Selection	Channel Selection		Description				
CH2	CH1	CH0	Single Mode	Scan Mode			
0	0	0	AN₀ (Initial value)	AN_{o}			
		1	AN ₁	AN ₀ , AN ₁			
	1	0	AN ₂	AN _o to AN ₂			
		1	AN ₃	AN _o to AN ₃			
1	0	0	AN ₄	AN ₄			
		1	AN ₅	AN ₄ , AN ₅			
	1	0	AN ₆	AN ₄ to AN ₆			
		1	AN ₇	AN ₄ to AN ₇			



15.2.3 A/D Control Register (ADCR)



Trigger enable

Enables or disables starting of A/D conversion by an external trigger or 8-bit timer compare match

ADCR is an 8-bit readable/writable register that enables or disables starting of A/D conversion by external trigger input or an 8-bit timer compare match signal. ADCR is initialized to H'7F by a reset and in standby mode.

Bit 7—Trigger Enable (TRGE): Enables or disables starting of A/D conversion by an external trigger or 8-bit timer compare match.

Bit 7 TRGE	Description	
0	Starting of A/D conversion by an external trigger or 8-bit timer compare match is disabled	(Initial value)
1	A/D conversion is started at the falling edge of the external trigger signal (ADTRG) or by an 8-bit timer compare match	

External trigger pin and 8-bit timer selection are performed by the 8-bit timer. For details, see section 10, 8-Bit Timers.

Bits 6 to 1—Reserved: These bits cannot be modified and are always read as 1.

Bit 0—Reserved: This bit can be read or written, but must not be set to 1.

15.3 CPU Interface

ADDRA to ADDRD are 16-bit registers, but they are connected to the CPU by an 8-bit data bus. Therefore, although the upper byte can be be accessed directly by the CPU, the lower byte is read through an 8-bit temporary register (TEMP).

An A/D data register is read as follows. When the upper byte is read, the upper-byte value is transferred directly to the CPU and the lower-byte value is transferred into TEMP. Next, when the lower byte is read, the TEMP contents are transferred to the CPU.

When reading an A/D data register, always read the upper byte before the lower byte. It is possible to read only the upper byte, but if only the lower byte is read, incorrect data may be obtained.

Figure 15.2 shows the data flow for access to an A/D data register.



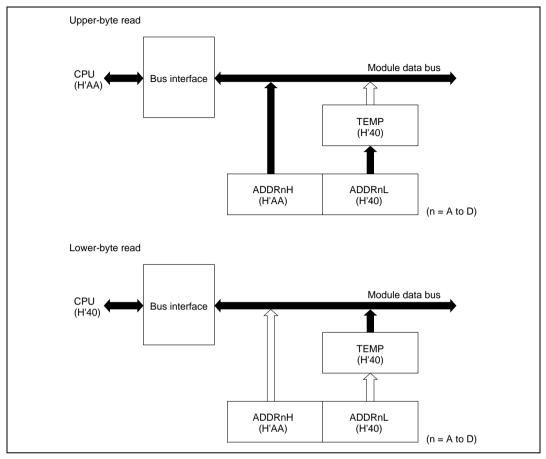


Figure 15.2 A/D Data Register Access Operation (Reading H'AA40)

15.4 Operation

The A/D converter operates by successive approximations with 10-bit resolution. It has two operating modes: single mode and scan mode.

15.4.1 Single Mode (SCAN = 0)

Single mode should be selected when only one A/D conversion on one channel is required. A/D conversion starts when the ADST bit is set to 1 by software, or by external trigger input. The ADST bit remains set to 1 during A/D conversion and is automatically cleared to 0 when conversion ends.

When conversion ends the ADF bit is set to 1. If the ADIE bit is also set to 1, an ADI interrupt is requested at this time. To clear the ADF flag to 0, first read ADCSR, then write 0 in ADF.

When the mode or analog input channel must be switched during analog conversion, to prevent incorrect operation, first clear the ADST bit to 0 in ADCSR to halt A/D conversion. After making the necessary changes, set the ADST bit to 1 to start A/D conversion again. The ADST bit can be set at the same time as the mode or channel is changed.

Typical operations when channel 1 (AN₁) is selected in single mode are described next.

Figure 15.3 shows a timing diagram for this example.

- Single mode is selected (SCAN = 0), input channel AN₁ is selected (CH2 = CH1 = 0, CH0 = 1), the A/D interrupt is enabled (ADIE = 1), and A/D conversion is started (ADST = 1).
- 2. When A/D conversion is completed, the result is transferred into ADDRB. At the same time the ADF flag is set to 1, the ADST bit is cleared to 0, and the A/D converter becomes idle.
- 3. Since ADF = 1 and ADIE = 1, an ADI interrupt is requested.
- 4. The A/D interrupt handling routine starts.
- 5. The routine reads ADCSR, then writes 0 in the ADF flag.
- 6. The routine reads and processes the conversion result (ADDRB).
- 7. Execution of the A/D interrupt handling routine ends. After that, if the ADST bit is set to 1, A/D conversion starts again and steps 2 to 7 are repeated.



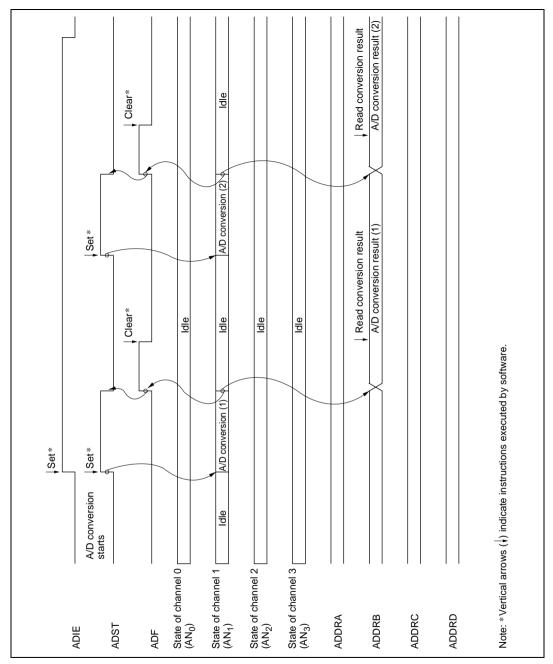


Figure 15.3 Example of A/D Converter Operation (Single Mode, Channel 1 Selected)

15.4.2 Scan Mode (SCAN = 1)

Scan mode is useful for monitoring analog inputs in a group of one or more channels. When the ADST bit is set to 1 by software or external trigger input, A/D conversion starts on the first channel in the group (AN_0 when CH2=0, AN_4 when CH2=1). When two or more channels are selected, after conversion of the first channel ends, conversion of the second channel (AN_1 or AN_5) starts immediately. A/D conversion continues cyclically on the selected channels until the ADST bit is cleared to 0. The conversion results are transferred for storage into the A/D data registers corresponding to the channels.

When the mode or analog input channel selection must be changed during analog conversion, to prevent incorrect operation, first clear the ADST bit to 0 in ADCSR to halt A/D conversion. After making the necessary changes, set the ADST bit to 1. A/D conversion will start again from the first channel in the group. The ADST bit can be set at the same time as the mode or channel selection is changed.

Typical operations when three channels in group 0 (AN₀ to AN₂) are selected in scan mode are described next. Figure 15.4 shows a timing diagram for this example.

- 1. Scan mode is selected (SCAN = 1), scan group 0 is selected (CH2 = 0), analog input channels AN_0 to AN_2 are selected (CH1 = 1, CH0 = 0), and A/D conversion is started (ADST = 1).
- 2. When A/D conversion of the first channel (AN₀) is completed, the result is transferred into ADDRA. Next, conversion of the second channel (AN₁) starts automatically.
- 3. Conversion proceeds in the same way through the third channel (AN₂).
- 4. When conversion of all selected channels $(AN_0 \text{ to } AN_2)$ is completed, the ADF flag is set to 1 and conversion of the first channel (AN_0) starts again. If the ADIE bit is set to 1, an ADI interrupt is requested at this time.
- 5. Steps 2 to 4 are repeated as long as the ADST bit remains set to 1. When the ADST bit is cleared to 0, A/D conversion stops. After that, if the ADST bit is set to 1, A/D conversion starts again from the first channel (AN₀).



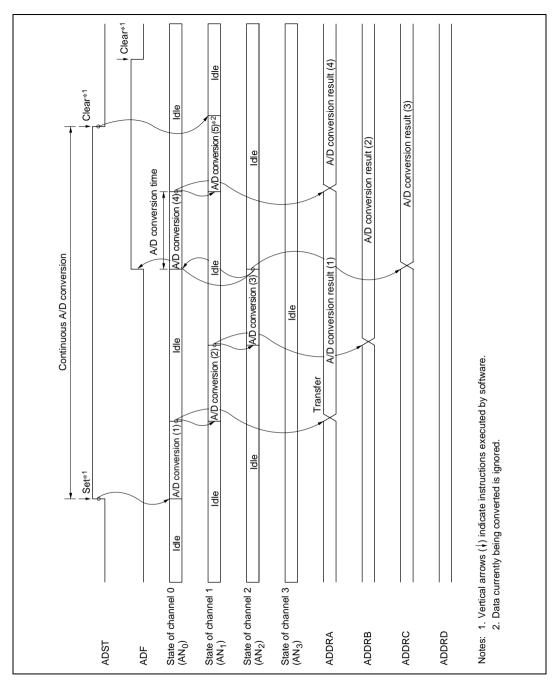


Figure 15.4 Example of A/D Converter Operation (Scan Mode, Channels AN₀ to AN₂ Selected)

15.4.3 Input Sampling and A/D Conversion Time

The A/D converter has a built-in sample-and-hold circuit. The A/D converter samples the analog input at a time t_D after the ADST bit is set to 1, then starts conversion. Figure 15.5 shows the A/D conversion timing. Table 15.4 indicates the A/D conversion time.

As indicated in figure 15.5, the A/D conversion time includes $t_{\scriptscriptstyle D}$ and the input sampling time. The length of $t_{\scriptscriptstyle D}$ varies depending on the timing of the write access to ADCSR. The total conversion time therefore varies within the ranges indicated in table 15.4.

In scan mode, the values given in table 15.4 apply to the first conversion. In the second and subsequent conversions the conversion time is fixed at 128 states when CKS = 0 or 66 states when CKS = 1.



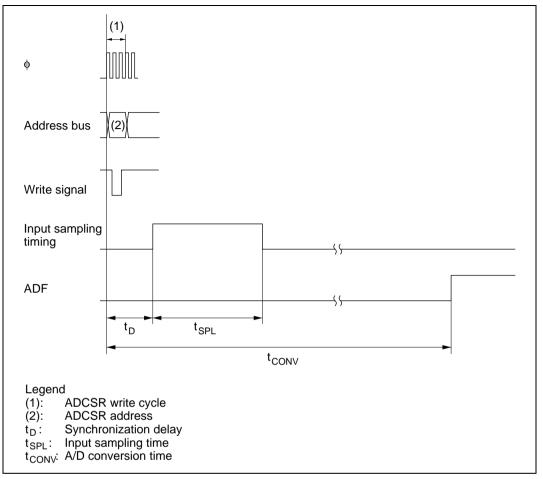


Figure 15.5 A/D Conversion Timing

Table 15.4 A/D Conversion Time (Single Mode)

		CKS = 0			CKS = 1		
	Symbol	Min	Тур	Max	Min	Тур	Max
Synchronization delay	t _D	6	_	9	4	_	5
Input sampling time	t _{spl}	_	31	_	_	15	_
A/D conversion time	t _{CONV}	131	_	134	69	_	70

Note: Values in the table are numbers of states.

15.4.4 External Trigger Input Timing

A/D conversion can be externally triggered. When the TRGE bit is set to 1 in ADCR and the 8-bit timer's ADTE bit is cleared to 0, external trigger input is enabled at the ADTRG pin. A high-to-low transition at the ADTRG pin sets the ADST bit to 1 in ADCSR, starting A/D conversion. Other operations, in both single and scan modes, are the same as if the ADST bit had been set to 1 by software. Figure 15.6 shows the timing.

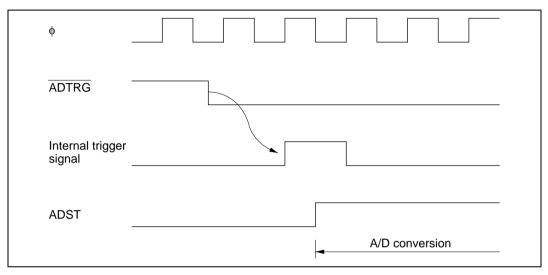


Figure 15.6 External Trigger Input Timing

15.5 Interrupts

The A/D converter generates an interrupt (ADI) at the end of A/D conversion. The ADI interrupt request can be enabled or disabled by the ADIE bit in ADCSR. The ADI interrupt request can be designated as a DMAC activation source. In this case, an interrupt request is not sent to the CPU.

15.6 Usage Notes

When using the A/D converter, note the following points:

- 1. Analog Input Voltage Range: During A/D conversion, the voltages input to the analog input pins should be in the range $AV_{SS} \le AN_n \le V_{REF}$.
- 2. Relationships of AV_{cc} and AV_{ss} to V_{cc} and V_{ss} : AV_{cc} , AV_{ss} , V_{cc} , and V_{ss} should be related as follows: $AV_{ss} = V_{ss}$. AV_{cc} and AV_{ss} must not be left open, even if the A/D converter is not used.
- 3. V_{REF} Programming Range: The reference voltage input at the V_{REF} pin should be in the range $V_{REF} \le AV_{CC}$.
- 4. Note on Board Design: In board layout, separate the digital circuits from the analog circuits as much as possible. Particularly avoid layouts in which the signal lines of digital circuits cross or closely approach the signal lines of analog circuits. Induction and other effects may cause the analog circuits to operate incorrectly, or may adversely affect the accuracy of A/D conversion. The analog input signals (AN $_0$ to AN $_7$), analog reference voltage (V $_{REF}$), and analog supply voltage (AV $_{CC}$) must be separated from digital circuits by the analog ground (AV $_{SS}$). The analog ground (AV $_{SS}$) should be connected to a stable digital ground (V $_{SS}$) at one point on the board.
- 5. Note on Noise: To prevent damage from surges and other abnormal voltages at the analog input pins (AN₀ to AN₇) and analog reference voltage pin (V_{REF}), connect a protection circuit like the one in figure 15.7 between AV_{CC} and AV_{SS}. The bypass capacitors connected to AV_{CC} and V_{REF} and the filter capacitors connected to AN₀ to AN₇ must be connected to AV_{SS}. If filter capacitors like the ones in figure 15.7 are connected, the voltage values input to the analog input pins (AN₀ to AN₇) will be smoothed, which may give rise to error. Error can also occur if A/D conversion is frequently performed in scan mode so that the current that charges and discharges the capacitor in the sample-and-hold circuit of the A/D converter becomes greater than that input to the analog input pins via input impedance Rin. The circuit constants should therefore be selected carefully.

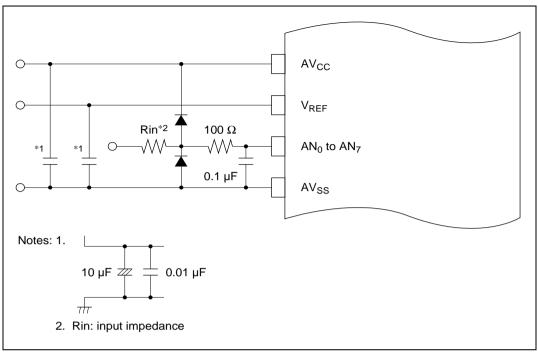


Figure 15.7 Example of Analog Input Protection Circuit

Table 15.5 Analog Input Pin Ratings

Item	min	max	Unit
Analog input capacitance	_	20	pF
Allowable signal-source impedance	_	10*	kΩ

Note: *When conversion time = 134 states, V_{cc} = 4.0 V to 5.5 V, and $\phi \le$ 13 MHz. For details see section 21, Electrical Characteristics.

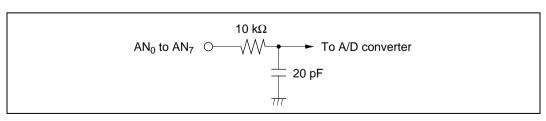


Figure 15.8 Analog Input Pin Equivalent Circuit

Note: Numeric values are approximate, except in table 15.5

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- 6. A/D Conversion Accuracy Definitions: A/D conversion accuracy in the H8/3067 Group is defined as follows:
 - Resolution:.....Digital output code length of A/D converter
 - Offset error:Deviation from ideal A/D conversion characteristic of analog input
 voltage required to raise digital output from minimum voltage value
 00000000000 to 0000000001 (figure 15.10)
 - Full-scale error:Deviation from ideal A/D conversion characteristic of analog input voltage required to raise digital output from 11111111110 to 11111111111 (figure 15.10)
 - Quantization error:.....Intrinsic error of the A/D converter; 1/2 LSB (figure 15.9)
 - Nonlinearity error:Deviation from ideal A/D conversion characteristic in range from zero volts to full scale, exclusive of offset error, full-scale error, and quantization error.
 - Absolute accuracy:Deviation of digital value from analog input value, including offset error, full-scale error, quantization error, and nonlinearity error.

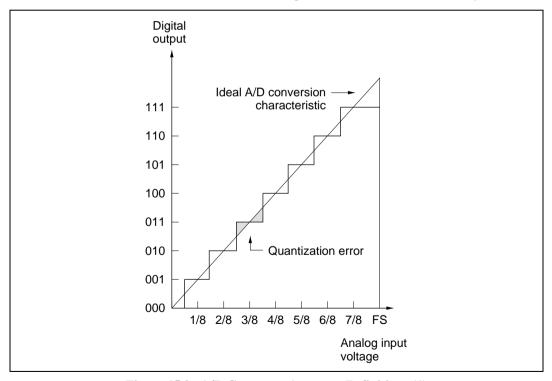


Figure 15.9 A/D Converter Accuracy Definitions (1)

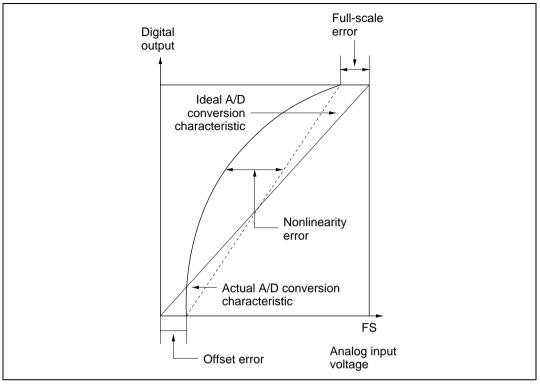


Figure 15.10 A/D Converter Accuracy Definitions (2)

7. Allowable Signal-Source Impedance: The analog inputs of the H8/3067 Group are designed to assure accurate conversion of input signals with a signal-source impedance not exceeding 10 k Ω . The reason for this rating is that it enables the input capacitor in the sample-and-hold circuit in the A/D converter to charge within the sampling time. If the sensor output impedance exceeds 10 k Ω , charging may be inadequate and the accuracy of A/D conversion cannot be guaranteed.

If a large external capacitor is provided in single mode, then the internal $10\text{-k}\Omega$ input resistance becomes the only significant load on the input. In this case the impedance of the signal source is not a problem.

A large external capacitor, however, acts as a low-pass filter. This may make it impossible to track analog signals with high dv/dt (e.g. a variation of 5 mV/ μ s) (figure 15.11). To convert high-speed analog signals or to use scan mode, insert a low-impedance buffer.

 Effect on Absolute Accuracy: Attaching an external capacitor creates a coupling with ground, so if there is noise on the ground line, it may degrade absolute accuracy. The capacitor must be connected to an electrically stable ground, such as AV_{ss}.



If a filter circuit is used, be careful of interference with digital signals on the same board, and make sure the circuit does not act as an antenna.

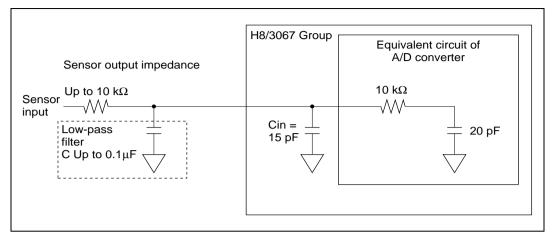


Figure 15.11 Analog Input Circuit (Example)

Section 16 D/A Converter

16.1 Overview

The H8/3067 Group includes a D/A converter with two channels.

16.1.1 Features

D/A converter features are listed below.

- Eight-bit resolution
- Two output channels
- Conversion time: maximum 10 µs (with 20-pF capacitive load)
- Output voltage: 0 V to V_{REF}
- D/A outputs can be sustained in software standby mode

16.1.2 Block Diagram

Figure 16.1 shows a block diagram of the D/A converter.

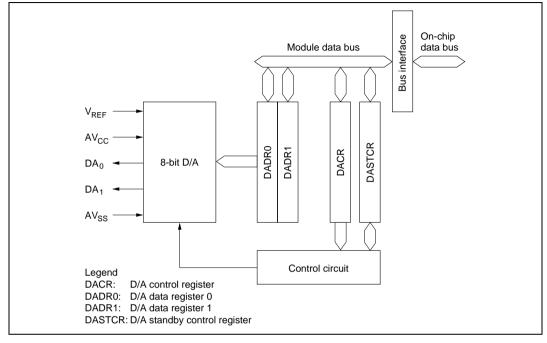


Figure 16.1 D/A Converter Block Diagram

16.1.3 Input/Output Pins

Table 16.1 summarizes the D/A converter's input and output pins.

Table 16.1 D/A Converter Pins

Pin Name	Abbreviation	I/O	Function
Analog power supply pin	AV _{cc}	Input	Analog power supply and reference voltage
Analog ground pin	AV _{ss}	Input	Analog ground and reference voltage
Analog output pin 0	DA _o	Output	Analog output, channel 0
Analog output pin 1	DA ₁	Output	Analog output, channel 1
Reference voltage input pin	V_{REF}	Input	Analog reference voltage

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16.1.4 Register Configuration

Table 16.2 summarizes the D/A converter's registers.

Table 16.2 D/A Converter Registers

Address*	Name	Abbreviation	R/W	Initial Value
H'FFF9C	D/A data register 0	DADR0	R/W	H'00
H'FFF9D	D/A data register 1	DADR1	R/W	H'00
H'FFF9E	D/A control register	DACR	R/W	H'1F
H'EE01A	D/A standby control register	DASTCR	R/W	H'FE

Note: * Lower 20 bits of the address in advanced mode.

16.2 Register Descriptions

16.2.1 D/A Data Registers 0 and 1 (DADR0/1)

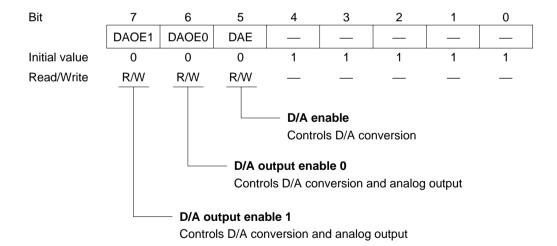
Bit	7	6	5	4	3	2	1	0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W							

The D/A data registers (DADR0 and DADR1) are 8-bit readable/writable registers that store the data to be converted. When analog output is enabled, the D/A data register values are constantly converted and output at the analog output pins.

The D/A data registers are initialized to H'00 by a reset and in standby mode.

When the DASTE bit is set to 1 in the D/A standby control register (DASTCR), the D/A registers are not initialized in software standby mode.

16.2.2 D/A Control Register (DACR)



DACR is an 8-bit readable/writable register that controls the operation of the D/A converter. DACR is initialized to H'1F by a reset and in standby mode.

When the DASTE bit is set to 1 in DASTCR, the DACR is not initialized in software standby mode.

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Bit 7—D/A Output Enable 1 (DAOE1): Controls D/A conversion and analog output.

Bit 7 DAOE1	Description
0	DA, analog output is disabled
1	Channel-1 D/A conversion and DA, analog output are enabled

Bit 6—D/A Output Enable 0 (DAOE0): Controls D/A conversion and analog output.

Bit 6	
DAOE0	Description
0	DA ₀ analog output is disabled
1	Channel-0 D/A conversion and DA₀ analog output are enabled

Bit 5—D/A Enable (DAE): Controls D/A conversion, together with bits DAOE0 and DAOE1. When the DAE bit is cleared to 0, analog conversion is controlled independently in channels 0 and 1. When the DAE bit is set to 1, analog conversion is controlled together in channels 0 and 1. Output of the conversion results is always controlled independently by DAOE0 and DAOE1.

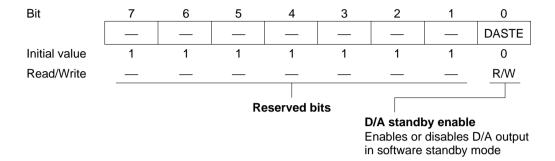
Bit 7 DAOE1	Bit 6 DAOE0	Bit 5 DAE	Description
0	0	_	D/A conversion is disabled in channels 0 and 1
	1	0	D/A conversion is enabled in channel 0
			D/A conversion is disabled in channel 1
		1	D/A conversion is enabled in channels 0 and 1
1	0	0	D/A conversion is disabled in channel 0
			D/A conversion is enabled in channel 1
		1	D/A conversion is enabled in channels 0 and 1
	1	_	D/A conversion is enabled in channels 0 and 1

When the DAE bit is set to 1, even if bits DAOE0 and DAOE1 in DACR and the ADST bit in ADCSR are cleared to 0, the same current is drawn from the analog power supply as during A/D and D/A conversion.

Bits 4 to 0—Reserved: These bits cannot be modified and are always read as 1.

16.2.3 D/A Standby Control Register (DASTCR)

DASTCR is an 8-bit readable/writable register that enables or disables D/A output in software standby mode.



DASTCR is initialized to H'FE by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bits 7 to 1—Reserved: These bits cannot be modified and are always read as 1.

Bit 0—D/A Standby Enable (DASTE): Enables or disables D/A output in software standby mode.

Bit 0 DASTE	Description	
0	D/A output is disabled in software standby mode	(Initial value)
1	D/A output is enabled in software standby mode	

16.3 Operation

The D/A converter has two built-in D/A conversion circuits that can perform conversion independently.

D/A conversion is performed constantly while enabled in DACR. If the DADR0 or DADR1 value is modified, conversion of the new data begins immediately. The conversion results are output when bits DAOE0 and DAOE1 are set to 1.

An example of D/A conversion on channel 0 is given next. Timing is indicated in figure 16.2.

- 1. Data to be converted is written in DADR0.
- 2. Bit DAOE0 is set to 1 in DACR. D/A conversion starts and DA0 becomes an output pin. The converted result is output after the conversion time.

The output value is
$$\frac{\text{DADR contents}}{256} \times V_{\text{REF}}$$

Output of this conversion result continues until the value in DADR0 is modified or the DAOE0 bit is cleared to 0.

- 3. If the DADR0 value is modified, conversion starts immediately, and the result is output after the conversion time.
- 4. When the DAOE0 bit is cleared to 0, DA0 becomes an input pin.

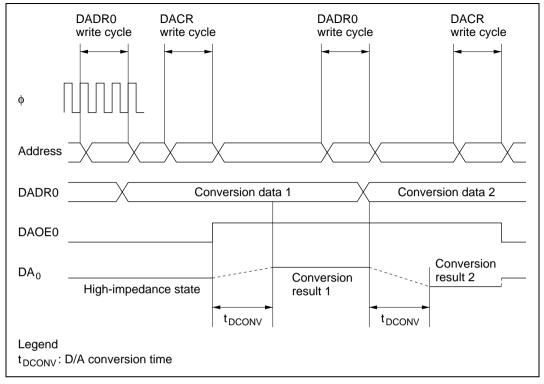


Figure 16.2 Example of D/A Converter Operation

16.4 D/A Output Control

In the H8/3067 Group, D/A converter output can be enabled or disabled in software standby mode.

When the DASTE bit is set to 1 in DASTCR, D/A converter output is enabled in software standby mode. The D/A converter registers retain the values they held prior to the transition to software standby mode.

When D/A output is enabled in software standby mode, the reference supply current is the same as during normal operation.



Section 17 RAM

17.1 Overview

The H8/3067 and H8/3066 have 4 kbytes of high-speed static RAM on-chip. The H8/3065 has 2 kbytes. The RAM is connected to the CPU by a 16-bit data bus. The CPU accesses both byte data and word data in two states, making the RAM useful for rapid data transfer.

The on-chip RAM of the H8/3067 and H8/3066 is assigned to addresses H'FEF20 to H'FFF1F in modes 1, 2, and 7, and to addresses H'FFEF20 to H'FFF1F in modes 3, 4, and 5, and to addresses H'EF20 to H'FF1F in mode 6. The on-chip RAM of the H8/3065 are assigned to addresses H'FF720 to H'FFF1F in modes 1, 2, and 7, and to addresses H'FFF720 to H'FFFF1F in modes 3, 4, and 5, and to addresses H'F720 to H'FF1F in mode 6. The RAM enable bit (RAME) in the system control register (SYSCR) can enable or disable the on-chip RAM.

17.1.1 Block Diagram

Figure 17.1 shows a block diagram of the on-chip RAM.

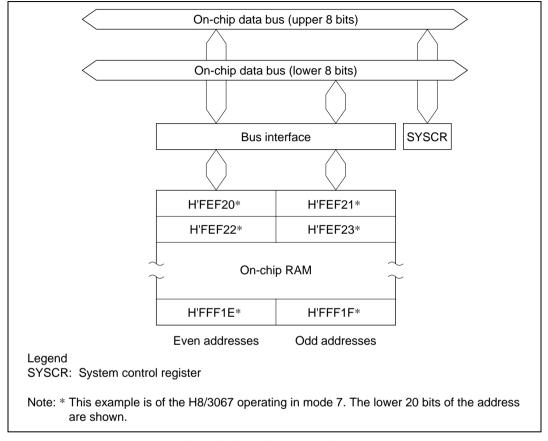


Figure 17.1 RAM Block Diagram

17.1.2 Register Configuration

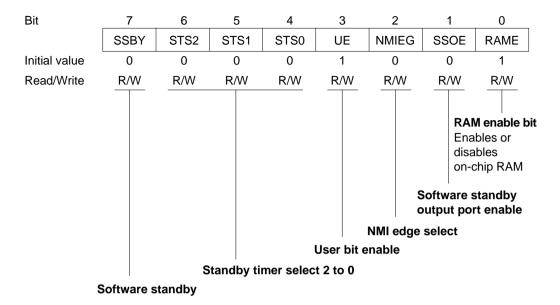
The on-chip RAM is controlled by SYSCR. Table 17.1 gives the address and initial value of SYSCR.

Table 17.1 System Control Register

Address*	Name	Abbreviation	R/W	Initial Value
H'EE012	System control register	SYSCR	R/W	H'09

Note: * Lower 20 bits of the address in advanced mode.

17.2 System Control Register (SYSCR)



One function of SYSCR is to enable or disable access to the on-chip RAM. The on-chip RAM is enabled or disabled by the RAME bit in SYSCR. For details about the other bits, see section 3.3, System Control Register (SYSCR).

Bit 0—RAM Enable (RAME): Enables or disables the on-chip RAM. The RAME bit is initialized at the rising edge of the input at the RES pin. It is not initialized in software standby mode.

Bit 0 RAME	Description	
0	On-chip RAM is disabled	
1	On-chip RAM is enabled	(Initial value)

17.3 Operation

When the RAME bit is set to 1, the on-chip RAM is enabled. Accesses to addresses H'FEF20 to H'FFF1F in the H8/3067 and H8/3066 in modes 1, 2, and 7, and to addresses H'FFEF20 to H'FFF1F in the H8/3067 and H8/3066 in modes 3, 4, and 5, and to addresses H'EF20 to H'FF1F in mode 6, are directed to the on-chip RAM. In the H8/3065, accesses to addresses H'FF720 to H'FFF1F in modes 1, 2, and 7, to addresses H'FFF720 to H'FFFF1F in modes 3, 4, and 5, and to addresses H'F720 to H'FF1F in mode 6, are directed to the on-chip RAM. In modes 1 to 5 (expanded modes), when the RAME bit is cleared to 0, the off-chip address space is accessed. In mode 6, 7 (single-chip mode), when the RAME bit is cleared to 0, the on-chip RAM is not accessed: read access always results in H'FF data, and write access is ignored.

Since the on-chip RAM is connected to the CPU by an internal 16-bit data bus, it can be written and read by word access. It can also be written and read by byte access. Byte data is accessed in two states using the upper 8 bits of the data bus. Word data starting at an even address is accessed in two states using all 16 bits of the data bus.

Section 18 ROM

18.1 Overview

The H8/3067 has 128 kbytes of on-chip ROM (flash memory or mask ROM), the H8/3066 has 96 kbytes, and H8/3065 has 64 kbytes. The ROM is connected to the CPU by a 16-bit data bus. The CPU accesses both byte and word data in two states, enabling rapid data transfer.

The mode pins (MD, to MD₀) can be set to enable or disable the on-chip ROM. See table 18.1.

The on-chip flash memory product (H8/3067RF-ZTAT) can be erased and programmed on-board as well as with a general-purpose PROM programmer.

Table 18.1 Operating Mode and ROM

	Mod	e Pins	5	On-Chip
Mode	MD ₂	MD₁	MD₀	ROM
Mode 1 (1-Mbyte expanded mode with on-chip ROM disabled)	0	0	1	Disabled
Mode 2 (1-Mbyte expanded mode with on-chip ROM disabled)	0	1	0	(external address area)
Mode 3 (16-Mbyte expanded mode with on-chip ROM disabled)	0	1	1	- address area)
Mode 4 (16-Mbyte expanded mode with on-chip ROM disabled)	1	0	0	_
Mode 5 (16-Mbyte expanded mode with on-chip ROM enabled)	1	0	1	Enabled
Mode 6 (single-chip normal mode)	1	1	0	_
Mode 7 (single-chip advanced mode)	1	1	1	_

18.2 Overview of Flash Memory

18.2.1 Features

The features of the flash memory are summarized below.

- Four flash memory operating modes
 - Program mode
 - Erase mode
 - Program-verify mode
 - Erase-verify mode
- Programming/erase methods

The flash memory is programmed 32 bytes at a time. Erasing is performed by block erase. The block to be erased can be specified by setting the corresponding bit. There are block areas of $32KB \times 3$ blocks, $28KB \times 1$ block, and $1KB \times 4$ blocks.

• Programming/erase times

The flash memory programming time is 10 ms (typ.) for simultaneous 32-byte programming, equivalent to $300 \mu \text{s}$ (typ.) per byte, and the erase time is 100 ms (typ.) per block.

• Reprogramming capability

The flash memory can be reprogrammed up to 100 times.

• On-board programming modes

There are two modes in which flash memory can be programmed/erased/verified on-board:

- Boot mode
- User program mode
- Automatic bit rate adjustment

With data transfer in boot mode, the H8/3067's bit rate can be automatically adjusted to match the transfer bit rate of the host (9600 bps and 4800 bps).

Flash memory emulation by RAM

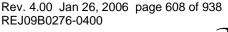
Part of the RAM area can be overlapped onto flash memory, to emulate flash memory updates in real time.

PROM mode

Flash memory can be programmed/erased in PROM mode, using a PROM programmer, as well as in on-board programming mode.

Protect modes

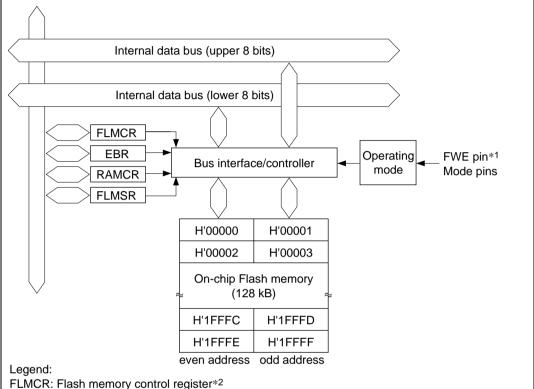
There are three protect modes, hardware, software, and error protect, which allow protected status to be designated for flash memory program/erase/verify operations.





18.2.2 **Block Diagram**

Figure 18.1 shows a block diagram of the flash memory.



EBR: Erase block register*2 RAMCR: RAM control register*2

FLMSR: Flash memory status register*2

Notes: 1. Functions as the FWE pin in the flash memory and flash memory R versions, and as the RESO pin in the mask ROM versions.

2. The registers that control the flash memory (FLMCR, EBR, RAMCR, and FLMSR) are used in the flash memory and flash memory R versions only. They are not provided in the mask ROM versions. Reading the corresponding addresses in a mask ROM version will always return 1s, and writes to these addresses are disabled.

Figure 18.1 Block Diagram of Flash Memory

18.2.3 Pin Configuration

The flash memory is controlled by means of the pins shown in table 18.2.

Table 18.2 Flash Memory Pins

Pin Name	Abbreviation	I/O	Function
Reset	RES	Input	Reset
Flash write enable	FWE*	Input	Flash program/erase protection by hardware
Mode 2	MD ₂	Input	Sets this LSI operating mode
Mode 1	MD ₁	Input	Sets this LSI operating mode
Mode 0	MD _o	Input	Sets this LSI operating mode
Transmit data	TxD ₁	Output	Serial transmit data output
Receive data	RxD ₁	Input	Serial receive data input

Note: The transmit data and receive data pins are used in boot mode.

18.2.4 Register Configuration

The registers used to control the on-chip flash memory when enabled are shown in table 18.3.

Table 18.3 Flash Memory Registers

Register Name	Abbreviation	R/W	Initial Value	Address*1
Flash memory control register	FLMCR	R/W	H'00 ^{*2}	H'EE030
Erase block register	EBR	R/W	H'00	H'EE032
RAM control register	RAMCR	R/W	H'F1	H'EE077
Flash memory status register	FLMSR	R	H'7F	H'EE07D

Notes: 1. Lower 20 bits of address in advanced mode.

2. When a high level is input to the FWE pin, the initial value is H'80.

The registers in table 18.3 are used in the flash memory and flash memory R versions only. Reading the corresponding addresses in a mask ROM version will always return 1s, and writes to these addresses are disabled.



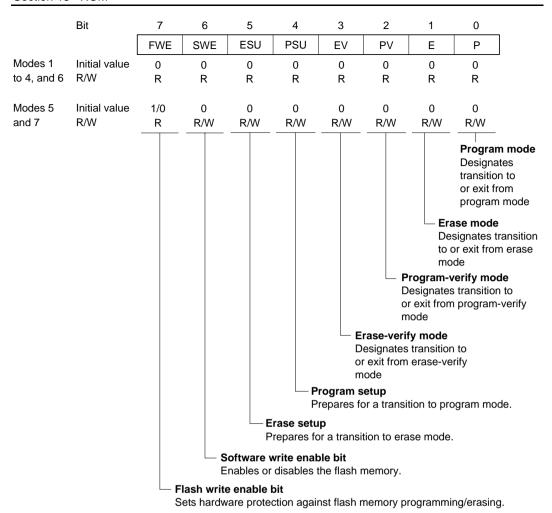
^{*} In the mask ROM versions, the FWE pin functions as the RESO pin.

18.3 Register Descriptions

18.3.1 Flash Memory Control Register (FLMCR)

FLMCR is an 8-bit register used for flash memory operating mode control. Program-verify mode or erase-verify mode is entered by setting SWE to 1 when FWE = 1. Program mode is entered by setting SWE to 1 when FWE = 1, then setting the PSU bit, and finally setting the P bit. Erase mode is entered by setting SWE to 1 when FWE = 1, then setting the ESU bit, and finally setting the E bit. FLMCR is initialized by a reset, and in hardware standby mode and software standby mode. Its initial value is H'80 when a high level is input to the FWE pin, and H'00 when a low level is input. In mode 6 the FWE pin must be fixed low, as flash memory on-board programming is not supported. Therefore, bits in this register cannot be set to 1 in mode 6. When on-chip flash memory is disabled, a read will return H'00, and writes are invalid. When setting bits 6 to 0 in this register to 1, each bit should be set individually.

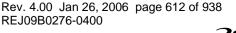
Writes to the ESU, PSU, EV and PV bits in FLMCR are enabled only when FWE = 1 and SWE = 1; writes to the E bit only when FWE = 1, SWE = 1, and ESU = 1; and writes to the P bit only when FWE = 1, SWE = 1, and PSU = 1.



Bit 7—Flash Write Enable Bit (FWE): Sets hardware protection against flash memory programming/erasing. When using this bit, refer to section 18.9, Notes on Flash Memory Programming/Erasing.

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FWE	Description
0	When a low level is input to the FWE pin (hardware-protected state)
1	When a high level is input to the FWE pin





Bit 6—Software Write Enable Bit (SWE)*1*2: This bit enables/disables flash memory programming/erasing. This bit should be set before setting FLMCR bits 5 to 0, and EBR bits 7 to 0. Do not set the ESU, PSU, EV, PV, E, or P bits at the same time.

Bit 6: SWE	Description	
0	Program/erase disabled	(Initial value)
1	Program/erase enabled [Setting condition] When FWE = 1	

Bit 5—Erase Setup Bit (ESU) *1: Prepares for a transition to erase mode. Do not set the SWE, PSU, EV, PV, E, or P bit at the same time.

Bit 5: ESU	Description	
0	Erase setup cleared	(Initial value)
1	Erase setup [Setting condition] When FWE = 1, and SWE = 1	

Bit 4—Program Setup Bit (PSU) *1: Prepares for a transition to program mode. Do not set the SWE, ESU, EV, PV, E, or P bit at the same time.

Bit 4: PSU	Description	
0	Program setup cleared	(Initial value)
1	Program setup [Setting condition] When FWE = 1, and SWE = 1	

Bit 3—Erase-Verify (EV) *1: Selects erase-verify mode transition or clearing. Do not set the SWE, ESU, PSU, PV, E, or P bit at the same time.

Bit 3:

EV	Description	
0	Erase-verify mode cleared	(Initial value)
1	Transition to erase-verify mode [Setting condition] When FWE = 1, and SWE = 1	

Bit 2—Program-Verify (**PV**)**: Selects program-verify mode transition or clearing. Do not set the SWE, ESU, PSU, EV, E, or P bit at the same time.

Rit 2

PV	Description	
0	Program-verify mode cleared	(Initial value)
1	Transition to program-verify mode [Setting condition] When FWE = 1, and SWE = 1	

Bit 1—Erase (E) *1*3: Selects erase mode transition or clearing. Do not set the SWE, ESU, PSU, EV, PV, or P bit at the same time.

Bit 1:

E	Description	
0	Erase mode cleared	(Initial value)
1	Transition to erase mode [Setting condition] When FWE = 1, SWE = 1, and ESU = 1	



Bit 0—Program (P) *1*3: Selects program mode transition or clearing. Do not set the SWE, ESU, PSU, EV, PV, or E bit at the same time.

В	it	0	:

Р	Description	
0	Program mode cleared	(Initial value)
1	Transition to program mode [Setting condition] When FWE = 1, SWE = 1, and PSU = 1	

Notes: 1. Do not set two or more bits at the same time.

Do not turn off V_{cc} when a bit is set.

- 2. Do not set/clear the SWE bit simultaneously with other bits (ESU, PSU, EV, PV, E, P).
- 3. Set the P and E bits according to the program and erase algorithms shown in section 18.5, Programming and Erasing Flash Memory.

For the usage precautions, see section 18.9, Notes on Flash Memory Programming/Erasing.

18.3.2 Erase Block Register (EBR)

EBR is an 8-bit register that designates the flash memory block for erasure. EBR is initialized to H'00 by a reset, in hardware standby mode, or software standby mode, when a high level is not input to the FWE terminal, or when the FLMCR SWE bit is 0 when a high level is applied to the FWE terminal. When a bit is set in EBR, the corresponding block can be erased. Other blocks are erase - protected. The blocks are erased block by block. Therefore, set only one bit in EBR; do not set bits in EBR to erase two or more blocks at the same time.

Each bit in EBR cannot be set until the SWE bit in FLMCR is set. The flash memory block configuration is shown in table 18.4. To erase all the blocks, erase each block sequentially.

The H8/3067 Group does not support the on-board programming mode in mode 6, so bits in this register cannot be set to 1 in mode 6.

	Bit	7	6	5	4	3	2	1	0
		EB7	EB6	EB5	EB4	EB3	EB2	EB1	EB0
Modes 1	Initial value	0	0	0	0	0	0	0	0
to 4, and 6	R/W	R	R	R	R	R	R	R	R
Modes 5	Initial value	0	0	0	0	0	0	0	0
and 7	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Bits 7 to 0—Block 7 to 0 (EB7 to EB0): These bits select blocks (EB7 to EB0) to be erased.

Bits 7 to 0:

EB7 to EB0 Description

0	Block EB7 to EB0 is not selected.	(Initial value)
1	Block EB7 to EB0 is selected.	

Note: Set each bit of EBR to H'00 except when erasing.

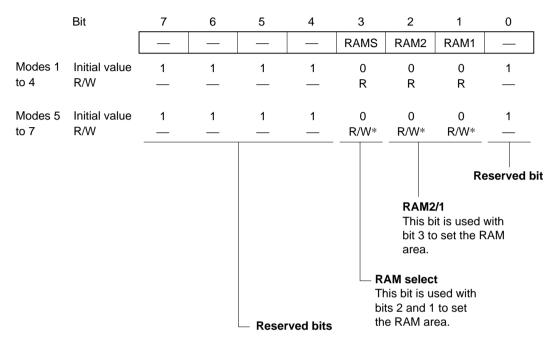
Table 18.4 Flash Memory Erase Blocks

Block (Size)	Address
EB0 (1 kB)	H'000000 to H'0003FF
EB1 (1 kB)	H'000400 to H'0007FF
EB2 (1 kB)	H'000800 to H'000BFF
EB3 (1 kB)	H'000C00 to H'000FFF
EB4 (28 kB)	H'001000 to H'007FFF
EB5 (32 kB)	H'008000 to H'00FFFF
EB6 (32 kB)	H'010000 to H'017FFF
EB7 (32 kB)	H'018000 to H'01FFFF



18.3.3 RAM Control Register (RAMCR)

RAMCR selects the RAM area used when emulating real-time reprogramming of the flash memory.



Note: Cannot be set to 1 in mode 6.

Bits 7 to 4—Reserved: These bits cannot be modified and are always read as 1.

Bit 3—RAM Select (RAMS): Is used with bits 2 to 1 to reassign an area to RAM (see table 18.5). The initial setting for this bit is 0 in Modes 5, 6, and 7 (internal flash memory enabled) and programming is enabled.* In modes other than 5 to 7, 0 is always read and writing is disabled. It is initialized by a reset and in hardware standby mode. It is not initialized in software standby mode.

When bit 3 is set, all flash-memory blocks are protected from programming and erasing.

Bits 2 to 1—RAM2 to RAM1: These bits are used with bit 3 to reassign an area to RAM (see table 18.5). The initial setting for this bit is 0 in Modes 5, 6, and 7 (internal flash memory enabled) and programming is enabled.* In modes other than 5 to 7, 0 is always read and writing is disabled. They are initialized by a reset and in hardware standby mode. They are not initialized in software standby mode.

Bit 0—Reserved: This bit cannot be modified and is always read as 1.

Note: * Flash memory emulation by RAM is not supported for Mode 6 (single chip normal mode), so programming is possible, but do not set 1.

When performing flash memory emulation by RAM, the RAME bit in SYSCR must be set to 1.

Table 18.5 RAM Area Reassignment

	Bit 3	Bit 2	Bit 1	RAM
RAM Area	RAMS	RAM2	RAM1	Emulation State
H'FFF000 to H'FFF3FF	0	0/1	0/1	No emulation
H'000000 to H'0003FF	1	0	0	Mapping RAM
H'000400 to H'0007FF	1	0	1	
H'000800 to H'000BFF	1	1	0	
H'000C00 to H'000FFF	1	1	1	

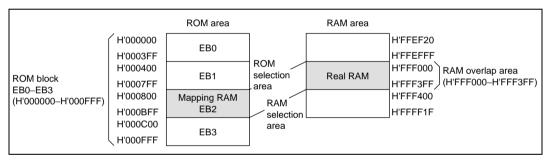
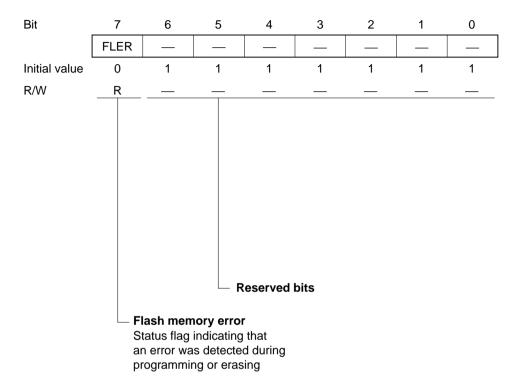


Figure 18.2 Example of Overlap ROM Area and RAM Area

18.3.4 Flash Memory Status Register

The flash memory status register (FLMSR) detects flash memory errors.



Bit 7—Flash Memory Error (FLER): Indicates that an error occurred while flash memory was being programmed or erased. When bit 7 is set, flash memory is placed in an error-protect mode.

Bit 7 FLER	Description				
0	Flash memory program/erase protection (error protection *1) is disabled (Initial value)				
	[Clearing conditions]				
	WDT reset, reset by RES pin, or hardware standby mode				
1	An error has occurred during flash memory programming/erasing Flash memory program/erase protection (error protection *1) is enabled				
	[Setting conditions]				
	 Flash memory was read*2 while being programmed or erased (including vector or instruction fetch, but not including reading of a RAM area overlapped onto flash memory). 				
	 A hardware exception-handling sequence (other than a reset, invalid instruction, trap instruction, or zero-divide exception) was executed just before programming or erasing.*3 				
	The SLEEP instruction (including software standby mode) was executed during programming or erasing.				

Notes: 1. For details, see section 18.6.3, Error Protection.

- 2. The read data has undetermined values.
- 3. Before stack and vector read by exception handling.

Bits 6 to 0—Reserved: These bits cannot be modified and are always read as 1.

18.4 On-Board Programming Modes

When pins are set to on-board programming mode, program/erase/verify operations can be performed on the on-chip flash memory. There are two on-board programming modes: boot mode and user program mode. The pin settings for transition to each of these modes are shown in table 18.6. In H8/3067RF mode 6 (on-chip ROM enabled), the boot mode and user program mode cannot be used. For the notes on FWE pin set/reset, see section 18.9 Notes on Flash Memory Programming/Erasing.

Table 18.6 Setting On-Board Programming Modes

Mode		FWE	MD_2	$MD_{_1}$	MD_{o}	Notes
Boot mode	mode 5	1*1	0*2	0	1	0 : V _{IL}
	mode 7		0*2	1	1	1 : V _{IH}
User program mode	mode 5		1	0	1	
	mode 7		1	1	1	

Notes: 1. For the High level input timing, see items (6) and (7) of Notes on Using the Boot Mode.

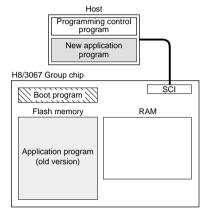
2. In the boot mode, the MD₂ setting becomes inverted input.
In the boot mode in the H8/3067 F-ZTAT™, the levels of the mode pins (MD₂ to MD₀) are reflected in mode select bits 2 to 0 (MDS2 to MDS0) in the mode control register (MDCR). Note that this specification differs from that of the H8/3039F Group.

On-Board Programming Modes

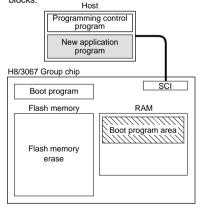
Boot mode

1. Initial state

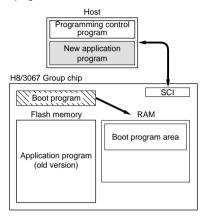
The flash memory is in the erased state when the device is shipped. The description here applies to the case where the old program version or data is being rewritten. The user should prepare the programming control program and new application program beforehand in the host.



Flash memory initialization
 The erase program in the boot program area (in RAM) is executed, and the flash memory is initialized (to H'FF). In boot mode, entire flash memory erasure is performed, without regard to blocks.



Programming control program transfer
When boot mode is entered, the boot program in
the H8/3067 Group chip (originally incorporated
in the chip) is started, an SCI communication
check is carried out, and the boot program
required for flash memory erasing is
automatically transferred to the RAM boot
program area.



Writing new application program
 The programming control program transferred from the host to RAM by SCI communication is executed, and the new application program in the host is written into the flash memory.

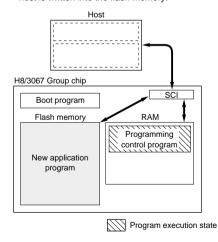
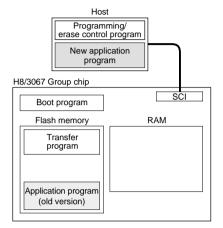


Figure 18.3 Boot Mode

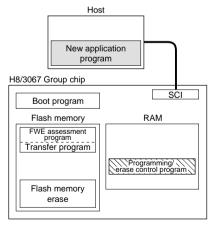
User program mode

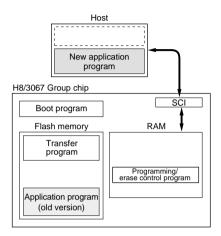
- 1. Initial state
 - (1) The program that will transfer the programming/ erase control program to on-chip RAM should be written into the flash memory by the user beforehand. (2) The programming/erase control program should be prepared in the host or in the flash memory.
- Programming/erase control program transfer When the FWE pin is driven high, user software confirms this fact, executes the transfer program in the flash memory, and transfers the programming/erase control program to RAM.



3. Flash memory initialization

The programming/erase program in RAM is executed, and the flash memory is initialized (to H'FF). Erasing can be performed in block units, but not in byte units.





Writing new application program
 Next, the new application program in the host is
 written into the erased flash memory blocks. Do
 not write to unerased blocks.

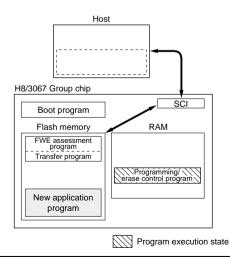


Figure 18.4 User Program Mode (Example)

18.4.1 Boot Mode

When boot mode is used, the flash memory programming control program must be prepared in the host beforehand. The channel 1 SCI to be used is set to asynchronous mode.

In reset start, after setting this LSI pin to the boot mode, start the microcomputer boot program, measure the Low period of the data sent from the host, and select the bit rate register (BRR) value beforehand. Then enable reception of the user program from the outside using the serial communication interface (SCI) on this LSI, and write the received user program to on-chip RAM.

After the program has been stored the end of writing, execution branches to the top address (H'FFF400) of the on-chip RAM, execute the program written on the on-chip RAM, and enable flash memory program/erase.

The system configuration in boot mode is shown in figure 18.5, and the boot program mode execution procedure in figure 18.6.

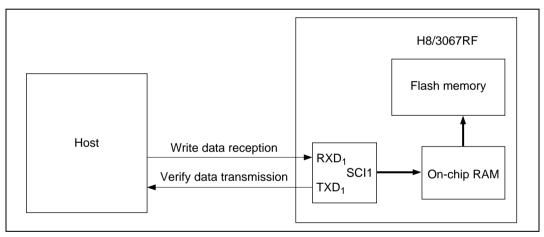


Figure 18.5 System Configuration in Boot Mode

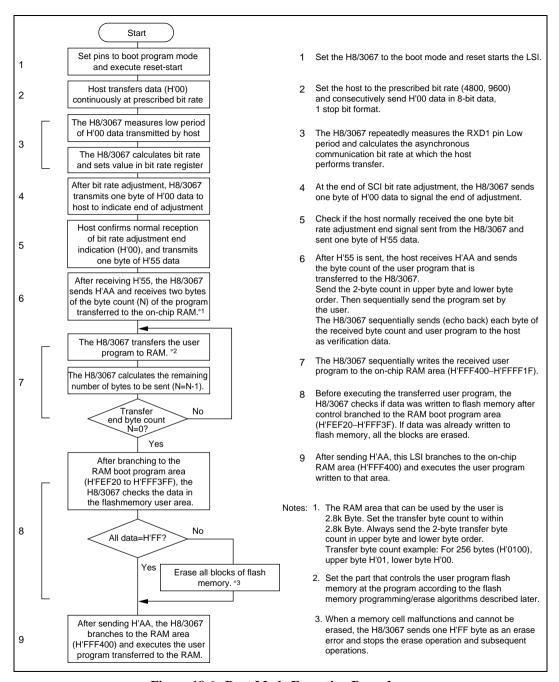


Figure 18.6 Boot Mode Execution Procedure

Automatic SCI Bit Rate Adjustment

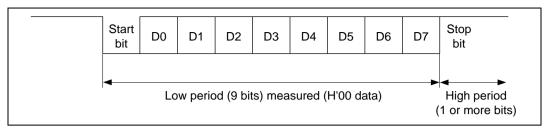


Figure 18.7 Measuring the low period of the communication data from the host

When boot mode is initiated, this LSI measures the low period of the asynchronous SCI communication data (H'00) transmitted continuously from the host (figure 18.7). The SCI transmit/receive format should be set as follows: 8-bit data, 1 stop bit, no parity. This LSI calculates the bit rate of the transmission from the host from the measured low period, and transmits one H'00 byte to the host to indicate the end of bit rate adjustment. The host should confirm that this adjustment end indication (H'00) has been received normally, and transmit one H'55 byte to the LSI. If reception cannot be performed normally, initiate boot mode again (reset), and repeat the above operations. Depending on the host's transmission bit rate and the system clock frequency of this LSI, there will be a discrepancy between the bit rates of the host and the LSI. To ensure correct SCI operation, the host's transfer bit rate should be set to 4800 and 9600 bps.*1

Table 18.7 shows typical host transfer bit rates and system clock frequencies for which automatic adjustment of this LSI bit rate is possible. The boot program should be executed within this system clock range*2.

Table 18.7 System Clock Frequencies for which Automatic Adjustment of This LSI Bit Rate is Possible

Host Bit Rate (bps)	System Clock Frequency for which Automatic Adjustment of This LSI Bit Rate is Possible (MHz)
9600	8 to 20
4800	4 to 20

Notes: 1. The host bit rate settings are 4800 and 9600bps only. Do not use any other setting.

 This LSI may automatically adjusts the bit rate except for bit rate and system clock combinations as shown in Table 18.7. However, the bit rate of the host and this LSI will be different and subsequent transfers will not be carried out normally. Therefore, always execute the boot mode within the range of the bit rate and system clock combinations shown in Table 18.7.



On-Chip RAM Area Divisions in Boot Mode: In boot mode, the RAM area is divided into an area used by the boot program and an area to which the user program is transferred via the SCI, as shown in figure 18.8. The boot program area can be used when a transition is made to the execution state for the user program transferred to RAM.

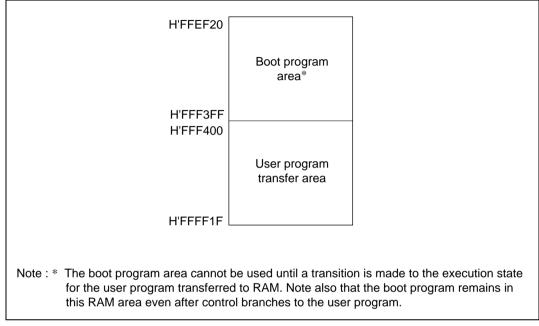


Figure 18.8 RAM Areas in Boot Mode

Notes on using the boot mode

- (1) When this LSI comes out of reset in boot mode, it measures the low period the input at the SCI's RXD₁ pin. The reset should end with RXD₁ high. After the reset ends, it takes about 100 states for this LSI to get ready to measure the low period of the RXD₁ input.
- (2) If any data has been written to the flash memory (if all data is not H'FF), all flash memory blocks are erased when this mode is executed. Therefore, boot mode should be used for initial on-board programming, or for forced recovery if the program to be activated in user program mode is accidentally erased and user program mode cannot be executed, for example.
- (3) Interrupts cannot be used during programming or erasing of flash memory.
- (4) The RXD₁ and TXD₁ pins should be pulled up on the board.

- (5) This LSI terminates transmit and receive operations by the on-chip SCI(channel 1) (by clearing the RE and TE bits in serial control register (SCR)) before branching to the user program. However, the adjusted bit rate is held in the bit rate register (BRR). At this time, the TXD₁ pin is in the high level output state (P9DDR P9₁DDR=1, P9DR P9₁DR=1).

 Before branching to the user program the value of the general registers in the CPU are also
 - undefined. Therefore, the general registers must be initialized immediately after control branches to the user program. Since the stack pointer (SP) is implicitly used during subroutine call, etc., a stack area must be specified for use by the user program.
 - There are no other internal I/O registers in which the initial value is changed.
- (6) Transition to the boot mode executes a reset-start of this LSI after setting the MD0 to MD2 and FWE pins according to the mode setting conditions shown in Table 18.6.
 - At this time, this LSI latches the status of the mode pin inside the microcomputer to maintain the boot mode status at the reset clear (startup with Low -> High) timing *1.
 - To clear boot mode, it is necessary to drive the FWE pin low during the reset, and then execute reset release*1. The following points must be noted:
 - (a) Before making a transition from the boot mode to the regular mode, the microcomputer boot mode must be reset by reset input via the \overline{RES} pin. At this time, the \overline{RES} pin must be hold at low level for at least 20 system clock. *3
 - (b) Do not change the input levels at the mode pins (MD₂ to MD₀) or the FWE pin while in boot mode. When making a mode transition, first enter the reset state by inputting a low level to the RES pin. When a watchdog timer reset was generated in the boot mode, the microcomputer mode is not reset and the on-chip boot program is restarted regardless of the state of the mode pin.
 - (c) Do not input low level to the FWE pin while the boot program is executing and when programming/erasing flash memory. *2
- (7) If the mode pin and FWE pin input levels are changed from 0 V to V_{cc} or from V_{cc} to 0V during a reset (while a low level is being input to the \overline{RES} pin), the microcomputer's operating mode will change.
 - Therefore, since the state of the address dual port and bus control output signals (\overline{AS} , \overline{RD} , \overline{HWR} , \overline{LWR}) changes, use of these pins as output signals during reset must be disabled outside the microcomputer.
- Notes: 1. The mode pin and FWE pin input must satisfy the mode programming setup time (t_{MDS}) relative to the reset clear timing.
 - 2. For notes on FWE pin High/Low, see section 18.9, Notes on Flash Memory Programming/Erasing.
 - 3. See section 4.2.2, Reset Sequence and 18.9, Notes on Flash Memory Programming/Erasing. With the mask ROM version of the H8/3067, H8/3066, and H8/3065, the minimum reset period during operation is 10 system clocks. However, the



flash memory and flash memory R versions of the H8/3037 requires a minimum of 20 system clocks.

18.4.2 User Program Mode

When set to the user program mode, this LSI can erase and program its flash memory by executing a user program. Therefore, on-chip flash memory on-board programming can be performed by providing a means of controlling FWE and supplying the write data on the board and providing a write program in a part of the program area.

To select this mode, set the LSI to on-chip ROM enable modes 5 and 7 and apply a high level to the FWE pin. In this mode, the peripheral functions, other than flash memory, are performed the same as in modes 5 and 7.

In mode 6, do not program/erase the flash memory. When setting mode 6, always input low level to the FWE pin.

Since the flash memory cannot be read while it is being programmed/erased, place a programming program on external memory, or transfer the programming program to RAM area, and execute it in the RAM.

Figure 18.9 shows the procedure for executing when transferred to on-chip RAM. During reset start, starting from the user program mode is possible.

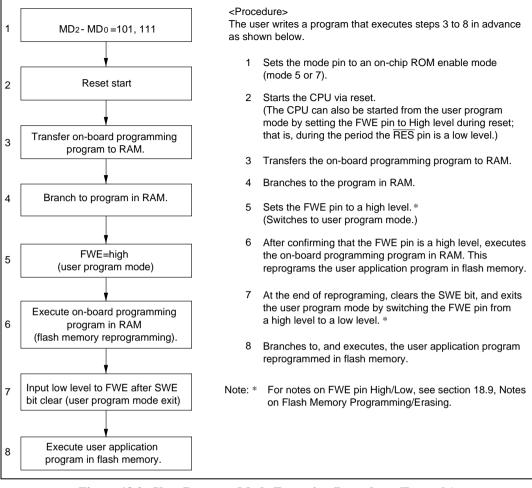


Figure 18.9 User Program Mode Execution Procedure (Example)

- Notes: 1. Normally do not apply a high level to the FWE pin. To prevent erroneous programming or erasing in the event of program runaway, etc., apply a high level to the FWE pin only when programming/erasing flash memory (including flash memory emulation by RAM). If program runaway, etc. causes overprogramming or overerasing of flash memory, the memory cells will not operate normally.

 Also, while a high level is applied to the FWE pin, the watchdog timer should be activated to prevent overprogramming or overerasing due to program runaway, etc.
 - 2. In mode 6, do not reprogram flash memory. When setting mode 6, always set the FWE pin to a low level.

18.5 Programming/Erasing Flash Memory

A software method, using the CPU, is employed to program and erase flash memory in the on-board programming modes. There are four flash memory operating modes: program mode, erase mode, program-verify mode, and erase-verify mode. Transitions to these modes can be made by setting the PSU, P, E, PV, and EV bits in FLMCR.

For a description of state transition by FLMCR bit setting, see figure 18.10.

The flash memory cannot be read while being programmed or erased. Therefore, the program that controls flash memory programming/erasing (the programming control program) should be located and executed in on-chip RAM or external memory.

For the programming/erasing notes, see section 18.9, Notes on Flash Memory Programming/Erasing. For the wait time after each bit in FLMCR is set or cleared, see section 21.2.6, Flash Memory Characteristics.

- Notes: 1. Operation is not guaranteed if setting/resetting of the SWE, ESU, PSU, EV, PV, E, and P bits in FLMCR is executed by a program in flash memory.
 - 2. When programming or erasing, set the FWE pin input level to the high level, and set FWE to 1. (programming/erasing will not be executed if FWE = 0).

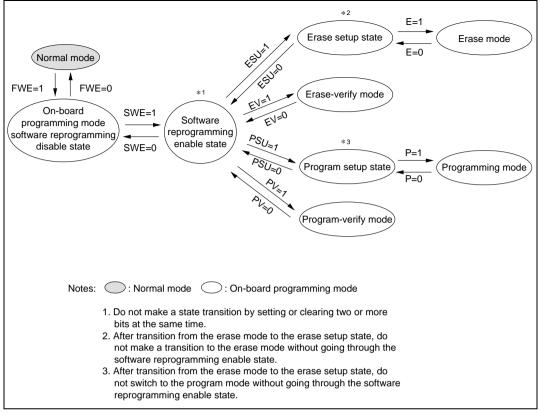


Figure 18.10 State Transition by Setting of Each Bit of FLMCR

18.5.1 Program Mode

Follow the procedure shown in the program/program-verify flowchart in figure 18.11 to write data or programs to flash memory. Performing program operations according to this flowchart will enable data or programs to be written to flash memory without subjecting the device to voltage stress or sacrificing program data reliability. Programming should be carried out 32 bytes at a time.

For the wait time $(x, y, z, \alpha, \beta, \gamma, \epsilon, \eta)$ after setting or clearing each bit in the flash memory control register (FLMCR) and the maximum programming count (N), see table 21.19 in section 21.2.6, Flash Memory Characteristics.

Following the elapse of (x) µs or more after the SWE bit is set to 1 in flash memory control register (FLMCR), 32-byte program data is stored in the program data area and reprogram data area, and the 32-byte data in the reprogram data area written consecutively to the write addresses.



(The lower 8 bits of the first address written to must be H'00, H'20, H'40, H'60, H'80, H'A0, H'C0, or H'E0.) 32 consecutive byte data transfers are performed. The program address and program data are latched in the flash memory. A 32-byte data transfer must be performed even if writing fewer than 32 bytes; in this case, H'FF data must be written to the extra addresses.

Next, the watchdog timer (WDT) is set to prevent overprogramming due to program runaway, etc. Set a value greater than $(y + z + \alpha + \beta)$ µs as the WDT overflow period. Preparation for entering program mode (program setup) is performed next by setting the PSU bit in FLMCR. The operating mode is then switched to program mode by setting the P bit in FLMCR after the elapse of at least (y) µs.

The time while the P bit is set is the flash memory programming time. Make a program setting so that the time for one programming operation is within the range of (z) μ s.

The wait time after P bit setting must be changed according to the number of reprogramming loops. For details, see section 21.2.6, Flash Memory Characteristics.

18.5.2 Program-Verify Mode

In program-verify mode, the data written in program mode is read to check whether it has been correctly written in the flash memory.

Clear the P bit in FLMCR, then wait for at least (α) µs before clearing the PSU bit to exit program mode. After exiting program mode, the watchdog timer setting is also cleared. Then the operating mode is switched to program-verify mode by setting the PV bit in FLMCR. Before reading in program-verify mode, a dummy write of H'FF data should be made to the addresses to be read. The dummy write should be executed after the elapse of (γ) µs or more. When the flash memory is read in this state (verify data is read in 16-bit units), the data at the latched address is read. Wait at least (ϵ) µs after the dummy write before performing this read operation. Next, the originally written data is compared with the verify data, and reprogram data is computed (see figure 18.11) and transferred to RAM. After verification of 32 bytes of data has been completed, exit program-verify mode, wait for at least (η) µs, then determine whether 32-byte programming has finished. If reprogramming is necessary, set program mode again, and repeat the program/program-verify sequence as before. However, ensure that the program/program-verify sequence is not repeated more than (N) times on the same bits.

Note: A 32-byte area to store program data and a 32-byte area to store reprogram data are required in RAM.

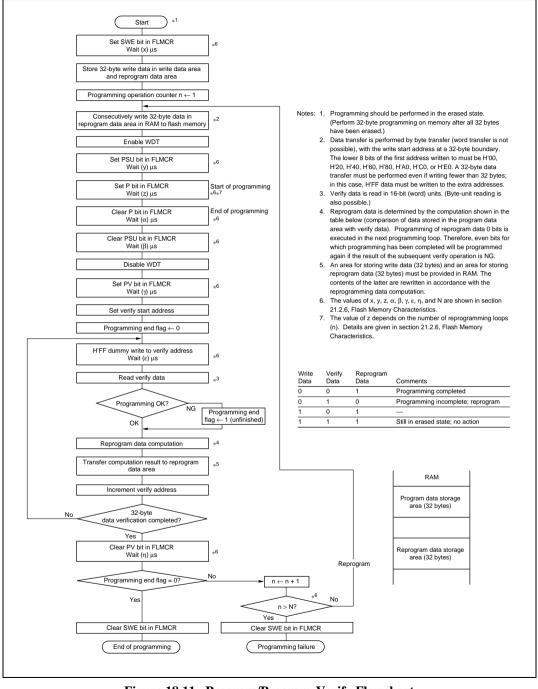


Figure 18.11 Program/Program-Verify Flowchart

18.5.3 Erase Mode

Flash memory erasing should be performed block by block following the procedure shown in the erase/erase-verify flowchart (single-block erase) shown in figure 18.12.

For the wait time $(x, y, z, \alpha, \beta, \gamma, \epsilon, \eta)$ after setting or clearing of each bit in the flash memory control register (FLMCR and the maximum erase count (N)), see table 21.19 of section 21.2.6, Flash Memory Characteristics.

To erase the contents of flash memory, make a 1 bit setting for the flash memory area to be erased in erase block register (EBR) at least (x) μ s after setting the SWE bit to 1 in FLMCR. Next, the watchdog timer (WDT) is set to prevent overerasing due to program runaway, etc. Set a value greater than (z) ms + (y + α + β) μ s as the WDT overflow period. Preparation for entering erase mode (erase setup) is performed next by setting the ESU bit in FLMCR. The operating mode is then switched to erase mode by setting the E bit in FLMCR after the elapse of at least (y) μ s.

The time during which the E bit is set is the flash memory erase time. Ensure that the erase time does not exceed (z) ms.

Note: With flash memory erasing, preprogramming (setting all data in the memory to be erased to "0") is not necessary before starting the erase procedure.

18.5.4 Erase-Verify Mode

In erase-verify mode, data is read after memory has been erased to check whether it has been correctly erased.

After the elapse of the fixed erase time, clear the E bit in FLMCR, then wait for at least (α) μ s before clearing the ESU bit to exit erase mode. After exiting erase mode, the watchdog timer setting is also cleared. The operating mode is then switched to erase-verify mode by setting the EV bit in FLMCR. Before reading in erase-verify mode, a dummy write of H'FF data should be made to the addresses to be read. The dummy write should be executed after the elapse of (γ) μ s or more. When the flash memory is read in this state (verify data is read in 16-bit units), the data at the latched address is read. Wait at least (ϵ) μ s after the dummy write before performing this read operation. If the read data has been erased (all "1"), a dummy write is performed to the next address, and erase-verify is performed. If the read data is unerased, set erase mode again, and repeat the erase/erase-verify sequence as before. However, do not repeat the erase/erase-verify sequence more than (N) times.

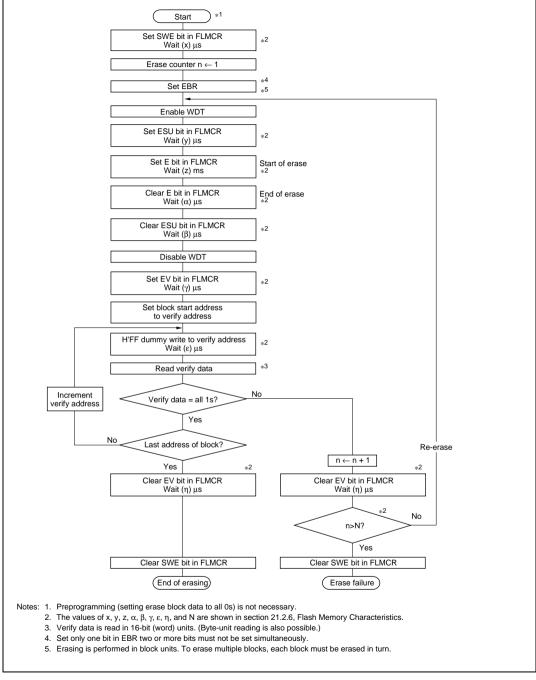


Figure 18.12 Erase/Erase-Verify Flowchart (Single-Block Erasing)

18.6 Flash Memory Protection

There are three kinds of flash memory program/erase protection: hardware protection, software protection, and error protection.

18.6.1 Hardware Protection

Hardware protection refers to a state in which programming/erasing of flash memory is forcibly disabled or aborted. Hardware protection is reset by settings in the flash memory control register (FLMCR) and erase block register (EBR). In the case of error protection, the P bit and E bit can be set, but a transition is not made to program mode or erase mode. (See table 18.8.)

Table 18.8 Hardware Protection

		Function		
Item	Description	Program	Erase	Verify*1
FWE pin protection	 When a low level is input to the FWE pin, FLMCR and EBR are initialized, and the program/erase-protected state is entered.**4 	No ^{*2}	No ^{*3}	No
Reset/standby protection	 In a reset (including a WDT overflow reset) and in standby mode, FLMCR and EBR are initialized, and the program/erase-protected state is entered. In a reset via the RES pin, the reset state is not entered unless the RES pin is held low until oscillation stabilizes after powering on (The minimum oscillation stabilization time is 20ms). In the case of a reset during operation, hold the RES pin low for at least 20 system clock cycles. 		No ^{*3}	No
Error protection	• When a microcomputer operation error (error generation (FLER=1)) was detected while flash memory was being programmed/erased, error protection is enabled. At this time, the FLMCR and EBR settings are held, but programming/erasing is aborted at the time the error was generated. Error protection is released only by a reset via the RES pin or a WDT reset, or in the hardware standby mode.	No I	No ^{*3}	Yes

Notes: 1. Two modes: program-verify and erase-verify.

- 2. The RAM area that overlapped flash memory is deleted.
- 3. All blocks become unerasable and specification by block is impossible.
- 4. For more information, see section 18.9, Notes on Flash Memory Programming/Erasing.
- See sections 4.2.2, Reset Sequence and 18.9, Notes on Flash Memory Programming/Erasing. The H8/3067RF requires a minimum reset time during operation of 20 system clocks.



18.6.2 Software Protection

Software protection can be implemented by setting the RAMS bit in RAM control register (RAMCR) and erase block register (EBR). When software protection is in effect, setting the P or E bit in flash memory control register (FLMCR) does not cause a transition to program mode or erase mode. (See table 18.9.)

Table 18.9 Software Protection

		Function		
Item	Description	Program	Erase	Verify*1
Emulation protection*2	Setting the RAMS bit in RAMCR sets the program/erase-protected state for all blocks.	No ^{*2}	No*3	Yes
Block specification protection	 Erase protection can be set for individual blocks by settings in erase block register (EBR).*4 	_	No	Yes
	However, program protection is disabled.			
	 Setting EBR to H'00 places all blocks in the erase-protected state. 			

Notes: 1. Two modes: program-verify mode and erase-verify mode.

- 2. Programming to the RAM area that overlaps flash memory is possible.
- 3. All blocks become unerasable, and specification by block is impossible.
- 4. Set H'00 in the EBR bits, except for erase.

18.6.3 Error Protection

In error protection, an error is detected when this LSI runaway occurs during flash memory programming/erasing*1, or operation is not performed in accordance with the program/erase algorithm, and the program/erase operation is aborted. Aborting the program/erase operation prevents damage to the flash memory due to overprogramming or overerasing.

If the LSI malfunctions during flash memory programming/erasing, the FLER bit*2 is set to 1 in flash memory status register (FLMSR) and the error protection state is entered. The FLMCR and EBR settings*3 are retained, but program mode or erase mode is aborted at the point at which the error occurred. When 1 is set in the FLER bit, transition to the program mode or erase mode cannot be made even by setting the P and E bits in FLMCR. However, PV and EV bit in FLMCR setting is enabled, and a transition can be made to verify mode.

Error protection is released only by a reset via the \overline{RES} pin or a WDT reset, or in the hardware standby mode.

Figure 18.13 shows the flash memory state transition diagram.

- Notes: 1. This is the state in which the P or E bit in FLMCR is set to 1. In this state, NMI input is disabled. For more information, see section 18.6.4, NMI Input Disable Conditions.
 - 2. For a detailed description of the FLER bits setting conditions, see section 18.3.4, Flash Memory Status Register (FLMSR).
 - 3. Data can be written to FLMCR and EBR. However, when transition to the software standby mode was made in the error protection state, the registers are initialized.



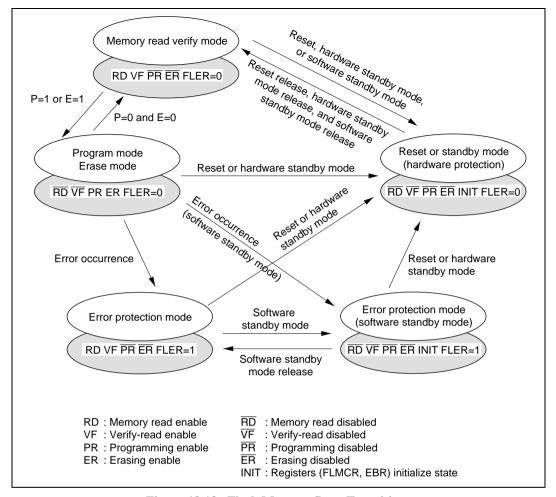


Figure 18.13 Flash Memory State Transitions (When High level apply to FWE pin in modes 5 and 7 (on-chip ROM enabled))

The error protection function is disabled for errors other than the FLER bit set conditions. If considerable time elapses up to transit to this protection state, the flash memory may already be damaged. As a result, this function cannot completely protect the flash memory against damage.

Therefore, to prevent such erroneous operation, operation must be carried out correctly in according with the program/erase algorithms in the state that flash write enable (FWE) is set. In addition, the operation must be always carried out correctly by supervising microcomputer errors inside and outside the chip with the watchdog timer, etc. At transition to this protection mode, the flash memory may be erroneously programmed or erased, or its abort may result in incomplete

programming and erasing. In such cases, always forcibly return (reprogram) by boot mode. However, overprogramming and overerasing may prevent the boot mode from starting normally.

18.6.4 NMI Input Disable Conditions

While flash memory is being programed/erased and the boot program is executing in the boot mode (however, period up to branching to on-chip RAM area)*1, NMI input is disabled because the programming/erasing operations have priority.

This is done to avoid the following operation states:

- 1. Generation of an NMI input during programming/erasing violates the program/erase algorithms and normal operation can not longer be assured.
- 2. Verify-read cannot be carried out normally*2 during NMI exception handling during programming/erasing and the microcomputer runs away as a result.
- 3. If an NMI input is generated during boot program execution, the normal boot mode sequence cannot be executed.

Therefore, this LSI has conditions that exceptionally disable NMI inputs only in the on-board programming mode. However, this does not assure normal programming/erasing and microcomputer operation.

Thus, in the FWE application state, all requests, including NMI, inside and outside the microcomputer, exception handling, and bus release must be restricted. NMI inputs are also disabled in the error protection state and the state that holds the P or E bit in FLMCR during flash memory emulation by RAM.

- Notes: 1. Indicates the period up to branching to the on-chip RAM boot program area (H'FEF20–H'FFF3F). (This branch occurs immediately after user program transfer was completed.)
 - Therefore, after branching to RAM area, NMI input is enabled in states other than the program/erase state. Thus, interrupt requests inside and outside the microcomputer must be disabled until initial writing by user program (writing of vector table and NMI processing program, etc.) is completed.
 - 2. In this case, vector read is not performed normally for the following two reasons:
 - a. The correct value cannot be read even by reading the flash memory during programming/erasing. (Value is undefined.)
 - b. If a value has not yet been written to the NMI vector table, NMI exception handling will not be performed correctly.



18.7 Flash Memory Emulation by RAM

Erasing and programming the flash memory takes time, which can make it difficult to tune parameters and other data in real time. In this case, overlapping part (H'FFF000 to H'FFF3FF) of RAM onto a small block area of flash memory can be performed to emulate real-time reprogramming of flash memory. This RAM reassignment is performed using bits 3 to 1 in the RAM control register (RAMCR).

After the RAM area change, two areas can be accessed: the overlapped flash memory area and the original RAM area (H'FFF000 to H'FFF3FF). For a description of the RAMCR and RAM area setting procedure, see section 18.3.3 RAM Control Register (RAMCR).

Example of real-time emulation of flash memory

An example of RAM area H'FFF000 to H'FFF3FF overlapping EB2 (H'000800 to H'000BFF) flash memory area is shown below.

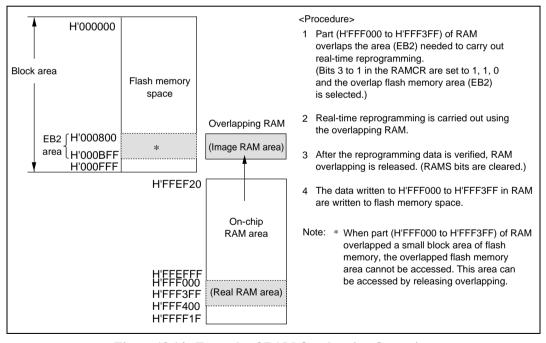


Figure 18.14 Example of RAM Overlapping Operation

Notes on use of the RAM emulation function

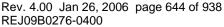
(1) Notes on flash write enable (FWE) high/low

Care is necessary to prevent erroneous programming/erasing at FWE=high/low, the same as in the on-board programming mode. To prevent erroneous programming and erasing due to program runaway, etc., during FWE application, in particular, the watchdog timer should be set when the PSU, P, ESU, or E bit is set to 1 in FLMCR, even while the emulation function is being used. For more information, see section 18.9, Notes on Flash Memory Programming/Erasing.

(2) NMI input disable conditions

When the P and E bits in FLMCR are set, NMI input is disabled, the same as normal program/erase even when using the emulation function.

NMI input is cleared when the P and E bits are reset (including watchdog timer reset), in the standby mode, when a high level is not applied to FWE, and when the SWE bit in FLMCR is 0 in state in which a high level is input to FWE.





18.8 Flash Memory PROM Mode

18.8.1 PROM Mode Setting

This LSI has a PROM mode, besides an on-board programming mode, as a flash memory program/erase mode. In the PROM mode, a program can be freely written to the on-chip ROM using a PROM writer that supports the Renesas 128kbytes flash memory on-chip microcomputer device type.

For notes on PROM mode use, see sections 18.8.9, Notes on Memory Programming and 18.9, Notes on Flash Memory Programming/Erasing.

18.8.2 Memory Map

Figure 18.15 shows the PROM mode memory map.

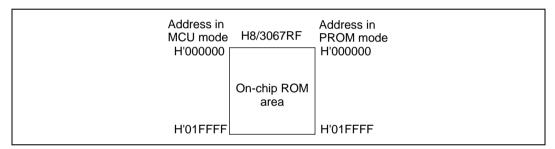


Figure 18.15 PROM Mode Memory Map

18.8.3 PROM Mode Operation

Table 18.10 shows how the different operating modes are set when using PROM mode, and table 18.11 lists the commands used in PROM mode. Details of each mode are given below.

- Memory Read Mode
 Memory read mode supports byte reads.
- Auto-Program Mode
 Auto-program mode supports programming of 128 bytes at a time. Status polling is used to confirm the end of auto-programming.
- Auto-Erase Mode
 Auto-erase mode supports automatic erasing of the entire flash memory. Status polling is used to confirm the end of auto-erasing.

Status Read Mode

Status polling is used for auto-programming and auto-erasing, and normal termination can be confirmed by reading the I/O 6 signal. In status read mode, error information is output if an error occurs.

Table 18.10 Settings for Each Operating Mode in PROM Mode

Pin Names*3

Mode	FWE	CE	ŌĒ	WE	D ₀ to D ₇	A ₀ to A ₁₇
Read	V _{cc} or 0	L	L	Н	Data output	Ain
Output disable	V _{cc} or 0	L	Н	Н	Hi-Z	Х
Command write	V _{cc} or 0	L	Н	L	Data input	Ain*2
Chip disable*1	V _{cc} or 0	Н	Χ	Х	Hi-Z	X

L : Low level H : High level X : Undefined

Hi-Z: High impedance

Notes: For command writes when making a transition to auto-program or auto-erase mode, input Vcc (V) to FWE.

- 1. Chip disable is not a standby state; internally, it is an operation state.
- 2. Ain indicates that there is also address input in auto-program mode.
- 3. The pin names are those assigned in H8/3067RF PROM mode.

Table 18.11 PROM Mode Commands

		1st Cy	1st Cycle			2nd Cycle		
Command Name	Number of Cycles	Mode	Address	Data	Mode	Address	Data	
Memory read mode	1	Write	Х	H'00	Read	RA	Dout	
Auto-program mode	129	Write	Χ	H'40	Write	WA	Din	
Auto-erase mode	2	Write	Χ	H'20	Write	Х	H'20	
Status read mode	2	Write	X	H'71	Write	Χ	H'71	

RA : Read address

WA : Program address

Dout : Read data

Din : Program data

Note: In auto-program mode. 129 cycles are required for command writing by a simultaneous

128-byte write.



Table 18.12 DC Characteristics in Memory Read Mode

(Conditions: $V_{cc} = 5.0 \text{ V} \pm 10\%$, $V_{ss} = 0 \text{ V}$, $T_a = 25^{\circ}\text{C} \pm 5^{\circ}\text{C}$)

Item		Symbol	Min	Тур	Max	Unit	Test Conditions
Input high voltage	0 ₇ -0 ₀ , A ₁₆ -A ₀	V _{IH}	2.2	_	Vcc + 0.3	V	
Input low voltage	0 ₇ -0 ₀ , A ₁₆ -A ₀	V _{IL}	0.3	_	0.8	V	
Schmitt trigger	$\overline{OE}, \overline{CE}, \overline{WE}$	$V_{\scriptscriptstyle T}^{\;-}$	1.0	_	2.5	V	
input voltage		V _T ⁺	2.0	_	3.5	V	
		$V_{T}^{+} - V_{T}^{-}$	0.4	_	_	V	
Output high voltage	0 ₇ 0 ₀	V _{OH}	2.4	_	_	V	Ι _{οΗ} = – 200 μΑ
Output low voltage	0 ₇ -0 ₀	V _{OL}	_	_	0.45	V	I _{OL} = 1.6 mA
Input leakage current	0 ₇ -0 ₀ , A ₁₆ -A ₀	I _u	_	_	2	μΑ	
V _{cc} current	Reading	Icc	_	40	65	mΑ	
	Programming	I _{cc}	_	50	85	mA	
	Erasing	I _{cc}	_	50	85	mΑ	

Note: For the absolute maximum ratings, see section 20.2.1, Absolute Maximum Ratings Exceeding the absolute maximum ratings may cause permanent damage to the chip.

18.8.4 Memory Read Mode

AC Characteristics

Table 18.13 AC Characteristics in Memory Read Mode Transition

(Conditions: $V_{cc} = 5.0 \text{ V} \pm 10\%$, $V_{ss} = 0 \text{ V}$, $T_a = 25^{\circ}\text{C} \pm 5^{\circ}\text{C}$)

Item	Symbol	Min	Max	Unit	Notes
Command write cycle	t _{nxtc}	20	_	μs	
CE hold time	t _{ceh}	0	_	ns	
CE setup time	t _{ces}	0	_	ns	
Data hold time	t _{dh}	50	_	ns	
Data setup time	t _{ds}	50	_	ns	
Write pulse width	t _{wep}	70	_	ns	
WE rise time	t _r	_	30	ns	
WE fall time	t _f	_	30	ns	

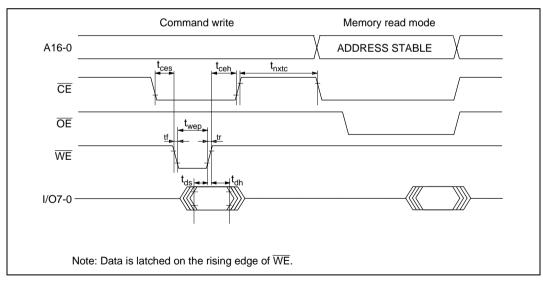
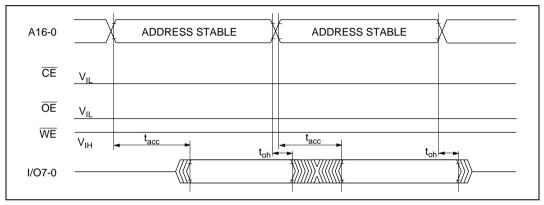


Figure 18.16 Timing Waveform in Memory Read Mode Transition

Table 18.14 AC Characteristics in Memory Contents Read

(Conditions: $V_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{SS} = 0 \text{ V}$, $T_a = 25^{\circ}\text{C} \pm 5^{\circ}\text{C}$)

Item	Symbol	Min	Max	Unit	Notes
Access time	t _{acc}	_	20	μs	
CE output delay time	t _{ce}	_	150	ns	
OE output delay time	t _{oe}	_	150	ns	
Output disable delay time	t _{df}	_	100	ns	
Data output hold time	t _{oh}	5	_	ns	



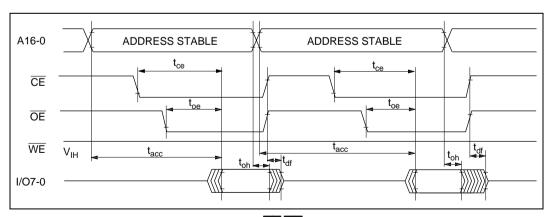


Figure 18.18 $\overline{CE}/\overline{OE}$ Clock Read

Table 18.15 AC Characteristics in Transition from Memory Read Mode to Another Mode

(Conditions: $V_{cc} = 5.0 \text{ V} \pm 10\%$, $V_{ss} = 0 \text{ V}$, $T_a = 25^{\circ}\text{C} \pm 5^{\circ}\text{C}$)

Item	Symbol	Min	Max	Unit	Notes
Command write cycle	t _{nxtc}	20	_	μs	
CE hold time	t _{ceh}	0	_	ns	
CE setup time	t _{ces}	0	_	ns	
Data hold time	t _{dh}	50	_	ns	
Data setup time	t _{ds}	50	_	ns	
Write pulse width	t _{wep}	70	_	ns	
WE rise time	t _r	_	30	ns	
WE fall time	t,	_	30	ns	

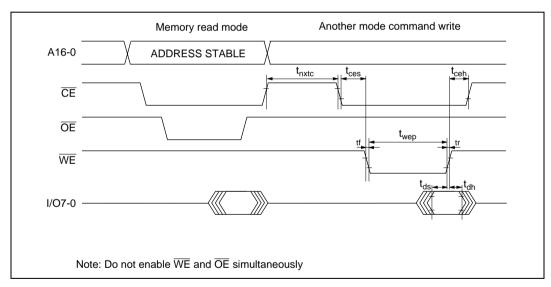


Figure 18.19 Transition From Memory Read Mode to Another Mode

18.8.5 Auto-Program Mode

AC Characteristics

Table 18.16 AC Characteristics in Auto-Program Mode

(Conditions: $V_{cc} = 5.0 \text{ V} \pm 10\%$, $V_{ss} = 0 \text{ V}$, $T_a = 25^{\circ}\text{C} \pm 5^{\circ}\text{C}$)

Item	Symbol	Min	Max	Unit	Notes
Command write cycle	t _{nxtc}	20	_	μs	
CE hold time	t _{ceh}	0	_	ns	
CE setup time	t _{ces}	0	_	ns	
Data hold time	t _{dh}	50	_	ns	
Data setup time	t _{ds}	50	_	ns	
Write pulse width	t_{wep}	70	_	ns	
Status polling start time	t _{wsts}	1	_	ms	
Status polling access time	t _{spa}	_	150	ns	
Address setup time	t _{as}	0	_	ns	
Address hold time	t_{ah}	60	_	ns	
Memory write time	t _{write}	1	3000	ms	
WE rise time	t _r	_	30	ns	
WE fall time	t _f	_	30	ns	
Write setup time	t _{pns}	100	_	ns	
Write end setup time	\mathbf{t}_{pnh}	100	_	ns	

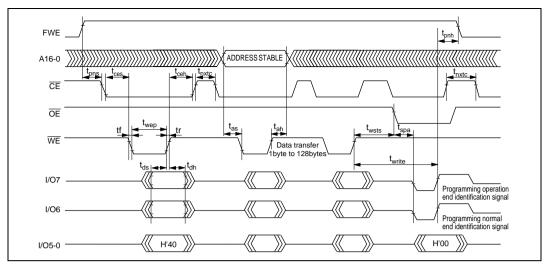


Figure 18.20 Auto-Program Mode Timing Waveforms

Cautions on Use of Auto-Program Mode

- In auto-program mode, 128 bytes are programmed simultaneously. This should be carried out by executing 128 consecutive byte transfers.
- A 128-byte data transfer is necessary even when programming fewer than 128 bytes. In this case, H'FF data must be written to the extra addresses.
- If a value other than an effective address is input, processing will switch to a memory write operation but a write error will be flagged.
- Memory address transfer is performed in the second cycle (figure 18.20). Do not perform transfer after the second cycle.
- Do not perform a command write during a programming operation.
- Perform one auto-programming operation for a 128-byte block for each address. Characteristics are not guaranteed for two or more programming operations.
- Confirm normal end of auto-programming by checking I/O 6. Alternatively, status read mode can also be used for this purpose.



18.8.6 Auto-Erase Mode

AC Characteristics

Table 18.17 AC Characteristics in Auto-Erase Mode

(Conditions: $V_{cc} = 5.0 \text{ V} \pm 10\%$, $V_{ss} = 0 \text{ V}$, $T_a = 25^{\circ}\text{C} \pm 5^{\circ}\text{C}$)

Item	Symbol	Min	Max	Unit	Notes
Command write cycle	t _{nxtc}	20	_	μs	
CE hold time	t _{ceh}	0	_	ns	
CE setup time	t _{ces}	0	_	ns	
Data hold time	t _{dh}	50	_	ns	
Data setup time	t _{ds}	50	_	ns	
Write pulse width	t _{wep}	70	_	ns	
Status polling start time	t _{ests}	1	_	ms	
Status polling access time	t _{spa}	_	150	ns	
Memory erase time	t _{erase}	100	40000	ms	
WE rise time	t _r	_	30	ns	
WE fall time	t _f	_	30	ns	
Erase setup time	t _{ens}	100	_	ns	
Erase end setup time	t _{enh}	100	_	ns	

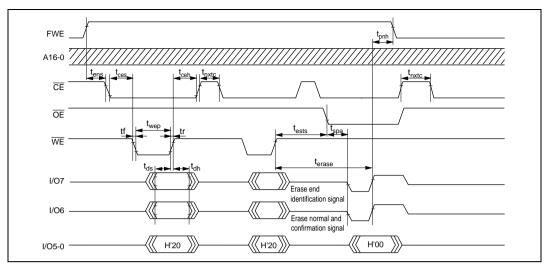


Figure 18.21 Auto-Erase Mode Timing Waveforms

Caution on Use of Erase-Program Mode

- Auto-erase mode supports only entire memory erasing.
- Do not perform a command write during auto-erasing.
- Confirm normal end of auto-erasing by checking I/O 6. Alternatively, status read mode can also be used for this purpose.

18.8.7 Status Read Mode

Table 18.18 AC Characteristics in Status Read Mode

(Conditions: $V_{cc} = 5.0 \text{ V} \pm 10\%$, $V_{ss} = 0 \text{ V}$, $T_a = 25^{\circ}\text{C} \pm 5^{\circ}\text{C}$)

Item	Symbol	Min	Max	Unit	Notes
Command write cycle	t _{nxtc}	20	_	μs	
CE hold time	$\mathbf{t}_{\sf ceh}$	0	_	ns	
CE setup time	t _{ces}	0	_	ns	
Data hold time	t _{dh}	50	_	ns	
Data setup time	t _{ds}	50	_	ns	
Write pulse width	\mathbf{t}_{wep}	70	_	ns	
OE output delay time	t _{oe}	_	150	ns	
Disable delay time	t _{df}	_	100	ns	
CE output delay time	t _{ce}	_	150	ns	
WE rise time	t _r	_	30	ns	
WE fall time	t,	_	30	ns	

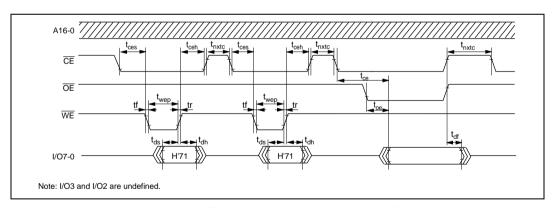


Figure 18.22 Status Read Mode Timing Waveforms

Table 18.19 Status Read Mode Return Commands

Pin Name	1/07	I/O6	I/O5	I/O4	I/O3	I/O2	I/O1	I/O0
Attribute	Normal end identifica- tion	Command error	Program- ming error	Erase error	_	_	Program- ming or erase count exceeded	Effective address error
Initial value	0	0	0	0	0	0	0	0
Indications	end: 0	Command error: 1	ming	Erase error: 1	_	_	Count exceeded:	Effective address error: 1
	Abnormal end: 1	Otherwise: 0	Otherwise:	Otherwise: 0			Otherwise:	Otherwise:

Notes on status read mode

After exiting auto-program mode or auto-erase mode, status read mode must be executed without dropping the power supply.

Immediately after powering on, or once powering off, the return command is undefined.

18.8.8 PROM Mode Transition Time

Commands cannot be accepted during the oscillation stabilization period or the PROM mode setup period. After the PROM mode setup time, a transition is made to memory read mode.

Table 18.20 Stipulated Transition Times to Command Wait State

Item	Symbol	Min	Max	Unit	Notes
Standby release (oscillation settling time)	t _{osc1}	20	_	ms	
PROM mode setup time	$\mathbf{t}_{\scriptscriptstyle bmv}$	10	_	ms	
V _{cc} hold time	t _{dwn}	0	_	ms	



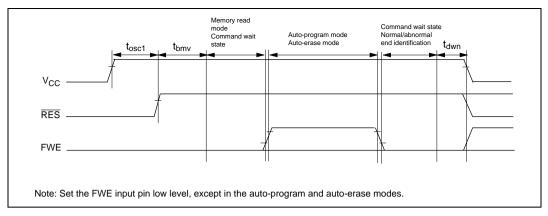


Figure 18.23 Oscillation Stabilization Time, Boot Program Transfer Time

18.8.9 Notes On Memory Programming

- When programming addresses which have previously been programmed, carry out autoerasing before auto-programming (figure 18.24).
- When performing programming using PROM mode on a chip that has been programmed/erased in an on-board programming mode, auto-erasing is recommended before carrying out auto-programming.
- Notes: 1. The flash memory is initially in the erased state when the device is shipped by Renesas. For other chips for which the erasure history is unknown, it is recommended that autoerasing be executed to check and supplement the initialization (erase) level.
 - 2. In the PROM mode, auto-programming to a 128-byte programming unit block should be performed only once.

Do not perform additional programming to a programmed 128-byte programming unit block.

To reprogram, perform auto-programming after auto-erasing.

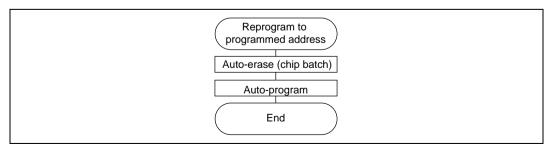


Figure 18.24 Reprogramming to Programmed Address

18.9 Notes on Flash Memory Programming/Erasing

The following describes notes when using the on-board programming mode, RAM emulation function, and PROM mode.

(1) Program/erase with the specified voltage and timing.

Applied voltages in excess of the rating can permanently damage the device.

Use a PROM writer that supports the Renesas 128kbytes flash memory on-board microcomputer device type.

Do not set the PROM writer at the HN28F101. If the PROM writer is set to the HN28F101 by mistake, a high level can be input to the FWE pin and the LSI can be destroyed.

(2) Notes on powering on/powering off (See figures 18.25 to 18.27.)

Input a high level to the FWE pin after verifying Vcc. Before turning off Vcc, set the FWE pin to a low level.

When powering on and powering off the Vcc power supply, fix the FWE pin a low level and set the flash memory to the hardware protection mode.

Be sure that the powering on and powering off timing is satisfied even when the power is turned off and back on in the event of a power interruption, etc. If this timing is not satisfied, microcomputer runaway, etc., may cause overprogramming or overerasing and the memory cells may not operate normally.

(3) Notes on FWE pin High/Low switching (See figures 18.25 to 18.27.)

Input FWE in the state microcomputer operation is verified. If the microcomputer does not satisfy the operation confirmation state, fix the FWE pin at a low level to set the protection mode.

To prevent erroneous programming/erasing of flash memory, note the following in FWE pin High/Low switching:

• Apply an input to the FWE pin after the Vcc voltage has stabilized within the rated voltage.

If an input is applied to the FWE pin when the microcomputer Vcc voltage does not satisfy the rated voltage, flash memory may be erroneously programmed or erased because the microcomputer is in the unconfirmed state.

 Apply an input to the FWE pin when the oscillation has stabilized (after the oscillation stabilization time).

When turning on the Vcc power, apply an input to the FWE pin after holding the RES pin at a low level during the oscillation stabilization time (t_{osci} =20ms). Do not apply an input to the FWE pin when oscillation is stopped or unstable.



- In the boot mode, perform FWE pin High/Low switching during reset.

 In transition to the boot mode, input FWE=High level and set MD₂ to MD₀ while the RES input is low. At this time, the FWE and MD₂ to MD₀ inputs must satisfy the mode programming setup time (t_{MDS}) relative to the reset clear timing. The mode programming setup time is necessary for RES reset timing even in transition from the boot mode to another mode.
 - In reset during operation, the \overline{RES} pin must be held at a low level for at least 20 system clocks.
- In the user program mode, FWE=High/Low switching is possible regardless of the RES input.
 - FWE input switching is also possible during program execution on flash memory.
- Apply an input to FWE when the program is not running away.
 When applying an input to the FWE pin, the program execution state must be supervised using a watchdog timer, etc.
- Input low level to the FWE pin when the SWE, ESU, PSU, EV, PV, E, and P bits in FLMCR have been cleared.
 - Do not erroneously set the SWE, ESU, PSU, EV, PV, E, and P bits when FWE High/Low.
- (4) Do not input a constant high level to the FWE pin.
 - To prevent erroneous programming/erasing in the event of program runaway, etc., input a high level to the FWE pin only when programming/erasing flash memory (including flash memory emulation by RAM). Avoid system configurations that constantly input a high level to the FWE pin. Handle program runaway, etc. by starting the watchdog timer so that flash memory is not overprogrammed/overerased even while a high level is input to the FWE pin.
- (5) Program/erase the flash memory in accordance with the recommended algorithms.

 The recommended algorithms can program/erase the flash memory without applying voltage stress to the device or sacrificing the reliability of the program data.
 - When setting the PSU and ESU bits in FLMCR, set the watchdog timer for program runaway, etc.
- (6) Do not set/clear the SWE bit while a program is executing on flash memory.
 - Before performing flash memory program execution or data read, clear the SWE bit.
 - If the SWE bit is set, the flash data can be reprogrammed, but flash memory cannot be accessed for purposes other than verify (verify during programming/erase).
 - Similarly perform flash memory program execution and data read after clearing the SWE bit even when using the RAM emulation function with a high level input to the FWE pin.
 - However, RAM area that overlaps flash memory space can be read/programmed whether the SWE bit is set or cleared.

- (7) Do not use an interrupt during flash memory programming or erasing. Since programming/erase operations (including emulation by RAM) have priority when a high level is input to the FWE pin, disable all interrupt requests, including NMI.
- (8) Do not perform additional programming. Reprogram flash memory after erasing. With on-board programming, program to 32-byte programming unit blocks one time only. Program to 128-byte programming unit blocks one time only even in the PROM mode. Erase all the programming unit blocks before reprogramming. Bus release must also be disabled.

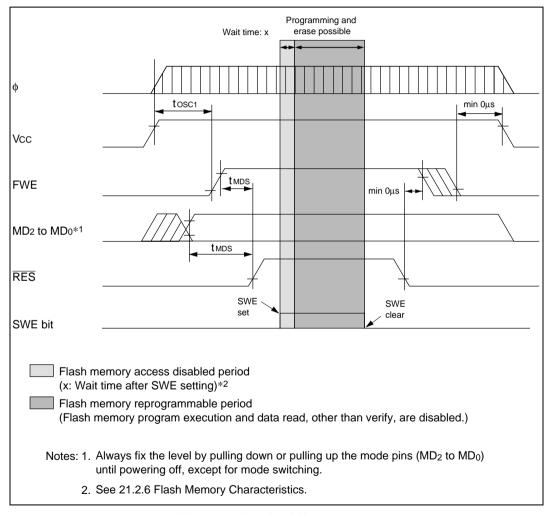


Figure 18.25 Powering On/Off Timing (Boot Mode)

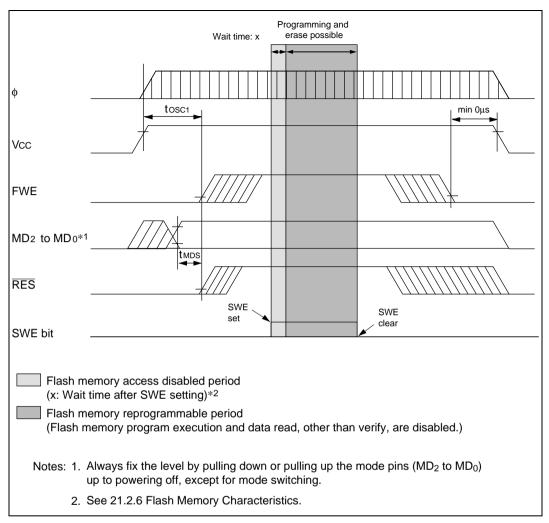


Figure 18.26 Powering On/Off Timing (User Program Mode)

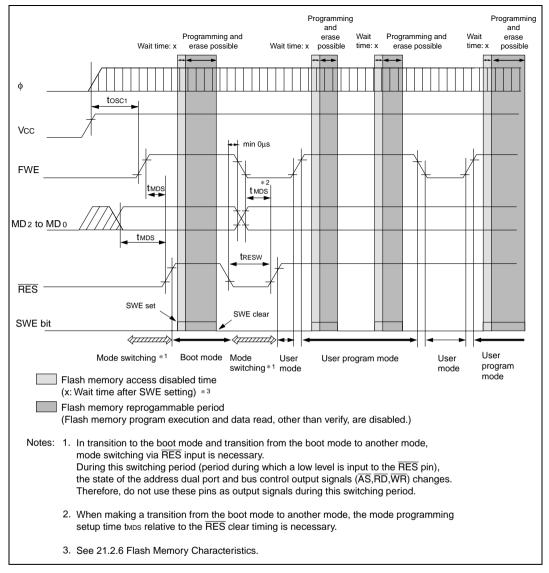


Figure 18.27 Mode Transition Timing (Example: Boot mode → User mode ↔ User program mode)

18.10 Mask ROM Overview

18.10.1 Block Diagram

Figure 18.28 shows a block diagram of the ROM.

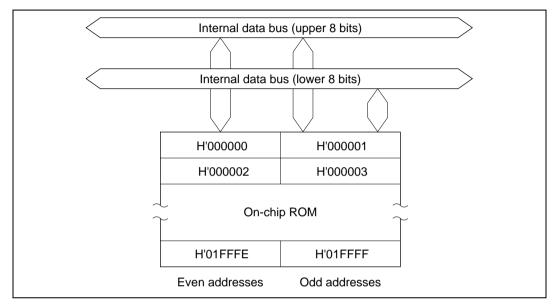


Figure 18.28 ROM Block Diagram (H8/3067)

18.11 Notes on Ordering Mask ROM Version Chip

When ordering the H8/3067 Group chips with a mask ROM, note the following.

- When ordering through an EPROM, use a 128-kbyte one.
- Fill all the unused addresses with H'FF as shown in figure 18.27 to make the ROM data size 128 kbytes for all H8/3067 Group chips, which incorporate different sizes of ROM. This applies to ordering through an EPROM and through electrical data transfer.
- The flash memory and flash memory R versions only registers for flash memory control (FLMCR, EBR, RAMCR, and FLMSR) are not provided in the mask ROM versions. Reading the corresponding addresses in a mask ROM version will always return 1s, and writes to these addresses are disabled. This must be borne in mind when switching from the flash memory and flash memory R versions to a mask ROM version.

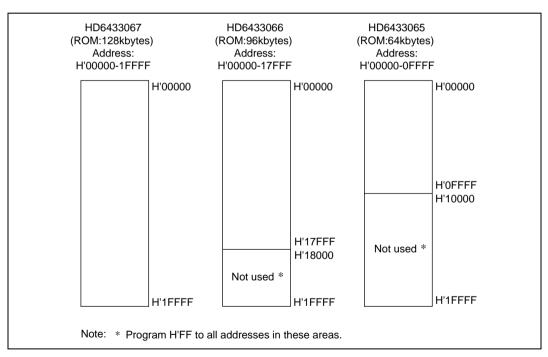


Figure 18.29 Mask ROM Addresses and Data

Section 19 Clock Pulse Generator

19.1 Overview

The H8/3067 Group has a built-in clock pulse generator (CPG) that generates the system clock (ϕ) and other internal clock signals (ϕ /2 to ϕ /4096). After duty adjustment, a frequency divider divides the clock frequency to generate the system clock (ϕ). The system clock is output at the ϕ pin^{*1} and furnished as a master clock to prescalers that supply clock signals to the on-chip supporting modules. Frequency division ratios of 1/1, 1/2, 1/4, and 1/8 can be selected for the frequency divider by settings in a division control register (DIVCR)*2. Power consumption in the chip is reduced in almost direct proportion to the frequency division ratio.

- Notes: 1. Usage of the φ pin differs depending on the chip operating mode and the PSTOP bit setting in the module standby control register (MSTCR). For details, see section 20.7, System Clock Output Disabling Function.
 - The division ratio of the frequency divider can be changed dynamically during operation. The clock output at the φ pin also changes when the division ratio is changed. The frequency output at the φ pin is shown below.

 $\phi = EXTAL \times n$

where, EXTAL: Frequency of crystal resonator or external clock signal

n: Frequency division ratio (n = 1/1, 1/2, 1/4, or 1/8)

19.1.1 Block Diagram

Figure 19.1 shows a block diagram of the clock pulse generator.

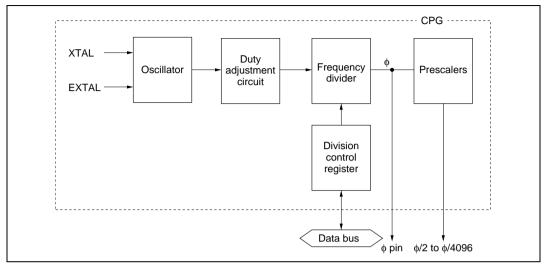


Figure 19.1 Block Diagram of Clock Pulse Generator

19.2 Oscillator Circuit

Clock pulses can be supplied by connecting a crystal resonator, or by input of an external clock signal.

19.2.1 Connecting a Crystal Resonator

Circuit Configuration: A crystal resonator can be connected as in the example in figure 19.2. The damping resistance Rd should be selected according to table 19.1. An AT-cut parallel-resonance crystal should be used.

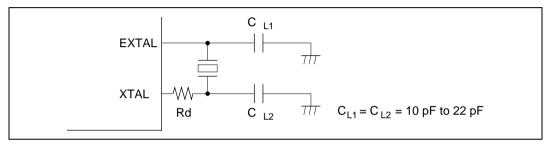


Figure 19.2 Connection of Crystal Resonator (Example)

Table 19.1 Damping Resistance Value

Damping Resistance	Frequ	ency f (N	IHz)					
		2 <f≤4< th=""><th>4<f≤8< th=""><th>8<f≤10< th=""><th>10 < f ≤ 13</th><th>13 < f ≤ 16</th><th>16 < f ≤ 18</th><th>18 < f ≤ 20</th></f≤10<></th></f≤8<></th></f≤4<>	4 <f≤8< th=""><th>8<f≤10< th=""><th>10 < f ≤ 13</th><th>13 < f ≤ 16</th><th>16 < f ≤ 18</th><th>18 < f ≤ 20</th></f≤10<></th></f≤8<>	8 <f≤10< th=""><th>10 < f ≤ 13</th><th>13 < f ≤ 16</th><th>16 < f ≤ 18</th><th>18 < f ≤ 20</th></f≤10<>	10 < f ≤ 13	13 < f ≤ 16	16 < f ≤ 18	18 < f ≤ 20
Rd (Ω)	1 k	500	200	0	0	0	0	0

Note: A crystal resonator between 2 MHz and 20 MHz can be used. If the chip is to be operated at less than 2 MHz, the on-chip frequency divider should be used. (A crystal resonator of less than 2 MHz cannot be used.)

Crystal Resonator: Figure 19.3 shows an equivalent circuit of the crystal resonator. The crystal resonator should have the characteristics listed in table 19.2.

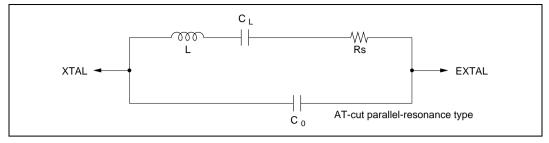


Figure 19.3 Crystal Resonator Equivalent Circuit

Table 19.2 Crystal Resonator Parameters

Frequency (MHz)	2	4	8	10	12	16	18	20	
Rs max (Ω)	500	120	80	70	60	50	40	40	_
Co (pF)	7 pF m	nax							_

Use a crystal resonator with a frequency equal to the system clock frequency (ϕ) .

Notes on Board Design: When a crystal resonator is connected, the following points should be noted:

Other signal lines should be routed away from the oscillator circuit to prevent induction from interfering with correct oscillation. See figure 19.4.

When the board is designed, the crystal resonator and its load capacitors should be placed as close as possible to the XTAL and EXTAL pins.

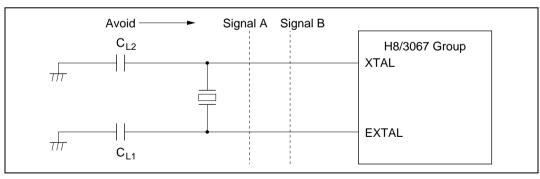


Figure 19.4 Example of Incorrect Board Design

19.2.2 External Clock Input

Circuit Configuration: An external clock signal can be input as shown in the examples in figure 19.5. If the XTAL pin is left open, the stray capacitance should not exceed 10 pF. If the stray capacitance at the XTAL pin exceeds 10 pF in configuration a, use configuration b instead and hold the clock high in standby mode.

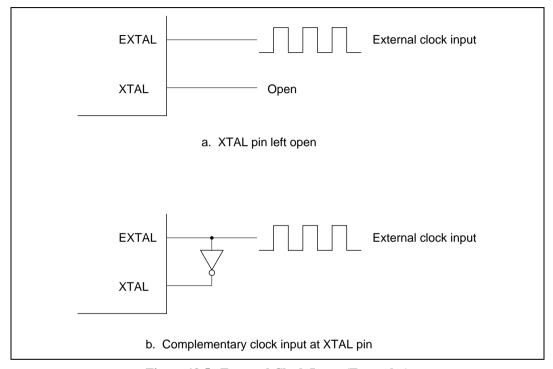


Figure 19.5 External Clock Input (Examples)

External Clock: The external clock frequency should be equal to the system clock frequency when not divided by the on-chip frequency divider. Table 19.3 shows the clock timing, figure 19.6 shows the external clock input timing, and figure 19.7 shows the external clock output settling delay timing. When the appropriate external clock is input via the EXTAL pin, its waveform is corrected by the on-chip oscillator and duty adjustment circuit.

When the appropriate external clock is input via the EXTAL pin, its waveform is corrected by the on-chip oscillator and duty adjustment circuit. The resulting stable clock is output to external devices after the external clock settling time (t_{DEXT}) has passed after the clock input. The system must remain reset with the reset signal low during t_{DEXT} , while the clock output is unstable.

Table 19.3 Clock Timing

		V _{cc} = 3 to 5.5		V _{cc} = to 5.5		V _{cc} = 1	5.0 V ±		
Item	Symbol	Min	Max	Min	Max	Min	Max	Unit	Test Conditions
External clock input low pulse width	t _{EXL}	40	_	30	_	15	_	ns	Figure 19.6
External clock input high pulse width	t _{EXH}	40	_	30		15	_	ns	-
External clock rise time	t _{EXr}		10		8	_	5	ns	-
External clock fall time	t _{EXf}		10		8	_	5	ns	-
Clock low pulse	t _{CL}	0.4	0.6	0.4	0.6	0.4	0.6	t _{cyc}	φ≥5 MHz Figure
width		80	_	80	_	80	_	ns	φ < 5 MHz 21.11
Clock high pulse	t _{ch}	0.4	0.6	0.4	0.6	0.4	0.6	t _{cyc}	φ≥5 MHz
width		80	_	80	_	80	_	ns	φ < 5 MHz
External clock output settling delay time	t _{DEXT} *1	500		500		500	_	μs	Figure 19.7

Notes: 1. t_{DEXT} includes RES pulse width (t_{RESW}) .

 $t_{\mbox{\tiny RESW}}$ is 10 tcyc in the mask ROM version, and 20 tcyc in the flash memory and flash memory R versions.

2. The operating range "V $_{\!\scriptscriptstyle CC}$ = 2.7 V to 5.5 V" applies to the mask ROM version.



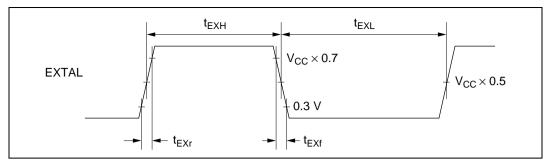


Figure 19.6 External Clock Input Timing

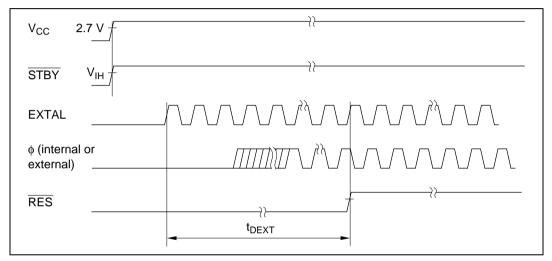


Figure 19.7 External Clock Output Settling Delay Timing

19.3 **Duty Adjustment Circuit**

When the oscillator frequency is 5 MHz or higher, the duty adjustment circuit adjusts the duty cycle of the clock signal from the oscillator to generate φ.

19.4 **Prescalers**

The prescalers divide the system clock (ϕ) to generate internal clocks (ϕ /2 to ϕ /4096).

19.5 **Frequency Divider**

The frequency divider divides the duty-adjusted clock signal to generate the system clock (φ). The frequency division ratio can be changed dynamically by modifying the value in DIVCR, as described below. Power consumption in the chip is reduced in almost direct proportion to the frequency division ratio. The system clock generated by the frequency divider can be output at the φ pin.

19.5.1 **Register Configuration**

Table 19.4 summarizes the frequency division register.

Table 19.4 Frequency Division Register

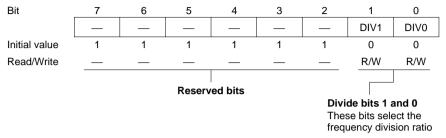
Address*	Name	Abbreviation	R/W	Initial Value
H'EE01B	Division control register	DIVCR	R/W	H'FC

Note: *Lower 20 bits of the address in advanced mode.



19.5.2 Division Control Register (DIVCR)

DIVCR is an 8-bit readable/writable register that selects the division ratio of the frequency divider.



DIVCR is initialized to H'FC by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bits 7 to 2—Reserved: These bits cannot be modified and are always read as 1.

Bits 1 and 0—Divide (DIV1 and DIV0): These bits select the frequency division ratio, as follows.

Bit 1 DIV1	Bit 0 DIV0	Frequency Division Ratio	
0	0	1/1	(Initial value)
0	1	1/2	
1	0	1/4	
1	1	1/8	

19.5.3 Usage Notes

The DIVCR setting changes the ϕ frequency, so note the following points.

- Select a frequency division ratio that stays within the assured operation range specified for the clock cycle time t_{cyc} in the AC electrical characteristics. Note that $\phi_{min} = 1$ MHz. Avoid settings that give system clock frequencies less than 1 MHz.
- All on-chip module operations are based on φ. Note that the timing of timer operations, serial communication, and other time-dependent processing differs before and after any change in the division ratio. The waiting time for exit from software standby mode also changes when the division ratio is changed. For details, see section 20.4.3, Selection of Waiting Time for Exit from Software Standby Mode.

Section 20 Power-Down State

20.1 Overview

The H8/3067 Group has a power-down state that greatly reduces power consumption by halting the CPU, and a module standby function that reduces power consumption by selectively halting on-chip modules.

The power-down state includes the following three modes:

- Sleep mode
- Software standby mode
- Hardware standby mode

The module standby function can halt on-chip supporting modules independently of the power-down state. The modules that can be halted are the 16-bit timer, 8-bit timer, SCI0, SCI1, SCI2, DMAC, DRAM interface, and A/D converter.

Table 20.1 indicates the methods of entering and exiting the power-down modes and module standby mode, and gives the status of the CPU and on-chip supporting modules in each mode.

Table 20.1 Power-Down State and Module Standby Function

									State	te							
Mode	Entering Conditions	Clock	CPU	CPU DRAM 16-Bit Clock CPU Registers DMAC Interface Timer	DMAC	DRAM 16-Bit Interface Timer	16-Bit Timer	8-Bit Timer	SCIO	SCI1	SCI2	A/D	Other Modules	RAM	Other ¢ clock Modules RAM output**	I/O Ports	Exiting Conditions
Sleep	SLEEP instruc- Active Halted Held tion executed while SSBY = 0 in SYSCR	Active	Halted		Active	Active	Active	Active	Active	Active	Active	Active	Active	Held		Held	• Interrupt • RES • STBY
Software standby mode	Software SLEEP instruc- Halted Halted Held standby tion executed mode while SSBY = 1 in SYSCR	Halted	Halted		Halted Halted and and reset held* ¹		Halted and reset	Halted and reset	Halted and reset	Halted and reset	Halted and reset	Hatted Hatted Hatted and and and and reset reset reset		Held	High output	Held	$ \bullet \ NMI \\ \bullet \ \overline{IRQ}_0 \ to \ \overline{IRQ}_2 \\ \bullet \ \overline{RES} \\ \bullet \ \overline{STBY} $
Hardware standby mode	Hardware Low input at standby STBY pin mode	Halted	Halted	Halted Halted Undeter- Halted mined and reset		Halted and reset	Halted and reset	Halted and reset	Halted and reset	Halted and reset	Halted and reset	Halted and reset	Halted and reset	Held*³ High impe	dance	High • <u>STB'</u> impedance • <u>RES</u>	• STBY • RES
Module	Corresponding Adive Adive — bit set to 1 in MSTCR	Active	Active		Halted* ² and reset	Halted* ² Halted* ² Halted* ² Halted* ² Halted* ² Halted* ² Active and and and and and and reset reset reset reset	Halted*² and reset	Halted*² and reset	Halted* ² and reset	Halted*² and reset	Halted* ² and reset	Halted* ² and reset	Active	1	High impedance* ²	T _	• STBY • RES • Clear MSTCR bit to 0*5
Notes:	Notes: 1. RTCNT and bits 7 and 6 of RTMCSR are initialized. Other bits and registers hold their previous states.	bits 7 a	and 6 o	I RTMCSF	Rare init	ialized. O	ther bits	and reg	isters ho	ld their p	revious	states.					

System control register SYSCR:

Software standby bit

MSTCRH: Module standby control register H

MSTCRL: Module standby control register L

State in which the corresponding MSTCR bit was set to 1. For details see section 20.2.2, Module Standby Control Register H (MSTCRH) and section 20.2.3, Module Standby Control Register L (MSTCRL).

The RAME bit must be cleared to 0 in SYSCR before the transition from the program execution state to hardware standby mode. რ

When P6, is used as the ϕ output pin.

When a MSTCR bit is set to 1, the registers of the corresponding on-chip supporting module are initialized. To restart the module, first clear the MSTCR bit to then set up the module registers again. 4. 3.

20.2 Register Configuration

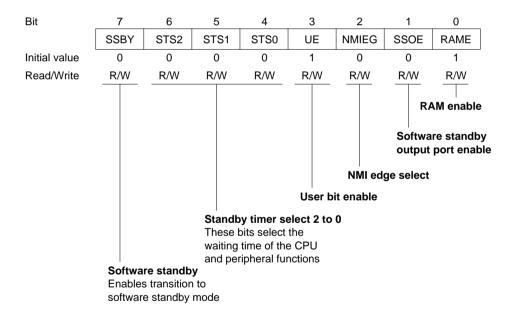
The H8/3067 Group has a system control register (SYSCR) that controls the power-down state, and module standby control registers H (MSTCRH) and L (MSTCRL) that control the module standby function. Table 20.2 summarizes these registers.

Table 20.2 Control Register

Address*	Name	Abbreviation	R/W	Initial Value
H'EE012	System control register	SYSCR	R/W	H'09
H'EE01C	Module standby control register H	MSTCRH	R/W	H'78
H'EE01D	Module standby control register L	MSTCRL	R/W	H'00

Note: * Lower 20 bits of the address in advanced mode.

20.2.1 System Control Register (SYSCR)



SYSCR is an 8-bit readable/writable register. Bit 7 (SSBY), bits 6 to 4 (STS2 to STS0), and bit 1 (SSOE) control the power-down state. For information on the other SYSCR bits, see section 3.3, System Control Register (SYSCR).

Bit 7—Software Standby (SSBY): Enables transition to software standby mode. When software standby mode is exited by an external interrupt, this bit remains set to 1 after the return to normal operation. To clear this bit, write 0.

Bit 7		
SSBY	Description	
0	SLEEP instruction causes transition to sleep mode	(Initial value)
1	SLEEP instruction causes transition to software standby mode	

Bits 6 to 4—Standby Timer Select (STS2 to STS0): These bits select the length of time the CPU and on-chip supporting modules wait for the clock to settle when software standby mode is exited by an external interrupt. If the clock is generated by a crystal resonator, set these bits according to the clock frequency so that the waiting time will be at least 7 ms (oscillation settling time). See table 20.3. If an external clock is used, any setting is permitted.

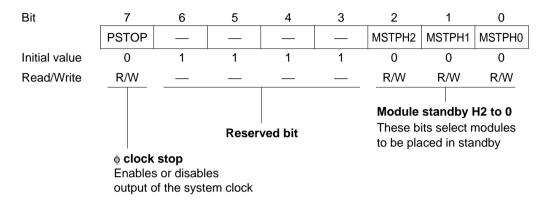
Bit 6 STS2	Bit 5 STS1	Bit 4 STS0	Description	
0	0	0	Waiting time = 8,192 states	(Initial value)
		1	Waiting time = 16,384 states	
	1	0	Waiting time = 32,768 states	
		1	Waiting time = 65,536 states	
1	0	0	Waiting time = 131,072 states	
		1	Waiting time = 262,144 states	
	1	0	Waiting time = 1,024 states	
		1	Illegal setting	

Bit 1—Software Standby Output Port Enable (SSOE): Specifies whether the address bus and bus control signals (\overline{CS}_0 to \overline{CS}_7 , \overline{AS} , \overline{RD} , \overline{HWR} , \overline{LWR} , \overline{UCAS} , \overline{LCAS} , and \overline{RFSH}) are kept as outputs or fixed high, or placed in the high-impedance state in software standby mode.

Bit 1 SSOE	Description	
0	In software standby mode, the address bus and bus control signals are all high-impedance	(Initial value)
1	In software standby mode, the address bus retains its output state and bus control signals are fixed high	

20.2.2 Module Standby Control Register H (MSTCRH)

MSTCRH is an 8-bit readable/writable register that controls output of the system clock (ϕ). It also controls the module standby function, which places individual on-chip supporting modules in the standby state. Module standby can be designated for the SCI0, SCI1, SCI2.



MSTCRH is initialized to H'78 by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bit 7— ϕ Clock Stop (PSTOP): Enables or disables output of the system clock (ϕ) .

Bit 1 PSTOP	Description	
0	System clock output is enabled	(Initial value)
1	System clock output is disabled	

Bits 6 to 3—Reserved: These bits cannot be modified and are always read as 1.

Bit 2—Module Standby H2 (MSTPH2): Selects whether to place the SCI2 in standby.

Bit 2 MSTPH2	Description	
0	SCI2 operates normally	(Initial value)
1	SCI2 is in standby state	

Bit 1—Module Standby H1 (MSTPH1): Selects whether to place the SCI1 in standby.

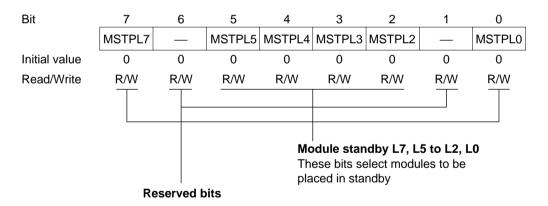
Bit 1 MSTPH1	Description	
0	SCI1 operates normally	(Initial value)
1	SCI1 is in standby state	

Bit 0—Module Standby H0 (MSTPH0): Selects whether to place the SCI0 in standby.

Bit 0 MSTPH0	Description	
0	SCI0 operates normally	(Initial value)
1	SCI0 is in standby state	

20.2.3 Module Standby Control Register L (MSTCRL)

MSTCRL is an 8-bit readable/writable register that controls the module standby function, which places individual on-chip supporting modules in the standby state. Module standby can be designated for the DMAC, 16-bit timer, DRAM interface, 8-bit timer, and A/D converter modules.



MSTCRL is initialized to H'00 by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bit 7—Module Standby L7 (MSTPL7): Selects whether to place the DMAC in standby.

Bit 7 MSTPL7	Description	
0	DMAC operates normally	(Initial value)
1	DMAC is in standby state	

Bit 6—Reserved: This bit can be written and read.

Bit 5—Module Standby L5 (MSTPL5): Selects whether to place the DRAM interface in standby.

Bit 5 MSTPL5	Description	
0	DRAM interface operates normally	(Initial value)
1	DRAM interface is in standby state	

Bit 4—Module Standby L4 (MSTPL4): Selects whether to place the 16-bit timer in standby.

Bit 4 MSTPL4	Description	
0	16-bit timer operates normally	(Initial value)
1	16-bit timer is in standby state	

Bit 3—Module Standby L3 (MSTPL3): Selects whether to place 8-bit timer channels 0 and 1 in standby.

Bit 3 MSTPL3	Description	
0	8-bit timer channels 0 and 1 operate normally	(Initial value)
1	8-bit timer channels 0 and 1 are in standby state	

Bit 2—Module Standby L2 (MSTPL2): Selects whether to place 8-bit timer channels 2 and 3 in standby.

Bit 2 MSTPL2	Description	
0	8-bit timer channels 2 and 3 operate normally	(Initial value)
1	8-bit timer channels 2 and 3 are in standby state	

Bit 1—Reserved: This bit can be written and read.

Bit 0—Module Standby L0 (MSTPL0): Selects whether to place the A/D converter in standby.

Bit 0 MSTPL0	Description	
0	A/D converter operates normally	(Initial value)
1	A/D converter is in standby state	



20.3 Sleep Mode

20.3.1 Transition to Sleep Mode

When the SSBY bit is cleared to 0 in SYSCR, execution of the SLEEP instruction causes a transition from the program execution state to sleep mode. Immediately after executing the SLEEP instruction the CPU halts, but the contents of its internal registers are retained. The DMA controller (DMAC), DRAM interface, and on-chip supporting modules do not halt in sleep mode. Modules which have been placed in standby by the module standby function, however, remain halted.

20.3.2 Exit from Sleep Mode

Sleep mode is exited by an interrupt, or by input at the \overline{RES} or \overline{STBY} pin.

Exit by Interrupt: An interrupt terminates sleep mode and causes a transition to the interrupt exception handling state. Sleep mode is not exited by an interrupt source in an on-chip supporting module if the interrupt is disabled in the on-chip supporting module. Sleep mode is not exited by an interrupt other than NMI if the interrupt is masked by interrupt priority settings and the settings of the I and UI bits in CCR, IPR.

Exit by \overline{RES} Input: Low input at the \overline{RES} pin exits from sleep mode to the reset state.

Exit by \overline{STBY} Input: Low input at the \overline{STBY} pin exits from sleep mode to hardware standby mode.

20.4 Software Standby Mode

20.4.1 Transition to Software Standby Mode

To enter software standby mode, execute the SLEEP instruction while the SSBY bit is set to 1 in SYSCR.

In software standby mode, current dissipation is reduced to an extremely low level because the CPU, clock, and on-chip supporting modules all halt. The DMAC and on-chip supporting modules are reset and halted. As long as the specified voltage is supplied, however, CPU register contents and on-chip RAM data are retained. The settings of the I/O ports and DRAM interface* are also held. When the WDT is used as a watchdog timer (WT/ $\overline{\text{IT}}$ = 1), the TME bit must be cleared to 0 before setting SSBY. Also, when setting TME to 1, SSBY should be cleared to 0.

Clear the BRLE bit in BRCR (inhibiting bus release) before making a transition to software standby mode.

Note: * RTCNT and bits 7 and 6 of RTMCSR are initialized. Other bits and registers hold their previous states.

20.4.2 Exit from Software Standby Mode

Software standby mode can be exited by input of an external interrupt at the NMI, \overline{IRQ}_0 , \overline{IRQ}_1 , or \overline{IRQ}_0 , pin, or by input at the \overline{RES} or \overline{STBY} pin.

Exit by Interrupt: When an NMI, IRQ₀, IRQ₁, or IRQ₂ interrupt request signal is received, the clock oscillator begins operating. After the oscillator settling time selected by bits STS2 to STS0 in SYSCR, stable clock signals are supplied to the entire chip, software standby mode ends, and interrupt exception handling begins. Software standby mode is not exited if the interrupt enable bits of interrupts IRQ₀, IRQ₁, and IRQ₂ are cleared to 0, or if these interrupts are masked in the CPU.

Exit by \overline{RES} Input: When the \overline{RES} input goes low, the clock oscillator starts and clock pulses are supplied immediately to the entire chip. The \overline{RES} signal must be held low long enough for the clock oscillator to stabilize. When \overline{RES} goes high, the CPU starts reset exception handling.

Exit by STBY Input: Low input at the STBY pin causes a transition to hardware standby mode.



20.4.3 Selection of Waiting Time for Exit from Software Standby Mode

Bits STS2 to STS0 in SYSCR and bits DIV1 and DIV0 in DIVCR should be set as follows.

Crystal Resonator: Set STS2 to STS0, DIV1, and DIV0 so that the waiting time (for the clock to stabilize) is at least 7 ms. Table 20.3 indicates the waiting times that are selected by STS2 to STS0, DIV1, and DIV0 settings at various system clock frequencies.

External Clock: Any values may be set.

Table 20.3 Clock Frequency and Waiting Time for Clock to Settle

DIV1	DIV0	STS2	STS1	STS0	Waiting Time	20 MHz	18 MHz	16 MHz	12 MHz	10 MHz	8 MHz	6 MHz	4 MHz	2 MHz	1 MHz	Unit
0	0	0	0	0	8192 states	0.4	0.46	0.51	0.65	0.8	1.0	1.3	2.0	4.1	8.2*	ms
		0	0	1	16384 states	0.8	0.91	1.0	1.3	1.6	2.0	2.7	4.1	8.2*	16.4	_
		0	1	0	32768 states	1.6	1.8	2.0	2.7	3.3	4.1	5.5	8.2*	16.4	32.8	-
		0	1	1	65536 states	3.3	3.6	4.1	5.5	6.6	8.2*	10.9*	16.4	32.8	65.5	_
		1	0	0	131072 states	6.6	7.3*	8.2*	10.9*	13.1*	16.4	21.8	32.8	65.5	131.1	_
		1	0	1	262144 states	13.1*	14.6	16.4	21.8	26.2	32.8	43.7	65.5	131.1	262.1	_
		1	1	0	1024 states	0.05	0.057	0.064	0.085	0.10	0.13	0.17	0.26	0.51	1.0	_
		1	1	1						Illegal se	etting					
0	1	0	0	0	8192 states	8.0	0.91	1.02	1.4	1.6	2.0	2.7	4.0	8.2*	16.4*	ms
		0	0	1	16384 states	1.6	1.8	2.0	2.7	3.3	4.1	5.5	8.2*	16.4	32.8	_
		0	1	0	32768 states	3.3	3.6	4.1	5.5	6.6	8.2*	10.9*	16.4	32.8	65.5	_
		0	1	1	65536 states	6.6	7.3*	8.2*	10.9*	13.1*	16.4	21.8	32.8	65.5	131.1	_
		1	0	0	131072 states	13.1*	14.6	16.4	21.8	26.2	32.8	43.7	65.5	131.1	262.1	_
		1	0	1	262144 states	26.2	29.1	32.8	43.7	52.4	65.5	87.4	131.1	262.1	524.3	-
		1	1	0	1024 states	0.10	0.11	0.13	0.17	0.20	0.26	0.34	0.51	1.0	2.0	_
		1	1	1						Illegal se	etting					_
1	0	0	0	0	8192 states	1.6	1.8	2.0	2.7	3.3	4.1	5.5	8.2*	16.4*	32.8*	ms
		0	0	1	16384 states	3.3	3.6	4.1	5.5	6.6	8.2*	10.9*	16.4	32.8	65.5	-
		0	1	0	32768 states	6.6	7.3*	8.2*	10.9*	13.1*	16.4	21.8	32.8	65.5	131.1	_
		0	1	1	65536 states	13.1*	14.6	16.4	21.8	26.2	32.8	43.7	65.5	131.1	262.1	_
		1	0	0	131072 states	26.2	29.1	32.8	43.7	52.4	65.5	87.4	131.1	262.1	524.3	
		1	0	1	262144 states	52.4	58.3	65.5	87.4	104.9	131.1	174.8	262.1	524.3	1048.6	-
		1	1	0	1024 states	0.20	0.23	0.26	0.34	0.41	0.51	0.68	1.02	2.0	4.1	_
		1	1	1						Illegal se	etting					
1	1	0	0	0	8192 states	3.3	3.6	4.1	5.5	6.6	8.2*	10.9*	16.4*	32.8*	65.5	ms
		0	0	1	16384 states	6.6	7.3*	8.2*	10.9*	13.1*	16.4	21.8	32.8	65.5	131.1	_
		0	1	0	32768 states	13.1*	14.6	16.4	21.8	26.2	32.8	43.7	65.5	131.1	262.1	
		0	1	1	65536 states	26.2	29.1	32.8	43.7	52.4	65.5	87.4	131.1	262.1	524.3	
		1	0	0	131072 states	52.4	58.3	65.5	87.4	104.9	131.1	174.8	262.1	524.3	1048.6	
		1	0	1	262144 states	104.9	116.5	131.1	174.8	209.7	262.1	349.5	524.3	1048.6	2097.1	_
		1	1	0	1024 states	0.41	0.46	0.51	0.68	0.82	1.0	1.4	2.0	4.1	8.2*	_
		1	1	1						Illegal se	etting					

^{*:} Recommended setting



20.4.4 Sample Application of Software Standby Mode

Figure 20.1 shows an example in which software standby mode is entered at the fall of NMI and exited at the rise of NMI.

With the NMI edge select bit (NMIEG) cleared to 0 in SYSCR (selecting the falling edge), an NMI interrupt occurs. Next the NMIEG bit is set to 1 (selecting the rising edge) and the SSBY bit is set to 1; then the SLEEP instruction is executed to enter software standby mode.

Software standby mode is exited at the next rising edge of the NMI signal.

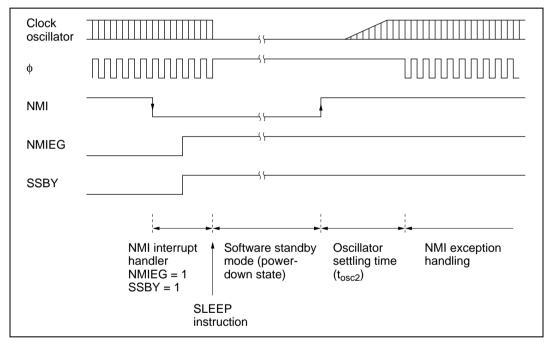


Figure 20.1 NMI Timing for Software Standby Mode (Example)

20.4.5 Note

The I/O ports retain their existing states in software standby mode. If a port is in the high output state, its output current is not reduced.

20.4.6 Cautions on Clearing the Software Standby Mode of F-ZTAT Version

(1) Operation phenomena

When using operating mode 5, 6, or 7* (on-chip flash memory enabled), the first read of on-chip flash memory after exiting software standby mode may not be carried out correctly. Software standby mode is exited by means of an external interrupt (via the NMI, $\overline{IRQ_0}$, $\overline{IRQ_1}$, or $\overline{IRQ_2}$ pin), the \overline{RES} pin, or the \overline{STBY} pin. In the case of an external interrupt via the NMI, $\overline{IRQ_0}$, $\overline{IRQ_1}$, or $\overline{IRQ_2}$ pin, the first read after exiting software standby mode is a read of the vector corresponding to the respective exception handling interrupt source. This vector may not be read correctly, resulting in program runaway.

Note: * Mode 5: expanded 16-Mbyte mode with on-chip ROM enabled

Mode 6: single-chip normal mode

Mode 7: single-chip advanced mode

(2) Exemplary procedures to avoid program runaway

This operation phenomenon can be avoided by writing or amending program code in accordance with the following procedures.

- (a) When using mode 5 or mode 7, assign addresses in the 64-kbyte space from H'00000 to H'0FFFF as the vector addresses for the external interrupts that clear software standby mode.
- (b) When using mode 6, change the mode to mode 7 in the program, and use change (a) above. Note that it is necessary to change vector address assignments and to extend addresses as follows.
 - Addresses H'DFFF and below (on-chip ROM area): H'xxxx → H'0xxxx
 - Addresses H'E000 to H'E0FF (internal I/O registers-1): H'yyyy \rightarrow H'Eyyyy

(Where x, y and z are any hexadecimal numbers)

With the production lots prior to the week code "9K1" of the HD64F3067 and HD64F3067R, avoid program runaway according to the procedures designated above.

Meanwhile, as for the production lots of the week code "9K1" and after, the special constraint according to of the aforementioned Section (2) is not applicable.



20.5 Hardware Standby Mode

20.5.1 Transition to Hardware Standby Mode

Regardless of its current state, the chip enters hardware standby mode whenever the \overline{STBY} pin goes low. Hardware standby mode reduces power consumption drastically by halting all functions of the CPU, DMAC, DRAM interface, and on-chip supporting modules. All modules are reset except the on-chip RAM. As long as the specified voltage is supplied, on-chip RAM data is retained. I/O ports are placed in the high-impedance state.

Clear the RAME bit to 0 in SYSCR before STBY goes low to retain on-chip RAM data.

The inputs at the mode pins (MD2 to MD0) should not be changed during hardware standby mode.

20.5.2 Exit from Hardware Standby Mode

Hardware standby mode is exited by inputs at the \overline{STBY} and \overline{RES} pins. While \overline{RES} is low, when \overline{STBY} goes high, the clock oscillator starts running. \overline{RES} should be held low long enough for the clock oscillator to settle. When \overline{RES} goes high, reset exception handling begins, followed by a transition to the program execution state.

20.5.3 Timing for Hardware Standby Mode

Figure 20.2 shows the timing relationships for hardware standby mode. To enter hardware standby mode, first drive \overline{RES} low, then drive \overline{STBY} low. To exit hardware standby mode, first drive \overline{STBY} high, wait for the clock to settle, then bring \overline{RES} from low to high.

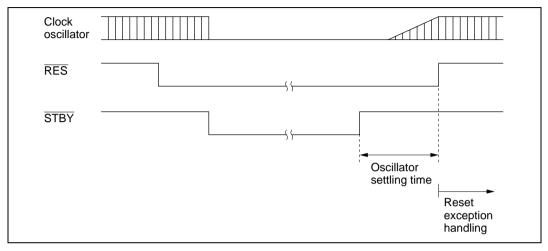


Figure 20.2 Hardware Standby Mode Timing

20.6 Module Standby Function

20.6.1 Module Standby Timing

The module standby function can halt several of the on-chip supporting modules (SCI2, SCI1, SCI0, the DMAC, 16-bit timer, 8-bit timer, DRAM interface, and A/D converter) independently in the power-down state. This standby function is controlled by bits MSTPH2 to MSTPH0 in MSTCRH and bits MSTPL7 to MSTPL0 in MSTCRL. When one of these bits is set to 1, the corresponding on-chip supporting module is placed in standby and halts at the beginning of the next bus cycle after the MSTCR write cycle.

20.6.2 Read/Write in Module Standby

When an on-chip supporting module is in module standby, read/write access to its registers is disabled. Read access always results in H'FF data. Write access is ignored.

20.6.3 Usage Notes

When using the module standby function, note the following points.

DMAC: When setting a bit in MSTCR to 1 to place the DMAC in module standby, make sure that the DMAC is not currently requesting the bus right. If the corresponding bit in MSTCR is set to 1 when a bus request is present, operation of the bus arbiter becomes ambiguous and a malfunction may occur.

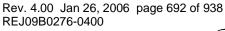
DRAM Interface: When the module standby function is used on the DRAM interface, set the MSTCR bit to 1 while DRAM space is deselected.

On-Chip Supporting Module Interrupts: Before setting a module standby bit, first disable interrupts by that module. When an on-chip supporting module is placed in standby by the module standby function, its registers are initialized, including registers with interrupt request flags.

Pin States: Pins used by an on-chip supporting module lose their module functions when the module is placed in module standby. What happens after that depends on the particular pin. For details, see section 8, I/O Ports. Pins that change from the input to the output state require special care. For example, if SCI1 is placed in module standby, the receive data pin loses its receive data function and becomes a port pin. If its port DDR bit is set to 1, the pin becomes a data output pin, and its output may collide with external SCI transmit data. Data collision should be prevented by clearing the port DDR bit to 0 or taking other appropriate action.

Register Resetting: When an on-chip supporting module is halted by the module standby function, all its registers are initialized. To restart the module, after its MSTCR bit is cleared to 0, its registers must be set up again. It is not possible to write to the registers while the MSTCR bit is set to 1.

MSTCR Access from DMAC Disabled: To prevent malfunctions, MSTCR can only be accessed from the CPU. It can be read by the DMAC, but it cannot be written by the DMAC.





20.7 System Clock Output Disabling Function

Output of the system clock (ϕ) can be controlled by the PSTOP bit in MSTCRH. When the PSTOP bit is set to 1, output of the system clock halts and the ϕ pin is placed in the high-impedance state. Figure 20.3 shows the timing of the stopping and starting of system clock output. When the PSTOP bit is cleared to 0, output of the system clock is enabled. Table 20.4 indicates the state of the ϕ pin in various operating states.

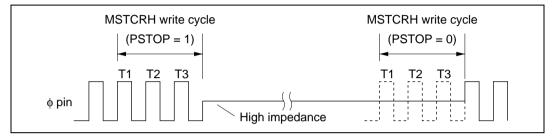


Figure 20.3 Starting and Stopping of System Clock Output

Table 20.4 ♦ Pin State in Various Operating States

Operating State	PSTOP = 0	PSTOP = 1	
Hardware standby	High impedance	High impedance	
Software standby	Always high	High impedance	
Sleep mode	System clock output	High impedance	
Normal operation	System clock output	High impedance	

Section 21 Electrical Characteristics

21.1 Electrical Characteristics of Mask ROM Version

21.1.1 Absolute Maximum Ratings

Table 21.1 lists the absolute maximum ratings.

Table 21.1 Absolute Maximum Ratings

Item	Symbol	Value	Unit
Power supply voltage	V _{cc}	-0.3 to +7.0	V
Input voltage (except for port 7)	V _{in}	-0.3 to V _{cc} +0.3	V
Input voltage (port 7)	V_{in}	-0.3 to AV _{cc} +0.3	V
Reference voltage	V_{REF}	-0.3 to AV _{cc} +0.3	V
Analog power supply voltage	AV _{cc}	-0.3 to +7.0	V
Analog input voltage	V_{AN}	-0.3 to AV _{cc} +0.3	V
Operating temperature	T _{opr}	Regular specifications: -20 to +75	°C
		Wide-range specifications: -40 to +85	°C
Storage temperature	T _{stg}	-55 to +125	°C

Caution: Permanent damage to the chip may result if absolute maximum ratings are exceeded.

21.1.2 DC Characteristics

Table 21.2 lists the DC characteristics. Table 21.3 lists the permissible output currents.

Table 21.2 DC Characteristics (1)

Conditions:
$$V_{CC} = 5.0 \text{ V} \pm 10\%$$
, $AV_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ V}$ to AV_{CC}^{*1} , $V_{SS} = AV_{SS} = 0 \text{ V}^{*1}$, $T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$ (regular specifications), $T_a = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ (wide-range specifications)

Item		Symbol	Min	Тур	Max	Unit	Test Conditions
Schmitt	Port A,	V _T -	1.0	_	_	V	
trigger input voltages	P8 ₀ to P8 ₂	$V_{T}^{}^{+}}$	_	_	$V_{cc} \times 0.7$	V	
voitages		$V_{\scriptscriptstyle T}^{\;\scriptscriptstyle +} - V_{\scriptscriptstyle T}^{\;\scriptscriptstyle -}$	0.4	_	_	V	
Input high voltage	RES, STBY, NMI, MD ₂ to MD ₀	V _{IH}	V _{cc} - 0.7	_	V _{cc} + 0.3	V	
	EXTAL	•	$V_{cc} \times 0.7$	_	V _{cc} + 0.3	V	_
	Port 7	:	2.0	_	AV _{cc} + 0.3	V	_
	Ports 1 to 6, P8 ₃ , P8 ₄ , P9 ₀ to P9 ₅ , port B	•	2.0	_	V _{cc} + 0.3	V	-
Input low voltage	RES, STBY, MD ₂ to MD ₀	V _{IL}	-0.3	_	0.5	V	
	NMI, EXTAL, ports 1 to 7, P8 ₃ , P8 ₄ , P9 ₀ to P9 ₅ , port B		-0.3	_	0.8	V	-
Output high	All output pins	V _{OH}	V _{cc} - 0.5	_	_	V	I _{OH} = -200 μA
voltage	(except RESO)		3.5	_	_	V	$I_{OH} = -1 \text{ mA}$
Output low voltage	All output pins (except RESO)	V _{oL}	_	_	0.4	V	I _{OL} = 1.6 mA
	Ports 1, 2, and 5	-	_	_	1.0	V	I _{OL} = 10 mA
	RESO	:	_	_	0.4	V	I _{OL} = 2.6 mA
Input leakage current	$\overline{\text{STBY}}$, NMI, $\overline{\text{RES}}$, MD ₂ to MD ₀	 	_	_	1.0	μA	$V_{in} = 0.5 \text{ V to}$ $V_{cc} - 0.5 \text{ V}$
	Port 7	•	_	_	1.0	μΑ	$V_{in} = 0.5 \text{ V to}$ $AV_{cc} - 0.5 \text{ V}$

Item		Symbol	Min	Тур	Max	Unit	Test Conditions
Three-state leakage	Ports 1 to 6 Ports 8 to B	I _{TSI}	_	_	1.0	μΑ	$V_{in} = 0.5 \text{ V to} $ $V_{cc} - 0.5 \text{ V} $
current	RESO	_	_	_	10.0	μΑ	$V_{in} = 0 V$
Input pull-up MOS current	Ports 2, 4, and 5	-I _p	50	_	300	μΑ	V _{in} = 0 V
Input	NMI	C _{in}	_	_	50	pF	$V_{in} = 0 V$
capacitance	All input pins except NMI		_	_	15	pF	f = 1 MHz T _a = 25°C
Current dissipation*2	Normal operation	I_*3	_	55 (5.0 V)	100	mA	f = 20 MHz
	Sleep mode	_	_	40 (5.0 V)	73	mA	f = 20 MHz
	Module standby mode		_	24 (5.0 V)	51	mA	f = 20 MHz
	Standby mode	_	_	0.01	5.0	μΑ	$T_a \le 50^{\circ}C$
			_	_	20.0	μΑ	$50^{\circ}\text{C} \leq \text{T}_{a}$
Analog power supply	During A/D conversion	Al _{cc}	_	0.6	1.5	mA	
current	During A/D and D/A conversion	-	_	0.6	1.5	mA	-
	Idle	=	_	0.01	5.0	μΑ	DASTE = 0
Reference current	During A/D conversion	Al _{cc}	_	0.5	0.8	mA	
	During A/D and D/A conversion	-	_	2.0	3.0	mA	_
	Idle	_	_	0.01	5.0	μΑ	DASTE = 0
RAM standby	RAM standby voltage		2.0			V	

Notes: 1. Do not open the pin connections of the AV_{CC}, V_{REF} and AV_{SS} pins while the A/D converter is not in use.

Connect the ${\rm AV_{cc}}$ and ${\rm V_{REF}}$ pins to the ${\rm V_{cc}}$ and connect the ${\rm AV_{ss}}$ pin to the ${\rm V_{ss}}$ respectively.

2. Given current consumption values are when all the output pins are made to unloaded state and, furthermore, when the on-chip pull-up MOS is turned off under conditions that $V_{\text{\tiny HI}}$ min = $V_{\text{\tiny CC}}$ – 0.5 V and $V_{\text{\tiny II}}$ max = 0.5 V.

Also, the aforesaid current consumption values are when V $_{\rm IH}$ min = V $_{\rm CC}$ \times 0.9 and V $_{\rm IL}$ max = 0.3 V under the condition of V $_{\rm RAM}$ \leq V $_{\rm CC}$ < 4.5 V.

3. I_{cc} max. (under normal operations) = 1.0 (mA) + 0.90 (mA/(MHz × V)) × V_{cc} × f I_{cc} max. (when using the sleeve) = 1.0 (mA) + 0.65 (mA/(MHz × V)) × V_{cc} × f I_{cc} max. (when the sleeve + module are standing by) = 1.0 (mA) + 0.45 (mA/(MHz × V)) × V_{cc} × f Also, the typ. values for current dissipation are reference values.

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Table 21.2 DC Characteristics (2)

Conditions: $V_{CC} = 2.7$ to 5.5 V, $AV_{CC} = 2.7$ to 5.5 V, $V_{REF} = 2.7$ V to AV_{CC}^{*1} , $V_{SS} = AV_{SS} = 0$ V*1, $T_a = -20^{\circ}$ C to +75°C (regular specifications), $T_a = -40^{\circ}$ C to +85°C (wide-range specifications)

Item		Symbol	Min	Тур	Max	Unit	Test Conditions
Schmitt	Port A,	V _T -	$V_{cc} \times 0.2$	_	_	V	
trigger input voltages	P8 ₀ to P8 ₂	V_{T}^{+}			$V_{cc} \times 0.7$	V	
		$V_T^+ - V_T^-$	$V_{cc} \times 0.07$			V	
Input high voltage	$\overline{\text{RES}}$, $\overline{\text{STBY}}$, NMI, MD_2 to MD_0	V _{IH}	$V_{cc} \times 0.9$	_	V _{cc} + 0.3	V	
	EXTAL	-	$V_{cc} \times 0.7$		V _{cc} + 0.3	V	_
	Port 7	_	$V_{cc} \times 0.7$	_	AV _{cc} + 0.3	V	_
	Ports 1 to 6 P8 ₃ , P8 ₄ , P9 ₀ to P9 ₅ , port B		$V_{cc} \times 0.7$	_	V _{cc} + 0.3	V	
Input low voltage	RES, STBY, MD ₂ to MD ₀	V _{IL}	-0.3	_	$V_{cc} \times 0.1$	V	
	NMI, EXTAL,	=	-0.3	_	$V_{cc} \times 0.2$	V	V _{cc} < 4.0 V
	ports 1 to 7 P8 ₃ , P8 ₄ , P9 ₀ to P9 ₅ , port B				0.8	V	$V_{cc} = 4.0 \text{ to } 5.5 \text{ V}$
Output high	All output pins	V _{OH}	V _{cc} - 0.5	_	_	V	I _{OH} = -200 μA
voltage	(except RESO)		$V_{cc} - 1.0$	_	_	V	$I_{OH} = -1 \text{ mA}$
Output low voltage	All output pins (except RESO)	V_{oL}	_	_	0.4	V	$I_{OL} = 1.6 \text{ mA}$
	Ports 1, 2, and 5		_	_	1.0	V	$I_{OL} = 5 \text{ mA}$ ($V_{CC} < 4.0 \text{ V}$)
							$I_{oL} = 10 \text{ mA}$ ($V_{cc} = 4.0 \text{ to}$ 5.5 V)
	RESO	-	_	_	0.4	V	I _{oL} = 1.6 mA
Input leakage current	STBY, NMI, RES, MD ₂ to MD ₀		_	_	1.0	μΑ	$V_{in} = 0.5 \text{ V to}$ $V_{cc} - 0.5 \text{ V}$
	Port 7		_	_	1.0	μΑ	$V_{in} = 0.5 \text{ V to}$ $AV_{cc} - 0.5 \text{ V}$

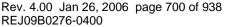
Item		Symbol	Min	Тур	Max	Unit	Test Conditions																				
Three-state leakage	Ports 1 to 6 Ports 8 to B	I _{TSI}	_	_	1.0	μΑ	$V_{in} = 0.5 \text{ V to} $ $V_{cc} - 0.5 \text{ V} $																				
current	RESO	=	_	_	10.0	μA	$V_{in} = 0 V$																				
Input pull-up MOS current	Ports 2, 4, and 5	- I _p	10	_	300	μΑ	V _{in} = 0 V																				
Input	NMI	C _{in}	_	_	50	pF	V _{in} = 0 V																				
capacitance	All input pins except NMI		_	_	15	pF	f = 1 MHz $T_a = 25$ °C																				
Current dissipation*2	Normal operation	I_cc*3	_	18 (3.0 V)	51	mA	f = 10 MHz																				
	Sleep mode	_	_	14 (3.0 V)	37	mA	f = 10 MHz																				
	Module standby mode		_	8 (3.0 V)	26	mA	f = 10 MHz																				
	Standby mode	_	_	0.01	5.0	μΑ	T _a ≤ 50°C																				
			_	_	20.0	μΑ	$50^{\circ}\text{C} \leq \text{T}_{a}$																				
Analog	During A/D	Al _{cc}	_	0.2	0.5	mA	$AV_{cc} = 3.0 \text{ V}$																				
power supply current	conversion		_	0.6	_	mA	$AV_{cc} = 5.0 V$																				
carrone	During A/D	_	_	0.2	0.5	mA	$AV_{cc} = 3.0 \text{ V}$																				
	and D/A conversion		_	0.6	_	mA	$AV_{cc} = 5.0 V$																				
	Idle	_	_	0.01	5.0	μΑ	DASTE = 0																				
Reference	During A/D	Al _{cc}	_	0.3	0.5	mA	V _{REF} = 3.0 V																				
current	conversion	_	-	=	_	_	_	_	_	_	_	_	_	_				_	_	_	_	_	_	0.5	_	mA	$V_{REF} = 5.0 \text{ V}$
	During A/D																					_	1.2	2.0	mA	V _{REF} = 3.0 V	
	and D/A conversion	_	_	2.0	_	mA	$V_{REF} = 5.0 \text{ V}$																				
	Idle			0.01	5.0	μΑ	DASTE = 0																				
RAM standby	RAM standby voltage		2.0	_	_	V																					

Notes: 1. Do not open the pin connections of the AV_{cc}, V_{REF} and AV_{ss} pins while the A/D converter is not in use

Connect the AV $_{\rm CC}$ and V $_{\rm REF}$ pins to the V $_{\rm CC}$ and connect the AV $_{\rm SS}$ pin to the V $_{\rm SS}$ respectively.

2. Given current consumption values are when all the output pins are made to unloaded state and, furthermore, when the on-chip pull-up MOS is turned off under conditions that V_{IH} min = $V_{\text{CC}} - 0.5$ V and V_{IL} max = 0.5 V.

Also, the aforesaid current consumption values are when V $_{\rm IH}$ min = V $_{\rm CC}$ \times 0.9 and V $_{\rm IL}$ max = 0.3 V under the condition of V $_{\rm RAM}$ \leq V $_{\rm CC}$ < 2.7 V.





3. I_{cc} max. (under normal operations) = 1.0 (mA) + 0.90 (mA/(MHz × V)) × V_{cc} × f I_{cc} max. (when using the sleeve) = 1.0 (mA) + 0.65 (mA/(MHz × V)) × V_{cc} × f I_{cc} max. (when the sleeve + module are standing by) = 1.0 (mA) + 0.45 (mA/(MHz × V)) × V_{cc} × f Also, the typ. values for current dissipation are reference values.

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Table 21.2 DC Characteristics (3)

Conditions: $V_{cc} = 3.0 \text{ to } 5.5 \text{ V}, AV_{cc} = 3.0 \text{ to } 5.5 \text{ V}, V_{REF} = 3.0 \text{ V to } AV_{cc}^{*1},$

 $V_{ss} = AV_{ss} = 0 V_{ss}^{*1}$, $T_a = -20^{\circ}C$ to +75°C (regular specifications), $T_a = -40^{\circ}C$ to +85°C (wide-range specifications)

Item		Symbol	Min	Тур	Max	Unit	Test Conditions
Schmitt trigger input voltages	Port A, P8 ₀ to P8 ₂	V_{T}^{-} V_{T}^{+} $V_{T}^{+} - V_{T}^{-}$	$V_{cc} \times 0.2$ $V_{cc} \times 0.07$			V V V	
Input high voltage	RES, STBY, NMI, MD ₂ to MD ₀	V _{IH}	$V_{cc} \times 0.9$			V	
	EXTAL	-	$V_{cc} \times 0.7$	_	V _{cc} + 0.3	V	_
	Port 7	-	$V_{cc} \times 0.7$		AV _{cc} + 0.3	V	_
	Ports 1 to 6 P8 ₃ , P8 ₄ , P9 ₀ to P9 ₅ , port B		$V_{cc} \times 0.7$	_	V _{cc} + 0.3	V	_
Input low voltage	RES, STBY, MD ₂ to MD ₀	V _{IL}	-0.3	_	$V_{cc} \times 0.1$	V	
	NMI, EXTAL,	:	-0.3	_	$V_{cc} \times 0.2$	V	V _{cc} < 4.0 V
	ports 1 to 7 P8 ₃ , P8 ₄ , P9 ₀ to P9 ₅ , port B				0.8	V	$V_{cc} = 4.0 \text{ to } 5.5 \text{ V}$
Output high	All output pins	V _{OH}	V _{cc} - 0.5		_	V	$I_{OH} = -200 \mu A$
voltage	(except RESO)		V _{cc} - 1.0	_	_	V	$I_{OH} = -1 \text{ mA}$
Output low voltage	All output pins (except RESO)	V_{oL}	_	_	0.4	V	$I_{OL} = 1.6 \text{ mA}$
	Ports 1, 2, and 5		_	_	1.0	V	$I_{OL} = 5 \text{ mA}$ ($V_{CC} < 4.0 \text{ V}$)
							$I_{oL} = 10 \text{ mA}$ ($V_{cc} = 4.0 \text{ to}$ 5.5 V)
	RESO	-	_	_	0.4	V	I _{OL} = 1.6 mA
Input leakage current	STBY, RES, NMI, MD_2 to MD_0	I _{in}	_	_	1.0	μA	$V_{in} = 0.5 \text{ V to}$ $V_{cc} - 0.5 \text{ V}$
	Port 7		_	_	1.0	μΑ	$V_{in} = 0.5 \text{ V to}$ $AV_{cc} - 0.5 \text{ V}$

Item		Symbol	Min	Тур	Max	Unit	Test Conditions
Three-state leakage	Ports 1 to 6 Ports 8 to B	I _{TSI}	_	_	1.0	μΑ	$V_{in} = 0.5 \text{ V to} $ $V_{cc} - 0.5 \text{ V} $
current	RESO	=	_	_	10.0	μA	$V_{in} = 0 V$
Input pull-up MOS current	Ports 2, 4, and 5	- I _p	10	_	300	μΑ	$V_{in} = 0 V$
Input	NMI	C _{in}	_	_	50	pF	$V_{in} = 0 V$
capacitance	All input pins except NMI		_	_	15	pF	f = 1 MHz $T_a = 25$ °C
Current dissipation*2	Normal operation	I_cc *3	_	28 (3.5 V)	66	mA	f = 13 MHz
	Sleep mode	_	_	20 (3.5 V)	48	mA	f = 13 MHz
	Module standby mode	_	_	13 (3.5 V)	34	mA	f = 13 MHz
	Standby mode	=	_	0.01	5.0	μA	$T_a \le 50$ °C
			_	_	20.0	μA	50°C ≤ T _a
Analog	During A/D	Al _{cc}	_	0.2	0.5	mA	$AV_{cc} = 3.0 \text{ V}$
power supply current	conversion	=	_	0.6	_	mA	$AV_{cc} = 5.0 V$
Current	During A/D	=	_	0.2	0.5	mA	$AV_{cc} = 3.0 V$
	and D/A conversion		_	0.6	_	mA	$AV_{cc} = 5.0 V$
	Idle	_	_	0.01	5.0	μA	DASTE = 0
Reference	During A/D	Al _{cc}	_	0.3	0.5	mA	V _{REF} = 3.0 V
current	conversion	=	_	0.5	_	mA	V _{REF} = 5.0 V
	During A/D	_	_	1.2	2.0	mA	$V_{REF} = 3.0 \text{ V}$
	and D/A conversion	_	_	2.0	_	mA	$V_{REF} = 5.0 \text{ V}$
	Idle	=	_	0.01	5.0	μΑ	DASTE = 0
RAM standby	voltage	$V_{\scriptscriptstyle{RAM}}$	2.0	_	_	V	

Notes: 1. Do not open the pin connections of the AV_{CC}, V_{REF} and AV_{SS} pins while the A/D converter is not in use.

Connect the AV $_{\rm CC}$ and V $_{\rm REF}$ pins to the V $_{\rm CC}$ and connect the AV $_{\rm SS}$ pin to the V $_{\rm SS}$, respectively.

2. Given current consumption values are when all the output pins are made to unloaded state and, furthermore, when the on-chip pull-up MOS is turned off under conditions that V_{IH} min = $V_{\text{CC}} - 0.5$ V and V_{IL} max = 0.5 V.

Also, the aforesaid current consumption values are when V $_{\rm IH}$ min = V $_{\rm CC}$ \times 0.9 and V $_{\rm IL}$ max = 0.3 V under the condition of V $_{\rm RAM}$ \leq V $_{\rm CC}$ < 3.0 V.

3. I_{cc} max. (under normal operations) = 1.0 (mA) + 0.90 (mA/(MHz × V)) × V_{cc} × f I_{cc} max. (when using the sleeve) = 1.0 (mA) + 0.65 (mA/(MHz × V)) × V_{cc} × f I_{cc} max. (when the sleeve + module are standing by) = 1.0 (mA) + 0.45 (mA/(MHz × V)) × V_{cc} × f Also, the typ. values for current dissipation are reference values.

Table 21.3 Permissible Output Currents

Conditions:
$$V_{cc} = 2.7 \text{ V to } 5.5 \text{ V}$$
, $AV_{cc} = 2.7 \text{ V to } 5.5 \text{ V}$, $V_{REF} = 2.7 \text{ V to } AV_{cc}$, $V_{ss} = AV_{ss} = 0 \text{ V}$, $T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$ (regular specifications), $T_a = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ (wide-range specifications)

Item		Symbol	Min	Тур	Max	Unit
Permissible output	Ports 1, 2, and 5	I _{OL}	_	_	10	mA
low current (per pin)	Other output pins		_	_	2.0	mA
Permissible output low current (total)	Total of 20 pins in Ports 1, 2, and 5	$\Sigma I_{_{ m OL}}$	_	_	80	mA
	Total of all output pins, including the above	_	_	_	120	mA
Permissible output high current (per pin)	All output pins	-I _{OH}	_	_	2.0	mA
Permissible output high current (total)	Total of all output pins	$ -\Sigma I_{OH} $	_	_	40	mA

Notes: 1. To protect chip reliability, do not exceed the output current values in table 21.3.

2. When driving a darlington pair, always insert a current-limiting resistor in the output line, as shown in figures 21.1 and 21.2.

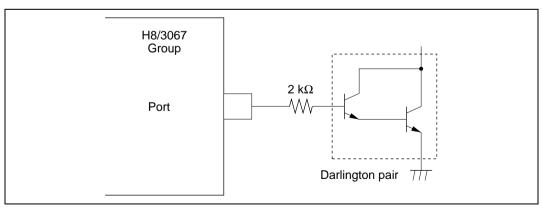


Figure 21.1 Darlington Pair Drive Circuit (Example)

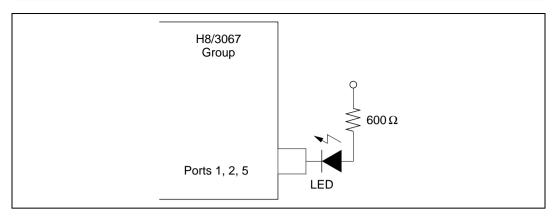


Figure 21.2 Sample LED Circuit

21.1.3 **AC Characteristics**

Clock timing parameters are listed in table 21.4, control signal timing parameters in table 21.5, and bus timing parameters in table 21.6. Timing parameters of the on-chip supporting modules are listed in table 21.7.

Table 21.4 Clock Timing

 $T_a = -20$ °C to +75°C (regular specifications), $T_a = -40$ °C to +85°C (wide-range Condition:

specifications)

Condition A: $V_{CC} = 2.7$ to 5.5 V, $AV_{CC} = 2.7$ to 5.5 V, $V_{REF} = 2.7$ to AV_{CC} , $V_{SS} = AV_{SS} = 0$ V

Condition B: $V_{CC} = 3.0 \text{ to } 5.5 \text{ V}, AV_{CC} = 3.0 \text{ to } 5.5 \text{ V}, V_{REF} = 3.0 \text{ to } AV_{CC}, V_{SS} = AV_{SS} = 0 \text{ V}$

Condition C: $V_{\text{CC}} = 5.0 \text{ V} \pm 10\%$, $AV_{\text{CC}} = 5.0 \text{ V} \pm 10\%$, $V_{\text{REF}} = 4.5 \text{ to } AV_{\text{CC}}$, $V_{\text{SS}} = AV_{\text{SS}} = 0 \text{ V}$

			Α		В		С	_	Test
Item	Symbol	Min	Max	Min	Max	Min	Max	Unit	Conditions
Clock cycle time	t _{cyc}	100	1000	76.9	1000	50	1000	ns	Figure 21.11
Clock pulse low width	t _{cL}	30	_	18	_	15	_	ns	_
Clock pulse high width	t _{ch}	30	_	18	_	15	_	ns	_
Clock rise time	t _{Cr}	_	20	_	15	_	10	ns	_
Clock fall time	t _{Cf}	_	20	_	15	_	10	ns	_
Clock oscillator settling time at reset	t _{osc1}	20	_	20	_	20	_	ms	Figure 21.7
Clock oscillator settling time in software standby	t _{osc2}	7	_	7	_	7	_	ms	Figure 20.1

Table 21.5 Control Signal Timing

Condition: $T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$ (regular specifications), $T_a = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ (wide-range

specifications)

Condition A: $V_{CC} = 2.7$ to 5.5 V, $AV_{CC} = 2.7$ to 5.5 V, $V_{REF} = 2.7$ to AV_{CC} , $V_{SS} = AV_{SS} = 0$ V

Condition B: $V_{CC} = 3.0 \text{ to } 5.5 \text{ V}$, $AV_{CC} = 3.0 \text{ to } 5.5 \text{ V}$, $V_{REF} = 3.0 \text{ to } AV_{CC}$, $V_{SS} = AV_{SS} = 0 \text{ V}$

Condition C: $V_{CC} = 5.0 \text{ V} \pm 10\%$, $AV_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ to } AV_{CC}$, $V_{SS} = AV_{SS} = 0 \text{ V}$

				Con					
			Α		В		С	_	Test
Item	Symbol	Min	Max	Min	Max	Min	Max	Unit	Conditions
RES setup time	t _{RESS}	200		200	_	150	_	ns	Figure 21.8
RES pulse width	t _{RESW}	10	_	10	_	10		t _{cyc}	_
Mode programming setup time	t _{MDS}	200	_	200	_	200	_	ns	_
RESO output delay time	t _{RESD}	_	100	_	100	_	50	ns	Figure 21.9
RESO output pulse width	t _{RESOW}	132	_	132	_	132	_	t _{cyc}	_
NMI, IRQ setup time	t _{NMIS}	200	_	200	_	150	_	ns	Figure 21.10
NMI, IRQ hold time	t _{nmih}	10	_	10	_	10	_	ns	_
NMI, IRQ pulse width	t _{NMIW}	200	_	200	_	200	_	ns	_

Table 21.6 Bus Timing

Condition: $T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$ (regular specifications), $T_a = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ (wide-range

specifications)

Condition A: $V_{CC} = 2.7$ to 5.5 V, $AV_{CC} = 2.7$ to 5.5 V, $V_{REF} = 2.7$ to AV_{CC} , $V_{SS} = AV_{SS} = 0$ V

Condition B: $V_{CC} = 3.0 \text{ to } 5.5 \text{ V}, AV_{CC} = 3.0 \text{ to } 5.5 \text{ V}, V_{REF} = 3.0 \text{ to } AV_{CC}, V_{SS} = AV_{SS} = 0 \text{ V}$

Condition C: $V_{CC} = 5.0 \text{ V} \pm 10\%$, $AV_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ to } AV_{CC}$, $V_{SS} = AV_{SS} = 0 \text{ V}$

		Α		Е	3	С		_	Test
Item	Symbol	Min	Max	Min	Max	Min	Max	Unit	Conditions
Address delay time	t _{AD}	_	50	_	40	_	25	ns	Figure 21.11,
Address hold time	t _{AH}	0.5 t _{cyc} - 45	_	0.5 t _{cyc} - 35	_	0.5 t _{cyc} - 20	_	ns	figure 21.12, figure 21.14, figure 21.15,
Read strobe delay time	t _{RSD}	_	60	_	50	_	25	ns	figure 21.17
Address strobe delay time	t _{ASD}	_	60	_	50	_	25	ns	_
Write strobe delay time	t _{wsd}	_	60	_	50	_	25	ns	_
Strobe delay time	t _{sd}	_	60	_	50	_	25	ns	=
Write strobe pulse width 1	t _{wsw1}	1.0 t _{cyc} - 50	_	1.0 t _{cyc} - 40	_	1.0 t _{cyc} - 25	_	ns	_
Write strobe pulse width 2	t _{wsw2}	1.5 t _{cyc} - 50	_	1.5 t _{cyc} - 40	_	1.5 t _{cyc} - 25	_	ns	_
Address setup time 1	t _{AS1}	0.5 t _{cyc} - 45	_	0.5 t _{cyc} - 29	_	0.5 t _{cyc} - 20	_	ns	_
Address setup time 2	t _{AS2}	1.0 t _{cyc} - 45	_	1.0 t _{cyc} - 35	_	1.0 t _{cyc} - 20	_	ns	_
Read data setup time	t _{RDS}	50	_	40	_	25	_	ns	_
Read data hold time	t _{RDH}	0	_	0	_	0	_	ns	_
Write data delay time	t _{wdd}	_	60	_	50	_	35	ns	_
Write data setup time 1	t _{wds1}	1.0 t _{cyc} – 50	-	1.0 t _{cyc} -		1.0 t _{cyc} –	- —	ns	_
Write data setup time 2	t _{wds2}	2.0 t _{cyc} – 50	-	2.0 t _{cyc} -	- —	2.0 t _{cyc} – 30	- —	ns	_

			A		В		С	_	Test
Item	Symbol	Min	Max	Min	Max	Min	Max	Unit	Conditions
Write data hold time	t _{wdh}	0.5 t _{cyc} - 30	_	0.5 t _{cyc} – 25	_	0.5 t _{cyc} – 15	_	ns	Figure 21.11, figure 21.12,
Read data access time 1	t _{ACC1}	_	2.0 t _{cyc} - 100	_	2.0 t _{cyc} - 80	_	2.0 t _{cyc} - 45	ns	figure 21.14, figure 21.15, figure 21.17
Read data access time 2	t _{ACC2}	_	3.0 t _{cyc} - 100	_	3.0 t _{cyc} - 80	_	3.0 t _{cyc} - 45	ns	ngaro 21117
Read data access time 3	t _{ACC3}	_	1.5 t _{cyc} - 100	_	1.5 t _{cyc} - 80	_	1.5 t _{cyc} - 45	ns	
Read data access time 4	t _{ACC4}	_	2.5 t _{cyc} - 100	_	2.5 t _{cyc} - 80	_	2.5 t _{cyc} - 45	ns	_
Precharge time 1	t _{PCH1}	1.0 t _{cyc} – 40	_	1.0 t _{cyc} - 30	_	1.0 t _{cyc} – 20	_	ns	_
Precharge time 2	t _{PCH2}	0.5 t _{cyc} - 40	_	0.5 t _{cyc} - 30	_	0.5 t _{cyc} - 20	_	ns	_
Wait setup time	t _{wts}	40	_	40	_	25	_	ns	Figure 21.13
Wait hold time	t _{wth}	5		5	_	5	_	ns	=
Bus request setup time	t _{BRQS}	40	_	40	_	25	_	ns	Figure 21.16
Bus acknowledge delay time 1	t _{BACD1}	_	60	_	50	_	30	ns	_
Bus acknowledge delay time 2	t _{BACD2}	_	60	_	50	_	30	ns	_
Bus-floating time	t _{BZD}	_	60	_	50	_	30	ns	_
RAS precharge time	t _{RP}	1.5 t _{cyc} - 50	_	1.5 t _{cyc} - 40	_	1.5 t _{cyc} - 25	_	ns	Figure 21.17 to figure 21.19
CAS precharge time	$\mathbf{t}_{\mathtt{CP}}$	$0.5 t_{cyc} - 30$	_	0.5 t _{cyc} - 25	_	0.5 t _{cyc} - 15	_	ns	_
Low address hold time	t _{RAH}	0.5 t _{cyc} - 30	_	0.5 t _{cyc} – 25	_	0.5 t _{cyc} - 15	_	ns	_
RAS delay time 1	t _{RAD1}	_	60	_	50	_	25	ns	_
RAS delay time 2	t _{RAD2}	_	60	_	50	_	30	ns	

			A		В	(С	-	Test
Item	Symbol	Min	Max	Min	Max	Min	Max	Unit	Conditions
CAS delay time 1	t _{CASD1}	_	60	_	50	_	25	ns	Figure 21.17
CAS delay time 2	t _{CASD2}	_	60	_	50	_	25	ns	⁻ to ₋ figure 21.19
WE delay time	t _{wcd}	_	60	_	50	_	25	ns	- ligare 21.15
CAS pulse width 1	t _{CAS1}	1.5 t _{cyc} - 50	_	1.5 t _{cyc} - 40	_	1.5 t _{cyc} – 20	_	ns	_
CAS pulse width 2	t _{CAS2}	1.0 t _{cyc} - 50	_	1.0 t _{cyc} - 40	_	1.0 t _{cyc} – 20	_	ns	_
CAS pulse width 3	t _{CAS3}	1.0 t _{cyc} - 50	_	1.0 t _{cyc} – 40	_	1.0 t _{cyc} – 20	_	ns	_
RAS access time	t _{RAC}	_	2.5 t _{cyc} - 80	_	2.5 t _{cyc} - 70	_	2.5 t _{cyc} - 40	ns	_
Address access time	t _{AA}	_	2.0 t _{cyc} - 100	_	2.0 t _{cyc} - 80	_	2.0 t _{cyc} - 50	ns	_
CAS access time	t _{CAC}	_	1.5 t _{cyc} - 100	_	1.5 t _{cyc} - 80	_	1.5 t _{cyc} – 50	ns	_
WE setup time	t _{wcs}	0.5 t _{cyc} - 45	_	0.5 t _{cyc} - 35	_	0.5 t _{cyc} - 20	_	ns	_
WE hold time	t _{wch}	0.5 t _{cyc} - 40	_	0.5 t _{cyc} - 28	_	0.5 t _{cyc} - 15	_	ns	_
Write data setup time	t _{wds}	0.5 t _{cyc} - 45	_	0.5 t _{cyc} - 35	_	0.5 t _{cyc} - 20	_	ns	_
WE write data hold time	t _{wdh}	0.5 t _{cyc} - 30	_	0.5 t _{cyc} - 25	_	0.5 t _{cyc} - 15	_	ns	_
CAS setup time 1	t _{CSR1}	0.5 t _{cyc} - 30	_	0.5 t _{cyc} - 25	_	0.5 t _{cyc} - 20	_	ns	_
CAS setup time 2	t _{CSR2}	0.5 t _{cyc} - 30	_	0.5 t _{cyc} - 25	_	0.5 t _{cyc} - 15	_	ns	_
CAS hold time	t _{CHR}	0.5 t _{cyc} - 30	_	0.5 t _{cyc} - 25	_	0.5 t _{cyc} - 15	_	ns	_
RAS pulse width	t _{RAS}	1.5 t _{cyc} - 30	_	1.5 t _{cyc} - 25	_	1.5 t _{cyc} - 15	_	ns	

Table 21.7 Timing of On-Chip Supporting Modules

Condition: $T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$ (regular specifications), $T_a = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ (wide-range

specifications)

Condition A: $V_{CC} = 2.7$ to 5.5 V, $AV_{CC} = 2.7$ to 5.5 V, $V_{REF} = 2.7$ to AV_{CC} , $V_{SS} = AV_{SS} = 0$ V

Condition B: $V_{CC} = 3.0 \text{ to } 5.5 \text{ V}$, $AV_{CC} = 3.0 \text{ to } 5.5 \text{ V}$, $V_{REF} = 3.0 \text{ to } AV_{CC}$, $V_{SS} = AV_{SS} = 0 \text{ V}$

Condition C: $V_{\text{CC}} = 5.0 \text{ V} \pm 10\%$, $AV_{\text{CC}} = 5.0 \text{ V} \pm 10\%$, $V_{\text{REF}} = 4.5$ to AV_{CC} , $V_{\text{SS}} = AV_{\text{SS}} = 0 \text{ V}$

				Α		В	(С		Test
Item		Symbol	Min	Max	Min	Max	Min	Max	Unit	Conditions
Ports and	Output data dela	y t _{PWD}	_	100	_	100	_	50	ns	Figure 21.20
TPC	Input data setup time	t _{PRS}	50	_	50	_	50	_	ns	_
	Input data hold time	t _{PRH}	50	_	50	_	50	_	ns	
16-bit timer	Timer output delay time	t _{TOCD}	_	100	_	100	_	50	ns	Figure 21.21
	Timer input setup	t _{TICS}	50	_	50	_	50	_	ns	_
	Timer clock input setup time	t _{TCKS}	50	_	50	_	50	_	ns	Figure 21.22
	Timer Single clock edge	t _{TCKWH}	1.5	_	1.5	_	1.5	_	t _{cyc}	_
	pulse Both width edges	t _{TCKWL}	2.5	_	2.5	_	2.5	_	t _{cyc}	
8-bit timer	Timer output delay time	t _{TOCD}	_	100	_	100	_	50	ns	Figure 21.21
	Timer input setup time	t _{TICS}	50	_	50	_	50	_	ns	_
	Timer clock input setup time	t _{TCKS}	50	_	50	_	50	_	ns	Figure 21.22
	Timer Single clock edge	t _{TCKWH}	1.5	_	1.5	_	1.5	_	t _{cyc}	_
	pulse Both width edges	t _{TCKWL}	2.5	_	2.5	_	2.5	_	t _{cyc}	_

						Cond					
					4	I	В		С		Test
Item			Symbol	Min	Max	Min	Max	Min	Max	Unit	Conditions
SCI	Input clock	Asyn- chronous	t _{Scyc}	4	_	4	_	4	_	t _{cyc}	Figure 21.23
	cycle	Syn- chronous	_	6	_	6	_	6	_	t _{cyc}	_
	Input c	lock rise	t _{SCKr}	1.5	_	1.5	_	1.5	_	$t_{\rm cyc}$	_
	Input c	lock fall	t _{SCKf}	1.5	_	1.5	_	1.5	_	t _{cyc}	_
	Input c		t _{sckw}	0.4	0.6	0.4	0.6	0.4	0.6	t _{Scyc}	_
	Transmit data delay time		t _{TXD}	_	100	_	100	_	100	ns	Figure 21.24
	Receiv setup t (synch		t _{RXS}	100		100		100		ns	_
	Receiv data ho	old input	t _{RXH}	100	_	100	_	100	_	ns	_
	time (s chrono		_	0	_	0	_	0	_	ns	_
DMAC	TEND time 1	delay	t _{TED1}	_	100	_	100	_	50	ns	Figure 21.25, figure 21.26
	TEND time 2	delay	t _{TED2}	_	100	_	100	_	50	ns	_
	DREQ time	setup	t _{DRQS}	40	_	40	_	25	_	ns	Figure 21.27
	DREQ time	hold	t _{DRQH}	10	_	10	_	10	_	ns	_

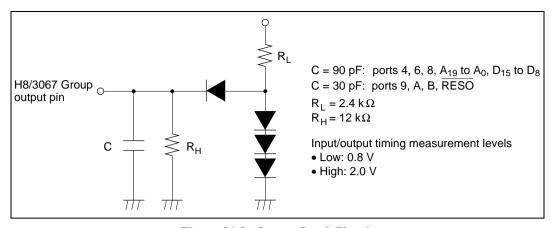


Figure 21.3 Output Load Circuit

21.1.4 A/D Conversion Characteristics

Table 21.8 lists the A/D conversion characteristics.

Table 21.8 A/D Conversion Characteristics

Condition: $T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$ (regular specifications), $T_a = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ (wide-range

specifications)

Condition A: $V_{CC} = 2.7$ to 5.5 V, $AV_{CC} = 2.7$ to 5.5 V, $V_{REF} = 2.7$ to AV_{CC} , $V_{SS} = AV_{SS} = 0$ V, fmax

= 10 MHz

Condition B: $V_{CC} = 3.0 \text{ to } 5.5 \text{ V}, AV_{CC} = 3.0 \text{ to } 5.5 \text{ V}, V_{REF} = 3.0 \text{ to } AV_{CC}, V_{SS} = AV_{SS} = 0 \text{ V}, \text{ fmax}$

= 13 MHz

Condition C: $V_{CC} = 5.0 \text{ V} \pm 10\%$, $AV_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ to } AV_{CC}$, $V_{SS} = AV_{SS} = 0 \text{ V}$,

						С	ondit	ion				
			Α			В			С			
Item			Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Conver-	Resolution		10	10	10	10	10	10	10	10	10	bits
sion time: 134 states	Conversion tir mode)	me (single	_		134	_		134	_	_	134	t _{cyc}
	Analog input of	capacitance	_	_	20		_	20	_	_	20	pF
	Permissible	φ ≤ 13 MHz	_	_	_		_	_	_	_	10	kΩ
	signal-source impedance	φ > 13 MHz	_	_	_	_	_	_	_	_	5	kΩ
		4.0 V ≤ AV _{cc} ≤ 5.5 V	_	_	10	_	_	10	_	_	_	kΩ
		2.7 V ≤ AV _{cc} < 4.0 V	_	_	5	_	_	5	_	_	_	kΩ
	Nonlinearity e	rror	_	_	±7.5	_	_	±7.5	_	_	±3.5	LSB
	Offset error		_	_	±7.5	_	_	±7.5	_	_	±3.5	LSB
	Full-scale erro	or		_	±7.5	_	_	±7.5	_		±3.5	LSB
	Quantization 6	error	_	_	±0.5	_	_	±0.5	_	_	±0.5	LSB
	Absolute accu	ıracy	_	_	±8.0	_	_	±8.0	_	_	±4.0	LSB

						С	ondi	tion				
				Α			В		С			
Item			Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Conver-	Resolution		10	10	10	10	10	10	10	10	10	bits
sion time: 70 states	Conversion tir mode)	me (single	_	_	70	_	_	70	_	_	70	t _{cyc}
	Analog input of	capacitance	_	_	20	_	_	20	_	_	20	pF
	Permissible signal-source impedance	φ ≤ 13 MHz	_	_	_	_	_	_	_	_	5	kΩ
		φ > 13 MHz	_	_	_	_	_	_	_	_	3	kΩ
		4.0 V ≤ AV _{cc} ≤ 5.5 V	_	_	5	_	_	5	_	_	_	kΩ
		2.7 V ≤ AV _{cc} < 4.0 V	_	_	3	_	_	3	_	_	_	kΩ
	Nonlinearity e	rror	_	_	±15.5	_	_	±15.5	_	_	±7.5	LSB
	Offset error		_	_	±15.5	_	_	±15.5	_	_	±7.5	LSB
	Full-scale erro	or	_	_	±15.5	_	_	±15.5	_	_	±7.5	LSB
	Quantization 6	Quantization error		_	±0.5	_	_	±0.5	_	_	±0.5	LSB
	Absolute accu	Absolute accuracy		_	±16	_	_	±16	_	_	±8.0	LSB

21.1.5 D/A Conversion Characteristics

Table 21.9 lists the D/A conversion characteristics.

Table 21.9 D/A Conversion Characteristics

Condition: $T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$ (regular specifications), $T_a = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ (wide-range

specifications)

Condition A: $V_{CC} = 2.7$ to 5.5 V, $AV_{CC} = 2.7$ to 5.5 V, $V_{REF} = 2.7$ to AV_{CC} , $V_{SS} = AV_{SS} = 0$ V, fmax

= 10 MHz

Condition B: $V_{CC} = 3.0 \text{ to } 5.5 \text{ V}, AV_{CC} = 3.0 \text{ to } 5.5 \text{ V}, V_{REF} = 3.0 \text{ to } AV_{CC}, V_{SS} = AV_{SS} = 0 \text{ V}, \text{ fmax}$

= 13 MHz

Condition C: $V_{CC} = 5.0 \text{ V} \pm 10\%$, $AV_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ to } AV_{CC}$, $V_{SS} = AV_{SS} = 0 \text{ V}$,

	Condition											
		Α			В			С			Test	
Item	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit		
Resolution	8	8	8	8	8	8	8	8	8	bits		
Conversion time (centering time)		_	10	_	_	10	_	_	10	μs	20 pF capacitive load	
Absolute accuracy	_	±2.0	±3.0	_	±2.0	±3.0	_	±1.5	±2.0	LSB	$2 \text{ M}\Omega$ resistive load	
	_	_	±2.0	_	_	±2.0	_	_	±1.5	LSB	4 MΩ resistive load	

21.2 Electrical Characteristics of Flash Memory and Flash Memory R Versions

21.2.1 Absolute Maximum Ratings

Table 21.10 lists the absolute maximum ratings.

Table 21.10 Absolute Maximum Ratings

Item	Symbol	Value	Unit
Power supply voltage	V _{cc}	-0.3 to +7.0	V
Programming voltage (FWE)*1	V _{in}	-0.3 to V _{cc} +0.3	V
Input voltage (except for port 7)*1	V_{in}	-0.3 to V _{cc} +0.3	V
Input voltage (port 7)	V_{in}	-0.3 to AV _{cc} +0.3	V
Reference voltage	V _{REF}	-0.3 to AV _{cc} +0.3	V
Analog power supply voltage	AV _{cc}	-0.3 to +7.0	V
Analog input voltage	V _{AN}	-0.3 to AV _{cc} +0.3	V
Operating temperature	T _{opr}	Regular specifications: -20 to +75*2	°C
		Wide-range specifications: -40 to +85*2	°C
Storage temperature	T _{stg}	-55 to +125	°C

Caution: Permanent damage to the chip may result if absolute maximum ratings are exceeded.

Notes: 1. 12 V must not be applied to any pin, as this may cause permanent damage to the device

2. The operating temperature range when programming and erasing the flash memory is: $T_a = 0$ to + 75°C (regular specifications), $T_a = 0$ to + 85°C (wide-range specifications).

21.2.2 DC Characteristics

Tables 21.11 lists the DC characteristics. Table 21.12 lists the permissible output currents.

Table 21.11 DC Characteristics (1)

Conditions:
$$V_{cc} = 5.0 \text{ V} \pm 10\%$$
, $AV_{cc} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ V}$ to AV_{cc}^{*1} , $V_{ss} = AV_{ss} = 0 \text{ V}^{*1}$, $T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$ (regular specifications), $T_a = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ (wide-range specifications) [Programming/erasing conditions: $T_a = 0^{\circ}\text{C}$ to $+75^{\circ}\text{C}$ (regular specifications), $T_a = 0^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ (wide-range specifications)]

Item		Symbol	Min	Тур	Max	Unit	Test Conditions
Schmitt trigger		V _T	1.0	_	_	V	
input voltages	P8 ₀ to P8 ₂	V _T ⁺	_	_	$V_{cc} \times 0.7$	V	_
		$V_T^+ - V_T^-$	0.4	_	_	V	
Input high voltage	RES, STBY, NMI, MD ₂ to MD ₀ , FWE	V _{IH}	V _{cc} - 0.7	_	V _{cc} + 0.3	V	
	EXTAL	:	$V_{cc} \times 0.7$	_	V _{cc} + 0.3	V	_
	Port 7	•	2.0	_	AV _{cc} + 0.3	V	=
	Ports 1 to 6, P8 ₃ , P8 ₄ , P9 ₀ to P9 ₅ , port B		2.0	_	V _{cc} + 0.3	V	_
Input low voltage	RES, STBY, FWE, MD ₂ to MD ₀	V _{IL}	-0.3	_	0.5	V	
	NMI, EXTAL, ports 1 to 7, P8 ₃ , P8 ₄ , P9 ₀ to P9 ₅ , port B		-0.3	_	0.8	V	-
Output high	All output pins	V _{OH}	V _{cc} - 0.5	_	_	V	I _{OH} = -200 μA
voltage			3.5	_	_	V	$I_{OH} = -1 \text{ mA}$
Output low	All output pins	V _{oL}	_	_	0.4	V	I _{OL} = 1.6 mA
voltage	Ports 1, 2, and 5	•	_	_	1.0	V	I _{OL} = 10 mA
Input leakage current	STBY, RES, NMI, FWE MD ₂ to MD ₀	I _{in}	_	_	1.0	μA	$V_{in} = 0.5 \text{ V to} $ $V_{cc} - 0.5 \text{ V} $
	Port 7	-	_	_	1.0	μΑ	$V_{in} = 0.5 \text{ V to}$ $AV_{cc} - 0.5 \text{ V}$

Item		Symbol	Min	Тур	Max	Unit	Test Conditions
Three-state leakage current	Ports 1 to 6 Ports 8 to B	I _{TSI}	_	_	1.0	μΑ	$V_{in} = 0.5 \text{ V to} $ $V_{cc} - 0.5 \text{ V} $
Input pull-up MOS current	Ports 2, 4, and 5	-I _p	50	_	300	μΑ	V _{in} = 0 V
Input	FWE	C _{in}	_	_	80	pF	$V_{in} = 0 V$
capacitance	NMI	_	_	_	50	pF	─ f = 1 MHz T _a = 25°C
	All input pins except NMI, and FWE	_	_	_	15	pF	— I _a = 25 C
Current dissipation*2	Normal operation	I _{cc} *3	_	55 (5.0 V)	100	mA	f = 20 MHz
	Sleep mode	-	_	40 (5.0 V)	73	mA	f = 20 MHz
	Module standby mode	-	_	24 (5.0 V)	51	mA	f = 20 MHz
	Standby mode		_	0.01	5.0	μΑ	$T_a \le 50$ °C
			_	_	20.0	μΑ	50°C ≤ T _a
	Flash memory programming/ erasing	-	_	60 (5.0 V)	110	mA	$0^{\circ}\text{C} \le \text{T}_{\text{a}} \le 85^{\circ}\text{C}$ f = 20 MHz
Analog power supply current	During A/D conversion	Al _{cc}	_	0.6	1.5	mA	
	During A/D and D/A conversion	-	_	0.6	1.5	mA	_
	Idle	-	_	0.01	5.0	μΑ	DASTE = 0
Reference current	During A/D conversion	Al _{cc}	_	0.5	0.8	mA	
	During A/D and D/A conversion	-	_	2.0	3.0	mA	_
	Idle	=	_	0.01	5.0	μΑ	DASTE = 0
RAM standby v	/oltage	V_{RAM}	2.0	_	_	V	

Notes: 1. Do not open the pin connections of the AV_{cc}, V_{REF} and AV_{ss} pins while the A/D converter is not in use.

Connect the AV $_{\rm CC}$ and V $_{\rm REF}$ pins to the V $_{\rm CC}$ and connect the AV $_{\rm SS}$ pin to the V $_{\rm SS}$ respectively.

- 2. Given current consumption values are when all the output pins are made to unloaded state and, furthermore, when the on-chip pull-up MOS is turned off under conditions that V_{IH} min = V_{CC} 0.5 V and V_{II} max = 0.5 V.
 - Also, the aforesaid current consumption values are when V $_{\rm IH}$ min = V $_{\rm CC}$ \times 0.9 and V $_{\rm IL}$ max = 0.3 V under the condition of V $_{\rm RAM}$ \leq V $_{\rm CC}$ < 2.7 V.
- 3. I_{cc} max. (under normal operations) = 1.0 (mA) + 0.90 (mA/(MHz × V)) × V_{cc} × f I_{cc} max. (when using the sleeve) = 1.0 (mA) + 0.65 (mA/(MHz × V)) × V_{cc} × f I_{cc} max. (when the sleeve + module are standing by) = 1.0 (mA) + 0.45 (mA/(MHz × V)) × V_{cc} × f

Also, the typ. values for current dissipation are reference values.



Table 21.11 DC Characteristics (2)

Conditions: $V_{CC} = 3.0 \text{ to } 5.5 \text{ V}, \text{ AV}_{CC} = 3.0 \text{ to } 5.5 \text{ V}, \text{ V}_{REF} = 3.0 \text{ V to AV}_{CC}^{*1},$ $V_{SS} = \text{AV}_{SS} = 0 \text{ V}^{*1}, \text{ T}_{a} = -20^{\circ}\text{C to } +75^{\circ}\text{C (regular specifications)},$

 $T_a = -40^{\circ}$ C to +85°C (wide-range specifications)

[Programming/erasing conditions: $V_{cc} = 3.0$ to 3.6 V, $T_a = 0$ to +75°C (regular specifications), $T_a = 0$ to +85°C (wide-range specifications)]

Item		Symbol	Min	Тур	Max	Unit	Test Conditions
Schmitt trigger	Port A,	V _T	$V_{cc} \times 0.2$	_	_	V	
input voltages	P8 ₀ to P8 ₂	V _T +	_	_	$V_{cc} \times 0.7$	V	_
		$V_{\scriptscriptstyle T}^{\;\scriptscriptstyle +} - V_{\scriptscriptstyle T}^{\;\scriptscriptstyle -}$	$V_{cc} \times 0.07$	_	_	V	_
Input high voltage	STBY, RES, NMI, MD ₂ to MD ₀ , FWE	V _{IH}	$V_{cc} \times 0.9$	_	V _{cc} + 0.3	V	
	EXTAL	•	$V_{cc} \times 0.7$	_	V _{cc} + 0.3	V	=
	Port 7	-	$V_{cc} \times 0.7$	_	AV _{cc} + 0.3	V	=
	Ports 1 to 6 P8 ₃ , P8 ₄ , P9 ₀ to P9 ₅ , port B		$V_{cc} \times 0.7$	_	V _{cc} + 0.3	V	_
Input low voltage	STBY, RES, FWE, MD ₂ to MD ₀	V _{IL}	-0.3	_	$V_{cc} \times 0.1$	V	
	NMI, EXTAL, Ports 1 to 7	•	-0.3	_	$V_{\rm cc} \times 0.2$	V	V _{cc} < 4.0 V
	P8 ₃ , P8 ₄ , P9 ₀ to P9 ₅ , port B				0.8	V	$V_{cc} = 4.0 \text{ to } 5.5 \text{ V}$
Output high	All output pins	V _{OH}	V _{cc} - 0.5	_	_	V	I _{OH} = -200 μA
voltage			V _{cc} - 1.0	_	_	V	$I_{OH} = -1 \text{ mA}$
Output low	All output pins	V _{oL}	_	_	0.4	V	I _{OL} = 1.6 mA
voltage	Ports 1, 2, and 5	-	_	_	1.0	V	I _{OL} = 5 mA
Input leakage current	STBY, RES, NMI, FWE, MD ₂ to MD ₀		_	_	1.0	μΑ	$V_{in} = 0.5 \text{ V to}$ $V_{cc} - 0.5 \text{ V}$
	Port 7		_	_	1.0	μΑ	$V_{in} = 0.5 \text{ V to}$ $AV_{cc} - 0.5 \text{ V}$

Item		Symbol	Min	Тур	Max	Unit	Test Conditions
Three-state leakage current	Ports 1 to 6 Ports 8 to B	I _{TSI}	_	_	1.0	μΑ	$V_{in} = 0.5 \text{ V to}$ $V_{cc} - 0.5 \text{ V}$
Input pull-up MOS current	Ports 2, 4, and 5	-I _p	10	_	300	μΑ	$V_{in} = 0 V$
Input	FWE	C _{in}	_	_	80	pF	$V_{in} = 0 V$
capacitance	NMI			_	50	pF	f = 1 MHz
	All input pins except NMI, and FWE	_	_	_	15	pF	– T _a = 25°C
Current dissipation*2	Normal operation	I_cc *3	_	28 (3.5 V)	66	mA	f = 13 MHz
	Sleep mode	-	_	20 (3.5 V)	48	mA	f = 13 MHz
	Module standby mode	-	_	13 (3.5 V)	34	mA	f = 13 MHz
	Standby mode	_	_	0.01	5.0	μΑ	T _a ≤ 50°C
			_	_	20.0	μΑ	50°C ≤ T _a
	Flash memory programming/ erasing	-	_	33 (3.5 V)	76	mA	0° C \leq T _a \leq 85°C f = 13 MHz
Analog power supply	During A/D conversion	Al _{cc}	_	0.2	0.5	mA	$AV_{cc} = 3.0 \text{ V}$
current	During A/D and D/A conversion	-	_	0.2	0.5	mA	AV _{cc} = 3.0 V
	Idle	-	_	0.01	5.0	μΑ	DASTE = 0
Reference current	During A/D conversion	Al _{cc}	_	0.3	0.5	mA	$V_{REF} = 3.0 \text{ V}$
	During A/D and D/A conversion	-	_	1.2	2.0	mA	V _{REF} = 3.0 V
	Idle	-	_	0.01	5.0	μΑ	DASTE = 0
RAM standby	voltage	V_{RAM}	2.0	_	_	V	

Notes: 1. Do not open the pin connections of the AV_{cc} , V_{REF} and AV_{SS} pins while the A/D converter is not in use.

> Connect the AV $_{\rm CC}$ and V $_{\rm REF}$ pins to the V $_{\rm CC}$ and connect the AV $_{\rm SS}$ pin to the V $_{\rm SS}$, respectively.

- 2. Given current consumption values are when all the output pins are made to unloaded state and, furthermore, when the on-chip pull-up MOS is turned off under conditions that $V_{_{IH}}$ min = $V_{_{CC}}$ 0.5 V and $V_{_{IL}}$ max = 0.5 V.
 - Also, the aforesaid current consumption values are when V $_{\rm IH}$ min = V $_{\rm CC}$ \times 0.9 and V $_{\rm IL}$ max = 0.3 V under the condition of V $_{\rm RAM}$ \leq V $_{\rm CC}$ < 3.0 V.
- 3. I_{cc} max. (under normal operations) = 1.0 (mA) + 0.90 (mA/(MHz × V)) × V_{cc} × f I_{cc} max. (when using the sleeve) = 1.0 (mA) + 0.65 (mA/(MHz × V)) × V_{cc} × f I_{cc} max. (when the sleeve + module are standing by) = 1.0 (mA) + 0.45 (mA/(MHz × V)) × V_{cc} × f

Also, the typ. values for current dissipation are reference values.

Table 21.12 Permissible Output Currents

Conditions:
$$V_{CC} = 3.0 \text{ V}$$
 to 5.5 V, $AV_{CC} = 3.0 \text{ V}$ to 5.5 V, $V_{REF} = 3.0 \text{ V}$ to AV_{CC} , $V_{ss} = AV_{ss} = 0 \text{ V}$, $T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$ (regular specifications), $T_a = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ (wide-range specifications)

Item		Symbol	Min	Тур	Max	Unit
Permissible output	Ports 1, 2, and 5	I _{OL}	_	_	10	mA
low current (per pin)	Other output pins	_	_	_	2.0	mA
Permissible output low current (total)	Sum of 20 pins in ports 1, 2, and 5	ΣI_OL	_	_	80	mA
	Total of all output pins, including the above	_	_	_	120	mA
Permissible output high current (per pin)	All output pins	-I _{OH}	_	_	2.0	mA
Permissible output high current (total)	Total of all output pins	$ -\Sigma I_{OH} $	_	_	40	mA

Notes: 1. To protect chip reliability, do not exceed the output current values in table 21.12.

2. When driving a darlington pair, always insert a current-limiting resistor in the output line, as shown in figures 21.4 and 21.5.

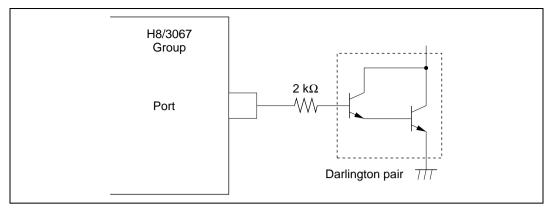


Figure 21.4 Darlington Pair Drive Circuit (Example)

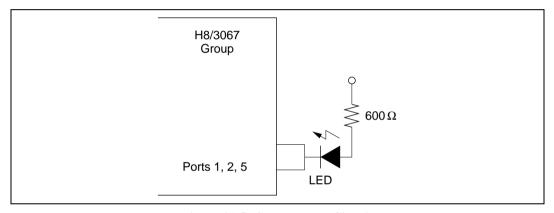


Figure 21.5 Sample LED Circuit

21.2.3 AC Characteristics

Clock timing parameters are listed in table 21.13, control signal timing parameters in table 21.14, and bus timing parameters in table 21.15. Timing parameters of the on-chip supporting modules are listed in table 21.16.

Table 21.13 Clock Timing

Condition: $T_a = -20$ °C to +75°C (regular specifications), $T_a = -40$ °C to +85°C (wide-range

specifications)

Condition A: $V_{CC} = 3.0 \text{ to } 5.5 \text{ V}, AV_{CC} = 3.0 \text{ to } 5.5 \text{ V}, V_{RFF} = 3.0 \text{ to } AV_{CC}, V_{SS} = AV_{SS} = 0 \text{ V},$

fmax = 13 MHz

Condition B: $V_{CC} = 5.0 \text{ V} \pm 10\%$, $AV_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ to } AV_{CC}$, $V_{SS} = AV_{SS} = 0 \text{ V}$,

			Cor	ndition			
			Α		В		Test
Item	Symbol	Min	Max	Min	Max	Unit	Conditions
Clock cycle time	t _{cyc}	76.9	1000	50	1000	ns	Figure 21.11
Clock pulse low width	t _{CL}	18	_	15	_	ns	
Clock pulse high width	t _{CH}	18	_	15	_	ns	
Clock rise time	t _{Cr}	_	15	_	10	ns	
Clock fall time	t _{Cf}	_	15	_	10	ns	
Clock oscillator settling time at reset	t _{osc1}	20	_	20	_	ms	Figure 21.7
Clock oscillator settling time in software standby	t _{osc2}	7	_	7	_	ms	Figure 20.1

Table 21.14 Control Signal Timing

Condition: $T_a = -20$ °C to +75°C (regular specifications), $T_a = -40$ °C to +85°C (wide-range

specifications)

Condition A: $V_{CC} = 3.0 \text{ to } 5.5 \text{ V}, AV_{CC} = 3.0 \text{ to } 5.5 \text{ V}, V_{REF} = 3.0 \text{ to } AV_{CC}, V_{SS} = AV_{SS} = 0 \text{ V},$

fmax = 13 MHz

Condition B: $V_{CC} = 5.0 \text{ V} \pm 10\%$, $AV_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ to } AV_{CC}$, $V_{SS} = AV_{SS} = 0 \text{ V}$,

fmax = 20 MHz

		A B			Test		
Item	Symbol	Min	Max	Min	Max	Unit	Conditions
RES setup time	t _{RESS}	200	_	150	_	ns	Figure 21.8
RES pulse width	t _{RESW}	20	_	20	_	t _{cyc}	
Mode programming setup time	t _{MDS}	200	_	200	_	ns	
NMI, IRQ setup time	t _{NMIS}	200	_	150	_	ns	Figure 21.10
NMI, IRQ hold time	t _{nmih}	10	_	10	_	ns	
NMI, IRQ pulse width	t _{NMIW}	200	_	200	_	ns	

Table 21.15 Bus Timing

Condition: $T_a = -20$ °C to +75°C (regular specifications), $T_a = -40$ °C to +85°C (wide-range

specifications)

Condition A: $V_{cc} = 3.0$ to 5.5 V, $AV_{cc} = 3.0$ to 5.5 V, $V_{REF} = 3.0$ to AV_{cc} , $V_{ss} = AV_{ss} = 0$ V,

fmax = 13 MHz

Condition B: $V_{cc} = 5.0 \text{ V} \pm 10\%$, $AV_{cc} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ to } AV_{cc}$, $V_{ss} = AV_{ss} = 0 \text{ V}$,

Condition	

			Α Β			Test		
Item	Symbol	Min	Max	Min	Max	Unit	Conditions	
Address delay time	t _{AD}	_	40	_	25	ns	Figure 21.11,	
Address hold time	t _{AH}	0.5 t _{cyc} - 35	_	0.5 t _{cyc} - 20	_	ns	figure 21.12, figure 21.14, – figure 21.15,	
Read strobe delay time	t _{RSD}	_	50	_	25	ns	figure 21.17	
Address strobe delay time	t	_	50	_	25	ns		
Write strobe delay time	t _{wsD}	_	50	_	25	ns		
Strobe delay time	t _{sd}	_	50	_	25	ns	_	
Write strobe pulse width 1	t _{wsw1}	1.0 t _{cyc} – 40	_	1.0 t _{cyc} - 25	_	ns	_	
Write strobe pulse width 2	t _{wsw2}	1.5 t _{cyc} – 40	_	1.5 t _{cyc} – 25	_	ns	_	
Address setup time 1	t _{AS1}	0.5 t _{cyc} – 29	_	0.5 t _{cyc} - 20	_	ns	_	
Address setup time 2	t _{AS2}	1.0 t _{cyc} - 35	_	1.0 t _{cyc} - 20	_	ns	_	
Read data setup time	t _{RDS}	40	_	25	_	ns		
Read data hold time	t _{RDH}	0	_	0	_	ns		
Write data delay time	\mathbf{t}_{WDD}	_	50	_	35	ns		
Write data setup time 1	t _{wDS1}	1.0 t _{cyc} - 40	_	1.0 t _{cyc} - 30	_	ns	_	
Write data setup time 2	t _{wds2}	2.0 t _{cyc} - 40	_	2.0 t _{cyc} - 30		ns	_	
Write data hold time	t _{wdh}	0.5 t _{cyc} - 25	_	0.5 t _{cyc} - 15	_	ns		

			Cond					
			A		В	_	Test	
Item	Symbol	Min	Max	Min	Max	Unit	Conditions	
Read data access time 1	t _{ACC1}	_	2.0 t _{cyc} - 80	_	2.0 t _{cyc} - 45	ns	Figure 21.11, figure 21.12,	
Read data access time 2	t _{ACC2}	_	3.0 t _{cyc} - 80	_	3.0 t _{cyc} - 45	ns	figure 21.14, figure 21.15,	
Read data access time 3	t _{ACC3}	_	1.5 t _{cyc} - 80	_	1.5 t _{cyc} - 45	ns	figure 21.17	
Read data access time 4	t _{ACC4}	_	2.5 t _{cyc} - 80	_	2.5 t _{cyc} - 45	ns	_	
Precharge time 1	t _{PCH1}	1.0 t _{cyc} - 30	_	1.0 t _{cyc} - 20	_	ns	_	
Precharge time 2	t _{PCH2}	0.5 t _{cyc} - 30	_	0.5 t _{cyc} - 20	_	ns		
Wait setup time	t _{wts}	40	_	25	_	ns	Figure 21.13	
Wait hold time	t _{wth}	5	_	5	_	ns	<u> </u>	
Bus request setup time	t _{BRQS}	40	_	25	_	ns	Figure 21.16	
Bus acknowledge delay time 1	t _{BACD1}	_	50	_	30	ns	_	
Bus acknowledge delay time 2	t _{BACD2}	_	50	_	30	ns	_	
Bus-floating time	$t_{_{BZD}}$	—	50	_	30	ns		
RAS precharge time	\mathbf{t}_{RP}	1.5 t _{cyc} - 40	_	1.5 t _{cyc} - 25	_	ns	Figure 21.17 to	
CAS precharge time	t _{CP}	0.5 t _{cyc} - 25	_	0.5 t _{cyc} - 15	_	ns	figure 21.19	
Low address hold time	t _{rah}	0.5 t _{cyc} - 25	_	0.5 t _{cyc} – 15	_	ns	_	
RAS delay time 1	t _{RAD1}	_	50	_	25	ns		
RAS delay time 2	t_{RAD2}	_	50	_	30	ns		
CAS delay time 1	t _{CASD1}	_	50	_	25	ns		
CAS delay time 2	t _{CASD2}	_	50	_	25	ns		
WE delay time	t _{wcd}	_	50	_	25	ns	_	
CAS pulse width 1	t _{CAS1}	1.5 t _{cyc} - 40	_	1.5 t _{cyc} - 20	_	ns		
CAS pulse width 2	t _{CAS2}	1.0 t _{cyc} – 40	_	1.0 t _{cyc} – 20	_	ns		
CAS pulse width 3	t _{CAS3}	1.0 t _{cyc} - 40	_	1.0 t _{cyc} – 20	_	ns	_	

Condition

		-	Α		В	_	Test
Item	Symbol	Min	Max	Min	Max	Unit	Conditions
RAS access time	t _{RAC}	_	2.5 t _{cyc} - 70	_	2.5 t _{cyc} - 40	ns	Figure 21.17 to
Address access time	t _{AA}	_	2.0 t _{cyc} - 80	_	2.0 t _{cyc} - 50	ns	⁻ figure 21.19
CAS access time	t _{CAC}	_	1.5 t _{cyc} - 80	_	1.5 t _{cyc} - 50	ns	
WE setup time	t _{wcs}	0.5 t _{cyc} - 35	_	0.5 t _{cyc} – 20	_	ns	_
WE hold time	t _{wch}	0.5 t _{cyc} – 28	_	0.5 t _{cyc} - 15	_	ns	_
Write data setup time	t _{wds}	0.5 t _{cyc} - 35	_	0.5 t _{cyc} – 20	_	ns	_
WE write data hold time	t _{wdh}	0.5 t _{cyc} - 25	_	0.5 t _{cyc} - 15	_	ns	_
CAS setup time 1	t _{CSR1}	0.5 t _{cyc} – 25		0.5 t _{cyc} - 20	_	ns	_
CAS setup time 2	t _{CSR2}	0.5 t _{cyc} – 25		0.5 t _{cyc} - 15	_	ns	_
CAS hold time	t _{CHR}	0.5 t _{cyc} – 25	_	0.5 t _{cyc} - 15	_	ns	_
RAS pulse width	t _{RAS}	1.5 t _{cyc} - 25	_	1.5 t _{cyc} - 15	_	ns	

Table 21.16 Timing of On-Chip Supporting Modules

Condition: $T_a = -20$ °C to +75°C (regular specifications), $T_a = -40$ °C to +85°C (wide-range

specifications)

Condition A: $V_{cc} = 3.0$ to 5.5 V, $AV_{cc} = 3.0$ to 5.5 V, $V_{REF} = 3.0$ to AV_{cc} , $V_{ss} = AV_{ss} = 0$ V,

fmax = 13 MHz

Condition B: $V_{cc} = 5.0 \text{ V} \pm 10\%$, $AV_{cc} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ to } AV_{cc}$, $V_{ss} = AV_{ss} = 0 \text{ V}$,

	1111				Cond	dition				
					Α		В		Test	
Item			Symbol	Min	Max	Min	Max	Unit	Conditions	
Port/	Output data	delay time	t _{PWD}	_	100	_	50	ns	Figure 21.20	
TPC	Input data s	etup time	$\mathbf{t}_{\mathtt{PRS}}$	50	_	50	_	ns		
	Input data h	old time	t _{PRH}	50		50	_	ns		
16-bit	Timer outpu	t delay time	t _{TOCD}	_	100	_	50	ns	Figure 21.21	
timer	Timer input	setup time	t _{rics}	50	_	50	_	ns		
	Timer clock	input setup time	t _{TCKS}	50	_	50	_	ns	Figure 21.22	
	Timer clock	Single edge	t _{TCKWH}	1.5	_	1.5	_	t _{cyc}		
	pulse width	Both edges	t _{TCKWL}	2.5	_	2.5	_	t _{cyc}	_	
8-bit	Timer outpu	t delay time	t _{TOCD}	_	100	_	50	ns	Figure 21.21	
timer	Timer input setup time		t _{TICS}	50	_	50	_	ns	_	
	Timer clock input setup time		t _{TCKS}	50	_	50	_	ns	Figure 21.22	
	Timer clock	Single edge	t _{TCKWH}	1.5	_	1.5	_	t _{cyc}	_	
	pulse width	Both edges	t _{TCKWLL}	2.5	_	2.5	_	t _{cyc}		
SCI	Input clock	Asynchronous	t _{Scyc}	4	_	4	_	t _{cyc}	Figure 21.23	
	cycle	Synchronous	=	6	_	6	_	t _{cyc}		
	Input clock r	ise time	t _{scKr}	1.5	_	1.5	_	t _{cyc}		
	Input clock f	all time	t _{sckf}	1.5	_	1.5	_	t _{cyc}		
	Input clock p	oulse width	t _{sckw}	0.4	0.6	0.4	0.6	t _{scyc}		
	Transmit da	ta delay time	t _{TXD}	_	100	_	100	ns	Figure 21.24	
	Receive dat (synchronou	•	t _{RXS}	100	_	100	_	ns	_	
	Receive	Clock input	t _{RXH}	100	_	100	_	ns		
	data hold time (syn- chronous)	Clock output	_	0	_	0	_	ns	_	

				Condition				
				Α		В		Test
Item		Symbol	Min	Max	Min	Max	Unit	Conditions
DMAC	TEND delay time 1	t _{TED1}	_	100	_	50	ns	Figure 21.25,
	TEND delay time 2	$\mathbf{t}_{\scriptscriptstyleTED2}$	_	100	_	50	ns	figure 21.26
	DREQ setup time	t _{DRQS}	40	_	25	_	ns	Figure 21.27
	DREQ hold time	\mathbf{t}_{DRQH}	10	_	10	_	ns	

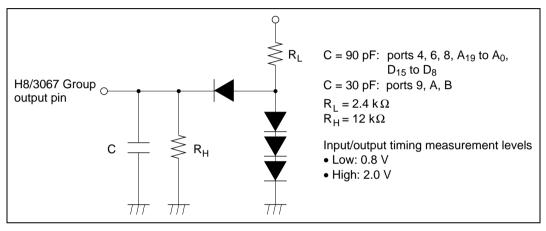


Figure 21.6 Output Load Circuit

21.2.4 A/D Conversion Characteristics

Table 21.17 lists the A/D conversion characteristics.

Table 21.17 A/D Conversion Characteristics

Condition: $T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$ (regular specifications), $T_a = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ (wide-range

specifications)

Condition A: $V_{CC} = 3.0 \text{ to } 5.5 \text{ V}$, $AV_{CC} = 3.0 \text{ to } 5.5 \text{ V}$, $V_{REF} = 3.0 \text{ to } AV_{CC}$, $V_{SS} = AV_{SS} = 0 \text{ V}$, fmax

= 13 MHz

Condition B: $V_{\text{CC}} = 5.0 \text{ V} \pm 10\%$, $AV_{\text{CC}} = 5.0 \text{ V} \pm 10\%$, $V_{\text{REF}} = 4.5 \text{ to } AV_{\text{CC}}$, $V_{\text{SS}} = AV_{\text{SS}} = 0 \text{ V}$,

	Condition								
				Α			В		_
Item			Min	Тур	Max	Min	Тур	Max	Unit
Conversion	Resolution		10	10	10	10	10	10	bits
time: 134 states	Conversion tim	ne (single mode)	_	_	134	_	_	134	t _{cyc}
	Analog input capacitance		_	_	20	_	_	20	pF
	Permissible	φ ≤ 13 MHz	_	_	_	_	_	10	kΩ
	signal-source impedance	φ > 13 MHz		_	_	_	_	5	kΩ
		4.0 V ≤ AV _{cc} ≤ 5.5 V	_	_	10	_	_	_	kΩ
		3.0 V ≤ AV _{cc} < 4.0 V	_	_	5	_	_	_	kΩ
	Nonlinearity error Offset error Full-scale error		_		±7.5	_	_	±3.5	LSB
			_	_	±7.5	_	_	±3.5	LSB
			_	_	±7.5	_	_	±3.5	LSB
	Quantization error		_	_	±0.5	_	_	±0.5	LSB
	Absolute accur	acy	_	_	±8.0	_	_	±4.0	LSB

					Con	dition			
				Α			В		_
Item			Min	Тур	Max	Min	Тур	Max	Unit
Conversion	Resolution		10	10	10	10	10	10	bits
time: 70 states	Conversion tim	ne (single mode)	_	_	70	_	_	70	t _{cyc}
	Analog input ca	apacitance	_	_	20	_	_	20	pF
	Permissible	φ≤13 MHz	_	_	_	_	_	5	kΩ
	signal-source	φ > 13 MHz	_	_	_	_	_	3	kΩ
	impedance	4.0 V ≤ AV _{cc} ≤ 5.5 V	_		5	_	_	_	kΩ
		3.0 V ≤ AV _{cc} < 4.0 V	_		3	_	_	_	kΩ
	Nonlinearity er	ror	_	_	±15.5	_	_	±7.5	LSB
	Offset error		_	_	±15.5	_	_	±7.5	LSB
	Full-scale error	r	_	_	±15.5	_	_	±7.5	LSB
	Quantization e	rror	_	_	±0.5	_	_	±0.5	LSB
	Absolute accur	acy	_	_	±16	_	_	±8.0	LSB

21.2.5 D/A Conversion Characteristics

Table 21.18 lists the D/A conversion characteristics.

Table 21.18 D/A Conversion Characteristics

Condition: $T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$ (regular specifications), $T_a = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ (wide-range

specifications)

Condition A: $V_{CC} = 3.0 \text{ to } 5.5 \text{ V}$, $AV_{CC} = 3.0 \text{ to } 5.5 \text{ V}$, $V_{REF} = 3.0 \text{ to } AV_{CC}$, $V_{SS} = AV_{SS} = 0 \text{ V}$, fmax

= 13 MHz

Condition B: $V_{\text{CC}} = 5.0 \text{ V} \pm 10\%$, $AV_{\text{CC}} = 5.0 \text{ V} \pm 10\%$, $V_{\text{REF}} = 4.5$ to AV_{CC} , $V_{\text{SS}} = AV_{\text{SS}} = 0$ V,

fmax = 20 MHz

			Cor	dition				
		Α			В		-	
Item	Min	Тур	Max	Min	Тур	Max	Unit	Test Conditions
Resolution	8	8	8	8	8	8	bits	
Conversion time (centering time)	ıg—	_	10	_	_	10	μs	20 pF capacitive load
Absolute accuracy	_	±2.0	±3.0	_	±1.5	±2.0	LSB	$2 \text{ M}\Omega$ resistive load
	_	_	±2.0	_	_	±1.5	LSB	4 M Ω resistive load



21.2.6 Flash Memory Characteristics

Table 21.19 shows the flash memory characteristics.

Table 21.19 Flash Memory Characteristics (1)

Conditions: $V_{cc}=4.5$ to 5.5V, $AV_{cc}=4.5$ to 5.5V, $V_{ss}=AV_{ss}=0$ V

T_a=0 to +75°C (Programming/erasing operating temperature range: regular

specification)

T₀=0 to +85°C (Programming/erasing operating temperature range: wide-range

specification)

Item		Symbol	Min	Тур	Max	Unit	Test Condition
Programming ti	me ^{*1 *2 *4}	t _p	_	10	200	ms/32 bytes	
Erase time*1 *3 *	⁴ 5	t _E	_	100	1200	ms/block	
Reprogramming	g count	N _{wec}	_	_	100	Times	
Programming	Wait time after SWE bit setting*1	Х	10	_	_	μs	
	Wait time after PSU bit setting*1	у	50	_	_	μs	
	Wait time after P bit setting*1 *4	Z	150	_	500	μs	
	Wait time after P bit clear*1	α	10	_	_	μs	
	Wait time after PSU bit clear*1	β	10	_	_	μs	
	Wait time after PV bit setting*1	γ	4	_	_	μs	
	Wait time after H'FF dummy write*1	ε	2	_	_	μs	
	Wait time after PV bit clear*1	η	4	_	_	μs	
	Maximum programming count*1 *4	N	_	_	403	Times	
Erase	Wait time after SWE bit setting*1	Х	10	_	_	μs	
	Wait time after ESU bit setting*1	у	200	_	_	μs	
	Wait time after E bit setting*1 *5	Z	5	_	10	ms	
	Wait time after E bit clear*1	α	10	_	_	μs	
	Wait time after ESU bit clear*1	β	10	_	_	μs	
	Wait time after EV bit setting*1	γ	20	_	_	μs	
	Wait time after H'FF dummy write*1	ε	2	_	_	μs	
	Wait time after EV bit clear*1	η	5	_	_	μs	
	Maximum erase count*1 *5	N	120	_	240	Times	

Notes:

- 1. Make each time setting in accordance with the program/program-verify flowchart or erase/erase-verify flowchart.
- 2. Programming time per 32 bytes (Shows the total period for which the P-bit in the flash memory control register (FLMCR) is set. It does not include the programming verification time.)
- Block erase time (Shows the total period for which the E-bit in FLMCR is set. It does not include the erase verification time.)
- 4. To specify the maximum programming time (t_p(max)) in the 32-byte programming flowchart, set the maximum value (403) for the maximum programming count (N).

The wait time after P bit setting (z) should be changed as follows according to the programming counter value. Programming counter value of 1 to 4: $z = 150 \mu s$

Programming counter value of 5 to 403 : $z = 500 \mu s$

 For the maximum erase time (t_E(max)), the following relationship applies between the wait time after E bit setting (z) and the maximum erase count (N):

 $t_{\epsilon}(max)$ = Wait time after E bit setting (z) x maximum erase count (N)

To set the maximum erase time, the values of z and N should be set so as to satisfy the above formula.

Examples: When z = 5 [ms], N = 240 times

When z = 10 [ms], N = 120 times

Table 21.19 Flash Memory Characteristics (2)

Conditions: $V_{cc} = 3.0 \text{ to } 3.6 \text{ V}, AV_{cc} = 3.0 \text{ to } 3.6 \text{ V}, V_{ss} = AV_{ss} = 0 \text{ V}$

T₂=0 to +75°C (Programming/erasing operating temperature range: regular

specification)

T₂=0 to +85°C (Programming/erasing operating temperature range: wide-range

specification)

Item		Symbol	Min	Тур	Max	Unit	Test Condition
Programming ti	me ^{*1 *2 *4}	t _P	_	10	200	ms/32 bytes	
Erase time*1 *3 *	:5	t _e	_	100	1200	ms/block	
Reprogramming	count	$N_{\scriptscriptstyle WEC}$	_	_	100	Times	
Programming	Wait time after SWE bit setting*1	х	10	_	_	μs	
	Wait time after PSU bit setting*1	у	50	_	_	μs	
	Wait time after P bit setting*1 *4	Z	150	_	500	μs	
	Wait time after P bit clear*1	α	10	_	_	μs	
	Wait time after PSU bit clear*1	β	10	_	_	μs	
	Wait time after PV bit setting*1	γ	4	_	_	μs	
	Wait time after H'FF dummy write*1	ε	2	_	_	μs	
	Wait time after PV bit clear*1	η	4	_	_	μs	
	Maximum programming count*1 *4	N	_	_	403	Times	
Erase	Wait time after SWE bit setting*1	х	10	_	_	μs	
	Wait time after ESU bit setting*1	у	200	_	_	μs	
	Wait time after E bit setting*1 *5	Z	5	_	10	ms	
	Wait time after E bit clear*1	α	10	_	_	μs	
	Wait time after ESU bit clear*1	β	10	_	_	μs	
	Wait time after EV bit setting*1	γ	20	_	_	μs	
	Wait time after H'FF dummy write*1	ε	2	_	_	μs	
	Wait time after EV bit clear*1	η	5	_	_	μs	
	Maximum erase count*1 *5	N	120	_	240	Times	

Notes:

- Make each time setting in accordance with the program/program-verify flowchart or erase/erase-verify flowchart.
- Programming time per 32 bytes (Shows the total period for which the P-bit in the flash memory control register (FLMCR) is set. It does not include the programming verification time.)
- Block erase time (Shows the total period for which the E-bit in FLMCR is set. It does not include the erase verification time.)
- 4. To specify the maximum programming time (t_a(max)) in the 32-byte programming flowchart, set the max. value (403) for the maximum programming count (N).

The wait time after P bit setting (z) should be changed as follows according to the programming counter value.

Programming counter value of 1 to 4: $z = 150 \mu s$ Programming counter value of 5 to 403: $z = 500 \mu s$

5. For the maximum erase time (t_(max)), the following relationship applies between the wait time after E bit setting (z) and the maximum erase count (N):

 $t_{\rm c}({\rm max}) = {\rm Wait\ time\ after\ E\ bit\ setting\ (z)} \times {\rm maximum\ erase\ count\ (N)}$

To set the maximum erase time, the values of z and N should be set so as to satisfy the above formula.

Examples: When z = 5 [ms]. N = 240 times When z = 10 [ms], N = 120 times

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21.3 Operational Timing

This section shows timing diagrams.

21.3.1 Clock Timing

Clock timing is shown as follows:

• Oscillator settling timing
Figure 21.7 shows the oscillator settling timing.

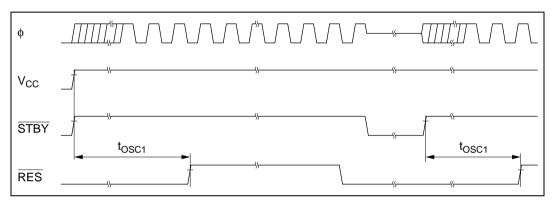


Figure 21.7 Oscillator Settling Timing

21.3.2 Control Signal Timing

Control signal timing is shown as follows:

- Reset input timing
 Figure 21.8 shows the reset input timing.
- Reset output timing*
 Figure 21.9 shows the reset output timing.
- Interrupt input timing Figure 21.10 shows the interrupt input timing for NMI and $\overline{IRQ}_{_{0}}$ to $\overline{IRQ}_{_{0}}$.

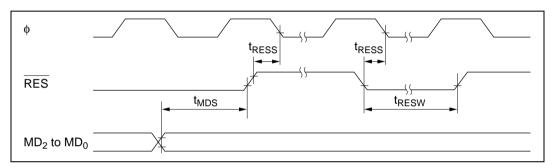


Figure 21.8 Reset Input Timing

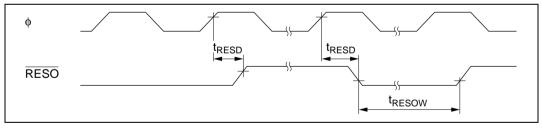


Figure 21.9 Reset Output Timing*

Note: * This function is used only in the mask ROM version, and is not provided in the flash memory and flash memory R versions.

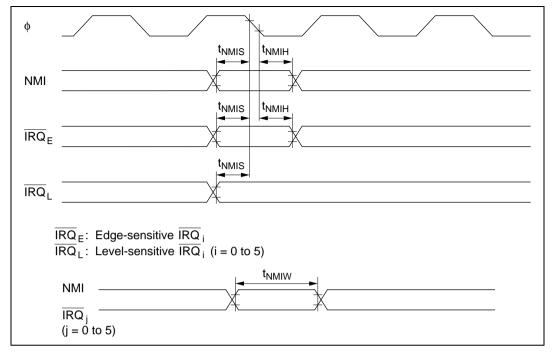


Figure 21.10 Interrupt Input Timing

21.3.3 Bus Timing

Bus timing is shown as follows:

- Basic bus cycle: two-state access
 Figure 21.11 shows the timing of the external two-state access cycle.
- Basic bus cycle: three-state access
 Figure 21.12 shows the timing of the external three-state access cycle.
- Basic bus cycle: three-state access with one wait state
 Figure 21.13 shows the timing of the external three-state access cycle with one wait state inserted.
- Burst ROM access timing: burst cycle two-state Figure 21.14 shows the timing of the burst cycle two-state access.
- Burst ROM access timing: burst cycle three-state
 Figure 21.15 shows the timing of the burst cycle three-state access.
- Bus-release mode timing
 Figure 21.16 shows the bus-release mode timing.

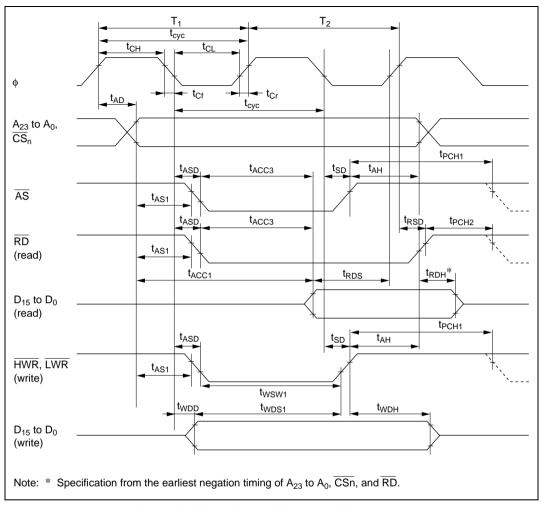


Figure 21.11 Basic Bus Cycle: Two-State Access

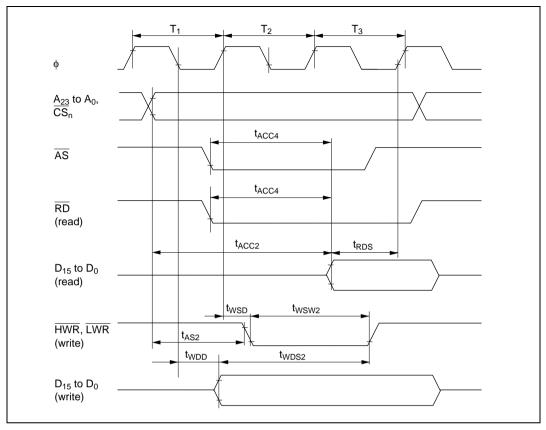


Figure 21.12 Basic Bus Cycle: Three-State Access

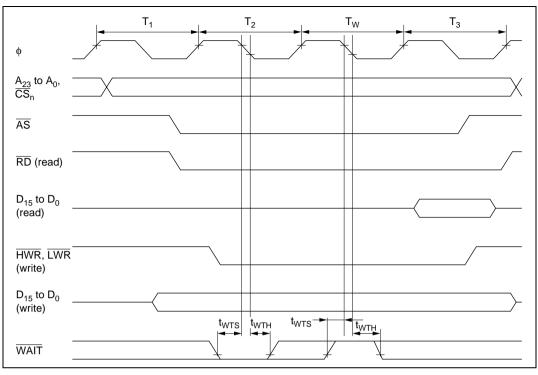


Figure 21.13 Basic Bus Cycle: Three-State Access with One Wait State

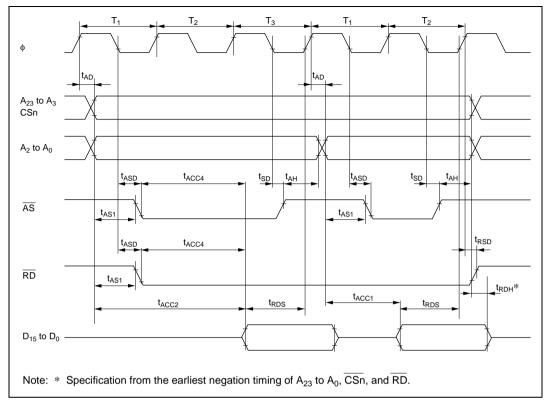


Figure 21.14 Burst ROM Access Timing: Two-State Access

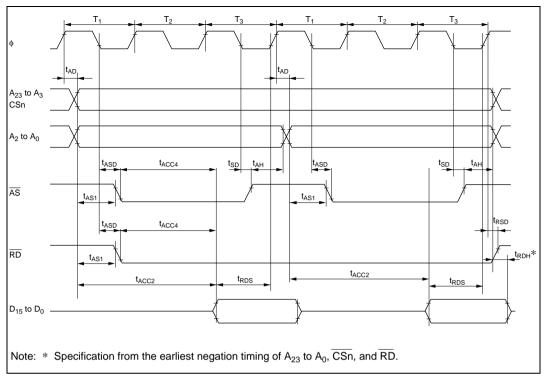


Figure 21.15 Burst ROM Access Timing: Three-State Access

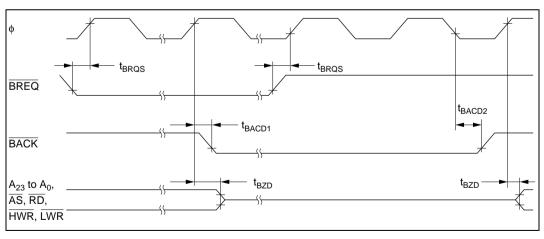


Figure 21.16 Bus-Release Mode Timing

21.3.4 DRAM Interface Bus Timing

DRAM interface bus timing is shown as follows:

- DRAM bus timing: read and write access
 Figure 21.17 shows the timing of the read and write access.
- DRAM bus timing: CAS before RAS refresh Figure 21.18 shows the timing of the CAS before RAS refresh.
- DRAM bus timing: self-refresh Figure 21.19 shows the timing of the self-refresh.

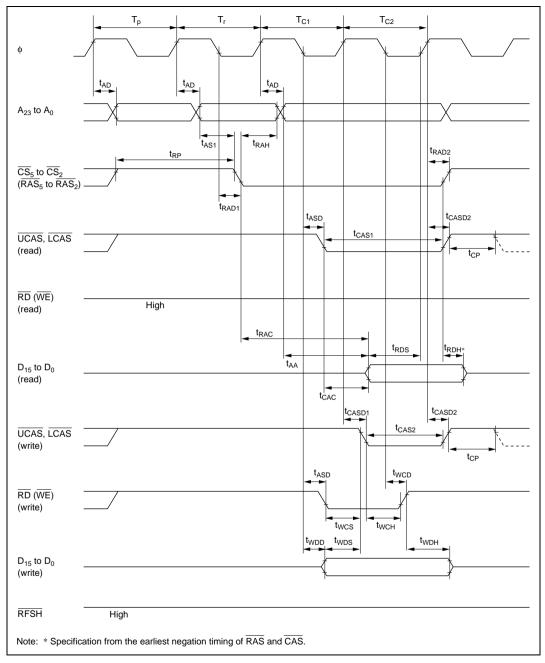


Figure 21.17 DRAM Bus Timing (Read/Write)

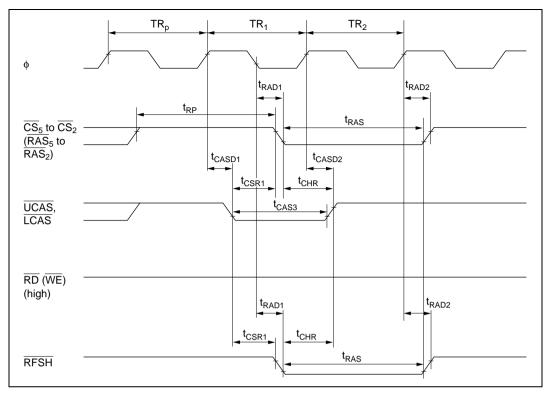


Figure 21.18 DRAM Bus Timing (CAS Before RAS Refresh)

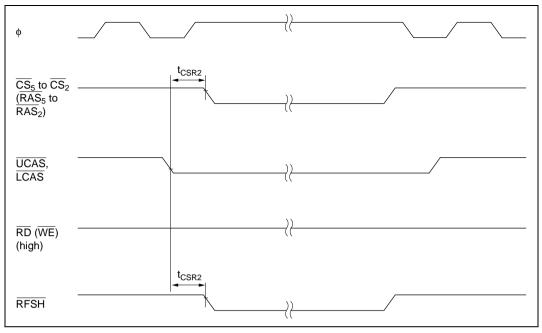


Figure 21.19 DRAM Bus Timing (Self-Refresh)

21.3.5 TPC and I/O Port Timing

Figure 21.20 shows the TPC and I/O port input/output timing.

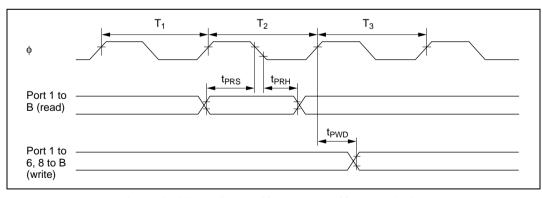


Figure 21.20 TPC and I/O Port Input/Output Timing

21.3.6 Timer Input/Output Timing

16-bit timer and 8-bit timer timing is shown as follows:

- Timer input/output timing
 Figure 21.21 shows the timer input/output timing.
- Timer external clock input timing
 Figure 21.22 shows the timer external clock input timing.

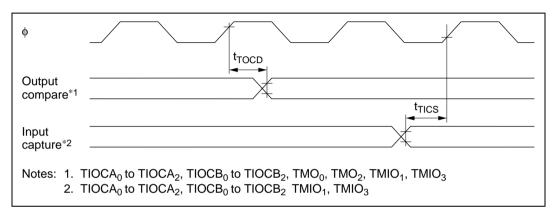


Figure 21.21 Timer Input/Output Timing

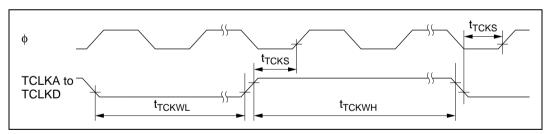


Figure 21.22 Timer External Clock Input Timing

21.3.7 SCI Input/Output Timing

SCI timing is shown as follows:

- SCI input clock timing Figure 21.23 shows the SCI input clock timing.
- SCI input/output timing (synchronous mode)
 Figure 21.24 shows the SCI input/output timing in synchronous mode.

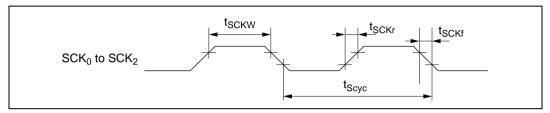


Figure 21.23 SCI Input Clock Timing

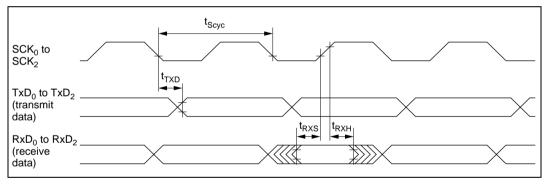


Figure 21.24 SCI Input/Output Timing in Synchronous Mode

21.3.8 DMAC Timing

DMAC timing is shown as follows.

- DMAC TEND output timing for 2 state access Figure 21.25 shows the DMAC TEND output timing for 2 state access.
- DMAC TEND output timing for 3 state access Figure 21.26 shows the DMAC TEND output timing for 3 state access.
- DMAC DREQ input timing
 Figure 21.27 shows DMAC DREQ input timing.

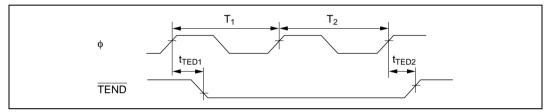


Figure 21.25 DMAC TEND Output Timing for 2 State Access

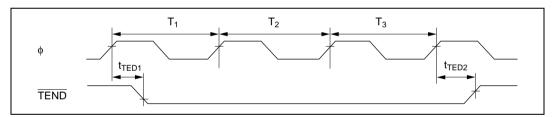


Figure 21.26 DMAC $\overline{\text{TEND}}$ Output Timing for 3 State Access

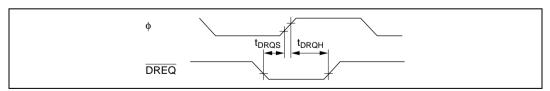


Figure 21.27 DMAC DREQ Input Timing

Appendix A Instruction Set

A.1 Instruction List

Operand Notation

Symbol	Description
Rd	General destination register
Rs	General source register
Rn	General register
ERd	General destination register (address register or 32-bit register)
ERs	General source register (address register or 32-bit register)
ERn	General register (32-bit register)
(EAd)	Destination operand
(EAs)	Source operand
PC	Program counter
SP	Stack pointer
CCR	Condition code register
N	N (negative) flag in CCR
Z	Z (zero) flag in CCR
V	V (overflow) flag in CCR
С	C (carry) flag in CCR
disp	Displacement
\rightarrow	Transfer from the operand on the left to the operand on the right, or transition from the state on the left to the state on the right
+	Addition of the operands on both sides
_	Subtraction of the operand on the right from the operand on the left
×	Multiplication of the operands on both sides
÷	Division of the operand on the left by the operand on the right
٨	Logical AND of the operands on both sides
V	Logical OR of the operands on both sides
\oplus	Exclusive logical OR of the operands on both sides
7	NOT (logical complement)
(), <>	Contents of operand

Note: General registers include 8-bit registers (R0H to R7H and R0L to R7L) and 16-bit registers (R0 to R7 and E0 to E7).

Condition Code Notation

Symbol	Description
_	Changed according to execution result
*	Undetermined (no guaranteed value)
0	Cleared to 0
1	Set to 1
_	Not affected by execution of the instruction
Δ	Varies depending on conditions, described in notes

Table A.1 Instruction Set

1. Data transfer instructions

						_	Mod)								No.	
	Operand Size	xx#	Rn	@ERn	@(d, ERn)	@-ERn/@ERn+	@aa	@(d, PC)	@ @ aa						on C		1	Normal	Advanced
Mnemonic MOV.B #xx:8, Rd	В	#	PE	0	•	9	•		•		Operation #xx:8 → Rd8	ı	Н	N	Z	0	С	2	
MOV.B Rs, Rd	В		2								Rs8 → Rd8			1	1	0		2	
MOV.B @ERs, Rd	В		_	2							@ERs → Rd8			↓	Ť	0		4	
MOV.B @(d:16, ERs), Rd	В			2	4						@(d:16, ERs) → Rd8	_	_	1	\$	0	_	6	
MOV.B @(d:24, ERs), Rd	В				8						@(d:24, ERs) → Rd8	_	_	\$	\$	0	_	1	0
MOV.B @ERs+, Rd	В					2					@ERs → Rd8 ERs32+1 → ERs32	_	_	\$	\$	0	_	6	;
MOV.B @aa:8, Rd	В						2				@aa:8 → Rd8	_	_	1	1	0	—	4	ļ.
MOV.B @aa:16, Rd	В						4				@aa:16 → Rd8	_	_	1	1	0	_	6	3
MOV.B @aa:24, Rd	В						6				@aa:24 → Rd8	-	_	1	1	0	_	8	3
MOV.B Rs, @ERd	В			2							Rs8 → @ERd	_	_	1	1	0	_	4	ļ
MOV.B Rs, @(d:16, ERd)	В				4						Rs8 → @(d:16, ERd)	_		\$	\$	0	_	6	
MOV.B Rs, @(d:24, ERd)	В				8						Rs8 → @(d:24, ERd)	_	_	\$	\$	0	_	1	0
MOV.B Rs, @ĐERd	В					2					ERd32Ð1 → ERd32 Rs8 → @ERd	_	_	\$	\$	0	_	6	;
MOV.B Rs, @aa:8	В						2				Rs8 → @aa:8	_	_	1	1	0	_	4	ŀ
MOV.B Rs, @aa:16	В						4				Rs8 → @aa:16	_	_	1	1	0	_	6	;
MOV.B Rs, @aa:24	В						6				Rs8 → @aa:24	_	_	1	1	0	_	8	}
MOV.W #xx:16, Rd	W	4									#xx:16 → Rd16	-	_	\$	1	0	_	4	ļ
MOV.W Rs, Rd	W		2								Rs16 → Rd16	_	_	1	1	0	_	2	2
MOV.W @ERs, Rd	W			2							@ERs → Rd16	_	_	1	1	0	_	4	ļ
MOV.W @(d:16, ERs), Rd	W				4						@(d:16, ERs) → Rd16		_	\$	\$	0	_	6	;
MOV.W @(d:24, ERs), Rd	W				8						@(d:24, ERs) → Rd16			\$	\$	0	_	1	0
MOV.W @ERs+, Rd	W					2					@ERs → Rd16 ERs32+2 → @ERd32		_	\$	\$	0	_	6	;
MOV.W @aa:16, Rd	W						4				@aa:16 → Rd16		_	1	\$	0	_	6	}

					essi tion	_)								l	. of es* ¹
	Operand Size	×		@ERn	@(d, ERn)	@-ERn/@ERn+	@aa	@(d, PC)	Фаа			(Con	ditio	on C	ode	9	Normal	Advanced
Mnemonic	ŏ	XX#	~	<u>@</u>	0	ø	0	0	(9)	I	Operation	ı	Н	N	z	٧	С	ž	Α̈́
MOV.W @aa:24, Rd	W						6				@aa:24 → Rd16	_	_	\$	1	0	_	8	3
MOV.W Rs, @ERd	W			2							Rs16 → @ERd	_	_	1	1	0	_	4	4
MOV.W Rs, @(d:16, ERd)	W				4						Rs16 → @(d:16, ERd)	_	_	1	1	0		6	3
MOV.W Rs, @(d:24, ERd)	W				8						Rs16 → @(d:24, ERd)	_	_	\$	\$	0		1	0
MOV.W Rs, @-ERd	W					2					ERd32–2 \rightarrow ERd32 Rs16 \rightarrow @ERd	_	_	\$	\$	0		6	3
MOV.W Rs, @aa:16	W						4				Rs16 → @aa:16	_	_	1	1	0	_	6	3
MOV.W Rs, @aa:24	W						6				Rs16 → @aa:24	_	_	1	1	0	_	8	3
MOV.L #xx:32, Rd	L	6									#xx:32 → Rd32	_	_	1	1	0	_	6	6
MOV.L ERs, ERd	L		2								ERs32 → ERd32	_	_	1	1	0	_	2	2
MOV.L @ERs, ERd	L			4							@ERs → ERd32	_	_	1	1	0	_	8	3
MOV.L @(d:16, ERs), ERd	L				6						@(d:16, ERs) → ERd32	_	_	\$	\$	0	_	1	0
MOV.L @(d:24, ERs), ERd	L				10						@(d:24, ERs) → ERd32	_	_	\$	\$	0		1	4
MOV.L @ERs+, ERd	L					4					@ERs → ERd32 ERs32+4 → ERs32	_	_	\$	\$	0		1	0
MOV.L @aa:16, ERd	L						6				@aa:16 → ERd32	_	_	1	1	0	_	1	0
MOV.L @aa:24, ERd	L						8				@aa:24 → ERd32	_	_	1	1	0	_	1	2
MOV.L ERs, @ERd	L			4							ERs32 → @ERd	_	_	1	1	0	_	8	3
MOV.L ERs, @(d:16, ERd)	L				6						ERs32 → @(d:16, ERd)	_	_	\$	\$	0	_	1	0
MOV.L ERs, @(d:24, ERd)	L				10						ERs32 → @(d:24, ERd)	_	_	\$	\$	0		1	4
MOV.L ERs, @-ERd	L					4					ERd32–4 \rightarrow ERd32 ERs32 \rightarrow @ERd	_	_	1	1	0		1	0
MOV.L ERs, @aa:16	L						6				ERs32 → @aa:16	_	_	1	1	0	_	1	0
MOV.L ERs, @aa:24	L						8				ERs32 → @aa:24	<u> </u>	_	1	1	0	_	1	2
POP.W Rn	w									2		_	_	\$	\$	0		6	3
POP.L ERn	L									4		_	_	\$	\$	0	_	1	0



					essi tion	_			nd /tes)									. of es* ¹
	Operand Size			@ERn	@(d, ERn)	@-ERn/@ERn+	2	d, PC)	@aa				Con	ditio	on C	Code	е	Normal	Advanced
Mnemonic	ŏ	XX#	몺	@ E	<u>@</u>	9	@aa	(d,	0	1	Operation	ı	Н	N	z	٧	С	ş	Αġ
PUSH.W Rn	W									2	$\begin{array}{c} SP-2 \to SP \\ Rn16 \to @SP \end{array}$	_	_	\$	\$	0	_	(6
PUSH.L ERn	L									4	$\begin{array}{c} SP4 \to SP \\ ERn32 \to @SP \end{array}$	_	_	\$	\$	0	_	1	0
MOVFPE @aa:16, Rd	В						4				Cannot be used in the H8/3067 Group	Cannot be used in the H8/3067 Group						•	
MOVTPE Rs, @aa:16	В						4				Cannot be used in the H8/3067 Group	Cannot be used in the H8/3067 Group							

2. Arithmetic instructions

				ddre ruct		•)								No. Stat	-
	Operand Size	×	_	@ERn	@(d, ERn)	@-ERn/@ERn+	@aa	@(d, PC)	@aa				Con	ditio	on C	ode	e	Normal	Advanced
Mnemonic	ō	XX#	몺	0	0	0	@	@	0	I	Operation	ı	Н	N	Z	٧	С	ž	AC
ADD.B #xx:8, Rd	В	2									Rd8+#xx:8 → Rd8	_	\$	\$	1	\$	1	2	2
ADD.B Rs, Rd	В		2								Rd8+Rs8 → Rd8	_	\$	\$	1	1	1	2	2
ADD.W #xx:16, Rd	W	4									Rd16+#xx:16 → Rd16	_	(1)	\$	1	1	1	4	1
ADD.W Rs, Rd	W		2								Rd16+Rs16 → Rd16	_	(1)	1	1	1	1	2	2
ADD.L #xx:32, ERd	L	6									ERd32+#xx:32 → ERd32	_	(2)	\$	\$	\$	\$	6	6
ADD.L ERs, ERd	L		2								ERd32+ERs32 → ERd32	_	(2)	\$	\$	\$	\$	2	2
ADDX.B #xx:8, Rd	В	2									Rd8+#xx:8 +C → Rd8	_	\$	1	(3)	1	1	2	2
ADDX.B Rs, Rd	В		2								Rd8+Rs8 +C → Rd8	_	1	\$	(3)	1	1	2	2
ADDS.L #1, ERd	L		2								ERd32+1 → ERd32	_	_	_	_	_	_	2	2
ADDS.L #2, ERd	L		2								ERd32+2 → ERd32	_	_		_	_	_	2	2
ADDS.L #4, ERd	L		2								ERd32+4 → ERd32	_	_	_	_	_	_	2	2
INC.B Rd	В		2								Rd8+1 → Rd8	_	_	1	1	1	_	2	2
INC.W #1, Rd	W		2								Rd16+1 → Rd16	_	_	1	1	1	_	2	2
INC.W #2, Rd	W		2								Rd16+2 → Rd16	_	_	\$	\$	1	_	2	2

				ddre ruct		_)								No. State	
	Operand Size			@ERn	@(d, ERn)	@-ERn/@ERn+	g	@(d, PC)	@aa				Con	ditio	on C	Code	•	Normal	Advanced
Mnemonic	o	XX#	조	@	<u>@</u>	@	@aa	@	0	1	Operation	ı	Н	N	z	٧	С	2	Ad
INC.L #1, ERd	L		2								ERd32+1 → ERd32	_	_	\$	1	1	_	2	
INC.L #2, ERd	L		2								$ERd32 + 2 \to ERd32$	_	_	\$	1	\$	_	2	
DAA Rd	В		2								Rd8 decimal adjust → Rd8	_	*	\$	\$	*	_	2	
SUB.B Rs, Rd	В		2								Rd8–Rs8 → Rd8	_	1	1	1	\$	\$	2	
SUB.W #xx:16, Rd	W	4									Rd16–#xx:16 → Rd16	_	(1)	\$	1	\$	\$	4	
SUB.W Rs, Rd	W		2								Rd16–Rs16 → Rd16	_	(1)	1	1	1	\$	2	
SUB.L #xx:32, ERd	L	6									ERd32-#xx:32 → ERd32	_	(2)	1	\$	\$	\$	6	
SUB.L ERs, ERd	L		2								ERd32–ERs32 → ERd32	_	(2)	\$	\$	\$	\$	2	
SUBX.B #xx:8, Rd	В	2									Rd8–#xx:8ĐC → Rd8	_	1	1	(3)	1	1	2	
SUBX.B Rs, Rd	В		2								Rd8–Rs8ĐC → Rd8	_	1	1	(3)	1	\$	2	
SUBS.L #1, ERd	L		2								ERd32−1 → ERd32	_	_	_	_	_	_	2	
SUBS.L #2, ERd	L		2								ERd32−2 → ERd32	_	_	_	_	_	_	2	
SUBS.L #4, ERd	L		2								ERd32–4 → ERd32	_	_	_	_	_	_	2	
DEC.B Rd	В		2								Rd8−1 → Rd8	_	_	\$	1	1	_	2	
DEC.W #1, Rd	W		2								Rd16–1 → Rd16	_	_	1	1	1	_	2	
DEC.W #2, Rd	W		2								Rd16–2 → Rd16	_	_	1	1	1	_	2	
DEC.L #1, ERd	L		2								ERd32−1 → ERd32	_	_	\$	1	1	_	2	
DEC.L #2, ERd	L		2								ERd32−2 → ERd32	_	_	\$	1	1	_	2	
DAS.Rd	В		2								Rd8 decimal adjust → Rd8	_	*	1	1	*		2	
MULXU. B Rs, Rd	В		2								$ \begin{array}{l} \text{Rd8} \times \text{Rs8} \rightarrow \text{Rd16} \\ \text{(unsigned multiplication)} \end{array} $	_	_		_	_		14	ļ
MULXU. W Rs, ERd	W		2								$ \begin{array}{c} \text{Rd16} \times \text{Rs16} \rightarrow \text{ERd32} \\ \text{(unsigned multiplication)} \end{array} $						_	22	2
MULXS. B Rs, Rd	В		4								Rd8 × Rs8 → Rd16 (signed multiplication)			1	\$			16	- -
MULXS. W Rs, ERd	W		4								Rd16 × Rs16 → ERd32 (signed multiplication)			1	\$			24	ļ
DIVXU. B Rs, Rd	В		2								Rd16 ÷ Rs8 → Rd16 (RdH: remainder, RdL: quotient) (unsigned division)			(6)	(7)			14	1



				ddre		_)								No. Stat	. of es* ¹
Mnemonic	Operand Size	#xx	Rn	@ERn	@(d, ERn)	@-ERn/@ERn+	@aa	@(d, PC)	@ @ aa	I	Operation	1	Con	ditio	on C	Sode V	C	Normal	Advanced
DIVXU. W Rs, ERd	W		2								ERd32 ÷ Rs16 → ERd32 (Ed: remainder, Rd: quotient) (unsigned division)			(6)	(7)			2	2
DIVXS. B Rs, Rd	В		4								Rd16 ÷ Rs8 → Rd16 (RdH: remainder, RdL: quotient) (signed division)			(8)	(7)			1	6
DIVXS. W Rs, ERd	w		4								ERd32 ÷ Rs16 → ERd32 (Ed: remainder, Rd: quotient) (signed division)			(8)	(7)			2	4
CMP.B #xx:8, Rd	В	2									Rd8-#xx:8	_	1	1	1	1	1	2	2
CMP.B Rs, Rd	В		2								Rd8-Rs8	_	1	1	1	1	1	2	2
CMP.W #xx:16, Rd	W	4									Rd16-#xx:16	_	(1)	1	1	1	1	4	1
CMP.W Rs, Rd	W		2								Rd16-Rs16	_	(1)	1	1	1	1	2	2
CMP.L #xx:32, ERd	L	6									ERd32-#xx:32	_	(2)	1	1	\$	1	6	3
CMP.L ERs, ERd	L		2								ERd32-ERs32	_	(2)	1	1	1	1	2	2
NEG.B Rd	В		2								0–Rd8 → Rd8	_	1	1	1	\$	1	2	2
NEG.W Rd	W		2								0–Rd16 → Rd16	_	1	1	1	1	1	2	2
NEG.L ERd	L		2								0–ERd32 → ERd32	_	1	1	1	1	1	2	2
EXTU.W Rd	w		2								$0 \rightarrow$ (<bits 15="" 8="" to=""> of Rd16)</bits>	_	_	0	1	0	_	2	2
EXTU.L ERd	L		2								0 → (<bits 16="" 31="" to=""> of ERd32)</bits>	_		0	1	0		2	2
EXTS.W Rd	W		2								(<bit 7=""> of Rd16) → (<bits 15="" 8="" to=""> of Rd16)</bits></bit>	_	_	\$	1	0	_	2	2
EXTS.L ERd	L		2								(<bit 15=""> of ERd32) → (<bits 16="" 31="" to=""> of ERd32)</bits></bit>	_		1	1	0		2	2

3. Logic instructions

			A Inst		essi	•)								No.	٠
	Operand Size			@ERn	@(d, ERn)	@-ERn/@ERn+	Фаа	@(d, PC)	@aa				Con	ditio	on C	ode	е	Normal	Advanced
Mnemonic	ŏ	XX#	~	<u>@</u>	ø	9	Ö	<u>@</u>	0	ı	Operation	ı	Н	N	z	٧	С	ž	Ą
AND.B #xx:8, Rd	В	2									Rd8∧#xx:8 → Rd8	_	_	1	1	0	_	2	!
AND.B Rs, Rd	В		2								Rd8∧Rs8 → Rd8	_	_	\$	1	0	_	2	!
AND.W #xx:16, Rd	W	4									Rd16∧#xx:16 → Rd16	_	_	\(\)	1	0	_	4	
AND.W Rs, Rd	W		2								Rd16∧Rs16 → Rd16	_	_	1	1	0	_	2	!
AND.L #xx:32, ERd	L	6									ERd32∧#xx:32 → ERd32	_	_	1	1	0	_	6	;
AND.L ERs, ERd	L		4								ERd32∧ERs32 → ERd32	_	_	1	\$	0	_	4	
OR.B #xx:8, Rd	В	2									Rd8∨#xx:8 → Rd8	_	_	1	1	0	_	2	:
OR.B Rs, Rd	В		2								Rd8∨Rs8 → Rd8	_	_	1	1	0	_	2	:
OR.W #xx:16, Rd	W	4									Rd16∨#xx:16 → Rd16	_	_	1	1	0	_	4	
OR.W Rs, Rd	W		2								Rd16∨Rs16 → Rd16	_	_	1	\$	0	_	2	:
OR.L #xx:32, ERd	L	6									ERd32∨#xx:32 → ERd32	_	_	1	1	0	_	6	i
OR.L ERs, ERd	L		4								ERd32√ERs32 → ERd32	_	_	1	1	0	_	4	
XOR.B #xx:8, Rd	В	2									Rd8⊕#xx:8 → Rd8	_	_	1	1	0	_	2	!
XOR.B Rs, Rd	В		2								Rd8⊕Rs8 → Rd8	_	_	1	1	0	_	2	:
XOR.W #xx:16, Rd	W	4									Rd16⊕#xx:16 → Rd16	_	_	1	1	0	_	4	
XOR.W Rs, Rd	W		2								Rd16⊕Rs16 → Rd16	_	_	1	\$	0	_	2	:
XOR.L #xx:32, ERd	L	6									ERd32⊕#xx:32 → ERd32	_	_	1	1	0	_	6	;
XOR.L ERs, ERd	L		4								ERd32⊕ERs32 → ERd32	_	_	1	1	0	_	4	
NOT.B Rd	В		2								$\neg Rd8 \rightarrow Rd8$	_	_	1	1	0	_	2	:
NOT.W Rd	W		2								¬Rd16 → Rd16	_	_	1	1	0	_	2	!
NOT.L ERd	L		2								$\neg Rd32 \rightarrow Rd32$	_	_	_	1	0	_	2	:



4. Shift instructions

					essi tion	_				.								No. of States*1
	Operand Size			@ERn	@(d, ERn)	@-ERn/@ERn+	@aa	@(d, PC)	@aa			(Con	ditio	on C	Code	9	Normal Advanced
Mnemonic	ŏ	xx#	R	<u>a</u>	<u>@</u>	<u>@</u>	9	ø	(9)	ı	Operation	ı	Н	N	z	٧	С	å å
SHAL.B Rd	В		2									_	_	1	\$	1	\$	2
SHAL.W Rd	W		2								-0		_	1	\$	1	\$	2
SHAL.L ERd	L		2								MSB LSB	_	_	\$	\$	1	\$	2
SHAR.B Rd	В		2									_	_	1	\$	0	\$	2
SHAR.W Rd	W		2									_	_	\$	\$	0	\$	2
SHAR.L ERd	L		2								MSB LSB	_	_	\$	1	0	1	2
SHLL.B Rd	В		2									_	_	\$	1	0	1	2
SHLL.W Rd	W		2								-0	_	_	1	\$	0	\$	2
SHLL.L ERd	L		2								MSB LSB	_	_	\$	1	0	1	2
SHLR.B Rd	В		2									_	_	1	\$	0	\$	2
SHLR.W Rd	W		2								0-	_	_	1	\$	0	1	2
SHLR.L ERd	L		2								MSB LSB	_	_	1	\$	0	1	2
ROTXL.B Rd	В		2									_	_	1	1	0	1	2
ROTXL.W Rd	W		2									_	_	1	1	0	1	2
ROTXL.L ERd	L		2								MSB ← LSB	_	_	1	\$	0	1	2
ROTXR.B Rd	В		2									_	_	1	\$	0	1	2
ROTXR.W Rd	w		2								 - - - - - - - - - - - - - - - - - -	_	_	1	1	0	1	2
ROTXR.L ERd	L		2								MSB → LSB	_	_	1	\$	0	1	2
ROTL.B Rd	В		2									_		1	1	0	1	2
ROTL.W Rd	w		2										_	1	1	0	1	2
ROTL.L ERd	L		2								MSB ← LSB		_	1	1	0	1	2
ROTR.B Rd	В		2									_	_	1	1	0	1	2
ROTR.W Rd	w		2								 - - - 		_	1	1	0	1	2
ROTR.L ERd	L		2								MSB → LSB		_	1	1	0	1	2

5. Bit manipulation instructions

						ng I)								No. Stat	
Mnemonic	Operand Size	*xx	Rn	@ERn	@(d, ERn)	@-ERn/@ERn+	@aa	@(d, PC)	@ @aa		Operation	,	Con	ditio	on C	Sode V	е	Normal	Advanced
BSET #xx:3, Rd	В	##	2							<u>'</u>	(#xx:3 of Rd8) ← 1	'	П	IN		V	C	2	
BSET #xx:3, @ERd	В		_	4							(#xx:3 of @ERd) ← 1							8	
BSET #xx:3, @aa:8	В			7			4				(#xx:3 of @aa:8) ← 1							8	
BSET Rn, Rd	В		2				_				(Rn8 of Rd8) ← 1							2	
BSET Rn, @ERd	В		_	4							(Rn8 of @ERd) ← 1							8	
BSET Rn, @aa:8	В			Ė			4				(Rn8 of @aa:8) ← 1								
BCLR #xx:3, Rd	В		2				_				(#xx:3 of Rd8) ← 0							2	
BCLR #xx:3, @ERd	В		-	4							(#xx:3 of @ERd) ← 0							- 8	
BCLR #xx:3, @aa:8	В			·			4				(#xx:3 of @aa:8) ← 0							8	
BCLR Rn, Rd	В		2								(Rn8 of Rd8) ← 0							2	
BCLR Rn, @ERd	В		-	4							(Rn8 of @ERd) ← 0							8	
BCLR Rn, @aa:8	В						4				(Rn8 of @aa:8) ← 0							8	
BNOT #xx:3, Rd	В		2								(#xx:3 of Rd8) ← ¬ (#xx:3 of Rd8)	_	_	_	_	_	_	2	2
BNOT #xx:3, @ERd	В			4							(#xx:3 of @ERd) ← ¬ (#xx:3 of @ERd)	_	_	_	_	_	_	8	3
BNOT #xx:3, @aa:8	В						4				(#xx:3 of @aa:8) ← ¬ (#xx:3 of @aa:8)	_	_	_	_	_	_	8	3
BNOT Rn, Rd	В		2								(Rn8 of Rd8) ← ¬ (Rn8 of Rd8)	_	_	_	_	_	_	2	2
BNOT Rn, @ERd	В			4							(Rn8 of @ERd) ← ¬ (Rn8 of @ERd)	_	_	_	_	_	_	8	3
BNOT Rn, @aa:8	В						4				(Rn8 of @aa:8) ← ¬ (Rn8 of @aa:8)	_	_	—	_	_	_	8	3
BTST #xx:3, Rd	В		2								¬ (#xx:3 of Rd8) → Z	_	_	_	1	_	_	2	2
BTST #xx:3, @ERd	В			4							¬ (#xx:3 of @ERd) → Z	_	_	_	1	_	_	6	6
BTST #xx:3, @aa:8	В						4				¬ (#xx:3 of @aa:8) → Z	_	_	_	1	_	_	6	3
BTST Rn, Rd	В		2								¬ (Rn8 of @Rd8) \rightarrow Z	_	_	_	1	_	_	2	2
BTST Rn, @ERd	В			4							¬ (Rn8 of @ERd) \rightarrow Z	_	_	_	1	_	_	6	3
BTST Rn, @aa:8	В						4				¬ (Rn8 of @aa:8) → Z	_	_	_	1		_	6	6
BLD #xx:3, Rd	В		2								(#xx:3 of Rd8) → C	_	_	_	_	_	1	2	2



						ng I Ler)								_	. of es*1
	Operand Size	xx#	Rn	@ERn	@(d, ERn)	@-ERn/@ERn+	@aa	@(d, PC)	@aa				Con					Normal	Advanced
Mnemonic	_	#	~		(a)	(a)	(a)	(a)	@	I	Operation	ı	Н	N	Z	٧	C		_ `
BLD #xx:3, @ERd	В			4							(#xx:3 of @ERd) → C	_	_	_	_	_	1	(
BLD #xx:3, @aa:8	В						4				(#xx:3 of @aa:8) → C	_	_	_	_	_	1		5
BILD #xx:3, Rd	В		2								¬ (#xx:3 of Rd8) → C	_	_	_	_	_	1		2
BILD #xx:3, @ERd	В			4							¬ (#xx:3 of @ERd) → C	_	_	_	_	_	\$	•	5
BILD #xx:3, @aa:8	В						4				¬ (#xx:3 of @aa:8) → C	_	_	_	_	_	1	6	5
BST #xx:3, Rd	В		2								C → (#xx:3 of Rd8)	_	_	_	_	_	_	2	2
BST #xx:3, @ERd	В			4							C → (#xx:3 of @ERd24)	_	_	_	_	_	_	8	3
BST #xx:3, @aa:8	В						4				C → (#xx:3 of @aa:8)	_	_	_	_	_	_	8	3
BIST #xx:3, Rd	В		2								$\neg C \rightarrow (\#xx:3 \text{ of Rd8})$	_	_	_	_	_	_	2	2
BIST #xx:3, @ERd	В			4							$\neg C \rightarrow (\#xx:3 \text{ of } @ERd24)$	_	_	_	_	_	_	8	3
BIST #xx:3, @aa:8	В						4				¬ C → (#xx:3 of @aa:8)	_	_	_	_	_	_	8	3
BAND #xx:3, Rd	В		2								$C \land (\#xx:3 \text{ of Rd8}) \rightarrow C$	_	_	_	_	_	\$	2	2
BAND #xx:3, @ERd	В			4							$C \land (\#xx:3 \text{ of } @ERd24) \rightarrow C$	_	_	_	_	_	\$	6	6
BAND #xx:3, @aa:8	В						4				C∧(#xx:3 of @aa:8) → C	_	_	_	_	_	\$	6	3
BIAND #xx:3, Rd	В		2								$C \land \neg (\#xx:3 \text{ of } Rd8) \rightarrow C$	_	_	_	_	_	1	2	2
BIAND #xx:3, @ERd	В			4							$C \land \neg \text{ (#xx:3 of @ERd24)} \rightarrow C$	_	_	_	_	_	1	6	3
BIAND #xx:3, @aa:8	В						4				$C \land \neg (\#xx:3 \text{ of } @aa:8) \rightarrow C$	_	_	_	_	_	\$	6	6
BOR #xx:3, Rd	В		2								$C \land (\#xx:3 \text{ of Rd8}) \rightarrow C$	_	_	_	_	_	1	2	2
BOR #xx:3, @ERd	В			4							$C \land (\#xx:3 \text{ of } @ERd24) \rightarrow C$	_	_	_	_	_	\$	6	3
BOR #xx:3, @aa:8	В						4				C∧(#xx:3 of @aa:8) → C	_	_	_	_	_	1	6	3
BIOR #xx:3, Rd	В		2								$C \land \neg (\#xx:3 \text{ of } Rd8) \rightarrow C$	_	_	_	_	_	1	2	2
BIOR #xx:3, @ERd	В			4							$C \land \neg \text{ (#xx:3 of @ERd24)} \rightarrow C$	_	_	_	_	_	1	6	6
BIOR #xx:3, @aa:8	В						4				$C \land \neg (\#xx:3 \text{ of } @aa:8) \rightarrow C$	_	_	_	_	_	1	6	3
BXOR #xx:3, Rd	В		2								C⊕(#xx:3 of Rd8) → C	_	_	_	_	_	1	2	2
BXOR #xx:3, @ERd	В			4							C⊕(#xx:3 of @ERd24) → C	_	_	_	_	_	1	6	3
BXOR #xx:3, @aa:8	В						4				C⊕(#xx:3 of @aa:8) → C	_	_	_	_	_	\$	6	6
BIXOR #xx:3, Rd	В		2								C⊕ ¬ (#xx:3 of Rd8) → C	_	_	_	_	_	1	2	2
BIXOR #xx:3, @ERd	В			4							C⊕ ¬ (#xx:3 of @ERd24) → C	_	_	_	_	_	1	6	3
BIXOR #xx:3, @aa:8	В						4				C⊕¬ (#xx:3 of @aa:8) → C	_	_	_	_	_	1	6	3

6. Branching instructions

					essi	_			nd /tes)									No. State	
Mnemonic	Operand Size	#xx	Rn	@ERn	@(d, ERn)	@-ERn/@ERn+	Фаа	@(d, PC)	@ @ aa	I	Operation	Branch Condition	1	Con	ditio	on (Code	е	Normal	Advanced
BRA d:8 (BT d:8)	_							2			If condition	Always	_	_	_	_	_	_	4	ļ
BRA d:16 (BT d:16)	_							4			is true then			_	_	_	_	_	6	 }
BRN d:8 (BF d:8)	_							2			PC ← PC+d else	Never	_	_	_	_	_	_	4	ļ
BRN d:16 (BF d:16)	_							4			next;		_	_	_	_	_	_	6	;
BHI d:8	_							2				C ∨ Z = 0	_	_	_	_	_	_	4	ļ
BHI d:16	_							4					_	_	_	_	_	_	6	3
BLS d:8	_							2				C ∨ Z = 1	_	_	_	_	_	_	4	ļ
BLS d:16	_							4					_	_	_	_	_	_	6	 }
BCC d:8 (BHS d:8)	_							2				C = 0	_	_	_	_	_	_	4	ļ
BCC d:16 (BHS d:16)	_							4					_	_	_	_	_	_	6	;
BCS d:8 (BLO d:8)	_							2				C = 1	_	_	_	_	_	_	4	ļ
BCS d:16 (BLO d:16)	_							4					_	_	_	_	_	_	6	;
BNE d:8	_							2				Z = 0	_	_	_	_	_	_	4	ļ
BNE d:16	_							4					_	_	_	_	_	_	6	3
BEQ d:8	_							2				Z = 1	_	_	_	_	_	_	4	ļ
BEQ d:16	_							4					_	_	_	_	_	_	6	;
BVC d:8	_							2				V = 0	_	_	_	_	_	_	4	ļ
BVC d:16	_							4					_	_	_	_	_	_	6	3
BVS d:8	_							2				V = 1	_	_	_	_	_	_	4	ļ
BVS d:16	_							4					_	_	_	_	_	_	6	5
BPL d:8	_							2				N = 0	_	_	_	_	_	_	4	ļ
BPL d:16								4					_	_	_	_	_	_	6	;
BMI d:8	_							2				N = 1	_	_	_	_	_	_	4	ļ
BMI d:16	_							4					_	_	_	_	_	_	6	;
BGE d:8								2				N⊕V = 0	Ŀ			Ŀ			4	ļ
BGE d:16								4											6	3
BLT d:8	_							2				N⊕V = 1	_	_	_	_	_	_	4	ŀ
BLT d:16	_							4						_	_	_	_	_	6	;
BGT d:8								2				Z ∨ (N⊕V)	L		Ŀ	Ŀ			4	ļ
BGT d:16	_							4				= 0	_	_	_	_	_	_	6	3

					essi tion	_)									No Stat	. of es* ¹
Mnemonic	Operand Size	#xx	Rn	@ERn	@(d, ERn)	@-ERn/@ERn+	@aa	@(d, PC)	@ @aa		Operation	Branch Condition	1	Con	ditio	on C	Code V	e C	Normal	Advanced
BLE d:8		-						2		Ė	If condition	Z ∨ (N⊕V) = 1								1
BLE d:16	_							4			is true then PC ← PC+d else next;							_	(
JMP @ERn	_			2							PC ← ERn		_	_	_	_	_	_	4	1
JMP @aa:24	_						4				PC ← aa:24	ļ	_	_	_	_	_	_	6	6
JMP @@aa:8	-								2		PC ← @aa:	8	_	_	_	_	_	_	8	10
BSR d:8								2			PC → @ĐS PC ← PC+d		_	_	_	_	_	_	6	8
BSR d:16	_							4			PC → @ĐS PC ← PC+d		_	_	_	_	_	_	8	10
JSR @ERn				2							PC → @ĐS PC ← @ER		_	_	_	_	_	_	6	8
JSR @aa:24	_						4				PC → @ĐS PC ← @aa:		_	_	_	_	_	_	8	10
JSR @@aa:8	_								2		PC → @ĐS PC ← @aa:		_	_	_	_	_	_	8	12
RTS	_									2	PC ← @SP	+	_	_	_	_	_	_	8	10

7. System control instructions

				ddre		_)								No Stat	. of es∗¹
	Operand Size			@ERn	@(d, ERn)	@-ERn/@ERn+	la	@(d, PC)	@aa				Con	ditie	on C	Code	e	Normal	Advanced
Mnemonic	ဝီ	XX#	쮼	9	<u>@</u>	9	@ aa	<u>@</u>	0	I	Operation	ı	Н	N	z	٧	С	2	Ad
TRAPA #x:2	_									2	PC → @ĐSP CCR → @ĐSP <vector> → PC</vector>	1		_				14	16
RTE	-										CCR ← @SP+ PC ← @SP+	\$	\$	\$	1	1	\$	1	0
SLEEP	-										Transition to powerdown state	_	_	_	_	_	_	2	2
LDC #xx:8, CCR	В	2									#xx:8 → CCR	1	1	1	1	1	1	2	2
LDC Rs, CCR	В		2								Rs8 → CCR	1	1	1	1	1	1	2	2
LDC @ERs, CCR	W			4							@ERs → CCR	1	1	1	1	1	1	6	5
LDC @(d:16, ERs), CCR	W				6						@(d:16, ERs) → CCR	\$	\$	1	1	1	\$	8	3
LDC @(d:24, ERs), CCR	W				10						@(d:24, ERs) → CCR	\$	\$	1	1	1	\$	1	2
LDC @ERs+, CCR	W					4					@ERs → CCR ERs32+2 → ERs32	\$	\$	1	1	1	\$	8	3
LDC @aa:16, CCR	W						6				@aa:16 → CCR	1	1	1	1	1	1	8	3
LDC @aa:24, CCR	W						8				@aa:24 → CCR	1	1	1	1	1	1	1	0
STC CCR, Rd	В		2								CCR → Rd8	_	_	_	_	_	_	2	2
STC CCR, @ERd	W			4							CCR → @ERd	_	_	_	_	_	_	6	3
STC CCR, @(d:16, ERd)	W				6						CCR → @(d:16, ERd)	_	_	_	_	_	_	8	3
STC CCR, @(d:24, ERd)	W				10						$CCR \rightarrow @(d:24, ERd)$	_	_	_	_	_	_	1	2
STC CCR, @ĐERd	W					4					ERd32Đ2 → ERd32 CCR → @ERd	_	_	_	_	_	_	8	3
STC CCR, @aa:16	W						6				CCR → @aa:16	_	_	_	_	_	_	8	3
STC CCR, @aa:24	W						8				CCR → @aa:24	_	_	<u> </u>	_	_	_	1	0
ANDC #xx:8, CCR	В	2									CCR∧#xx:8 → CCR	1	1	1	1	1	1	2	2
ORC #xx:8, CCR	В	2									CCR√#xx:8 → CCR	1	1	1	1	1	1	2	2
XORC #xx:8, CCR	В	2									CCR⊕#xx:8 → CCR	1	1	1	1	1	1	2	2
NOP	-									2	PC ← PC+2	_	_	_	_	_	_	2	2



8. Block transfer instructions

					essi tion)								No Stat	
	Operand Size	L L		@ERn	@(d, ERn)	@-ERn/@ERn+	33	@(d, PC)	@aa				Con	ditio	on C	ode	В	Normal	Advanced
Mnemonic	o	*	R	<u>@</u>	<u>@</u>	9	@aa	<u>@</u>	0	1	Operation	ı	Н	N	z	٧	С	Š	Pφ
EEPMOV. B	_									4	$\begin{array}{ll} \text{if R4L} \neq 0 \\ \text{repeat} & @R5 \rightarrow @R6 \\ & R5\text{+}1 \rightarrow R5 \\ & R6\text{+}1 \rightarrow R6 \\ & R4\text{L}\text{-}1 \rightarrow R4\text{L} \\ \text{until} & R4\text{L}\text{=}0 \\ \text{else next;} \end{array}$		_	_			_	8+ 4n* ²	
EEPMOV. W										4	$ \begin{tabular}{ll} \begin{tabular}{ll} if R4 \neq 0 \\ repeat & @R5 \rightarrow @R6 \\ R5+1 \rightarrow R5 \\ R6+1 \rightarrow R6 \\ R4-1 \rightarrow R4 \\ until & R4=0 \\ else next; \end{tabular} $							8+ 4n* ²	

- Notes: 1. The number of states is the number of states required for execution when the instruction and its operands are located in on-chip memory. For other cases see section A.3.
 - 2. n is the value set in register R4L or R4.
 - (1) Set to 1 when a carry or borrow occurs at bit 11; otherwise cleared to 0.
 - (2) Set to 1 when a carry or borrow occurs at bit 27; otherwise cleared to 0.
 - (3) Retains its previous value when the result is zero; otherwise cleared to 0.
 - (4) Set to 1 when the adjustment produces a carry; otherwise retains its previous value.
 - (5) The number of states required for execution of an instruction that transfers data in synchronization with the E clock is variable.
 - (6) Set to 1 when the divisor is negative; otherwise cleared to 0.
 - (7) Set to 1 when the divisor is zero; otherwise cleared to 0.
 - (8) Set to 1 when the quotient is negative; otherwise cleared to 0.

A.2 Operation Code Maps

Table A.2 Operation Code Map (1)

Instruc	Instruction code:	le:	1st byte 2nd byte	2nd by	yte	L,	— Inst	 Instruction when most significant bit of BH is 0. 	when n	ost sig	nifican	t bit of I	BH is 0			
		AH	H AL	BH	BL]← Inst	→ Instruction when most significant bit of BH is 1	when n	ost sig	nifican	t bit of I	3H is 1			
AH AL	0	-	2	е	4	2	9	7	∞	6	4	В	O	۵	ш	ш
0	NOP	Table A.2 (2)	STC	LDC	ORC	XORC	ANDC	LDC	ADD		Table A.2 Table A.2 (2)	Table A.2 (2)	MOV	2	ADDX	Table A.2 (2)
-	Table A.2 (2)	Table A.2 (2)	Table A.2 Table A.2 Table A.2 Table A.2 (2) (2) (2)	Table A.2 (2)	OR.B	XOR.B	AND.B	Table A.2 (2)	SUB		Table A.2 Table A.2 (2)	Table A.2 (2)	S	CMP	SUBX	Table A.2 (2)
2																
ဗ								MO V V								
4	BRA	BRN	BHI	BLS	BCC	BCS	BNE	BNQ O	BVC	BVS	BPL	BMI	BGE	BLT	BGT	BLE
22	MULXU	DIVXU	MULXU	DIVXU	RTS	BSR	RTE	PA	Table A.2 (2)		JMP		BSR		JSR	
9					OR	XOR	AND	BST				MOV	2			
7	BSET	BNOT	BCLR	BISI	BOR	BXOR BIXOR	BAND	BLD	MOV	Table A.2 (2)	Table A.2 Table A.2 EEPMOV (2)	EEPMOV		Table A.2 (3)	A.2	
8								ADD								
o								ADDX								
٧								CMP								
В								SUBX								
Э								OR								
Q								XOR								
3								AND								
ш								MOV								

Table A.2 Operation Code Map (2)

AH AL	0	-	2	ю	4	25	9	7	∞	o	4	Ф	O	۵	ш	ш
01	MOV				LDC/STC				SLEEP				Table A.2 Table A.2 (3)	Table A.2 (3)		Table A.2 (3)
0A	NC											ΑΓ	ADD			
0B	ADDS					INC		INC	ADDS	SC				NC		NC NC
0F	DAA											MOV	20			
10	SHLL	1		SHLL					SHAL	AL		SHAL				
11	SHLR	R		SHLR					SHAR	AR		SHAR				
12	ROTXL	'XL		ROTXL					ROTL	Т.		ROTL				
13	ROTXR	XR		ROTXR					ROTR	TR		ROTR				
17	NOT	т		NOT		ЕХТО		EXTU	NEG	9:		NEG		EXTS		EXTS
1A	DEC											าร	SUB			
1B	SUBS					DEC		DEC	sans	38				DEC		DEC
1F	DAS											Ö	CMP			
28	BRA	BRN	BH	BLS	BCC	BCS	BNE	BEQ	BVC	BVS	BPL	BMI	BGE	BLT	BGT	BLE
79	MOV	ADD	CMP	SUB	OR	XOR	AND									
7.A	MOV	ADD	CMP	SUB	OR	XOR	AND									

Instruction code: 1st byte 2nd byte AH AL BH BL

Table A.2 Operation Code Map (3)

3rd byte 4th byte CH CL DH DL CH CL CH CL DH DL CH CH CH CH CH CH CH C	4 S 6 A B C D E F	LDC LDC LDC STC LDC STC			OR XOR AND		R BXOR BAND BLD BIOR BIXOR BIAND BILD	BST			ROR BAND BLD BIOR BIXOR BIAND BILD	BST		
2nd byte BH BL				S.		-	B /				8 /			
	ю			DIVXS		BTST	BTST			BTST	BTST			
1st byte AH AL	8		SXJUM					BCLR	BCLR			BCLR	BCLR	
	-			DIVIXS				BNOT	BNOT			BNOT	BNOT	
on code	0		MULXS					BSET	BSET			BSET	BSET	
Instruction code:	AH ALBH BLCH	01406	01C05	01D05	01F06	7Cr06 *1	7Cr07 *1	7Dr06 *1	7Dr07 *1	7Eaa6 *2	7Eaa7 *2	7Faa6 *2	7Faa7 *2	

Notes: 1. r is the register designation field. 2. aa is the absolute address field.

A.3 Number of States Required for Execution

The tables in this section can be used to calculate the number of states required for instruction execution by the H8/300H CPU. Table A.4 indicates the number of instruction fetch, data read/write, and other cycles occurring in each instruction. Table A.3 indicates the number of states required per cycle according to the bus size. The number of states required for execution of an instruction can be calculated from these two tables as follows:

Number of states =
$$I \times S_1 + J \times S_1 + K \times S_K + L \times S_L + M \times S_M + N \times S_N$$

Examples of Calculation of Number of States Required for Execution

Examples: Advanced mode, stack located in external address space, on-chip supporting modules accessed with 8-bit bus width, external devices accessed in three states with one wait state and 16-bit bus width.

BSET #0, @FFFFC7:8

From table A.4,
$$I = L = 2$$
 and $J = K = M = N = 0$
From table A.3, $S_I = 4$ and $S_L = 3$
Number of states $= 2 \times 4 + 2 \times 3 = 14$

JSR @@30

From table A.4,
$$I = J = K = 2$$
 and $L = M = N = 0$
From table A.3, $S_I = S_J = S_K = 4$
Number of states = $2 \times 4 + 2 \times 4 + 2 \times 4 = 24$

Table A.3 Number of States per Cycle

Access Conditions

			On-Chip	Sun-	External	Device		
			porting	-	8-Bit Bu	s	16-Bit B	us
Execution State (Cycle)		On-Chip Memory	8-Bit Bus	16-Bit Bus	2-State Access	3-State Access	2-State Access	3-State Access
Instruction fetch	Sı	2	6	3	4	6 + 2m	2	3 + m
Branch address read	S	=						
Stack operation	S_{κ}	=						
Byte data access	S _L	=	3	_	2	3 + m	•	
Word data access	S _M	_	6	_	4	6 + 2m		
Internal operation	S_{N}	1						

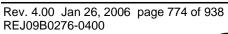
Legend

m: Number of wait states inserted into external device access

Table A.4 Number of Cycles per Instruction

Instruction	Mnemonic	Instruction Fetch I	Branch Addr. Read J	Stack Operation K		Word Data Access M	Internal Operation N
ADD	ADD.B #xx:8, Rd	1					
	ADD.B Rs, Rd	1					
	ADD.W #xx:16, Rd	2					
	ADD.W Rs, Rd	1					
	ADD.L #xx:32, ERd	3					
	ADD.L ERs, ERd	1					
ADDS	ADDS #1/2/4, ERd	1					
ADDX	ADDX #xx:8, Rd	1					
	ADDX Rs, Rd	1					
AND	AND.B #xx:8, Rd	1					
	AND.B Rs, Rd	1					
	AND.W #xx:16, Rd	2					
	AND.W Rs, Rd	1					
	AND.L #xx:32, ERd	3					
	AND.L ERs, ERd	2					
ANDC	ANDC #xx:8, CCR	1					
BAND	BAND #xx:3, Rd	1					
	BAND #xx:3, @ERd	2			1		
	BAND #xx:3, @aa:8	2			1		
Всс	BRA d:8 (BT d:8)	2					
	BRN d:8 (BF d:8)	2					
	BHI d:8	2					
	BLS d:8	2					
	BCC d:8 (BHS d:8)	2					
	BCS d:8 (BLO d:8)	2					
	BNE d:8	2					
	BEQ d:8	2					
	BVC d:8	2					
	BVS d:8 BPL d:8	2 2					
	BMI d:8	2					
	BGE d:8	2					
	BLT d:8	2					
	BGT d:8	2					
	BLE d:8	2					

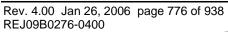
Instruction	Mnemonic	Instruction Fetch I	Branch Addr. Read J	Stack Operation K	-	Word Data Access M	Internal Operation N
Всс	BRA d:16 (BT d:16)	2					2
	BRN d:16 (BF d:16)	2					2
	BHI d:16	2					2
	BLS d:16	2					2
	BCC d:16 (BHS d:16)	2					2
	BCS d:16 (BLO d:16)	2					2
	BNE d:16	2					2
	BEQ d:16	2					2
	BVC d:16	2					2
	BVS d:16	2					2
	BPL d:16	2					2
	BMI d:16	2					2
	BGE d:16	2					2
	BLT d:16	2					2
	BGT d:16	2					2
	BLE d:16	2					2
BCLR	BCLR #xx:3, Rd	1					
	BCLR #xx:3, @ERd	2			2		
	BCLR #xx:3, @aa:8	2			2		
	BCLR Rn, Rd	1					
	BCLR Rn, @ERd	2			2		
	BCLR Rn, @aa:8	2			2		
BIAND	BIAND #xx:3, Rd	1					
	BIAND #xx:3, @ERd	2			1		
	BIAND #xx:3, @aa:8	2			1		
BILD	BILD #xx:3, Rd	1					
	BILD #xx:3, @ERd	2			1		
	BILD #xx:3, @aa:8	2			1		
BIOR	BIOR #xx:8, Rd	1					
	BIOR #xx:8, @ERd	2			1		
	BIOR #xx:8, @aa:8	2			1		
BIST	BIST #xx:3, Rd	1					
	BIST #xx:3, @ERd	2			2		
	BIST #xx:3, @aa:8	2			2		
BIXOR	BIXOR #xx:3, Rd	1					
	BIXOR #xx:3, @ERd	2			1		
	BIXOR #xx:3, @aa:8	2			1		
BLD	BLD #xx:3, Rd	1			·		
	BLD #xx:3, @ERd	2			1		
	BLD #xx:3, @aa:8	2			1		
	•						





Instruction			Instruction Fetch	Branch Addr. Read J	Stack Operation K		Word Data Access M	Internal Operation N
BNOT	BNOT #xx: BNOT #xx:	3, @ERd	1 2			2		
	BNOT #xx:	-	2			2		
	BNOT Rn,		1			0		
	BNOT Rn, BNOT Rn,		2			2		
BOR	BOR #xx:3		1					
	BOR #xx:3	•	2			1		
-	BOR #xx:3	, @aa:8	2			1		
BSET	BSET #xx:		1					
	BSET #xx:	-	2			2		
	BSET #xx:	-	2 1			2		
	BSET Rn,		2			2		
	BSET Rn,		2			2		
BSR	BSR d:8	Normal	2		1			
		Advanced	2		2			
	BSR d:16	Normal	2		1			2
		Advanced	2		2			2
BST	BST #xx:3,	Rd	1					
	BST #xx:3,	@ERd	2			2		
	BST #xx:3,	@aa:8	2			2		
BTST	BTST #xx:	-	1					
	BTST #xx:	-	2			1		
	BTST #xx:3, @aa:8 BTST Rn, Rd		2			1		
	•		1			1		
	BTST Rn, (2			1		
BXOR	BXOR #xx:		1			•		
DAUK	BXOR #xx:		2			1		
	BXOR #xx:	-	2			1		
CMP	CMP.B #xx	::8, Rd	1					
	CMP.B Rs,	Rd	1					
	CMP.W #x	x:16, Rd	2					
	CMP.W Rs		1					
	CMP.L #xx		3					
	CMP.L ER	s, EKd	1					
DAA	DAA Rd		1					
DAS	DAS Rd		1					

Instruction	n Mnemonic		Instruction Fetch I	Branch Addr. Read J	Stack Operation K	-	Word Data Access M	Internal Operation N
DEC	DEC.B Rd		1					
	DEC.W #1/2,		1					
	DEC.L #1/2, I	ERd	1					
DIVXS	DIVXS.B Rs,	Rd	2					12
	DIVXS.W Rs,	, ERd	2					20
DIVXU	DIVXU.B Rs,	Rd	1					12
	DIVXU.W Rs	, ERd	1					20
EEPMOV	EEPMOV.B		2			2n + 2*1		
	EEPMOV.W		2			2n + 2*1		
EXTS	EXTS.W Rd		1					
	EXTS.L ERd		1					
EXTU	EXTU.W Rd		1					
	EXTU.L ERd		1					
INC	INC.B Rd		1					
	INC.W #1/2, I	Rd	1					
	INC.L #1/2, E	Rd	1					
JMP	JMP @ERn		2					
	JMP @aa:24		2					2
	JMP @@aa:8	3 Normal	2	1				2
		Advanced	2	2				2
JSR	JSR @ERn Normal		2		1			
		Advanced	2		2			
	JSR @aa:24	Normal	2		1			2
		Advanced	2		2			2
	JSR @@aa:8	3 Normal	2	1	1			
		Advanced	2	2	2			
LDC	LDC #xx:8, C	CR	1					
	LDC Rs, CCF		1					
	LDC @ERs,	CCR	2				1	
	LDC @(d:16,	ERs), CCR	3				1	
	LDC @(d:24,	ERs), CCR	5				1	
	LDC @ERs+		2				1	2
	LDC @aa:16		3				1	
	LDC @aa:24	, CCR	4				1	





Instruct	ion Mnemonic	Instruction Fetch	Branch Addr. Read J	Stack Operation K	-	Word Data Access M	Internal Operation N
MOV	MOV.B #xx:8, Rd	1					
	MOV.B Rs, Rd	1					
	MOV.B @ERs, Rd	1			1		
	MOV.B @(d:16, ERs), Rd	2			1		
	MOV.B @(d:24, ERs), Rd	4			1		
	MOV.B @ERs+, Rd	1			1		2
	MOV.B @aa:8, Rd	1			1		
	MOV.B @aa:16, Rd	2			1		
	MOV.B @aa:24, Rd	3			1		
	MOV.B Rs, @ERd	1			1		
	MOV.B Rs, @(d:16, ERd)	2			1		
	MOV.B Rs, @(d:24, ERd)	4			1		
	MOV.B Rs, @-ERd	1			1		2
	MOV.B Rs, @aa:8	1			1		
	MOV.B Rs, @aa:16	2			1		
	MOV.B Rs, @aa:24	3			1		
	MOV.W #xx:16, Rd	2			•		
	MOV.W Rs, Rd	1					
	MOV.W @ERs, Rd	1				1	
	MOV.W @(d:16, ERs), Rd					1	
	MOV.W @(d:24, ERs), Rd					1	
	MOV.W @ERs+, Rd	1				1	2
	MOV.W @aa:16, Rd	2				1	_
	MOV.W @aa:24, Rd	3				1	
	MOV.W Rs, @ERd	1				1	
	MOV.W Rs, @(d:16, ERd)					1	
	MOV.W Rs, @(d:24, ERd)					1	
	MOV.W Rs, @-ERd	1				1	2
	MOV.W Rs, @aa:16	2				1	_
	MOV.W Rs, @aa:24	3				1	
	MOV.L #xx:32, ERd	3					
	MOV.L ERs, ERd	1					
	MOV.L @ERs, ERd	2				2	
	MOV.L @(d:16, ERs), ERd					2	
	MOV.L @(d:10, ERs), ERd					2	
		2				2	2
	MOV.L @ERs+, ERd MOV.L @aa:16, ERd	3				•	2
	MOV.L @aa:16, ERd	4				2	
	MOV.L @aa.24, ERG MOV.L ERs, @ERd	2				2	
	MOV.L ERS, @(d:16, ERd)	3				2	
	MOV.L ERS, @(d:10, ERd)					2	
	MOV.L ERS, @(d.24, ERd)	2				2	2
	MOV.L ERS, @-ERG MOV.L ERS, @aa:16	3				2	_
	MOV.L ERS, @aa:10	4				2	
	WOV.L LNS, @dd.24	7				۷	

Instruction	Mnemonic	Instruction Fetch I	Branch Addr. Read J	Stack Operation K		Word Data Access M	Internal Operation N
MOVFPE	MOVFPE @aa:16, Rd*2	2			1		
MOVTPE	MOVTPE Rs, @aa:16*	⁵² 2			1		
MULXS	MULXS.B Rs, Rd MULXS.W Rs, ERd	2 2					12 20
MULXU	MULXU.B Rs, Rd MULXU.W Rs, ERd	1					12 20
NEG	NEG.B Rd NEG.W Rd NEG.L ERd	1 1 1					
NOP	NOP	1					
NOT	NOT.B Rd NOT.W Rd NOT.L ERd	1 1 1					
OR	OR.B #xx:8, Rd OR.B Rs, Rd OR.W #xx:16, Rd OR.W Rs, Rd OR.L #xx:32, ERd OR.L ERs, ERd	1 1 2 1 3 2					
ORC	ORC #xx:8, CCR	1					
POP	POP.W Rn POP.L ERn	1 2				1 2	2 2
PUSH	PUSH.W Rn PUSH.L ERn	1 2				1 2	2 2
ROTL	ROTL.B Rd ROTL.W Rd ROTL.L ERd	1 1 1					
ROTR	ROTR.B Rd ROTR.W Rd ROTR.L ERd	1 1 1					
ROTXL	ROTXL.B Rd ROTXL.W Rd ROTXL.L ERd	1 1 1					
ROTXR	ROTXR.B Rd ROTXR.W Rd ROTXR.L ERd	1 1 1					
RTE	RTE	2		2			2

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Instruction	Mnemonic		Instruction Fetch I	Branch Addr. Read J	Stack Operation K	•	Word Data Access M	Internal Operation N
RTS	RTS	Normal	2		1			2
		Advance	d 2		2			2
SHAL	SHAL.B Rd		1					
	SHAL.W Rd		1					
	SHAL.L ERd		1					
SHAR	SHAR.B Rd		1					
	SHAR.W Rd		1					
	SHAR.L ERd		1					
SHLL	SHLL.B Rd		1					
	SHLL.W Rd		1					
	SHLL.L ERd		1					
SHLR	SHLR.B Rd		1					
	SHLR.W Rd		1					
	SHLR.L ERd		1					
SLEEP	SLEEP		1					
STC	STC CCR, Ro	t	1					
	STC CCR, @		2				1	
	STC CCR, @						1	
	STC CCR, @						1	
	STC CCR, @		2				1	2
	STC CCR, @		3				1	
-	STC CCR, @	aa:24	4				1	
SUB	SUB.B Rs, Ro		1					
	SUB.W #xx:1	-	2					
	SUB.W Rs, R		1					
	SUB.L #xx:32	-	3					
	SUB.L ERs, E		1					
SUBS	SUBS #1/2/4,	ERd	1					
SUBX	SUBX #xx:8,	Rd	1					
	SUBX Rs, Rd	<u> </u>	1					
TRAPA	TRAPA #x:2	Normal	2	1	2			4
		Advance	d2	2	2			4
XOR	XOR.B #xx:8,	Rd	1					
	XOR.B Rs, R	d	1					
	XOR.W #xx:1	6, Rd	2					
	XOR.W Rs, R	Rd	1					
	XOR.L #xx:32	2, ERd	3					
	XOR.L ERs, E	ERd	2					
XORC	XORC #xx:8,	CCR	1					
Notes: 1	n is the valu	e set in r	egister R/I	or R/I The s	ource and	destination	are access	sed n ± 1

Notes: 1. n is the value set in register R4L or R4. The source and destination are accessed n + 1 times each.

2. Not available in the H8/3067 Group.

Appendix B Internal I/O Registers

B.1 Addresses

		Data									
Address	Register	Bus	Bit Name	es							Module
(Low)	Name	Width	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Name
H'EE000	P1DDR	8	P1,DDR	P1 ₆ DDR	P1₅DDR	$P1_4DDR$	P1 ₃ DDR	P1 ₂ DDR	P1,DDR	P1₀DDR	Port 1
H'EE001	P2DDR	8	P2,DDR	P2 ₆ DDR	P2₅DDR	P2 ₄ DDR	P2 ₃ DDR	P2 ₂ DDR	P2 ₁ DDR	P2₀DDR	Port 2
H'EE002	P3DDR	8	P3,DDR	P3 ₆ DDR	P3₅DDR	P3 ₄ DDR	P3 ₃ DDR	P3 ₂ DDR	P3,DDR	P3₀DDR	Port 3
H'EE003	P4DDR	8	P4,DDR	P4 ₆ DDR	P4₅DDR	P4 ₄ DDR	P4 ₃ DDR	P4 ₂ DDR	P4 ₁ DDR	P4 ₀ DDR	Port 4
H'EE004	P5DDR	8	_	_	_	_	P5 ₃ DDR	P5 ₂ DDR	P5₁DDR	P5 _₀ DDR	Port 5
H'EE005	P6DDR	8	_	P6 ₆ DDR	P6₅DDR	P6 ₄ DDR	P6 ₃ DDR	P6 ₂ DDR	P6₁DDR	P6₀DDR	Port 6
H'EE006	_		_	_	_	_	_	_	_	_	
H'EE007	P8DDR	8	_	_	_	P8 ₄ DDR	P8 ₃ DDR	P8 ₂ DDR	P8,DDR	P8₀DDR	Port 8
H'EE008	P9DDR	8	_	_	P9₅DDR	P9₄DDR	P9 ₃ DDR	P9 ₂ DDR	P9₁DDR	P9₀DDR	Port 9
H'EE009	PADDR	8	PA,DDR	PA ₆ DDR	$PA_{\scriptscriptstyle 5}DDR$	PA_4DDR	PA ₃ DDR	PA ₂ DDR	PA,DDR	$PA_{_{0}}DDR$	Port A
H'EE00A	PBDDR	8	PB,DDR	PB ₆ DDR	PB₅DDR	PB₄DDR	PB ₃ DDR	PB ₂ DDR	PB₁DDR	PB₀DDR	Port B
H'EE00B	_		_	_	_	_	_	_	_	_	_
H'EE00C	_		_	_	_	_	_	_	_	_	_
H'EE00D	_		_	_	_	_	_	_	_	_	
H'EE00E	_		_	_	_	_	_	_	_	_	
H'EE00F	_		_	_	_	_	_	_	_	_	_
H'EE010	_		_	_	_	_	_	_	_	_	
H'EE011	MDCR	8	_	_	_	_	_	MDS2	MDS1	MDS0	System
H'EE012	SYSCR	8	SSBY	STS2	STS1	STS0	UE	NMIEG	SSOE	RAME	control
H'EE013	BRCR	8	A23E	A22E	A21E	A20E	_	_	_	BRLE	Bus controller
H'EE014	ISCR	8	_	_	IRQ5SC	IRQ4SC	IRQ3SC	IRQ2SC	IRQ1SC	IRQ0SC	Interrupt
H'EE015	IER	8	_	_	IRQ5E	IRQ4E	IRQ3E	IRQ2E	IRQ1E	IRQ0E	controller
H'EE016	ISR	8	_	_	IRQ5F	IRQ4F	IRQ3F	IRQ2F	IRQ1F	IRQ0F	_
H'EE017	_		_	_	_	_	_	_	_	_	_
H'EE018	IPRA	8	IPRA7	IPRA6	IPRA5	IPRA4	IPRA3	IPRA2	IPRA1	IPRA0	_
H'EE019	IPRB	8	IPRB7	IPRB6	IPRB5	_	IPRB3	IPRB2	IPRB1	_	-
H'EE01A	DASTCR	8	_	_	_	_	_	_	_	DASTE	D/A converter
H'EE01B	DIVCR	8	_	_	_	_	_	_	DIV1	DIV0	System
H'EE01C	MSTCRH	8	PSTOP			_	_	MSTPH2	MSTPH1	MSTPH0	control
H'EE01D	MSTCRL	8	MSTPL7	_	MSTPL5	MSTPL4	MSTPL3	MSTPL2	_	MSTPL0	
H'EE01E	ADRCR*1	8	_	_	_	_	_	_	_	ADRCTL	Bus controller
H'EE01F	CSCR	8	CS7E	CS6E	CS5E	CS4E					=

		Data									
Address	Register		Bit Name		D:4 5	D:4.4	D:4 0	D:4 0	D:4.4	D:4 0	_ Module
(Low)	Name	Width	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Name
H'EE020	ABWCR	8	ABW7	ABW6	ABW5	ABW4	ABW3	ABW2 AST2	ABW1	ABW0	Bus controller
H'EE021	ASTCR	8	AST7	AST6	AST5	AST4	AST3		AST1	AST0	=
H'EE022	WCRH	8	W71	W70	W61	W60	W51	W50	W41	W40	=
H'EE023	WCRL	8	W31	W30	W21	W20	W11	W10	W01	W00	-
H'EE024	BCR	8	ICIS1	ICIS0	BROME	BRS IS1	BRSTS0	_	RDEA	WAITE	_
H'EE025	_		_	_	_	_	_	_	_	_	
H'EE026	DRCRA	8	DRAS2	DRAS1	DRAS0	_	BE	RDM	SRFMD	RFSHE	DRAM Interface
H'EE027	DRCRB	8	MXC1	MXC0	CSEL	RCYCE		TPC	RCW	RLW	interiace -
H'EE028	RTMCSR	8	CMF	CMIE	CKS2	CKS1	CKS0	_	_	_	=
H'EE029	RTCNT	8									_
H'EE02A	RTCOR	8									
H'EE02B	Reserved	area (ad	ccess proh	nibited)							
H'EE02C	=										
H'EE02D	_										
H'EE02E	_										
H'EE02F											
H'EE030	FLMCR*2	8	FWE	SWE	ESU	PSU	EV	PV	E	Р	Flash memory
H'EE031	Reserved	area (ad	ccess proh	nibited)							=
H'EE032	EBR*2	8	EB7	EB6	EB5	EB4	EB3	EB2	EB1	EB0	_
H'EE033	Reserved	area (ad	ccess proh	nibited)							_
H'EE034	_		_	_	_	_	_	_	_	_	
H'EE035	_		_	_	_	_	_	_	_	_	_
H'EE036	_		_	_	_	_	_	_	_	_	_
H'EE037	_		_	_	_	_	_	_	_	_	_
H'EE038	_		_	_	_	_	_	_	_	_	_
H'EE039	_		_	_	_	_	_	_	_	_	_
H'EE03A	_		_	_	_	_	_	_	_	_	=
H'EE03B	_		_	_	_	_	_	_	_	_	=
H'EE03C	P2PCR	8	P2,PCR	P2 ₆ PCR	P2 ₅ PCR	P2 ₄ PCR	P2 ₃ PCR	P2,PCR	P2,PCR	P2 ₀ PCR	Port 2
H'EE03D	_		_	_	_	_	_	_	_	_	
H'EE03E	P4PCR	8	P4,PCR	P4 _s PCR	P4 _e PCR	P4,PCR	P4 ₃ PCR	P4,PCR	P4,PCR	P4 ₀ PCR	Port 4
H'EE03F	P5PCR	8	_	_	_	_	-	P5,PCR	P5,PCR	P5 PCR	Port 5
		-					-3	- z ·	-1	-0	

KUOW) Name Width Bit 7 Bit 6 Bit 5 Bit 4 Bit 2 Bit 1 Bit 0 Name HEEO40	Address	Register	Data Bus	Bit Nam	es							Module
HEE041 —		_		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
HEE042	H'EE040	_		_	_	_	_	_	_	_	_	
HEE043	H'EE041	_		_	_	_	_	_	_	_	_	_
HEEO44	H'EE042	_		_	_	_	_	_	_	_	_	=
HEEO46	H'EE043	_		_	_	_	_	_	_	_	_	_
H'EE046	H'EE044	_		_	_	_	_	_	_	_	_	
H'EE047	H'EE045	_		_	_	_	_	_	_	_	_	_
H'EE048	H'EE046	_		_	_	_	_	_	_	_	_	_
H'EE04A — — — — — — — — — — — — — — — — — — —	H'EE047	_		_	_	_	_	_	_	_	_	_
H'EE04A	H'EE048	_		_	_	_	_	_	_	_	_	=
H'EE04B — </td <td>H'EE049</td> <td>_</td> <td></td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>=</td>	H'EE049	_		_	_	_	_	_	_	_	_	=
H'EE04C — </td <td>H'EE04A</td> <td>_</td> <td></td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>=</td>	H'EE04A	_		_	_	_	_	_	_	_	_	=
H'EE04D — </td <td>H'EE04B</td> <td>_</td> <td></td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td>	H'EE04B	_		_	_	_	_	_	_	_	_	_
H'EE04E — — — — — — — — — — — — — — — — — — —	H'EE04C	_		_	_	_	_	_	_	_	_	=
H'EE04F — </td <td>H'EE04D</td> <td>_</td> <td></td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>=</td>	H'EE04D	_		_	_	_	_	_	_	_	_	=
H'EE050 — — — — — — — — — — — — — — — — — —	H'EE04E	_		_	_	_	_	_	_	_	_	=
H'EE051 — — — — — — — — — — — — — — — — — — —	H'EE04F	_		_	_	_	_	_	_	_	_	=
H'EE052 — </td <td>H'EE050</td> <td>_</td> <td></td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td></td>	H'EE050	_		_	_	_	_	_	_	_	_	
H'EE053 — </td <td>H'EE051</td> <td>_</td> <td></td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td>	H'EE051	_		_	_	_	_	_	_	_	_	_
H'EE054 — </td <td>H'EE052</td> <td>_</td> <td></td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td>	H'EE052	_		_	_	_	_	_	_	_	_	_
H'EE055 — </td <td>H'EE053</td> <td>_</td> <td></td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>=</td>	H'EE053	_		_	_	_	_	_	_	_	_	=
H'EE056 — </td <td>H'EE054</td> <td>_</td> <td></td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>=</td>	H'EE054	_		_	_	_	_	_	_	_	_	=
H'EE057 — </td <td>H'EE055</td> <td>_</td> <td></td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td>	H'EE055	_		_	_	_	_	_	_	_	_	_
H'EE058 — </td <td>H'EE056</td> <td>_</td> <td></td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td> <td>_</td>	H'EE056	_		_	_	_	_	_	_	_	_	_
H'EE059 — — — — — — H'EE05A — — — — — — H'EE05B — — — — — — H'EE05C — — — — — — H'EE05D — — — — — — H'EE05E — — — — — —	H'EE057	_		_	_	_	_	_	_	_	_	=
H'EE05A — — — — — — H'EE05B — — — — — — H'EE05C — — — — — — H'EE05D — — — — — — H'EE05E — — — — — —	H'EE058	_		_	_	_	_	_	_	_	_	_
H'EE05B — — — — — — H'EE05C — — — — — — H'EE05D — — — — — — H'EE05E — — — — — —	H'EE059	_		_	_	_	_	_	_	_	_	_
H'EE05C — — — — — H'EE05D — — — — — H'EE05E — — — — —	H'EE05A	_		_	_	_	_	_	_	_	_	_
H'EE05D — — — — — H'EE05E — — — — —	H'EE05B	_		_	_	_	_	_	_	_	_	_
H'EE05E — — — — — — — —	H'EE05C	_		_	_	_	_	_	_	_	_	
	H'EE05D	_		_	_	_	_	_	_	_	_	_
H'EE05F — — — — — — —	H'EE05E	_		_	_	_	_	_	_	_	_	
	H'EE05F	_		_	_	_	_	_	_	_	_	_

		Data									
Address	Register		Bit Nam							D 1: 0	Module
(Low)	Name	Width	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Name
H'EE060			_	_	_	_	_	_	_	_	_
H'EE061	_		_	_		_		_	_		
H'EE062	_		_	_	_	_	_	_	_	_	_
H'EE063	_		_					_	_		<u></u>
H'EE064	_		_	_							
H'EE065	_		_	_	_	_	_	_	_	_	_
H'EE066	_		_	_	_	_	_	_	_	_	_
H'EE067	_		_	_	_	_	_	_	_	_	
H'EE068	_		_	_	_	_	_	_	_	_	
H'EE069	_		_	_	_	_	_	_	_	_	
H'EE06A	_		_	_	_	_	_	_	_	_	
H'EE06B	_		_	_	_	_	_	_	_	_	
H'EE06C	_		_	_	_	_	_	_	_	_	
H'EE06D	_		_	_	_	_	_	_	_	_	
H'EE06E	_		_	_	_	_	_	_	_	_	_
H'EE06F	_		_	_	_	_	_	_	_	_	_
H'EE070	_		_	_	_	_	_	_	_	_	
H'EE071	_		_	_	_	_	_	_	_	_	
H'EE072	_		_	_	_	_	_	_	_	_	
H'EE073	_		_	_	_	_	_	_	_	_	
H'EE074	Reserved	area (ad	ccess pro	hibited)							
H'EE075	=										
H'EE076	_										
H'EE077	RAMCR*3	8	_	_	_	_	RAMS	RAM2	RAM1	_	Flash
H'EE078	Reserved	area (ad	ccess pro	hibited)							memory*
H'EE079	_										
H'EE07A											
H'EE07B											
H'EE07C	=										
H'EE07D	FLMSR*3	8	FLER	_	_	_	_	_	_	_	
H'EE07E	Reserved	area (ad	ccess pro	hibited)							_
H'EE07F	_	,	•	,							
H'EE080	_										
H'EE081	_										

		Data									
Address	Register	Bus	Bit Nan	nes							Module
(Low)	Name	Width	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Name
H'FFF20	MAR0AR	8									DMAC channel 0A
H'FFF21	MAR0AE	8									=
H'FFF22	MAR0AH	8									-
H'FFF23	MAR0AL	8									-
H'FFF24	ETCR0AH	8									_
H'FFF25	ETCR0AL	8									_
H'FFF26	IOAR0A	8									
H'FFF27	DTCR0A	8	DTE	DTSZ	DTID	RPE	DTIE	DTS2	DTS1	DTS0	Short address mode
			DTE	DTSZ	SAID	SAIDE	DTIE	DTS2A	DTS1A	DTS0A	Full address mode
H'FFF28	MAR0BR	8									DMAC channel 0B
H'FFF29	MAR0BE	8	-	-	-	-			-	-	_
H'FFF2A	MAR0BH	8									_
H'FFF2B	MAR0BL	8									_
H'FFF2C	ETCR0BH	8									_
H'FFF2D	ETCR0BL	8									_
H'FFF2E	IOAR0B	8									
H'FFF2F	DTCR0B	8	DTE	DTSZ	DTID	RPE	DTIE	DTS2	DTS1	DTS0	Short address mode
			DTME	_	DAID	DAIDE	TMS	DTS2B	DTS1B	DTS0B	Full address mode
H'FFF30	MAR1AR	8									DMAC channel 1A
H'FFF31	MAR1AE	8									-
H'FFF32	MAR1AH	8									-
H'FFF33	MAR1AL	8									_
H'FFF34	ETCR1AH	8									_
H'FFF35	ETCR1AL	8									_
H'FFF36	IOAR1A	8									
H'FFF37	DTCR1A	8	DTE	DTSZ	DTID	RPE	DTIE	DTS2	DTS1	DTS0	Short address mode
			DTE	DTSZ	SAID	SAIDE	DTIE	DTS2A	DTS1A	DTS0A	Full address mode
H'FFF38	MAR1BR	8									DMAC channel 1B
H'FFF39	MAR1BE	8				-					
H'FFF3A	MAR1BH	8									-
H'FFF3B	MAR1BL	8									=
H'FFF3C	ETCR1BH	8									-
H'FFF3D	ETCR1BL	8									=
H'FFF3E	IOAR1B	8									=
H'FFF3F	DTCR1B	8	DTE	DTSZ	DTID	RPE	DTIE	DTS2	DTS1	DTS0	Short address mode
			DTME	_	DAID	DAIDE	TMS	DTS2B	DTS1B	DTS0B	Full address mode



		Data									
Address	Register		Bit Nan								_ Module
(Low)	Name	Width	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Name
H'FFF40			_		_			_			=
H'FFF41	_		_	_		_	_	_	_	_	=
H'FFF42	_		_	_		_	_		_		_
H'FFF43	_		_		_	_	_		_		_
H'FFF44 H'FFF45	_										_
	_		_	_	_	_	_	_	_	_	_
H'FFF46	_			_			_		_	_	_
H'FFF47	_		_	_	_	_	_		_		=
H'FFF48	_		_	_	_		_	_	_	_	=
H'FFF49	_		_				_	_	_	_	=
H'FFF4A	_		_	_			_	_		_	_
H'FFF4B	_			_							_
H'FFF4C	_		_								=
H'FFF4D	_		_	_			_	_	_		
H'FFF4E	_		_	_	_	_	_	_	_	_	_
H'FFF4F	_		_	_	_	_	_	_	_	_	
H'FFF50	_		_	_	_	_	_	_	_	_	_
H'FFF51	_		_	_	_	_	_	_	_	_	
H'FFF52	_		_	_	_	_	_	_	_	_	_
H'FFF53	_		_	_	_	_	_	_	_	_	_
H'FFF54	_		_	_	_	_	_	_	_	_	_
H'FFF55	_		_	_	_	_	_	_	_	_	_
H'FFF56	_		_	_	_	_	_	_	_	_	_
H'FFF57	_		_	_	_	_	_	_	_	_	_
H'FFF58	_		_	_	_	_	_	_	_	_	-
H'FFF59	_		_	_	_	_	_	_	_	_	-
H'FFF5A	_		_	_	_	_	_	_	_	_	-
H'FFF5B	_		_	_	_	_	_	_	_	_	-
H'FFF5C	_		_	_	_	_	_	_	_	_	=
H'FFF5D	_		_	_	_	_	_	_	_	_	_
H'FFF5E	_		_	_	_	_	_	_	_	_	_
H'FFF5F	_		_	_	_	_	_	_	_	_	=

		Data									
Address (Low)	Register Name	Bus Width	Bit Nam	es Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	_ Module Name
H'FFF60	TSTR	8	_	_	_	_	_	STR2	STR1	STR0	16-bit timer,
H'FFF61	TSNC	8	_	_	_	_	_	SYNC2	SYNC1	SYNC0	(all channels)
H'FFF62	TMDR	8	_	MDF	FDIR	_	_	PWM2	PWM1	PWM0	=
H'FFF63	TOLR	8	_	_	TOB2	TOA2	TOB1	TOA1	TOB0	TOA0	=
H'FFF64	TISRA	8	_	IMIEA2	IMIEA1	IMIEA0	_	IMFA2	IMFA1	IMFA0	<u> </u>
H'FFF65	TISRB	8	_	IMIEB2	IMIEB1	IMIEB0	_	IMFB2	IMFB1	IMFB0	_
H'FFF66	TISRC	8	_	OVIE2	OVIE1	OVIE0	_	OVF2	OVF1	OVF0	_
H'FFF67											_
H'FFF68	TCR0	8	_	CCLR1	CCLR0	CKEG1	CKEG0	TPSC2	TPSC1	TPSC0	16-bit timer
H'FFF69	TIOR0	8	_	IOB2	IOB1	IOB0	_	IOA2	IOA1	IOA0	channel 0
H'FFF6A	TCNT0H	16									
H'FFF6B	TCNT0L	=									
H'FFF6C	GRA0H	16									
H'FFF6D	GRA0L	=									- "
H'FFF6E	GRB0H	16									
H'FFF6F	GRB0L	=									- "
H'FFF70	TCR1	8	_	CCLR1	CCLR0	CKEG1	CKEG0	TPSC2	TPSC1	TPSC0	16-bit timer
H'FFF71	TIOR1	8	_	IOB2	IOB1	IOB0	_	IOA2	IOA1	IOA0	channel 1
H'FFF72	TCNT1H	16									
H'FFF73	TCNT1L	_									
H'FFF74	GRA1H	16									
H'FFF75	GRA1L	=									- "
H'FFF76	GRB1H	16									
H'FFF77	GRB1L										
H'FFF78	TCR2	8	_	CCLR1	CCLR0	CKEG1	CKEG0	TPSC2	TPSC1	TPSC0	16-bit timer
H'FFF79	TIOR2	8	_	IOB2	IOB1	IOB0	_	IOA2	IOA1	IOA0	channel 2
H'FFF7A	TCNT2H	16									_
H'FFF7B	TCNT2L										_
H'FFF7C	GRA2H	16									_
H'FFF7D	GRA2L										_
H'FFF7E	GRB2H	16									_
H'FFF7F	GRB2L										

		Data									
Address	Register	Bus	Bit Nam								_ Module
(Low)	Name	Width		Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Name
H'FFF80	TCR0	8	CMIEB	CMIEA	OVIE	CCLR1	CCLR0	CKS2	CKS1	CKS0	8-bit timer
H'FFF81	TCR1	8	CMIEB	CMIEA	OVIE	CCLR1	CCLR0	CKS2	CKS1	CKS0	channels 0 and 1
H'FFF82	TCSR0	8	CMFB	CMFA	OVF	ADTE	OIS3	OIS2	OS1	OS0	— —
H'FFF83	TCSR1	8	CMFB	CMFA	OVF	ICE	OIS3	OIS2	OS1	OS0	_
H'FFF84	TCORA0	8									_
H'FFF85	TCORA1	8									_
H'FFF86	TCORB0	8									<u> </u>
H'FFF87	TCORB1	8									_
H'FFF88	TCNT0	8									_
H'FFF89	TCNT1	8									_
H'FFF8A	_		_	_	_	_	_	_	_	_	_
H'FFF8B	_		_	_	_	_	_	_	_	_	
H'FFF8C	TCSR*4	8	OVF	WT/IT	TME	_	_	CKS2	CKS1	CKS0	WDT
H'FFF8D	TCNT*4	8									_
H'FFF8E	_		_	_	_	_	_	_	_	_	_
H'FFF8F	RSTCSR*	8	WRST	RSTOE	_	_	_	_	_	_	
H'FFF90	TCR2	8	CMIEB	CMIEA	OVIE	CCLR1	CCLR0	CKS2	CKS1	CKS0	8-bit timer
H'FFF91	TCR3	8	CMIEB	CMIEA	OVIE	CCLR1	CCLR0	CKS2	CKS1	CKS0	channels 2
H'FFF92	TCSR2	8	CMFB	CMFA	OVF	_	OIS3	OIS2	OS1	OS0	and 3
H'FFF93	TCSR3	8	CMFB	CMFA	OVF	ICE	OIS3	OIS2	OS1	OS0	_
H'FFF94	TCORA2	8									_
H'FFF95	TCORA3	8									_
H'FFF96	TCORB2	8									_
H'FFF97	TCORB3	8									_
H'FFF98	TCNT2	8									_
H'FFF99	TCNT3	8									_
H'FFF9A	_		_	_	_	_	_	_	_	_	_
H'FFF9B	_		_	_	_	_	_	_	_	_	_
H'FFF9C	DADR0	8									D/A converter
H'FFF9D	DADR1	8									_
H'FFF9E	DACR	8	DAOE1	DAOE0	DAE	_	_	_	_	_	_
H'FFF9F	_	8	_	_	_	_	_	_	_	_	_

Address	Register	Data	Bit Name	s							Module
(Low)	Name	Width		Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Name
H'FFFA0	TPMR	8	_	_	_	_	G3NOV	G2NOV	G1NOV	G0NOV	TPC
H'FFFA1	TPCR	8	G3CMS1	G3CMS0	G2CMS1	G2CMS0	G1CMS1	G1CMS0	G0CMS1	G0CMS0	
H'FFFA2	NDERB	8	NDER15	NDER14	NDER13	NDER12	NDER11	NDER10	NDER9	NDER8	
H'FFFA3	NDERA	8	NDER7	NDER6	NDER5	NDER4	NDER3	NDER2	NDER1	NDER0	•
H'FFFA4	NDRB*5	8	NDER15	NDER14	NDER13	NDER12	NDER11	NDER10	NDER9	NDER8	•
			NDER15	NDER14	NDER13	NDER12	_	_	_	_	
H'FFFA5	NDRA*5	8	NDER7	NDER6	NDER5	NDER4	NDER3	NDER2	NDER1	NDER0	•
			NDER7	NDER6	NDER5	NDER4	_	_	_	_	
H'FFFA6	NDRB*5	8	_	_	_	_	_	_	_	_	
			_	_	_	_	NDER11	NDER10	NDER9	NDER8	:
H'FFFA7	NDRA*5	8	_	_	_	_	_	_	_	_	:
			_	_	_	_	NDER3	NDER2	NDER1	NDER0	•
H'FFFA8											
H'FFFA9											
H'FFFAA											
H'FFFAB											
H'FFFAC											
H'FFFAD											
H'FFFAE											
H'FFFAF											
H'FFFB0	SMR	8	C/A	CHR	PE	O/Ē	STOP	MP	CKS1	CKS0	SCI
H'FFFB1	BRR	8									channel 0
H'FFFB2	SCR	8	TIE	RIE	TE	RE	MPIE	TEIE	CKE1	CKE0	
H'FFFB3	TDR	8									
H'FFFB4	SSR	8	TDRE	RDRF	ORER	FER/ERS	PER	TEND	MPB	MPBT	
H'FFFB5	RDR	8									
H'FFFB6	SCMR	8	_	_	_	_	SDIR	SINV	_	SMIF	
H'FFFB7	Reserved	l area (a	ccess proh	ibited)							
H'FFFB8	SMR	8	C/A	CHR	PE	O/Ē	STOP	MP	CKS1	CKS0	SCI
H'FFFB9	BRR	8									channel 1
H'FFFBA	SCR	8	TIE	RIE	TE	RE	MPIE	TEIE	CKE1	CKE0	
H'FFFBB	TDR	8									
H'FFFBC	SSR	8	TDRE	RDRF	ORER	FER/ERS	PER	TEND	MPB	MPBT	
H'FFFBD	RDR	8									
H'FFFBE	SCMR	8	_	_	_	_	SDIR	SINV	_	SMIF	
H'FFFBF	Reserved	l area (a	ccess proh	ibited)							

A -1 -1	Danistan	Data	Bit Nam	oe.							Madula
Address (Low)	Register Name	Bus Width	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	_ Module Name
H'FFFC0	SMR	8	C/Ā	CHR	PE	O/Ē	STOP	MP	CKS1	CKS0	SCI
H'FFFC1	BRR	8									channel 2
H'FFFC2	SCR	8	TIE	RIE	TE	RE	MPIE	TEIE	CKE1	CKE0	_
H'FFFC3	TDR	8									_
H'FFFC4	SSR	8	TDRE	RDRF	ORER	FER/ER S	PER	TEND	MPB	MPBT	
H'FFFC5	RDR	8									_
H'FFFC6	SCMR	8	_	_	_	_	SDIR	SINV	_	SMIF	_
H'FFFC7	Reserved	area (ad	ccess prof	nibited)							-
H'FFFC8	_		_	_	_	_	_	_	_	_	
H'FFFC9	_		_	_	_	_	_	_	_	_	-
H'FFFCA	_		_	_	_	_	_	_	_	_	_
H'FFFCB	_		_	_	_	_	_	_	_	_	-
H'FFFCC	_		_	_	_	_	_	_	_	_	_
H'FFFCD	_		_	_	_	_	_	_	_	_	-
H'FFFCE	_		_	_	_	_	_	_	_	_	_
H'FFFCF	_		_	_	_	_	_	_	_	_	-
H'FFFD0	P1DR	8	P1,	P1 ₆	P1 ₅	P1 ₄	P1 ₃	P1 ₂	P1,	P1 _o	Port1
H'FFFD1	P2DR	8	P2,	P2 ₆	P2 ₅	P2 ₄	P2 ₃	P2 ₂	P2,	P2 ₀	Port2
H'FFFD2	P3DR	8	P3,	P3 ₆	P3 ₅	P3 ₄	P3 ₃	P3 ₂	P3,	P3 ₀	Port3
H'FFFD3	P4DR	8	P4,	P4 ₆	P4 ₅	P4 ₄	P4 ₃	P4 ₂	P4,	P4 ₀	Port4
H'FFFD4	P5DR	8	_	_	_	_	P5 ₃	P5 ₂	P5,	P5 ₀	Port5
H'FFFD5	P6DR	8	P6,	P6 ₆	P6 ₅	P6 ₄	P6 ₃	P6 ₂	P6,	P6 _o	Port6
H'FFFD6	P7DR	8	P7,	P7 ₆	P7 ₅	P7 ₄	P7 ₃	P7 ₂	P7,	P7 ₀	Port7
H'FFFD7	P8DR	8	_	_	_	P8 ₄	P8 ₃	P8 ₂	P8,	P8 ₀	Port8
H'FFFD8	P9DR	8	_	_	P9 ₅	P9 ₄	P9 ₃	P9 ₂	P9,	P9₀	Port9
H'FFFD9	PADR	8	PA,	PA ₆	PA ₅	$PA_{_4}$	PA ₃	PA ₂	PA ₁	PA _o	PortA
H'FFFDA	PBDR	8	PB,	PB ₆	PB₅	PB ₄	PB ₃	PB ₂	PB ₁	PB₀	PortB
H'FFFDB	_		_	_	_	_	_	_	_	_	
H'FFFDC	_		_	_	_	_	_	_	_	_	
H'FFFDD	_		_	_	_	_	_	_	_	_	
H'FFFDE	_		_	_	_	_	_	_	_	_	
H'FFFDF	_		_	_	_	_	_	_	_	_	

Address	Register	Data Bus	Bit Nam	es							Module
(Low)	Name	Width	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Name
H'FFFE0	ADDRAH	8	AD9	AD8	AD7	AD6	AD5	AD4	AD3	AD2	A/D converter
H'FFFE1	ADDRAL	8	AD1	AD0	_	_	_	_	_	_	
H'FFFE2	ADDRBH	8	AD9	AD8	AD7	AD6	AD5	AD4	AD3	AD2	-
H'FFFE3	ADDRBL	8	AD1	AD0	_	_	_	_	_	_	
H'FFFE4	ADDRCH	8	AD9	AD8	AD7	AD6	AD5	AD4	AD3	AD2	
H'FFFE5	ADDRCL	8	AD1	AD0	_	_	_	_	_	_	
H'FFFE6	ADDRDH	8	AD9	AD8	AD7	AD6	AD5	AD4	AD3	AD2	
H'FFFE7	ADDRDL	8	AD1	AD0	_	_	_	_	_	_	
H'FFFE8	ADCSR	8	ADF	ADIE	ADST	SCAN	CKS	CH2	CH1	CH0	-
H'FFFE9	ADCR	8	TRGE	_	_	_	_	_	_	_	

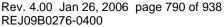
- Notes: 1. The ADRCR register is provided only in the flash memory R version and mask ROM versions; it is not present in the flash memory version.
 - 2. The FLMCR and EBR registers are used only in the flash memory and flash memory R versions, and are not provided in the mask ROM versions.
 - 3. The RAMCR and FLMCR registers are used only in the flash memory and flash memory R versions, and are not provided in the mask ROM versions.
 - For write access to TCSR, TCNT, and RSTCSR, see section 12.2.4, Notes on Register Access.
 - 5. The address depends on the output trigger setting.

Legend

WDT: Watchdog timer

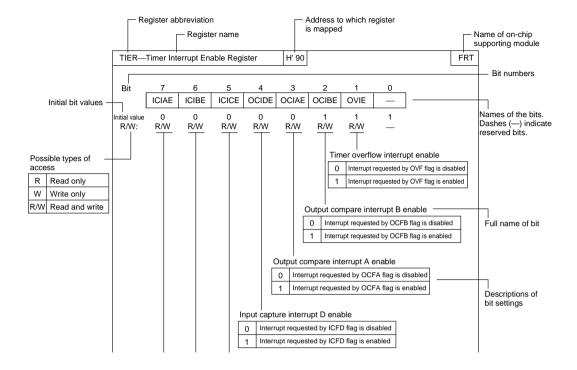
TPC: Programmable timing pattern controller

SCI: Serial communication interface





B.2 Functions



1DDR—Port	1 Data Dir	ection R	egister			H'EE	000		Port 1
	Bit	7	6	5	4	3	2	1	0
		P17DDR	P16DDR	P15DDR	P14DDF	P13DDR	P12DDR	P11DDR	P10DDF
Modes 1 to 4	Initial value Read/Write	1	1	1	1_	1_	1	1_	1_
Modes 5 to 7	Initial value Read/Write	0 W	0 W	0 W	0 W	0 W	0 W	0 W	0 W
					Port 1 in	out/output s	elect		
					0 Ge	neric input			
					1 Ge	neric outpu	t		

2DDR—Port	2 Data Dir	ection R		H'EE		Port 2			
								·	
	Bit	7	6	5	4	3	2	1	0
		P27DDR	P26DDR	P25DDR	P24DDR	P23DDR	P22DDR	P21DDR	P20DDF
Modes 1 to 4 <	Initial value	1	1	1	1	1	1	1	1
	Read/write	_	_	_	_	_	_	_	_
Modes 5 to 7 <	Initial value Read/Write	0 W	0	0	0	0	0	0	0
Modes 5 to 7	Read/Write	W	W	W	W	W	W	W	W

Port 2 input/output select

0	Generic input
1	Generic output



								iai ii o i tog
DR—Port 3 I	Data Dire	ction Re	gister			H'EE002	2	Port 3
Bit	7	6	5	4	3	2	1	0
	P37DDR	P36DDR	P35DDR	P34DDR	P33DDR	P32DDR	P31DDR	P30DDR
Initial value	0	0	0	0	0	0	0	0
Read/Write		W	W	W	W	W	W	
				Port 3 inpu	it/output c	oloct		
			ſ		eric input			
			-		eric input			
			Ĺ	i Gen	enc outpu			
DD Dowt 4.1	Data Dina	otion Do	-!			LUCEOO		Dowt 4
DR—Port 4 I	Jata Dire	ction Re	gister			H'EE003	S	Port 4
Bit	7	6	5	4	3	2	1	0
	P47DDR	P46DDR	P45DDR	P44DDR	P43DDR	P42DDR	P41DDR	P40DDR
Initial value	0	0	0	0	0	0	0	0
Read/Write	W	W	W	W	W	W	W	
			ſ	Port 4 inpu	ut/output seeric input	elect		
			-		eric output	t		
			L	.				
DR—Port 5 I	Data Diro	ction Po	nietor			H'EE004	<u> </u>	Port 5
DICTION 3		CHOII IVE	gistei			11 LL00-		1 011 3
	Bit	7	6	5	4	3 2	. 1	0
				_	_ P53	DDR P52E	DDR P51DI	DR P50DDR
	ĺ				1 00			
	nitial value Read/Write	1 —	1	1 —		1 1	1	1_
Modes 1 to 4		1 - 1 -	1 - 1	1 - 1	1 1	1 1 0 W W	0 0	1 0 W
Modes 1 to 4	Read/Write	_	_	_	1 1	0 0 W W	0 0 V W	0 W
Modes 1 to 4	Read/Write	_	_	_	1 1	0 0 W V	0 0 V W	0 W
Modes 1 to 4	Read/Write	_	_	_	1 1	0 0 0 W W Port 5	0 0 V W	0 W

R—Port 6 D	ata Dire		H'EE005	Port 6				
Bit	7	6	5	4	3	2	1	0
	_	P66DDR	P65DDR	P64DDR	P63DDR	P62DDR	P61DDR	P60DDR
Initial value Read/Write	<u>1</u>	0 W	0 W	0 W	0 W	0 W	0 W	0 W
			_	Port 6 inp	ut/output s	elect		
				0 Ger	neric input			
				1 Ger	neric outpu	t		

P8DDR—Port 8 Data Di	rection F		H'EE0	H'EE007				
Bit	7	6	5	4	3	2	1	0
	_	_	_	P84DDR	P83DDR	P82DDR	P81DDR	P80DDR
Madaga 4 to 4 ∫Initial value	1	1	1	1	0	0	0	0
Modes 1 to 4 Read/Write		_	_	W	W	W	W	W
Modes 5 to 7 Initial value	1	1	1	0	0	0	0	0
Read/Write		_	_	W	W	W	W	W
					Port 8	input/outp	out select	
					0	Generic ir	nput	
					1	Generic o	utput	

D0DDD D 40.5	D. (11155000		D. 10
P9DDR—Port 9 [Data Dire	ction Re	gister			H'EE008	3	Port 9
Bit	7	6	5	4	3	2	1	0
	_	_	P95DDR	P94DDR	P93DDR	P92DDR	P91DDR	P90DDR
Initial value Read/Write	1_	<u>1</u>	0 W	0 W	0 W	0 W	0 W	0 W
				Port		tput select		
				1	Generic Generic			
PADDR—Port A	Data Dire	ection Re	egister			H'EE009)	Port A
	Bit	7	6	5 A₅DDR PA	4 3		1	0
		PA7DDR I	PA6DDR PA	A5DDR PA	4DDR PA3I	DDR PA2DL	PA1DDF	PA ₀ DDR
	nitial value Read/Write	<u>1</u>	0 W	0 W	0 (W V		0 W	0 W
	nitial value Read/Write	0 W	0 W	0 W	0 (W V		0 W	0 W
				Por	t A input/ou	tput select		
				1	Generic i	nput		
PBDDR—Port B	Data Dire	ection Re	egister			H'EE00A	A	Port B
Dia	7	6	5	4	3	2	1	0
Bit	PB7DDR				PB3DDR			PB ₀ DDR
Initial value Read/Write	0 W	0 W	0 W	0 W	0 W	0 W	0 W	0 W
			ı		out/output	select		
					neric input			
				1 Ger	neric outpu	it		

MDCR—Mode	Control	Registe	H'EI	≣011	Syst	em control			
Bit	7	6	5	4	3	2	1	0	
	_		_			MDS2	MDS1	MDS0	
Initial value	1	1	0	0	0	*	*	*	
Read/Write	_	_	_	_	_	R	R	R	

Mode select 2 to 0

Bit 2	Bit 1	Bit 0	Operating Mode
MD ₂	MD1	MD ₀	Operating wode
	0	0	_
0	0	1	Mode 1
0	4	0	Mode 2
	l I	1	Mode 3
	0	0	Mode 4
4	0	1	Mode 5
'	4	0	Mode 6
		1	Mode 7

Note: * Determined by the state of the mode pins (MD_2 to MD_0).



SYSCR—S	Systen	n Cont	rol Re	giste	r				Н	l'EE01	2	System control
											l	
Bit	7	6		5	4	3	3	2		1	0	
	SSBY	STS	S2 S	TS1	STS0	UE		NMIE	}	SSOE	RAME	
Initial value Read/Write	0 R/W	0 R/V		0 R/W	0 R/W	1 R/		0 R/W	_	0 R/W	1 R/W	_
							(inter	Softwar O crim Irr ar 1 st si ect	On-cre standby a software Il address ontrol sign npedance a software ddress but ate and but gnals are	hip RAM is disabled hip RAM is enabled y output port enable standby mode, bus and bus hals are high-
				U	lser bit er	nable		•				
							<u> </u>				ıpt mask l	oit
						R bit 6	(UI)	is used a	as a	user bit		
		Standby		_								
		Bit 6 STS2	Bit 5 STS1	Bit STS		Sta	ndby	Timer				
		0.02		0	-	ting Tir	ne =	8,192 st	ates	5		
		0	0	1				16,384 s				
		J	1	0				32,768				
			'	1				65,536 s				
			0	0				131,072				
		1		1				26,2144				
			1	1		ııng 11r al setti		1,024 st	aies	·		
_			l	1 1	lileg	ai ətill	ııy					
_	oftware											
	0 SL	EEP inst	truction (causes	transitio	n to sle	eep r	node				

BRCR—Bu	us Release	Control F	Register			H'EE0	13	Bus con	troller
					l				
	Bit	7	6	5	4	3	2	1	0
		A23E	A22E	A21E	A20E	_			BRLE
Modes 1, 2, 6, 7	Initial value Read/Write	1_	1_			1_	1_	1_	0 R/W
Modes 3, 4	Initial value Read/Write	1 R/W	1 R/W	1 R/W	<u>0</u>	<u>1</u>		1_	0 R/W
Mode 5	Initial value Read/Write	1 R/W	1 R/W	1 R/W	1 R/W	1 —	1	1	0 R/W
		Add 0 1	Iress 23 to Address Other inp				E	0 release externa The bu release	enable s cannot be d to an il device s can be d to an il device
ISCR—IRC	Sense Co	ntrol Reg	ister			H'EE0	14	Interrupt	Controller
ı	Bit 7	6	5	4	3	2		1 0	
	_	_	IRQ5SC	IRQ4SC	IRQ3SC	IRQ2S	C IRC	Q1SC IRQ0	sc
Initial val Read/Wr		0 R/W	0 R/W	0 R/W	0 R/W	0 R/W		0 0 I/W R/V	V
		10	RQ5 to IRC	lo sense co	ontrol				
				upts are re		vhen IRC	5 to ĪR0	 Q̄₀ are low	
			_	-				put at ĪRQ₅	to ĪRQ₀

IER-IRQ Enable Register H'EE015 **Interrupt Controller** 2 Bit 5 3 0 IRQ0E IRQ5E IRQ4E IRQ3E IRQ2E IRQ1E 0 Initial value 0 0 0 0 0 0 0 R/W R/W Read/Write R/W R/W R/W R/W R/W R/W IRQ₅ to IRQ₀ enable IRQ5 to IRQ0 interrupts are disabled 1 IRQ5 to IRQ0 interrupts are enabled

ISR—IRQ Status Register

H'EE016

Interrupt Controller

Bit	7	6	5	4	3	2	1	0
	_	_	IRQ5F	IRQ4F	IRQ3F	IRQ2F	IRQ1F	IRQ0F
Initial value Read/Write	0	0	0 R/(W)*	0 R/(W)*	0 R/(W)*	0 R/(W)*	0 R/(W)*	0 R/(W)*

IRQ5 to IRQ0 flags

Bits 5 to 0	Setting and Clearing Conditions
IRQ5F to IRQ0F	Setting and Cleaning Conditions
	[Clearing conditions]
	• Read IRQnF when IRQnF = 1, then write 0 in IRQnF.
0	IRQnSC = 0, IRQn input is high, and interrupt exception
	handling is being carried out.
	IRQnSC = 1 and IRQn interrupt exception handling is being
	carried out.
	[Setting conditions]
1	IRQnSC = 0 and IRQn input is low.
	IRQnSC = 1 and IRQn input changes from high to low.

(n = 5 to 0)

Note: * Only 0 can be written, to clear the flag.

IPRA—Interrupt Priority Register A H'EE018 **Interrupt Controller** Bit 7 6 5 3 0 IPRA7 IPRA6 IPRA5 IPRA4 IPRA3 IPRA2 IPRA1 IPRA0 Initial value 0 0 0 0 0 0 R/W R/W Read/Write R/W R/W R/W R/W R/W R/W

Priority level A7 to A0

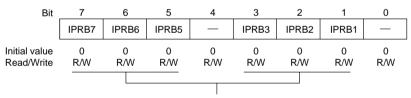
0 Priority level 0 (low priority)
1 Priority level 1 (high priority)

• Interrupt sources controlled by each bit

	Bit	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
	DIL	IPRA7	IPRA6	IPRA5	IPRA4	IPRA3	IPRA2	IPRA1	IPRA0
IPRA		IRQ0	IRQ1	IRQ2,	IRQ4,	WDT,	16-bit	16-bit	16-bit
	Interrupt			IRQ3	IRQ5	DRAM	timer	timer	timer
	source					interface,	channel 0	channel 1	channel 2
						A/D converter			

IPRB—Interrupt Priority Register B H'EE019 II

Interrupt Controller



Priority level B7 to B5, B3 to B1

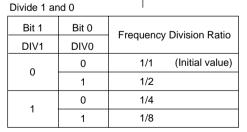
0	Priority level 0 (low priority)
1	Priority level 1 (high priority)

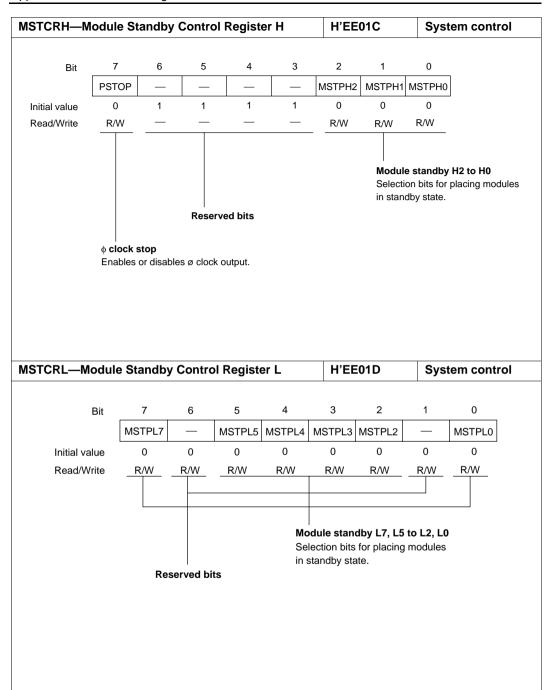
• Interrupt sources controlled by each bit

Bit 0
_
_

DASTCR—D)/A Stan	dby Cont	rol Regis	ter		H'EE0	1A	D/A		
Bit	7	6	5	4	3	2	1	0		
		_			_	_	_	DASTE		
Initial value Read/Write	<u>1</u>	<u>1</u>	<u>1</u>	<u>1</u>		<u>1</u>	<u>1</u>	0 R/W		
			D/A standb	oy enable						
			0 D/A	output is	disabled ir	software	standby m	node (Ir	nitial value	
			1 D/A	output is	enabled in	software	standby m	ode		

DIVCR—Divis	ion Con	trol Regi	ster		H'EE01B		System control		
Bit	7	6	5	4	3	2	1	0	
	_	_	_	_	_	_	DIV1	DIV0	
Initial value Read/Write	1	1_	1	1	1	1	0 R/W	0 R/W	



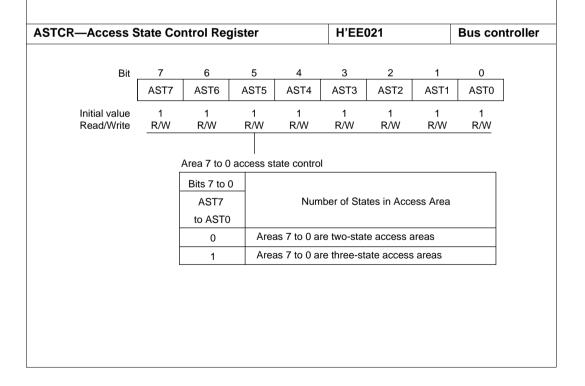


ADRCR—A	H'l	EE01E	01E Bus controller							
Bit	7	6	5	4	3		2		1	0
	_	_	_	_	-		_	-	_	ADRCTL
Initial value	1	1	1	1	1		1		1	1
Read/Write	_	_	_	_	_		_	-	_	R/W
										$\overline{}$
			!	Reserved b	its			_	A	ddress control
									mo	ts address update de 1 or address odate mode 2.

ADRCTL	Description
0	Address update mode 2 is selected
1	Address update mode 1 is selected (Initial value)

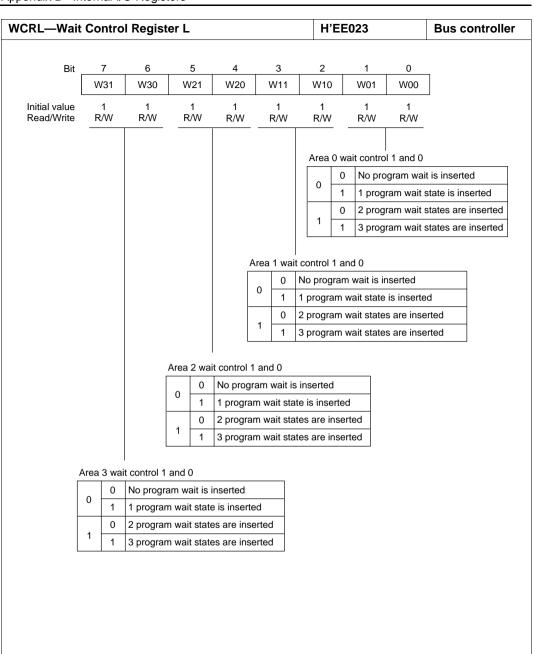
R—Chip Selec	t Contr	H'E	E01F	Bu	Bus controller						
Bit	7	6	5	4	3	2	1	0			
	CS7E	CS6E	CS5E	CS4E	_	_	_	_			
Initial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W	1	1	1	1_			
	r	Chip selec	t 7 to 4 ena	able							
	_	Bit n		Description							
		CSnE	Безсприот								
	•	0	Output o	f chip sele	ct signal C	Sn is disal	bled (Initia	l value)			
	-	1	Output o	f chip sele	ct signal C	Sn is enab	oled				
	L	(n = 7 to 4)									
		(11 = 7 to 4)	·)								

BWCR—Bus W	idth Contr	ol Regis	ster		H'EE	Bus controlle			
	Bit	7	6	5	4	3	2	1	0
		ABW7	ABW6	ABW5	ABW4	ABW3	ABW2	ABW1	ABW0
Modes 1, 3, 5, 6, 7 Modes 2, 4	Initial value Initial value Read/Write	1 0 R/W	1 0 R/W Area 7 to 0	1 0 R/W	1 0 R/W	1 0 R/W	1 0 R/W	1 0 R/W	1 0 R/W
			Bits 7 to 0 ABW7 to ABW0	-		Bus Width	of Access	s Area	
			0	Area	as 7 to 0 a	re 16-bit a	ccess area	ıs	
			1	Area	as 7 to 0 a	re 8-bit ac	cess areas	;	

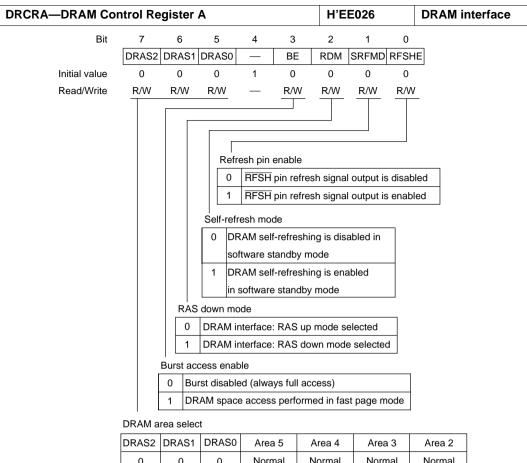


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RH—Wait	Contro	l Regis	ter H				H'EE	022	Bus	controlle
Bit	7	6	5	4	3	2	1	0		
2	W71	W70	W61	W60	W51	W50	W41	W40		
Initial value Read/Write	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W		
					Area 5 v 0 0 1 1 0 1	vait contro No progra 1 progra 2 progra	No pro 1 1 pro 0 2 pro 1 3 pro 1 1 and 0 ram wait is m wait sta		ait is inset state is a state sat states a state	
			Area 6 v		gram wai	t is inserte				
			1 0	2 progra	am wait	states are states are	inserted			
	Area 7 v	 vait contro	nl 1 and 0	1						
	0 0	No prog	ram wait s	is inserte						
	1 0	2 progra	am wait s am wait s	tates are	inserted	1				



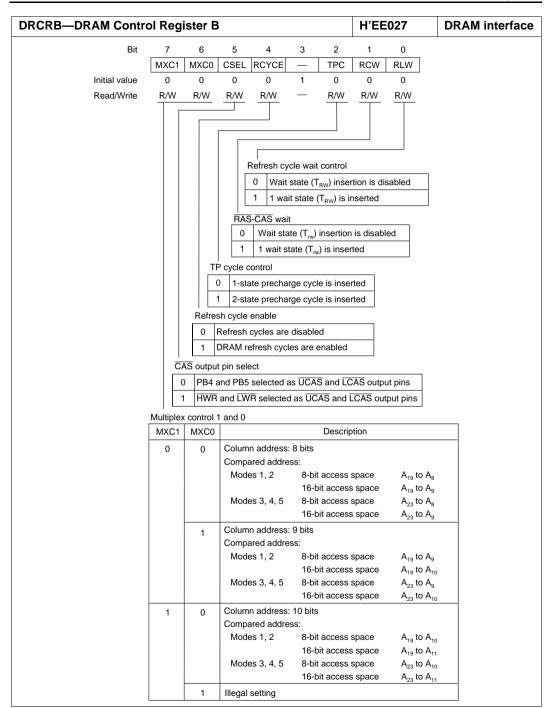
ock—bus	Contro	ol Regis	ter				H'EI	E024	Bus controlle	er:
Bit	7	6	5	4	3	2	1	0	1	
	ICIS1	ICIS0	BROME	BRSTS1	BRSTS0	_	RDEA	WAITE		
nitial value Read/Write	1 R/W	1 R/W	0 R/W	0 R/W	0 R/W	<u>1</u>	1 R/W	0 R/W		
							w	ait pin ena	able	
								0 WAIT	pin wait input is disa	ıble
								1 WAIT	pin wait input is ena	ble
								'		
							a division u			
						0			as follows: rea 4: 1.93 MB	
									rea 5: 4 kB	
									rea 6: 23.75 kB	
							Area 3:	2 MB A	rea 7: 22 B	
						1	Areas 0 t	o 7 are the	e same size	
							(2 MB)			
					Burst cycle	select 0				
					0 Max.	4 words	in burst ac	cess		
					1 Max.	8 words	in burst ac	cess		
				_						
				Burst cycl						
					st access cy					
				1 Burs	st access cy	cie comp	orises 3 sta	ites		
			Burst RO	M enable						
			0 Are	a 0 is a ba	sic bus inter	face are	a			
			1 Are	a 0 is a bu	rst ROM inte	erface ar	rea			
	Idle	e cycle ins	ertion 0							
	0	No idle	cycle is in:	serted in c	ase of conse	cutive e	external rea	nd and writ	e cycles	
	1	Idle cy	cle is insert	ed in case	of consecut	ive exte	rnal read a	nd write c	ycles	
									<u></u>	
lo	dle cycle i	nsertion 1								
	0 No id	lle cycle is	inserted in	case of c	onsecutive e	xternal	read cycles	for differe	ent areas	
	1 Idle o	مرز ما مامر	serted in ca	oo of oone	a austinua austa					



DRAS2	DRAS1	DRAS0	Area 5	Area 4	Area 3	Area 2		
0	0	0	Normal	Normal	Normal	Normal		
		1	Normal	Normal	Normal	DRAM space		
						(\overline{CS}_2)		
	1	0	Normal	Normal	DRAM space	DRAM space		
					(\overline{CS}_3)	(\overline{CS}_2)		
		1	Normal	Normal	DRAM sp	ace(CS ₂)*		
1	0	0	Normal	DRAM space	DRAM space	DRAM space		
				(\overline{CS}_4)	$(\overline{CS}_{3)}$	(\overline{CS}_2)		
		1	DRAM space	DRAM space	DRAM space	DRAM space		
			($\overline{\text{CS}}_5$)	(\overline{CS}_4)	(\overline{CS}_3)	(\overline{CS}_2)		
	1	0	DRAM space(\overline{CS}_4)* DRAM space(\overline{CS}_2)					
		1	DRAM space($\overline{\text{CS}}_2$)*					

Note: * A single $\overline{\text{CSn}}$ pin serves as a common $\overline{\text{RAS}}$ output pin for a number of areas. Unused $\overline{\text{CSn}}$ pins can be used as input/output ports.





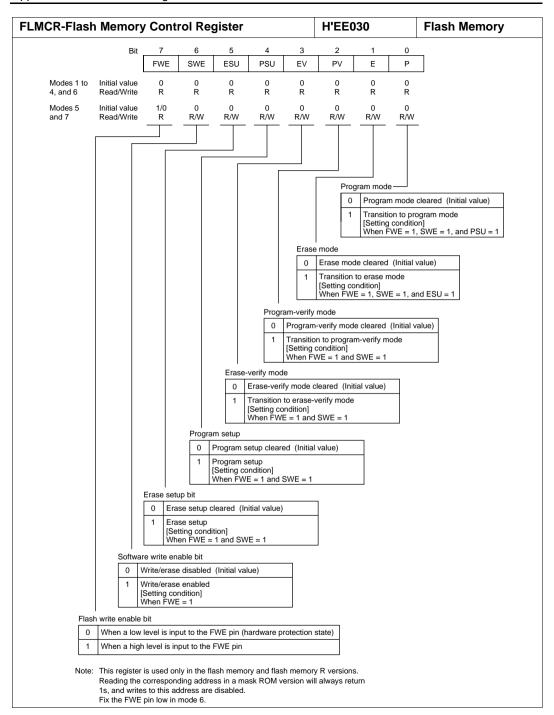
CSR—Refresh	Timer	Contro	I/Statu	s Regist	er	H'EE028	DRAM interfa			
Bit	7	6	5	4	3	2 1	0			
	CMF	CMIE	CKS2	_	CKS0					
Initial value	0	0	0	0	0	1 1	1			
Read/Write	R/(W)*	R/W	R/W	R/W	R/W					
		F	Refresh	counter cl	ock seled	et				
			CKS2	CKS1	CKS0	Descrip	otion			
			0	0	0	Count operation hal	ted			
					1		clock			
				1	0	φ/8 used as counter	clock			
				-	1		er clock			
			1	0	0		ter clock			
				-	1	∮/512 used as coun	ter clock			
				1	0	∮/2048 used as cou	nter clock			
				-	1	φ/4096 used as cou	nter clock			
	C	ompare	match i	nterrupt e	nable					
		0 T	he CMI	interrupt	requeste	d by the CMF flag is o	disabled			
						d by the CMF flag is e				
C	∟ ompare n			· ·		, ,				
		learing o		iel						
	ا ا	Ū		-	ctandby	modo				
		Cleared by a reset and in standby mode								
		• Cleared by reading CMF when CMF = 1, then writing 0 in CMF [Setting condition]								
	1 1									
		When RTCNT = RTCOR								
No	te: Only (can be	written to	clear the f	lag.					

RTCNT—Refresh Time	H'EE029		DRA	M interface					
Bit	7	6	5	4	3	2	1	0	1
Initial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	
incad willo	1000		ncremen	ted by in	ternal clo	ock selec		10,00	

RTCOR—Refresh Tim	02A	DRA	M interface						
Bit	7	6	5	4	3	2	1	0	
Initial value	1	1	1	1	1	1	1	1	
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	

RTCNT compare match period

Note: Only byte access can be used on this register.



EBR-Erase	Block Regis	ster	EBR-Erase Block Register H'								
	Bit EBR	7 EB7	6 EB6	5 EB5	4 EB4	3 EB3	2 EB2	1 EB1	0 EB0		
Modes 1 to 4, and 6	Initial value Read/Write	0 R	0 R	0 R	0 R	0 R	0 R	0 R	0 R		
Modes 5 and 7	Initial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W		
		Bloc	ck 7 to 0								
		0	Block E	EB7 to EB0) is not sel	ected (In	itial value	e)			
		1	Block E	B7 to EB0) is selecte	ed					

Note: When not erasing flash memory, EBR should be cleared to H'00.

Note: This register is used only in the flash memory and flash memory R versions. Reading the corresponding address in a mask ROM version will always return 1s, and writes to this address are disabled.

P2PCR—Port 2 I	nput Pull	-Up Con	trol Regi	ster		H'EE030	C	Port 2		
Bit	7	6	5	4	3	2	1	0		
	P27PCR	P26PCR	P25PCR	P24PCR	P23PCR	P22PCR	P21PCR	P20PCR		
Initial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W		
		P	ort 2 input	pull-up co	ntrol 7 to 0)				
			0 Input	oull-up trar	nsistor is o	ff				
			1 Input	oull-up trar	nsistor is o	n				
	Note: Valid when the corresponding P2DDR bit is cleared to 0									

Note: Valid when the corresponding P2DDR bit is cleared to 0 (designating generic input).

R—Port 4 I	nput Pull	H'EE03E	Port 4					
Bit	7	6	5	4	3	2	1	0
	P47PCR	P46PCR	P45PCR	P44PCR	P43PCR	P42PCR	P41PCR	P40PCR
Initial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W
		Po	ort 4 input	pull-up cor	ntrol 7 to 0			
		() Input p	ull-up tran	sistor is of	f		
		1	Input p	ull-up tran	sistor is or	1		
		Not	e: Valid w	then the co	orreenondi	na PADDR	hit is clas	red to 0

Note: Valid when the corresponding P4DDR bit is cleared to 0 (designating generic input).

CR—Port 5	Input Pu	H'EE03	F	Port 5				
Bit	7	6	5	4	3	2	1	0
		_	_	_	P53PCR	P52PCR	P51PCR	P50PCR
Initial value Read/Write	<u>1</u>	<u>1</u>	<u>1</u>	<u>1</u>	0 R/W	0 R/W	0 R/W	0 R/W
				0	input pull-u nput pull-u nput pull-u	p transisto	r is off	
					/alid when cleared to 0			5DDR bit is input).

RAM Co	ntrol Register	,	RAMCR	R H'EE077			FI	ash Mem	ory
	Bit	7	6	5	4	3	2	1	0
		_	_	_	_	RAMS	RAM2	RAM1	_
Modes 1 to 4	Initial value R/W	1	1	1	1	0 R	0 R	0 R	1 —
Modes 5 to 7	Initial value R/W	1	1	1	1	0 R/W*	0 R/W*	0 R/W*	1
			Reser	ved bits					

RAM select, RAM2, RAM1

Bit 3	Bit 2	Bit 1	RAM Area	RAM Emulation Status
RAMS	RAM2	RAM1		KAIVI EIIIUIALIOIT Status
0	0/1	0/1	H'FFF000 to H'FFF3FF	No emulation
1	0	0	H'000000 to H'0003FF	Mapping RAM
		1	H'000400 to H'0007FF	
	1	0	H'000800 to H'000BFF	
		1	H'000C00 to H'000FFF	

Note: * In mode 6 (single-chip normal mode), flash memory emulation by RAM is not supported; these bits can be modified, but must not be set to 1.

Note: This register is used only in the flash memory and flash memory R versions. Reading the corresponding address in a mask ROM version will always return 1s, and writes to this address are disabled.

FLMSR-Flas	h Memory	/ Status I	Register		H'E	€07D	Flas	Flash Memor		
Bit	7	6	5	4	3	2	1	0		
	FLER	_	_	_	_	_	_			
Initial value	0	1	1	1	1	1	1	1		
R/W	R	_		_	_	_	—			
				R	leserved	bits				

RAM select, RAM2, RAM1

Bit 7	Description
FLER	Description
0	Flash memory program/erase protection (error protection) is disabled (Initial value) [Clearing condition] WDT reset, reset via the RES pin or hardware standby mode
1	An error has occurred during flash memory programming/erasing, and error protection*1 is enabled [Setting conditions] 1. Flash memory was read*2 while being programmed or erased (including vector or instruction fetch, but not including reading of a RAM area overlapped onto flash memory). 2. A hardware exception-handling sequence (other than a reset, invalid instruction, trap instruction, or zero-divide exception) was executed just before programming or erasing.*3 3. The SLEEP instruction (including software standby mode) was executed during programming or erasing.

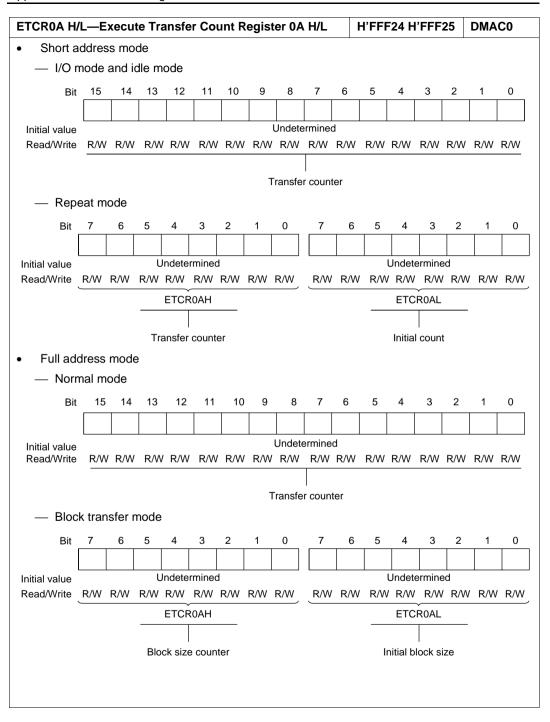
- Notes 1. See 18.6.3, Error Protection, for details.
 - 2. The read value in this case is undefined.
 - 3. Before stack and vector read by exception handling.

Note: This register is used only in the flash memory and flash memory R versions. Reading the corresponding address in a mask ROM version will always return 1s, and writes to this address are disabled.



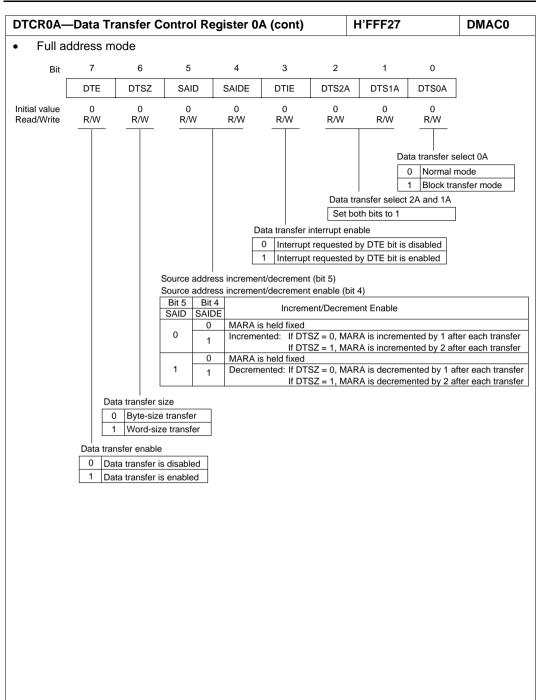
/IAROA R/E	E/H/L-	-Mei	mory	Add	ress	Regi	ster (A R/	E/H/L	•	H'FF H'FF				DMA	AC0
Bit	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Initial value	1	1	1	1	1	1	1	1				Undet	ermine	ed		
Read/Write	_	_	_	_	_	_	_		R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
				MAR	0AR							MAI	Ř0AE			
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value				Undet	ermine	ed e						Undet	ermine	ed		
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
				MAR	0AH							MA	R0AL			

Source or destination address



IOAR0A—I/C) Address	s Register	0A			H'FFF26		DMAC0
Bit	7	6	5	4	3	2	1	0
Initial value		•	•	Undete	rmined	'		'
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
				node : sourc		nation address		

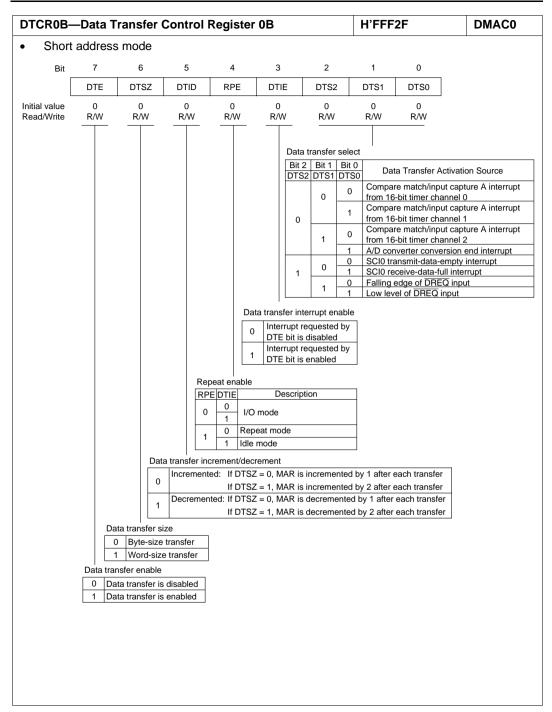
TCR0A—	-Data Tr	anster C	ontrol R	egister	UA			пгг	F27		DMAC0
Short a	address	mode									
Bit	7	6	5	4	3		2		1	0	
	DTE	DTSZ	DTID	RPE	DTIE		DTS2	D	TS1	DTS0	
nitial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	_	0 R/W	F	0 R/W	0 R/W	
					0	Bit 2 DTS2 0 1 er inter upt req	0 1 0 1	Bit 0 DTS0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	Compa nterrup Compa nterrup Compa nterrup A/D cor SCI0 tr SCI0 re	ore match/inp bot from 16-bit ire match/inp bot from 16-bit ire match/inp bot from 16-bit inverter conve	timer channel 0 ut capture A timer channel 1 ut capture A timer channel 2 rsion end interrupt empty interrupt ull interrupt ess mode
					1 DTE		uested	ру			
				peat enabl		scription	nn .				
			0	0	O mode	00	<u> </u>				
				0 R	epeat mod	е					
				1 ld	le mode						
		Da 0	Incremen	ted: If DT	SZ = 0, MA					each transfe	
		1	Decremen	nted: If DT	SZ = 0, MA	AR is d	ecreme	nted by	1 after	r each transfer r each transfer	er
	Da	ta transfer s	ize								
			e transfer e transfer								
	Data trai	nsfer enable ta transfer i ta transfer i	s disabled	1							



Appendix B	Intern	nal I/C) Reg	isters	3											
MAR0B R/E	E/H/L-	-Mei	mory	Add	ress	Regi	ster (B R/	E/H/L				FFF2 FFF2		DMA	C0
Bit	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Initial value	1	1	1	1	1	1	1	1				Undet	ermine	ed		
Read/Write	_	_	_	<u> </u>	_	_	_	_	R/W	R/W	R/W		~	R/W	R/W	R/W
				MAR	0BR							MA	R0BE			
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
				l lo dot	ermine	٠ ما						ا امامه	ermine			
Initial value Read/Write	R/W	R/W					R/W	R/W	R/W	R/W					R/W	R/W
				MAR	0BH							MA	R0BL			
						_										
						Sc	ource o	or dest	ination	n addre	ess					

ETCR0B H/	L—E	xecut	e Tra	nsfe	r Cou	ınt R	egist	er 0B	H/L		FFF2 FFF2			I	DMAC	0
Short act	ddres	s mo	de											,		
— I/O m	node a	and ic	dle mo	ode												
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
		T			···			Γ						_		$\overline{}$
Initial value							l	⊥ Undete	ermine	l d						
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W		R/W			R/W	R/W	R/W	R/W	R/W	R/W
																-
							Т	ransfe	r coun	ter						
— Repe	eat mo	ode														
Bit	7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
Initial value	•	•			mined		•						ermine			
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
				ETCR	0BH							ETC	R0BL			
			Tra	nsfer	counte	r						Initia	l coun	t		
E. II - II																
Full add)													
— Norm	nai mo	oae														
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value								Undete								
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
									١.							
								Not	used							
— Block	tran	cfor n	aada													
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	D 4 · ·	D 44:	5 44.	D 44:	D. 0.4.	5.44		Undete			D 44:	D 44:	D.44:	D 04:	D 0.4.	D 444
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
							Di.	.l. 4		4						
							RIO	ck trans	sier co	unter						

AR0B—I/O	Address	s Register	0B			H'FFF2E		DMAC0	
Bit	7	6	5	4	3	2	1	0	
nitial value					ermined				
ead/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
				ode : source le : not use		ation address			



DTCR0B—Data Transfer Control Register 0B (cont) H'FFF2F DMAC0 Full address mode 7 5 3 Bit 6 4 2 0 DTME DAID DAIDE TMS DTS2B DTS1B DTS0B Initial value 0 0 0 0 0 0 Read/Write R/W R/W R/W R/W R/W R/W R/W R/W Data transfer select 2B to 0B Data transfer master enable Bit 2 Bit 1 Bit 0 Data Transfer Activation Source Data transfer is disabled DTS2B DTS1B DTS0B Normal Mode Block Transfer Mode Data transfer is enabled Compare match/input Auto-request capture A interrupt from (burst mode) 16-bit timer channel 0 0 Not available Compare match/input capture A interrupt from 0 16-bit timer channel 1 Compare match/input Auto-request 1 capture A interrupt from (cycle-steal mode) 16-bit timer channel 2 A/D converter conversion Not available end interrupt Not available Not available 0 Not available Not available 1 Falling edge input of Falling edge input of 1 DREO DREQ Low level input at DREQ Not available Transfer mode select 0 Destination is the block area in block transfer mode Source is the block area in block transfer mode Destination address increment/decrement (bit 5) Destination address increment/decrement enable (bit 4)

Bit 4	Increment/Decrement Enable
DAIDE	increment/decrement chable
0	MARB is held fixed
1	Incremented: If DTSZ = 0, MARB is incremented by 1 after each transfer
'	If DTSZ = 1, MARB is incremented by 2 after each transfer
0	MARB is held fixed
1	Decremented: If DTSZ = 0, MARB is decremented by 1 after each transfer
·	If DTSZ = 1, MARB is decremented by 2 after each transfer
	DAIDE 0

MAR1A R/E	E/H/L-	-Me	mory	Add	ress	Regi	ster '	1A R/	E/H/L	•	H'FF H'FF				DMA	AC1
Bit	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Initial value	1	1	1	1	1	1	1	1				Undet	ermine	ed		
Read/Write	_	_	_	_	_	_	_	—	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
				MAR	1AR							MA	R1AE			
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value				Undet	ermine	ed						Undet	ermine	ed	•	
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
				MAR	1AH							MA	Ř1AL			
Note: Bit	t functi	ons ar	e the s	same a	as for	DMAC	0.									
								ter 1	Δ H/I		H'FF	F34 I	H'FFF	-35	DM4	\C1
								ter 1 <i>l</i>	A H/L		H'FF	F34 I	H'FFF	F35	DMA	AC1
								ter 1 /	A H/L	6	H'FF	F34 I	H'FF	-35	DM 2	AC1
ETCR1A H/	L—E	xecu	te Tra	ansfe	er Co	unt R	egis			6						
Bit Initial value	/L—E	xecu	13	ansfe	er Co	unt R	gegis	8 Jndete	7 rmined	1	5	4	3	2	1	0
Bit Initial value	/L—E	xecu	13	ansfe	er Co	unt R	gegis	8 Jndete	7 rmined	1	5	4	3	2	1	0
ETCR1A H/ Bit	/L—E	xecu	13	ansfe	er Co	unt R	gegis	8 Jndete	7 rmined	1	5	4	3	2	1	0
Bit Initial value Read/Write	/L—E 15 R/W	14 R/W	13 R/W	12 R/W	11 R/W	10 R/W	9 L R/W	8 Jndete R/W	7 ermined R/W	i R/W	5 R/W	4 R/W	3 R/W	2 R/W	1 R/W	0 R/W
Bit Initial value Read/Write	/L—E 15 R/W	14 R/W	13 R/W	12 R/W	11 R/W	unt R 10 R/W	9 L R/W	8 Jndete R/W	7 ermined R/W	i R/W	5 R/W	4 R/W	3 R/W	2 R/W	1 R/W	0 R/W
Bit Initial value Read/Write	/L—E 15 R/W 7	14 R/W	13 R/W	12 R/W 4	11 R/W	unt R 10 R/W	9 L R/W	Jndete R/W	7 rmined R/W	R/W	5 R/W	4 R/W	3 R/W 3	2 R/W 2	1 R/W	0 R/W

Note: Bit functions are the same as for DMAC0.

IOAR1A—I/C	Address	Register	1A			H'FFF36		DMAC1
Bit	7	6	5	4	3	2	1	0
Initial value Read/Write	R/W	R/W	R/W	Undete R/W	ermined R/W	R/W	R/W	R/W
Note: Bit fu	unctions are	the same a	s for DMAC	D.				

DTCR1A—D	ata Trans	fer Contro	l Registe	r 1A		H'FFF37		DMAC1
 Short ad 	ldress mod	de			,		,	
Bit	7	6	5	4	3	2	1	0
	DTE	DTSZ	DTID	RPE	DTIE	DTS2	DTS1	DTS0
Initial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W
 Full add 	ress mode							
Bit	7	6	5	4	3	2	1	0
	DTE	DTSZ	SAID	SAIDE	DTIE	DTS2A	DTS1A	DTS0A
Initial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W
Note: Bit	functions ar	e the same a	as for DMAC	0.				



MAR1B R/	E/H/L	—Ме	mory	Add	ress	Regi	ster '	1B R/	E/H/L				FFF3		DMA	C1
Bit	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Initial value	1	1	1	1	1	1	1	1	1			Undet	ermine	ed		
Read/Write	_	_	_	_	_	_	_	_	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
				MAR	1BR							MA	R1BE			
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value				Undet	ermine	ed						Undet	ermine	ed		
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
				MAR	1BH							MA	Ř1BL			
Note: Bi	t functi	ons ar	e the	same a	as for I	DMAC	0.									
Note: Bi								ter 1E	3 H/L	Н	'FFF:	BC H	FFF3	BD	DMA	C 1
								ter 1E	3 H/L	Н	'FFF:	зс н	FFF3	BD	DMA	C1
								ter 1E	3 H/L	H	' FFF :	3 C H	' FFF3	BD 2	DMA	C1
ETCR1B H	/L—E	xecu	te Tr	ansfe	er Co	unt R	egis									
ETCR1B H	/L—E	xecu	te Tr	ansfe	er Co	unt R	egis	8		6						
ETCR1B H	/L—E	14	te Tr	ansfe	er Co	unt R	gegis	8 Jndete	7 rmined	6	5	4	3	2	1	0
ETCR1B HA	/L—E	14	te Tr	ansfe	er Co	unt R	gegis	8 Jndete	7 rmined	6	5	4	3	2	1	0
ETCR1B HA	/L—E	14	te Tr	ansfe	er Co	unt R	gegis	8 Jndete	7 rmined	6	5	4	3	2	1	0
Bit Initial value Read/Write	/L—E	14 R/W	13 R/W	12 R/W	11 R/W	10 R/W	9 L R/W	8 Jndete R/W	7 ermined R/W	6 d R/W	5 R/W	4 R/W	3 R/W	2 R/W	1 R/W	0 R/W
Bit Initial value Read/Write	/L—E	14 R/W	13 R/W	12 R/W	11 R/W	10 R/W	9 L R/W	8 Jndete R/W	7 ermined R/W	6 d R/W	5 R/W	4 R/W	3 R/W	2 R/W	1 R/W	0 R/W
Bit Initial value Read/Write	/L—E	14 R/W 6	13 R/W	ansfe 12 R/W 4	11 R/W	10 R/W	9 L R/W	8 Jndete R/W	7 rmined R/W	6 R/W	5 R/W	4 R/W	3 R/W 3	2 R/W 2	1 R/W	0 R/W

Note: Bit functions are the same as for DMAC0.

IOAR1B—I/O	O Address	s Register	1B			H'FFF3E		DMAC1
Bit	7	6	5	4	3	2	1	0
Initial value				Undete	rmined			
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

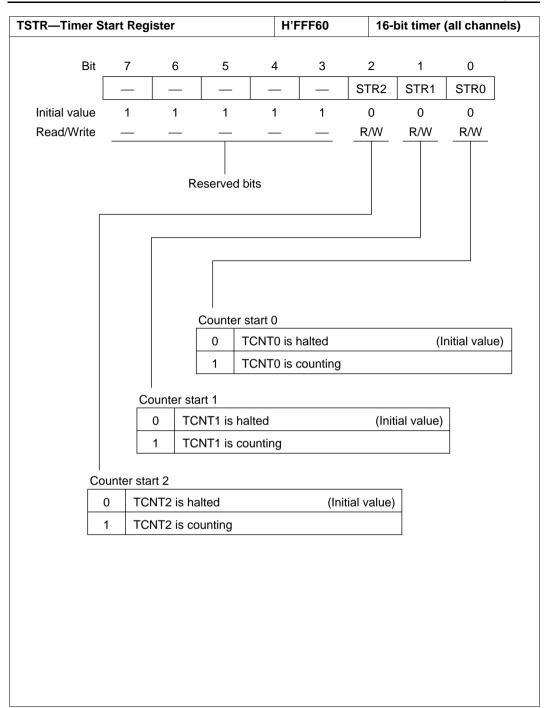
Note: Bit functions are the same as for DMAC0.

DTCR1B—D	ata Trans	fer Contro	l Registe	r 1B		H'FFF3F		DMAC1
Short ad	ldress mod	de					,	
Bit	7	6	5	4	3	2	1	0
	DTE	DTSZ	DTID	RPE	DTIE	DTS2	DTS1	DTS0
Initial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W
Full add	ress mode							
Bit	7	6	5	4	3	2	1	0
	DTME	_	DAID	DAIDE	TMS	DTS2B	DTS1B	DTS0B
Initial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W

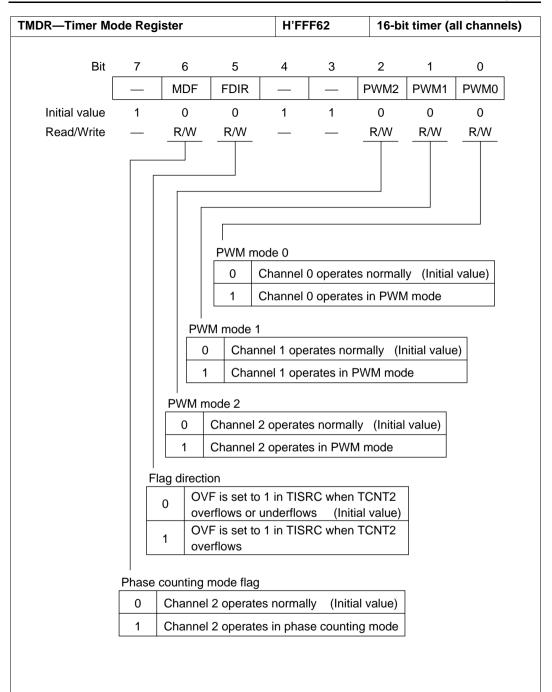
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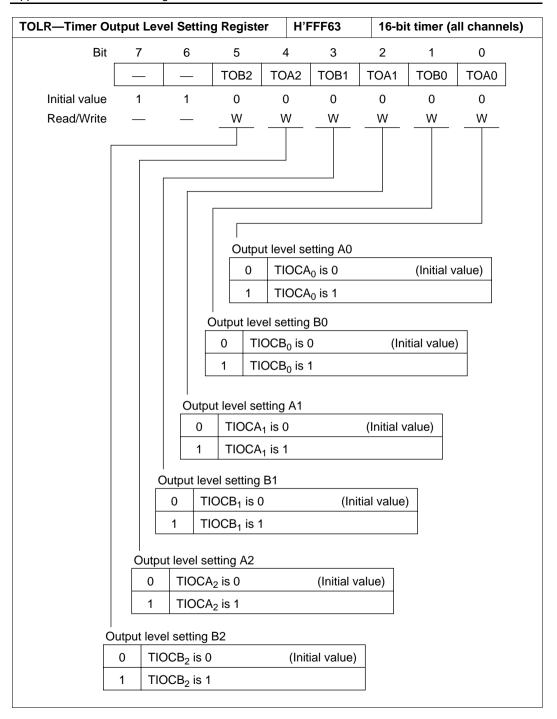
Note: Bit functions are the same as for DMAC0.

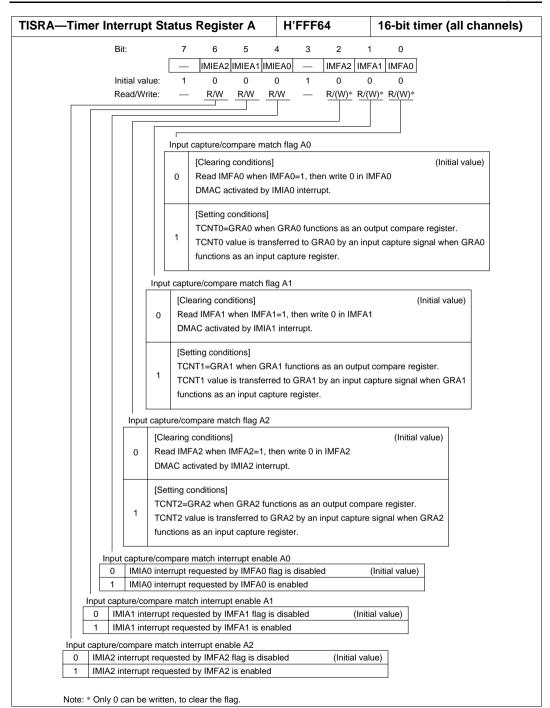


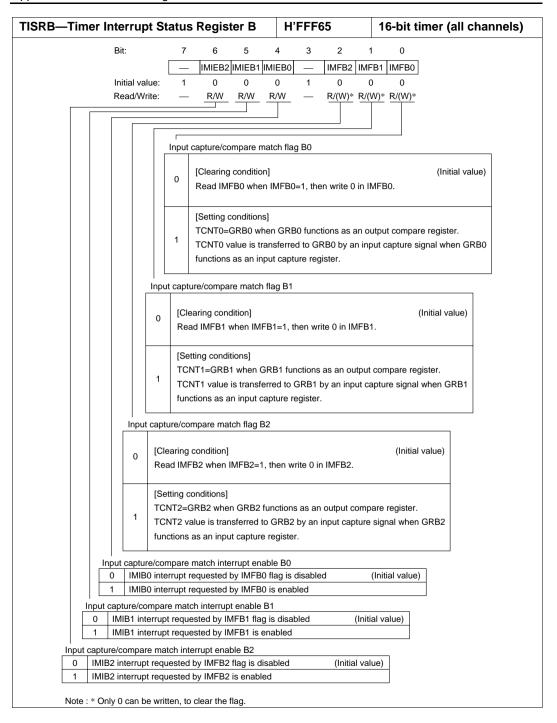


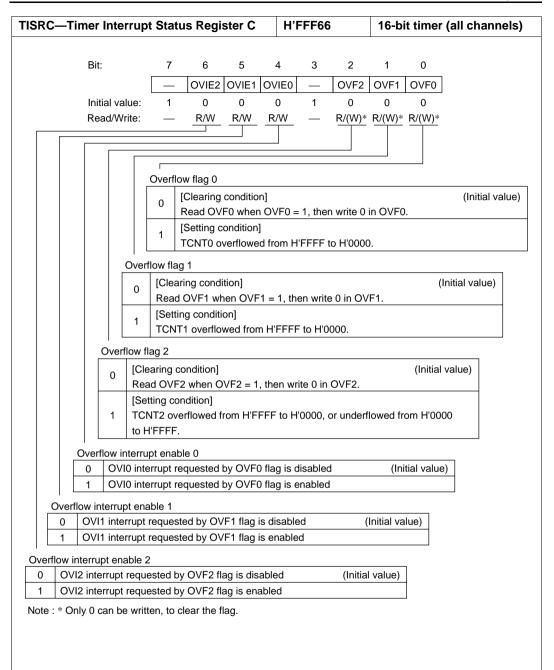
SNC—Timer	Synchro	Register	•	H'l	FFF61	16	-bit timer	(all channels)			
Bit	7	6	5	4	3	2	1	0			
			_	_		SYNC2	SYNC1	SYNC0			
Initial value	1	1	1	1	1	0	0	0			
Read/Write						R/W	R/W	R/W			
		R	eserved t	oits							
			Timer s	ynchroniz		ounter (T	CNTO) on	orotoo			
			0	independ unrelated	ently (TO to other	CNT0 pres					
			1	Channel of TCNT0 syclearing is	ynchrono	ous prese	onously tting/sync	hronous			
	- -										
		Cha 0 ind	ependent	mer count ly (TCNT	l presett	ing/clearir					
	unrelated to other channels) (Initial value) Channel 1 operates synchronously TCNT1 synchronous presetting/synchronous clearing is possible										
l Tiı	mer syncl	nronizatio	n 2								
	Cha 0 inde	annel 2 tii ependent	mer coun	ter (TCNT 2 presettir innels)	ng/clearii						
	1 TCI		hronous	ynchronoi presetting		nous					











0—111	mer Con	trol Reg	ister			H'FFF68		16-bit t	imer chan	nel 0
	Bit	7	6	5	4	3	2	1	0	
			CLR1	CCLR0	CKEG1		TPSC2	TPSC1	TPSC0	
Initi	∟ al value	1	0	0	0	0	0	0	0	
	ad/Write	<u> </u>	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
			prescaler		* 0					
		Bit 2			sco		TCN	Γ Clock So	urce	
			0		0 I	Internal cloc			(Init	tial value
		0	_			Internal cloc	- '			
			1			Internal cloc Internal cloc	<u> </u>			
			0	-		External clo				
		1				External clo				
			1			External clo External clo		•		
	Clock ed Bit 4 CKEG1 0 0	ge 1 and 0 Bit 3 CKEG0 0 1	Falling	edges co edges cou	ounted ounted	unted Edges	of Extern		tial value)	
ounter of Bit 6	clear 1 and Bit 5 CCLR0	0			TCNT cl	ear Sources	 S			
Bit 6	Bit 5 CCLR0	TCNT is	not clear	ed			(Initi	al value)		
Bit 6 CCLR1	Bit 5 CCLR0	TCNT is	cleared b	ed by GRA c	ompare r	ear Sources match or inp	(Initiout capture	•		

Bit: 7 6 5 4 3 2 1 0 — IOB2 IOB1 IOB0 — IOA2 IOA1 IOA0 Initial value: 1 0 0 0 1 0 0 0 Read/Write: — R/W R/W R/W - R/W R/W R/W	0—Timer I/O C	ontrol	Regist	ter 0		H'FF	F69		16-bit ti	mer channel (
Initial value: 1 0 0 0 1 0 0	Bit:	7	6	5	4	3	2	1	0	
		_	IOB2	IOB1	IOB0	_	IOA2	IOA1	IOA0	
Read/Write:	Initial value:	1	0	0	0	1	0	0	0	
	Read/Write:	_	R/W	R/W	R/W	_	R/W	R/W	R/W	
			-							-

I/O control A2 to A0

Bit 2	Bit 1	Bit 0		GRA Functions
IOA2	IOA1	IOA0		GRA FUNCTIONS
	0	0	GRA is an output	No output at compare match (Initial value)
	U	1	compare register	0 output at GRA compare match
0		0		1 output at GRA compare match
	1	1		Output toggles at GRA compare match (channel 2 only: 1 output)
	_	0	GRA is an input	GRA captures rising edges of input
1	0	1	capture register	GRA captures falling edges of input
'		0		GRA captures both edges of input
	1	1		

I/O control B2 to B0

Bit 6	Bit 5	Bit 4		GRB Functions
IOB2	IOB1	IOB0		GRB Functions
	0	0	GRB is an output	No output at compare match (Initial value)
	0	1	compare register	0 output at GRB compare match
0		0		1 output at GRB compare match
	1	1		Output toggles at GRB compare match (channel 2 only: 1 output)
	_	0	GRB is an input	GRB captures rising edges of input
1	0	1	capture register	GRB captures falling edges of input
'		0		GRB captures both edges of input
	1	1		

TCNT0 H/L	—Tin	ner C	ounte	er 0 H	I/L			H'FF	F6A,	H'FFI	F6B	16-	bit tir	ner c	hann	el 0
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
							ι	Jp - c	ounte	r						
								•								

GRA0 H/L-	-Gen	eral F	Regis	ter A	0 H/L	•		H'FF	F6C,	H'FF	F6D	16-	bit tir	ner c	hann	el 0
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	1	1	1		1	1	1	1	1	1			4	1	4	
Initial value Read/Write	R/W	R/W	R/W	R/W	•	R/W	•	'	'	'	R/W	R/W	R/W	R/W	R/W	R/W

Output compare or input capture register

GRB0 H/L-	-Gen	eral i	Regis	ter B	0 H/L			H'FF	F6E,	H'FFI	F6F	16-	bit tir	ner c	hann	el 0
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Output compare or input capture register

TCR1 Timer Contr	ol Regis	ter 1		H'FF	F70		16-bit ti	mer char	nnel 1
Bit	7	6	5	4	3	2	1	0	
	_	CCLR1	CCLR0	CKEG1	CKEG0	TPSC2	TPSC1	TPSC0	
Initial value	1	0	0	0	0	0	0	0	
Read/Write	_	R/W	R/W	R/W	R/W	R/W	R/W	R/W	

^{*} Bit functions are the same as for 16-bit timer channel 0.

TIOR1—Timer I/O	Control	Register	1	H'FF	F71		16-bit t	imer chann	el 1
Bit	7	6	5	4	3	2	1	0	
		IOB2	IOB1	IOB0	_	IOA2	IOA1	IOA0	
Initial value	1	0	0	0	1	0	0	0	
Read/Write		R/W	R/W	R/W	_	R/W	R/W	R/W	

^{*} Bit functions are the same as for 16-bit timer channel 0.

TCNT1 H/L	—Tin	ner C	ounte	er 1 H	/L			H'FF	F72, I	H'FFF	73	16-	bit tin	ner c	hann	el 1
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

^{*} Bit functions are the same as for 16-bit timer channel 0.

GRA1 H/L-	–Gen	eral l	Regis	ster A	1 H/L	-		H'FF	F74,	H'FF	F75	16	-bit ti	mer o	chanr	nel 1
Dia	15	14	13	12	11	10	0	0	7	6	5	4	3	2	1	0
Bit	15	14	13	12	<u> </u>	10	9	0		0	5	4	<u>ي</u>		'	
Initial value	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

^{*} Bit functions are the same as for 16-bit timer channel 0.

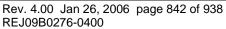
GRB1 H/L-	–Gen	eral l	Regis	ter B	1 H/L			H'FF	F76,	H'FF	F77	16-	bit ti	mer d	chani	nel 1
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	1	1	1		•	•	•	•	•	1 D/M	•	1	1	1	1	1

Bit	7	6	5	4	3	2	1	0
	_	CCLR1	CCLR0	CKEG1	CKEG0	TPSC2	TPSC1	TPSC0
Initial value	1	0	0	0	0	0	0	0
Read/Write		R/W						

H'FFF78

16-bit timer channel 2

Note: When phase counting mode is selected in channel 2, the settings of bits CKEG1 and CKEG0 and TPSC2 to TPSC0 in TCR2 are ignored.



TCR2 Timer Control Register 2

^{*} Bit functions are the same as for 16-bit timer channel 0.

^{*} Bit functions are the same as for 16-bit timer channel 0.

TIOR2—Timer I/O	Control	Register	2	H'FF	F79		16-bit ti	imer chan	nel 2
Dia	7	0	F	4	2	0	4	0	
Bit		6	5	4	3		1		
		IOB2	IOB1	IOB0		IOA2	IOA1	IOA0	
Initial value	1	0	0	0	1	0	0	0	
Read/Write	_	R/W	R/W	R/W	_	R/W	R/W	R/W	

^{*} Bit functions are the same as for 16-bit timer channel 0.

TCNT2 H/L	—Tin	ner C	ounte	er 2 H	l/L			H'FF	FF7A,	H'FF	F7B	16	-bit ti	mer o	chanr	nel 2
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Phase counting mode: up / down counter

Other mode: up - counter

GRA2 H/L-	–Gen	eral l	Regis	ster A	2 H/L	-		H'FF	F7C,	H'FF	F7D	16	-bit ti	mer (chan	nel 2
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

^{*} Bit functions are the same as for 16-bit timer channel 0.

GRB2 H/L-	-Gen	eral l	Regis	ter B	32 H/L	•		H'FF	F7E,	H'FF	F7F	16	-bit ti	mer d	chani	nel 2
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

^{*} Bit functions are the same as for 16-bit timer channel 0.



)—Timer C I—Timer C							F80 F81			t timer channel t timer channel
Bit	7	6	5	4	3		2	1	0	
	CMIEB	CMIEA	OVIE	CCLR1	CCLR	0 0	CKS2	CKS1	CKS0	
Initial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W		0 R/W	0 R/W	0 R/W	
					Clock	c sele	ct 2 to	0		
							0	Clock inp	ut is disab	led
						0	1	Internal cl edge of ϕ		ted on rising
					0	1	0	Internal cl edge of ϕ		ted on rising
							1	Internal cl edge of ϕ		ted on rising
					1	0	0	Channel 1	n TCNT1 d I:	overflow signal*
							1	External cl	ock, counte	d on falling edge
							0	External cl	ock, counte	d on rising edge
						1	1		clock, cour falling ed	ited on both
					Notes:	o\ T(in	erflow	signal and compare m nting clock	that of ch atch signa	is the TCNT1 annel 1 is the I, no ed. Do not use
				Counter c	lear 1 ar	d 0				
				0 0			s disab			
				1				are match		
				1 0				capture B	B/input ca	ipture B
			Timer o	verflow inte	-		y input	Сартите В		
							hv OVE	is disable	d	
					•			is enable		
		Compar		nterrupt en			•			
				rupt reque		CMF	A is dis	abled		
				rupt reque						
	Compa	re match in	errupt ena	able B						
	0	CMIB interr	upt reques	sted by CM	IFB is di	sable	d			
	1 (CMIB interr	upt reques	ted by CN	IFB is er	nable	d			

CSR0—Timer Co	ntrol/S	Status	Regist	er O		H'	FFF82		8-bit timer char	nnel
Bit	7	6	5	4	3	2	1	0		
	CMFB	CMFA	OVF	ADTE	OIS3	OIS2	OS1	OS0		
Initial value Read/Write	0 R/(W)*	0 R/(W)*	0 R/(W)*	R/W	R/W	0 R/W	0 R/W	0 R/W		
							select A1 a	nd A0		
						Bit 1 Bit OS1 OS		Description		
						0 -		nge at compa		
								t at compare i		
						1	Output	toggles at con		
				0	utput/input	capture e	dge select			
					E in Bit 3 SR1 OIS3		D	escription		
					0			at compare ma		
					0	_		ompare match ompare match		
					1		Output togg	es at compare		
					0	О Т		it capture on r	ising	
					1	1 T		it capture on f	alling	
					1		CORB inpuising and fa	it capture on b lling edges	ooth	
			A/E	trigger	enable (TO	CSR0 only	')			
			TRG	E* Bit 4			escription			
				0			t requests igger are d	oy compare m sabled	atch	
			0	1			-	by compare m	atch	
				0			igger are e t requests		trigger are enabled	
			1	1					atch A are enabled	
			Note	e: * TRG	E IS bit 7	of the A/D	control reg	ister (ADCR).		
			mer overflov	v flag g conditi	ionl					
		(Read C	OVF whe	n OVF = 1	, then wri	te 0 in OVF			
				condition overflow:	n] s from H'F	F to H'00.				
	Co	ompare ma	tch flag A							
		[Clear Read	ing condition	n] n CMFA	= 1, then v	vrite 0 in C	CMFA.			
		[Setting	g condition] = TCORA							
C	ompare m		capture flag	В						
		ing condition	on] en CMFB =	1, then v	write 0 in C	MFB.				
	1 TCN1	ng conditio		- 44- TO	ODD b	- !				
	The I		is transferr s as an inpu			n input ca	pture signa	wnen		
Note: * Only	0 can be	written to b	its 7 to 5, to	clear the	ese flags.					

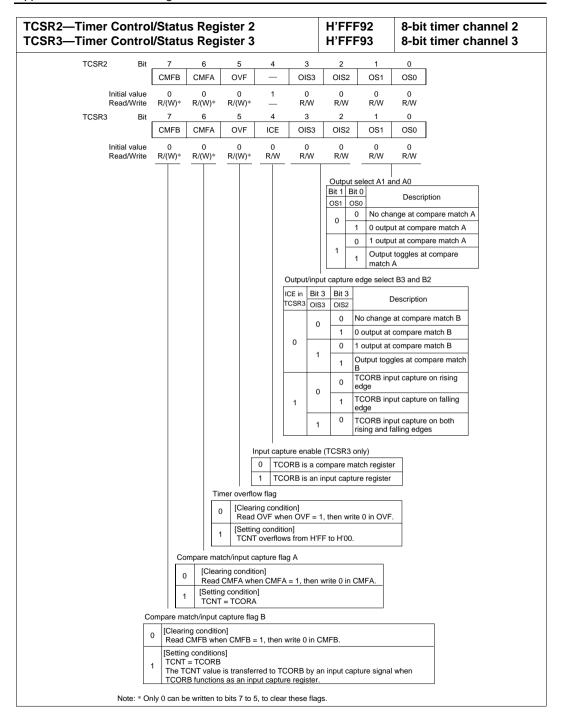
TCSR1—Timer Conti	rol/Sta	tus Re	gister '	1			Н	'FF	F83		8-bit timer channel 1
Bit	7	6	5	4		3	2		1	0	
	CMFB	CMFA	OVF	ICI		OIS3	OIS		OS1	OS0	
Initial value Read/Write	0 R/(W)*	0 R/(W)*	0 R/(W)*	0 R/\		0 R/W	0 R/V		0 R/W	0 R/W	
					Outp	Bit 3	Bit 1 OS1 1 captur	0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	No char O output Output t match A ge select I De change a utput at co	Description of the state of the	pompare match A Inpare match B Inpar
					1	0	0 1 0 1	TC edg	ge ORB inpu ge	t captui	re on falling re on both ges
			In	put ca	pture e	enable				_	
				_					h register	_	
						is an in	put car	oture	register		
			mer overflo		l ndition	1				\neg	
			Read	OVF	when C		, then	write	0 in OVF.	_	
						om H'F	F to H'	00.			
	_ <u>c</u>	ompare ma			flag A						
			ng condition		IFA = 1	I, then v	vrite 0	in CN	лFA.		
			ng condition								
<u>C</u>	ompare m	natch/input	capture flag	gВ							
	0 [Clea	ring conditi d CMFB wh	on] en CMFB =	= 1, th	en writ	e 0 in C	MFB.				
	1 TCN The	ng conditio T = TCORB TCNT value RB function	is transfer				n input	capt	ure signal	when	
Note: * Only 0 car	n be writte	n to bits 7 t	o 5, to clea	ar thes	e flags	š.					

CORA0—1 CORA1—1										FFF8 FFF8			8-bit 8-bit			
				тсо	RA0							TCC	RA1			
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value Read/Write	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W									
CORB0—1										FFF8 FFF8			8-bit 8-bit			
				TCO	RB0				•			TCC	RB1			
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
Read/Write	-	-		-	-	-	-		R/W		-	-	-	-	-	-
CNT0—Tir CNT1—Tir										FFF8			8-bit 8-bit			
				TCI	NT0				_			TCI	NT1			
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W									

CSR—Tim	er Co	ontro	I/Stat	us R	egister			H'FI	FF8C			WDT
Bit	7	•		6	5	4	3		2		1	0
	OV	/F	W	Γ/ĪT	TME	_	_	С	KS2	Ck	(S1	CKS0
Initial value Read/Write	0 R/(V		R/		0 R/W	1	1_	_ F	0 R/W		0 /W	0 R/W
								Clock	select	2 to 0		
									CKS1		De	escription
										0	φ/2	
									0	1	φ/32	
								0		0	φ/64	
									1	1	φ/128	I
									_	0	φ/256	i
									0	1	φ/512	
								1		0	φ/204	-8
									1	1	φ/409	6
					Timer ena	able						
					Tii	mer disabled						
					0 •	TCNT is initia	lized to H	00 and	I			
						halted						
						mer enabled						
					1 •	TCNT is cou	nting					
			Time	mode	select							
					val timer:							
			0			timer interru	pts					
				Wato	hdog timer:							
			1		rates a rese							
	0	امین دا										
	Over	flow fla		nditi -	-1							
	0		_	onditior when		en write 0 in	OVF					
	1	[Setti	ng cor	ndition]								
Note: * Only	0 can							ı				

TCNT—Time	er Cou	nter		H'FF	FF8D (read	d), H'FFF8	C (write)	WDT
Bit	7	6	5	4	3	2	1	0
Initial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W
				Count	value			
RSTCSR—R	eset C	ontrol/Status	s Register	H'FF	FF8F (read	l), H'FFF8	E (write)	WDT
Bit	7	6	5	4	3	2	1	0
	WRS	RSTOE	_	_	_	_	_	_
Initial value Read/Write	Watce	Reset ou	ternal output itions] t RES pin then WRST	t of reset sign t of reset sign = 1, then wri	nal is enable	d	1	1
	1	TCNT overflov		a reset signa	I			
Note: * (Only 0 ca	an be written in b	oit 7, to clear	the flag.				

R2—Time R3—Time								FFF90 FFF91		oit timer chann oit timer chann
Bit	7	6	5	4		3	2	1	0	
	CMIEB	CMIEA	OVIE	CCLR	1 CC	LR0	CKS2	CKS1	CKS0	
Initial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W		0 /W	0 R/W	0 R/W	0 R/W	-
					011	1				
						select	CSK0		escription	
					00112	Joon	0	Clock inpu		
						0	1	Internal cl	ock, count	ted on rising edge
					0	1	0	Internal cl of \$/64	ock, count	ted on rising edge
							1	Internal cl of \$\phi/8192	ock, count	ted on rising edge
						0	0	Channel 3	n TCNT3 3:	overflow signal* compare match A*
					1		1	External c	lock, cour	nted on falling edge
							0	External c	lock, cour	nted on rising edge
						1	1	External c		nted on both
					Note:	sign: mate	al and th	at of chann , no increm	el 3 is the	ne TCNT3 overflow TCNT2 compare ck is generated. Do
				Counter	clear 1	and (1			
) Cle	earing	s disabl	ed		
					_			are match A		
				1 —	_		• •	are match E	3/input cap	oture B
			Timera					capture B		
				overflow i				F is disable	d	
								F is enabled	_	
		Compa	re match i		-	-				
			CMIA inter				FA is dis	abled		
			CMIA inter							
	Compor	o match in	iterrupt en	able B						
	Compan	e matemi	itorrupt on	abio B						



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											ppen	uix D	IIIC	illai	/O IX	egistei
TCORA2—1 TCORA3—1										FFF9			-			nnel 2 nnel 3
				TCC	RA2							TCC	RA3			
D :	45		40	40		40										
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
Initial value Read/Write	-		-	-	T R/W	-	-	-	-	R/W	-	-	-	T R/W	-	-
TCORB2—1										FFF9						nnel 2
TCORB3—1	Time (Cons	tant	Regi	ster E	33			H'	FFF9	7		8-bit	time	r cha	nnel 3
				тсо	RB2							TCC	RB3			
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
TCNT2—Tir TCNT3—Tir										FFF9 FFF9						nnel 2 nnel 3
				TCI	NT2							TCI	NT3			
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

DADR0—D/A	Data Re	gister 0				H'FFF9C		D/A
Bit _	7	6	5	4	3	2	1	0
Initial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W
				D/A conve	ersion data			

DADR1—D/	A Data Re	gister 1				H'FFF9D		D/A	
Bit	7	6	5	4	3	2	1	0	
]
Initial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	J
				D/A conve	ersion data				

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ACR—D/A	Contro	ol R	egist	er					H'FFF	9E		D/A
Bit	7		6		5	4	3		2	1		0
	DAOE	1	DAOE	:0 C	AE	_	_	-	_	_		_
Initial value Read/Write	0 R/W		0 R/W	F	0 R/W	1_	1	-	1_	1 _		1
				D/A ena	lble							
					t 7	Bit 6	6		Bit 5			
				DAG	DE1	DAO	Ξ0		DAE	Des	criptic	n
				()	0			_	D/A conv		is disabled nd 1
)	1			0	D/A conv		is enabled
										D/A conv in channe		is disabled
				()	1			1	D/A conv		is enabled nd 1
				,	1	0			0	D/A conv		is disabled
										D/A conv		is enabled
					1	0			1	D/A conv		is enabled nd 1
					1	1			_	D/A convin channe		n is enabled nd 1
			D/A o	utput ena	able 0							
			0	-		tput is disab	led					
			1			conversion are enabled	and DA	Ao				
		-	enable									
	0			output is								
	1			D/A conv out are er		and DA1						

PMR—	TPC Ou	itput Mo	ode Reg	ister				H'FFFA0	TPC
Bit	7	6	5	4	3	2	1	0	
	_	_	_	_	G3NOV	G2NOV	G1NOV	G0NOV	
Bit	7 - 1 -	1		1	G3NOV OR/W Group 3 n O No cor No No	G2NOV 0 R/W Grou 1 up 2 non-ove Normal T compare Non-over(compare match	p 1 non-ove compare PC output match A in the so	Group 0 non-overlap Normal TPC output in change at compare n 16-bit timer channel Non-overlapping TPC controlled by compar selected 16-bit timer	e match A and B in the channel put values change 116-bit timer channel up 1, controlled by cted 16-bit timer channel change at channel billed by timer channel

TPCR—TPC Output Control Register H'FFFA1 **TPC** Bit 6 5 3 2 G3CMS0 G2CMS1 G2CMS0 G1CMS1 G0CMS1 G3CMS1 G1CMS0 G0CMS0 Initial value R/W R/W R/W R/W R/W R/W R/W R/W Read/Write Group 0 compare match select 1 and 0 Bit 1 16-Bit Timer Channel Selected as Output Trigger G0CMS1 G0CMS0 TPC output group 0 (TP3 to TP0) is triggered by 0 compare match in 16-bit timer channel 0 0 TPC output group 0 (TP3 to TPo) is triggered by 1 compare match in 16-bit timer channel 1 0 TPC output group 0 (TP3 to TP0) is triggered by 1 compare match in 16-bit timer channel 2 Group 1 compare match select 1 and 0 Bit 3 Bit 2 16-Bit Timer Channel Selected as Output Trigger G1CMS1 G1CMS0 TPC output group 1 (TP7 to TP4) is triggered by 0 compare match in 16-bit timer channel 0 0 TPC output group 1 (TP7 to TP4) is triggered by 1 compare match in 16-bit timer channel 1 0 TPC output group 1 (TP7 to TP4) is triggered by 1 compare match in 16-bit timer channel 2 1 Group 2 compare match select 1 and 0 Bit 5 Bit 4 16-Bit Timer Channel Selected as Output Trigger G2CMS1 G2CMS0 0 TPC output group 2 (TP11 to TP8) is triggered by compare match in 16-bit timer channel 0 0 TPC output group 2 (TP11 to TP8) is triggered by compare match in 16-bit timer channel 1 1 0 TPC output group 2 (TP11 to TP8) is triggered by compare match in 16-bit timer channel 2 Group 3 compare match select 1 and 0

	Bit 7	Bit 6	40 Dit Times Observal Calcated as Outset Trimes
ı	G3CMS1	G3CMS0	16-Bit Timer Channel Selected as Output Trigger
	0	0	TPC output group 3 (TP15 to TP12) is triggered by compare match in 16-bit timer channel 0
١	U	1	TPC output group 3 (TP15 to TP12) is triggered by compare match in 16-bit timer channel 1
ı	4	0	TPC output group 3 (TP15 to TP12) is triggered by compare match in 16-bit timer channel 2
١	1	1	1 FO output group 3 (1F15 to 1F12) is triggered by compare match in 16-bit timer channel 2

JEKD—N	ext Data E	nable Reg	ister B			H'FFFA2		TPC
Bit	7	6	5	4	3	2	1	0
	NDER15	NDER14	NDER13	NDER12	NDER11	NDER10	NDER9	NDER8
Initial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W
				Nevt data e	enable 15 to	Ω		
		Bits 7 to	0.0	Next data e	mable 13 to			
		NDER1	15		Descripti	on		
		0		outputs TP19		disabled nsferred to PE	37 to PB0)	
		1		outputs TP18		enabled rred to PB7 to	PB0)	
IDERA—N	ext Data E	nable Reg	ister A			H'FFFA3		TPC
I DERA—N o	ext Data E	nable Reg	ister A	4	3	H'FFFA3	1	TPC 0
			<u> </u>	4 NDER4	3 NDER3		1 NDER1	
	7	6	5			2		0
Bit Initial value	7 NDER7	6 NDER6	5 NDER5	NDER4	NDER3	2 NDER2	NDER1	0 NDER0
Bit Initial value	7 NDER7	6 NDER6	5 NDER5	NDER4 0 R/W	NDER3	2 NDER2 0 R/W	NDER1	0 NDER0
Bit Initial value	7 NDER7	6 NDER6	5 NDER5 0 R/W	NDER4 0 R/W	NDER3 0 R/W enable 7 to 0	2 NDER2 0 R/W	NDER1	0 NDER0
Bit Initial value	7 NDER7	6 NDER6 0 R/W	5 NDER5 0 R/W	NDER4 0 R/W	NDER3 0 R/W	2 NDER2 0 R/W	NDER1	0 NDER0
Bit Initial value	7 NDER7	6 NDER6 0 R/W Bits 7 to	5 NDER5 0 R/W	NDER4 0 R/W Next data of	NDER3 0 R/W enable 7 to 0 Descripti	2 NDER2 OR/W On	NDER1 0 R/W	0 NDER0

Appendix B Internal I/O Registers NDRB—Next Data Register B H'FFFA4/H'FFFA6 **TPC** Same trigger for TPC output groups 2 and 3 Address H'FFFA4 7 6 5 4 3 2 1 0 Bit NDR10 NDR15 NDR14 NDR13 NDR12 NDR11 NDR9 NDR8 Initial value 0 0 0 0 0 0 R/W R/W R/W R/W R/W R/W Read/Write R/W R/W Store the next output data for TPC output group 3 Store the next output data for TPC output group 2 - Address H'FFFA6 Bit 6 5 3 2 Initial value 1 1 1 1 1 Read/Write Different triggers for TPC output groups 2 and 3 Address H'FFFA4 6 5 4 3 2 0 Bit NDR15 NDR14 NDR13 NDR12 Initial value 0 0 1 1 Read/Write R/W R/W R/W R/W Store the next output data for TPC output group 3 Address H'FFFA6

Bit	7	6	5	4	3	2	1	0
	_	_		_	NDR11	NDR10	NDR9	NDR8
Initial value Read/Write	1	1	1	1	0 R/W	0 R/W	0 R/W	0 R/W

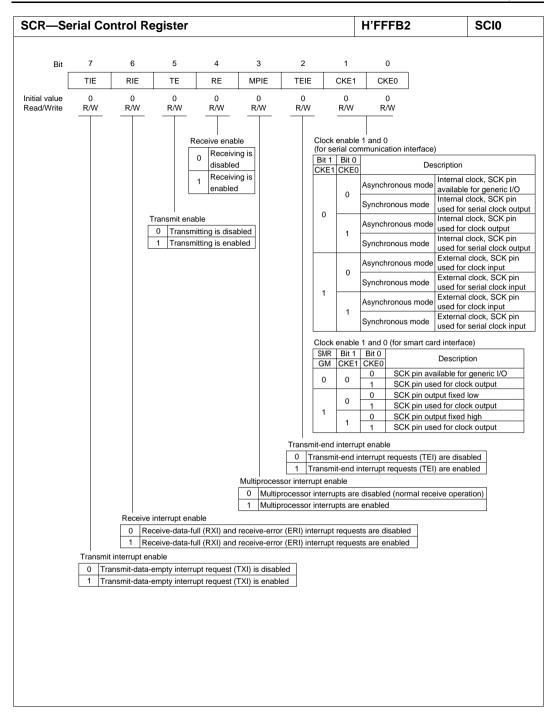
Store the next output data for TPC output group 2

NDRA-Next Data Register A H'FFFA5/H'FFFA7 **TPC** Same trigger for TPC output groups 0 and 1 Address H'FFFA5 7 6 5 4 3 2 1 0 Bit NDR7 NDR6 NDR5 NDR4 NDR3 NDR2 NDR1 NDR0 Initial value 0 0 0 0 0 R/W R/W R/W R/W R/W R/W Read/Write R/W R/W Store the next output data for TPC output group 1 Store the next output data for TPC output group 0 - Address H'FFFA7 Bit 3 2 0 6 5 1 Initial value 1 1 1 1 1 1 1 Read/Write Different triggers for TPC output groups 0 and 1 Address H'FFFA5 7 6 5 4 3 2 1 0 Bit NDR7 NDR6 NDR5 NDR4 Initial value 0 1 1 1 Read/Write R/W R/W R/W R/W Store the next output data for TPC output group 1 - Address H'FFFA7 Bit 6 5 4 3 2 1 0 NDR3 NDR2 NDR1 NDR0 Initial value 1 1 1 1 Read/Write R/W R/W R/W R/W

Store the next output data for TPC output group 0

R—Serial I	Mode Re	giste	r							H'FF	FB0		SCI0
Bit	7		6	5		4		3	3	2		1	0
	C/Ā	С	HR	PE		O/E	Ē	ST	ЭP	М	P	CKS1	CKS0
	0 R/W	(R/) W	0 R/\		0 R/V	V	R/		0 R/\		0 R/W	0 R/W
Initial value Read/Write	0	R/) W	Parity 0 1	enabl Parity	Parity r	mode Even Odd	Stop O 1 parity	Mu 0 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	OR/A Itiproce Mu Mu ngth e stop be o stop be	Clock Bit 1 CKS1 0 1 essor meditiproces	O R/W select Bit 0 CKS0 0 1 0 1 ode ssor fur	0
				1	Parity	y bit is a	adde	d and	check	red			
		Char	acter le	ength	-								
		0	8-bit	data									
		1	7-bit	data									
	Communic	ation m	ode (f	or seria	l com	munica	tion i	nterfac	ce)				
-	0 Asy	nchron	ous mo	ode									
L		chrono											
([GSM mode	-					., ¬						
-						r start b							
	1 TEN	D flag i Eleme				r start b	it						

R—Bit Ra	te Regis	ter				H'FFFB1		SCI0
Bit	7	6	5	4	3	2	1	0
nitial value Read/Write	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W
			Seria	I communica	tion bit rate	e setting		



Bit 7 6 5 4 3 2 Initial value 1 1 1 1 1 1 1 1 1 Read/Write R/W	1 0 1 1 R/W R/V
Read/Write R/W R/W R/W R/W R/W	1 1 R/W R/W

SSR—Ser	ial Stat	tus Reg	ister					H'FFFB4	SCI0
Bit	7	6	5	4	3	2	1	0	
	TDRE	RDRF	ORER	FER/ERS	PER	TEND	MPB	MPBT	
Initial value Read/Write	1 R/(W)*	0 R/(W)*	0 R/(W)*	0 R/(W)*	0 R/(W)*	1 R	0 R	0 R/W	
Read/Write	<u>R/(W)*</u>	<u>R/(W)*</u>	<u>R/(W)*</u>			Transmit end Clearin Read T The DM ISetting Reset C Transmit end Clearin O Read T The DM ISetting Reset C THE DM ISETING Reset C THE DM ISETTING RESET C THE DM ISET	Multip O 1 (for seria g condition or transitic eared to 0 g condition or transitic cared to 0 s 1 and F GM = 0) c er is transit	Multiprocessor bit transfer Multiprocessor bit value in tr Multiprocessor bit value in tr Multiprocessor bit value in receive Multiprocessor bit value in receive Multiprocessor bit value in receive I communication interface) ons] an TDRE = 1, then write 0 in TDR s data in TDR. Ins] on to standby mode of in SCR. last bit of 1-byte serial character t card interface) ons] an TDRE = 1, then write 0 in TDR is data in TDR. It card interface) ons] on to standby mode of in SCR and FER/ERS is cleare ER/ERS is 0 (normal transmiss) or 1.0 et u (Mene GM = 1) affest 1.0 tr 10 et u (Mene GM = 1) affest 1.0 tr 10 et u (Mene GM = 1) affest 1.0 tr 10 et u (Mene GM = 1) affest 1.0 tr 1.0 et u (Mene GM = 1) affest 1.0 tr	re data is 0 re data is 1 RE. RE. ris RE. ris red to 0. rol 2.5 etu* byte serial
				0	[Clearing			ransition to standby mode R when PER = 1, then write 0 in F	PER.
				1	[Setting			or (parity of receive data does no O/E bit in SMR)	match parity
				I COL	ror (for seri	al communicat		ace) n to standby mode	
						Read FE	R when	FER = 1, then write 0 in FER.	_
				-	ng condition	n] Framing smart card int	•	op bit is 0)	
					ring conditi	ons] Reset or	transitio	n to standby mode	7
				-	ng condition			ERS = 1, then write 0 in ERS.	4
		Ove	errun error	ı Iroem	g condition	, A NOW EI	. or orginal		_
		0		conditions]	Reset or to	ransition to sta	ndby mod	de	
		1	Setting	condition]				en write 0 in ORER. xt serial data ends when RDRF:	= 1)
		Receive d			3.0.10116	(1000pii011			• /
			aring condi	tions] Reset		n to standby m		A in DDDE	
				The D	MAC reads	n RDRF = 1, the data from RD	R.		
	_		ing condition	on] Serial	data is rec	eived normally	and tran	sferred from RSR to RDR.	
	100	data register		d TDDE w/	TDBE 4	thon write O:	, TDDC		
	0 [Ci	earing condit	The	DMAC writes	data in TD	, then write 0 i R.	II IUKE.		
	1 [Set	tting condition	TE is	et or transition s 0 in SCR. i is transferre		•	ling new	data to be written in TDR	
Note: * Only	0 can be wi	ritten, to clea	r the flag.						

DR—Receiv	e Data R	Register				H'FFFB5		SCI0
Bit	7	6	5	4	3	2	1	0
nitial value	0	0	0	0	0	0	0	0
Read/Write		R	R	R	R	R	R	R
				Serial rece	eive data			

CMR—Smart Card Mode Regis	ster		H'FFFB6	SCI0
Bit 7 6 5 -	4 3 2 — SDIR SII 1 0 0 — R/W R/ Smal 0 1 Smart card data 0 TDR con 0 Receive 1 TDR con	N	rface mode select ard interface function is disabled and interface function is enabled and interface function is enabled. The face mode select and interface function is enabled and interface function is enabled. The face mode select and interface function is enabled and interface function is enabled. The face mode select and interface function is disable and interface function is enabled. The face mode select and interface function is disable and interface function is enabled.	d (Initial value

SMR—Seria	l Mode Re	H'FFFB8		SCI1				
Bit	7	6	5	4	3	2	1	0
	C/A	CHR	PE	O/E	STOP	MP	CKS1	CKS0
Initial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W

BRR—Bit R	ate Regis	ter				H'FFFB9		SCI1	
Bit	7	6	5	4	3	2	1	0	
Initial value Read/Write	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W	

Note: Bit functions are the same as for SCIO.

SCR—Seria	l Control l	H'FFFBA	SCI1					
D.,	7	0	F	4	2	2	4	0
Bit	,	6	5	4	3	2	1	0
	TIE	RIE	TE	RE	MPIE	TEIE	CKE1	CKE0
Initial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W

TDR—Transr	nit Data R	egister				H'FFFBB		SCI1
Bit	7	6	5	4	3	2	1	0
Initial value Read/Write	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W

SSR—Serial	Status Re		H'FFFBC		SCI1			
Bit	7	6	5	4	3	2	1	0
Dit.	TDRE	RDRF	ORER	FER/ERS	PER	TEND	MPB	MPBT
Initial value Read/Write	0 R/(W)*	0 R/(W)*	0 R/(W)*	0 R/(W)*	0 R/(W)*	1 R	0 R	0 R/W

Note: Bit functions are the same as for SCI0.

RDR—Recei	ve Data Re	egister	H'FFFBD		SCI1				
Bit	7	6	5	4	3	2	1	0	
Initial value Read/Write	0 R	0 R	0 R	0 R	0 R	0 R	0 R	0 R	-

^{*} Only 0 can be written, to clear the flag.

SCMR—Sma	rt Card Mo		H'FFFBE		SCI1			
Bit	7	6	5	4	3	2	1	0
Dit.		_	_		SDIR	SINV		SMIF
Initial value Read/Write	1	1 —	1 —	1 _	0 R/W	0 R/W	1 —	0 R/W

SMR—Serial	Mode Re	gister	H'FFFC0		SCI2			
Bit	7	6	5	4	3	2	1	0
	C/A	CHR	PE	O/Ē	STOP	MP	CKS1	CKS0
Initial value Read/Write	0 R/W							

Note: Bit functions are the same as for SCI0.

BRR—Bit Ra	te Registe	er		H'FFFC1	SCI2			
Bit	7	6	5	4	3	2	1	0
Initial value Read/Write	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W

Note: Bit functions are the same as for SCI0.

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SCR—Serial	Control R	I	H'FFFC2	SCI2				
Bit	7	6	5	4	3	2	1	0
	TIE	RIE	TE	RE	MPIE	TEIE	CKE1	CKE0
Initial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W

TDR—Transı	mit Data R	egister				H'FFFC3		SCI2
Bit	7	6	5	4	3	2	1	0
Initial value Read/Write	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W	1 R/W

Note: Bit functions are the same as for SCI0.

SSR—Serial	Status Re	H'FFFC4		SCI2				
Bit	7	6	5	4	3	2	1	0
	TDRE	RDRF	ORER	FER/ERS	PER	TEND	MPB	MPBT
Initial value Read/Write	1 R/(W)*	0 R/(W)*	0 R/(W)*	0 R/(W)*	0 R/(W)*	1 R	0 R	0 R/W

^{*} Only 0 can be written, to clear the flag.

RDR—Recei	ve Data Re	H'FFFC5		SCI2				
Bit	7	6	5	4	3	2	1	0
Initial value Read/Write	0 R	0 R	0 R	0 R	0 R	0 R	0 R	0 R

SCMR—Sma	rt Card Mo	I	H'FFFC6		SCI2			
Bit	7	6	5	4	3	2	1	0
	_	_	_	_	SDIR	SINV	_	SMIF
Initial value Read/Write	1	1	1	1	0 R/W	0 R/W	1	0 R/W

P1DR—Port	1 Data Re	H'FFFD0		Port 1				
Bit	7	6	5	4	3	2	1	0
	P17	P16	P15	P14	P13	P12	P1 ₁	P10
Initial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W

Data for port 1 pins

P2DR—Port	2 Data Re	H'FFFD1	Port 2					
Bit	7	6	5	4	3	2	1	0
	P27	P26	P25	P24	P23	P22	P21	P20
Initial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W
				Data for p	oort 2 pins			

P3DR—Port	3 Data Re	H'FFFD2		Port 3				
Bit	7	6	5	4	3	2	1	0
	P37	P36	P35	P34	P33	P32	P31	P30
Initial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W

Data for port 3 pins

4DR—Port	4 Data Re	egister		H'FFFD3	Port 4			
Bit	7	6	5	4	3	2	1	0
	P47	P46	P45	P44	P43	P42	P41	P40
Initial value Read/Write	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W

Data for port 4 pins

P5DR—Port	DR—Port 5 Data Register					H'FFFD4						
Bit	7	6	5	4	3	2	1	0				
	_	_	_	_	P53	P52	P51	P50				
Initial value Read/Write		1_	<u>1</u>	1_	0 R/W	0 R/W	0 R/W	0 R/W				
						l Data for port 5 pins						

6DR—Port 6 Data Register						H'FFFD5	Port 6		
Bit	7	6	5	4	3	2	1	0	
	P67	P66	P65	P64	P63	P62	P61	P60	
Initial value Read/Write	1 R	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	
				Data for r	oort 6 pins				

P7DR—Port	7 Data Re	egister				H'FFFD6	Port 7		
Bit	7	6	5	4	3	2	1	0	
	P77	P76	P75	P74	P73	P72	P71	P70]
Initial value	*	*	*	*	*	*	*	*	
Read/Write	R	R	R	R	R	R	R	R	
								_	

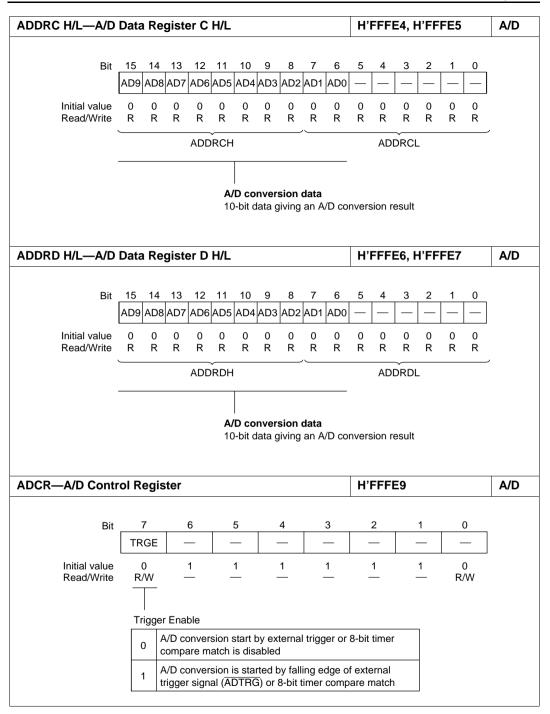
Data for port 7 pins

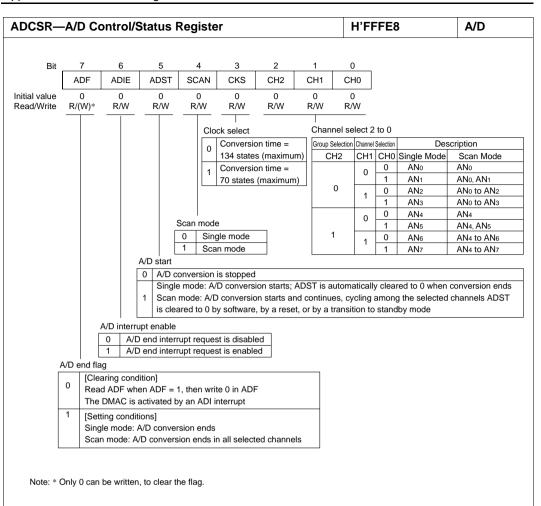
Note: * Determined by pins P77 to P70.

BDR—Port	8 Data Re	Data Register				H'FFFD7				
Bit	7	6	5	4	3	2	1	0		
	_	_	_	P84	P83	P82	P81	P80		
Initial value Read/Write		1_	1_	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W		
					Di	ata for port 8 p	pins			
DR—Port		egister				H'FFFD8		Port 9		
Bit	7	6	5	4	3	2	1	0		
		_	P9 ₅	P94	P93	P92	P91	P90		
Initial value Read/Write	<u>1</u>	<u>1</u>	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W	0 R/W		
					Data for	port 9 pins				
ADR—Port	A Data R	egister				H'FFFD9		Port A		
ADR—Port Bit	A Data R	egister 6	5	4	3	H'FFFD9	1	Port A		
ADR—Port Bit			5 PAs	4 PA4			1 PA1			

Data for port A pins

BDR—Port B Data Register												H'I	Poi	rt B					
Bit7		7 6			5		4	4		3		2		1		0			
	PB	7	Р	B ₆		PB ₅		PE	84	ı	PB3		PB:	2	F	PB1		PB ₀	
nitial value Read/Write	0 R/V			0 /W	·	0 R/W	·	0 R/\		F	0 R/W	·	0 R/V	V		0 R/W	·	0 R/W	
								Data	a for _l	oort E	3 pins								
DRA H/L—	-A/D	Data	a Re	giste	er A	H/L					ı	H'FF	FEO), H'	FFFI	E1		A/D	
	Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
		AD9	AD8	AD7	AD6	AD5	AD4	AD3	AD2	AD1	AD0	_	_	_	_	_	_		
Initial value Read/Write		0 R	0 R	0 R	0 R	0 R	0 R	0 R	0 R	0 R	0 R	0 R	0 R	0 R	0 R	0 R	0 R		
		ADDRAH											ADDRAL						
							/D co)-bit d				/D co	nvers	sion re	esult					
DRB H/L—	-A/D	Data	a Re	giste	er B	H/L					ı	H'FF	FE2	2, H'	FFFI	E3		A/D	
	Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
											AD0	_	_	_	_	_	_		
Initial v Read/V		0 R	0 R	0 R	0 R	0 R	0 R	0 R	0 R	0 R	0 R	0 R	0 R	0 R	0 R	0 R	0 R		
		ADDRBH											ADDRBL						
							/D co 0-bit d				/D 000	0.40 50	ion r	ocult					





Appendix C I/O Port Block Diagrams

C.1 Port 1 Block Diagram

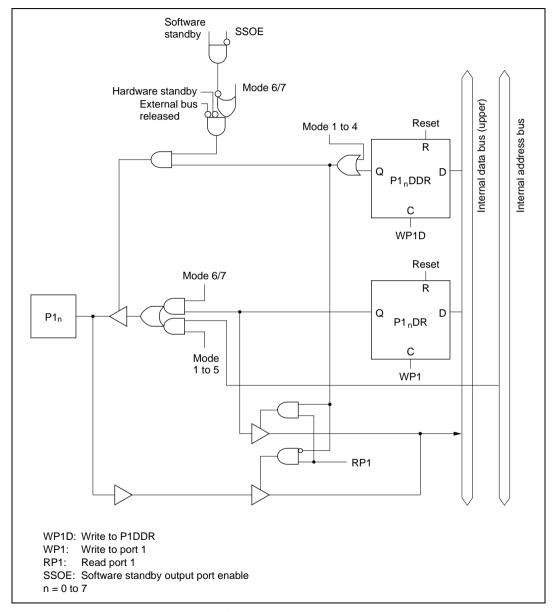


Figure C.1 Port 1 Block Diagram

C.2 Port 2 Block Diagram

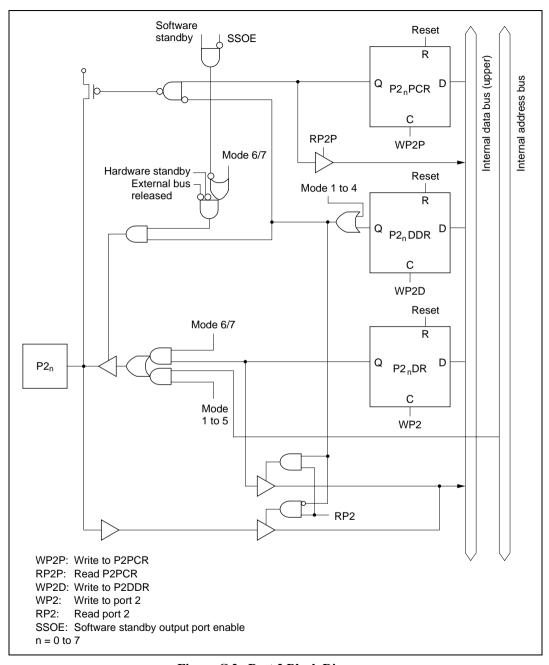


Figure C.2 Port 2 Block Diagram

C.3 Port 3 Block Diagram

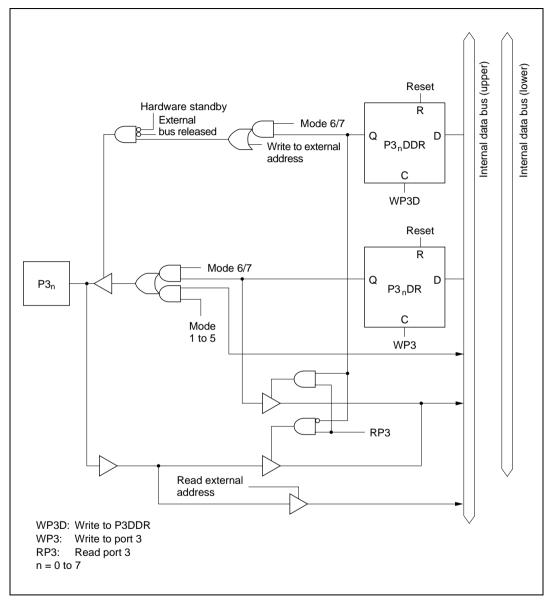


Figure C.3 Port 3 Block Diagram

C.4 Port 4 Block Diagram

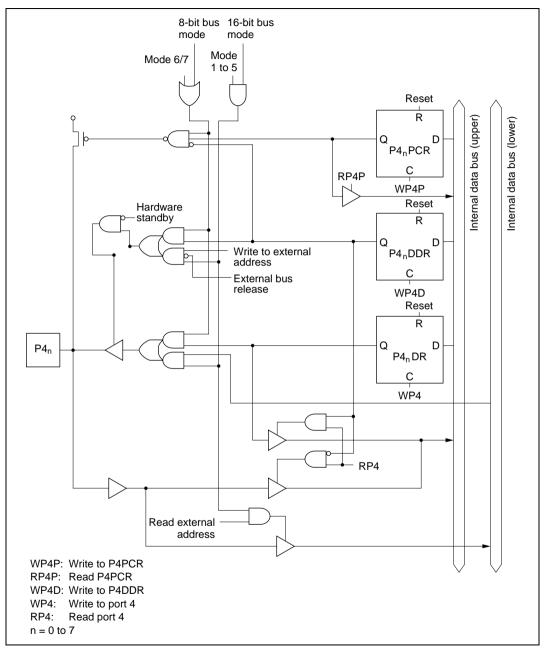


Figure C.4 Port 4 Block Diagram

C.5 Port 5 Block Diagram

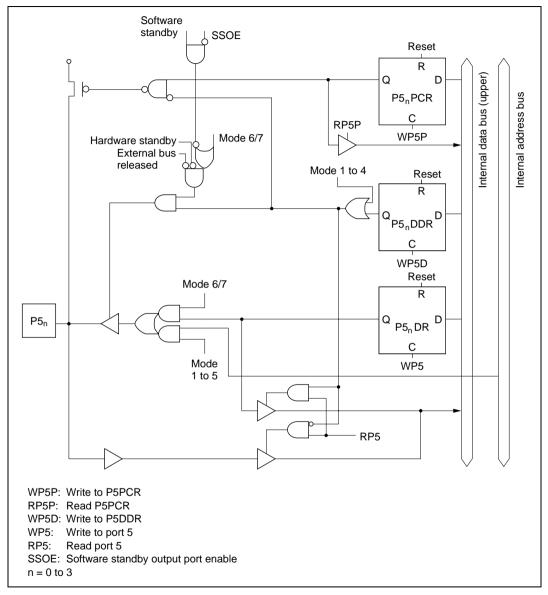


Figure C.5 Port 5 Block Diagram

C.6 Port 6 Block Diagrams

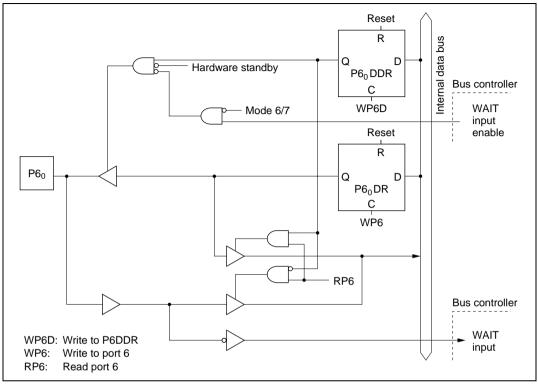


Figure C.6 (a) Port 6 Block Diagram (Pin P6₀)

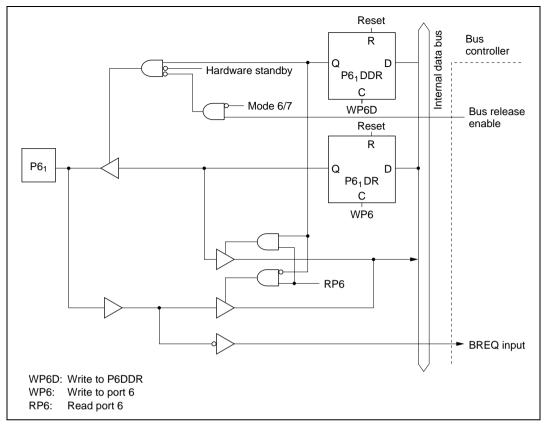


Figure C.6 (b) Port 6 Block Diagram (Pin P6₁)

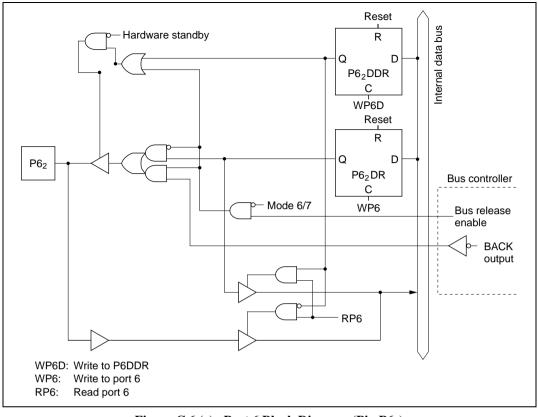


Figure C.6 (c) Port 6 Block Diagram (Pin P62)

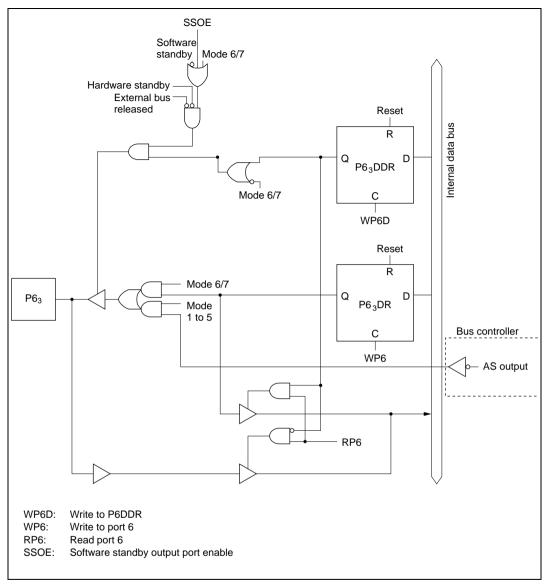


Figure C.6 (d) Port 6 Block Diagram (Pin P63)

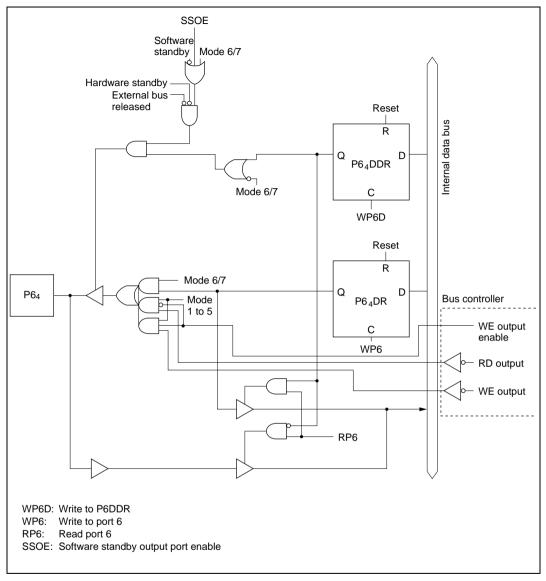


Figure C.6 (e) Port 6 Block Diagram (Pin P64)

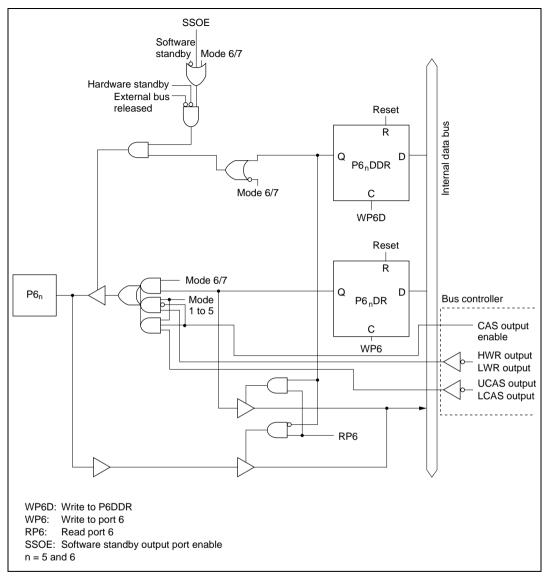


Figure C.6 (f) Port 6 Block Diagram (Pins $P6_5$ and $P6_6$)

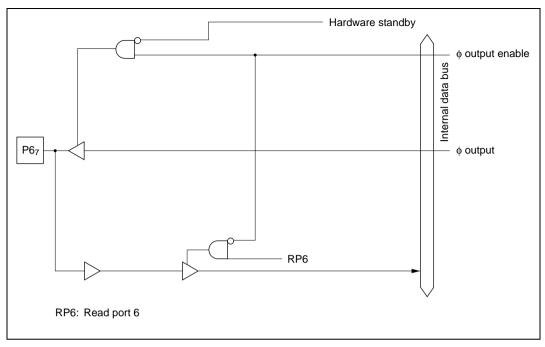


Figure C.6 (g) Port 6 Block Diagram (Pin P67)

C.7 Port 7 Block Diagrams

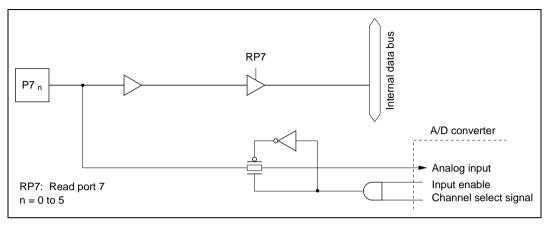


Figure C.7 (a) Port 7 Block Diagram (Pins P7₀ to P7₅)

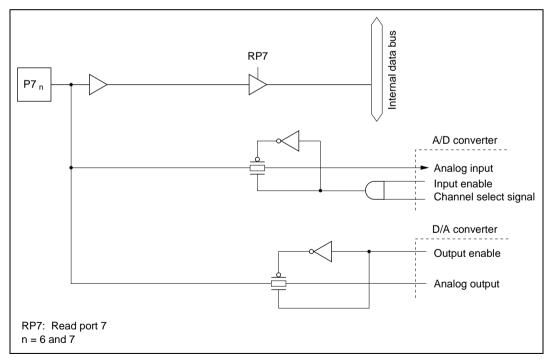


Figure C.7 (b) Port 7 Block Diagram (Pins P7₆ and P7₇)

C.8 Port 8 Block Diagrams

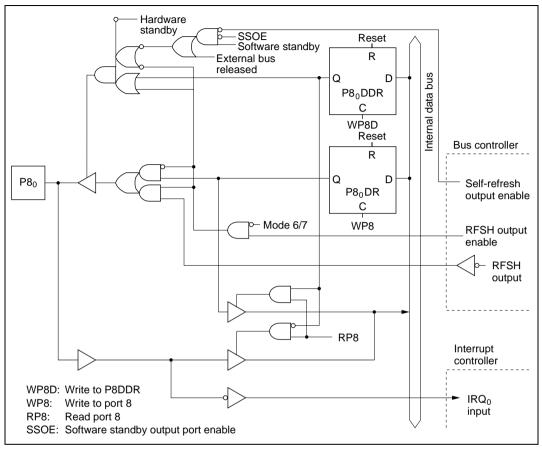


Figure C.8 (a) Port 8 Block Diagram (Pin $P8_0$)

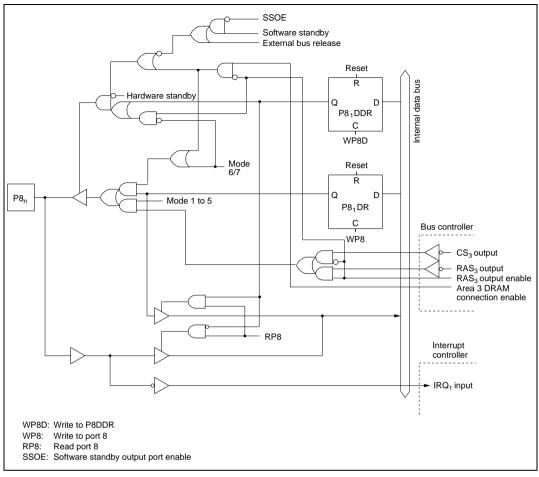


Figure C.8 (b) Port 8 Block Diagram (Pin P8₁)

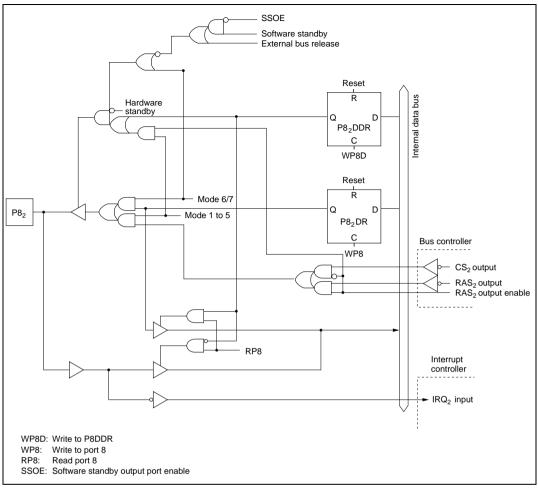
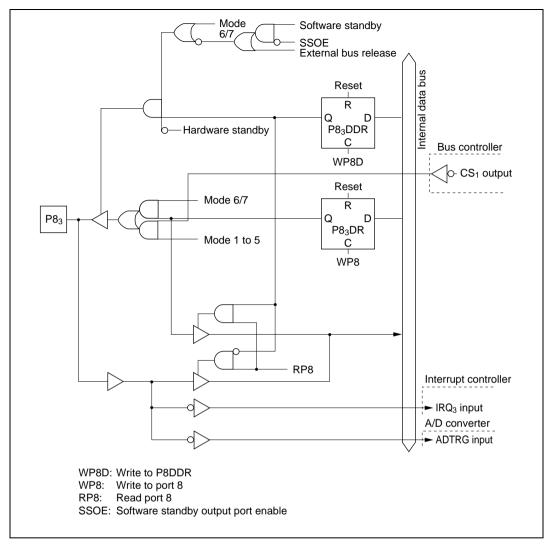


Figure C.8 (c) Port 8 Block Diagram (Pin P82)



 $Figure~C.8~(d)~~Port~8~Block~Diagram~(Pin~P8_3)\\$

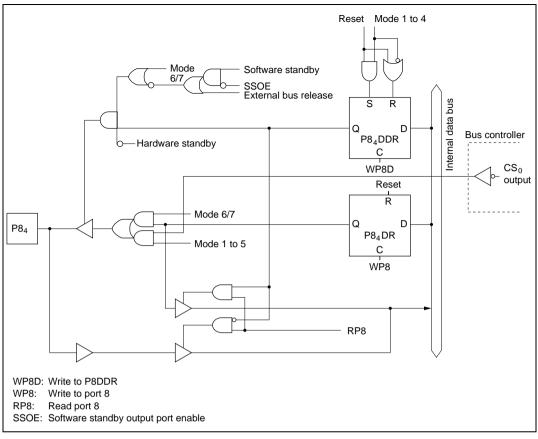


Figure C.8 (e) Port 8 Block Diagram (Pin P84)

C.9 Port 9 Block Diagrams

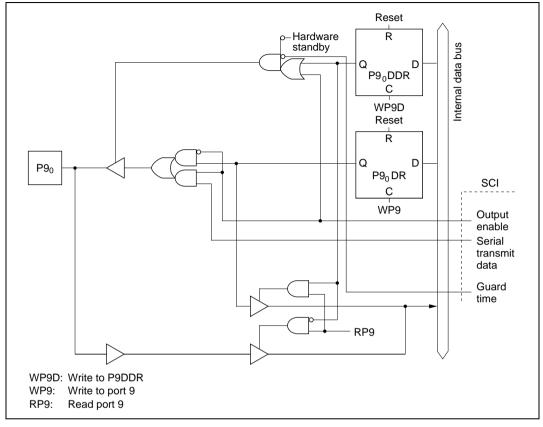


Figure C.9 (a) Port 9 Block Diagram (Pin $P9_0$)

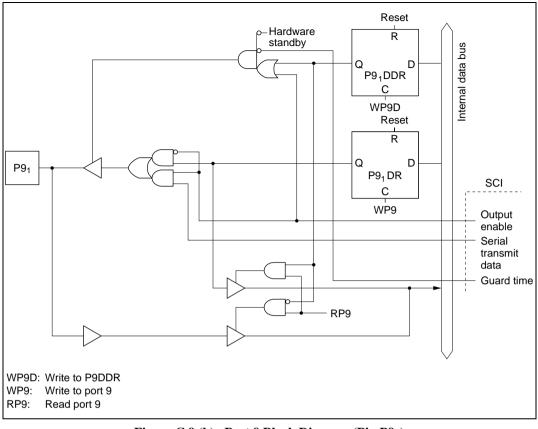
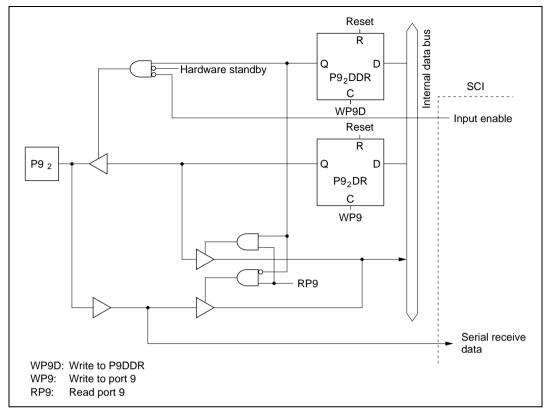


Figure C.9 (b) Port 9 Block Diagram (Pin P9₁)



 $Figure~C.9~(c)~~Port~9~Block~Diagram~(Pin~P9_2)\\$

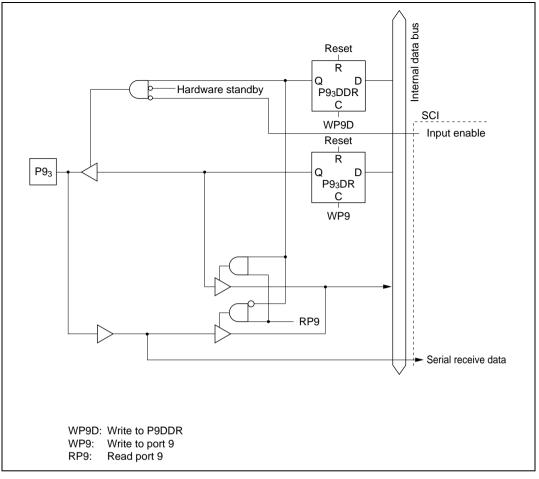


Figure C.9 (d) Port 9 Block Diagram (Pin P93)

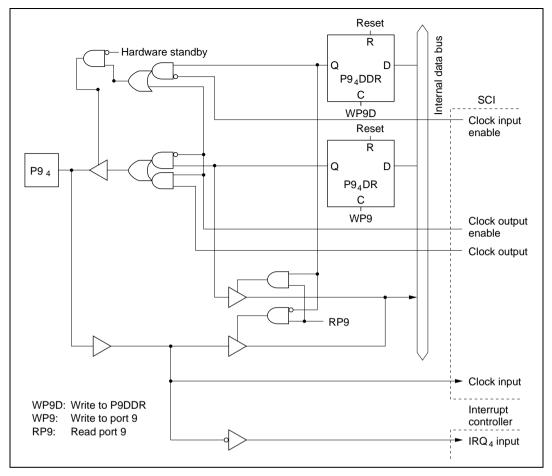


Figure C.9 (e) Port 9 Block Diagram (Pin P94)

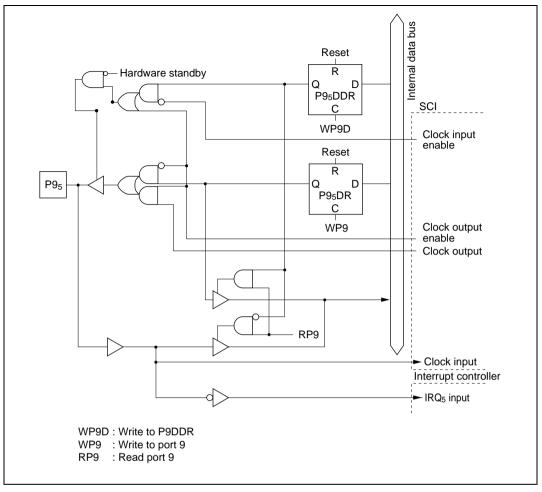
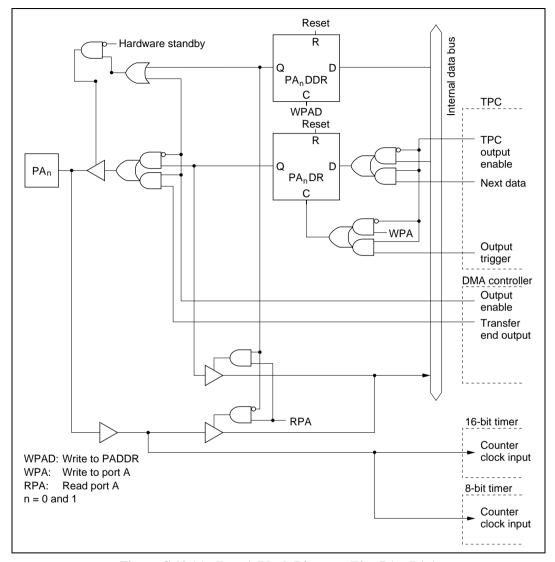


Figure C.9 (f) Port 9 Block Diagram (Pin P95)

C.10 Port A Block Diagrams



 $Figure~C.10~(a)~~Port~A~Block~Diagram~(Pins~PA_0,PA_1)\\$

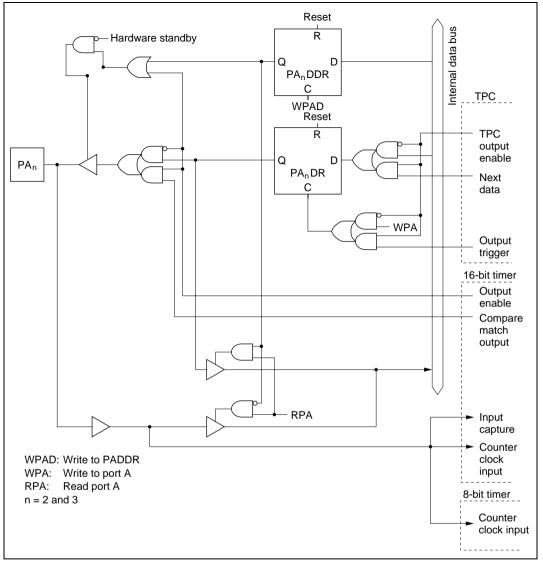


Figure C.10 (b) Port A Block Diagram (Pins PA₂, PA₃)

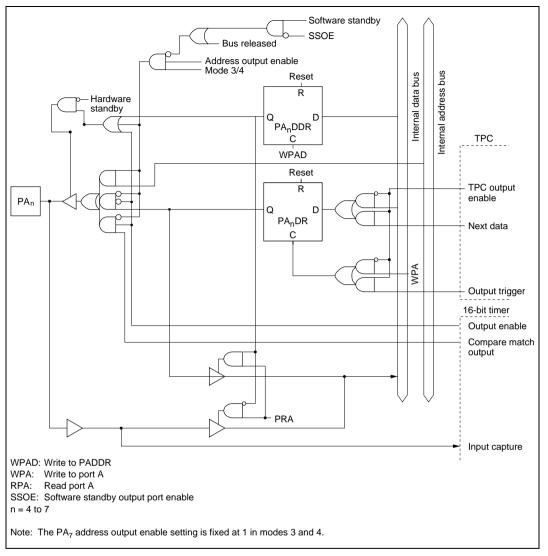


Figure C.10 (c) Port A Block Diagram (Pins PA₄ to PA₇)

C.11 Port B Block Diagrams

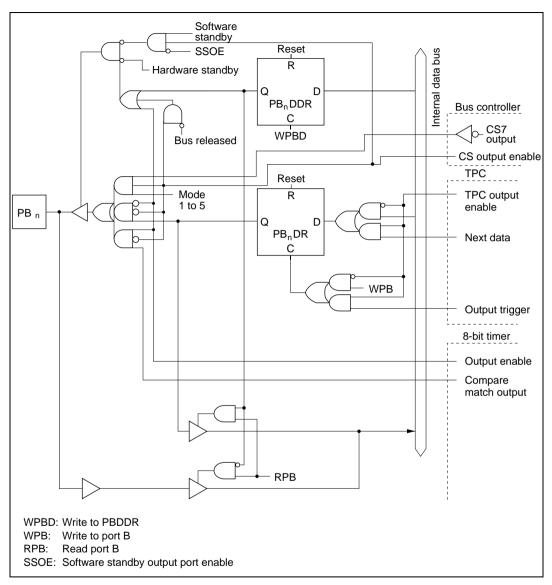
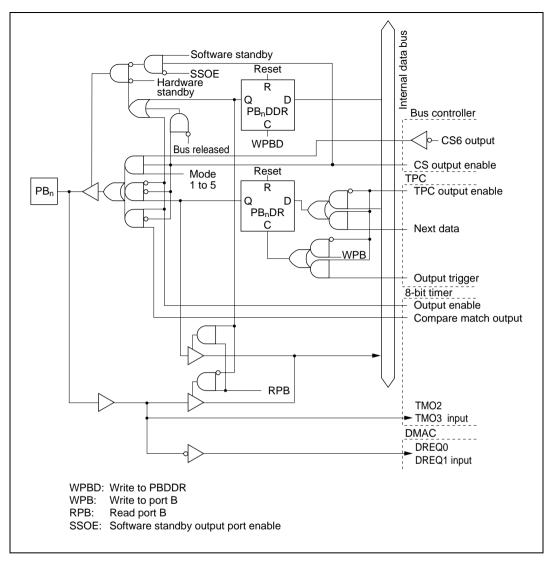


Figure C.11 (a) Port B Block Diagram (Pin PB₀)



 $Figure~C.11~(b)~~Port~B~Block~Diagram~(Pin~PB_1)\\$

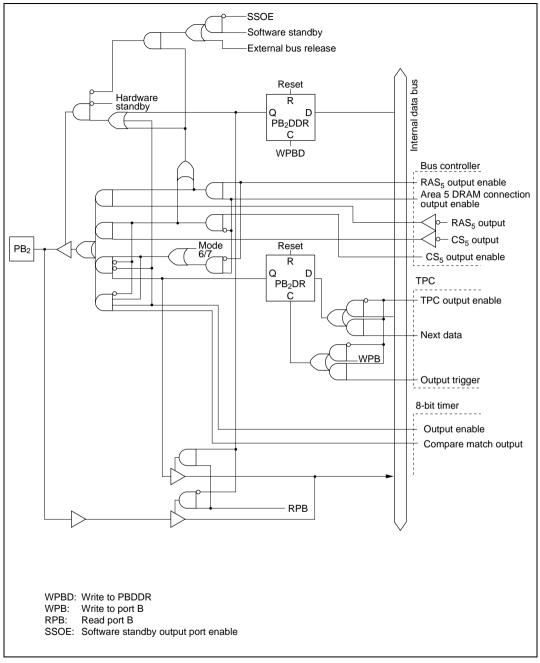


Figure C.11 (c) Port B Block Diagram (Pin PB₂)

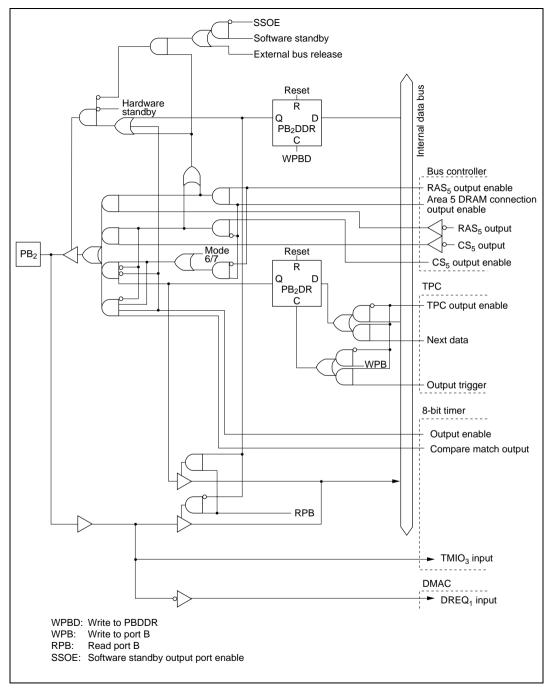


Figure C.11 (d) Port B Block Diagram (Pin PB₃)

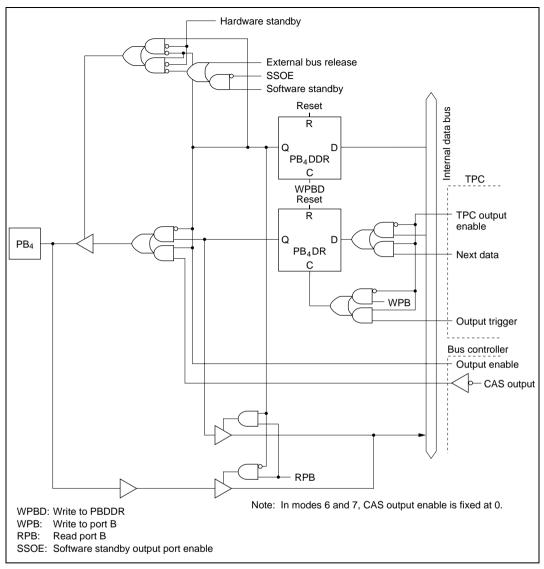


Figure C.11 (e) Port B Block Diagram (Pin PB₄)

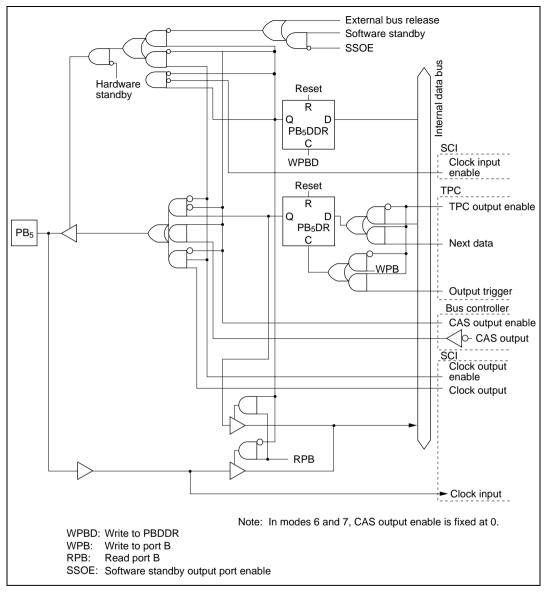


Figure C.11 (f) Port B Block Diagram (Pin PB₅)

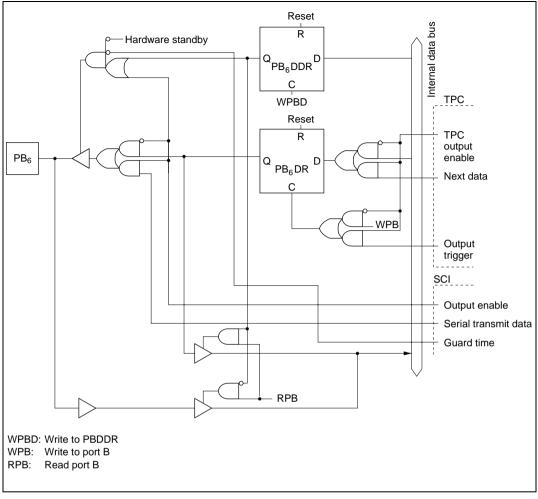
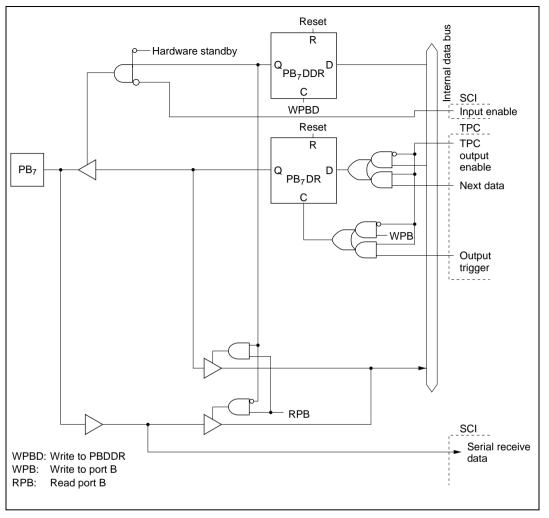


Figure C.11 (g) Port B Block Diagram (Pin PB₆)



 $Figure~C.11~(h)~~Port~B~Block~Diagram~(Pin~PB_7)\\$

Appendix D Pin States

D.1 Port States in Each Mode

Table D.1 Port States

Pin Name	Mode	Reset			Bus-Released Mode	Program Execution Mode
RESO	*17	T*17	T*17	Т	T*17	T*17
P17 to P10	1 to 4	L	Т	(SSOE=0) T (SSOE=1) Keep	Т	A7 to A0
	5	Т	Τ	(DDR = 0) Keep (DDR=1, SSOE=0) T (DDR=1, SSOE=1) Keep	Т	(DDR=0) Input port (DDR=1) A7 to A0
	6, 7	T	Т	Keep	_	I/O port
P27 to P20	1 to 4	L	Т	(SSOE = 0) T (SSOE = 1) Keep	Т	A ₁₅ to A ₈
	5	T	Т	(DDR = 0) Keep (DDR=1,SSOE=0) T (DDR=1,SSOE=1) Keep	Т	(DDR=0) Input port (DDR=1) A ₁₅ to A ₈
	6, 7	Т	Т	Keep	_	I/O port
	1 to 5	T	T	Т	Т	D ₁₅ to D ₈
P3 ₀	6, 7	T	Т	Keep	_	I/O port
	1, 3, 5	Ţ	T	Keep	Keep	I/O port
P4 ₀	2, 4	Ţ	T	Т	Т	D ₇ to D ₀
	6, 7	Т	Т	Keep	_	I/O port



Pin Name	Mode	Reset	Hardware Standby Mode	Software Standby Mode	Bus-Released Mode	Program Execution Mode
P53 to P50	1 to 4	L	T	(SSOE=0) T (SSOE=1) Keep	Т	A19 to A16
	5	Т	Т	(DDR=0) Keep (DDR=1, SSOE=0) T (DDR=1, SSOE=1) Keep	Т	(DDR=0) Input port (DDR=1) A19 to A16
	6, 7	Т	T	Keep	_	I/O port
P6 ₀	1 to 5	Т	Т	Keep	Keep	I/O port WAIT
	6, 7	Т	Т	Keep	_	I/O port
P6 ₁	1 to 5	Т	Т	(BRLE=0) Keep (BRLE=1) T	Т	I/O port BREQ
	6, 7	Т	Т	Кеер	_	I/O port
P62	1 to 5	Т	Т	(BRLE=0) Keep (BRLE=1) H	L	(BRLE=0) I/O port (BRLE=1) BACK
	6, 7	Т	Т	Keep	_	I/O port
P66 to P63	1 to 5	Н	T	(SSOE=0) T (SSOE=1) H	Т	AS, RD, HWR, LWR
	6, 7	Т	Т	Keep	_	I/O port
P67	1 to 7	Clock output		(PSTOP=0) H (PSTOP=1) Keep	(PSTOP=0) ¢ (PSTOP=1) Keep	(PSTOP=0) ¢ (PSTOP=1) Input port
P7 ₇ to P7 ₀	1 to 7	Т	Т	Т	Т	Input port

Pin Name	Mode	Reset	Hardware Standby Mode		Bus-Released Mode	Program Execution Mode
P80	1 to 5	T	T	When DRAM space is not selected*1 (RFSHE=0) Keep (RFSHE=1) Illegal setting When DRAM space is selected*2 (RFSHE=0) Keep (RFSHE=1, SRFMD=0, SSOE=0) T (RFSHE=1, SRFMD=0, SSOE=1) H (RFSHE=1, SRFMD=1) RFSH		(RFSHE=0) I/O port (RFSHE=1) RFSH
	6, 7	Т	Т	Keep	_	I/O port
P81	1 to 5	T	T	When DRAM space is selected*3 (SSOE=0) T (SSOE=1) H When DRAM space is selected*4 Keep Otherwise*5*1 (DDR=0) T (DDR=1, SSOE=0) T (DDR=1, SSOE=1) H	When DRAM space is selected*3 T When DRAM space is selected*4 Keep Otherwise*1 (DDR=0) Keep (DDR=1) T	When DRAM space is selected and RAS3 is output RAS3 When DRAM space is selected and RAS3 is not output I/O port Otherwise (DDR=0) Input port (DDR=1) CS3
	6, 7	Т	Т	Keep	_	I/O port

Pin Name	Mode	Reset	Hardware Standby Mode	Software Standby Mode	Bus-Released Mode	Program Execution Mode
P82	1 to 5	T	Т	RAS ₂ output* ² (SSOE=0) T (SSOE=1) H Otherwise* ¹ (DDR=0) T (DDR=1, SSOE=0) T (DDR=1, SSOE=1) H	RAS ₂ output* ² T Otherwise* ¹ (DDR=0) Keep (DDR=1) T	RAS ₂ output RAS ₂ Otherwise (DDR=0) I/O port (DDR=1) CS ₂
	6, 7	T	Т	Keep	_	I/O port
P83	1 to 5	Т	Т	(DDR=0) T (DDR=1, SSOE=0) T (DDR=1, SSOE=1) H	(DDR=0) Keep (DDR=1) T	(DDR=0) Input port (DDR=1) CS ₁
	6, 7	Т	Т	Keep	_	I/O port
P84	1 to 4	Н	Т	(DDR=0) T (DDR=1, SSOE=0) T (DDR=1, SSOE=1) H	(DDR = 0) Keep (DDR = 1) T	(DDR = 0) Input port (DDR = 1) CS ₀
	5	T	Т	(DDR=0) T (DDR=1, SSOE=0) T (DDR=1, SSOE=1) H	(DDR=0) Keep (DDR=1) T	(DDR=0) Input port (DDR=1) CS ₀
	6, 7	Т	Т	Keep	_	I/O port
P95 to	1 to 7	Т	Т	Keep	Keep	I/O port
PA ₃ to	1 to 7	Т	Т	Keep	Keep	I/O port
PA ₆ to PA ₄	1, 2, 6 7	, T	Т	Кеер	Keep	I/O port

Pin Name	Mode	Reset	Hardware Standby Mode	Software Standby Mode	Bus-Released Mode	Program Execution Mode
PA ₆ to PA ₄	3 to 5	Т	Т	Address output*5 (SSOE=0) T (SSOE=1) Keep Otherwise*6 Keep	Address output*5 T Otherwise*6 Keep	Address output A ₂₃ to A ₂₁ Otherwise I/O port
PA ₇	1, 2	Т	Т	Keep	Keep	I/O port
	3, 4	L	Т	(SSOE=0) T (SSOE=1) Keep	Т	A20
	5	L	Т	When A20E = 0 SSOE = 0 T SSOE = 1 Keep When A20E = 1 Keep	When A20E = 0 T When A20E = 1 Keep	When A20E = 0 A ₂₀ When A20E = 1 I/O port
	6, 7	Т	Т	Keep	_	I/O port
PB ₁ to PB ₀	1 to 5	T	Т	CS output*7 (SSOE=0) T (SSOE=1) H Otherwise*8 Keep	CS output* ⁷ T Otherwise* ⁸ Keep	CS output CS7 to CS6 Otherwise I/O port
	6, 7	Т	Т	Keep	_	I/O port
PB ₂	1 to 5	T	T	RAS5 output*9 (SSOE=0) T (SSOE=1) H CS output*10 (SSOE=0) T (SSOE=1) H Otherwise*11 Keep	RAS5 output*9 T CS output*10 T Otherwise*11 Keep	RAS5 output RAS5 CS output CS5 Otherwise I/O port
	6, 7	Т	Т	Кеер	_	I/O port

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Pin Name	Mode	Reset	Hardware Standby Mode		Bus-Released Mode	Program Execution Mode
PB ₃	1 to 5	Т	T	RAS4 output*12 (SSOE=0) T (SSOE=1) H CS output*13 (SSOE=0) T (SSOE=1) H Otherwise*14 Keep	RAS4 output*12 T CS output*13 T Otherwise*14 Keep	RAS4 output RAS4 CS output CS4 Otherwise I/O port
	6, 7	Т	Т	Кеер	_	I/O port
PB ₅ to PB ₄	1 to 5	Т	Т	CAS output*15 (SSOE=0) T (SSOE=1) H Otherwise*16 Keep	CAS output*15 T Otherwise*16 Keep	CAS output UCAS, LCAS Otherwise I/O port
	6, 7	Т	Т	Кеер	_	I/O port
PB7 to PB6	1 to 7	Т	Т	Keep	Keep	I/O port

Legend

H: High

T: High-impedance state

Keep: Input pins are in the high-impedance state; output pins maintain their previous state.

DDR: Data direction register

Notes: 1. When bits DRAS2, DRAS1, and DRAS0 in DRCRA (DRAM control register A) are all cleared to 0.

- When any of bits DRAS2, DRAS1, or DRAS0 in DRCRA (DRAM control register A) is set to 1.
- 3. When the setting of bits DRAS2, DRAS1, and DRAS0 in DRCRA (DRAM control register A) is 010, 100, or 101.
- 4. When the setting of bits DRAS2, DRAS1, and DRAS0 in DRCRA (DRAM control register A) is other than 010, 100, 101, or 000.
- 5. When bit A23E, A22E, or A21E, respectively, in BRCR (bus release control register) is cleared to 0.
- 6 When bit A23E, A22E, or A21E, respectively, in BRCR (bus release control register) is set to 1.

- 7. When bit CS7E or CS6E, respectively, in CSCR (chip select control register) is set to 1.
- 8. When bit CS7E or CS6E, respectively, in CSCR (chip select control register) is cleared to 0.
- 9. When the setting of bits DRAS2, DRAS1, and DRAS0 in DRCRA (DRAM control register A) is 101.
- 10. When the setting of bits DRAS2, DRAS1, and DRAS0 in DRCRA (DRAM control register A) is other than 101, and bit CS5E in CSCR (chip select control register) is set to 1.
- 11. When the setting of bits DRAS2, DRAS1, and DRAS0 in DRCRA (DRAM control register A) is other than 101, and bit CS5E in CSCR (chip select control register) is cleared to 0.
- 12. When the setting of bits DRAS2, DRAS1, and DRAS0 in DRCRA (DRAM control register A) is 100, 101, or 110.
- 13. When the setting of bits DRAS2, DRAS1, and DRAS0 in DRCRA (DRAM control register A) is other than 100, 101, or 110, and bit CS4E in CSCR (chip select control register) is set to 1.
- 14. When the setting of bits DRAS2, DRAS1, and DRAS0 in DRCRA (DRAM control register A) is other than 100, 101, or 110, and bit CS4E in CSCR (chip select control register) is cleared to 0.
- 15. When any of bits DRAS2, DRAS1, or DRAS0 in DRCRA (DRAM control register A) is set to 1, and bit CSEL in DRCRB (DRAM control register B) is cleared to 0.
- 16. When any of bits DRAS2, DRAS1, or DRAS0 in DRCRA (DRAM control register A) is set to 1, and bit CSEL in DRCRB (DRAM control register B) is set to 1; or, when bits DRAS2, DRAS1, and DRAS0 are all cleared to 0.
- 17. RESO output is a mask ROM version function. A low level is output only in the case of a reset due to WDT overflow. There is no bus-released state in modes 6 and 7.



D.2 Pin States at Reset

Modes 1 and 2: Figure D.1 is a timing diagram for the case in which \overline{RES} goes low during an external memory access in mode 1 or 2. As soon as \overline{RES} goes low, all ports are initialized to the input state. \overline{AS} , \overline{RD} , \overline{HWR} , \overline{LWR} , and \overline{CS}_0 go high, and D_{15} to D_0 go to the high-impedance state. The address bus is initialized to the low output level 2.5 ϕ clock cycles after the low level of \overline{RES} is sampled. Clock pin $P6_7/\phi$ goes to the output state at the next rise of ϕ after \overline{RES} goes low.

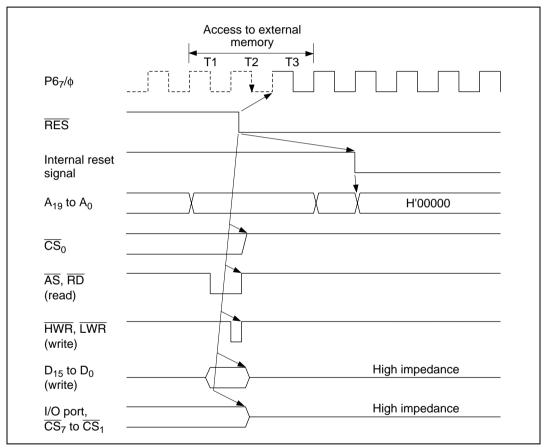


Figure D.1 Reset during Memory Access (Modes 1 and 2)

Modes 3 and 4: Figure D.2 is a timing diagram for the case in which \overline{RES} goes low during an external memory access in mode 3 or 4. As soon as \overline{RES} goes low, all ports are initialized to the input state. \overline{AS} , \overline{RD} , \overline{HWR} , \overline{LWR} , and \overline{CS}_0 go high, and D_{15} to D_0 go to the high-impedance state. The address bus is initialized to the low output level 2.5 ϕ clock cycles after the low level of \overline{RES} is sampled. However, when PA_4 to PA_6 are used as address bus pins, or when $P8_3$ to $P8_1$ and PB_0 to $P8_3$ are used as CS output pins, they go to the high-impedance state at the same time as \overline{RES} goes low. Clock pin $P6_4/\phi$ goes to the output state at the next rise of ϕ after \overline{RES} goes low.

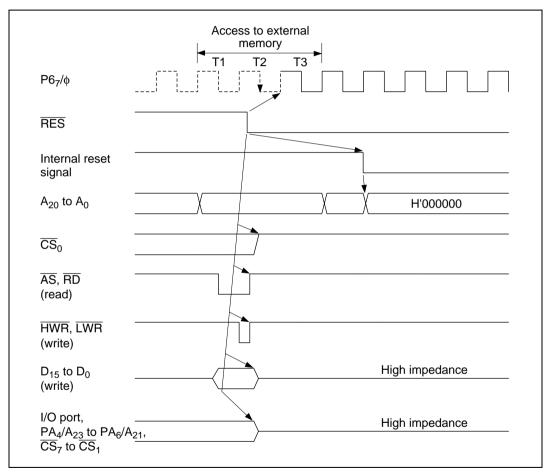


Figure D.2 Reset during Memory Access (Modes 3 and 4)

Mode 5: Figure D.3 is a timing diagram for the case in which \overline{RES} goes low during an external memory access in mode 5. As soon as \overline{RES} goes low, all ports are initialized to the input state. \overline{AS} , \overline{RD} , \overline{HWR} , and \overline{LWR} go high, and the address bus and D_{15} to D_0 go to the high-impedance state. Clock pin P6₂/ φ goes to the output state at the next rise of φ after \overline{RES} goes low.

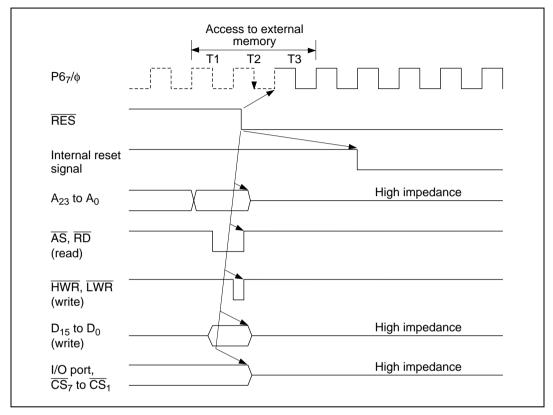


Figure D.3 Reset during Memory Access (Mode 5)

Modes 6 and 7: Figure D.4 is a timing diagram for the case in which \overline{RES} goes low during an operation in mode 6 or 7. As soon as \overline{RES} goes low, all ports are initialized to the input state. Clock pin P6₇/ ϕ goes to the output state at the next rise of ϕ after \overline{RES} goes low.

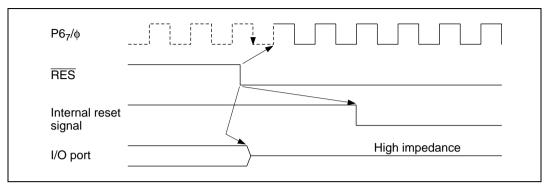
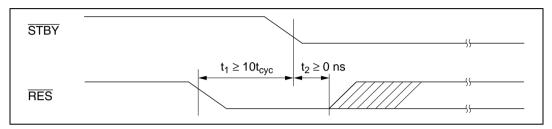


Figure D.4 Reset during Operation (Modes 6 and 7)

Appendix E Timing of Transition to and Recovery from Hardware Standby Mode

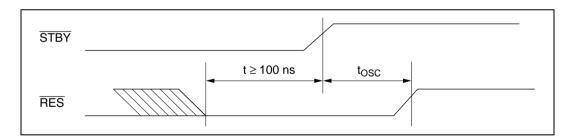
Timing of Transition to Hardware Standby Mode

1. To retain RAM contents with the RAME bit set to 1 in SYSCR, drive the RES signal low 10 system clock cycles before the STBY signal goes low, as shown below. RES must remain low until STBY goes low (minimum delay from STBY low to RES high: 0 ns).



2. To retain RAM contents with the RAME bit cleared to 0 in SYSCR, RES does not have to be driven low as in (1).

Timing of Recovery from Hardware Standby Mode: Drive the \overline{RES} signal low approximately 100 ns before \overline{STBY} goes high.



Appendix F Product Code Lineup

Product T	уре		Product Code	Mark Code	Package (Package Code)
H8/3067	On-chip flash	5 VR	HD64F3067RF	HD64F3067RF	100-pin QFP (PRQP0100KA-A)
	memory		HD64F3067RTE	HD64F3067RTE	100-pin TQFP (PTQP0100KA-A)
			HD64F3067RFP	HD64F3067RFP	100-pin QFP (PRQP0100JE-B)
		3 VR	HD64F3067RVF	HD64F3067RVF	100-pin QFP (PRQP0100KA-A)
			HD64F3067RVTE	HD64F3067RVTE	100-pin TQFP (PTQP0100KA-A)
			HD64F3067RVFP	HD64F3067RVFP	100-pin QFP (PRQP0100JE-B)
	On-chip mask	5 V	HD6433067F	HD6433067(***)F	100-pin QFP (PRQP0100KA-A)
	ROM		HD6433067TE	HD6433067(***)TE	100-pin TQFP (PTQP0100KA-A)
			HD6433067FP	HD6433067(***)FP	100-pin QFP (PRQP0100JE-B)
		3 V	HD6433067VF	HD6433067(***)VF	100-pin QFP (PRQP0100KA-A)
			HD6433067VTE	HD6433067(***)VTE	100-pin TQFP (PTQP0100KA-A)
			HD6433067VFP	HD6433067(***)VFP	100-pin QFP (PRQP0100JE-B)

Product 1	Гуре		Product Code	Mark Code	Package (Package Code)
H8/3066	On-chip mask	5 V	HD6433066F	HD6433066(***)F	100-pin QFP (PRQP0100KA-A)
	ROM		HD6433066TE	HD6433066(***)TE	100-pin TQFP (PTQP0100KA-A)
			HD6433066FP	HD6433066(***)FP	100-pin QFP (PRQP0100JE-B)
		3 V	HD6433066VF	HD6433066(***)VF	100-pin QFP (PRQP0100KA-A)
			HD6433066VTE	HD6433066(***)VTE	100-pin TQFP (PTQP0100KA-A)
			HD6433066VFP	HD6433066(***)VFP	100-pin QFP (PRQP0100JE-B)
H8/3065	On-chip mask	5 V	HD6433065F	HD6433065(***)F	100-pin QFP (PRQP0100KA-A)
	ROM		HD6433065TE	HD6433065(***)TE	100-pin TQFP (PTQP0100KA-A)
			HD6433065FP	HD6433065(***)FP	100-pin QFP (PRQP0100JE-B)
		3 V	HD6433065VF	HD6433065(***)VF	100-pin QFP (PRQP0100KA-A)
			HD6433065VTE	HD6433065(***)VTE	100-pin TQFP (PTQP0100KA-A)
			HD6433065VFP	HD6433065(***)VFP	100-pin QFP (PRQP0100JE-B)

Note: For mask ROM versions, (***) is the ROM code.

Appendix G Package Dimensions

Figures G.1 show the PRQP0100KA-A package dimensions of the H8/3067 Group. Figure G.2 shows the PTQP0100KA-A package dimensions. Figure G.3 shows the PRQP0100JE-B package dimensions.

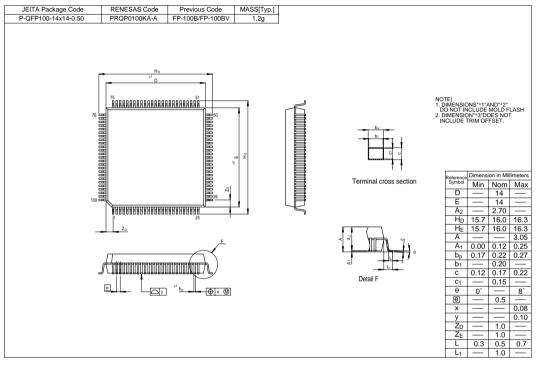


Figure G.1 Package Dimensions (PRQP0100KA-A)

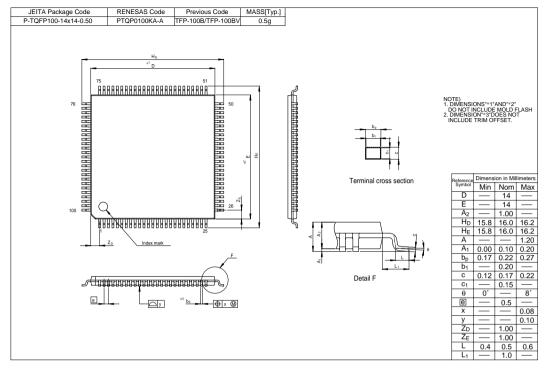


Figure G.2 Package Dimensions (PTQP0100KA-A)

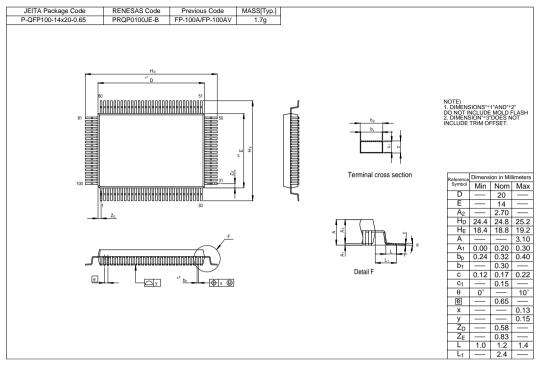


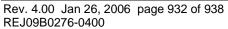
Figure G.3 Package Dimensions (PRQP0100JE-B)

Appendix H Comparison of H8/300H Series Product Specifications

H.1 Differences between H8/3067 and H8/3062 Group, H8/3048 Group, H8/3007 and H8/3006, and H8/3002

	perating ode	Mode 5				
			16 MB ROM enabled expanded mode	1 MB ROM enabled expanded mode		
		Mode 6	64 KB single-chip mode	16 MB ROM enabled expanded mode		
	terrupt	•	36 (H8/3067)	30	36	30
COI	ontroller	sources	27 (H8/3062)			
3 Bu		Burst ROM	Yes (H8/3067)	No	Yes	No
COI	ontroller	interface	No (H8/3062)			
		Idle cycle insertion function	Yes	No	Yes	No
		Wait mode	2 modes	4 modes	2 modes	4 modes
		Wait state number setting	Per area	Common to all areas	Per area	Common to all areas
		Address output method	Choice of address update mode (mask ROM and flash memory R versions only)	Fixed	Fixed	Fixed
	RAM terface	Connectable areas	Area 2/3/4/5 (H8/3067 only)	Area 3	Area 2/3/4/5	Area 3
		Precharge cycle insertion function	Yes (H8/3067 only)	No	Yes	No
		Fast page mode	Yes (H8/3067 only)	No	Yes	No
		Address shift amount	8 bit/9 bit/10 bit (H8/3067 only)	8 bit/9 bit	8 bit/9 bit/10 bit	8 bit/9 bit

	Item		H8/3067, H8 Group	3/3062	H8/3048 Group	H8/3006, 30	007	H8/3002
5	Timer fund	ctions	16-bit timers	8-bit timers	ITU	16-bit timers	8-bit timers	ITU
		Number of channels	16 bits \times 3	8 bits × 4 (16 bits × 2)	16 bits × 5	16 bits \times 3	8 bits × 4 (16 bits × 2)	16 bits × 5
		Pulse output	6 pins	4 pins (2 pins)	12 pins	6 pins	4 pins (2 pins)	12 pins
		Input capture	6	2	10	6	2	10
		External clock	4 systems (selectable)	4 systems (fixed)	4 systems (selectable)	4 systems (selectable)	4 systems (fixed)	4 systems (selectable)
		Internal clock	φ, φ/2, φ/4, φ/8	φ/8, φ/64, φ/8192	φ, φ/2, φ/4, φ/8	φ, φ/2, φ/4, φ/8	φ/8, φ/64, φ/8192	φ, φ/2, φ/4, φ/8
		Complementary PWM function	No	No	Yes	No	No	Yes
		Reset- synchronous PWM function	No	No	Yes	No	No	Yes
		Buffer operation	No	No	Yes	No	No	Yes
		Output initialization function	Yes	No	No	Yes	No	No
		PWM output	3	4 (2)	5	3	4 (2)	5
		DMAC activation	3 channels (H8/3067 only)	No	4 channels	3 channels	No	4 channels
		A/D conversion activation	No	Yes	No	No	Yes	No
		Interrupt sources	3 sources × 3	8 sources	3 sources × 5	3 sources × 3	8 sources	3 sources × 5
6	TPC	Time base	3 kinds, 16-l base	bit timer	4 kinds, ITU base	3 kinds, 16- base	bit timer	4 kinds, ITU base
7	WDT	Reset signal external output function	Yes (except with on-chip memory)	•	Yes	Yes		Yes
8	SCI	Number of	3 channels	(H8/3067)	2 channels	3 channels		2 channels
		channels	2 channels	(H8/3062)				
		Smart card interface	Supported of channels	on all	Supported on SCI0 only	Supported of channels	on all	No





	Item		H8/3067, H8/3062 Group	H8/3048 Group	H8/3006, 3007	H8/3002
9	A/D converter	Conversion start trigger input	External trigger/8-bit timer compare match	External trigger	External trigger/8-bit timer compare match	External trigger
10	Pin control	φ pin	φ/input port multiplexing	φ output only	φ/input port multiplexing	φ output only
		A ₂₀ in 16 MB ROM enabled expanded mode	A ₂₀ / I/O port multiplexing	A ₂₀ output		
		Address bus, AS, RD, HWR, LWR, CS,-CS, RFSH in software standby state	High-level output/high- impedance selectable (RFSH: H8/3067 only)	High-level output (except $\overline{\text{CS}}_{\scriptscriptstyle{0}}$)	High-level output/high- impedance selectable	High-level output (except $\overline{\text{CS}}_{\scriptscriptstyle{0}}$)
)	Low-level output (\overline{CS}_0)		Low-level output (\overline{CS}_0)
		CS, −CS₀ in busreleased state	High-impedance	High-level output	High-impedance	High-level output
11	Flash memory functions	Program/erase voltage	12 V application unnecessary. Single-power-supply programming.	12 V application from off-chip)	
		Block divisions	8 blocks	16 blocks		

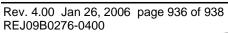
H.2 Comparison of Pin Functions of 100-Pin Package Products (PRQP0100KA-A, PTQP0100KA-A)

Table H.1 Pin Arrangement of Each Product (PRQP0100KA-A, PTQP0100KA-A)

Pin	On-chip-ROM P	roducts	ROMIess Products			
No.	H8/3067 Group	H8/3062 Group	H8/3048 Group	H8/3042 Group	H8/3006, 3007	H8/3002
1	Vcc	Vcc	Vcc	Vcc	Vcc	Vcc
2	PB ₀ /TP ₈ /TMO ₀ / CS ₇	PB ₀ /TP ₈ /TMO ₀ / CS ₇	PB ₀ /TP ₈ / TIOCA ₃	PB ₀ /TP ₂ / TIOCA ₃	PB ₀ /TP _x /TMO ₀ / CS ₇	PB ₀ /TP ₈ / TIOCA ₃
3	PB ₁ /TP ₉ /TMIO ₁ / DREQ ₀ /CS ₆	PB ₁ /TP ₉ /TMIO ₁ / CS ₆	PB₁/TP₅/ TIOCB₃	PB ₁ /TP ₉ / TIOCB ₃	PB ₁ /TP ₉ /TMIO ₁ / DREQ ₀ /CS ₆	PB₁/TP₅/ TIOCB₃
4	$\frac{PB_2/TP_{10}/TMO_2/}{\overline{CS}_5}$	$\frac{PB_2/TP_{10}/TMO_2/}{\overline{CS}_5}$	PB ₂ /TP ₁₀ / TIOCA ₄	PB ₂ /TP ₁₀ / TIOCA ₄	$\frac{PB_2/TP_{10}/TMO_2/}{CS_5}$	PB ₂ /TP ₁₀ / TIOCA ₄
5	PB ₃ /TP ₁₁ / TMIO ₃ /DREQ ₁ / CS ₄	PB ₃ /TP ₁₄ / TMIO ₃ /CS ₄	PB ₄ /TP ₁₁ / TIOCB ₄	PB ₄ /TP ₁₁ / TIOCB ₄	PB ₃ /TP ₁₁ / TMIO ₃ /DREQ ₁ / CS ₄	PB ₃ /TP ₁₁ / TIOCB ₄
6	PB ₄ /TP ₁₂ / UCAS	PB ₄ /TP ₁₂	PB ₄ /TP ₁₂ / TOCXA ₄	PB ₄ /TP ₁₂ / TOCXA ₄	PB ₄ /TP ₁₂ / UCAS	PB ₄ /TP ₁₂ / TOCXA ₄
7	PB ₅ /TP ₁₃ / LCAS/SCK ₂	PB ₅ /TP ₁₃	PB _s /TP ₁₃ / TOCXB ₄	PB ₅ /TP ₁₃ / TOCXB ₄	PB _s /TP ₁₃ / LCAS/SCK ₂	PB _s /TP ₁₃ / TOCXB ₄
8	PB ₆ /TP ₁₄ /TxD ₂	PB ₆ /TP ₁₄	PB ₆ /TP ₁₄ / DREQ ₀ /CS ₇	PB ₆ /TP ₁₄ / DREQ ₀	PB ₆ /TP ₁₄ /TxD ₂	PB,/TP ₁₄ / DREQ ₀
9	PB ₇ /TP ₁₅ /RxD ₂	PB ₇ /TP ₁₅	PB ₇ /TP ₁₅ / DREQ ₁ /ADTRG	PB ₇ /TP ₁₅ / DREQ ₁ /ADTRG	PB ₇ /TP ₁₅ /RxD ₂	PB ₇ /TP ₁₅ / DREQ ₁ /ADTRG
10	RESO/FWE*	RESO/FWE*	RESO/V _{PP} *	RESO	RESO	RESO
11	Vss	Vss	Vss	Vss	Vss	Vss
12	P9 ₀ /TxD ₀	P9 ₀ /TxD ₀	P9 ₀ /TxD ₀	P9 ₀ /TxD ₀	P9 ₀ /TxD ₀	P9 ₀ /TxD ₀
13	P9 ₁ /TxD ₁	P9 ₁ /TxD ₁	P9 ₁ /TxD ₁	P9 ₁ /TxD ₁	P9 ₁ /TxD ₁	P9 ₁ /TxD ₁
14	P9 ₂ /RxD ₀	P9 ₂ /RxD ₀	$P9_{2}/RxD_{0}$	P9 ₂ /RxD ₀	P9 ₂ /RxD ₀	P9 ₂ /RxD ₀
15	P9 ₃ /RxD ₁	P9 ₃ /RxD ₁	P9 ₃ /RxD ₁	P9 ₃ /RxD ₁	P9 ₃ /RxD ₁	P9 ₃ /RxD ₁
16	P9 ₄ /SCK ₀ /IRQ ₄	P9 ₄ /SCK ₀ /IRQ ₄	P9 ₄ /SCK ₀ /IRQ ₄	P9 ₄ /SCK ₀ /IRQ ₄	$P9_4/SCK_0/\overline{IRQ}_4$	P9 ₄ /SCK ₀ /IRQ ₄
17	$P9_{5}/SCK_{1}/\overline{IRQ}_{5}$	$P9_{5}/SCK_{1}/\overline{IRQ}_{5}$	$P9_{5}/SCK_{1}/\overline{IRQ}_{5}$	$P9_{5}/SCK_{1}/\overline{IRQ}_{5}$	$P9_{5}/SCK_{1}/\overline{IRQ}_{5}$	P9₅/SCK₁/ĪRQ₅
18	P4 ₀ /D ₀	P4 ₀ /D ₀	P4 ₀ /D ₀	P4 ₀ /D ₀	P4 ₀ /D ₀	P4 ₀ /D ₀
19	P4 ₁ /D ₁	P4 ₁ /D ₁	P4 ₁ /D ₁	P4 ₁ /D ₁	P4 ₁ /D ₁	P4 ₁ /D ₁
20	P4 ₂ /D ₂	P4 ₂ /D ₂	P4 ₂ /D ₂	P4 ₂ /D ₂	P4 ₂ /D ₂	P4 ₂ /D ₂
21	P4 ₃ /D ₃	P4 ₃ /D ₃	P4 ₃ /D ₃	P4 ₃ /D ₃	P4 ₃ /D ₃	P4 ₃ /D ₃
22	Vss	Vss	Vss	Vss	Vss	Vss
23	P4 ₄ /D ₄	P4 ₄ /D ₄	P4 ₄ /D ₄	P4 ₄ /D ₄	P4 ₄ /D ₄	P4 ₄ /D ₄

Pin	On-chip-ROM Products				ROMIess Products	
No.	H8/3067 Group	H8/3062 Group	H8/3048 Group	H8/3042 Group	H8/3006, 3007	H8/3002
24	P4 ₅ /D ₅	P4 ₅ /D ₅	P4 ₅ /D ₅	P4 _s /D _s	P4 ₅ /D ₅	P4 ₅ /D ₅
25	P4 ₆ /D ₆	P4 ₆ /D ₆	P4 ₆ /D ₆			
26	P4 ₇ /D ₇	P4 ₇ /D ₇	P4 ₇ /D ₇			
27	P3 ₀ /D ₈	D ₈	D ₈			
28	P3 ₁ /D ₉	D ₉	D ₉			
29	P3 ₂ /D ₁₀	D ₁₀	D ₁₀			
30	P3 ₃ /D ₁₁	D ₁₁	D ₁₁			
31	P3 ₄ /D ₁₂	D ₁₂	D ₁₂			
32	P3 ₅ /D ₁₃	D ₁₃	D ₁₃			
33	P3 ₆ /D ₁₄	D ₁₄	D ₁₄			
34	P3/D ₁₅	P3 ₇ /D ₁₅	P3 ₇ /D ₁₅	P3 ₇ /D ₁₅	D ₁₅	D ₁₅
35	Vcc	Vcc	Vcc	Vcc	Vcc	Vcc
36	P1 ₀ /A ₀	P1 ₀ /A ₀	P1 _o /A _o	P1 ₀ /A ₀	A _o	A _o
37	P1,/A,	P1,/A,	P1,/A,	P1,/A,	A ₁	A ₁
38	P1 ₂ /A ₂	A ₂	A ₂			
39	P1 ₃ /A ₃	A ₃	A_3			
40	P1 ₄ /A ₄	P1,/A,	P1 ₄ /A ₄	P1 ₄ /A ₄	A ₄	A ₄
41	P1 ₅ /A ₅	A ₅	A ₅			
42	P1 ₆ /A ₆	A ₆	A ₆			
43	P1,/A,	P1 ₇ /A ₇	P1 ₇ /A ₇	P1 ₇ /A ₇	A,	A,
44	Vss	Vss	Vss	Vss	Vss	Vss
45	P2 ₀ /A ₈	A ₈	A ₈			
46	P2 ₁ /A ₉	P2,/A ₉	P2 ₁ /A ₉	P2,/A ₉	A ₉	A ₉
47	P2 ₂ /A ₁₀	A ₁₀	A ₁₀			
48	P2 ₃ /A ₁₁	A ₁₁	A ₁₁			
49	P2,/A ₁₂	P2,/A ₁₂	P2,/A ₁₂	P2,/A ₁₂	A ₁₂	A ₁₂
50	P2 ₅ /A ₁₃	A ₁₃	A ₁₃			
51	P2 ₆ /A ₁₄	A ₁₄	A ₁₄			
52	P2/A ₁₅	P2 ₇ /A ₁₅	P2,/A ₁₅	P2 ₇ /A ₁₅	A ₁₅	A ₁₅
53	P5 ₀ /A ₁₆	A ₁₆	A ₁₆			
54	P5 ₁ /A ₁₇	A ₁₇	A ₁₇			
55	P5 ₂ /A ₁₈	A ₁₈	A ₁₈			
56	P5 ₃ /A ₁₉	A ₁₉	A ₁₉			

Pin	On-chip-ROM Products				ROMless Products	
	H8/3067 Group	H8/3062 Group	H8/3048 Group	H8/3042 Group	H8/3006, 3007	H8/3002
57	Vss	Vss	Vss	Vss	Vss	Vss
58	P6 ₀ /WAIT	P6 ₀ /WAIT	P6 ₀ /WAIT	P6₀/WAIT	P6₀/WAIT	P6 ₀ /WAIT
59	P6₁/BREQ	P6₁/BREQ	P6₁/BREQ	P6₁/BREQ	P6₁/BREQ	P6₁/BREQ
60	P6 ₂ /BACK	P6 ₂ /BACK	P6 ₂ /BACK	P6 ₂ /BACK	P6₂/BACK	P6 ₂ /BACK
61	P6,/ф	P6,/\$	ф	ф	P6,/ф	ф
62	STBY	STBY	STBY	STBY	STBY	STBY
63	RES	RES	RES	RES	RES	RES
64	NMI	NMI	NMI	NMI	NMI	NMI
65	Vss	Vss	Vss	Vss	Vss	Vss
66	EXTAL	EXTAL	EXTAL	EXTAL	EXTAL	EXTAL
67	XTAL	XTAL	XTAL	XTAL	XTAL	XTAL
68	Vcc	Vcc	Vcc	Vcc	Vcc	Vcc
69	P6 ₃ /AS	P6 ₃ /AS	P6₃/AS	P6 ₃ /AS	ĀS	ĀS
70	P6₄/RD	P6₄/RD	P6₄/RD	P6₄/RD	RD	RD
71	P6₅/ HWR	P6₅/ HWR	P6₅/ HWR	P6₅/ HWR	HWR	HWR
72	P6 ₆ /LWR	P6 ₆ /LWR	P6 ₆ /LWR	P6 ₆ /LWR	LWR	LWR
73	MD_{o}	MD_{\circ}	MD_{\circ}	MD _o	MD_o	MD₀
74	MD ₁	MD ₁				
75	MD ₂	MD ₂	MD ₂	MD ₂	$MD_{\scriptscriptstyle 2}$	$MD_{\scriptscriptstyle 2}$
76	AVcc	AVcc	AVcc	AVcc	AVcc	AVcc
77	V_{REF}	V_{REF}	V_{REF}	V _{REF}	V _{REF}	V _{REF}
78	P7 ₀ /AN ₀	P7 ₀ /AN ₀				
79	P7,/AN,	P7,/AN,	P7,/AN,	P7,/AN,	P7 ₁ /AN ₁	P7,/AN,
80	P7 ₂ /AN ₂	P7 ₂ /AN ₂				
81	P7 ₃ /AN ₃	P7 ₃ /AN ₃				
82	P7 ₄ /AN ₄	P7 ₄ /AN ₄				
83	P7 ₅ /AN ₅	P7 ₅ /AN ₅				
84	P7 ₆ /AN ₆ /DA ₀	P7 ₆ /AN ₆				
85	P7 _/ AN _/ DA ₁	P7 ₇ /AN ₂ /DA ₁	P7 _/ AN _/ DA ₁	P7,/AN,/DA,	P7 ₇ /AN ₇ /DA ₁	P7 ₇ /AN ₇
86	AVss	AVss	AVss	AVss	AVss	AVss
87	P8 ₀ /RFSH/IRQ ₀	P8 ₀ /IRQ ₀	P8 ₀ /RFSH/IRQ ₀	P8 ₀ /RFSH/IRQ ₀	P8,/RFSH/IRQ ₀	P8 ₀ /RFSH/IRQ ₀
	P8,/CS,/IRQ,	P8,/CS,/IRQ,	P8,/CS,/IRQ,	P8,/CS,/IRQ,	P8,/CS,/IRQ,	P8,/CS,/IRQ,





Pin	On-chip-ROM Products				ROMIess Products	
No.	H8/3067 Group	H8/3062 Group	H8/3048 Group	H8/3042 Group	H8/3006, 3007	H8/3002
89	P8 ₂ /CS ₂ /IRQ ₂	P8 ₂ /CS ₂ /IRQ ₂	P8 ₂ /CS ₂ /IRQ ₂	P8 ₂ /CS ₂ /IRQ ₂	P8 ₂ /CS ₂ /IRQ ₂	P8 ₂ /CS ₂ /IRQ ₂
90	P8 ₃ /CS ₁ /IRQ ₃ / ADTRG	P8 ₃ /CS ₁ /IRQ ₃ /ADTRG	P8 ₃ /CS ₁ /IRQ ₃	P8 ₃ /CS ₁ /IRQ ₃	P8 ₃ /CS ₁ /IRQ ₃ /ADTRG	P8 ₃ /CS ₁ /IRQ ₃
91	P8₄/ CS ₀	P8₄/CS₀	P8₄/ CS ₀	P8 ₄ /CS ₀	P8 ₄ /CS ₀	P8₄/ CS ₀
92	Vss	Vss	Vss	Vss	Vss	Vss
93	PA,/TP,/ TEND,/TCLKA	PA,/TP,/TCLKA	PA,/TP,/ TEND,/TCLKA	PA,/TP,/ TEND,/TCLKA	PA/TP/ TEND/TCLKA	PA/TP/ TEND/TCLKA
94	PA,/TP,/ TEND,/TCLKB	PA,/TP,/TCLKB	PA,/TP,/ TEND,/TCLKB	PA,/TP,/ TEND,/TCLKB	PA,/TP,/ TEND,/TCLKB	PA,/TP,/ TEND,/TCLKB
95	PA_/TP_/ TIOCA ₀ /TCLKC	PA_/TP_/ TIOCA_/TCLKC	PA ₂ /TP ₂ / TIOCA ₀ /TCLKC	PA_/TP_/ TIOCA ₀ /TCLKC	PA ₂ /TP ₂ / TIOCA ₀ /TCLKC	PA ₂ /TP ₂ / TIOCA ₀ /TCLKC
96	PA,/TP,/ TIOCB ₀ /TCLKD	PA,/TP,/ TIOCB,/TCLKD	PA,/TP,/ TIOCB,/TCLKD	PA ₃ /TP ₃ / TIOCB ₀ /TCLKD	PA ₃ /TP ₃ / TIOCB ₀ /TCLKD	PA,/TP,/ TIOCB,/TCLKD
97	PA ₄ /TP ₄ / TIOCA ₁ /A ₂₃	PA ₄ /TP ₄ / TIOCA ₁ /A ₂₃	PA ₄ /TP ₄ / TIOCA ₁ / CS ₆ /A ₂₃	PA ₄ /TP ₄ / TIOCA ₁ /A ₂₃	PA ₄ /TP ₄ / TIOCA ₁ /A ₂₃	PA ₄ /TP ₄ / TIOCA ₁ /A ₂₃
98	PA _x /TP _x / TIOCB ₁ /A ₂₂	PA ₅ /TP ₅ / TIOCB ₁ /A ₂₂	PA ₅ /TP ₅ / TIOCB ₁ / CS ₅ /A ₂₂	PA ₂ /TP ₂ / TIOCB ₁ /A ₂₂	PA _x /TP _x / TIOCB ₁ /A ₂₂	PA ₂ /TP ₂ / TIOCB ₁ /A ₂₂
99	PA ₆ /TP ₆ / TIOCA ₂ /A ₂₁	PA ₆ /TP ₆ / TIOCA ₂ /A ₂₁	PA ₆ /TP ₆ / TIOCA ₂ / CS ₄ /A ₂₁	PA ₆ /TP ₆ / TIOCA ₂ /A ₂₁	PA ₆ /TP ₆ / TIOCA ₂ /A ₂₁	PA ₆ /TP ₆ / TIOCA ₂ /A ₂₁
100	PA/TP/ TIOCB ₂ /A ₂₀	PA ₇ /TP ₇ / TIOCB ₂ /A ₂₀	PA/TP/ TIOCB ₂ /A ₂₀	PA ₂ /TP ₂ / TIOCB ₂ /A ₂₀	PA/TP ₇ / TIOCB ₂ /A ₂₀	PA/TP/ TIOCB ₂ /A ₂₀

Note: * Functions as RESO in the mask ROM versions, and as FWE in the flash memory and flash memory R versions.

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Renesas Technology America, Inc.

450 Holger Way, San Jose, CA 95134-1368, U.S.A Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

Renesas Technology Europe Limited Dukes Meadow, Millboard Road, Boume End, Buckinghamshire, SL8 5FH, U.K. Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

Renesas Technology (Shanghai) Co., Ltd. Unit 205, AZIA Center, No. 133 Yincheng Rd (n), Pudong District, Shanghai 200120, China Tei: <865 (21) 5877-1818, Fax: <865 (21) 6887-7898

Renesas Technology Hong Kong Ltd.
7th Floor, North Tower, World Finance Centre, Harbour City, 1 Canton Road, Tsimshatsui, Kowloon, Hong Kong Tel: <852> 2265-6688, Fax: <852> 2730-6071

Renesas Technology Taiwan Co., Ltd. 10th Floor, No.99, Fushing North Road, Taipei, Taiwan Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

Renesas Technology Singapore Pte. Ltd. 1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632 Tel: -655-6213-0200, Fax: -655-6278-8001

Renesas Technology Korea Co., Ltd. Kukje Center Bldg. 18th Fl., 191, 2-ka, Hangang-ro, Yongsan-ku, Seoul 140-702, Korea Tel: <82> (2) 796-3115, Fax: <82> (2) 796-2145

Renesas Technology Malaysia Sdn. Bhd

Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia Tel: <603> 7955-9390. Fax: <603> 7955-9510

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